

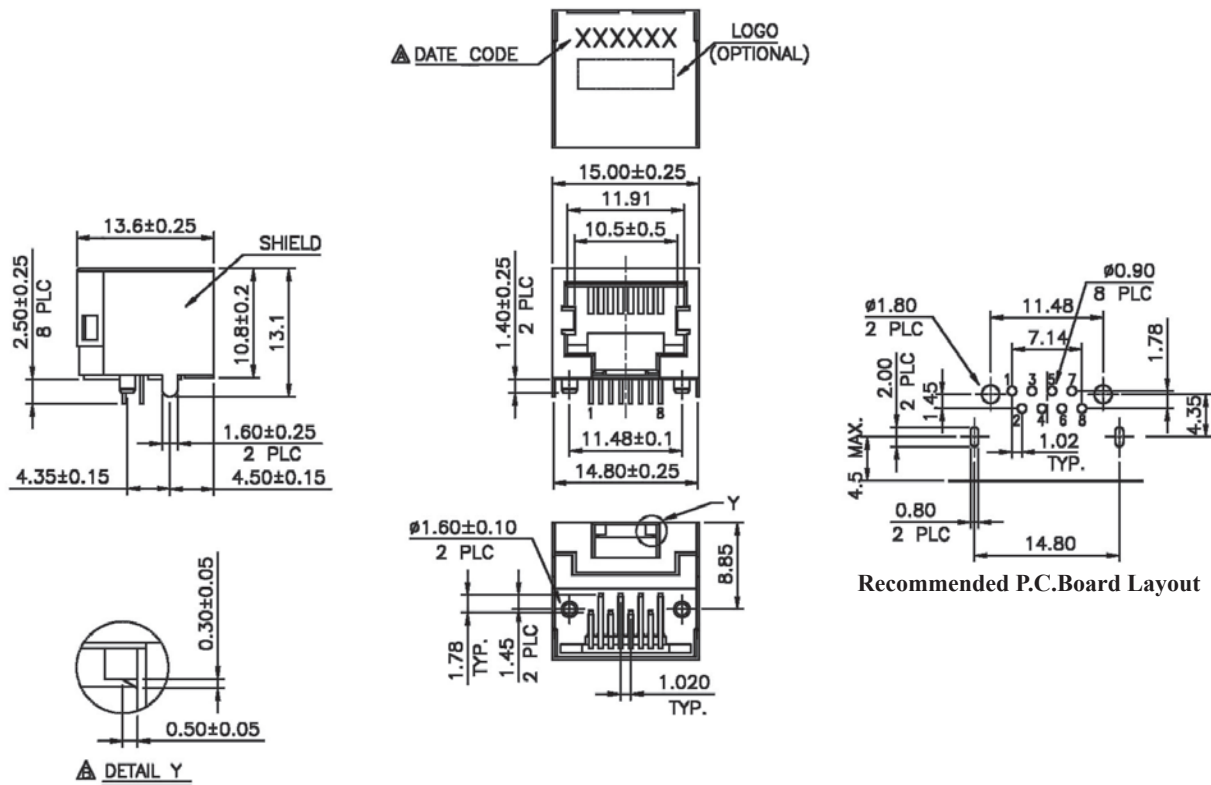
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=10.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J NG - 88 x B
 I 2 3 4

- MODULAR JACK TYPE:
"NG" VERY LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

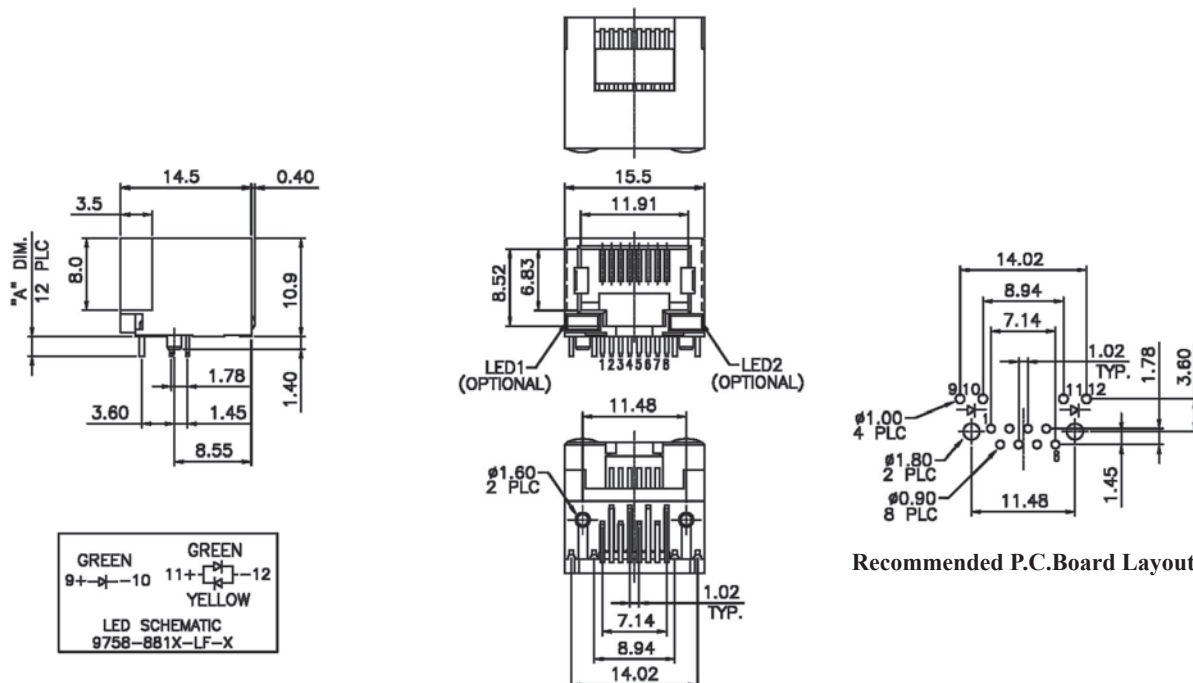
SIDE ENTRY MODULAR PCB JACK 8P WITH LED PROFILE=10.90MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J K P - 88 x B x x
 1 2 3 4 5

1. MODULAR JACK TYPE:
"KP" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

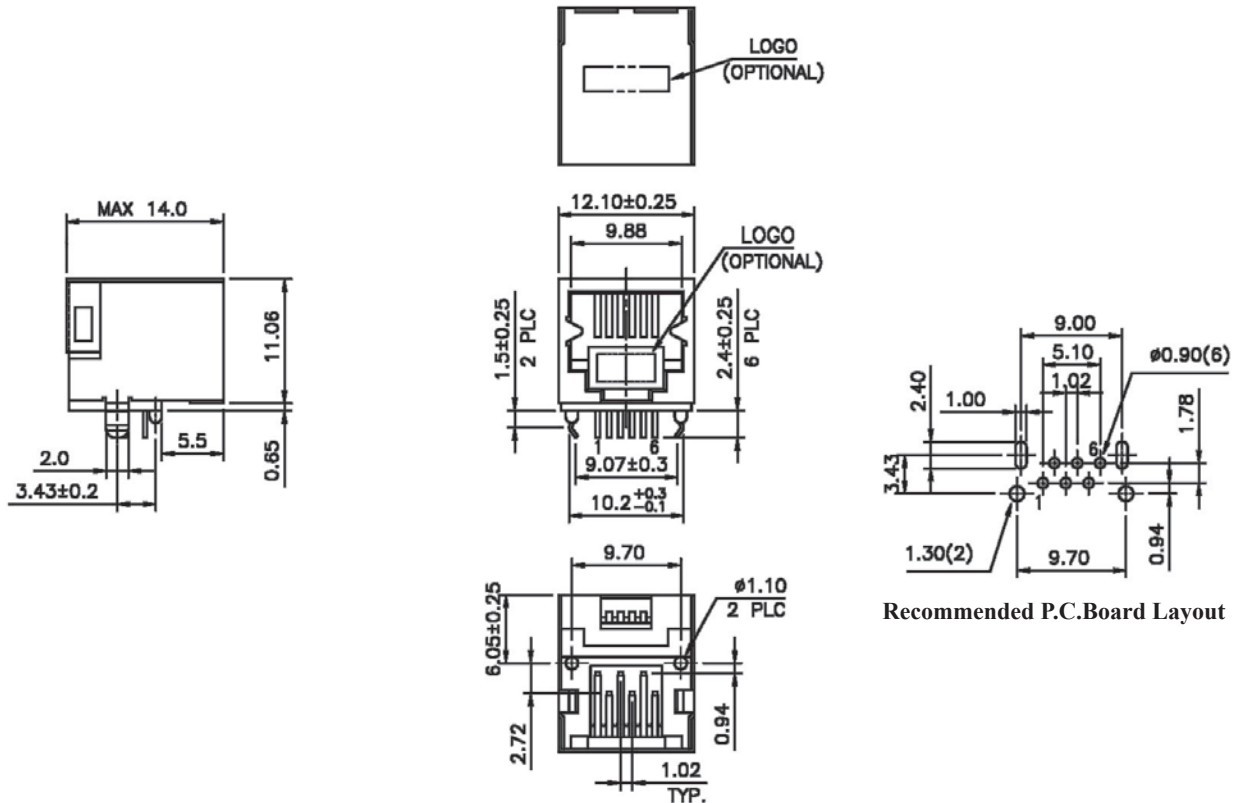
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J K U - x x x B
 I 2 3 4

1. MODULAR JACK TYPE:
"KU" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

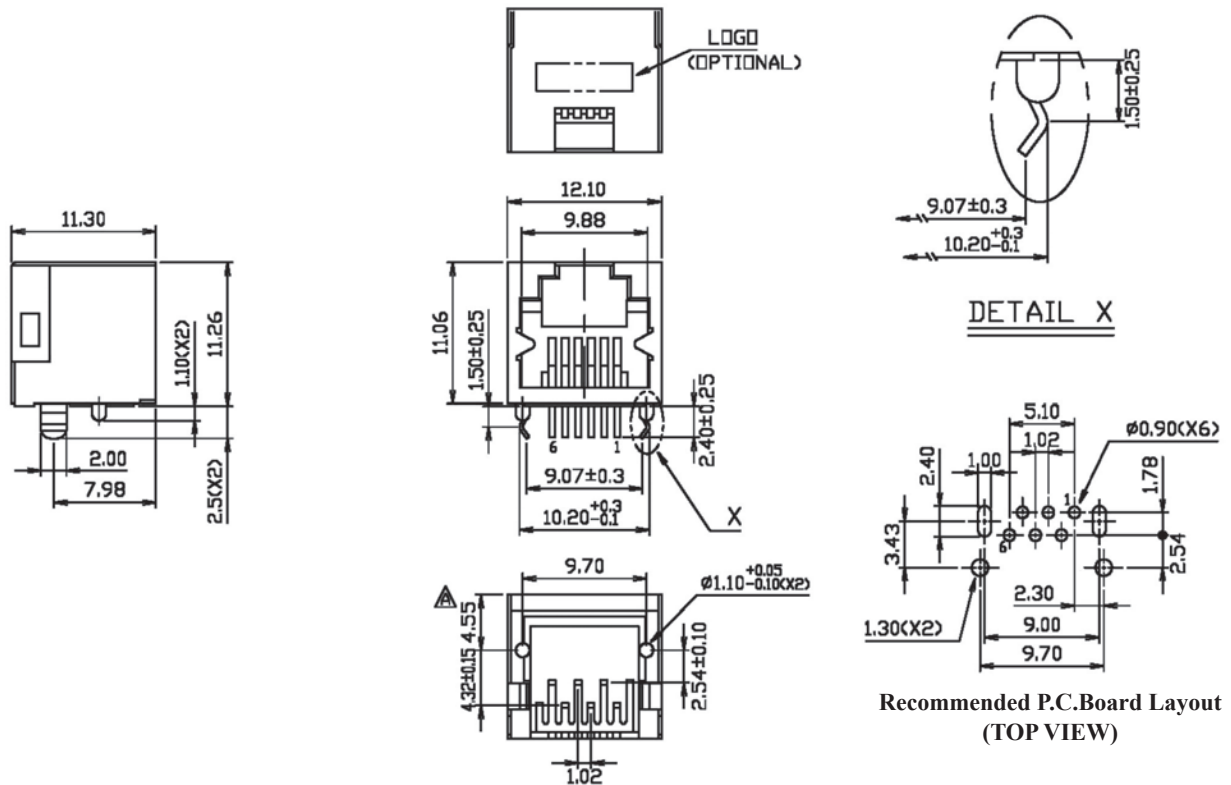
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J Y M - 6 6 x B
 1 2 3 4

1. MODULAR JACK TYPE:
"YM" RJ11 JACK
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

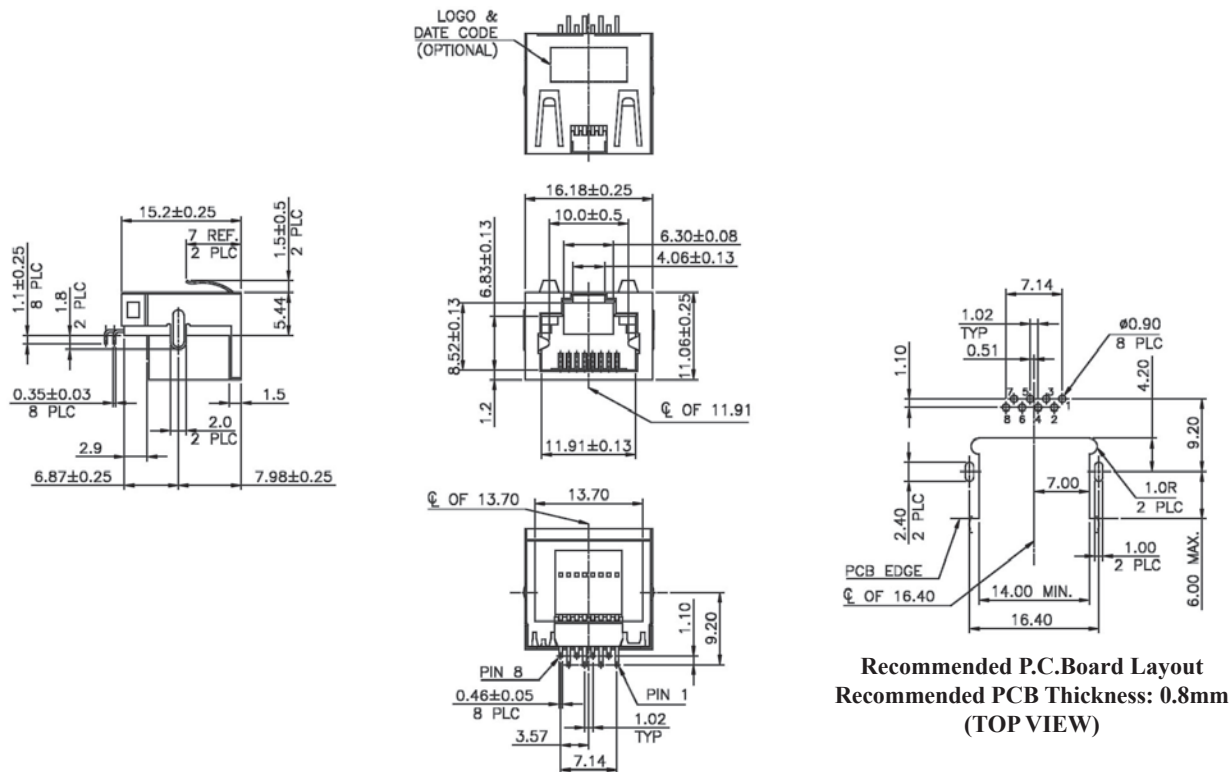
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

- Insulation Resistance:** 500MΩ Min.
- Contact Resistance:** 20mΩ Max.
- Rating Current:** 1.5A Max.
- Rating Voltage:** 120V AC.
- Dielectric Voltage:** 1000 Vrms 60 Sec. Min.
- Temperature Range:** -40°C / +85°C
- Durability:** 500 Mating cycles Min.

MATERIALS

- Housing:** PBT Glass Filled (UL 94V-0)
- Soldering Temperature:** 235°C
- Color:** Black
- Spring Wire:** Phosphor Bronze
Gold plating Over Nickel
- Shield:** Brass plating Nickel Alloy
- *RoHS & REACH compliant.**



Recommended P.C.Board Layout
Recommended PCB Thickness: 0.8mm
(TOP VIEW)

ORDERING INFORMATION:

P/N M J N F - 8 8 x B
1 2 3 4

1. MODULAR JACK TYPE:
"NF" EMBEDDED PCB JACK
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

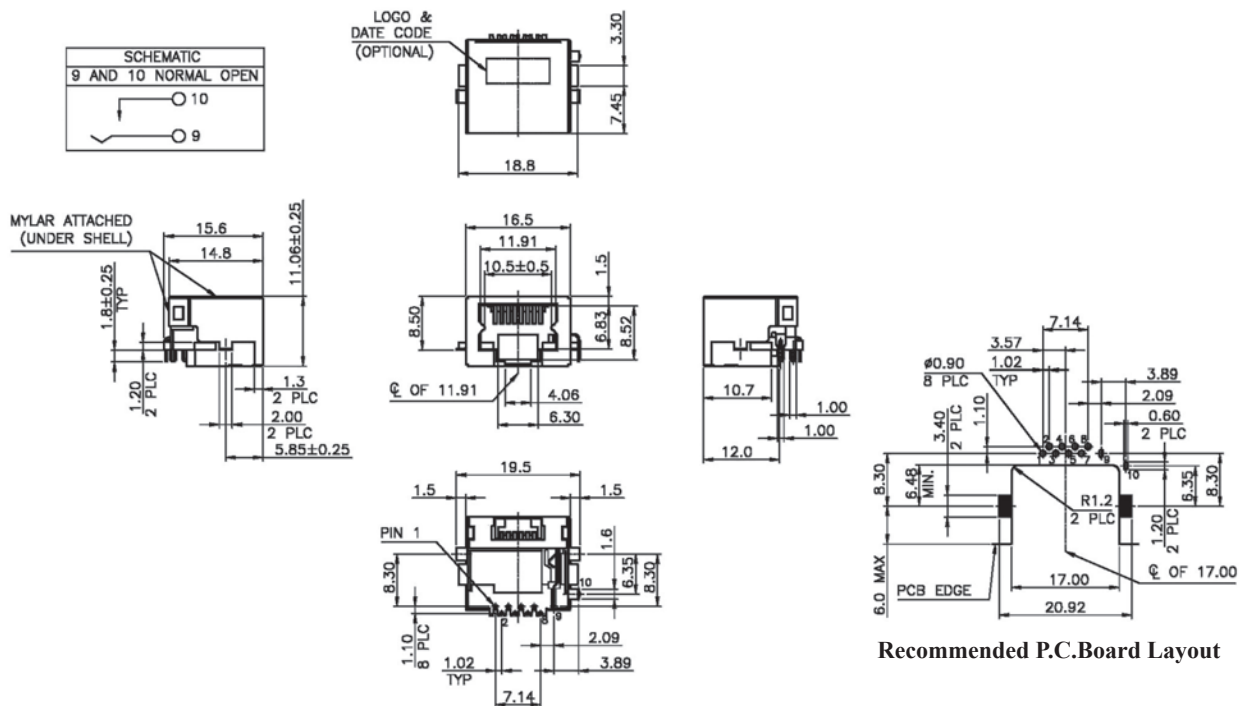
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH SWITCH PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Y S - 8 8 x B
 I 2 3 4

- MODULAR JACK TYPE:
"YS" EMBEDDED PCB JACK WITH SWITCH
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

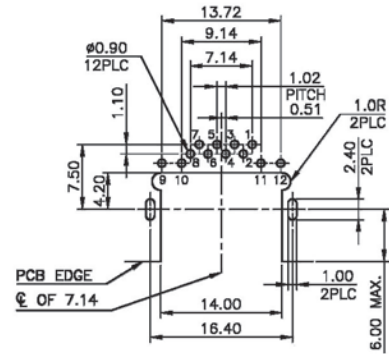
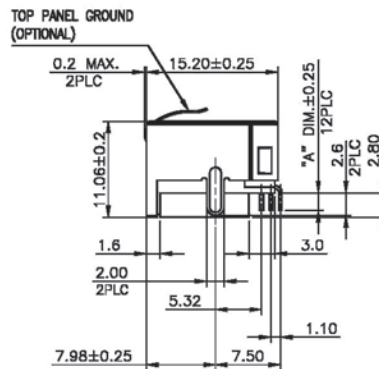
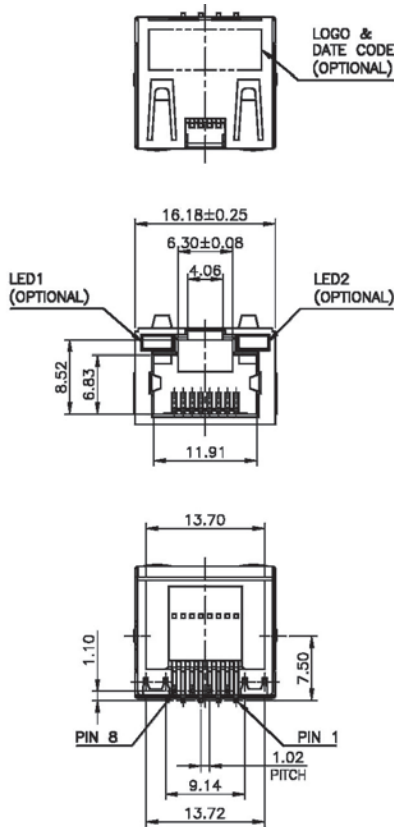
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

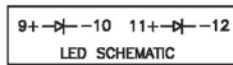
- Insulation Resistance: 500MΩ Min.
- Contact Resistance: 20mΩ Max.
- Rating Current: 1.5A Max.
- Rating Voltage: 120V AC.
- Dielectric Voltage: 1000 Vrms 60 Sec. Min.
- Temperature Range: -40°C / +85°C
- Durability: 500 Mating cycles Min.

MATERIALS

- Housing: PBT Glass Filled (UL 94V-0)
- Soldering Temperature: 235°C
- Color: Black
- Spring Wire: Phosphor Bronze
Gold plating Over Nickel
- Shield: Brass plating Nickel Alloy
- *RoHS & REACH compliant.



Recommended P.C. Board Layout



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{B}{4}$ $\frac{x}{5}$

- MODULAR JACK TYPE:
"NA" WITH TOP PANEL GROUP
"NB" WITHOUT PANEL GROUP
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

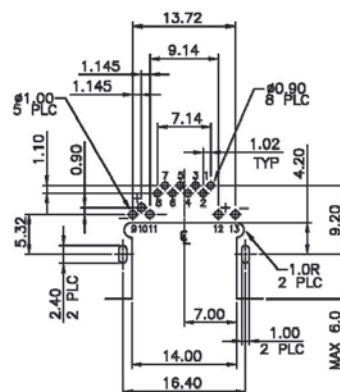
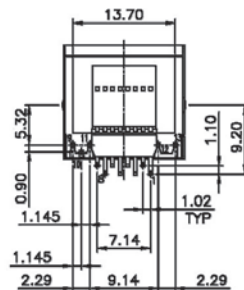
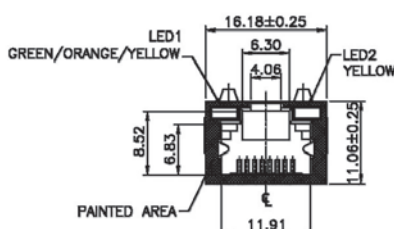
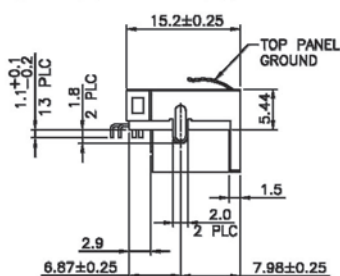
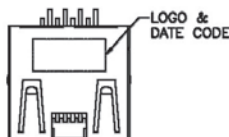
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**

LED SCHEMATIC						
NODE	COLOR	9(-)	10(+)	NODE	COLOR	
9(-)	10(+)	GREEN		12(+)	13(-)	YELLOW
11(-)	10(+)	ORANGE				
8(-)	11(-)	10(+)	YELLOW			

{ ANODE(+) → CATHODE(-) }



Recommended P.C. Board Layout
Recommended PCB Thickness: 0.8mm
(TOP VIEW)

P/N MJND-88xBTY

ORDERING INFORMATION:

P/N M J N D - 8 8 x B T Y

- MODULAR JACK TYPE:
"ND" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"TY" LED1 = GREEN/ORANGE/YELLOW
LED2 = YELLOW

NOTE: OTHER LED COLORS UPON REQUEST!

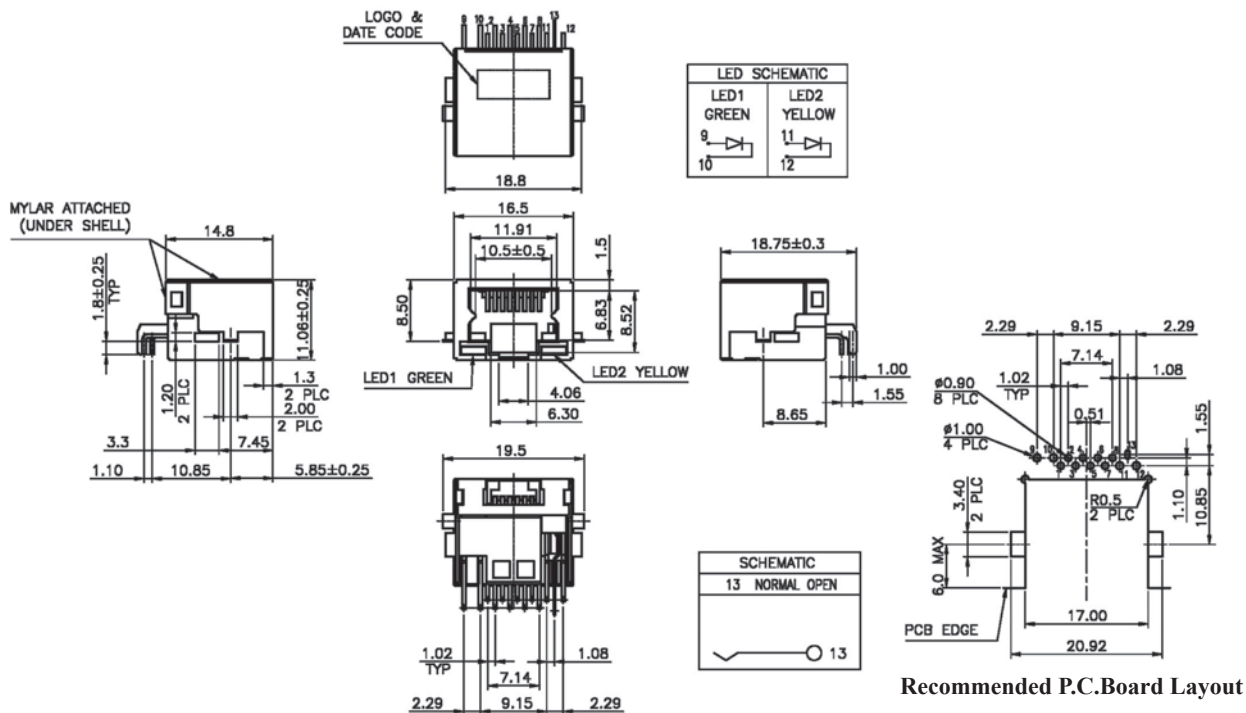
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH SWITCH & LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



P/N MJYT-88xBNY

ORDERING INFORMATION:

P/N M J Y T - 8 8 X B X X
1 2 3 4 5

- MODULAR JACK TYPE:
"YT" EMBEDDED PCB JACK WITH SWITCH
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED

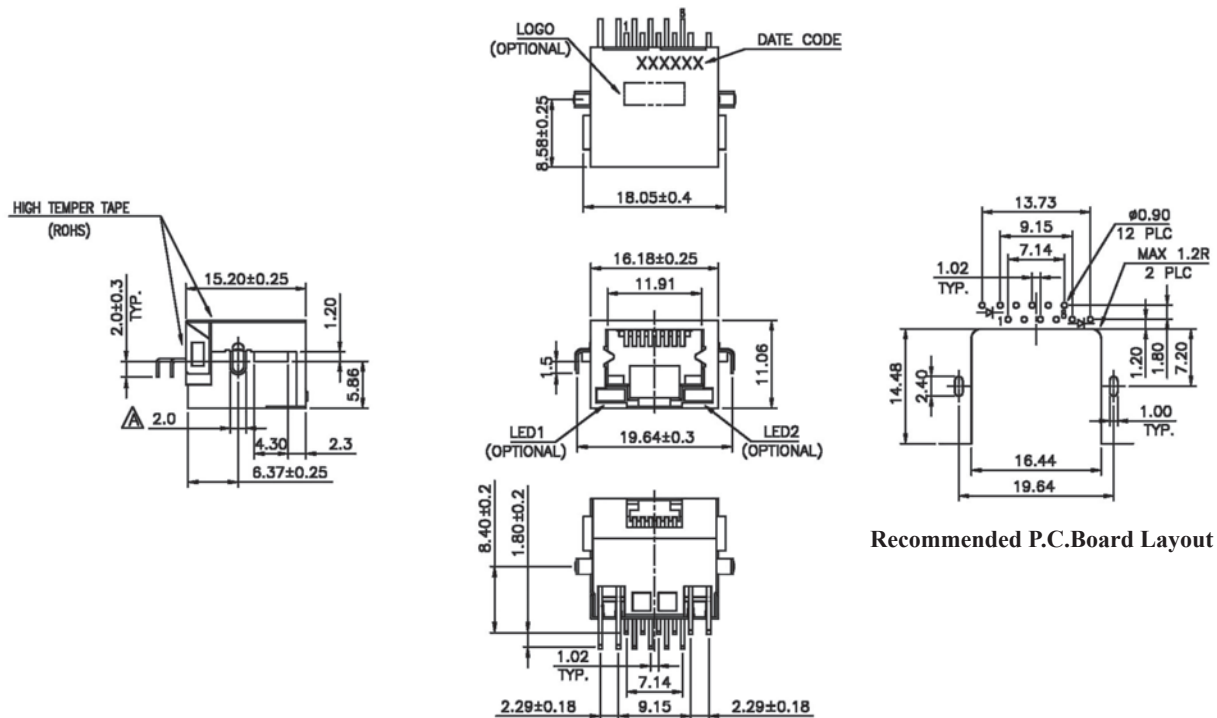
SIDE ENTRY EMBEDDED REVERSE MOUNT MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Y V - 8 8 x B X X
1 2 3 4 5

- MODULAR JACK TYPE:
"YV" EMBEDDED PCB JACK REVERSE TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED

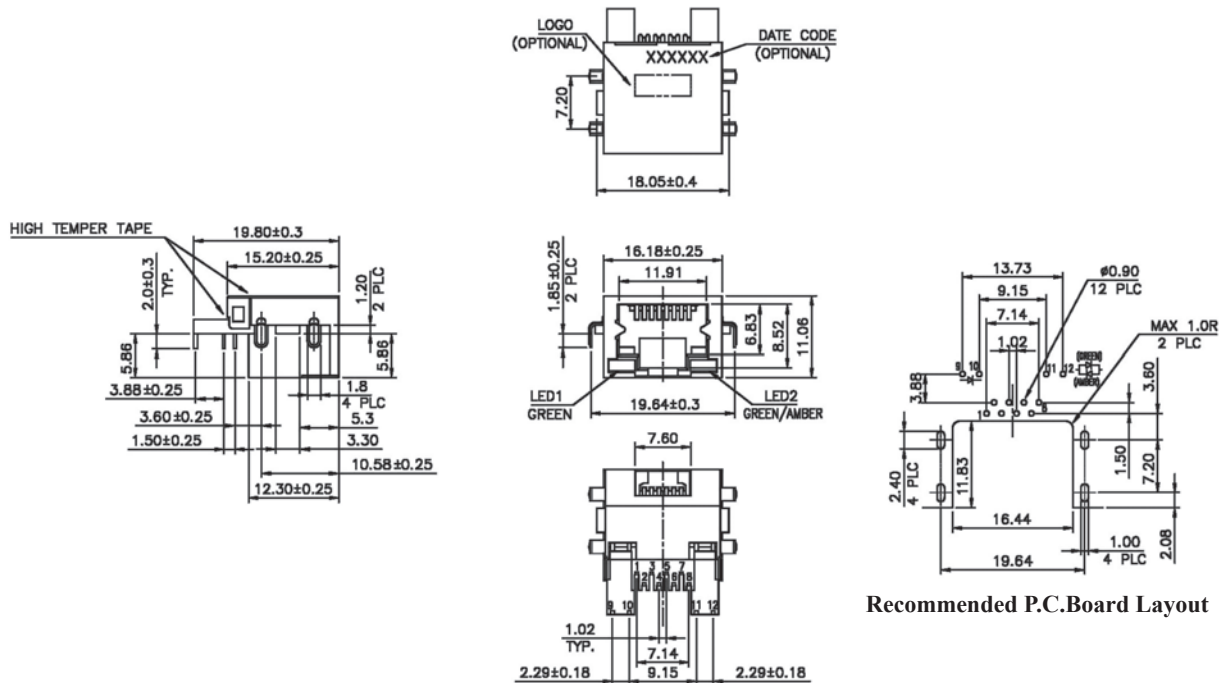
SIDE ENTRY EMBEDDED REVERSE MOUNT MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

P/N MJYW-88xBNB

ORDERING INFORMATION:

P/N M J Y W - 8 8 x B N B
 1 2 3 4 5

1. MODULAR JACK TYPE:
"YW" EMBEDDED PCB JACK REVERSE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. LED COLORS:
"NB" LED1 = GREEN &
 LED2 = GREEN/AMBER

SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

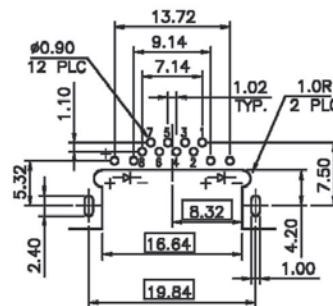
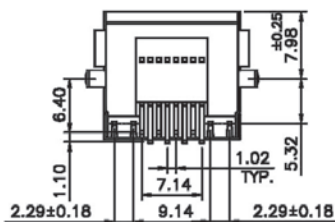
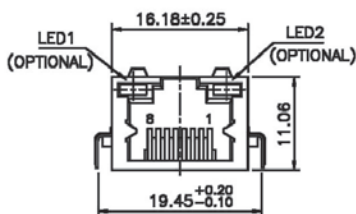
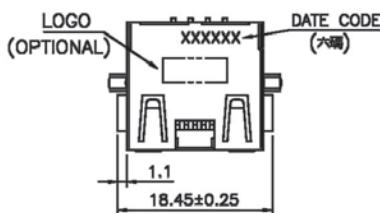
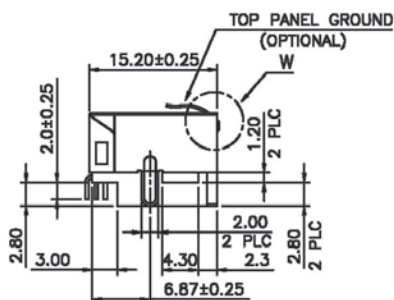
- Insulation Resistance: 500MΩ Min.
- Contact Resistance: 20mΩ Max.
- Rating Current: 1.5A Max.
- Rating Voltage: 120V AC.
- Dielectric Voltage: 1000 Vrms 60 Sec. Min.
- Temperature Range: -40°C / +85°C
- Durability: 500 Mating cycles Min.

MATERIALS

- Housing: PBT Glass Filled (UL 94V-0)
- Soldering Temperature: 235°C
- Color: Black
- Spring Wire: Phosphor Bronze
Gold plating Over Nickel
- Shield: Brass plating Nickel Alloy
- *RoHS & REACH compliant.



DETAIL W



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J Y X - 8 8 x B x X X
1 2 3 4 5

- MODULAR JACK TYPE:
"YX" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED

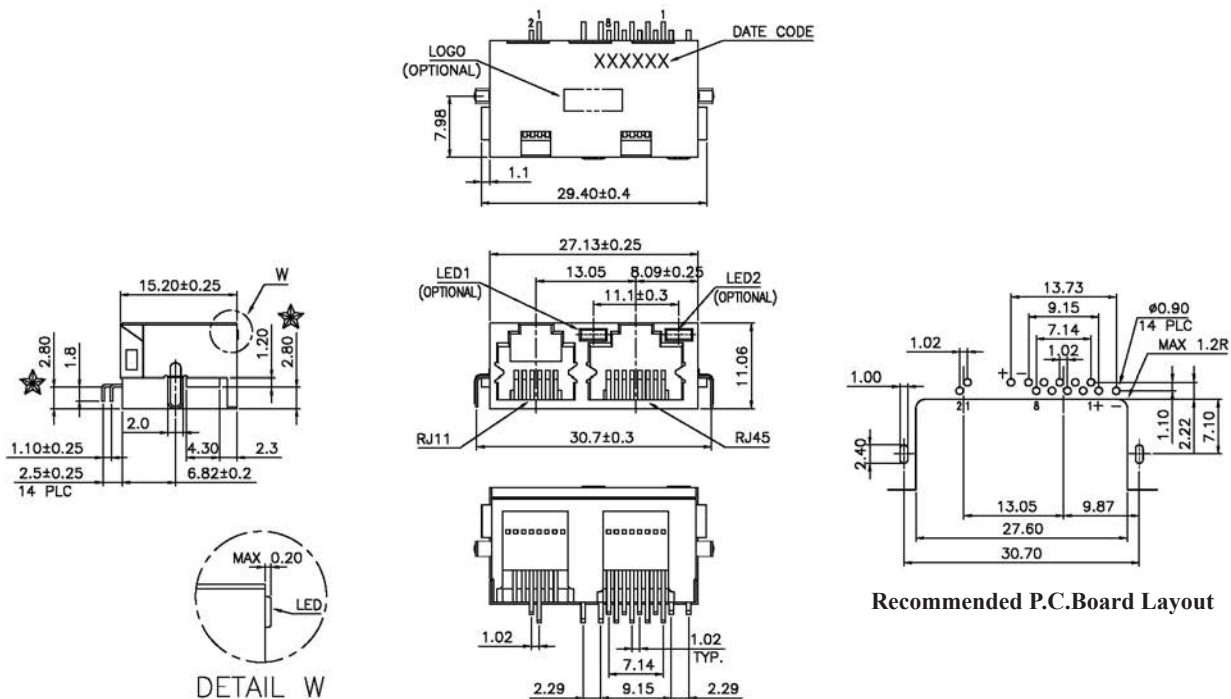
SIDE ENTRY 2-PORT EMBEDDED MODULAR PCB JACK 6P+8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{ZC}{1}$ - $\frac{28}{2}$ x $\frac{B}{3}$ $\frac{XX}{4}$ $\frac{02}{5}$ $\frac{02}{6}$

- MODULAR JACK TYPE:
"ZC" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED
- NO. OF PORTS:
02

SIDE ENTRY EMBEDDED MODULAR PCB JACK WITH LED 8P PROFILE=11.12MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

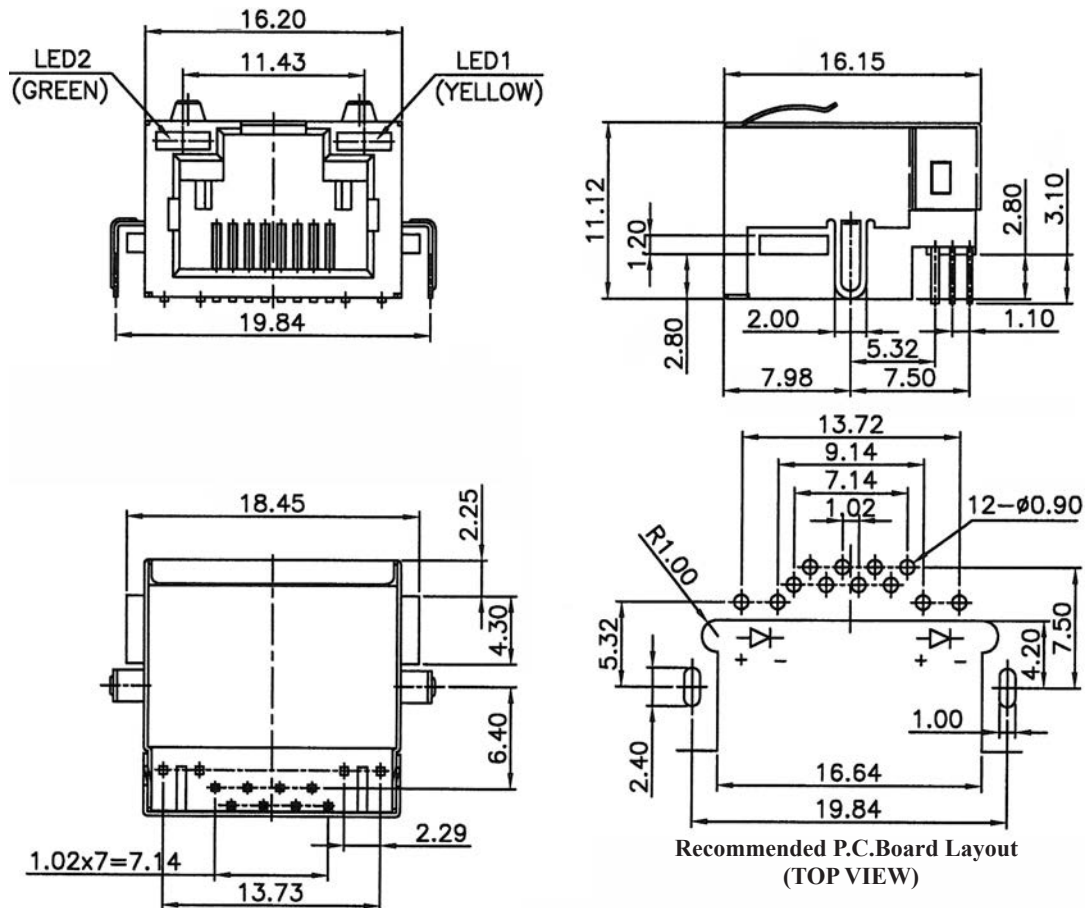
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J B 7 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. COLORS OF LED:

"NN" LED1: GREEN & LED2: GREEN

"NY" LED1: GREEN & LED2: YELLOW

"YN" LED1: YELLOW & LED2: GREEN

"YY" LED1: YELLOW & LED2: YELLOW

"XX" W/O LED

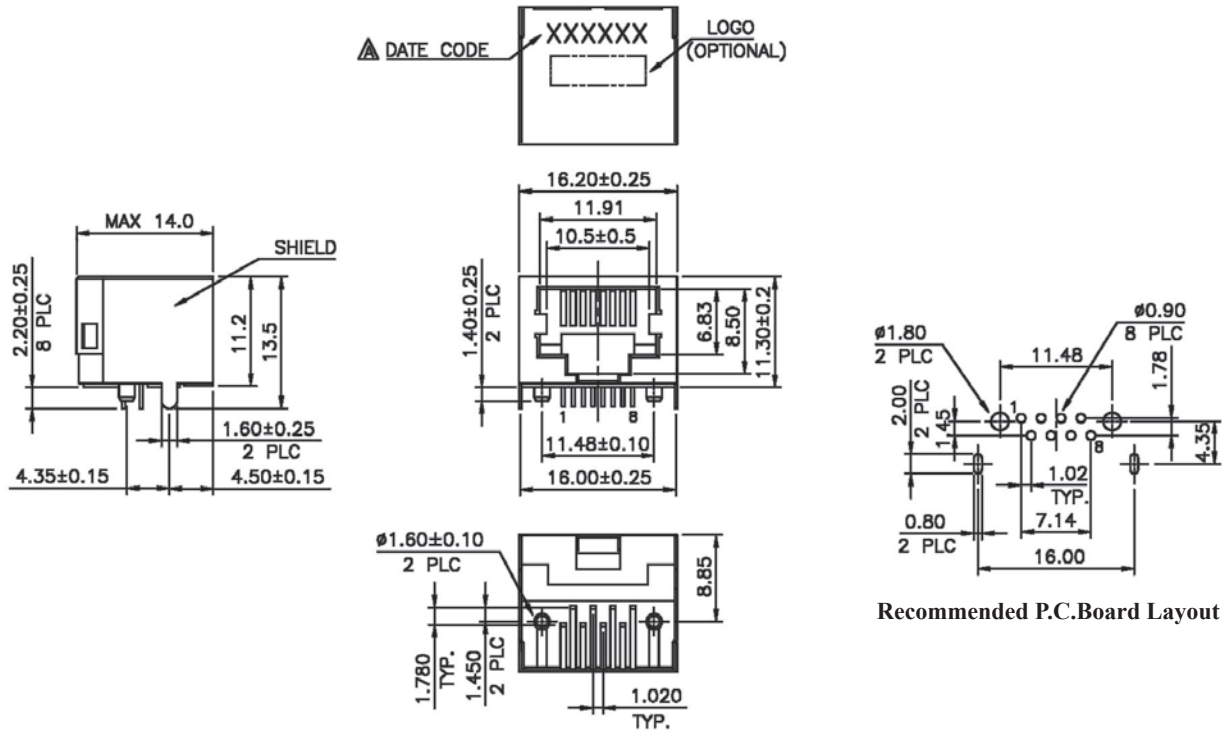
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J N P - 88 x B
 I 2 3 4

1. MODULAR JACK TYPE:
"NP" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

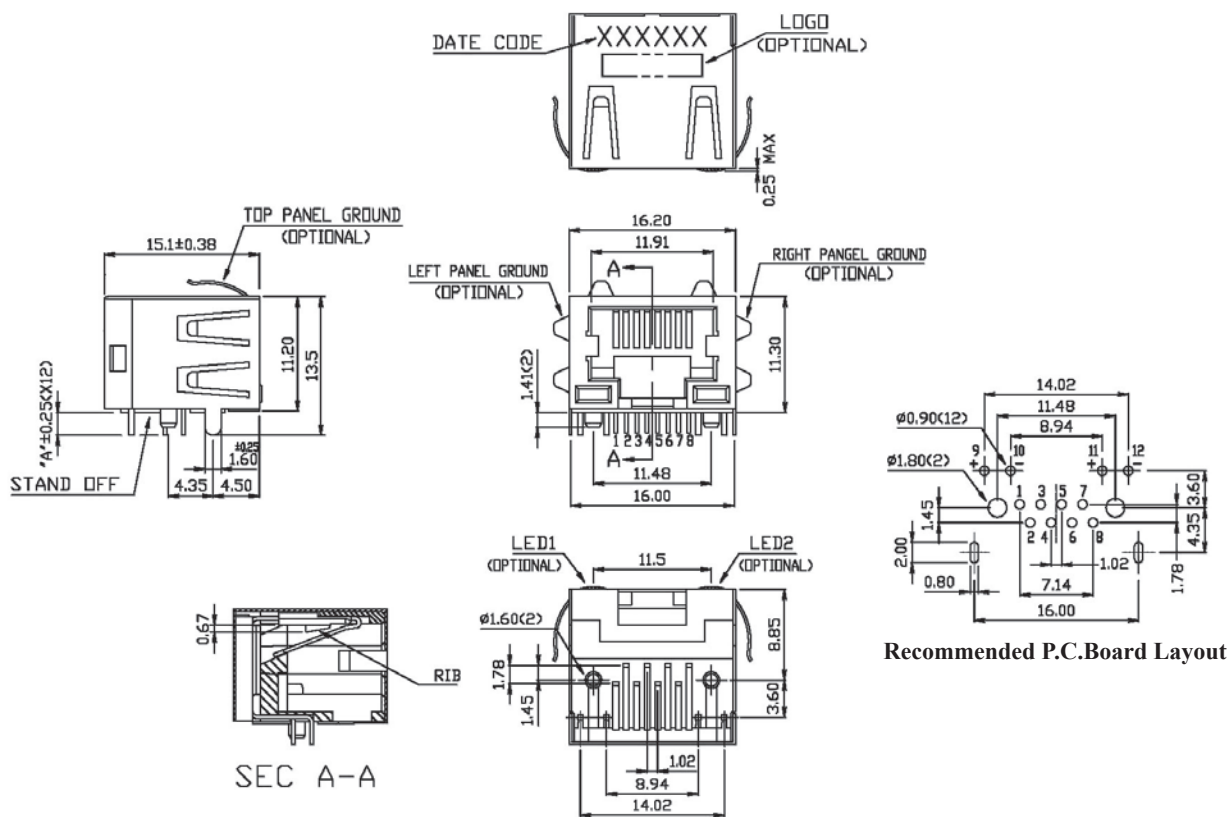
SIDE ENTRY MODULAR PCB JACK 8P WITH LED PROFILE=11.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{8}{2}$ $\frac{8}{3}$ $\frac{x}{4}$ $\frac{B}{5}$ $\frac{x}{5}$

- MODULAR JACK TYPE:
 "KT" WITH TOP/RIGHT/LEFT SIDE TABS
 "KS" WITH RIGHT/LEFT TABS
 "KR" WITH TOP SIDE TABS
 "KQ" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- LED COLORS:
 "NN" LED1/2 = GREEN/GREEN
 "NY" LED1/2 = GREEN/YELLOW
 "YN" LED1/2 = YELLOW/GREEN
 "YY" LED1/2 = YELLOW/YELLOW
 "XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

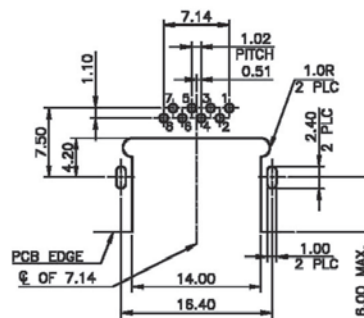
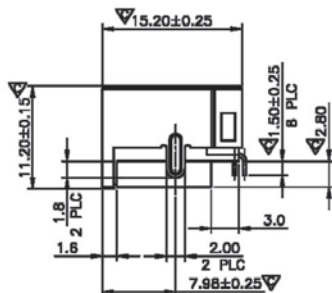
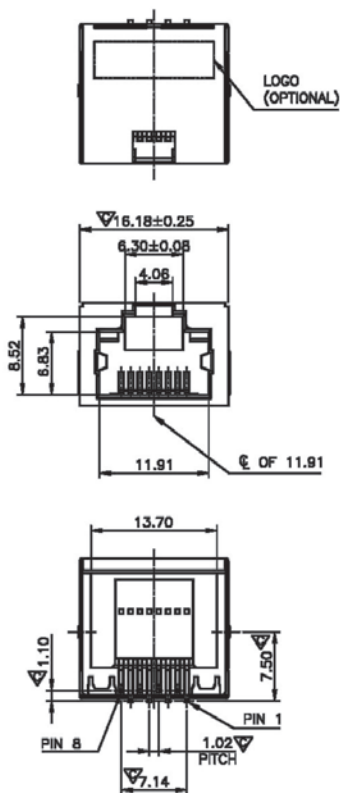
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P PROFILE=11.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C.Board Layout
 Recommended PCB Thickness: 1.2mm
 (TOP VIEW)

ORDERING INFORMATION:

P/N M J Z G - 8 8 x B
 1 2 3 4

- MODULAR JACK TYPE:
"ZG" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

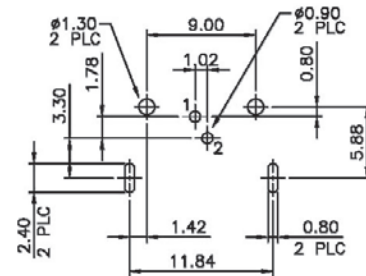
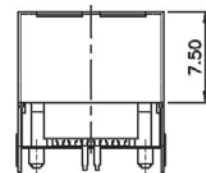
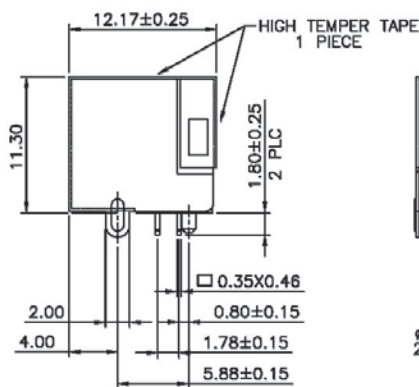
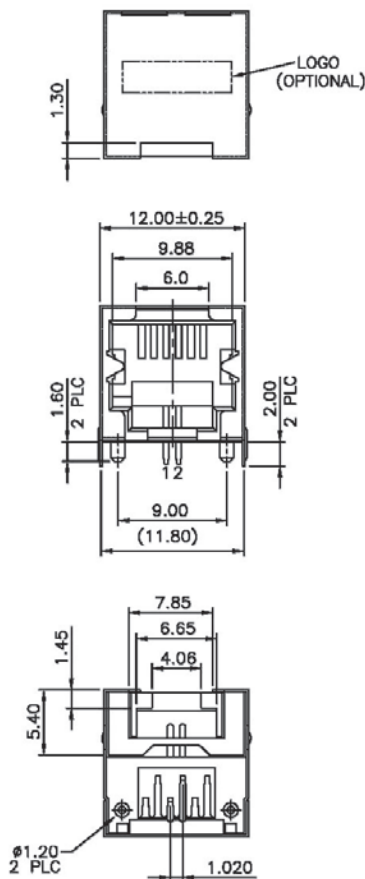
SIDE ENTRY MODULAR PCB JACK 6P2C PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout (TOP VIEW)

ORDERING INFORMATION:

P/N M J $\frac{V}{I}$ $\frac{Z}{2}$ - 62 x $\frac{B}{3}$ $\frac{A}{4}$

- MODULAR JACK TYPE:
"VZ" 6P2C JACK
- NO. OF POSITIONS & CONTACTS:
"62" 6P2C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

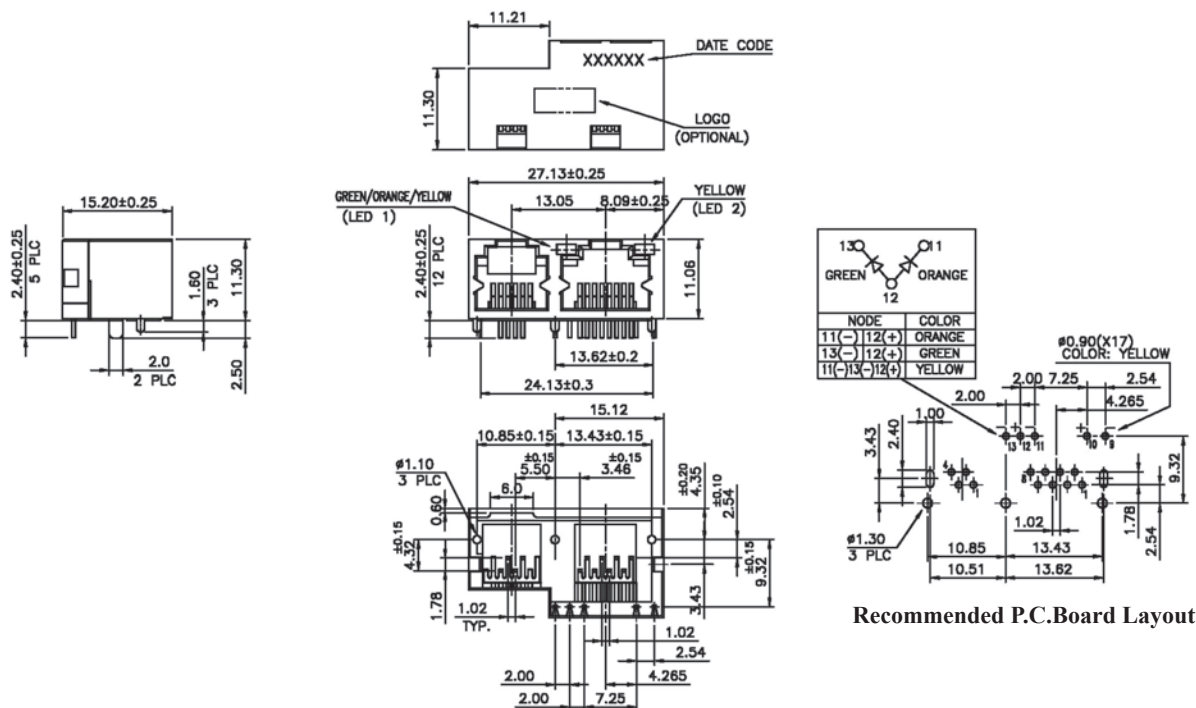
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 4P+8P WITH LED PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°c / +85°c
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°c
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



P/N MJKH-48xBTY02

ORDERING INFORMATION:

P/N M J K H - 4 8 x B T Y 0 2
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"KH" RJ11/RJ45 SIDE BY SIDE JACK
- NO. OF POSITIONS & CONTACTS:
"48" 4P4C & 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- LED COLORS:
"TY" LED1 = GREEN/ORANGE/YELLOW &
LED2 = YELLOW
- NO. OF PORTS:
02

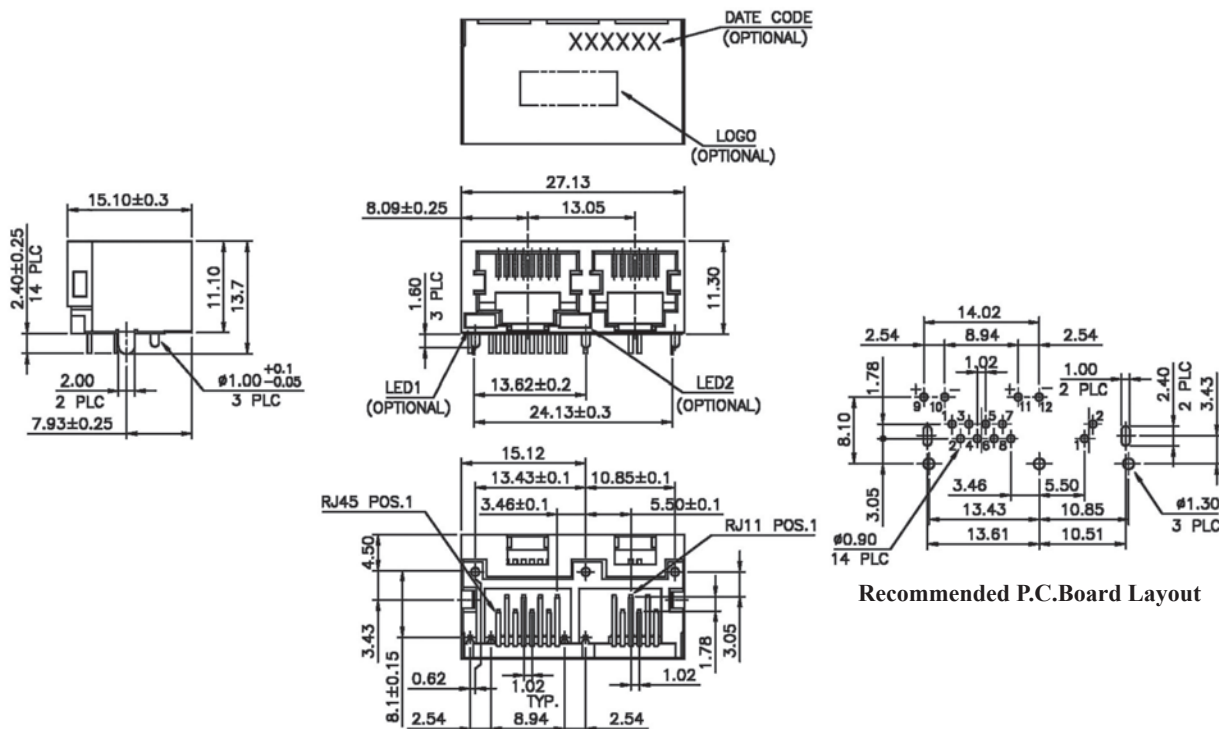
SIDE ENTRY 2-PORT MODULAR PCB JACK 8P+2P WITH LED PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J N Q - 2 8 x B x x 0 2
1 2 3 4 5 6

- MODULAR JACK TYPE:
"NQ" RJ45+RJ11 SIDE BY SIDE JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C & 8P8C JACK
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPON REQUEST!

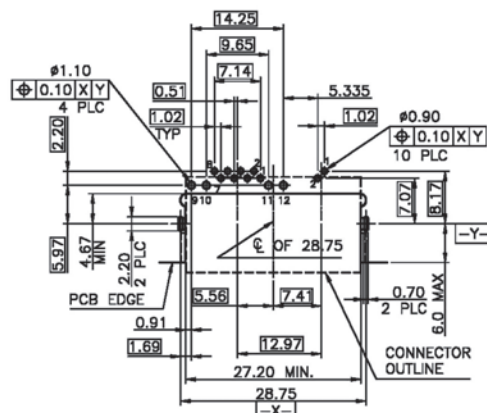
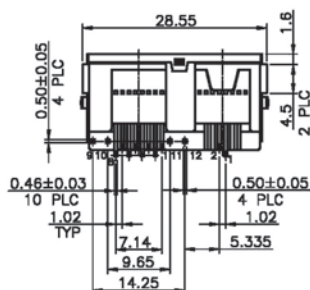
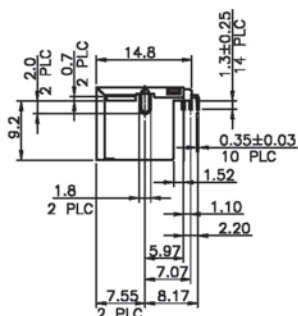
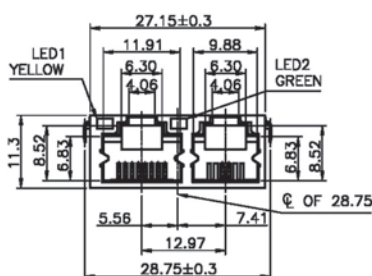
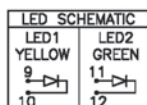
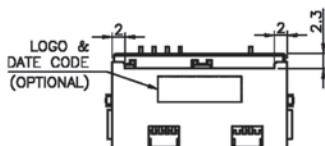
SIDE ENTRY 2-PORT EMBEDDED MODULAR PCB JACK 6P+8P WITH LED PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

P/N MJYP-28xBYN02

ORDERING INFORMATION:

P/N M J Y P - 2 8 x B x x 0 2
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"YP" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED
- NO. OF PORTS:
02

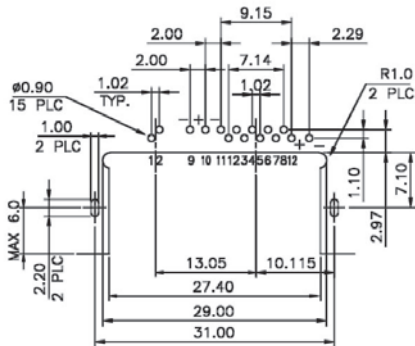
SIDE ENTRY 2-PORT EMBEDDED MODULAR PCB JACK 2P+8P WITH LED PROFILE=11.40MM (FULLY SHIELDED)

SPECIFICATIONS

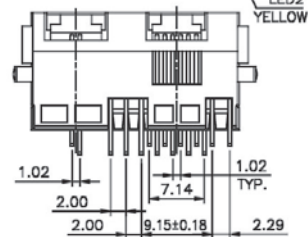
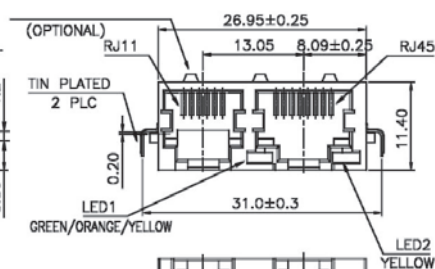
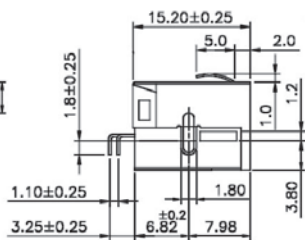
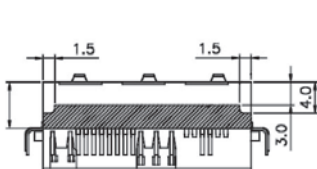
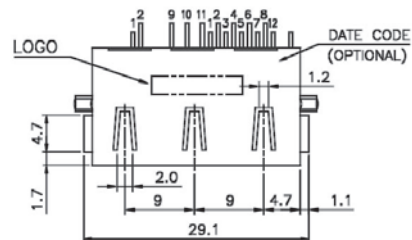
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout



P/N MJZB-28xBTY02

ORDERING INFORMATION:

P/N MJZB - 28 x BTY02
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"ZB" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- LED COLORS:
"TY" LED1 = GREEN/ORANGE/YELLOW &
LED2 = YELLOW
- NO. OF PORTS:
02

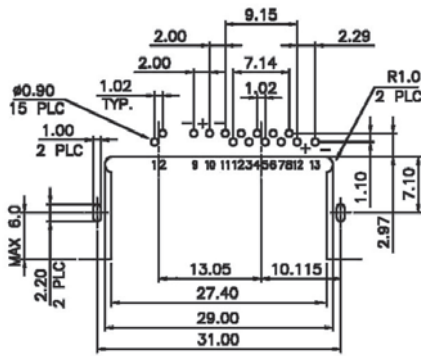
SIDE ENTRY 2-PORT EMBEDDED REVERSE MOUNT MODULAR PCB JACK 6P+8P WITH LED PROFILE=11.40MM (FULLY SHIELDED)

SPECIFICATIONS

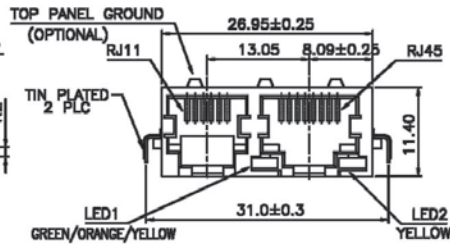
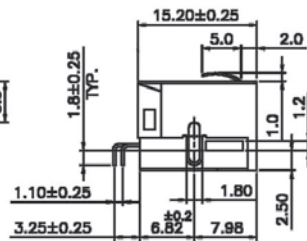
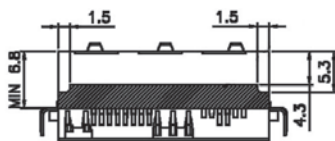
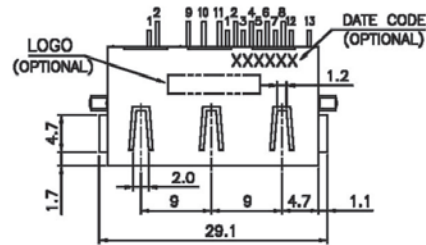
Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

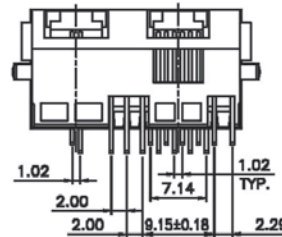
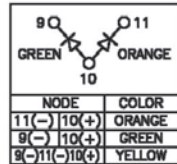
Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C. Board Layout



P/N MJZF-28xBTY02



ORDERING INFORMATION:

P/N MJZF-28xBTY02
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"ZF" EMBEDDED PCB JACK REVERSE TYPE
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"TY" LED1 = GREEN/ORANGE/YELLOW &
LED2 = YELLOW
- NO. OF PORTS:
02

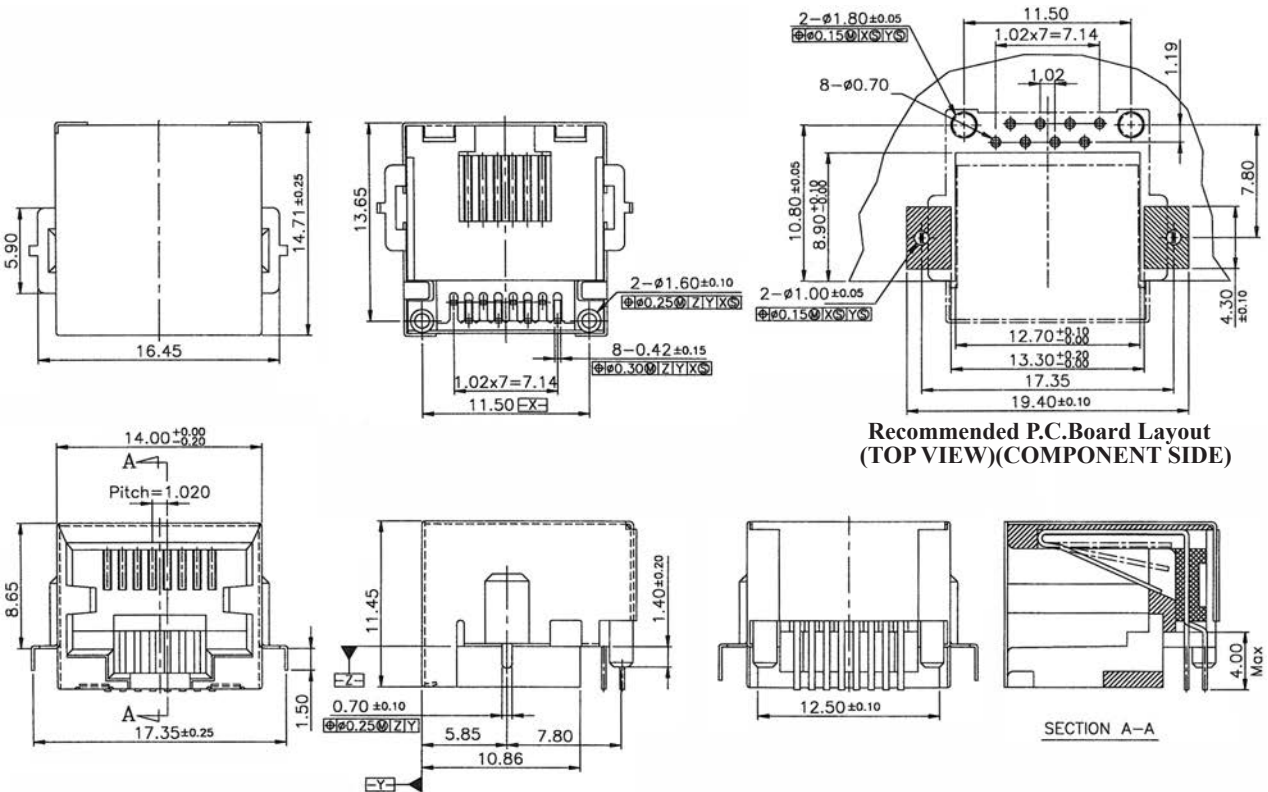
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ8S - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

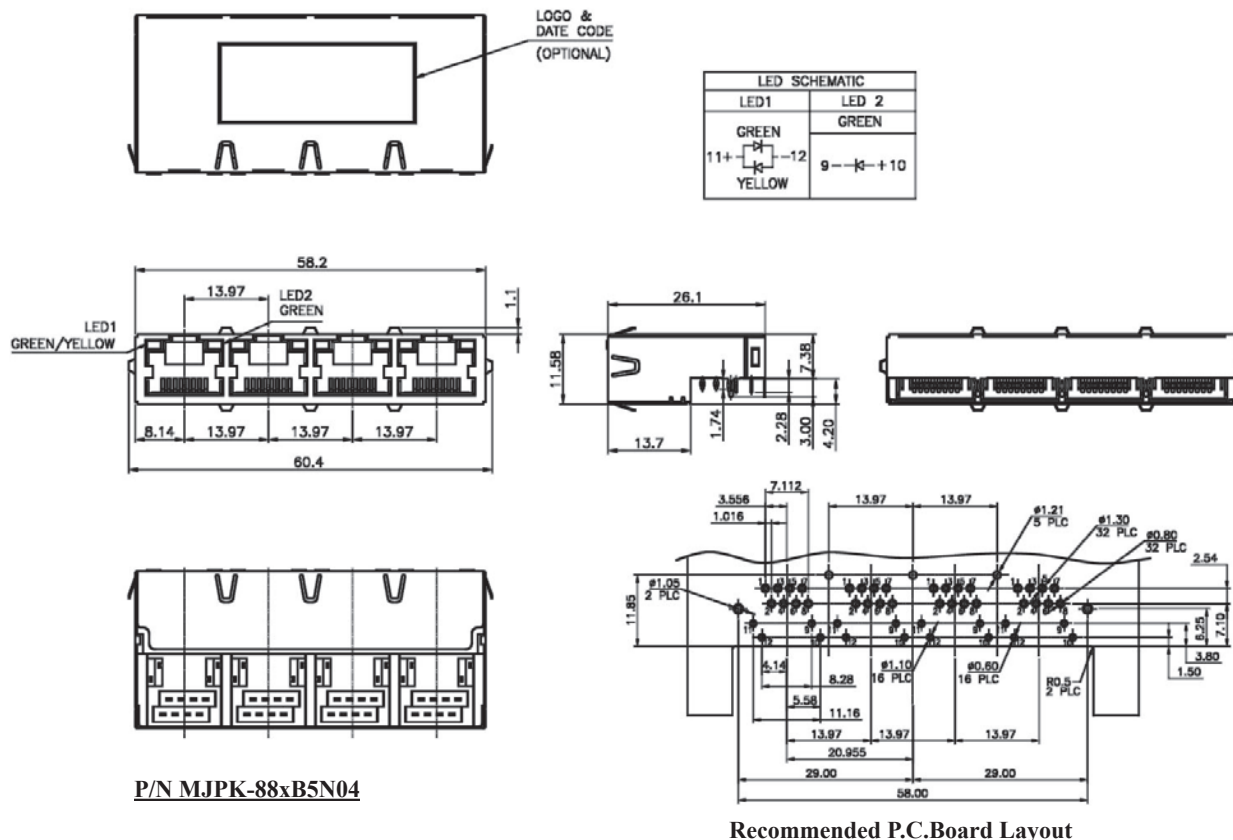
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PRESS FIT TYPE WITH LED PROFILE=11.58MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J P K - $\frac{88}{1} \times \frac{B5}{234} \frac{M04}{56}$

- MODULAR JACK TYPE:
"PK" PRESS FIT TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"5M" LED1 = GREEN/YELLOW &
LED2 = REVERSE GREEN
- NO. OF PORTS:
04

NOTE: OTHER LED COLORS UPON REQUEST!

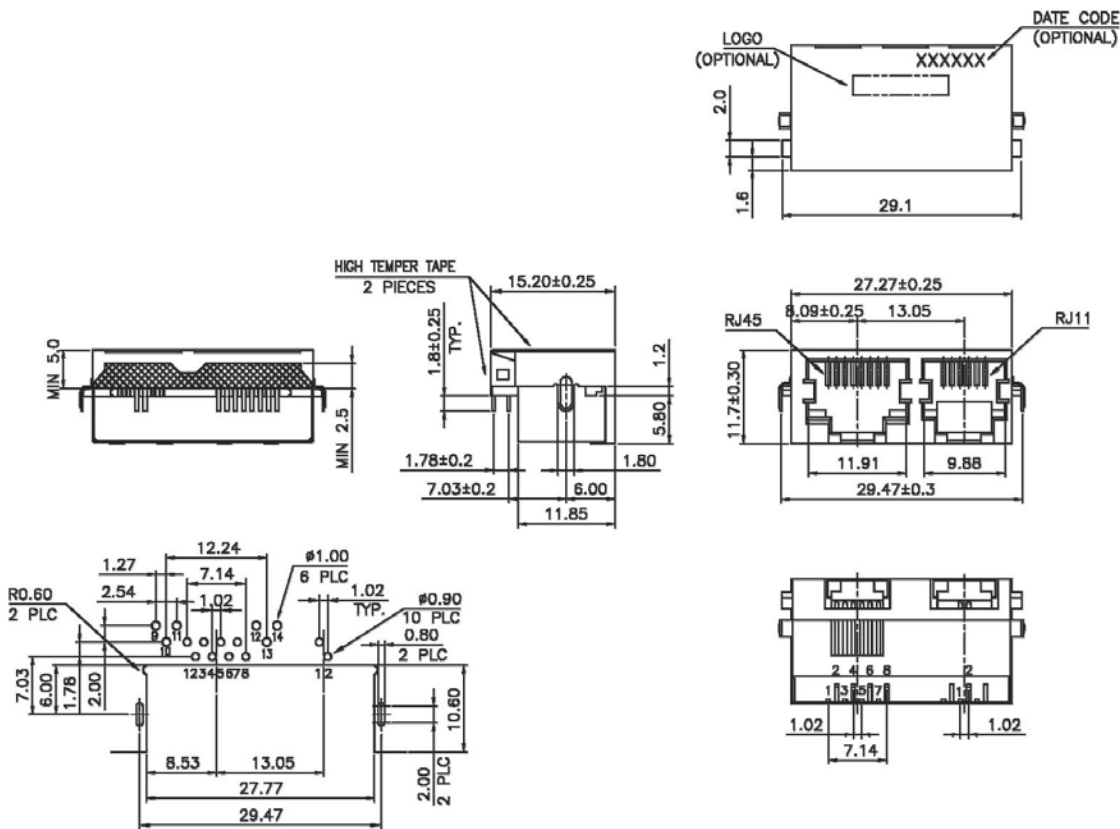
SIDE ENTRY 2-PORT EMBEDDED REVERSE TYPE MODULAR PCB JACK 6P+8P PROFILE=11.70MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Z D - 2 8 x B 0 2
 1 2 3 4 5

- MODULAR JACK TYPE:
"ZD" EMBEDDED PCB JACK REVERSE TYPE
- NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
02

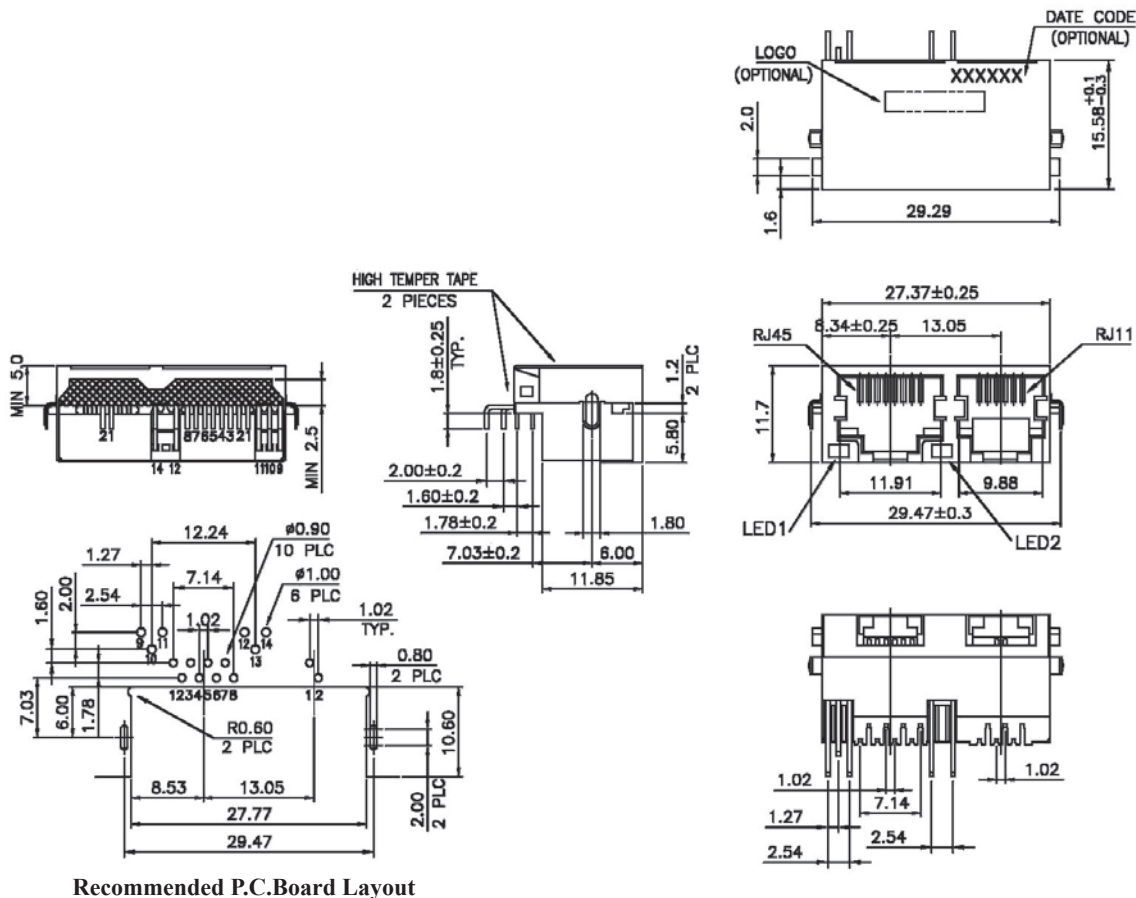
SIDE ENTRY 2-PORT EMBEDDED REVERSE TYPE MODULAR PCB JACK 6P+8P WITH LED PROFILE=11.70MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Z E - 2 8 x B x x 0 2
 I 2 3 4 5 6

1. MODULAR JACK TYPE:
"ZE" EMBEDDED PCB JACK REVERSE TYPE
2. NO. OF POSITIONS & CONTACTS:
"28" 6P2C+8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED
6. NO. OF PORTS:
02

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

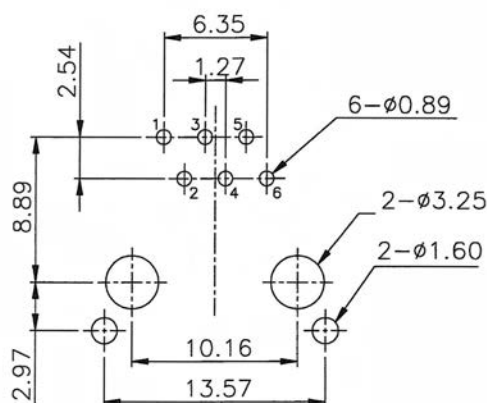
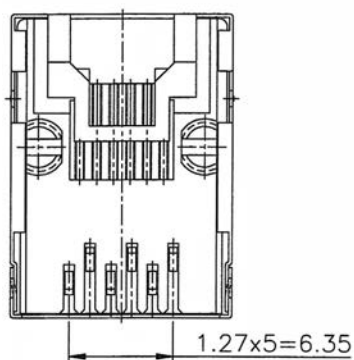
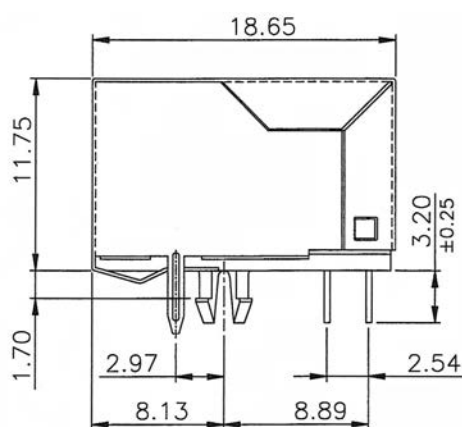
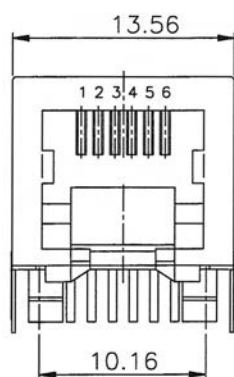
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 1 8 - $\frac{x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"64" 6P4C

"66" 6P6C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 2.97MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

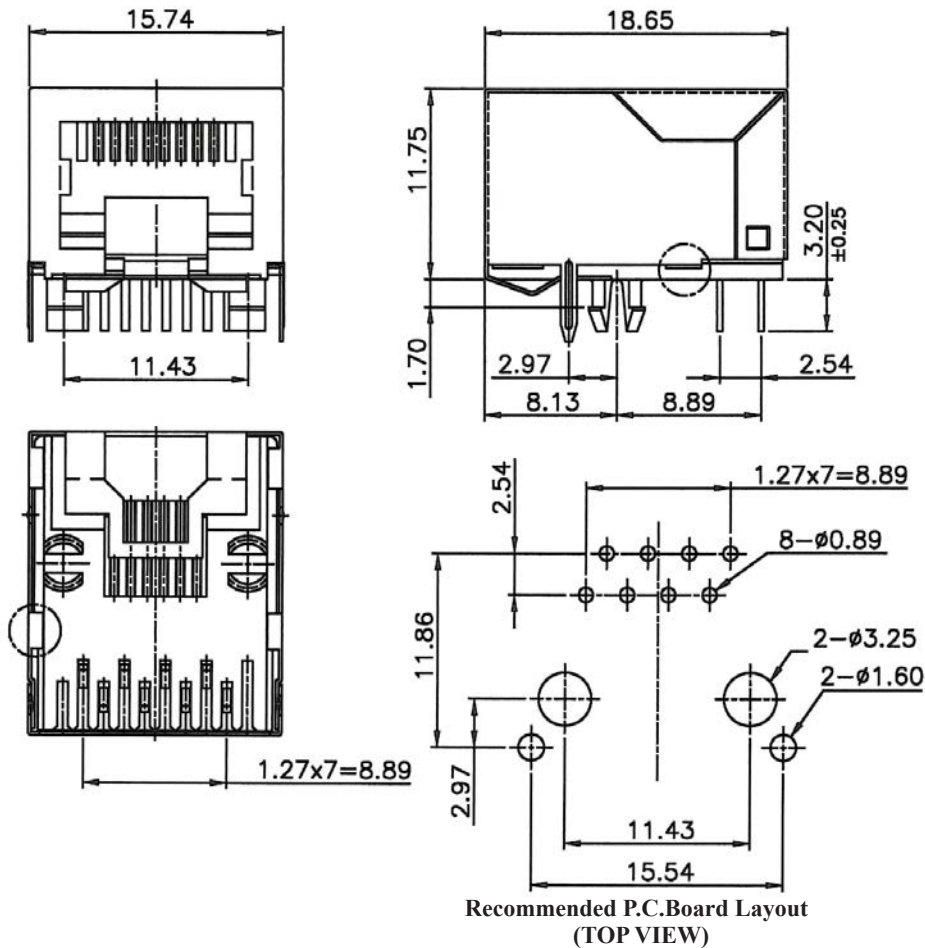
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 8 - $\frac{x}{1} \frac{x}{2} \frac{B}{3} \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

NOTE: 2.97MM SPACING BEFORE PEG

DRAWING REVISED

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

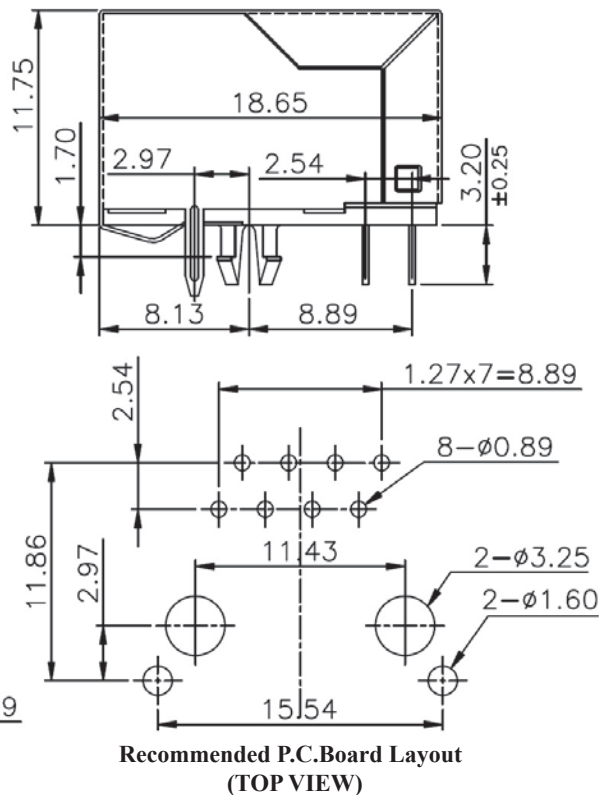
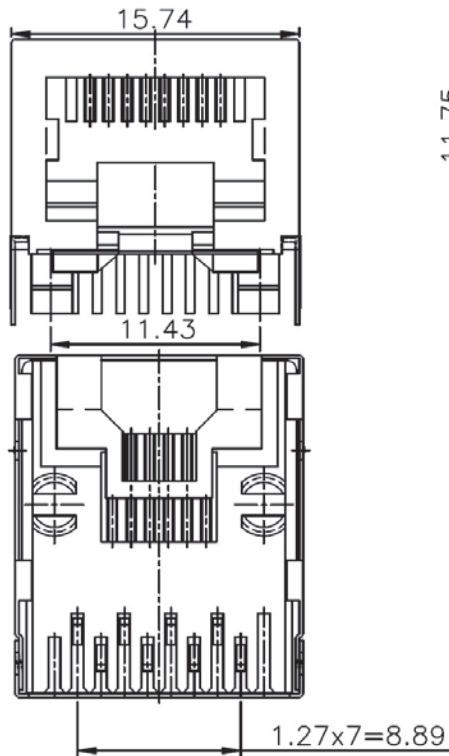
Plastic Housing: Engineering Thermoplastic
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ 18J - 88 x B

1. MODULAR JACK TYPE:
"18J" F2.97 TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: IT CAN BE USED FOR REPLACING P/N MJ18-88xB.

NOTE 2: 2.97MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

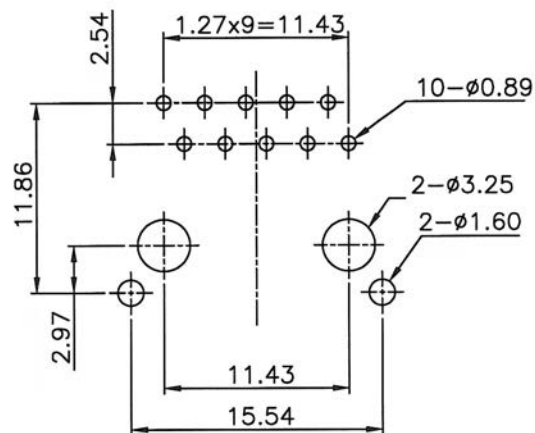
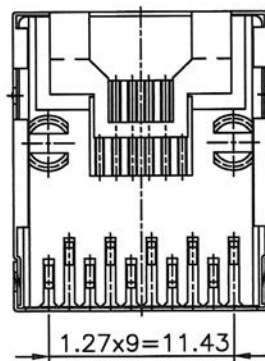
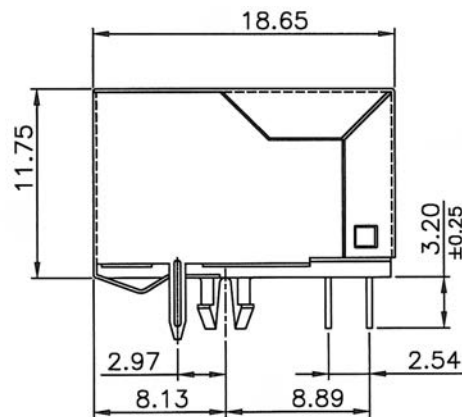
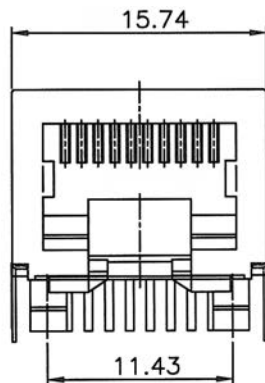
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 1 8 - $\frac{x}{1} \frac{x}{2} x B$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 2.97MM SPACING BEFORE PEG

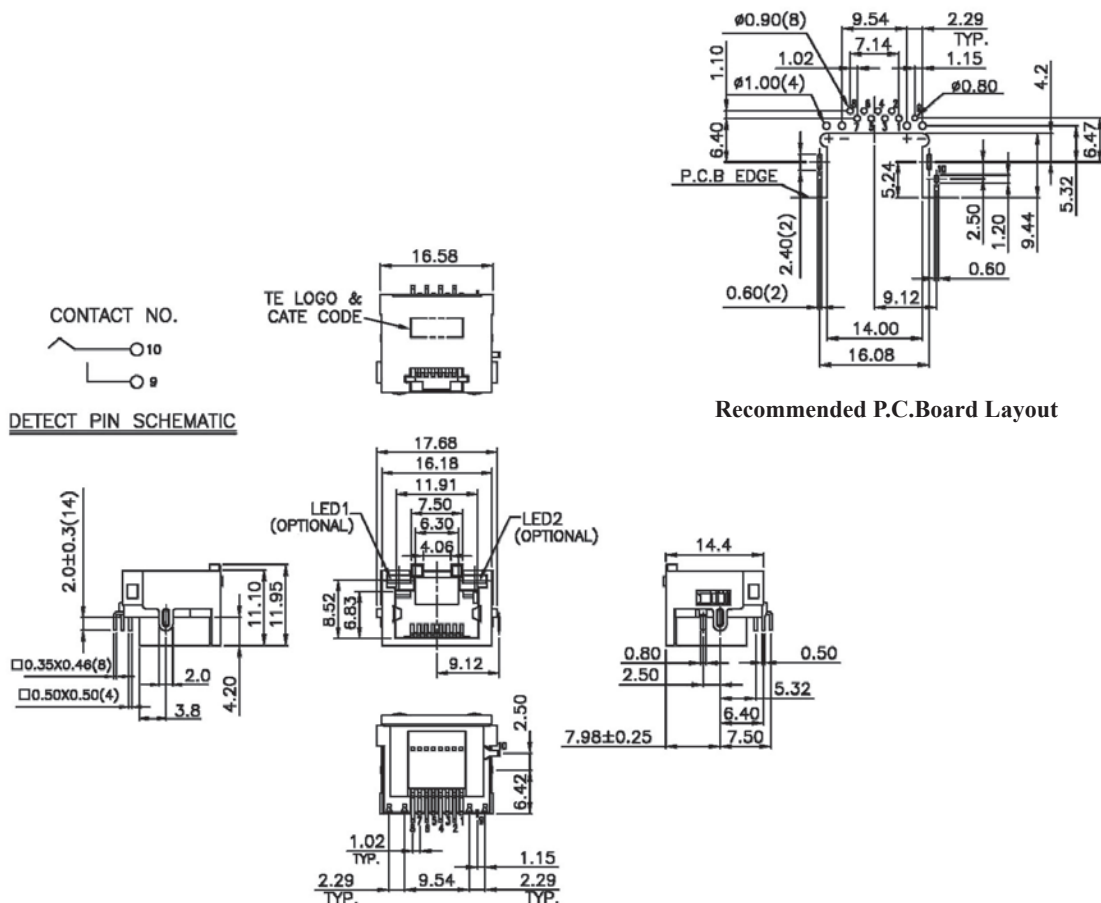
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P WITH LED PROFILE=11.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J YY - 88 x B x X
1 2 3 4 5

- MODULAR JACK TYPE:
"YY" EMBEDDED PCB JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- LED COLORS:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"XX" WITHOUT LED

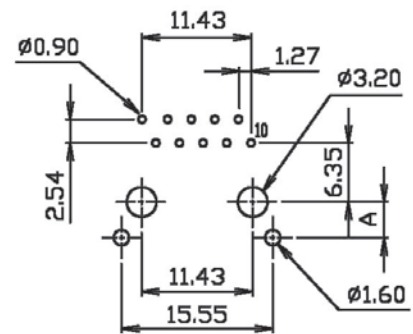
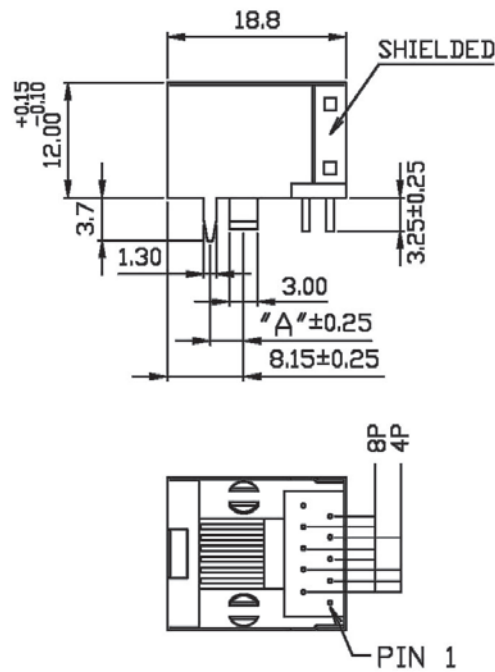
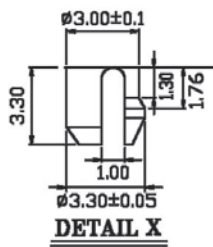
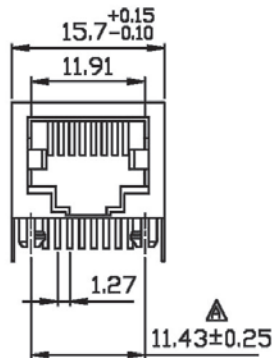
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{HF}{I}$ - $\frac{X}{2}$ $\frac{X}{3}$ $\frac{B}{4}$

1. MODULAR JACK TYPE:
"HF" DIM.A = 3.05MM BEFORE PEG
2. NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

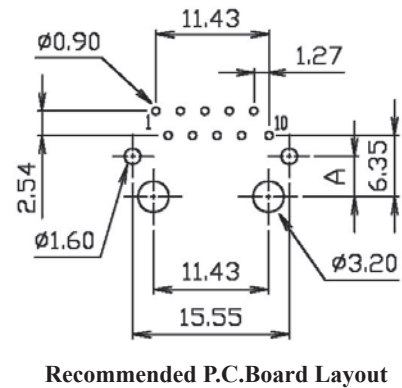
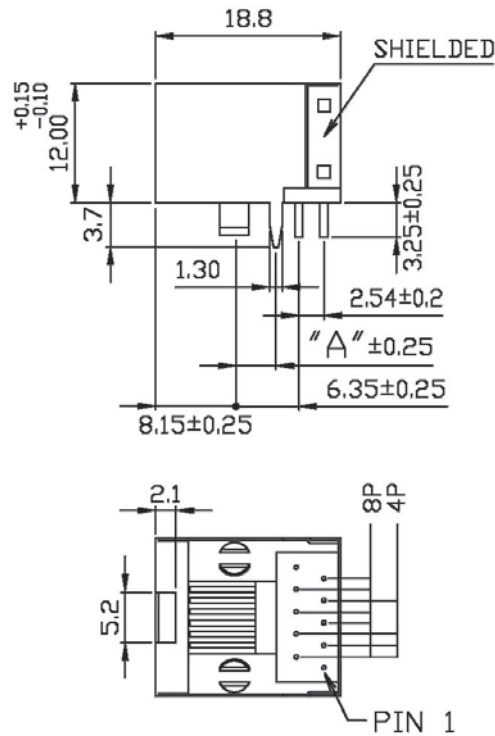
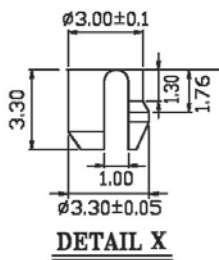
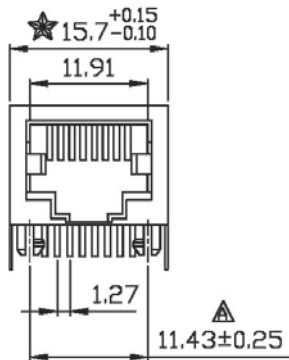
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{HP}{I}$ - $\frac{XX}{2}$ $\frac{XB}{34}$

- MODULAR JACK TYPE:
"HP" DIM.A = 3.05MM BEHIND PEG
- NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

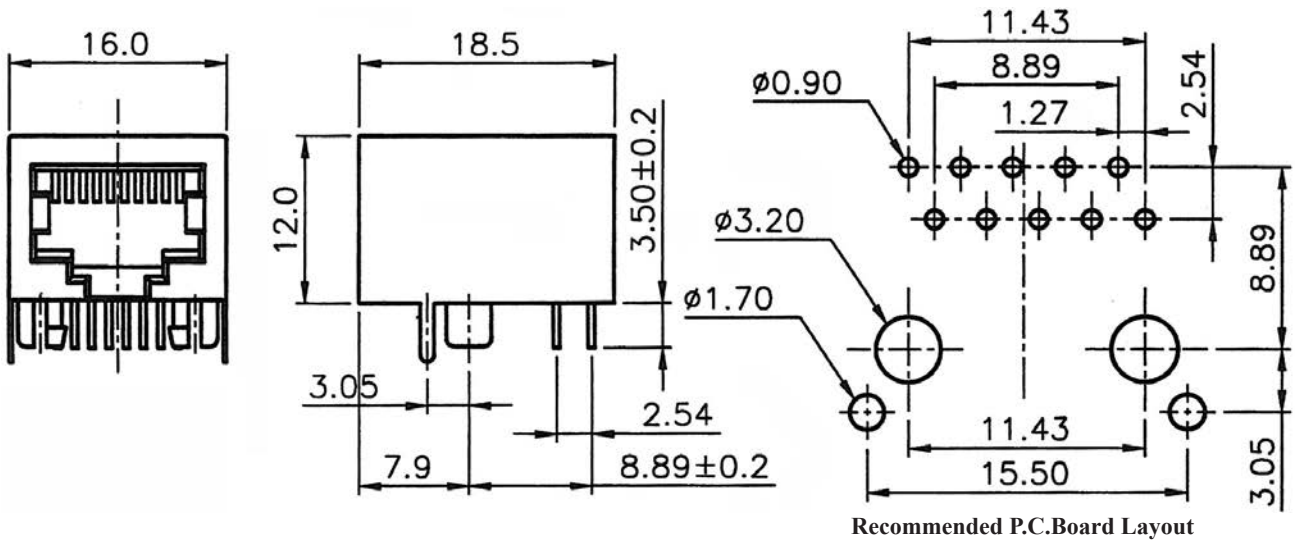
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ 87 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C
"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.00MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

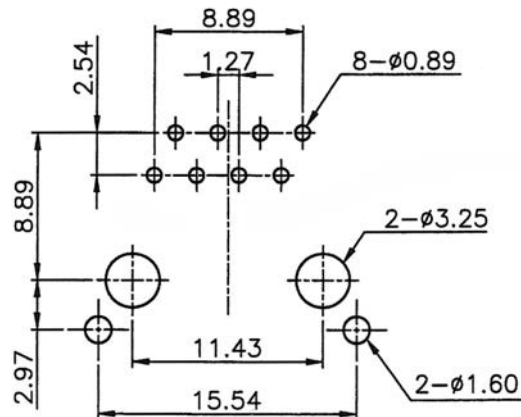
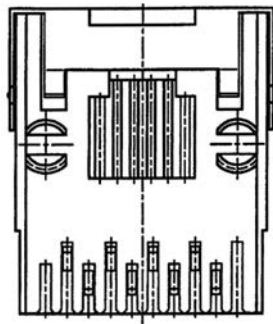
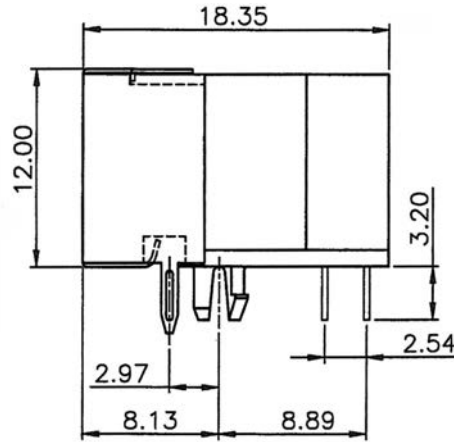
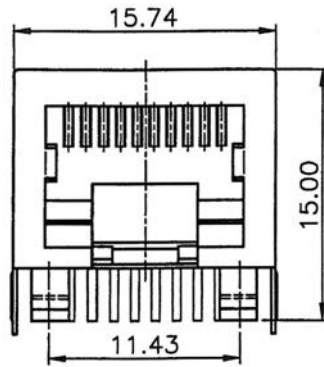
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 3 - $\frac{88}{1} \times \frac{B}{2} \times \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

NOTE: 2.97MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.00MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

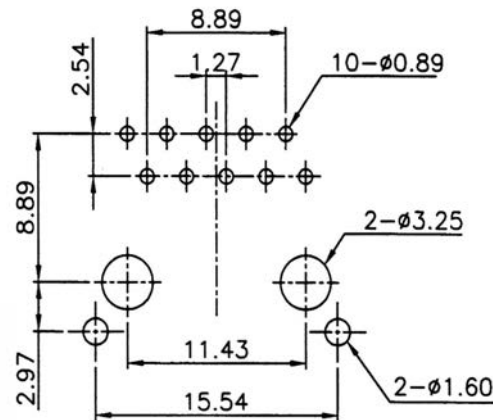
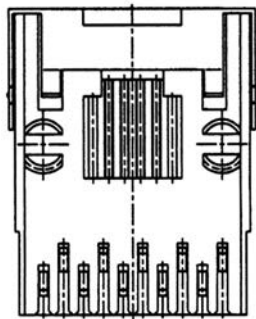
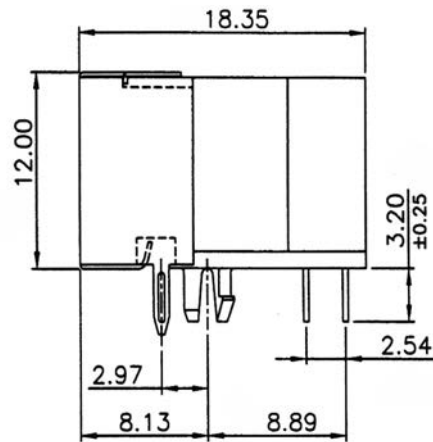
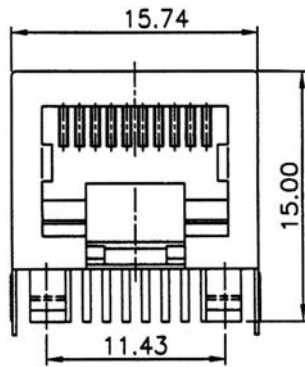
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 7 H - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

NOTE: 2.97MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

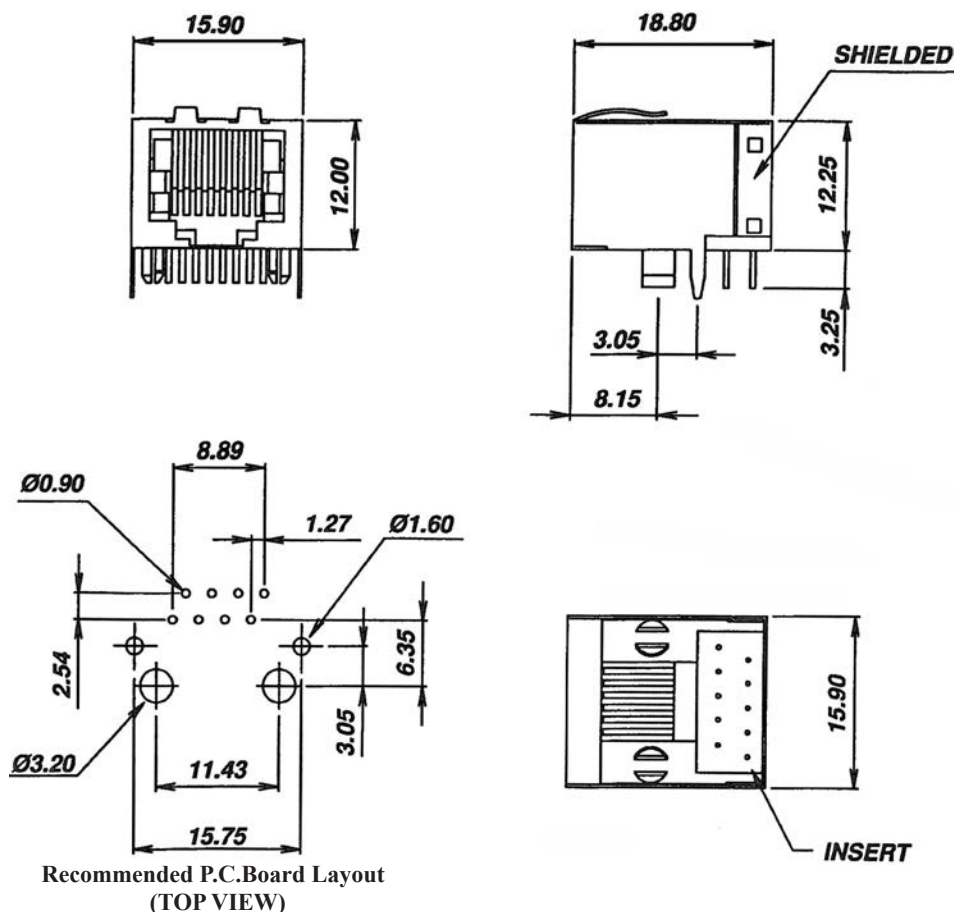
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R X - $\frac{88}{1} \times \frac{x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRXHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

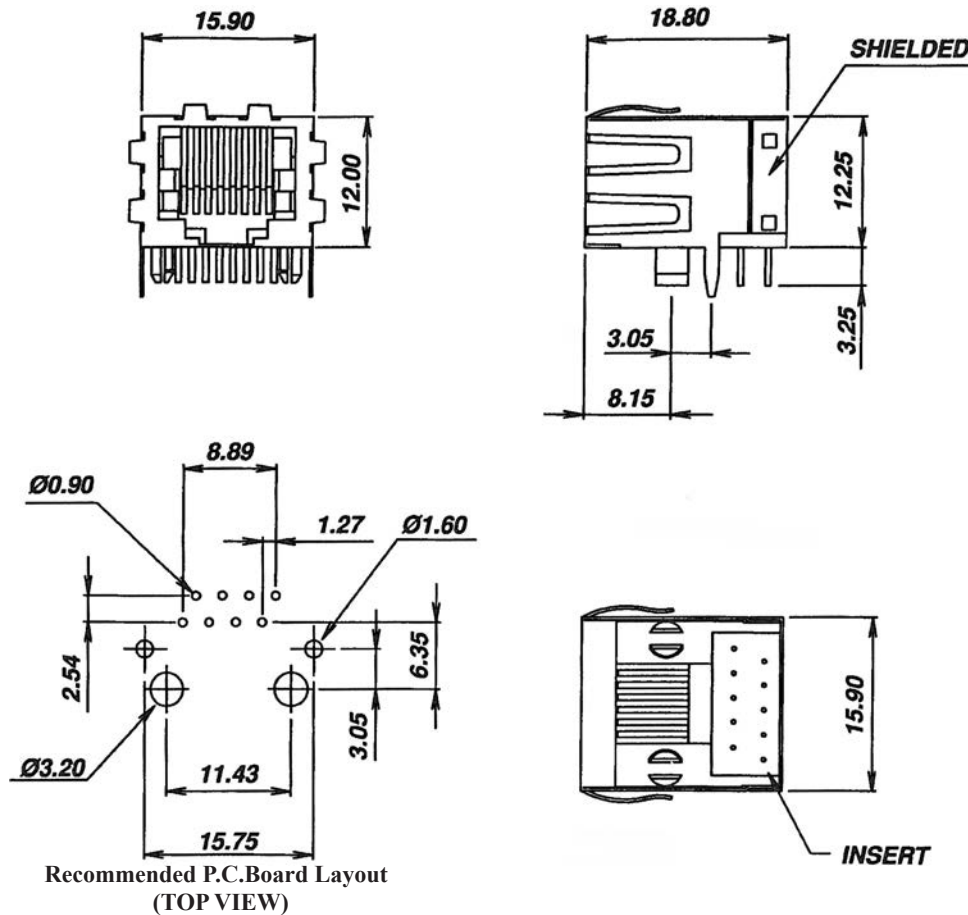
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJRY - $\frac{88}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRYHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

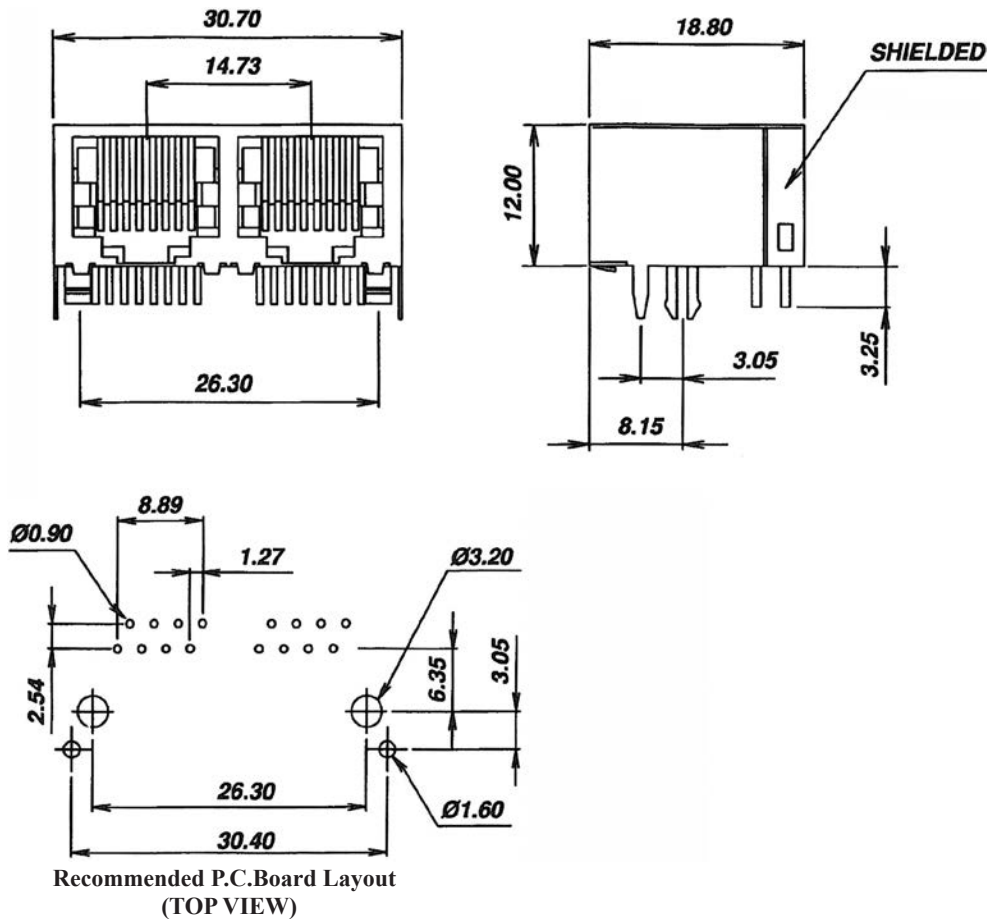
SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S A - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
02

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

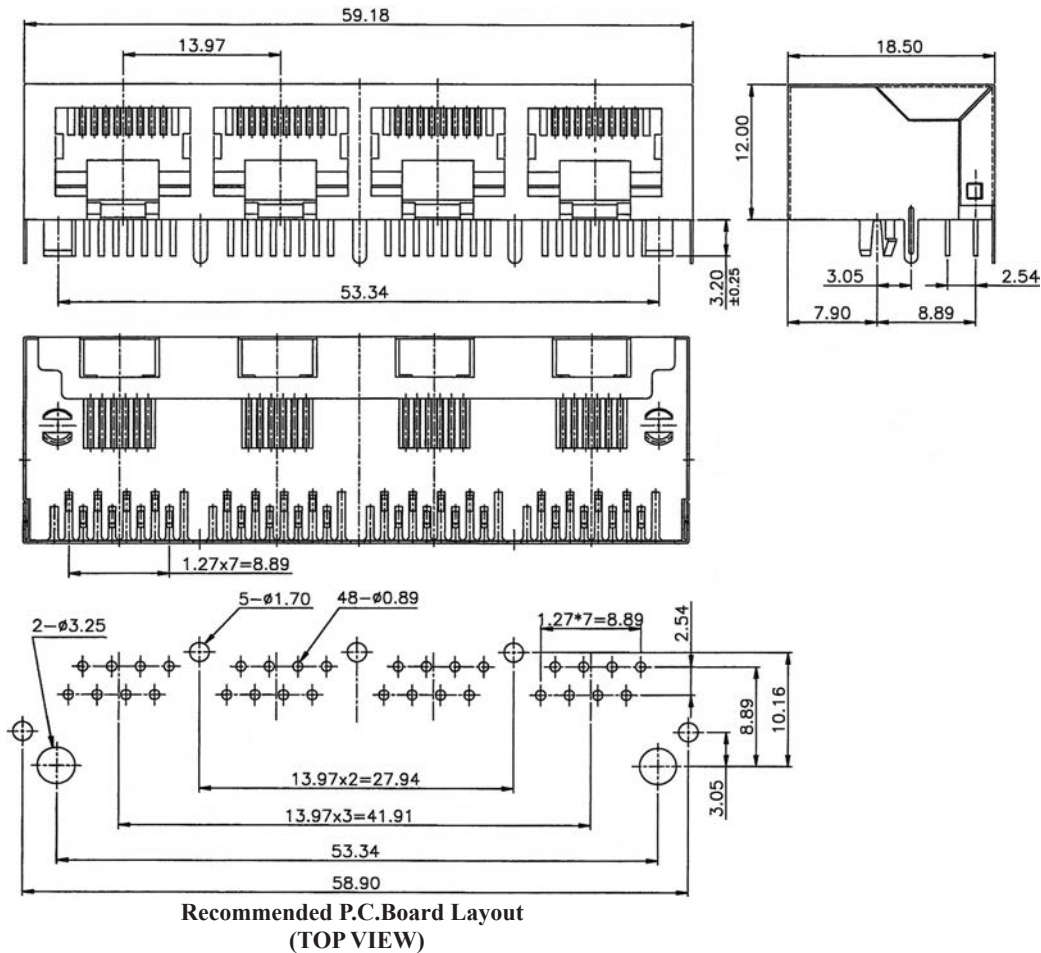
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 S - $\frac{x}{1} \frac{x}{2} \frac{B}{3} 04$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: GROUNDING PIN SPACING= 3.05MM BEHIND PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

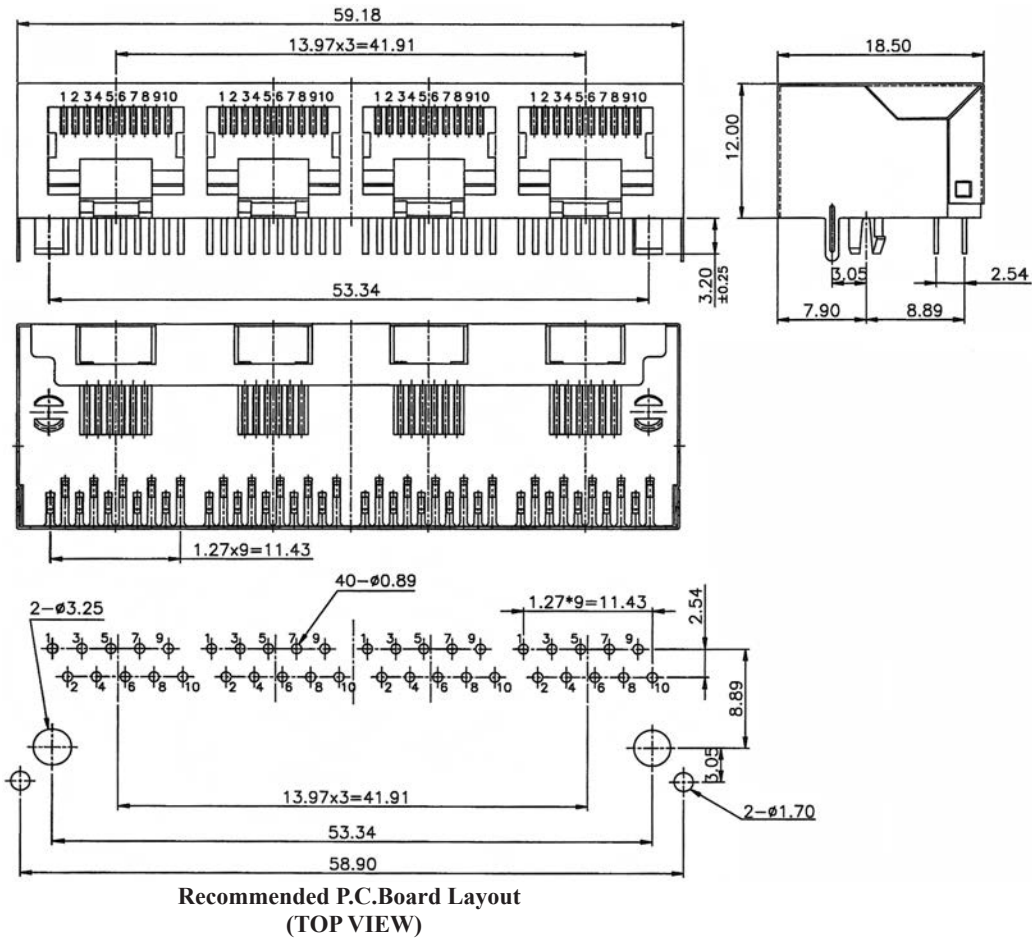
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ2J - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} 4$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: GROUNDING PIN SPACING= 3.05MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

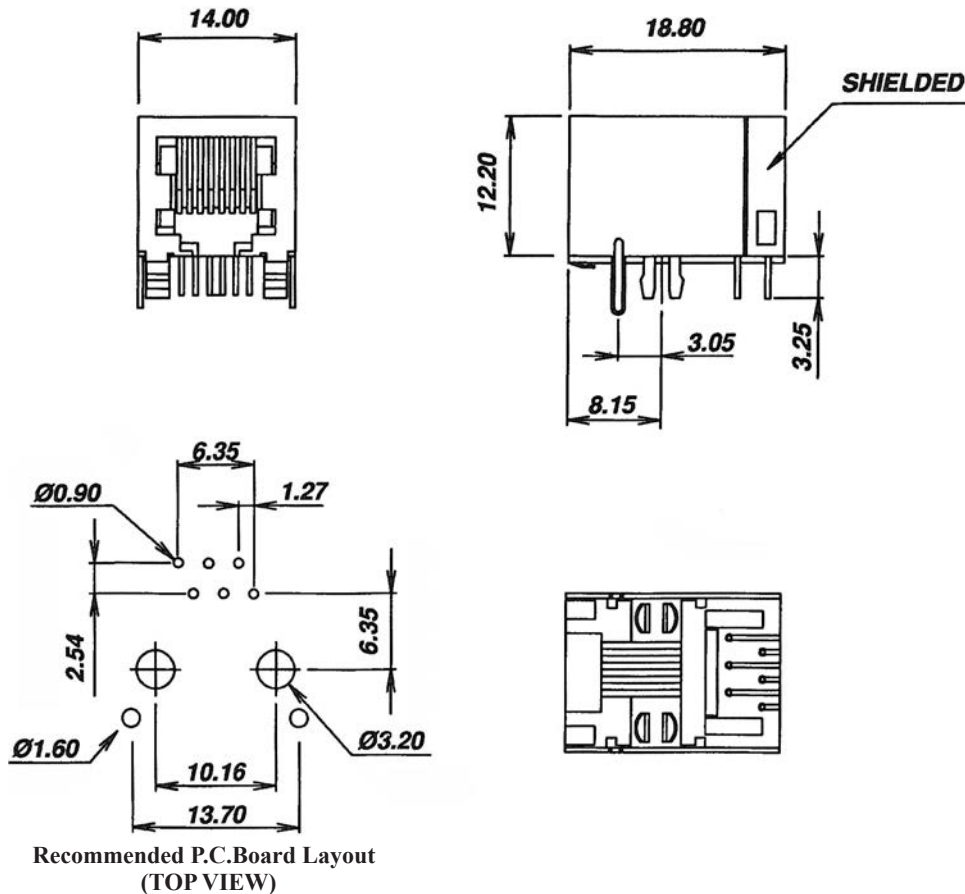
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRT - $\frac{x \times x}{T} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

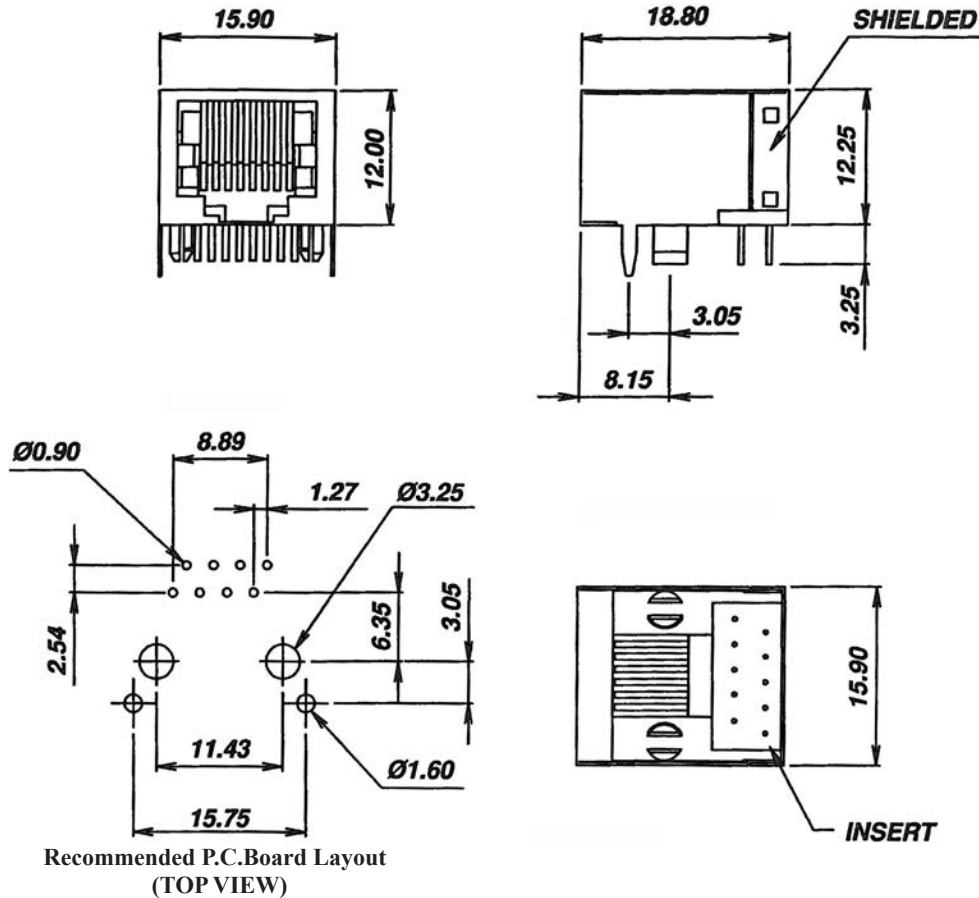
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRT - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

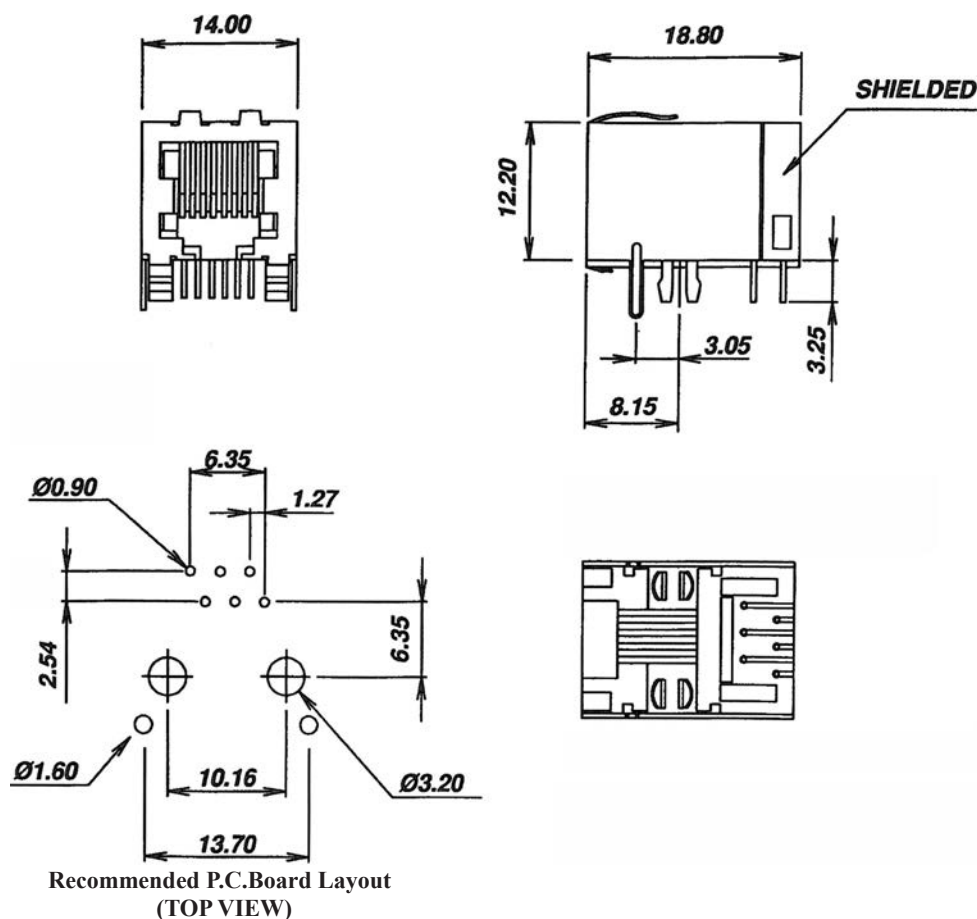
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R U - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRUHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500M Ω Min.

Contact Resistance: 20m Ω Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40 $^{\circ}$ c / +85 $^{\circ}$ c

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235 $^{\circ}$ c

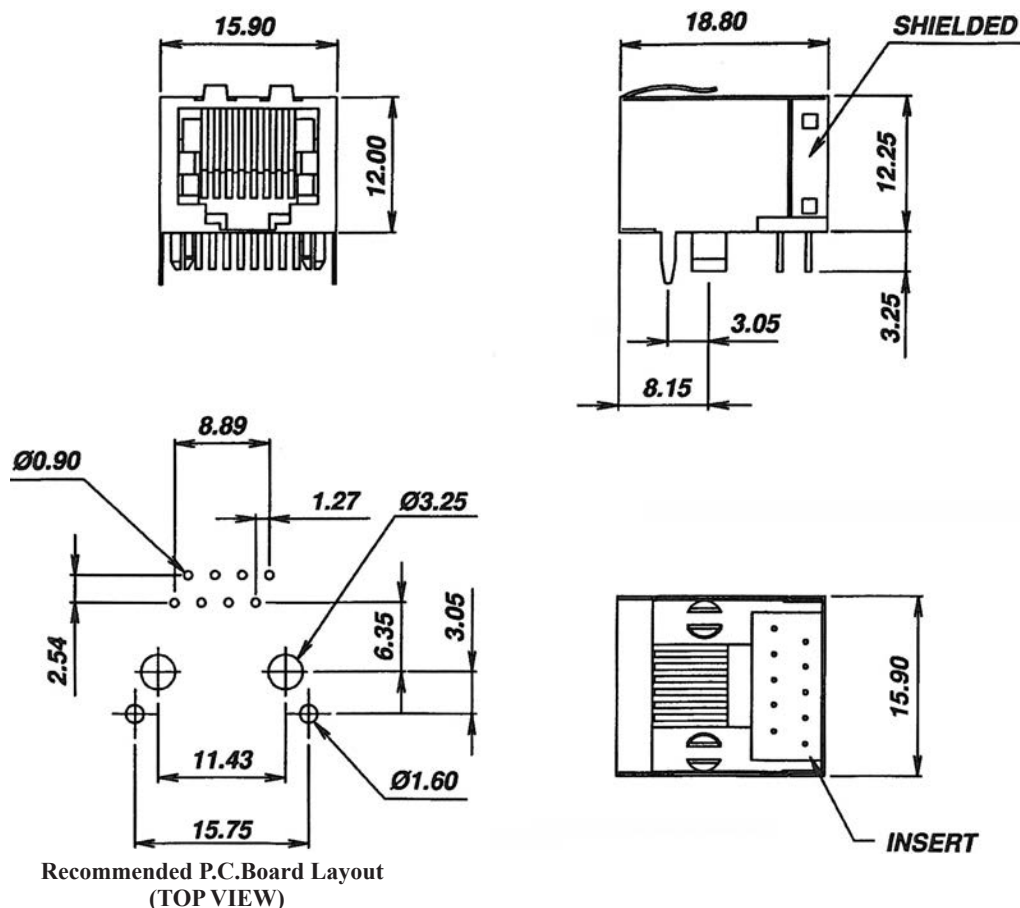
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRU - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRUHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

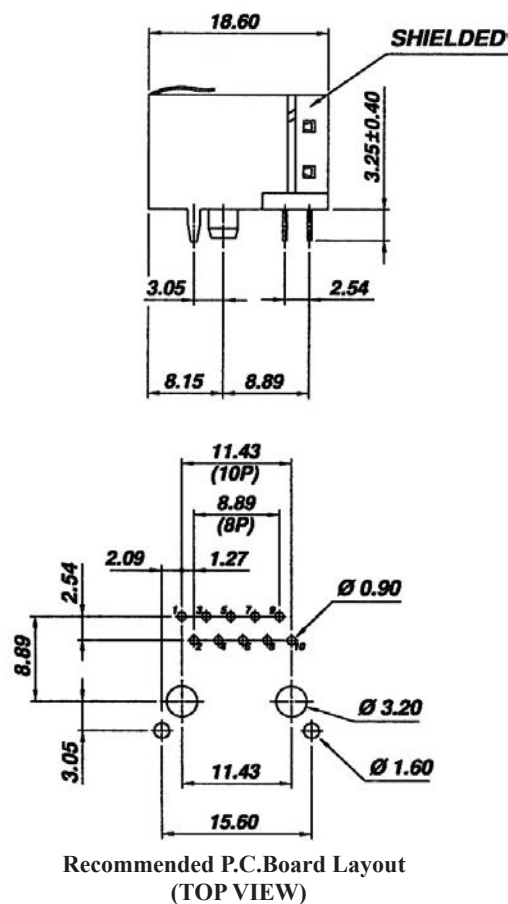
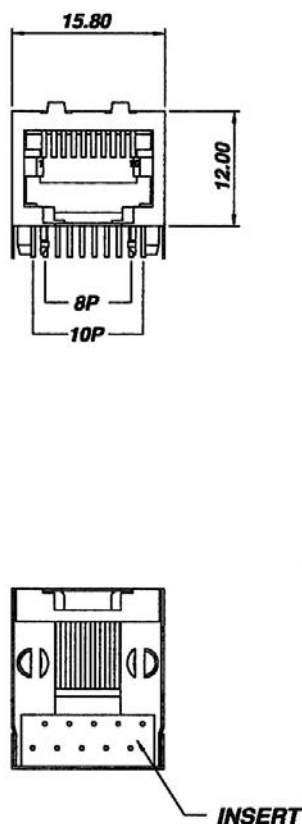
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRU - $\frac{xx}{1} \frac{xB}{2}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRUHT-0xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

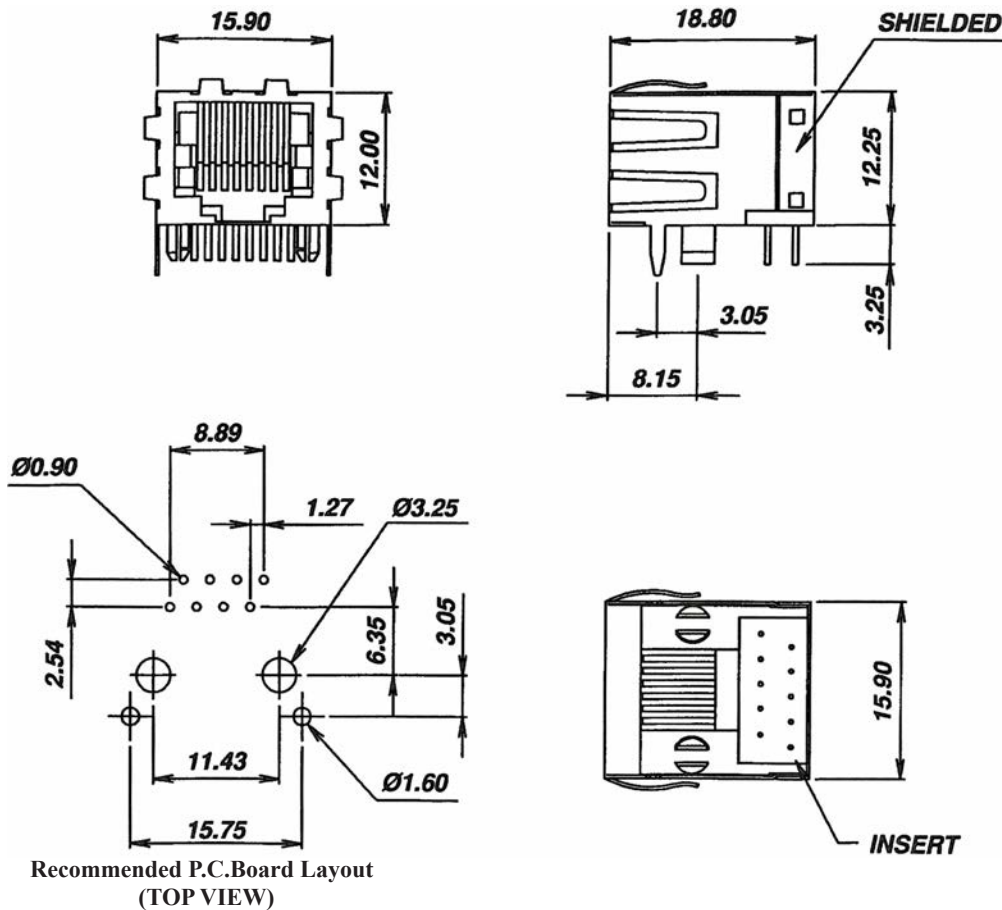
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R V - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRVHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

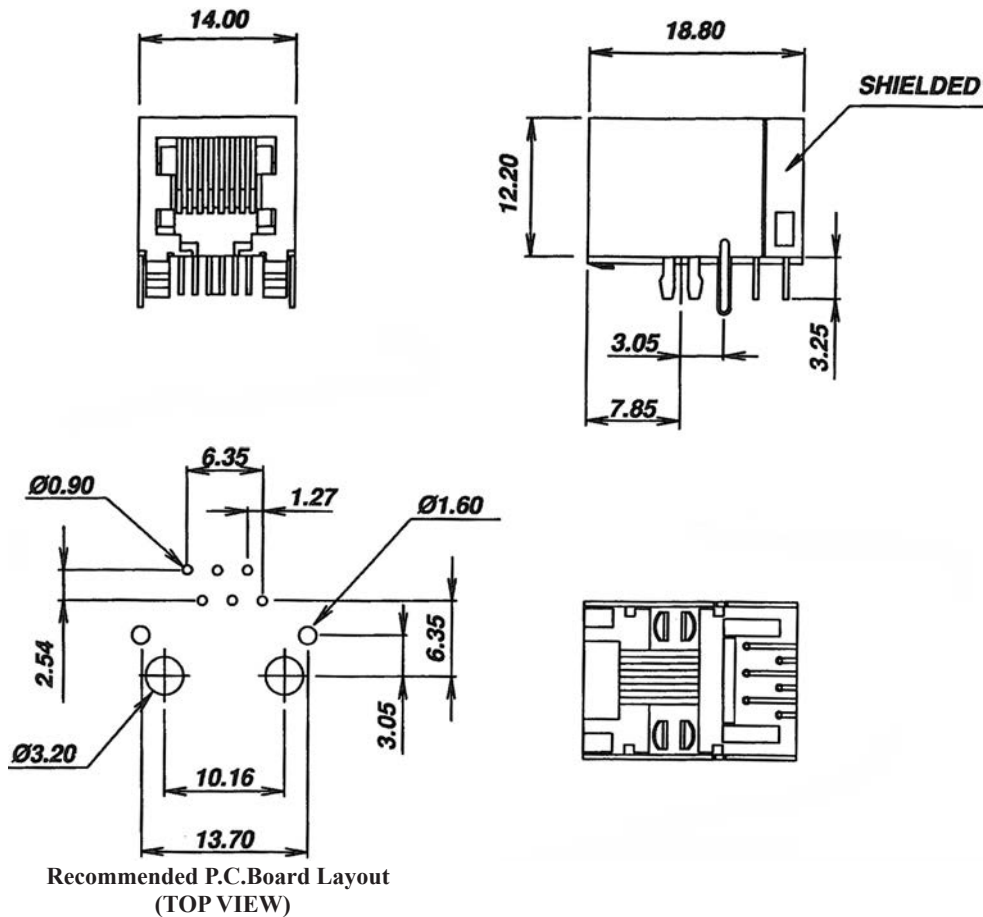
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R W - $\frac{x}{1} \frac{x}{2} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRWHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

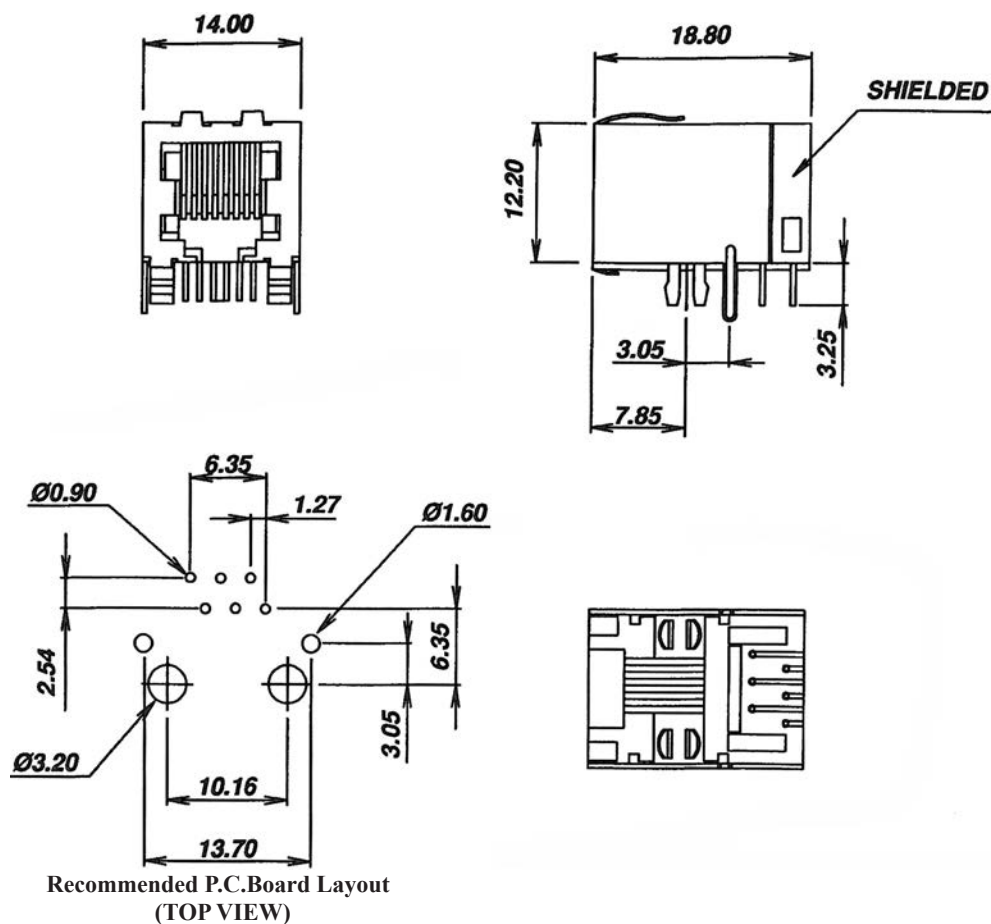
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R X - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRXHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

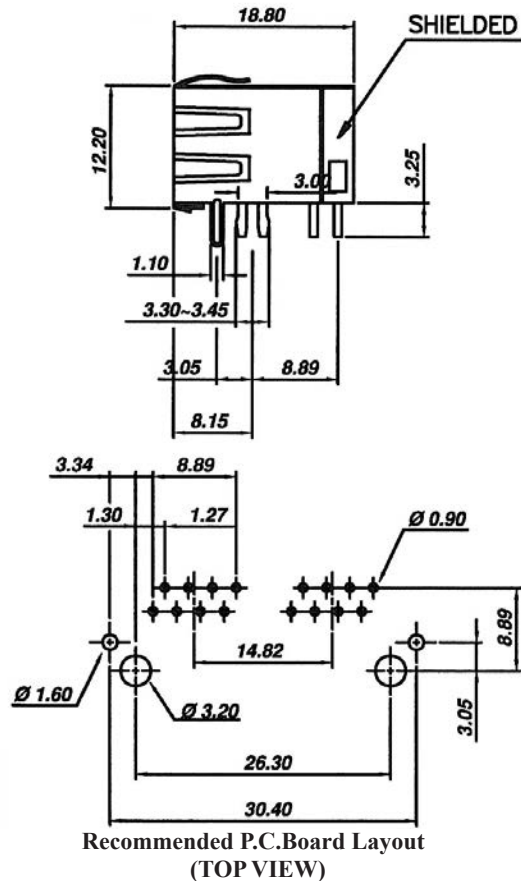
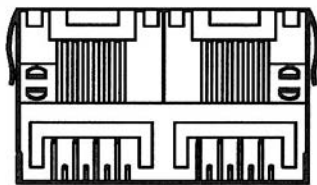
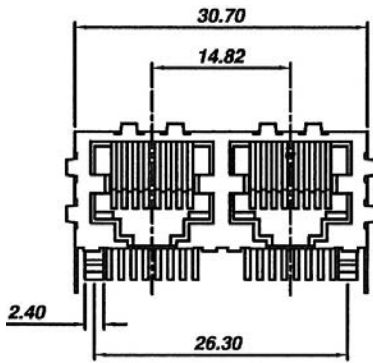
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S B - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
02

NOTE: 3.05MM SPACING BEFORE PEG

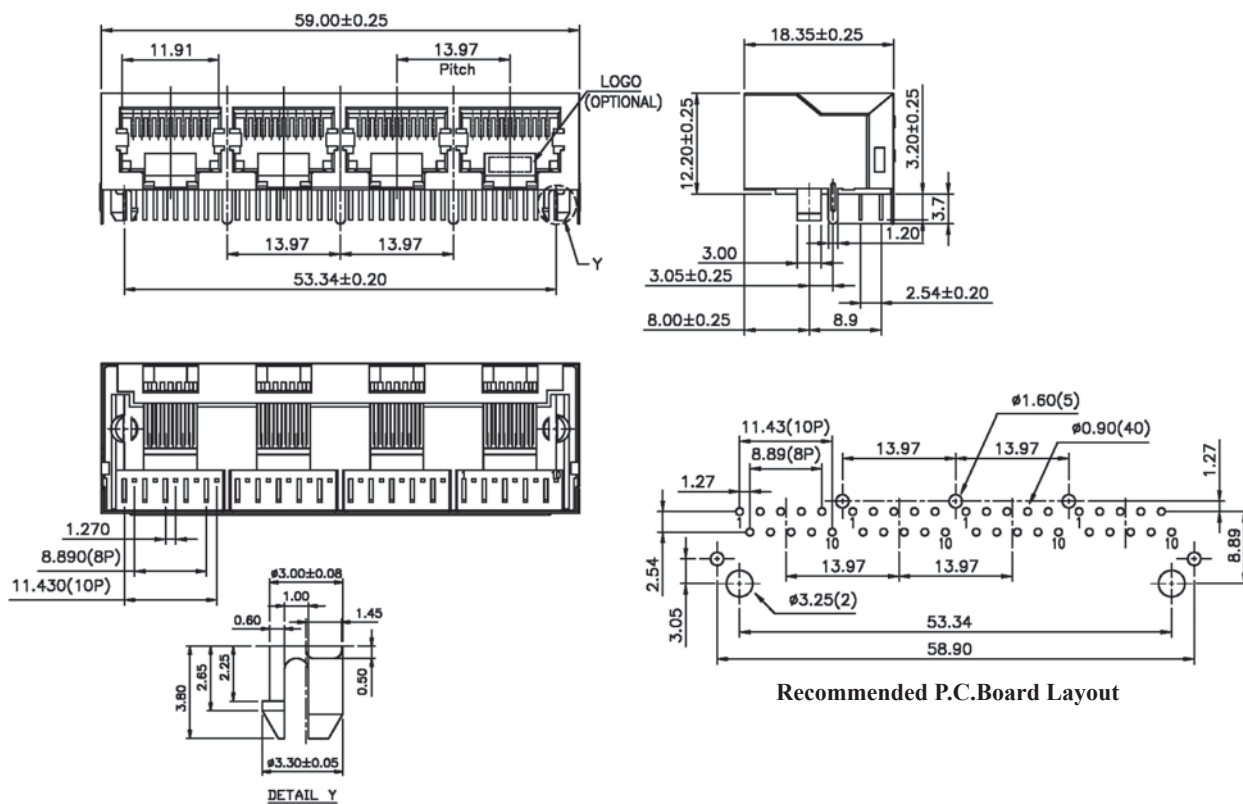
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=12.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J N H - 88 x B 04
1 2 3 4 5

1. MODULAR JACK TYPE:
"NH" H=12.20MM
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. NO. OF PORTS:
04

NOTE: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

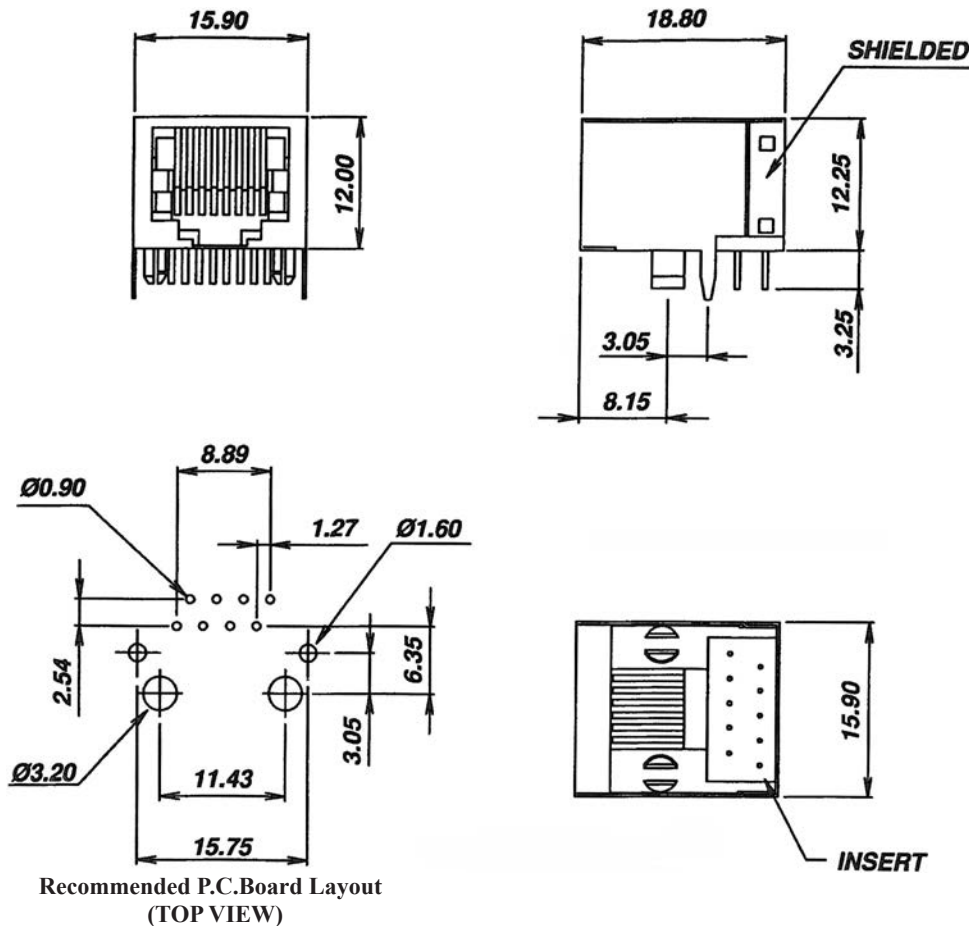
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R W - $\frac{x}{1} \frac{x}{2} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRWHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

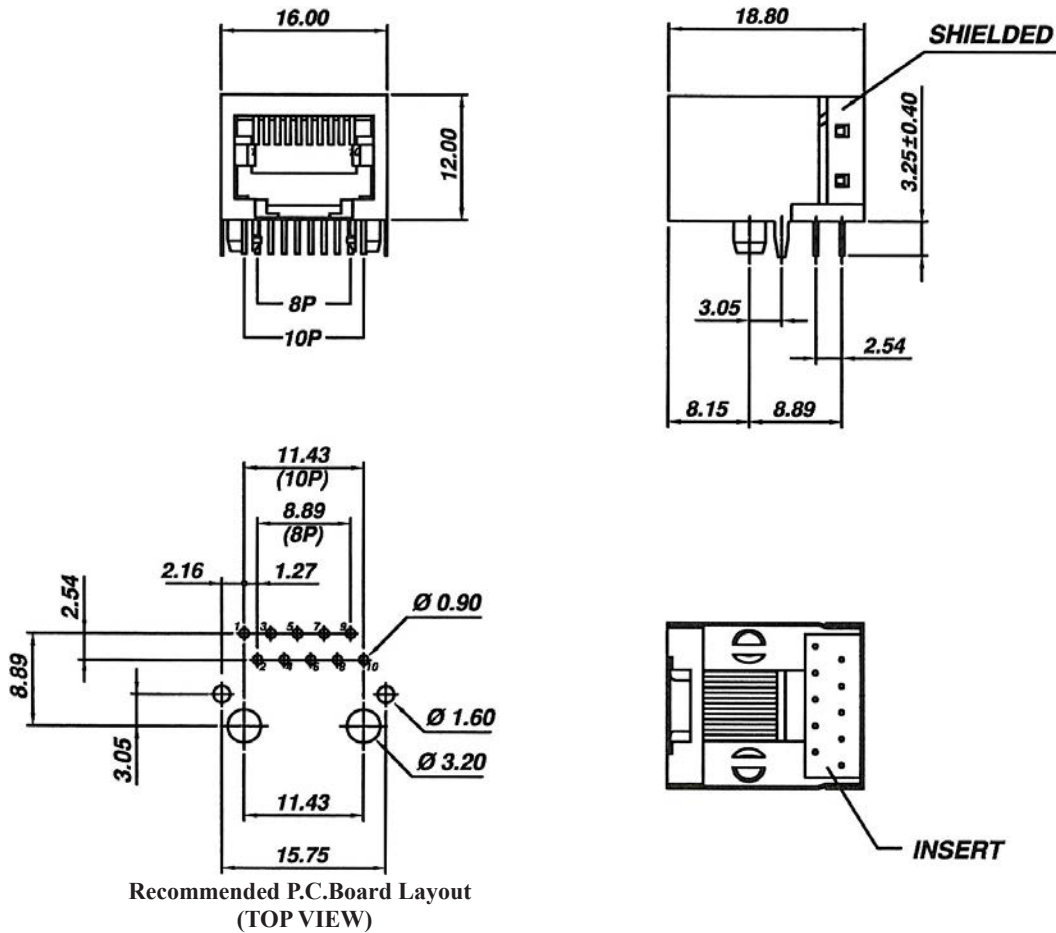
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R W - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRWHT-0xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

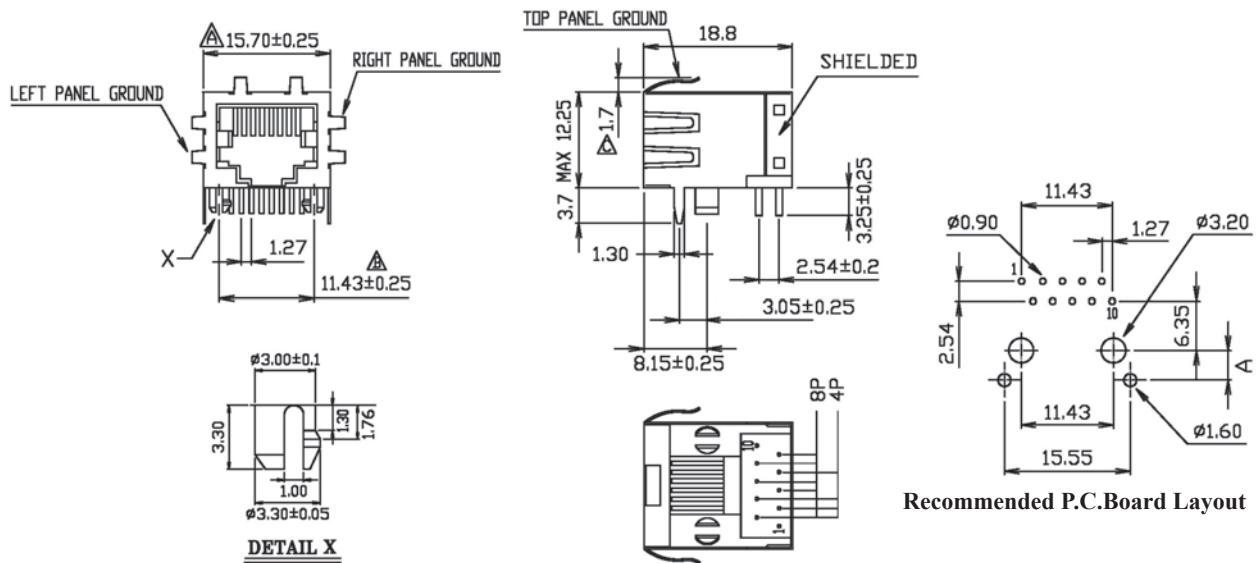
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{X X}{1}$ - $\frac{X X X}{2 3 4}$ B

- MODULAR JACK TYPE:
 "HM" A=3.05MM WITH FLAT PINS
 "HJ" A=3.05MM WITH ROUND PINS
- NO. OF POSITIONS & CONTACTS:
 "08" 10P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

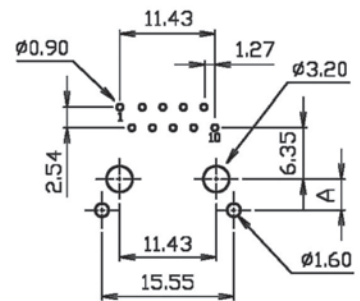
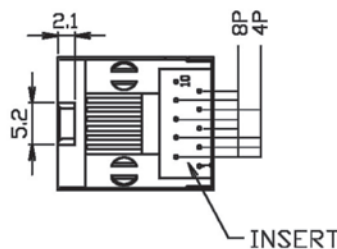
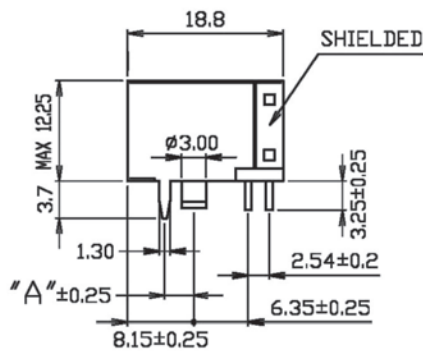
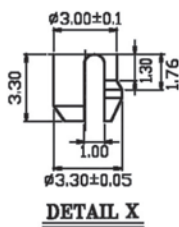
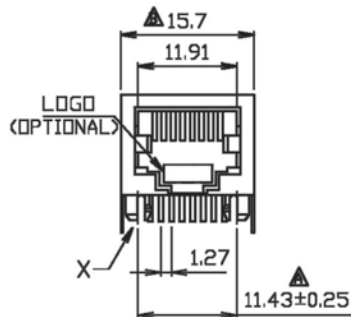
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J HG - xx x B
 1 2 3 4

1. MODULAR JACK TYPE:
"HG" DIM.A = 3.05MM
2. NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

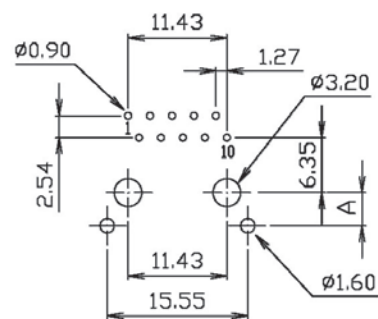
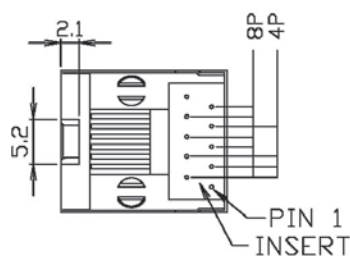
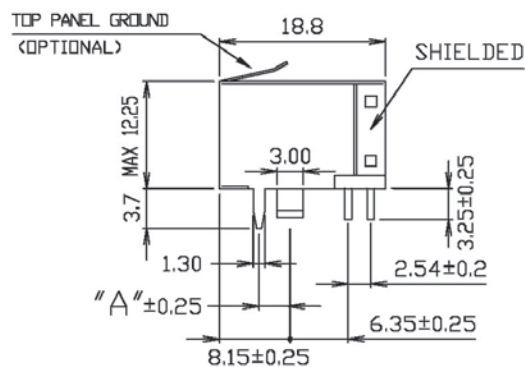
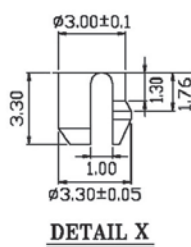
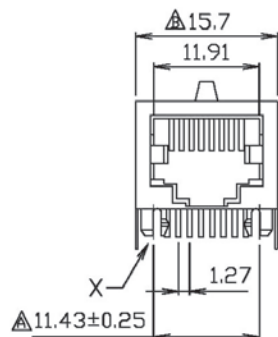
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{H L}{1} - \frac{x x x}{2 3 4} B$

- MODULAR JACK TYPE:
"HL" DIM.A = 3.05MM
- NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.25MM (FULLY SHIELDED)

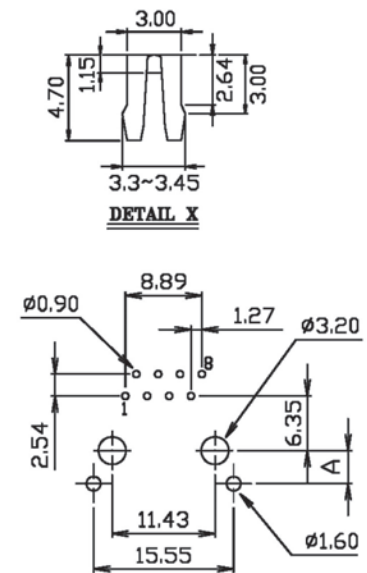
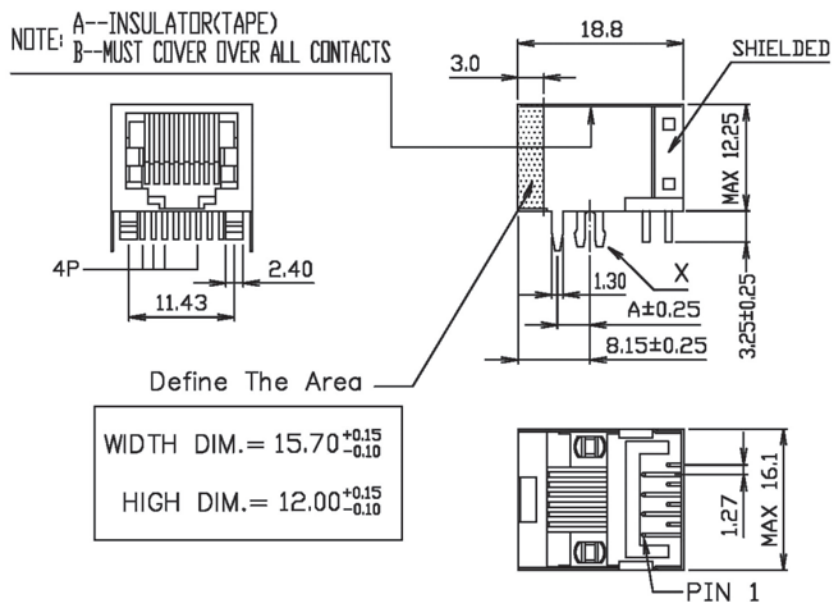
SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**

NOTE: A--INSULATOR(TAPE)
B--MUST COVER OVER ALL CONTACTS



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J HH - 88 x B
 1 2 3 4

- MODULAR JACK TYPE:
"HH" DIM.A = 3.05MM
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

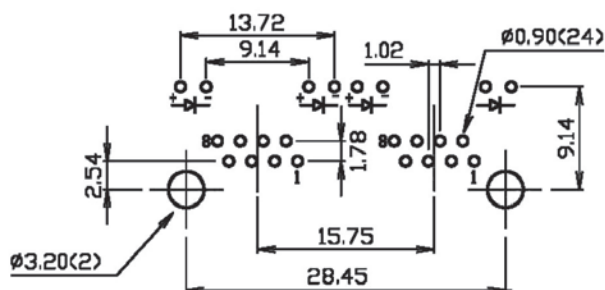
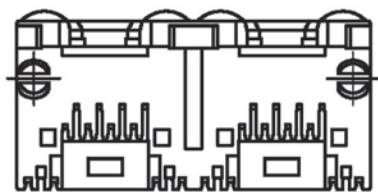
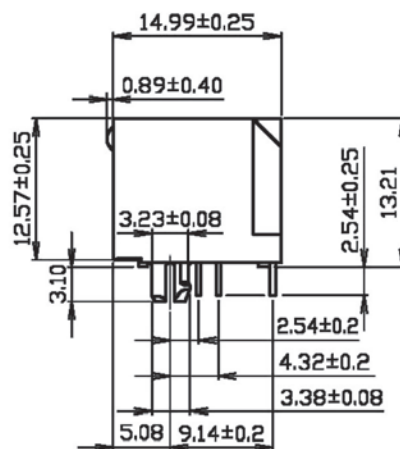
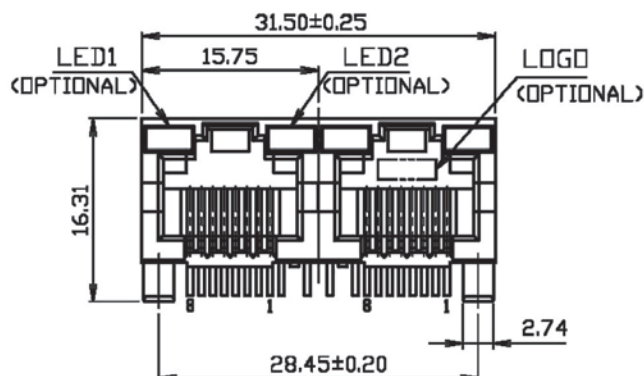
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=12.57MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J K F - 8 8 x B x x 0 2
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"KF" MODULAR PCB GANGED JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPON REQUEST!

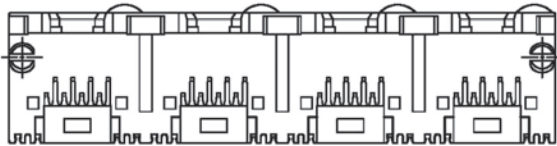
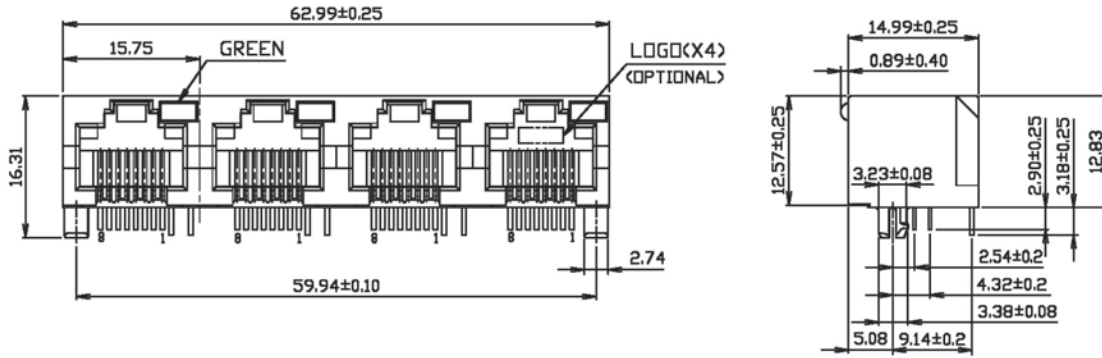
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=12.57MM (FULLY SHIELDED)

SPECIFICATIONS

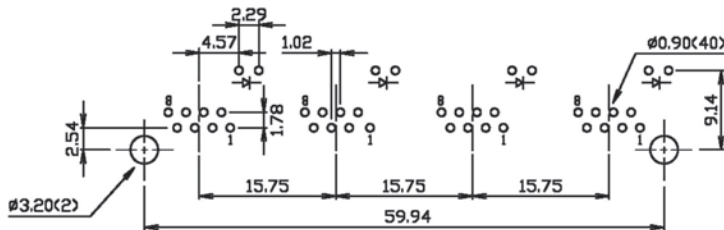
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



P/N MJKF-88xBXN04



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N MJKF-88xBXN04
 1 2 3 4 5 6

1. MODULAR JACK TYPE:
"KF" MODULAR PCB GANGED JACK WITH LED
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. COLORS OF LED:
"XN" LED1/2 = NIL/GREEN
"XX" WITHOUT LED
6. NO. OF PORTS:
04

NOTE: OTHER LED COLORS UPON REQUEST!

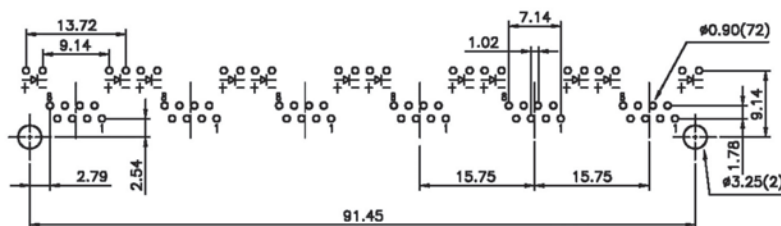
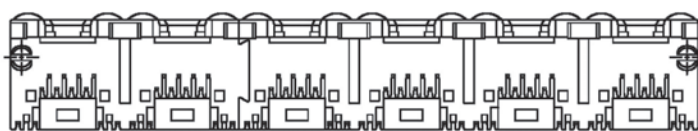
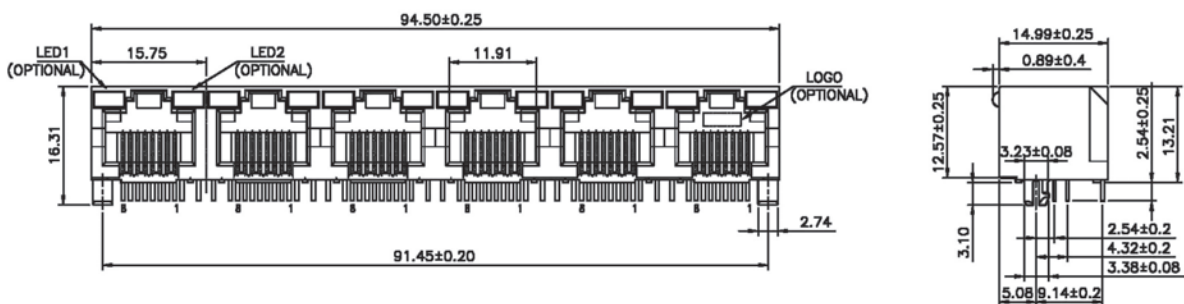
SIDE ENTRY 6-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=12.57MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J K F - 8 8 x B x x 0 6
1 2 3 4 5 6

- MODULAR JACK TYPE:
"KF" MODULAR PCB GANGED JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
06

NOTE: OTHER LED COLORS UPON REQUEST!

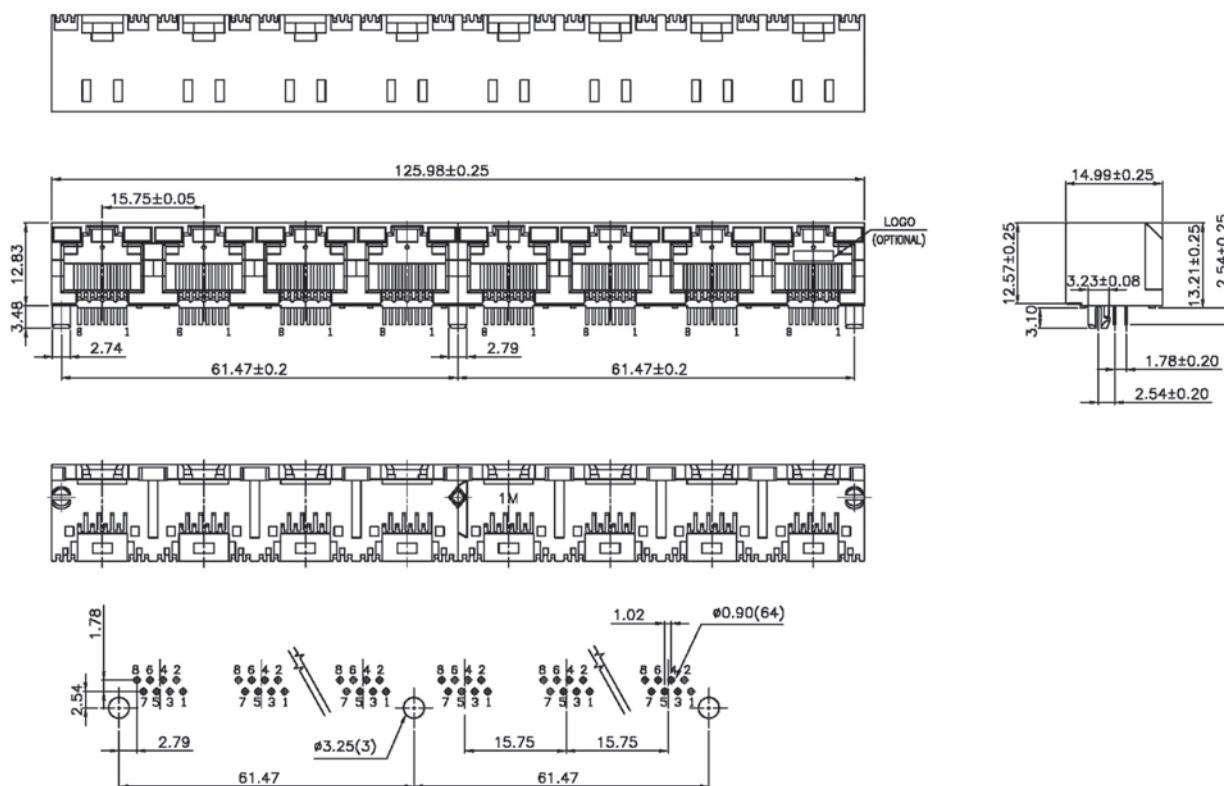
SIDE ENTRY 8-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=12.57MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J K F - 8 8 x B x x 0 8
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"KF" MODULAR PCB GANGED JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
08

NOTE: OTHER LED COLORS UPON REQUEST!

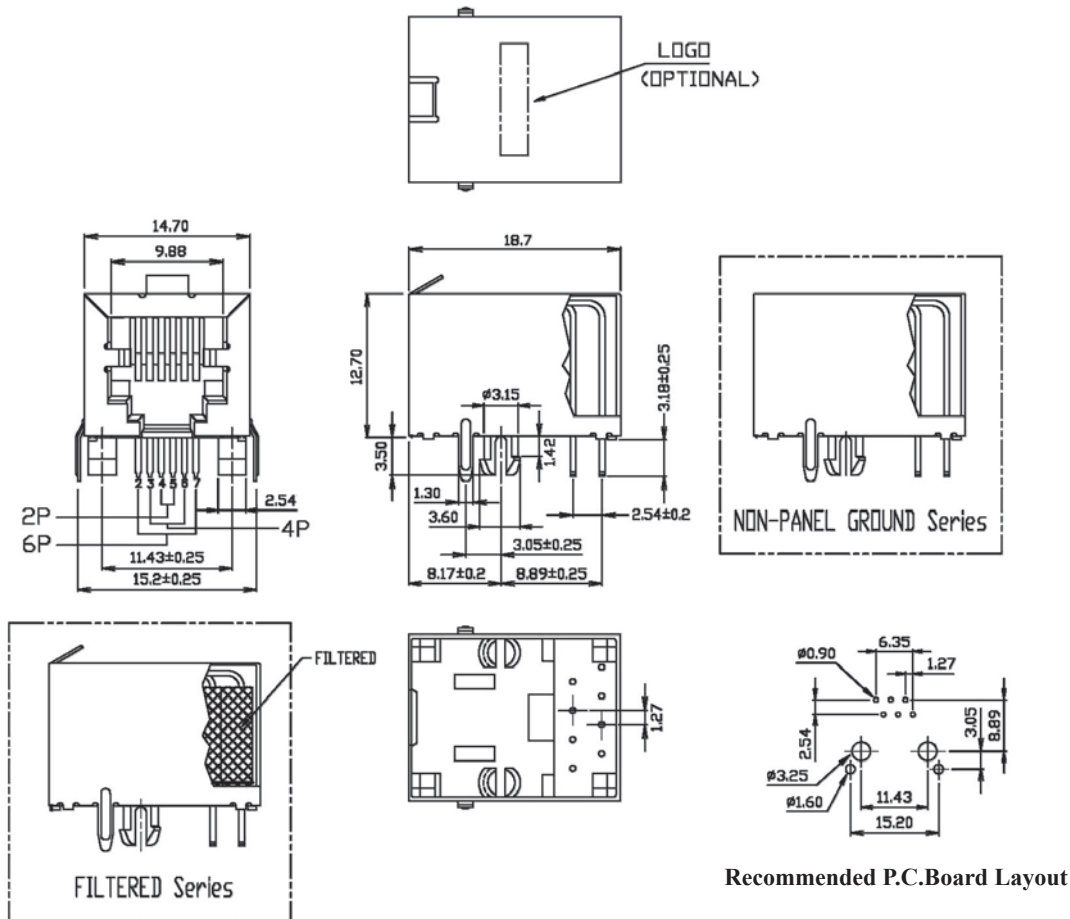
SIDE ENTRY MODULAR PCB JACK 6P WITH FERITTE PROFILE=12.70MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{XX}{3}$ $\frac{B}{4}$

- MODULAR JACK TYPE:
 "YK" FILTERED WITH TOP PANEL GROUND
 "YL" FILTERED WITHOUT PANEL GROUND
- NO. OF POSITIONS & CONTACTS:
 "64" 6P4C
 "66" 6P6C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

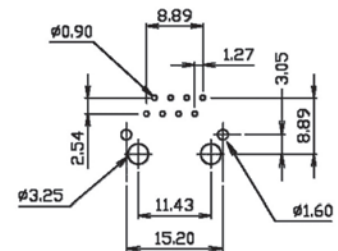
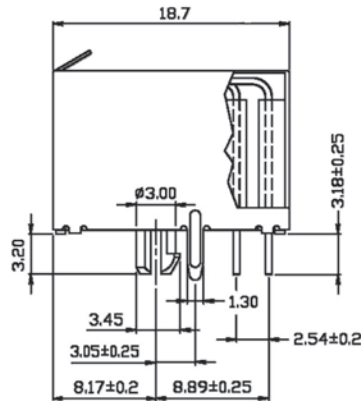
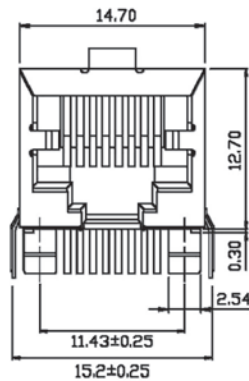
SIDE ENTRY MODULAR PCB JACK 8P WITH FERITTE PROFILE=12.70MM (FULLY SHIELDED)

SPECIFICATIONS

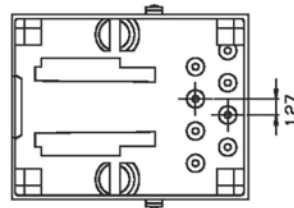
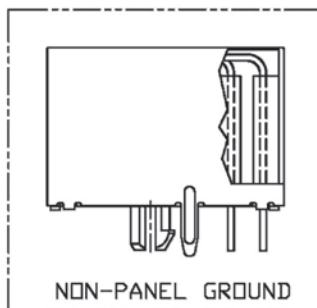
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B

1. MODULAR JACK TYPE:
 "YK" FILTERED WITH TOP PANEL GROUND
 "YL" FILTERED WITHOUT PANEL GROUND
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. HOUSING COLOR:
 "B" BLACK

NOTE: 3.05MM SPACING BEHIND PEG

SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=12.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

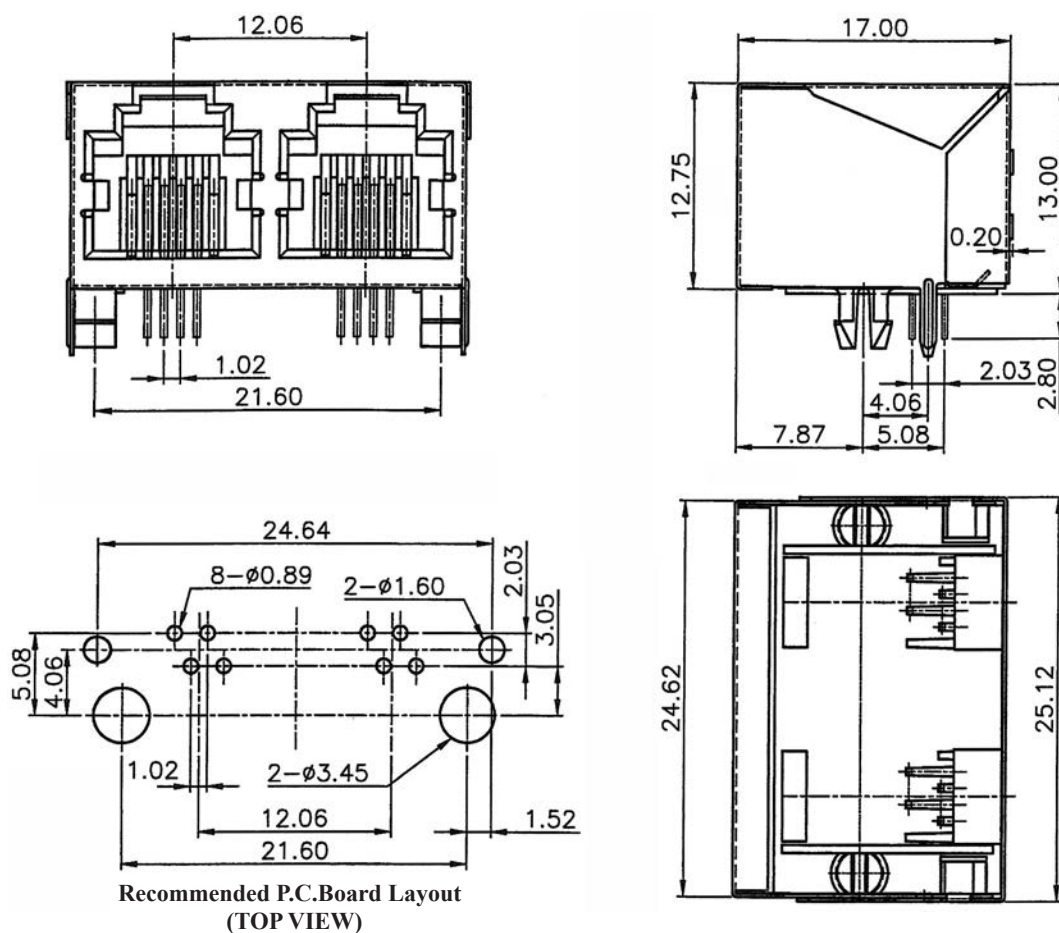
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 Q - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 2$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: 4.06MM SPACING BEHIND PEG

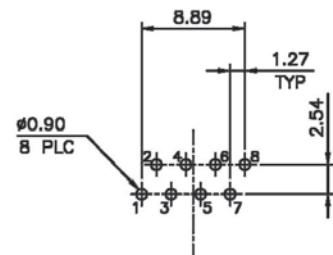
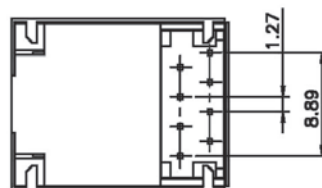
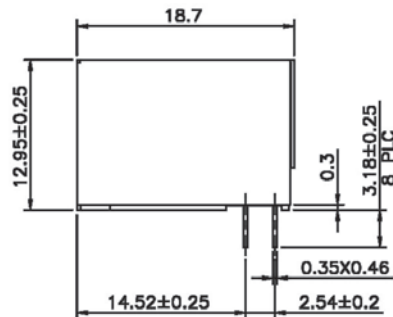
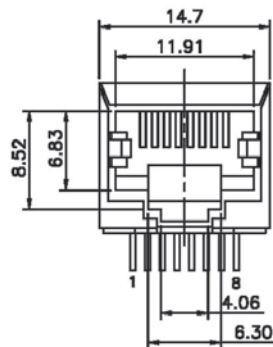
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{K J}{1}$ - $\frac{8 8}{2}$ x $\frac{B}{3 4}$

1. MODULAR JACK TYPE:
"KJ" W/O LOCATING PEGS
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

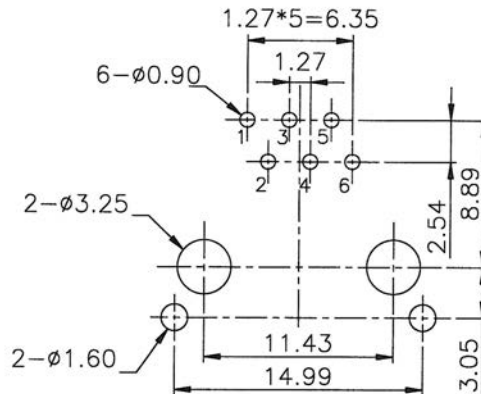
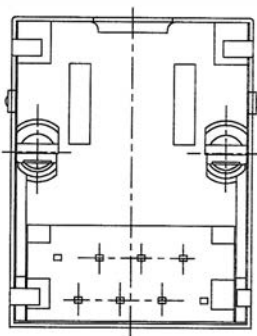
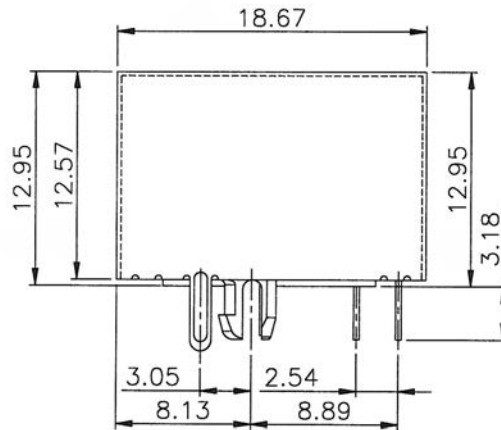
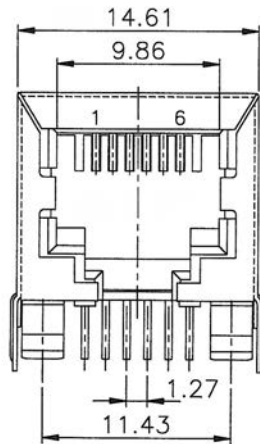
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 4 5 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

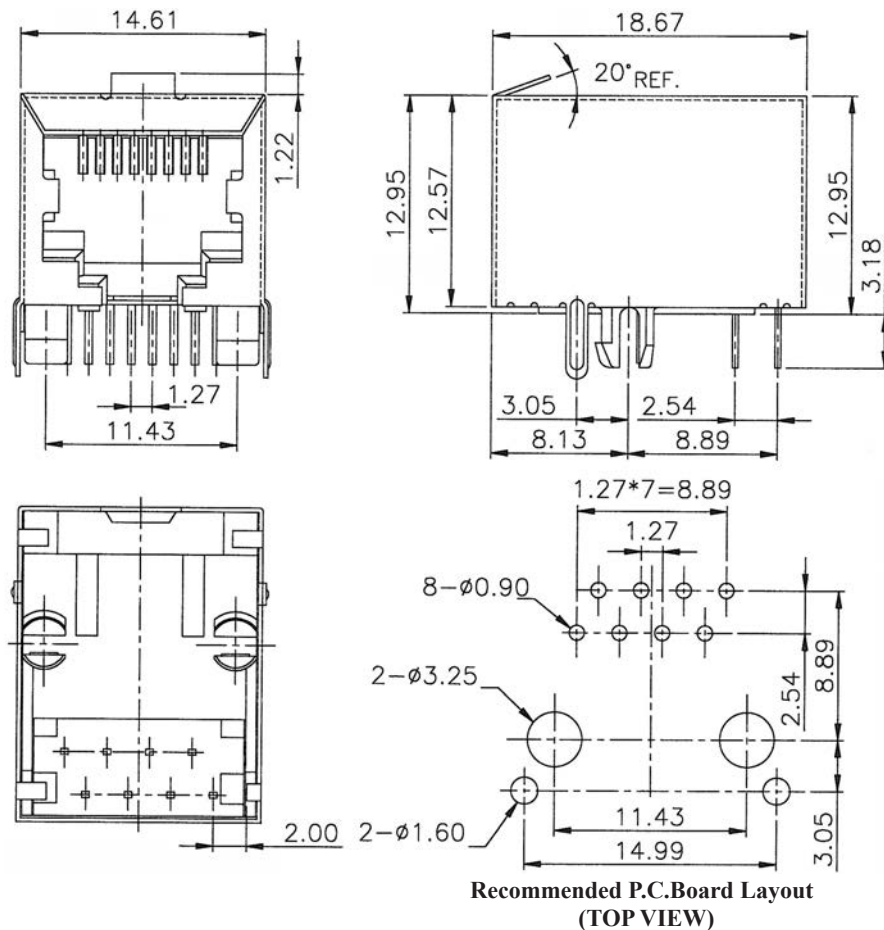
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 5 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

NOTE: 3.05MM SPACING BEFORE PEG

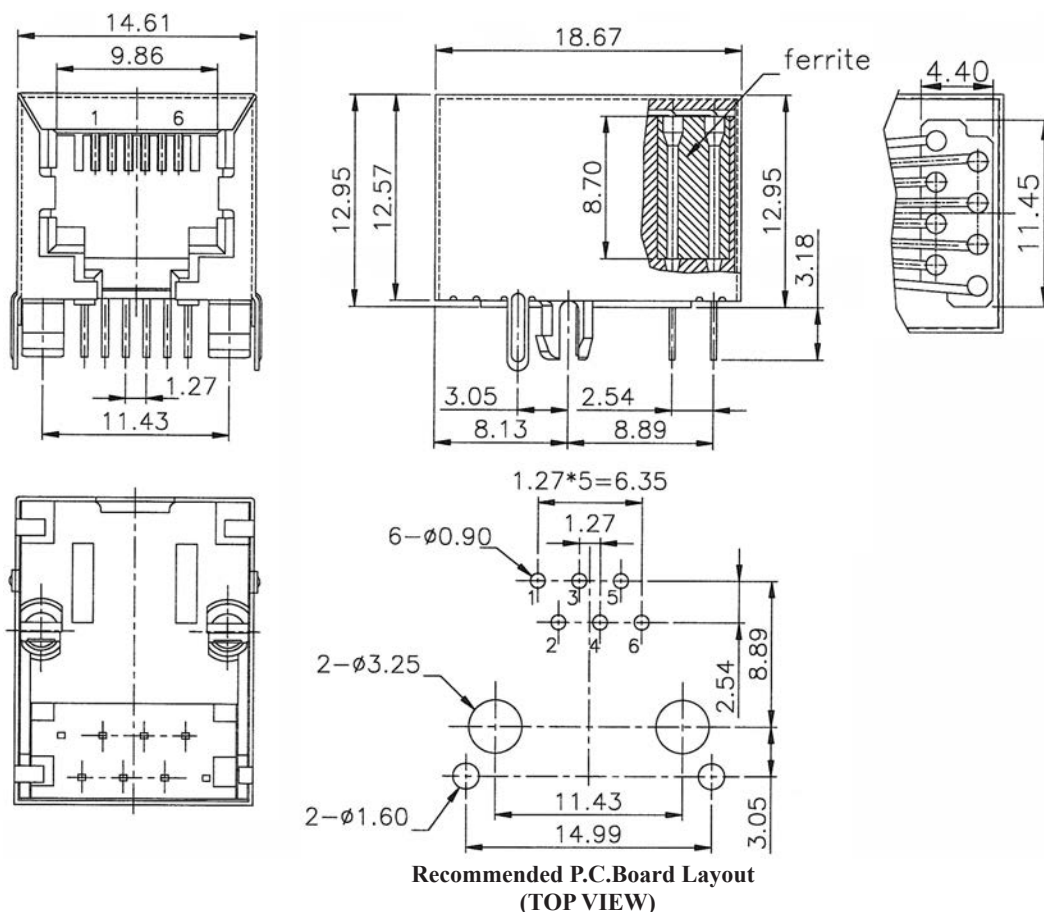
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 6P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1T - $\frac{XX}{T} \frac{X}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

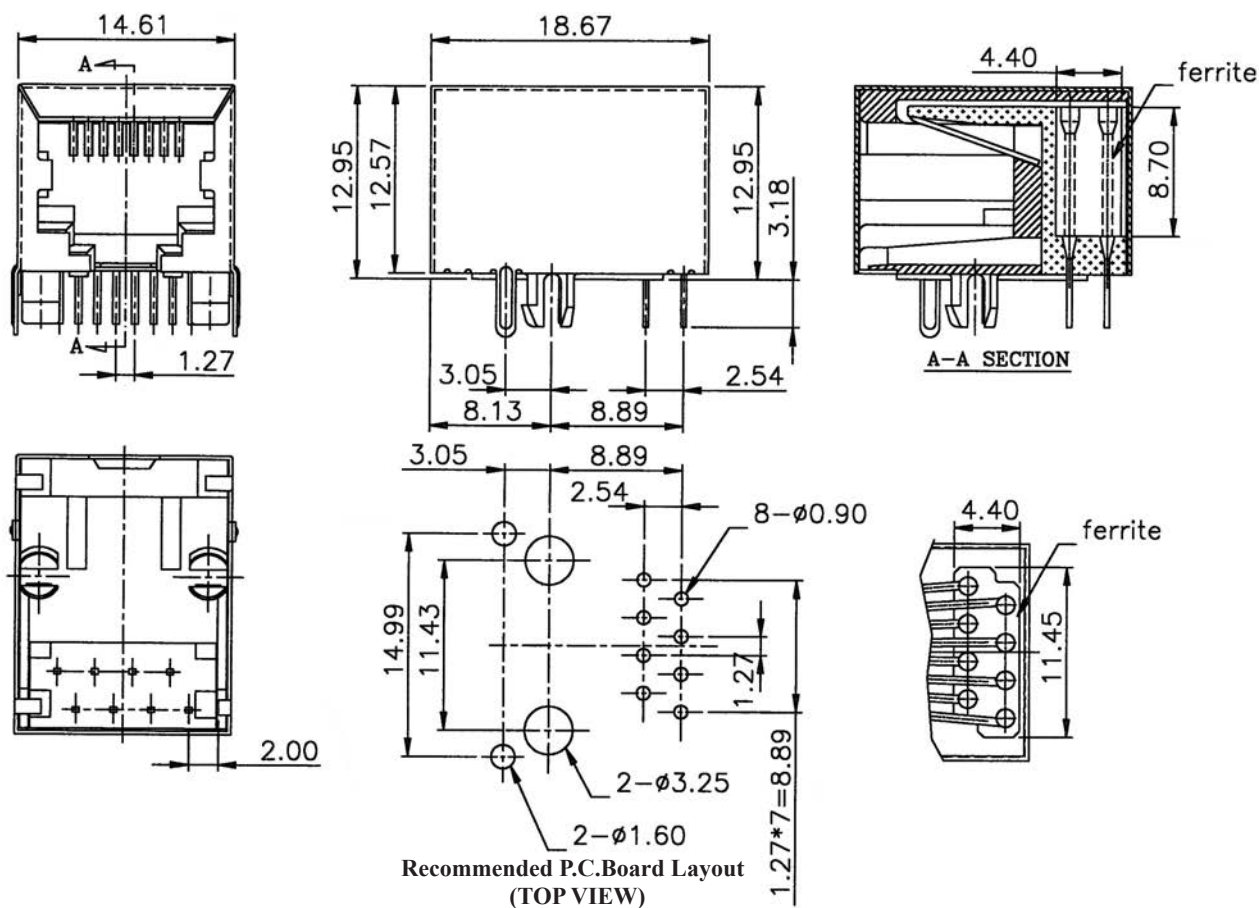
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=12.95MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°c / +85°c
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°c
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ1T- $\frac{88 \times B}{T2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

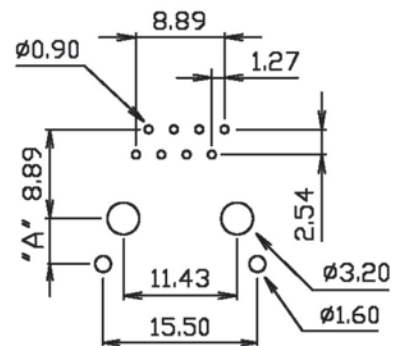
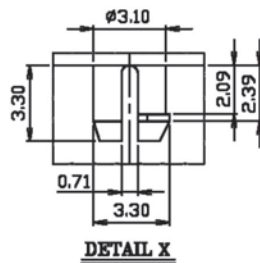
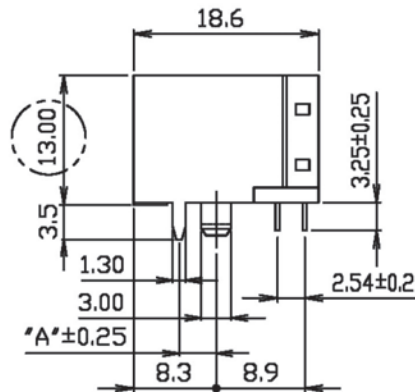
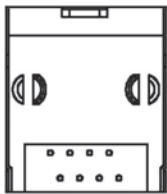
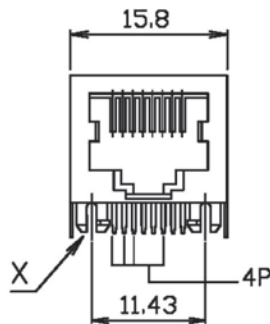
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{HS}{I}$ - $\frac{88}{2}$ x $\frac{B}{34}$

- MODULAR JACK TYPE:
"HS" DIM.A = 3.05MM
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

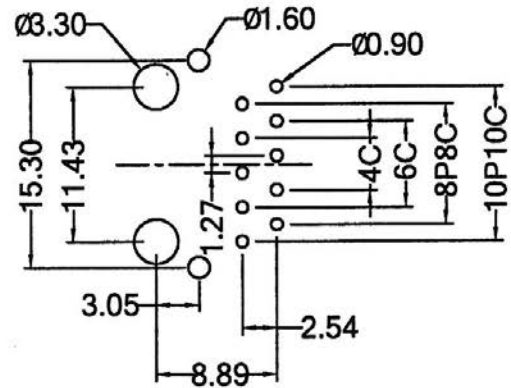
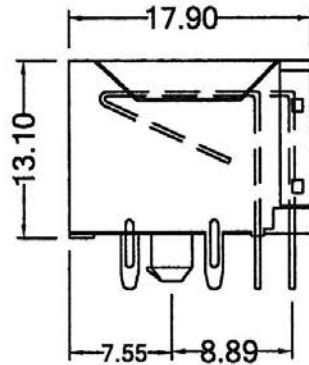
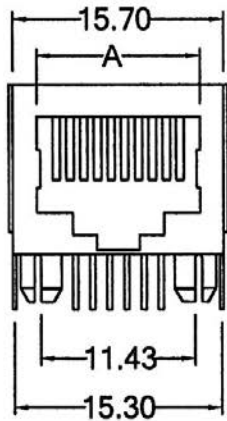
SIDE ENTRY MODULAR PCB JACK 6P+8P+10P PROFILE=13.10MM (FULLY SHIELDED)

SPECIFICATIONS

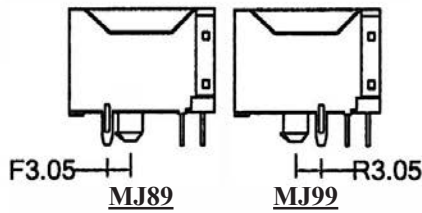
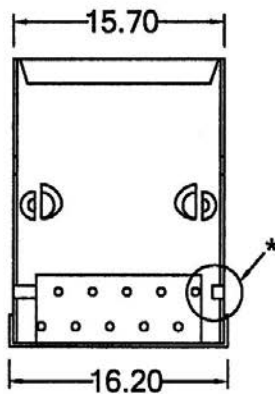
Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

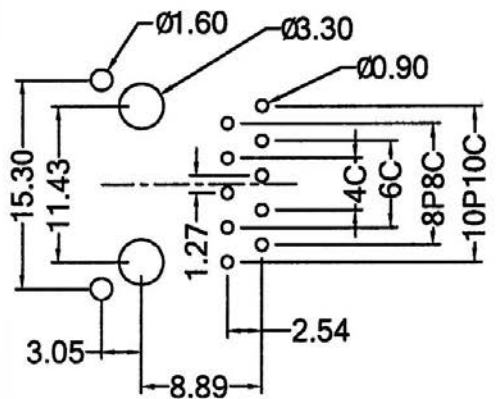
Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C. Board Layout (TOP VIEW) **MJ99**



No. of Positions	No. of Contacts	A
6P	2C/4C/6C	9.90
8P	4C/6C/8C	11.95
10P	10C	11.95



Recommended P.C. Board Layout (TOP VIEW) **MJ89**

ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XX}{2} \frac{X}{3} B$

- TYPE OF JACK:
 "89" F3.05
 "99" R3.05
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

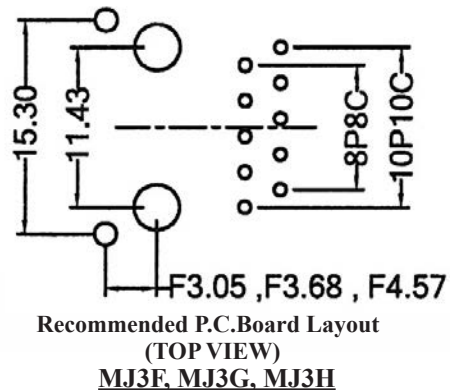
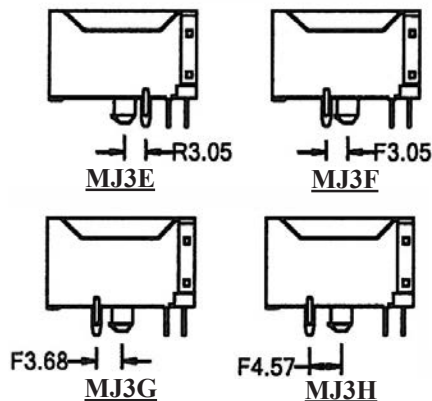
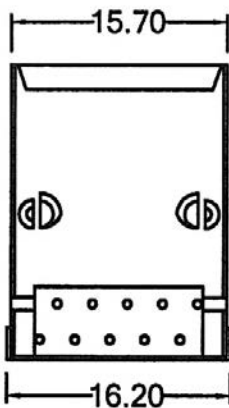
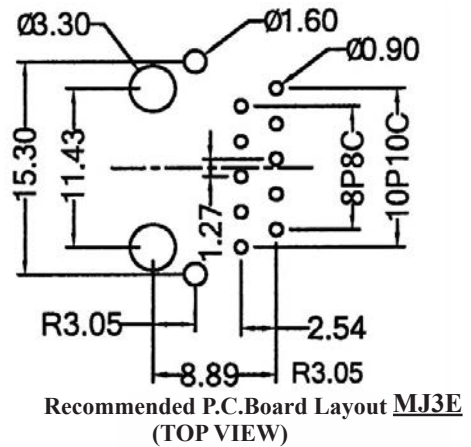
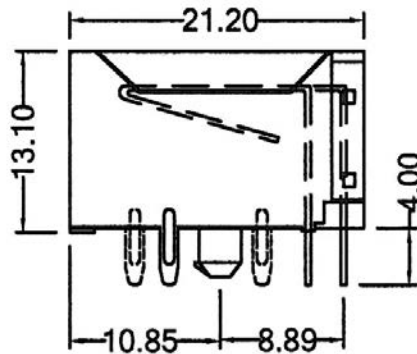
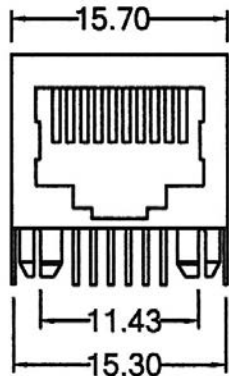
SIDE ENTRY MODULAR PCB JACK 8P+10P PROFILE=13.10MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B

- PANEL STOP OPTION:
 "3E" R3.05 TYPE
 "3F" F3.05 TYPE
 "3G" F3.68TYPE
 "3H" F4.57 TYPE
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 6P+8P+10P PROFILE=13.10MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

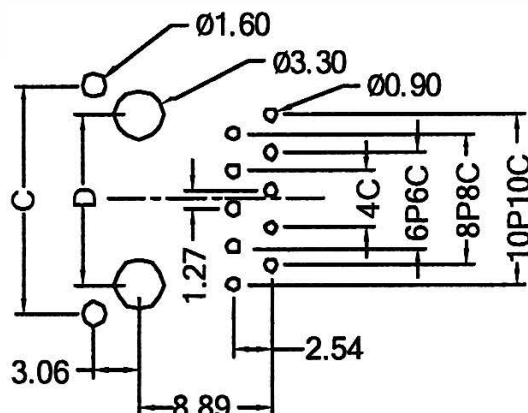
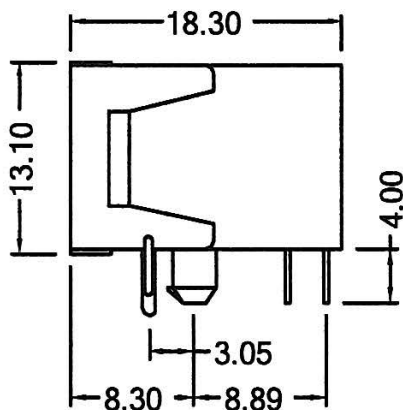
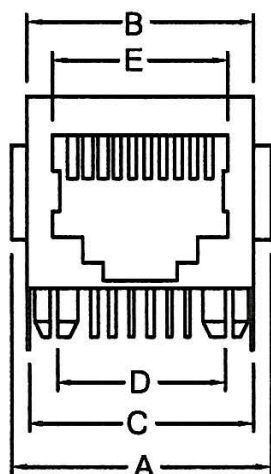
Color: Black

Spring Wire: Phosphor Bronze

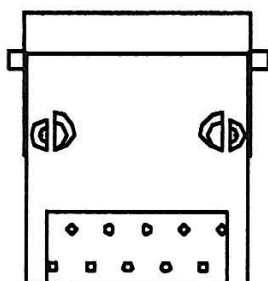
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)



No. of Positions	No. of Contacts	A	B	C	D	E
6P	2C/4C/6C	15.60	13.65	13.40	10.16	9.90
8P	8C	17.50	15.65	15.40	11.43	11.85
10P	10C	17.50	15.65	15.40	11.43	11.85

ORDERING INFORMATION:

P/N MJ80 - $\frac{X}{1} \frac{X}{2} B$

1. NO. OF POSITIONS & CONTACTS:

- "66" 6P6C
- "64" 6P4C
- "88" 8P8C
- "00" 10P10C

2. CONTACT FINISH:

- "A" 6 MICROINCH GOLD
- "B" 15 MICROINCH GOLD
- "C" 30 MICROINCH GOLD
- "D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

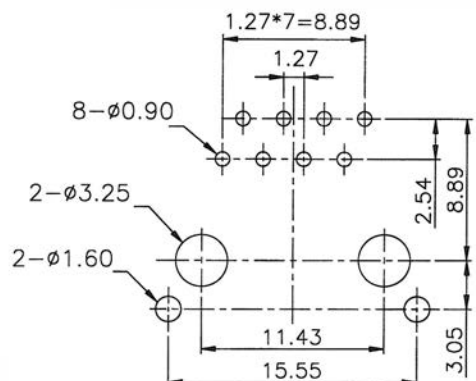
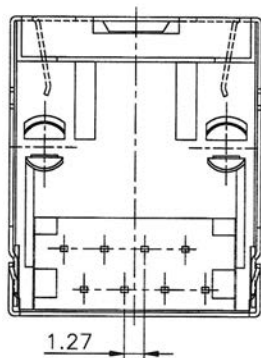
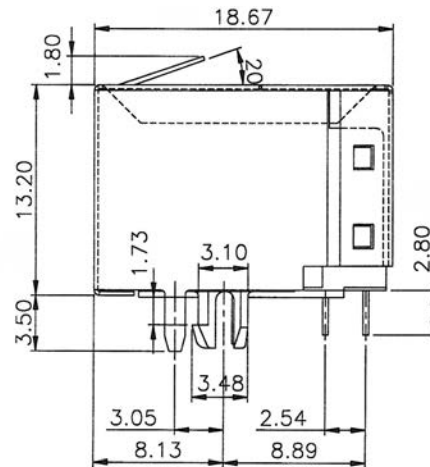
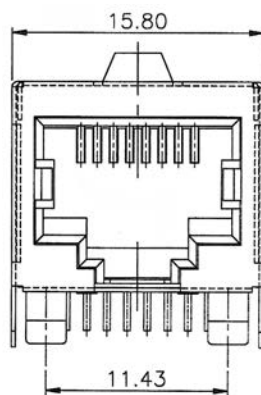
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 1 V - $\frac{x x x}{1 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

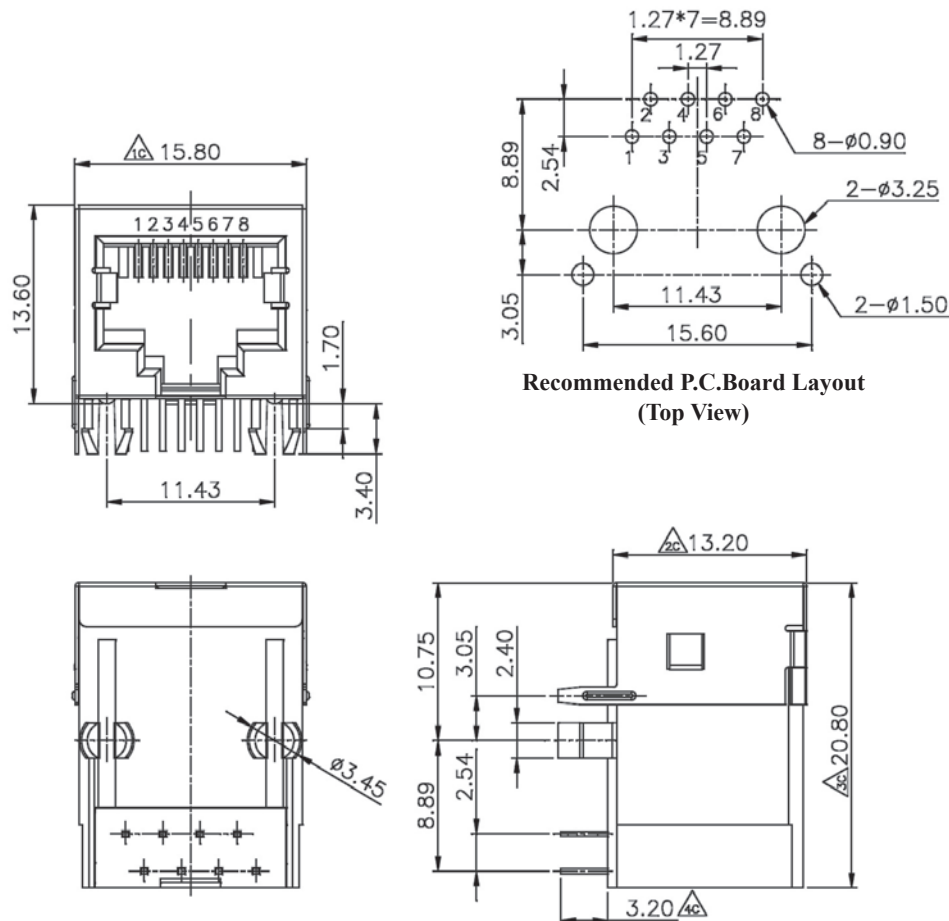
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.20MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J T V - $\frac{x \times x}{1 \ 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

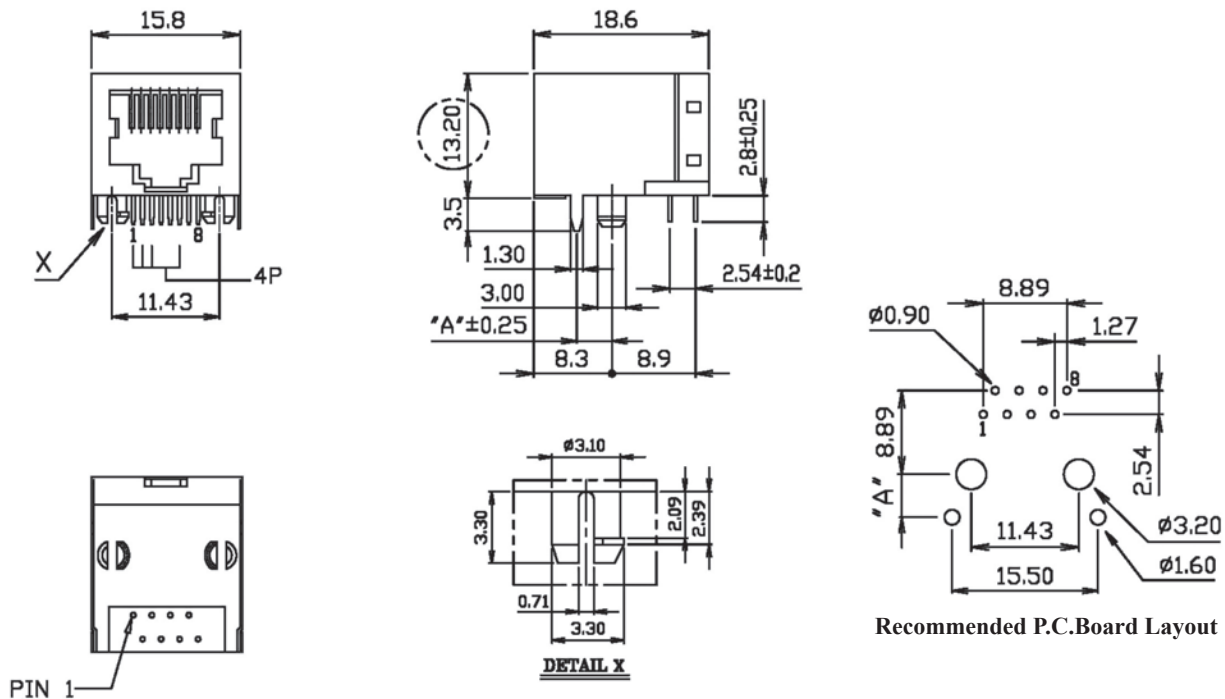
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{HT}{I}$ - $\frac{88}{2}$ x $\frac{B}{34}$

1. MODULAR JACK TYPE:
"HT" DIM.A = 3.05MM
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

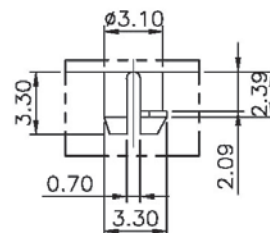
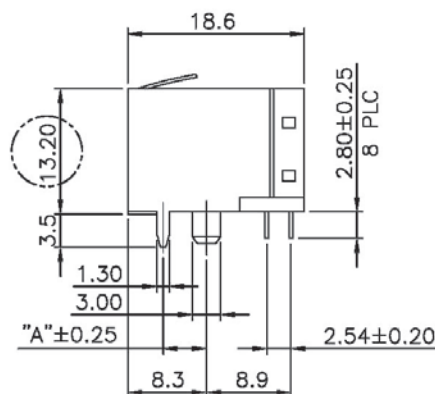
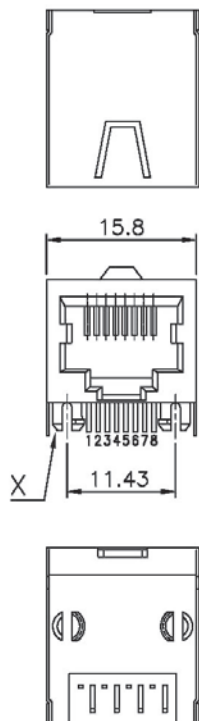
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

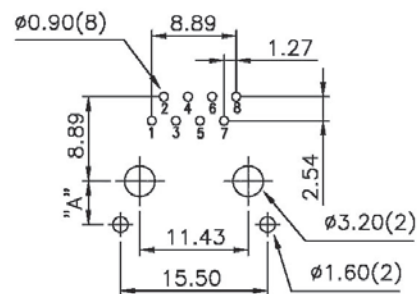
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



DETAIL X



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{HN}{I}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{B}{4}$

1. MODULAR JACK TYPE:
"HN" DIM.A = 3.05MM
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEFORE PEG

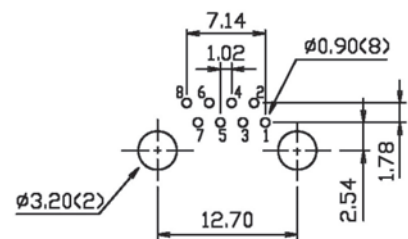
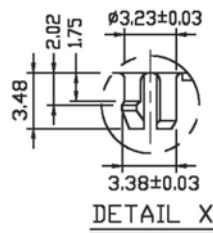
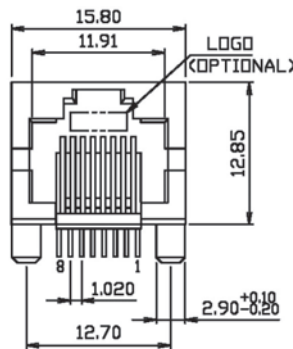
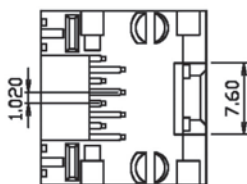
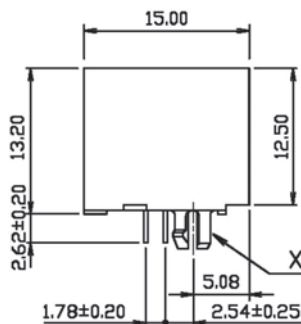
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J HR - 88 x B
1 2 3 4

1. MODULAR JACK TYPE:
"HR" WITH ROUND PINS
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

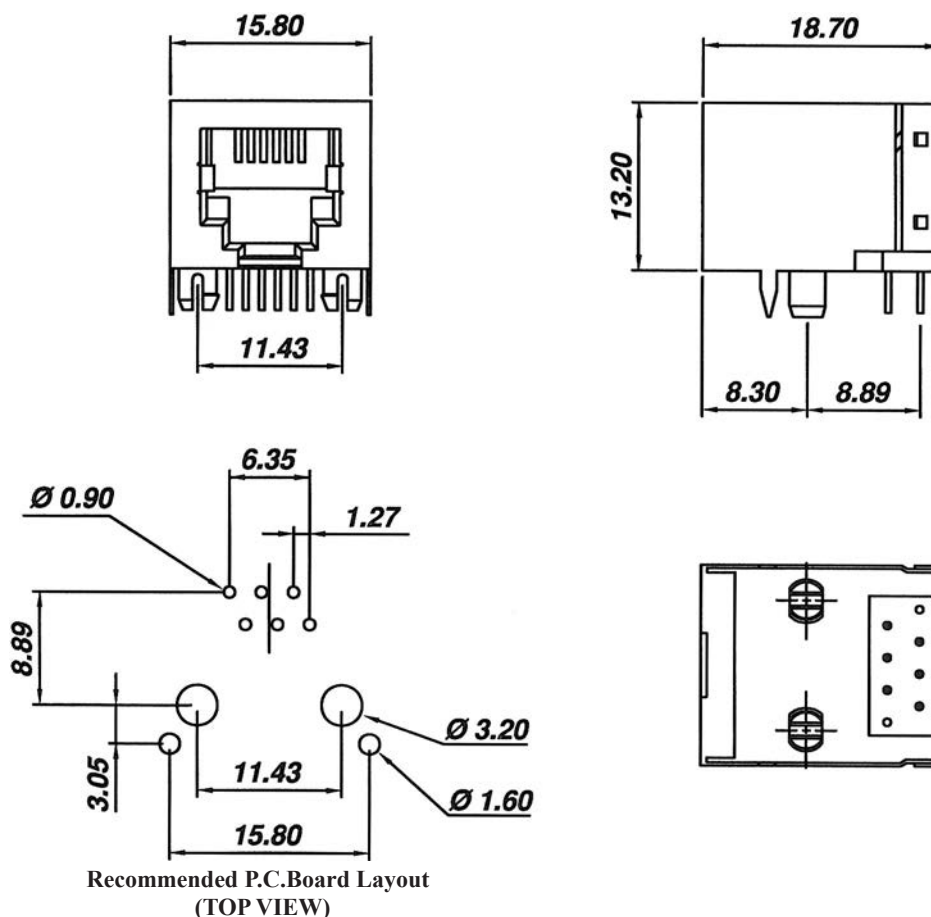
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S L - $\frac{x x x}{1 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY DATA LINK MODULAR PCB JACK 4P PROFILE=13.20MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

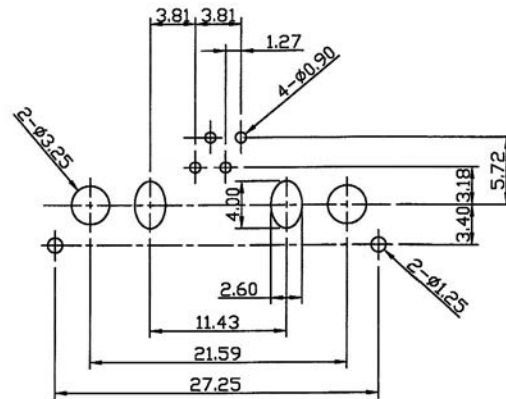
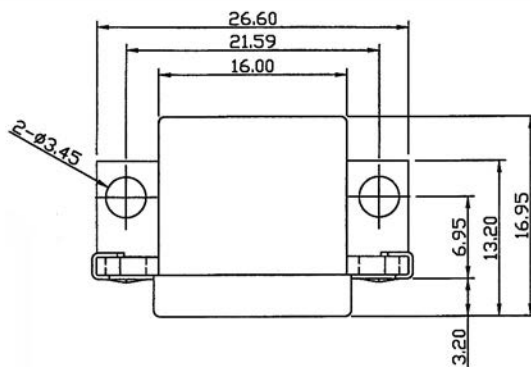
Color: Black

Spring Wire: Phosphor Bronze

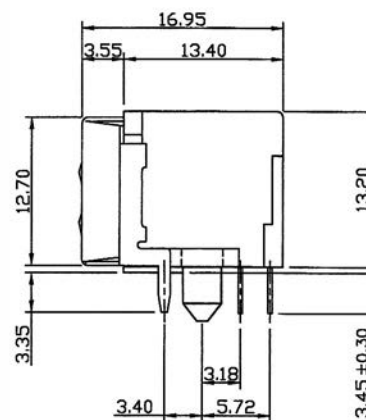
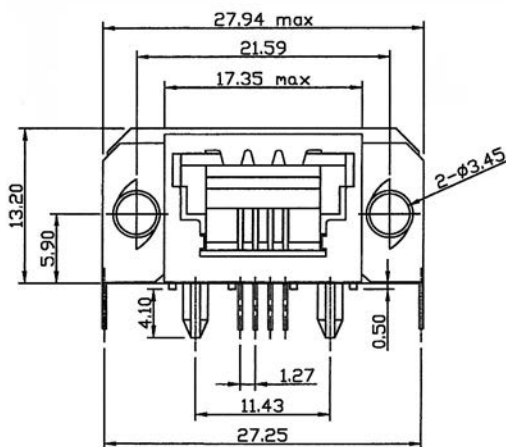
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJ4F - $\frac{44}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

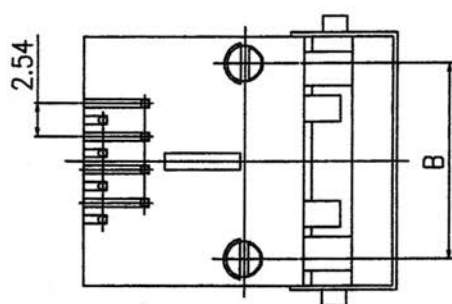
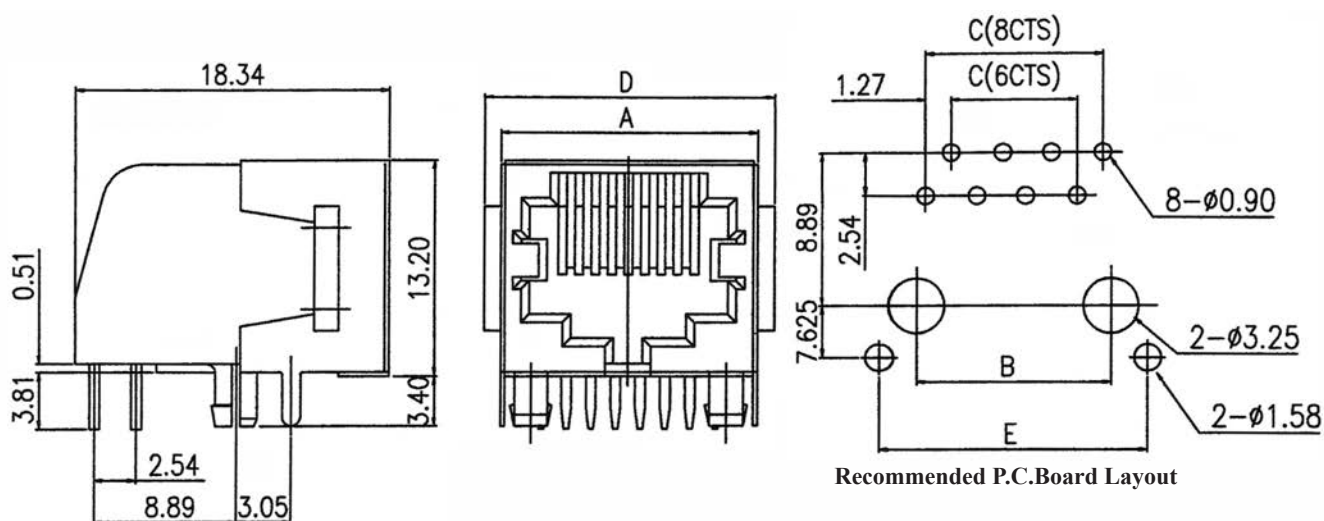
SIDE ENTRY MODULAR PCB JACK 6P+8P PROFILE=13.20MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



No. of Positions	Dimensions				
	A	B	C	D	E
06	13.83	10.16	6.35	15.74	13.58
08	15.86	11.43	8.89	17.78	15.57

ORDERING INFORMATION:

P/N M J 1 5 - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C
 "88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

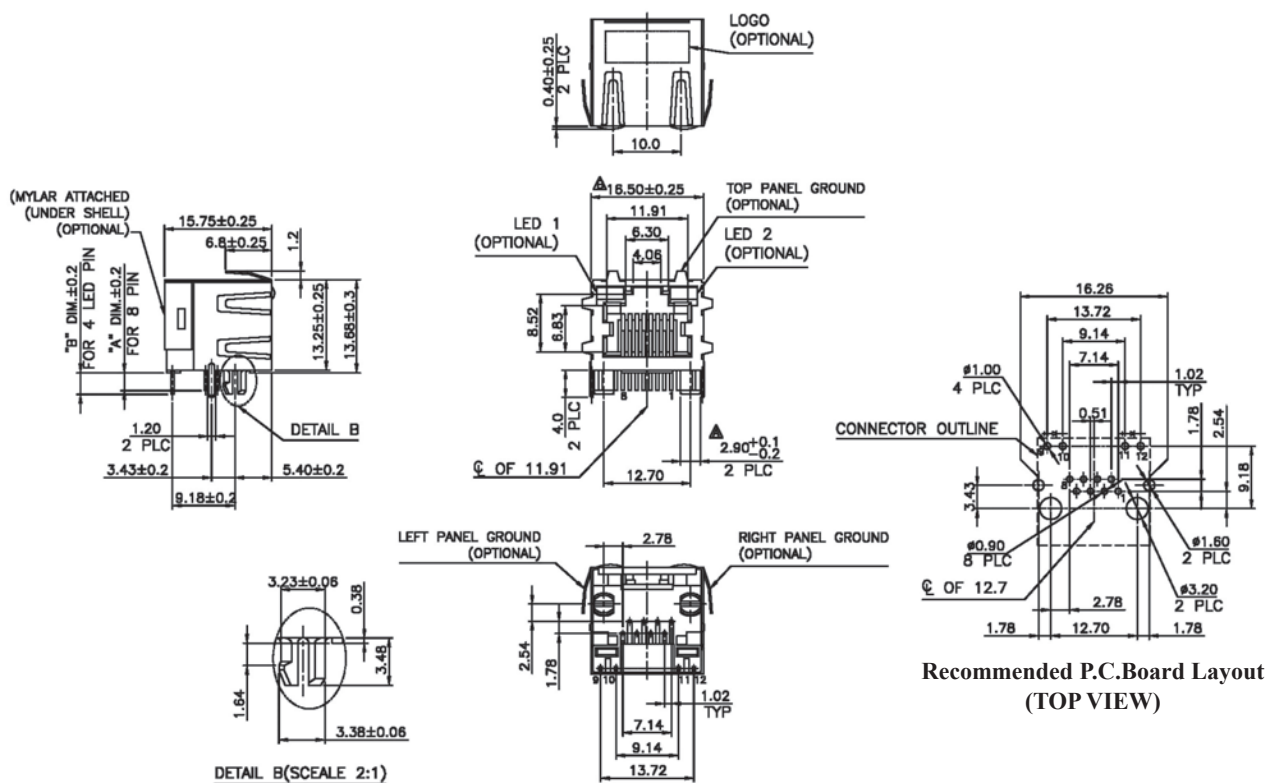
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.25MM (FULLY SHIELDED)

SPECIFICATIONS

- Insulation Resistance: 500MΩ Min.
- Contact Resistance: 20mΩ Max.
- Rating Current: 1.5A Max.
- Rating Voltage: 120V AC.
- Dielectric Voltage: 1000 Vrms 60 Sec. Min.
- Temperature Range: -40°C / +85°C
- Durability: 500 Mating cycles Min.

MATERIALS

- Housing: PBT Glass Filled (UL 94V-0)
- Soldering Temperature: 235°C
- Color: Black
- Spring Wire: Phosphor Bronze
Gold plating Over Nickel
- Shield: Brass plating Nickel Alloy
- *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - 88 $\frac{X}{2}$ B $\frac{XX}{345}$

- MODULAR JACK TYPE:
"JE" WITH TOP/RIGHT/LEFT SIDE TABS
"JF" WITH RIGHT/LEFT TABS
"JG" WITH TOP SIDE TABS
"JH" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1: GREEN & LED2: GREEN
"NY" LED1: GREEN & LED2: YELLOW
"YN" LED1: YELLOW & LED2: GREEN
"YY" LED1: YELLOW & LED2: YELLOW

NOTE: OTHER LED COLORS UPON REQUEST!

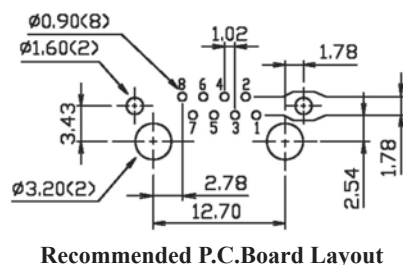
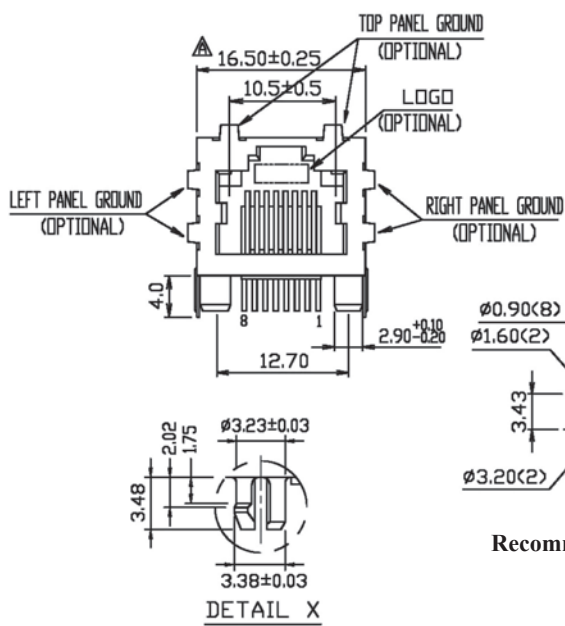
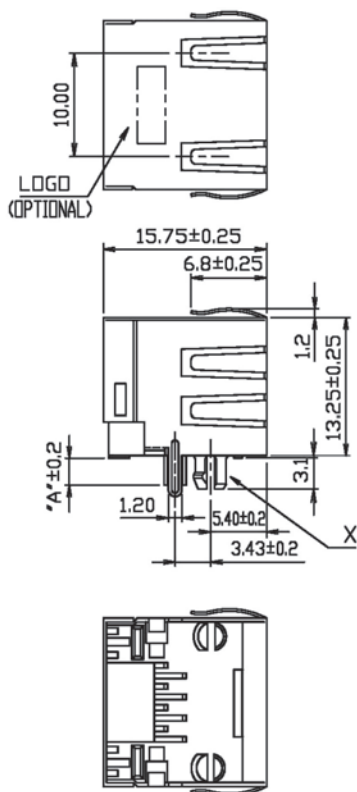
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P W/O LED PROFILE=13.25MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B

- MODULAR JACK TYPE:
 "JA" WITH TOP/RIGHT/LEFT SIDE TABS
 "JB" WITH RIGHT/LEFT TABS
 "JC" WITH TOP SIDE TABS
 "JD" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

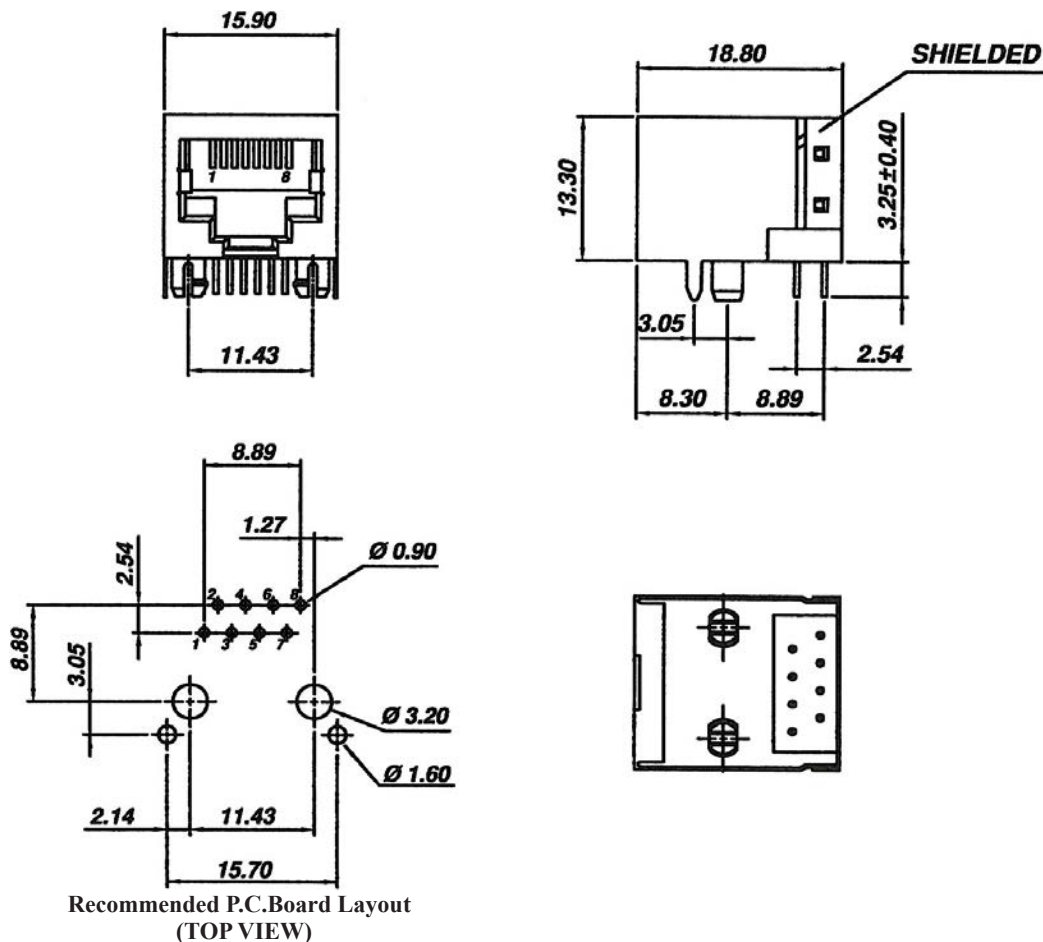
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S L - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJSLHT-88xB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

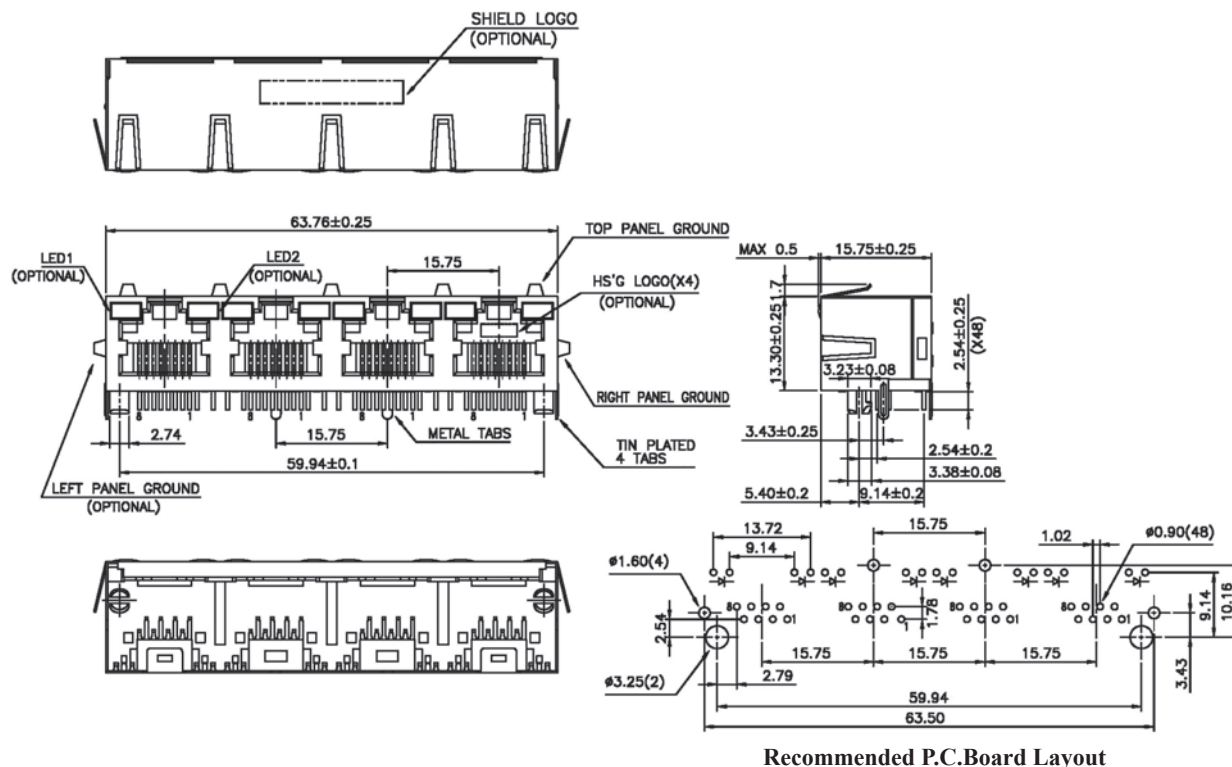
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°c / +85°c
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°c
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - 88 $\frac{x}{2}$ B $\frac{xx}{3}$ $\frac{04}{5}$ $\frac{6}{6}$

- MODULAR JACK TYPE:
 "BE" WITH TOP/RIGHT/LEFT SIDE TABS
 "BF" WITH RIGHT/LEFT TABS
 "BG" WITH TOP SIDE TABS
 "BH" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- COLORS OF LED:
 "NN" LED1/2 = GREEN/GREEN
 "NY" LED1/2 = GREEN/YELLOW
 "YN" LED1/2 = YELLOW/GREEN
 "YY" LED1/2 = YELLOW/YELLOW
 "XX" WITHOUT LED
- NO. OF PORTS:
 04

NOTE: OTHER LED COLORS UPON REQUEST!

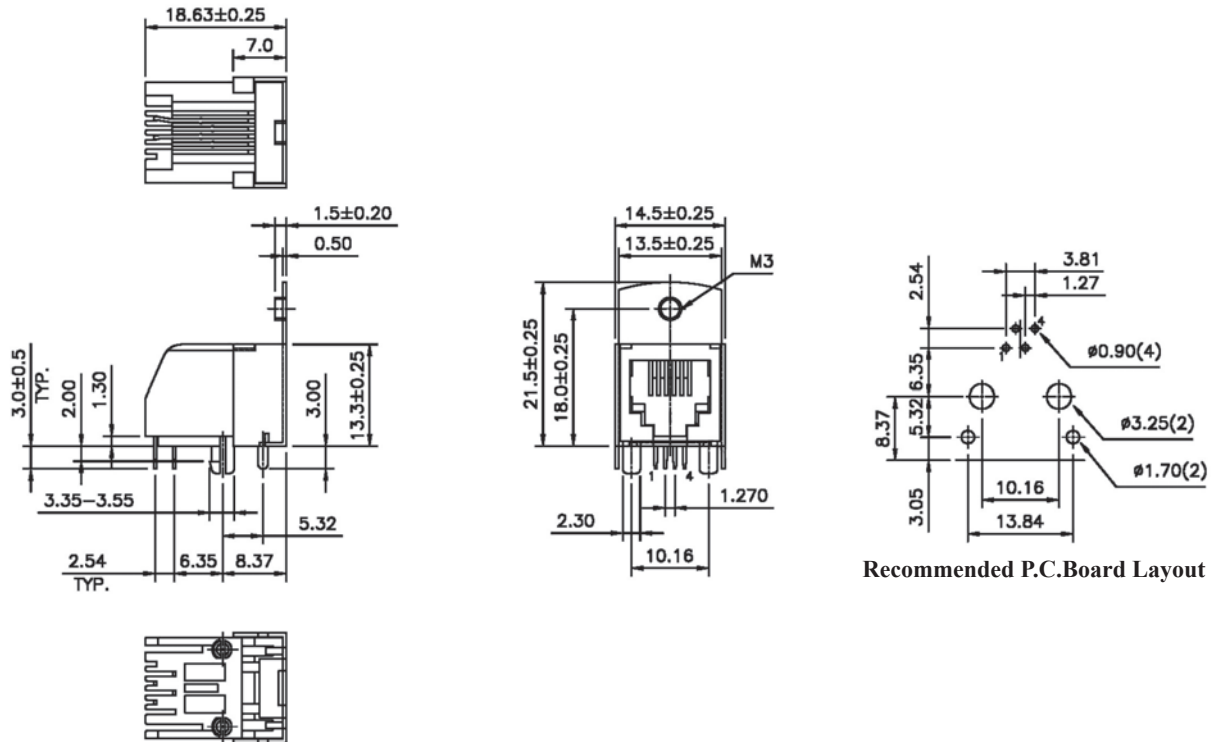
SIDE ENTRY MODULAR PCB JACK 4P PROFILE=13.30MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N $\frac{M}{1} \frac{J}{2} \frac{H}{3} \frac{W}{4} - 44 \times \frac{B}{34}$

1. MODULAR JACK TYPE:
"HW" WITH M3 SCREW HOLE
2. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

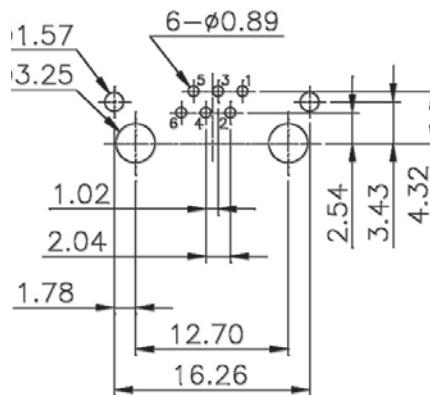
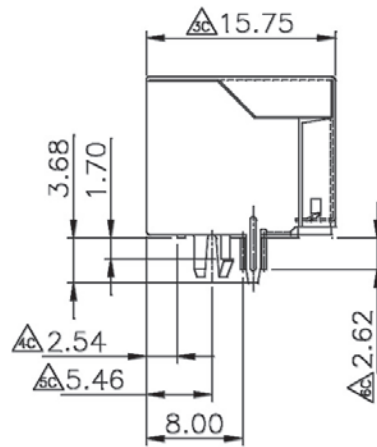
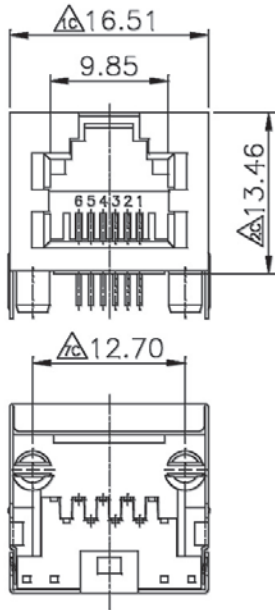
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 2 A - $\frac{x}{1} \frac{x}{2} B$

- NO. OF POSITIONS & CONTACTS:
 "64" 6P4C
 "66" 6P6C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

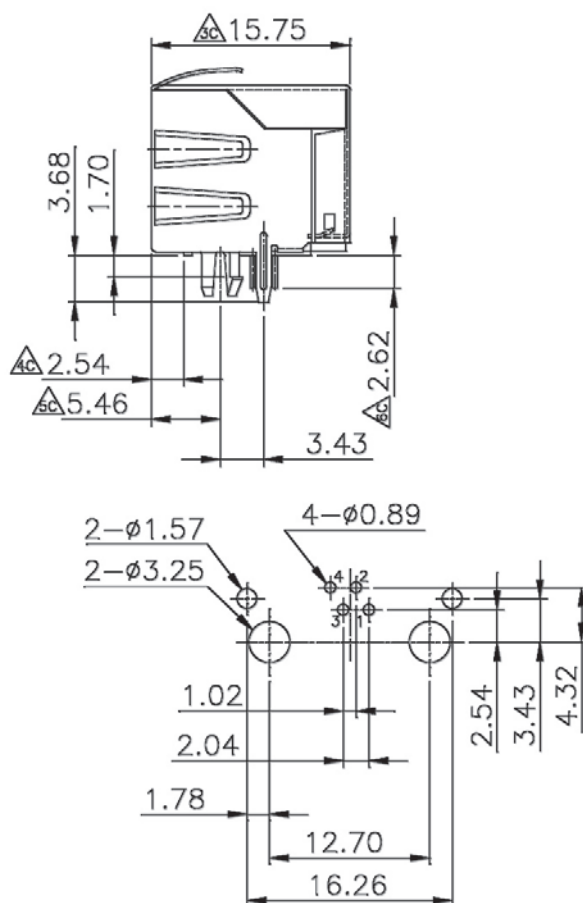
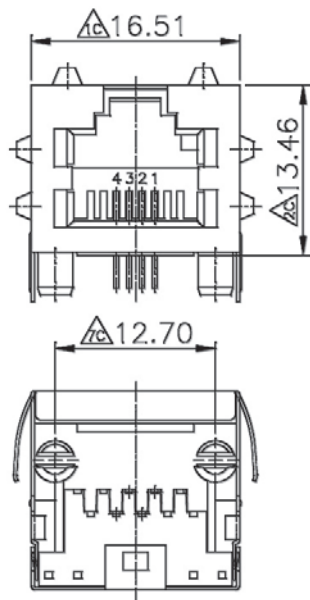
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 2 D - $\frac{x x x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"64" 6P4C

"66" 6P6C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

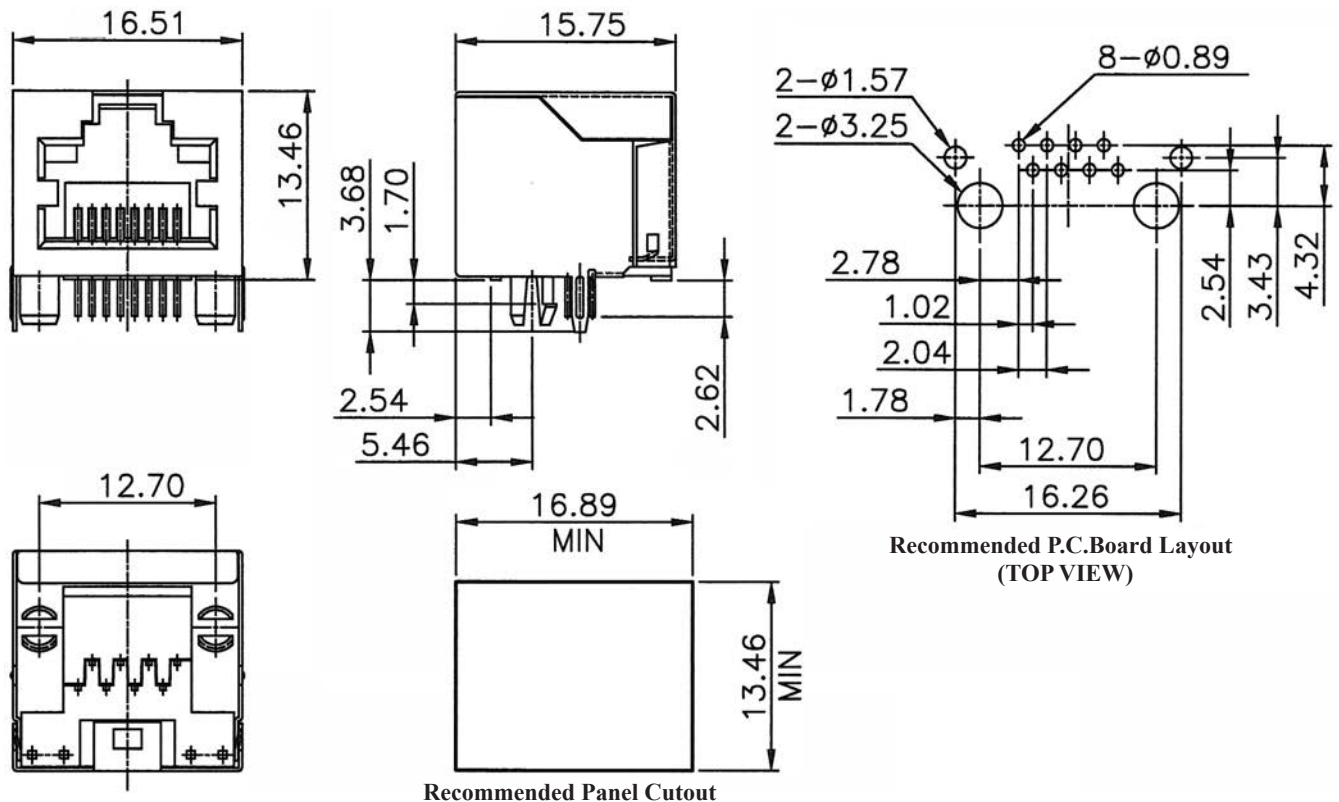
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 A - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

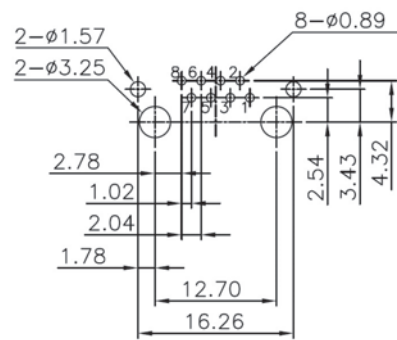
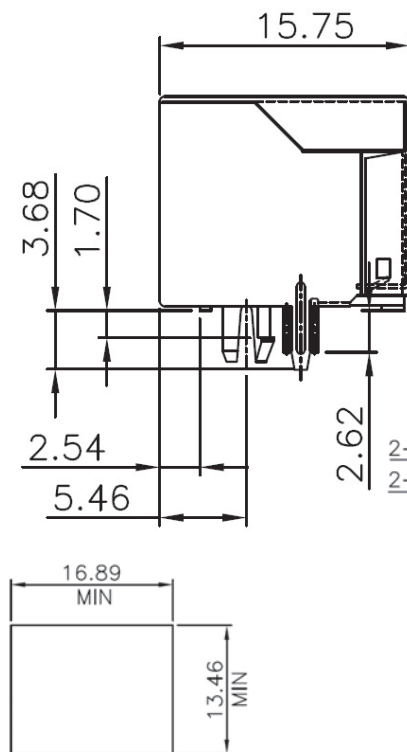
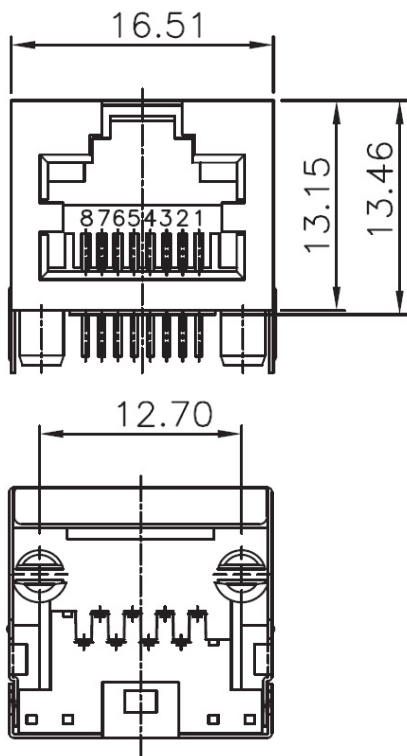
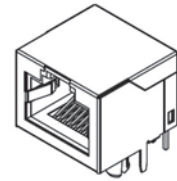
Plastic Housing: Engineering Thermoplastic

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



Recommended Panel Cutout

Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ $\frac{2AJ}{1}$ - $\frac{88}{2}$ x $\frac{B}{3}$

1. MODULAR JACK TYPE:
"2AJ" UP LATCH TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: IT CAN BE USED FOR REPLACING P/N MJ2A-88xB.

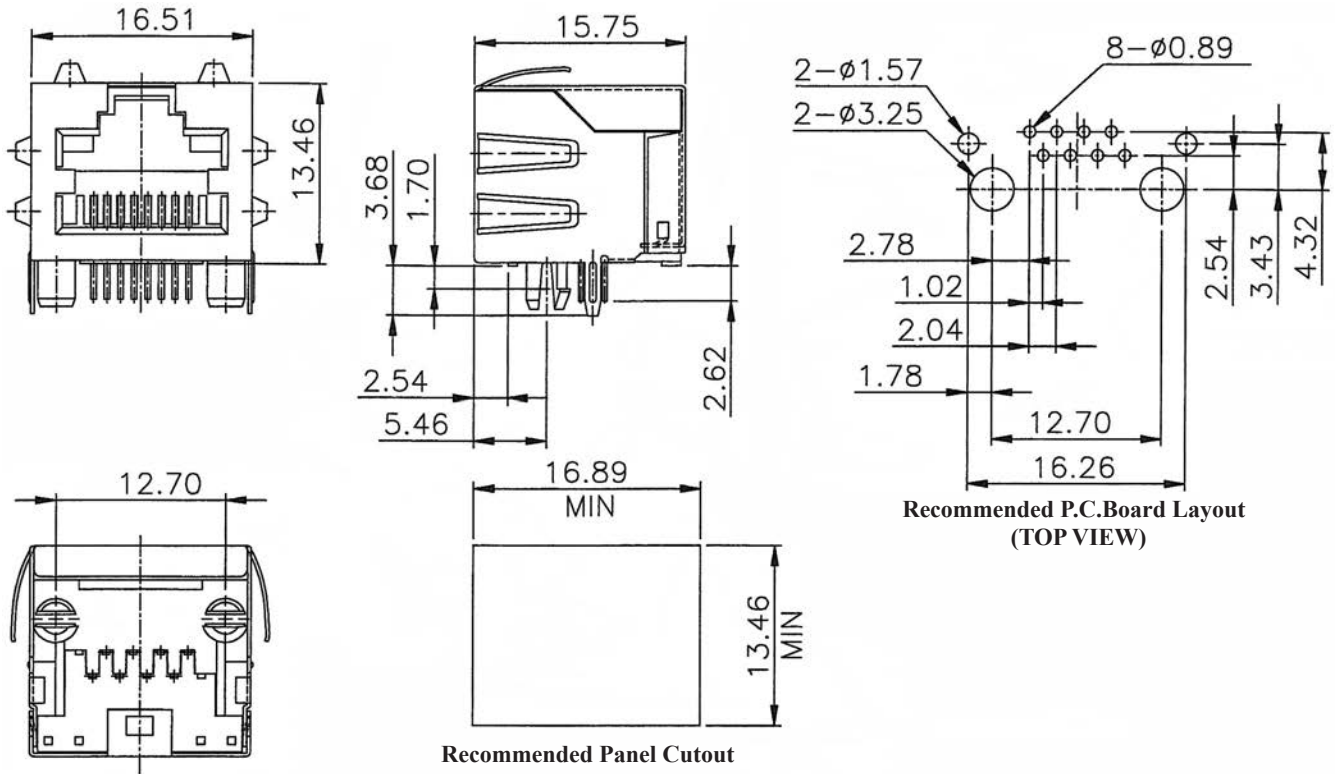
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500M Ω Min.
Contact Resistance: 20m Ω Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 D - $\frac{x x}{1}$ $\frac{x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

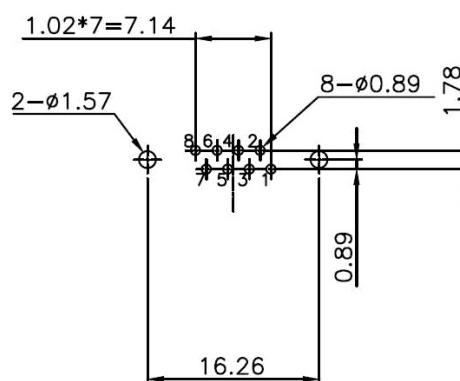
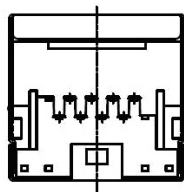
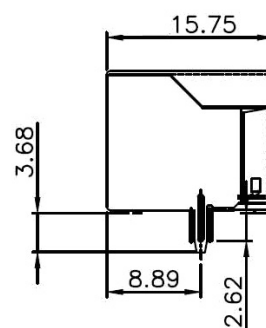
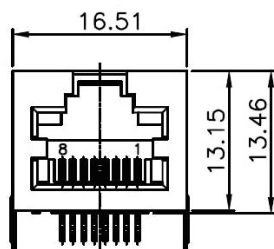
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J 3 X - $\frac{X X X}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

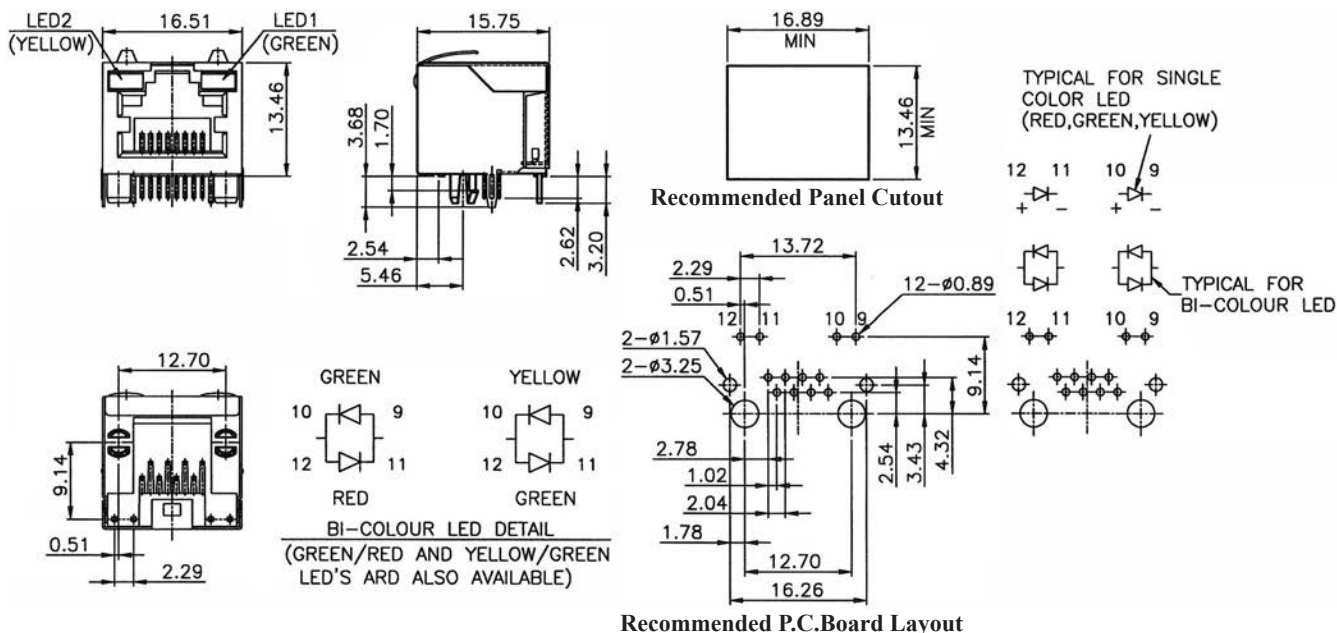
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

- Insulation Resistance:** 500MΩ Min.
- Contact Resistance:** 20mΩ Max.
- Rating Current:** 1.5A Max.
- Rating Voltage:** 120V AC.
- Dielectric Voltage:** 1000 Vrms 60 Sec. Min.
- Temperature Range:** -40°C / +85°C
- Durability:** 500 Mating cycles Min.

MATERIALS

- Housing:** PBT Glass Filled (UL 94V-0)
- Soldering Temperature:** 235°C
- Color:** Black
- Spring Wire:** Phosphor Bronze
Gold plating Over Nickel
- Shield:** Brass plating Nickel Alloy
- *RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N **M J 3 A - 8 8 x B x x 0 1**
1 2 3 4 5

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
01

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

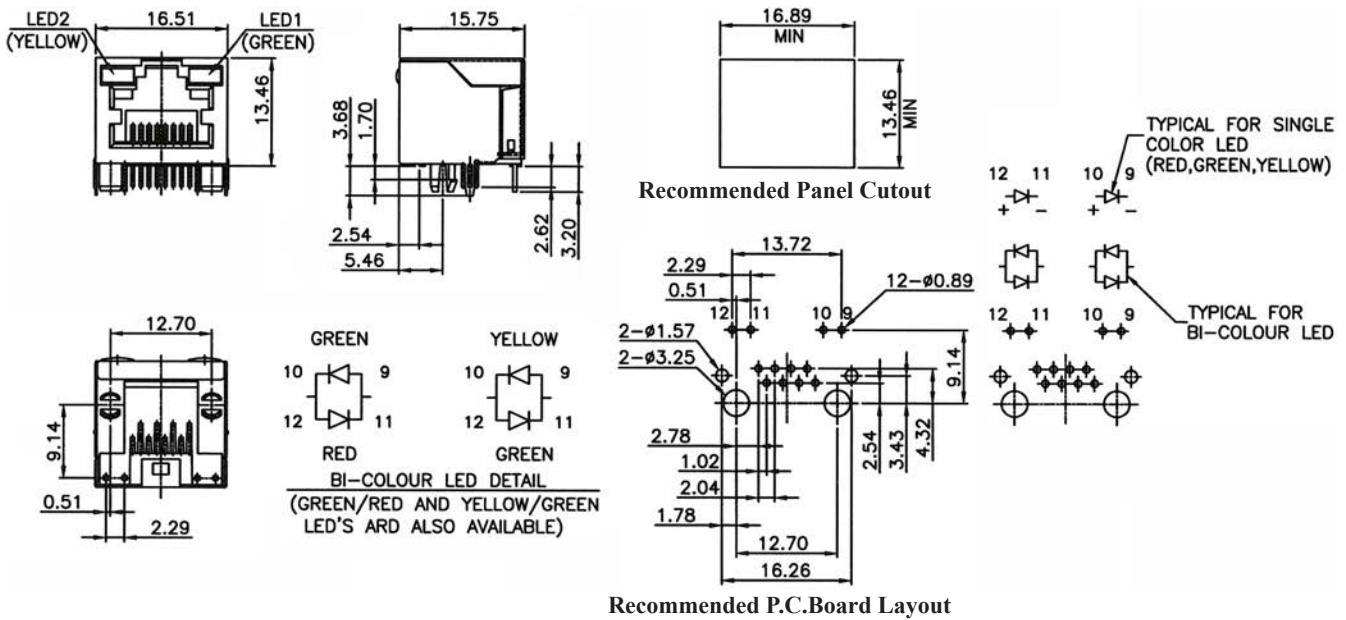
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 3 B - $\frac{88}{1} \times \frac{B}{2} \times \frac{01}{345}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
01

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

Plastic Housing: Engineering Thermoplastic

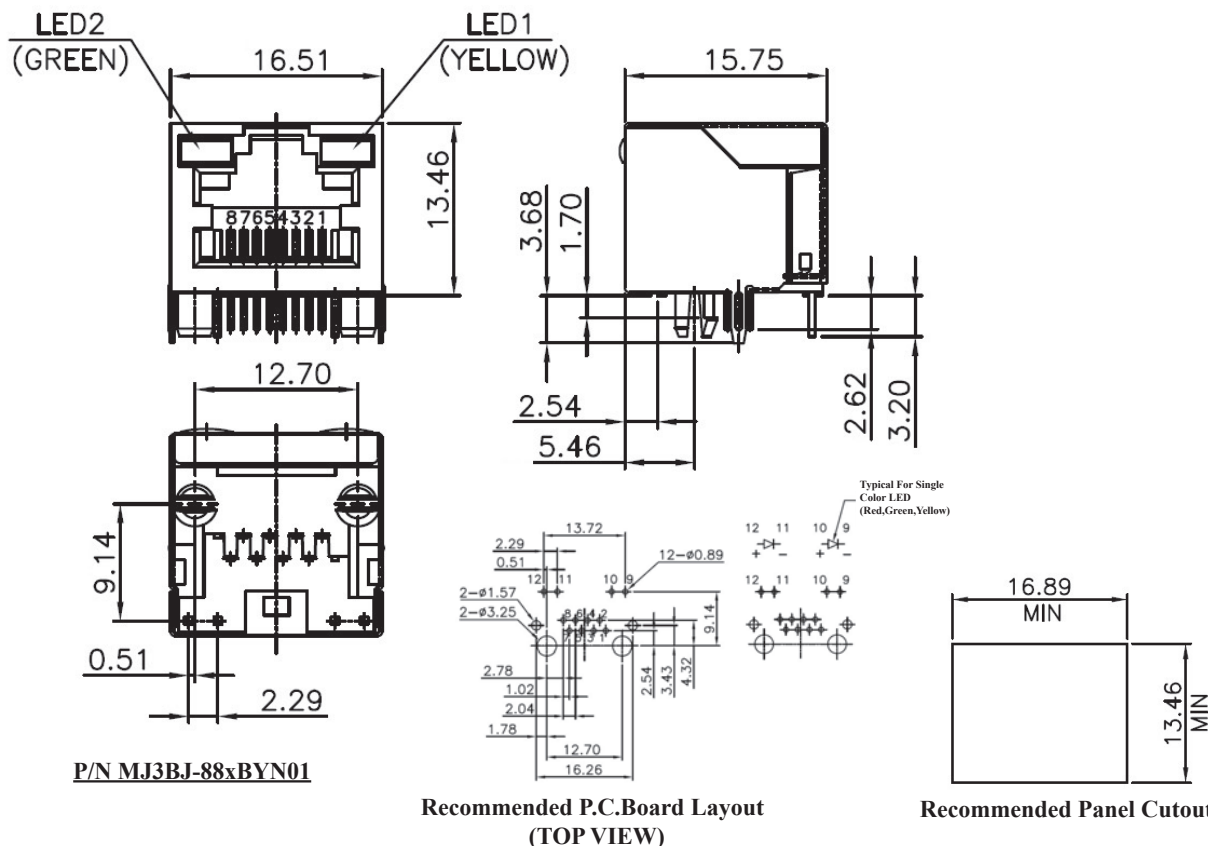
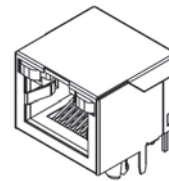
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.v



P/N MJ3BJ-88xBYN01

Recommended P.C.Board Layout
(TOP VIEW)

Recommended Panel Cutout

ORDERING INFORMATION:

P/N M 3 B J - 88 X B X 0 1
1 2 3 4

1. MODULAR JACK TYPE:

"3BJ" WITHOUT PANEL GROUNDS

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

4. COLOR OF LED:

"NN" LED 1/2 = GREEN/GREEN

"NY" LED 1/2 = GREEN/YELLOW

"YN" LED 1/2 = YELLOW/GREEN

"YY" LED 1/2 = YELLOW/YELLOW

"XX" WITHOUT LED

NOTE: LED 1 = RIGHT LED &

LED 2 = LEFT LED

NOTE: IT CAN BE USED FOR REPLACING

P/N MJ3B-88xBxx01.

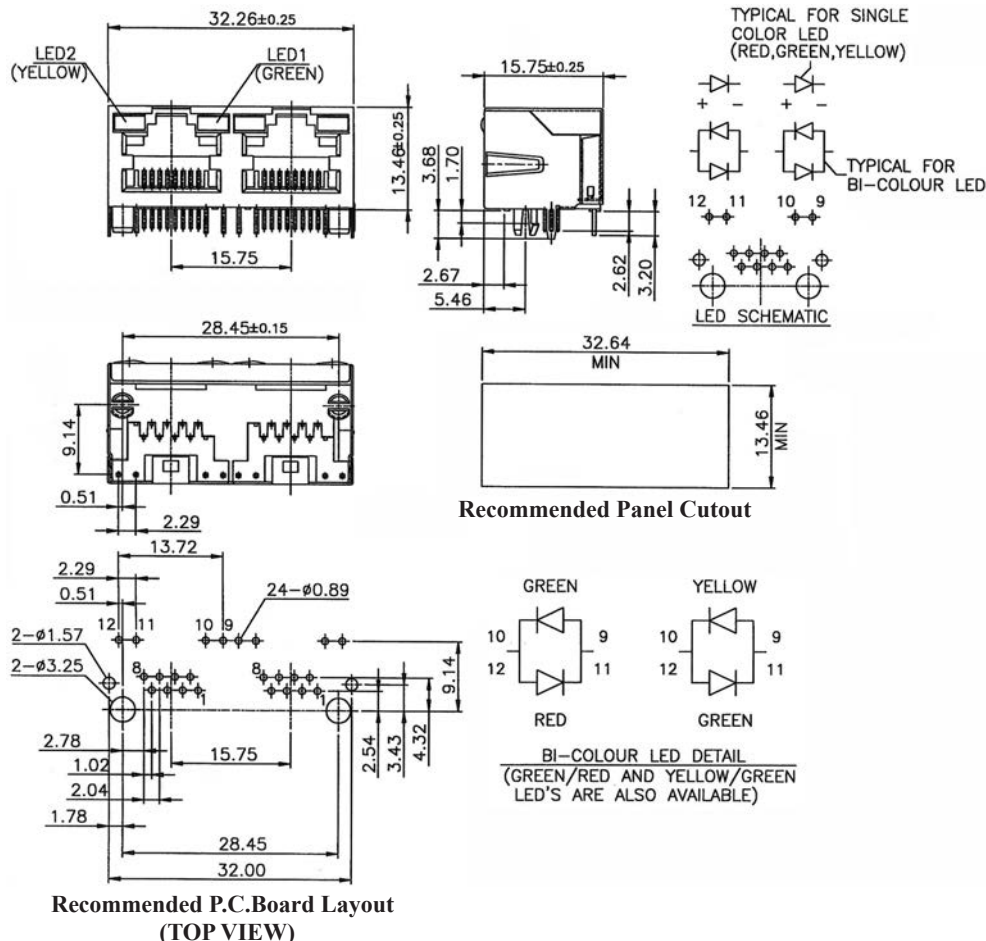
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 3 B - $\frac{88}{1} \times \frac{B}{2} \times \frac{02}{345}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
02

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

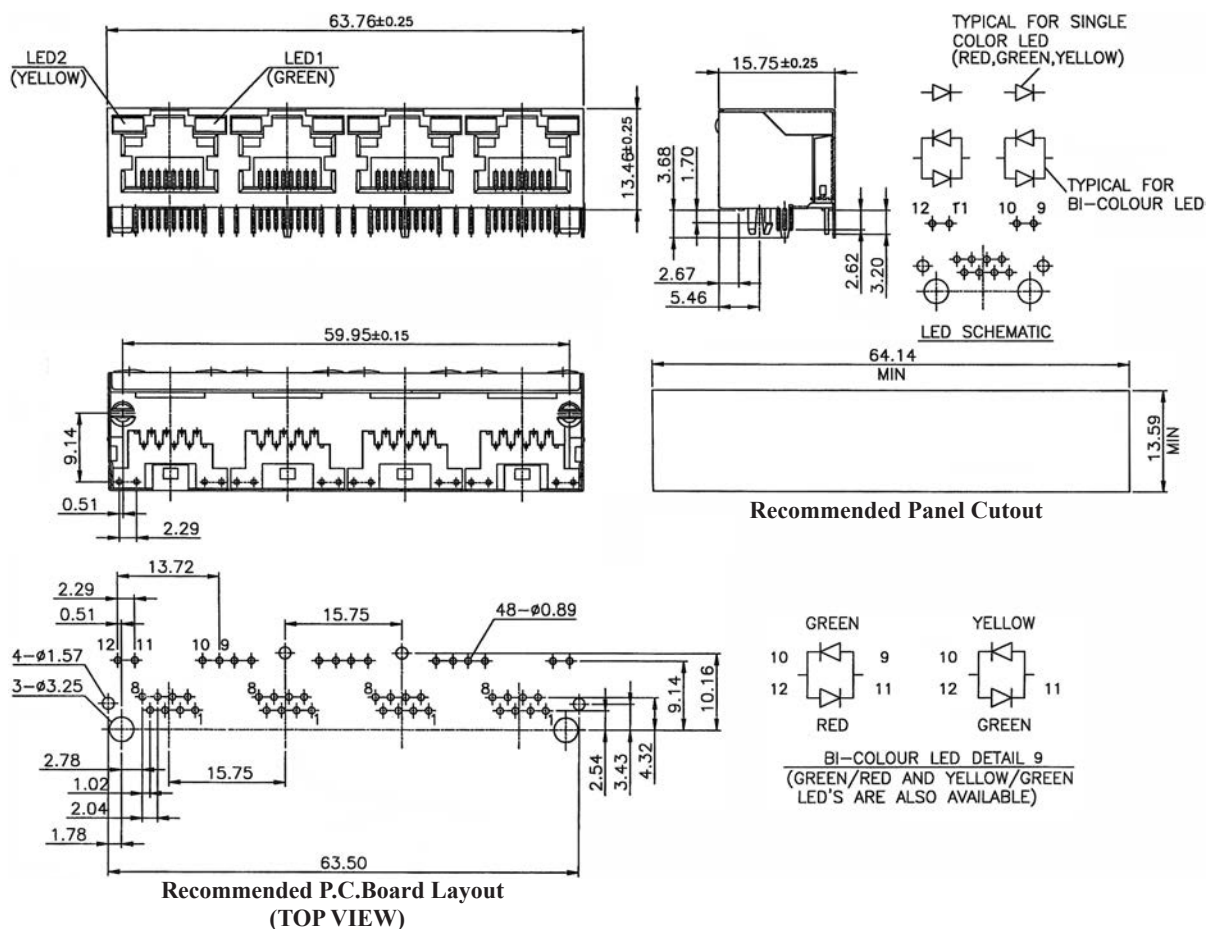
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 3 B - $\frac{88}{1} \times \frac{B}{2} \times \frac{04}{345}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
04

NOTE: P/N MJ3BHT-88xBxx04 FOR HIGH TEMP. VERSION

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

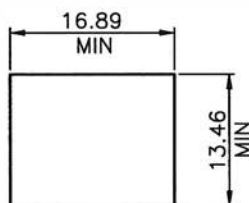
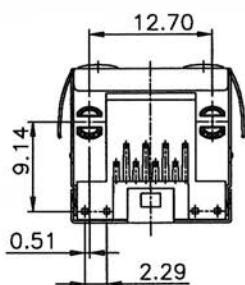
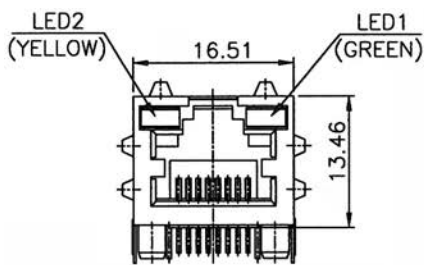
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

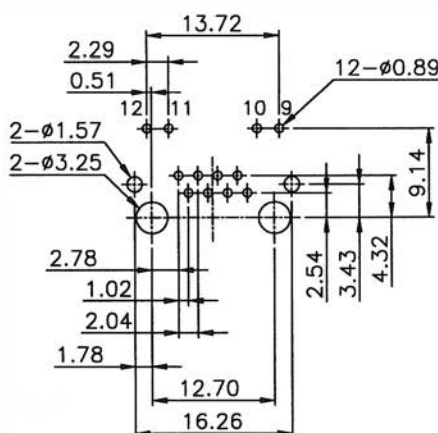
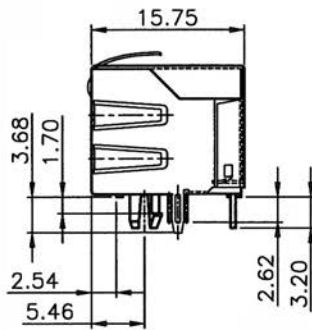
Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

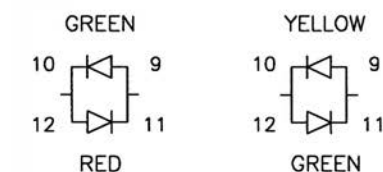
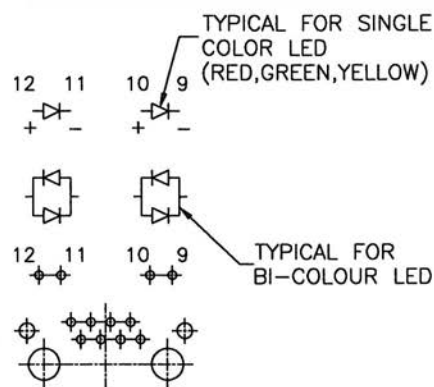
Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended Panel Cutout



Recommended P.C.Board Layout



BI-COLOUR LED DETAIL
 (GREEN/RED AND YELLOW/GREEN LED'S AND ALSO AVAILABLE)

ORDERING INFORMATION:

P/N M J 2 T - $\frac{88}{1} \times \frac{B}{2} \times \frac{01}{345}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
01

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
 LED 2 = LEFT LED

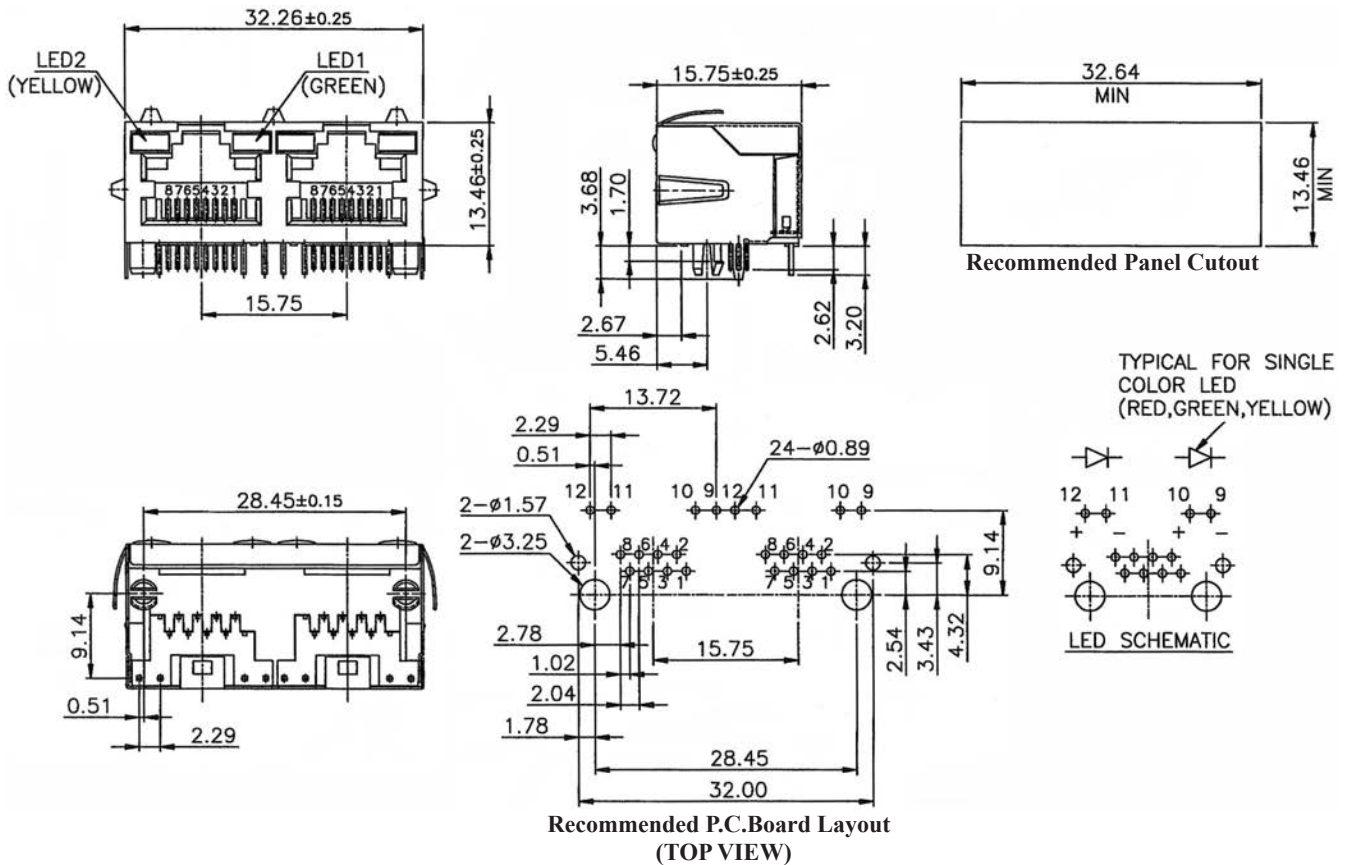
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

- Insulation Resistance: 500MΩ Min.
- Contact Resistance: 20mΩ Max.
- Rating Current: 1.5A Max.
- Rating Voltage: 120V AC.
- Dielectric Voltage: 1000 Vrms 60 Sec. Min.
- Temperature Range: -40°C / +85°C
- Durability: 500 Mating cycles Min.

MATERIALS

- Housing: PBT Glass Filled (UL 94V-0)
- Soldering Temperature: 235°C
- Color: Black
- Spring Wire: Phosphor Bronze
Gold plating Over Nickel
- Shield: Brass plating Nickel Alloy
- *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 T - $\frac{88}{1} \times \frac{B}{2} \times \frac{02}{345}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
02

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

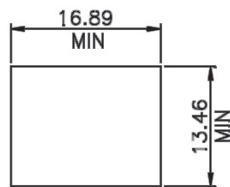
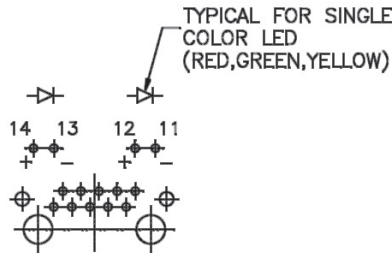
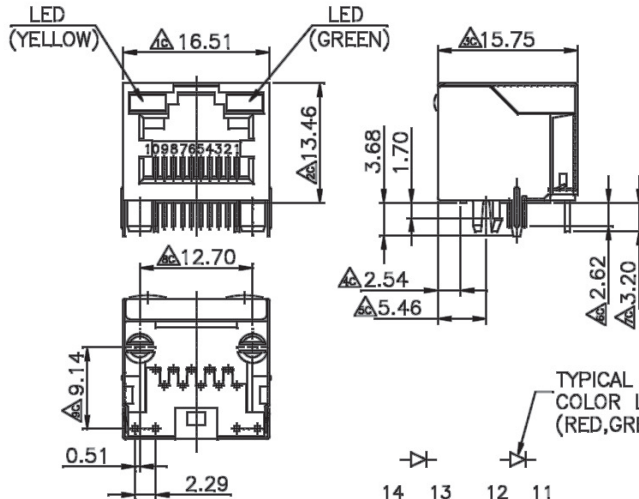
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 10P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

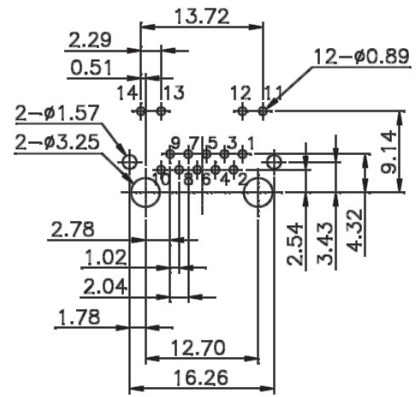
MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



P/N MJ2A-00xBYN

RECOMMENDED PANEL CUTOUT



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N MJ2A - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C
 "08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. COLORS OF LED:

"NN" LEFT/RIGHT LED = GREEN/GREEN
 "NY" LEFT/RIGHT LED = YELLOW/GREEN
 "YN" LEFT/RIGHT LED = GREEN/YELLOW
 "YY" LEFT/RIGHT LED = YELLOW/YELLOW
 "XX" WITHOUT LED

OTHER LED COLORS UPON REQUEST!

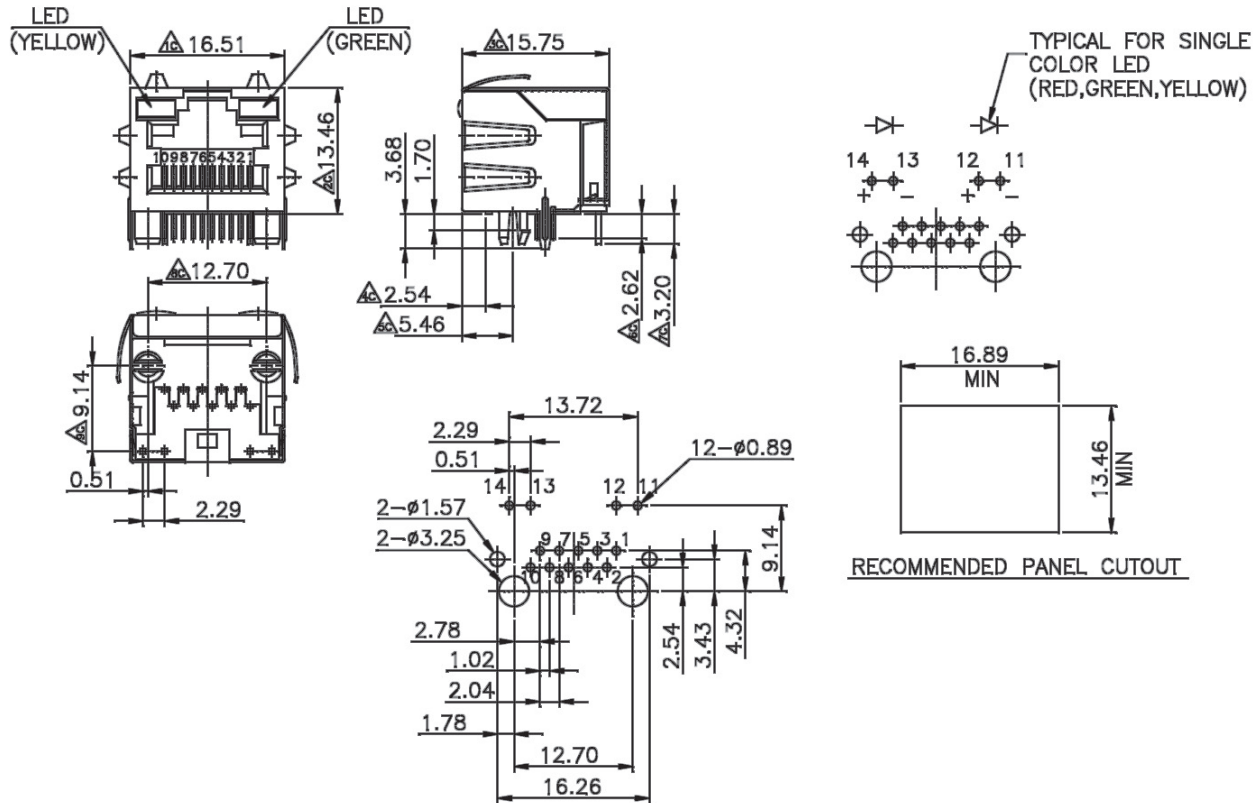
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 10P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



P/N MJ2T-00xBYN

Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N MJ2T - $\frac{xx}{1} \frac{xx}{2} B \frac{xx}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. COLORS OF LED:

"NN" LEFT/RIGHT LED = GREEN/GREEN

"NY" LEFT/RIGHT LED = YELLOW/GREEN

"YN" LEFT/RIGHT LED = GREEN/YELLOW

"YY" LEFT/RIGHT LED = YELLOW/YELLOW

"XX" WITHOUT LED

OTHER LED COLORS UPON REQUEST!

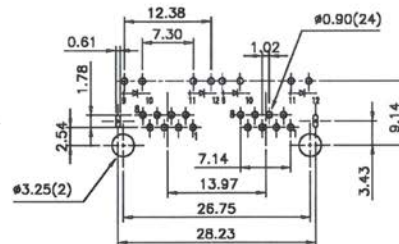
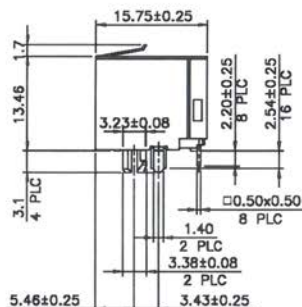
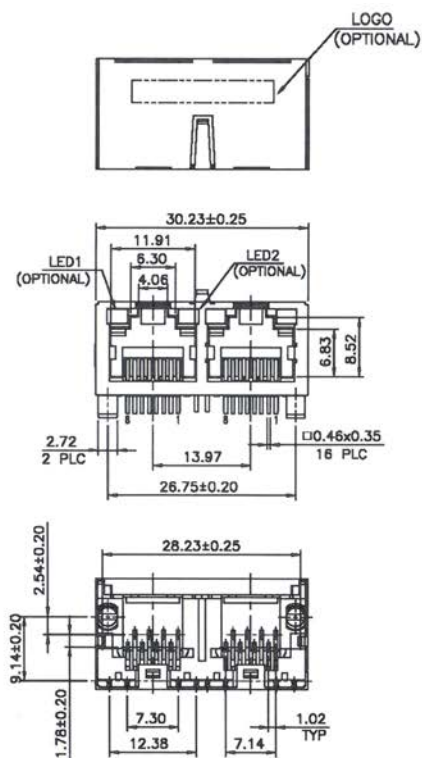
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J H Y - 8 8 x B x x 0 2
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"HY" 2 PORTS WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

Plastic Housing: Engineering Thermoplastic

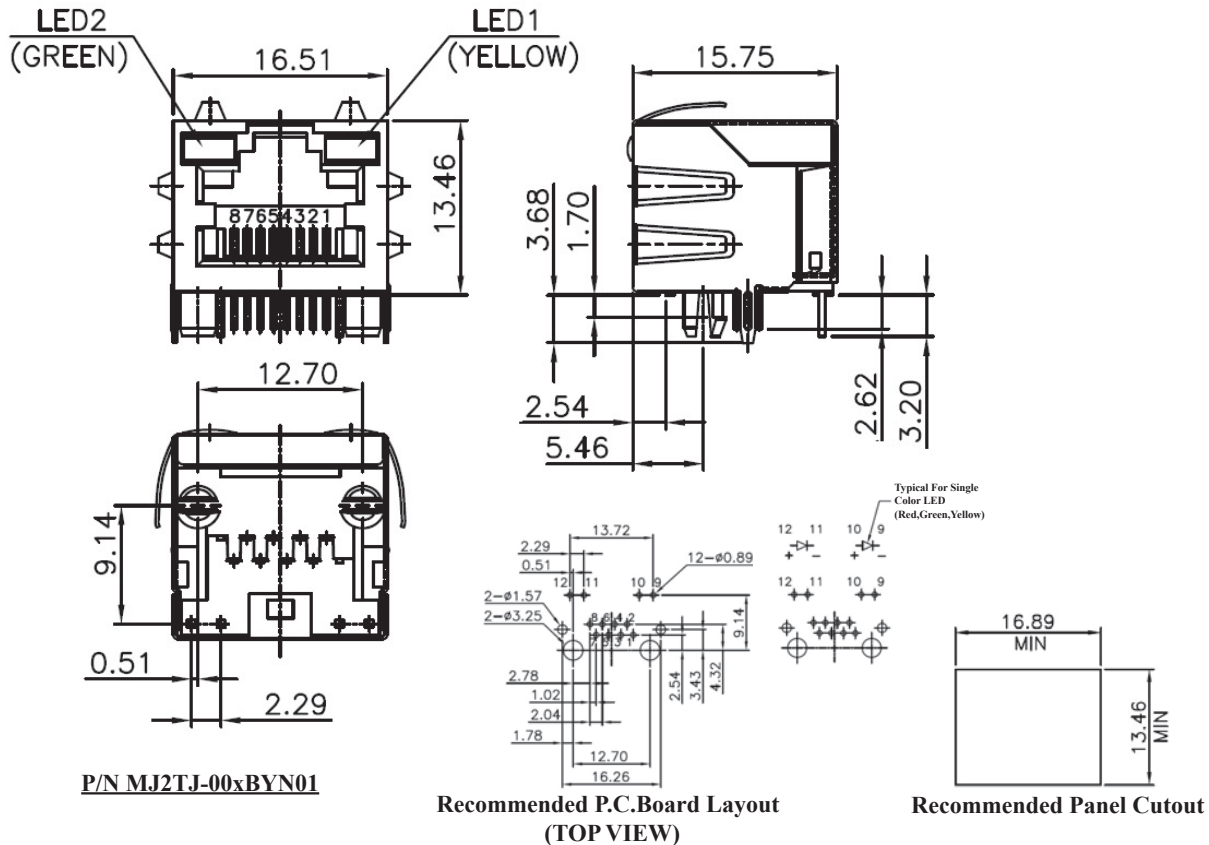
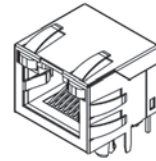
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ 2 T J - 8 8 x B xx 01
1 2 3 4

- MODULAR JACK TYPE:
"2TJ" WITH TOP & SIDE PANEL GROUNDS
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

- COLOR OF LED:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

NOTE: IT CAN BE USED FOR REPLACING P/N MJ2T-88xBxx01.

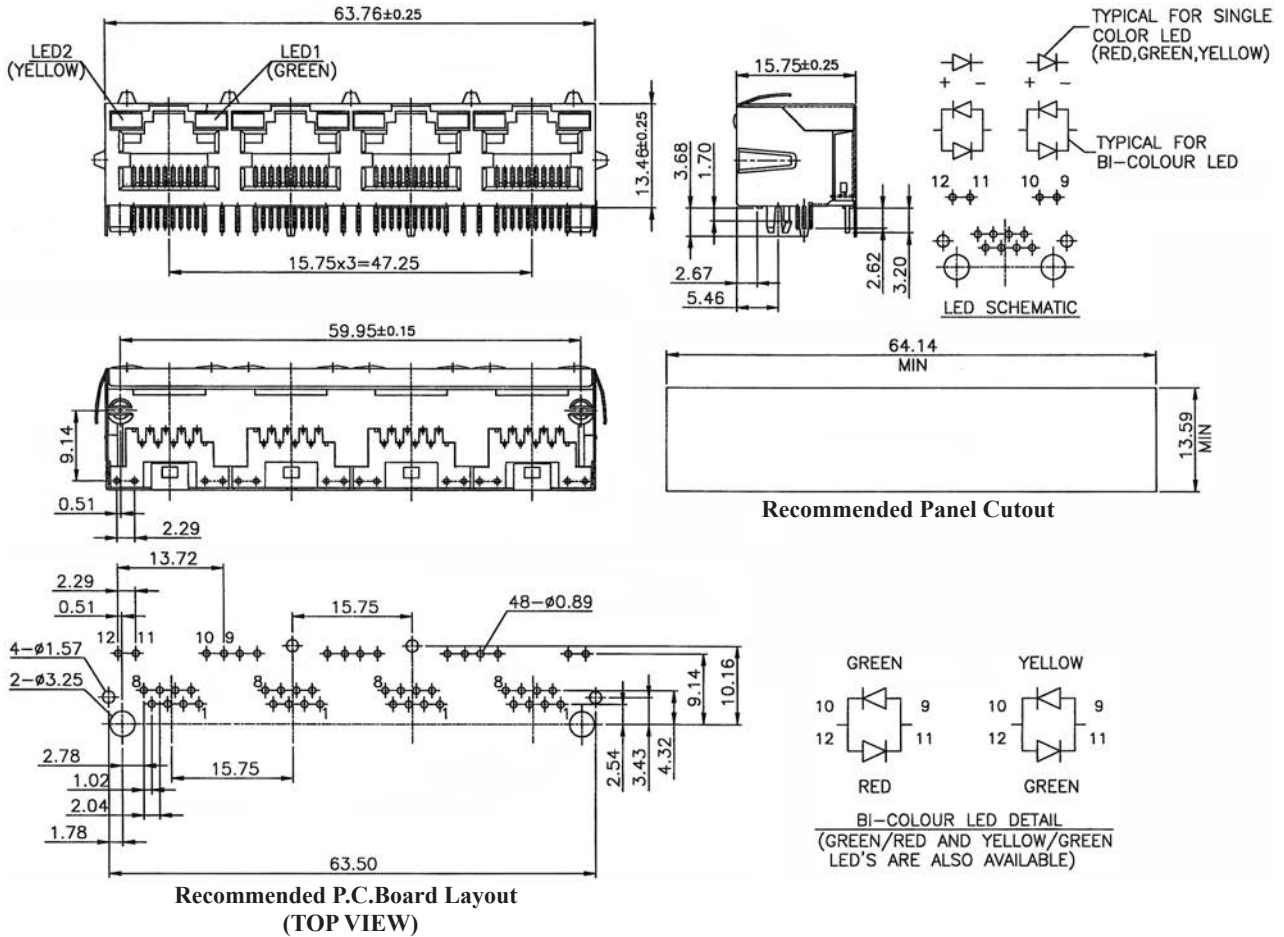
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.46MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ2T - $\frac{88}{1} \times \frac{B}{2} \times \frac{04}{345}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
04

NOTE: P/N MJ2T-88xUxx04 for Color in Blue

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.50MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

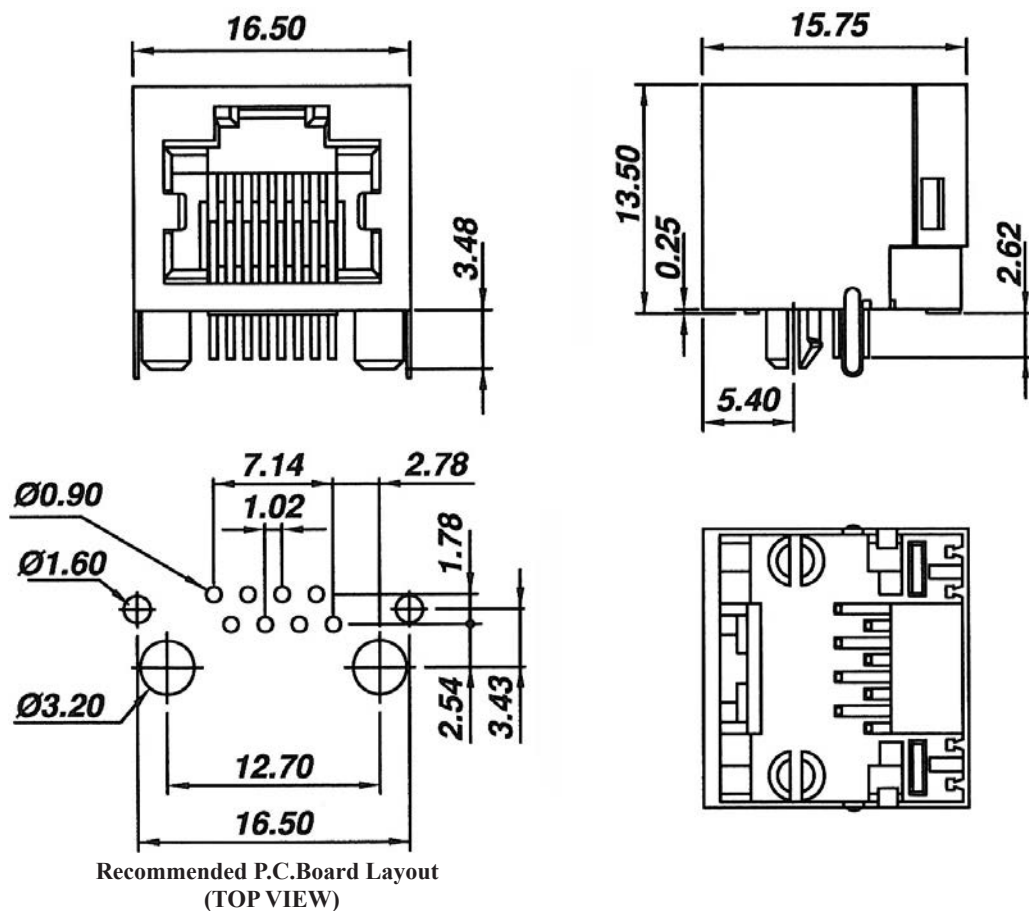
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R G - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

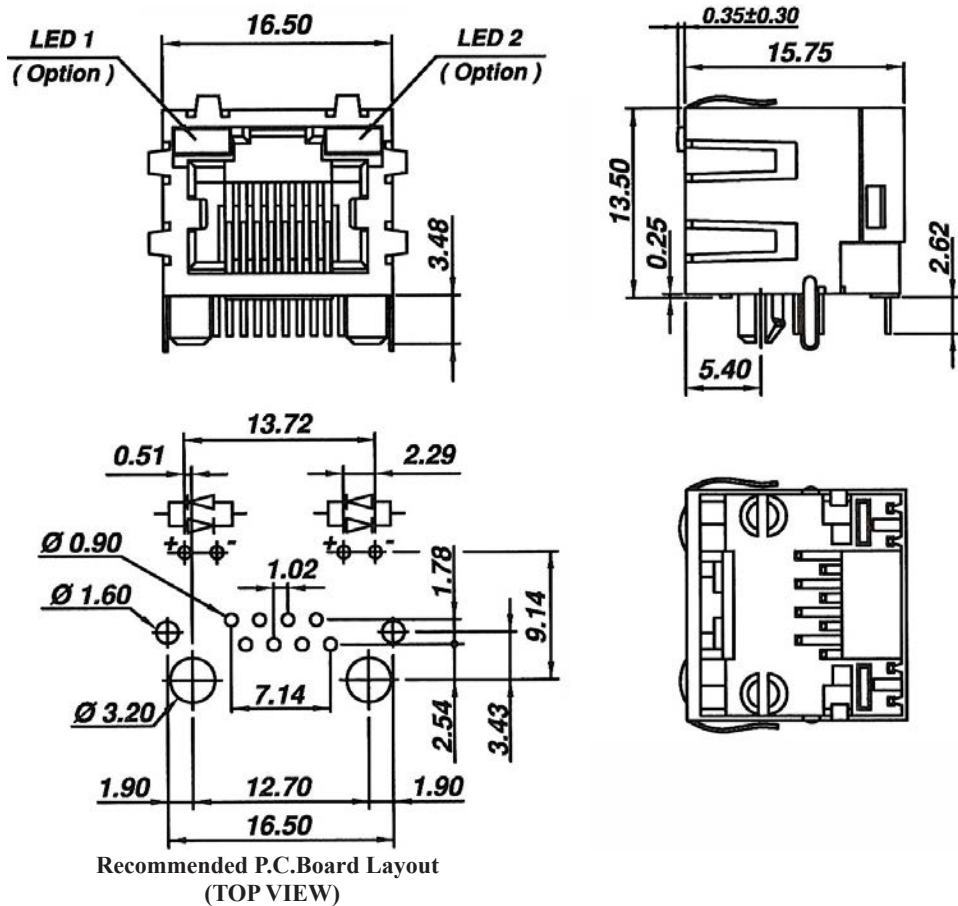
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.50MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRL - $\frac{88}{T} \frac{x}{2} \frac{B}{3} \frac{x}{4}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

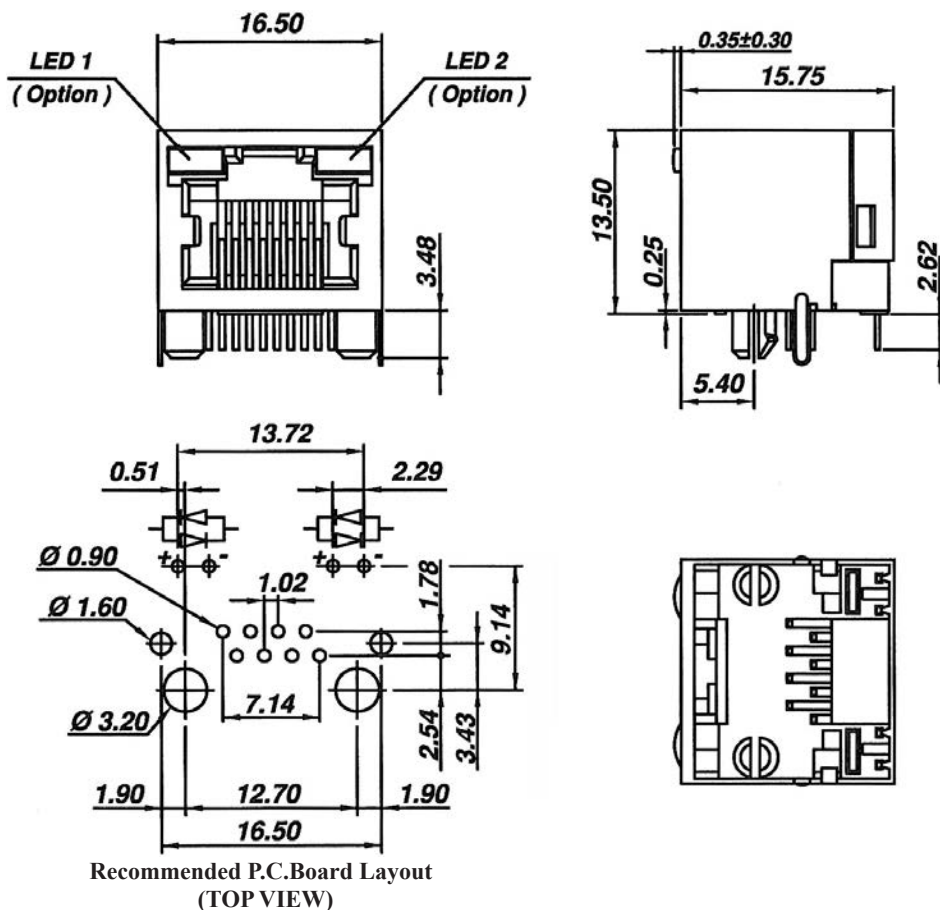
SIDE ENTRY CAT. 5 UP LTACH MODULAR PCB JACK WITH LED 8P PROFILE=13.50MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
 Soldering Temperature: 260°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R K - $\frac{88}{1} \times \frac{B}{2} \times \frac{X}{3} \times \frac{X}{4}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.50MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

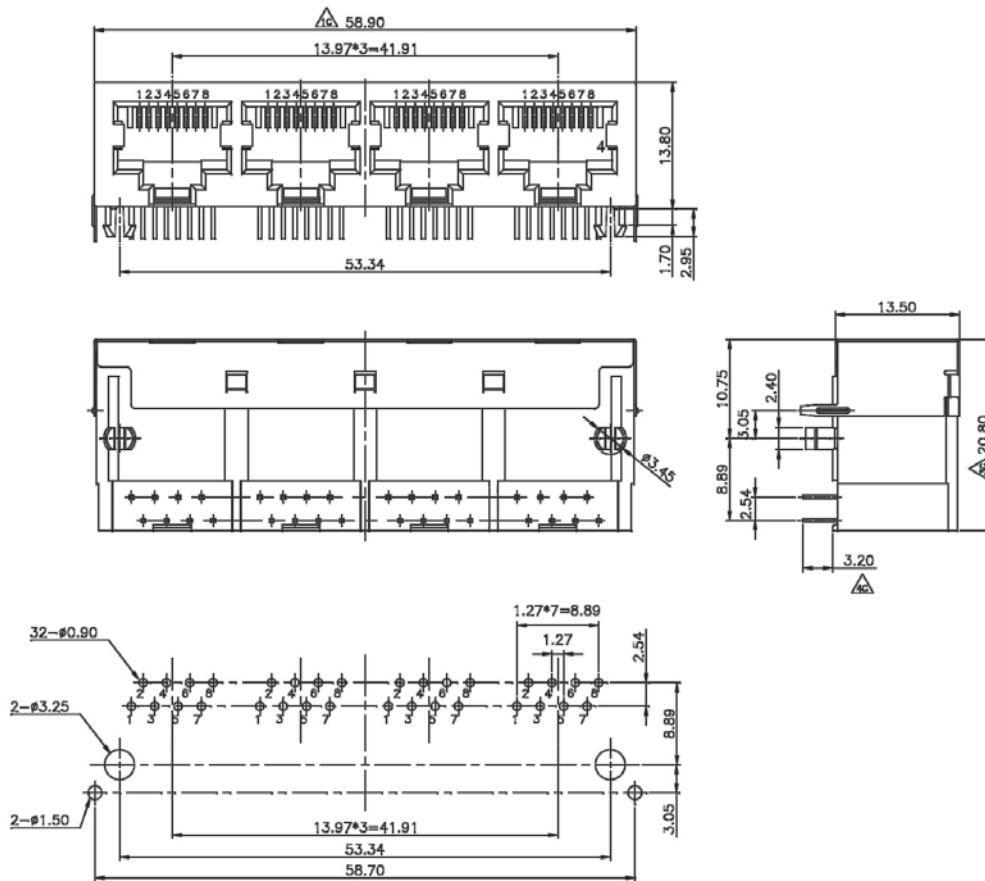
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J T W - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 4$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: 3.05MM SPACING BEFORE PEG

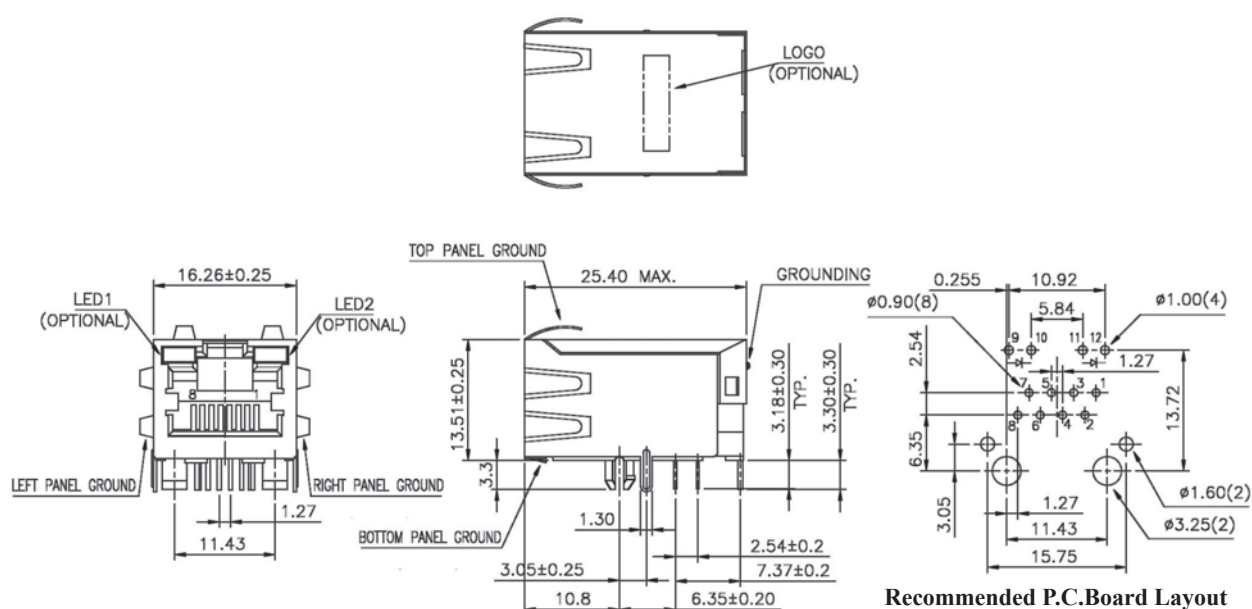
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.51MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - 88 $\frac{X}{2}$ $\frac{B}{3}$ $\frac{XX}{4}$ $\frac{XX}{5}$

- MODULAR JACK TYPE:
 "WA" NO PANEL GROUNDS
 "WB" TOP PANEL GROUNDS
 "WC" SIDE PANEL GROUNDS
 "WD" TOP & SIDE PANEL GROUNDS
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- COLORS OF LED:
 "NN" LED1/2 = GREEN/GREEN
 "NY" LED1/2 = GREEN/YELLOW
 "YN" LED1/2 = YELLOW/GREEN
 "YY" LED1/2 = YELLOW/YELLOW
 "XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

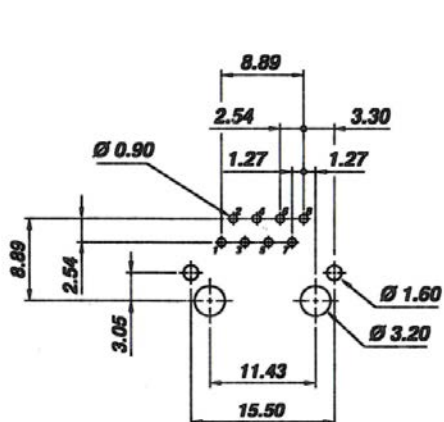
SIDE ENTRY CAT. 5 MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

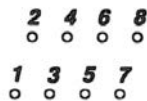
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

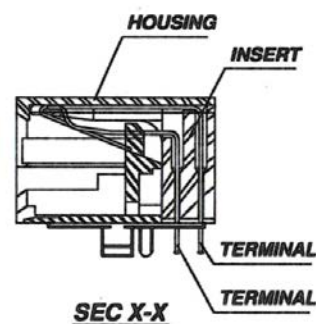
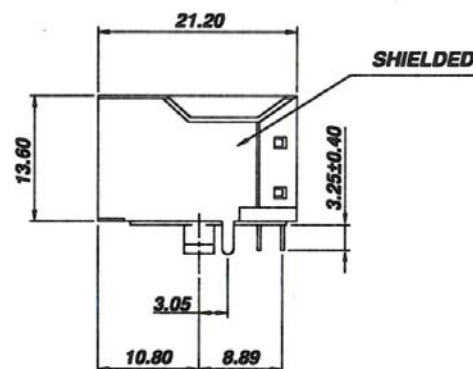
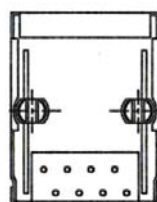
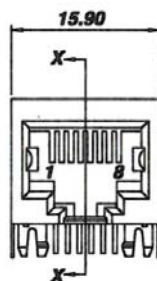
Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(Top View)



**CATEGORY 5
PCB LAYOUT**



ORDERING INFORMATION:

P/N M J S N - 88 x B
 T 2

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

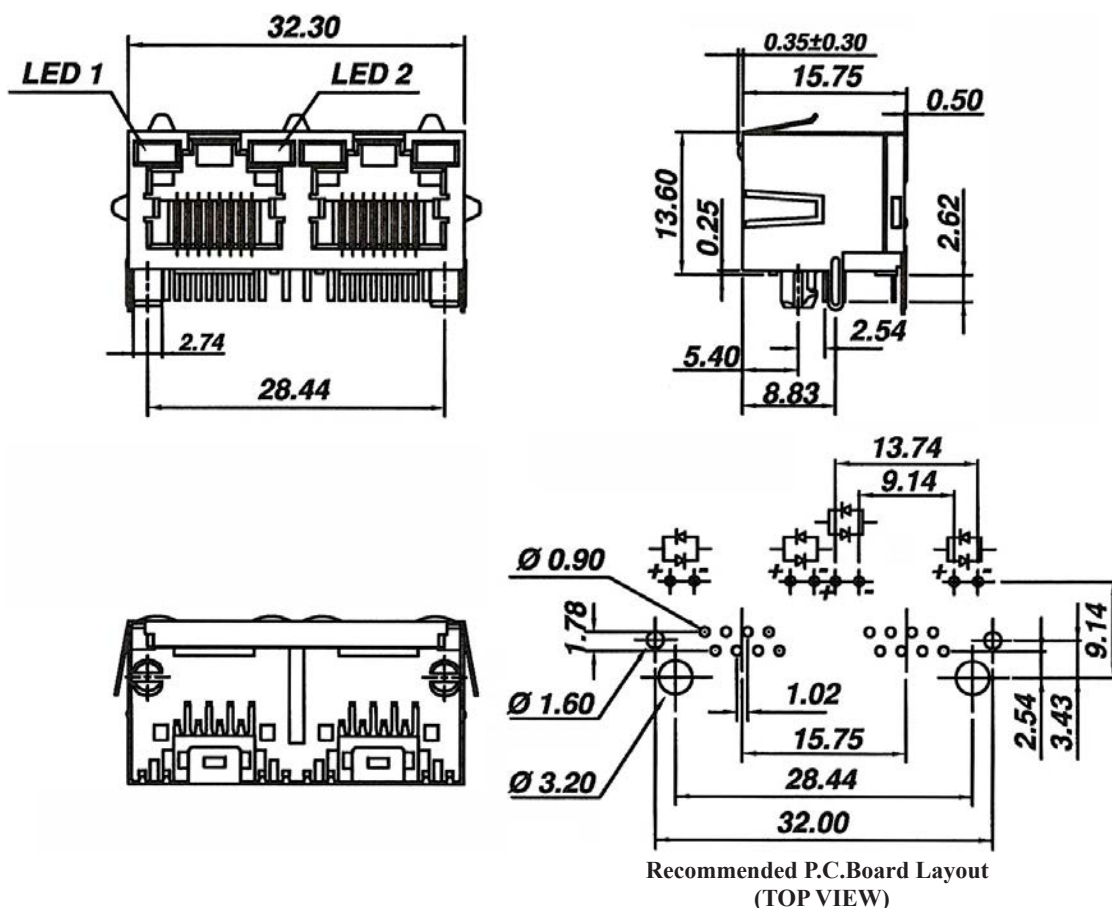
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
 Soldering Temperature: 260°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R S - $\frac{88}{12} \times \frac{B}{34} \times \frac{02}{5}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
02

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

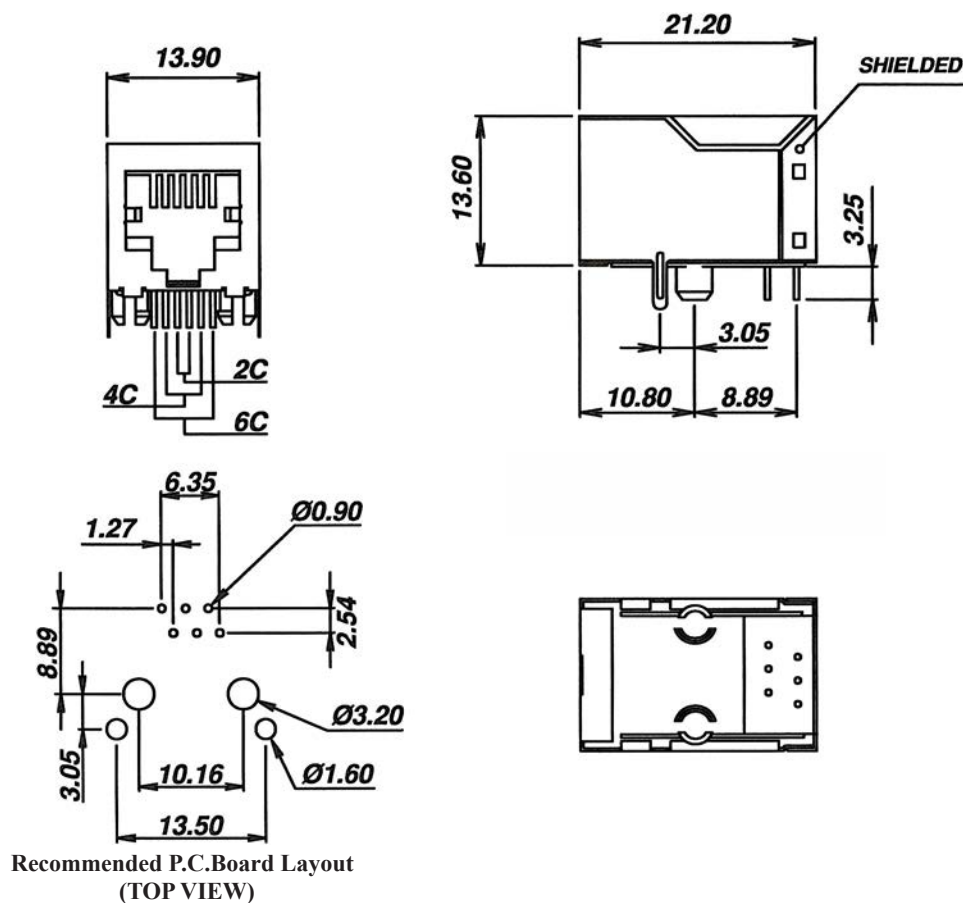
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRA - $\frac{x \times x}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRAHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

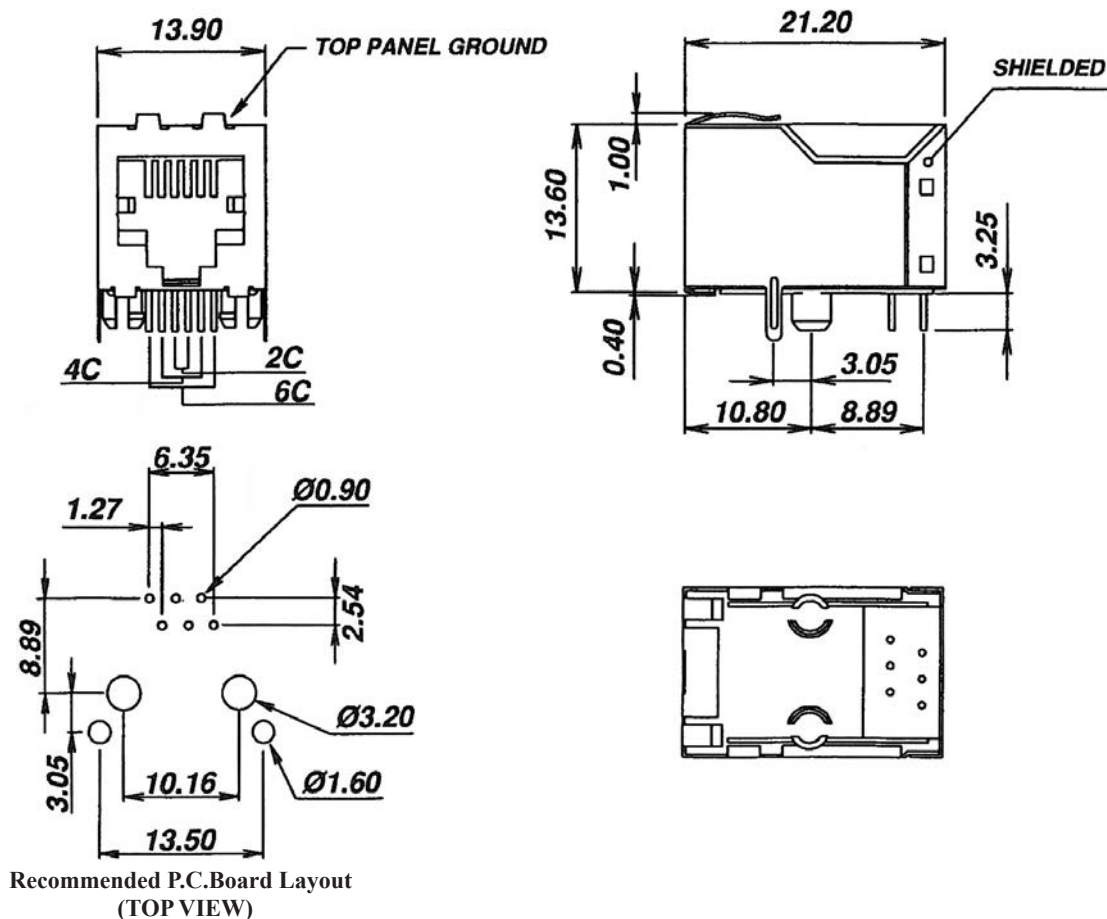
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R B - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRBHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

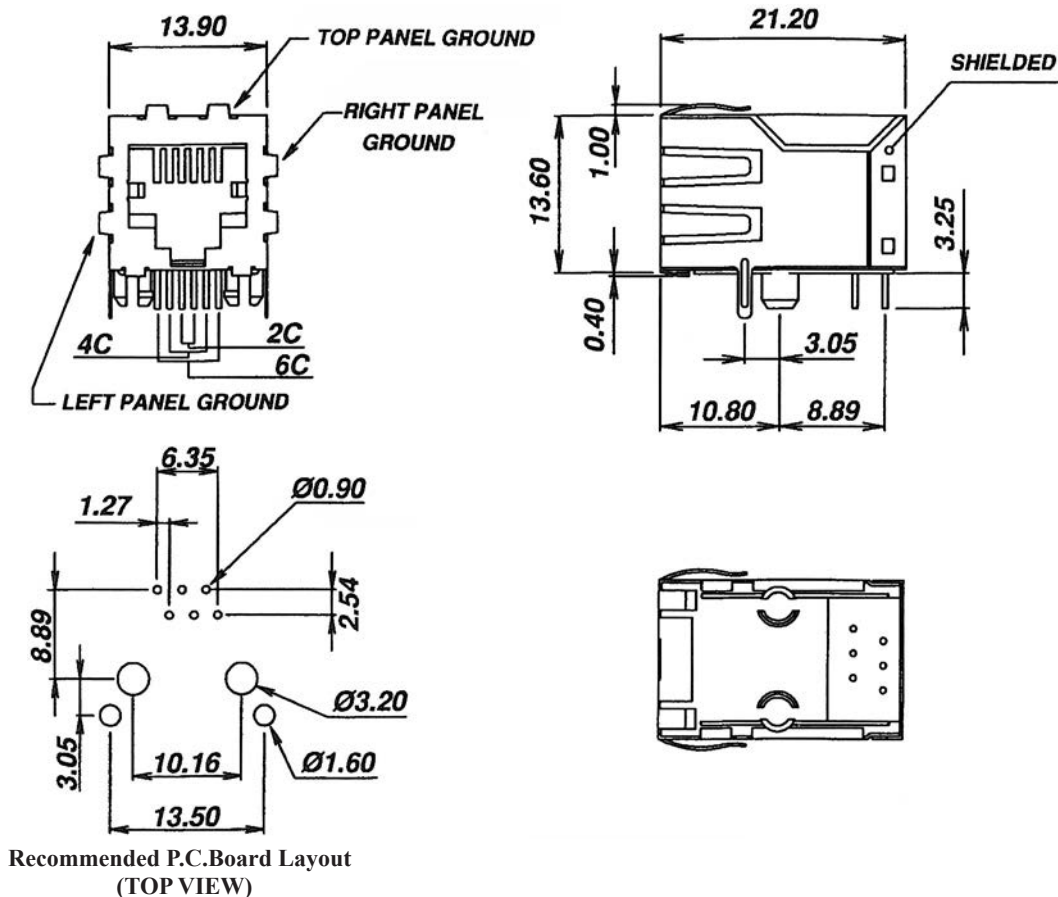
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRC - $\frac{x \times x}{1 \ 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJRCHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEFORE PEG

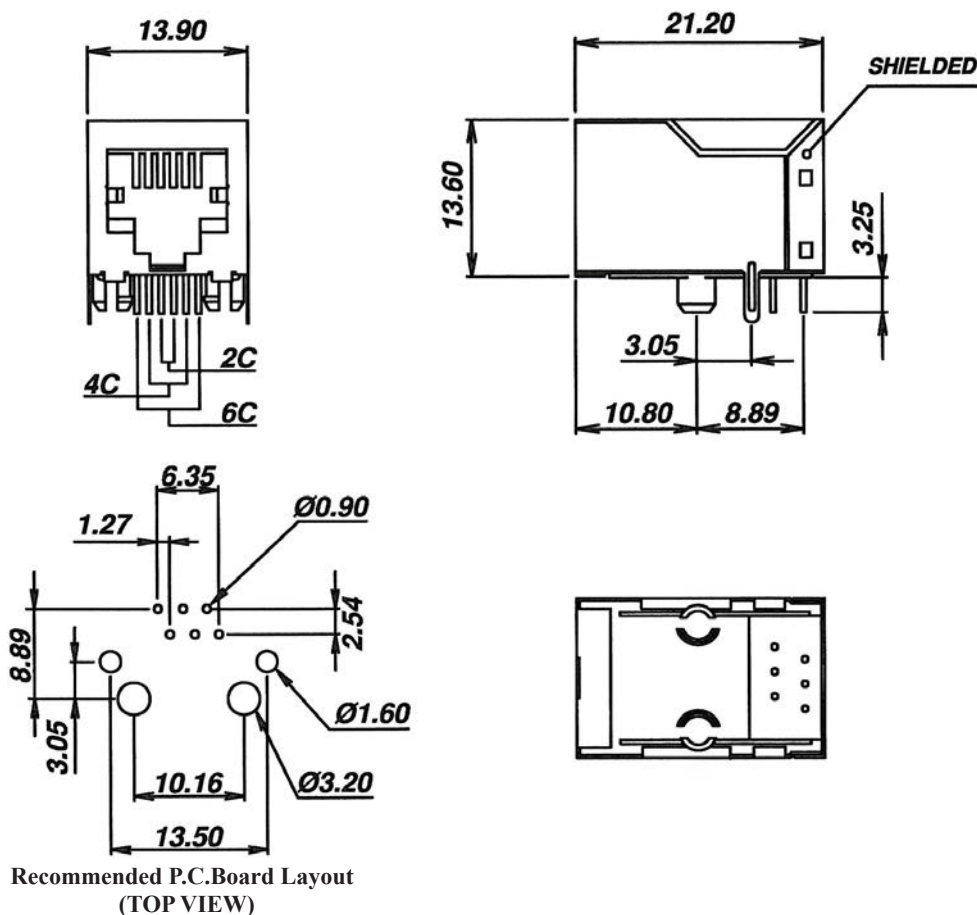
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J R D - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE 1: P/N MJRDHT-6xxB FOR HIGH TEMP. VERSION
 NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

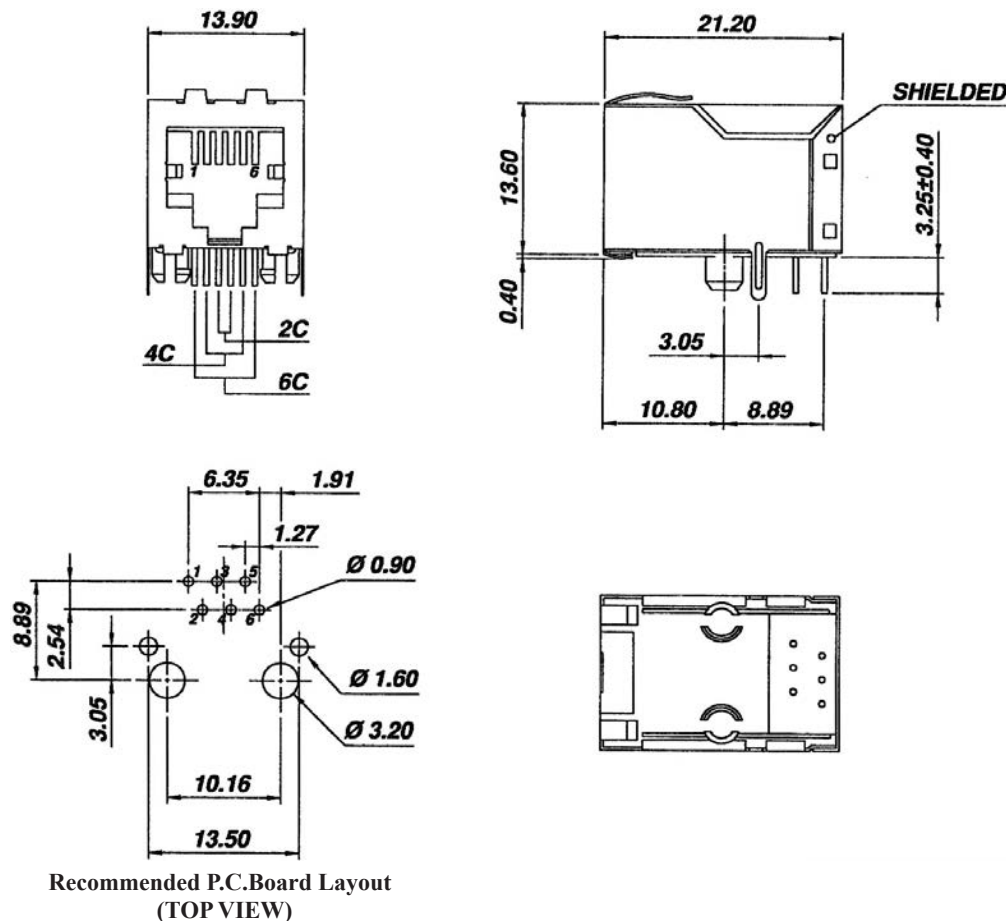
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJRE - $\frac{\text{xxxB}}{\text{T 2}}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE 1: P/N MJREHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

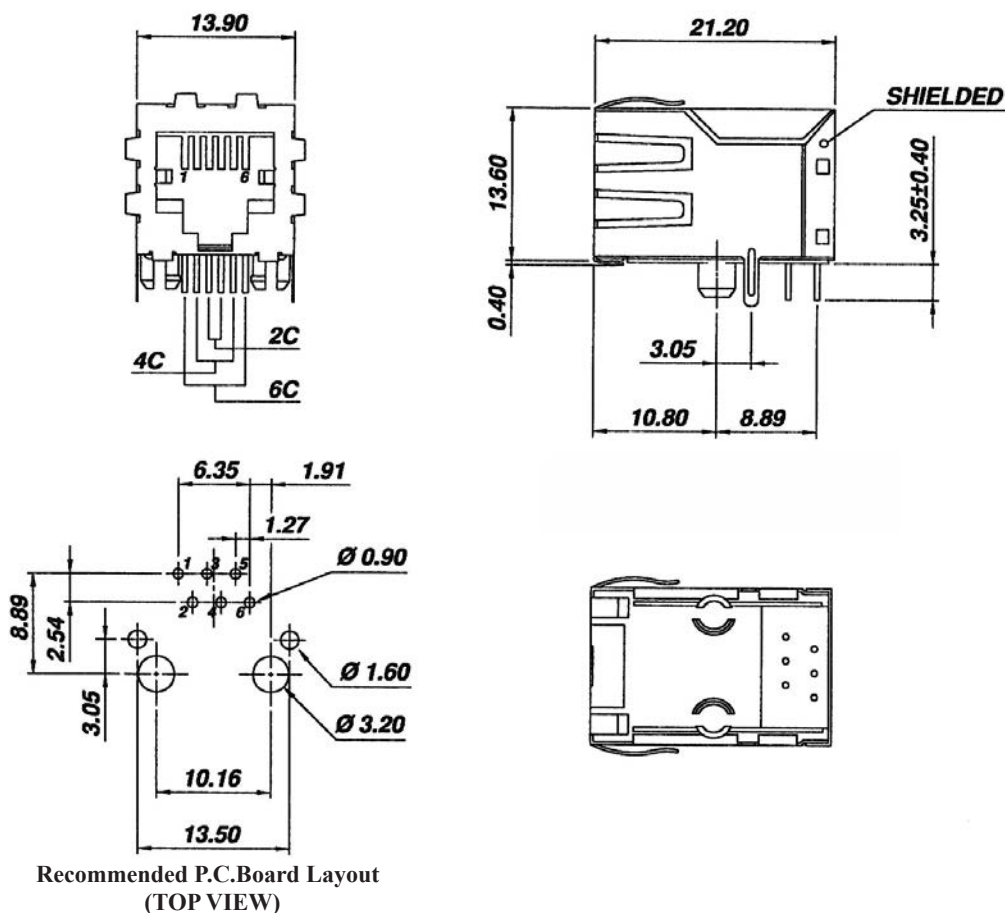
SIDE ENTRY MODULAR PCB JACK WITH ROUND PINS 6P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J R F - $\frac{x \times x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE 1: P/N MJRFHT-6xxB FOR HIGH TEMP. VERSION

NOTE 2: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

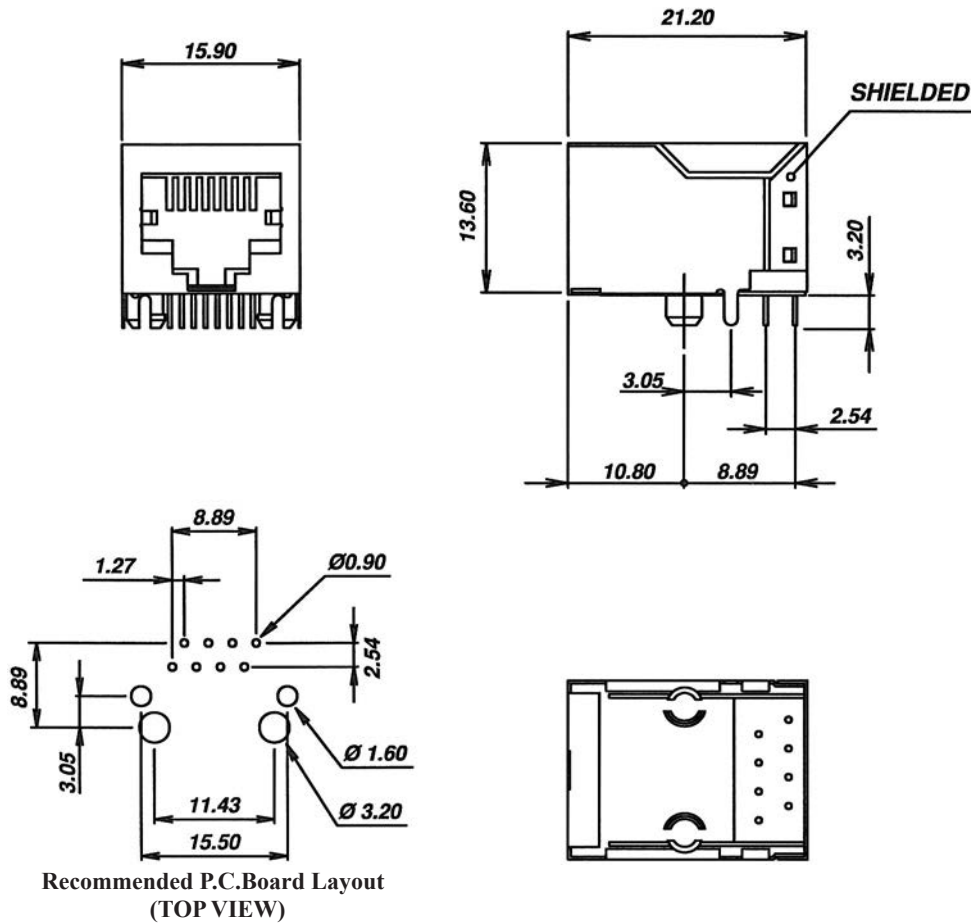
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S C - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

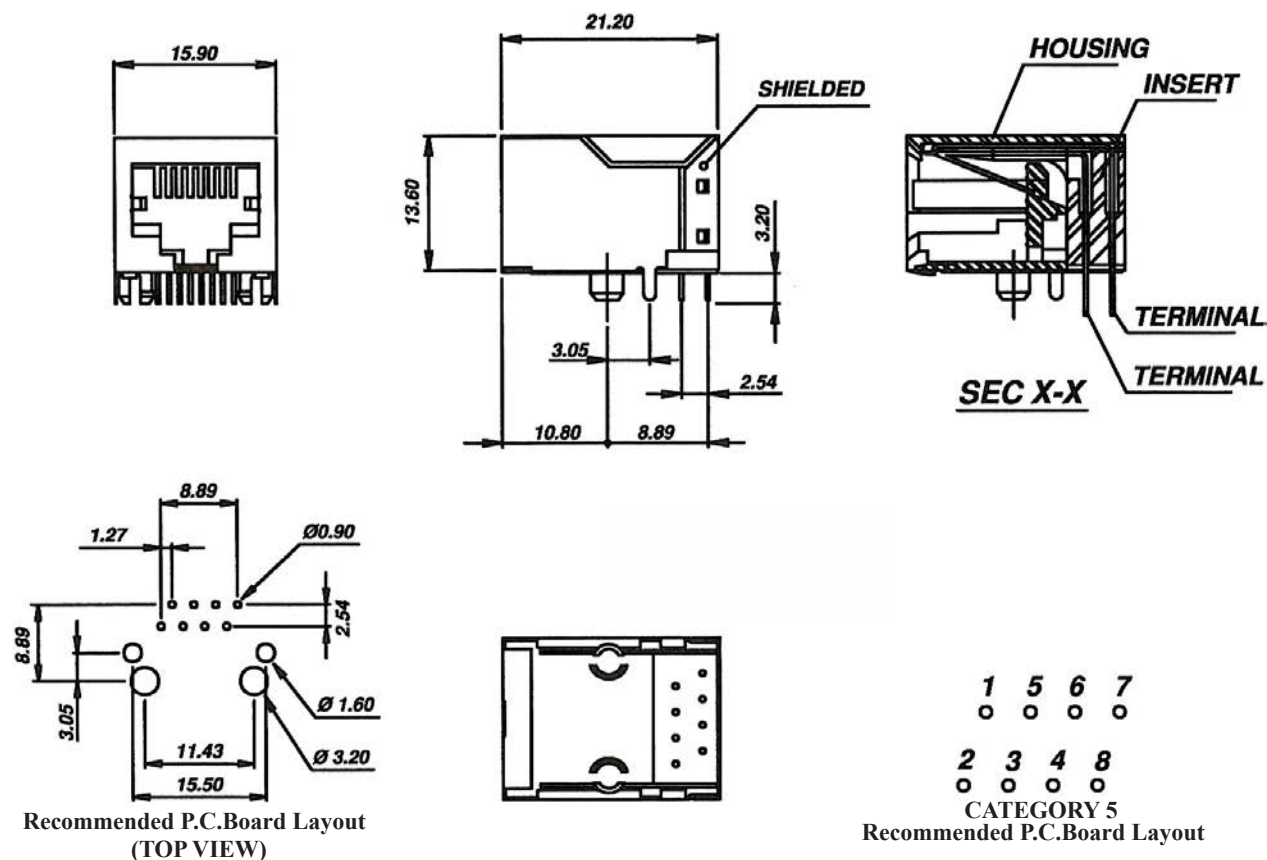
SIDE ENTRY CAT. 5 MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J S D - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

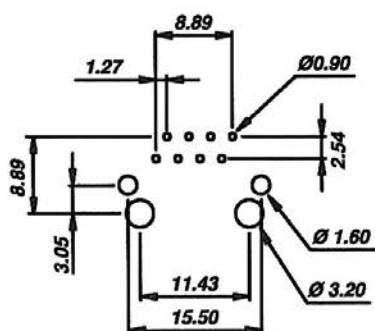
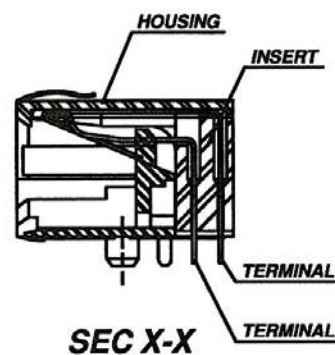
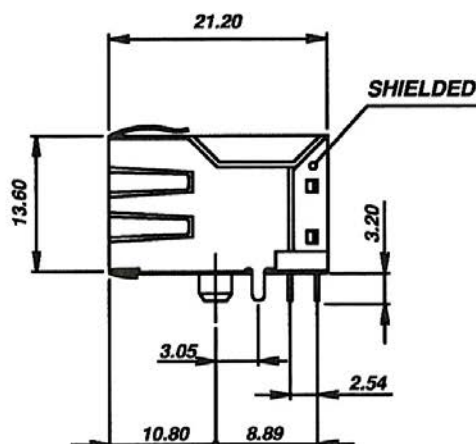
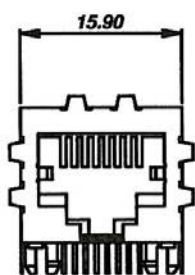
SIDE ENTRY CAT. 5 MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

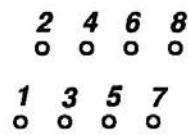
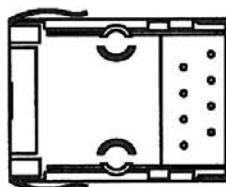
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)



CATEGORY 5
Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J S E - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

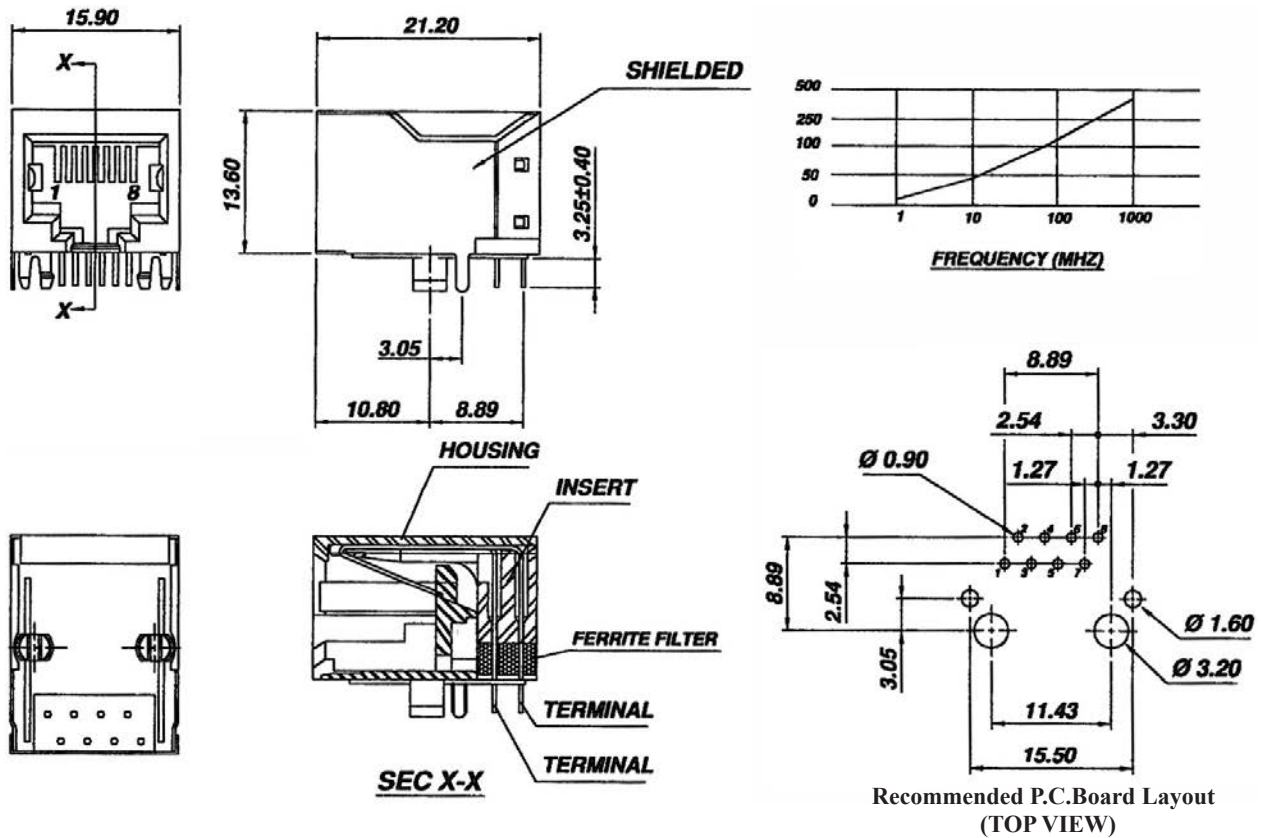
SIDE ENTRY MODULAR PCB JACK WITH FERRITE FILTER 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJSF - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJSFHT-88xB FOR HIGH TEMP. VERSION
 NOTE 2: 3.05MM SPACING BEHIND PEG

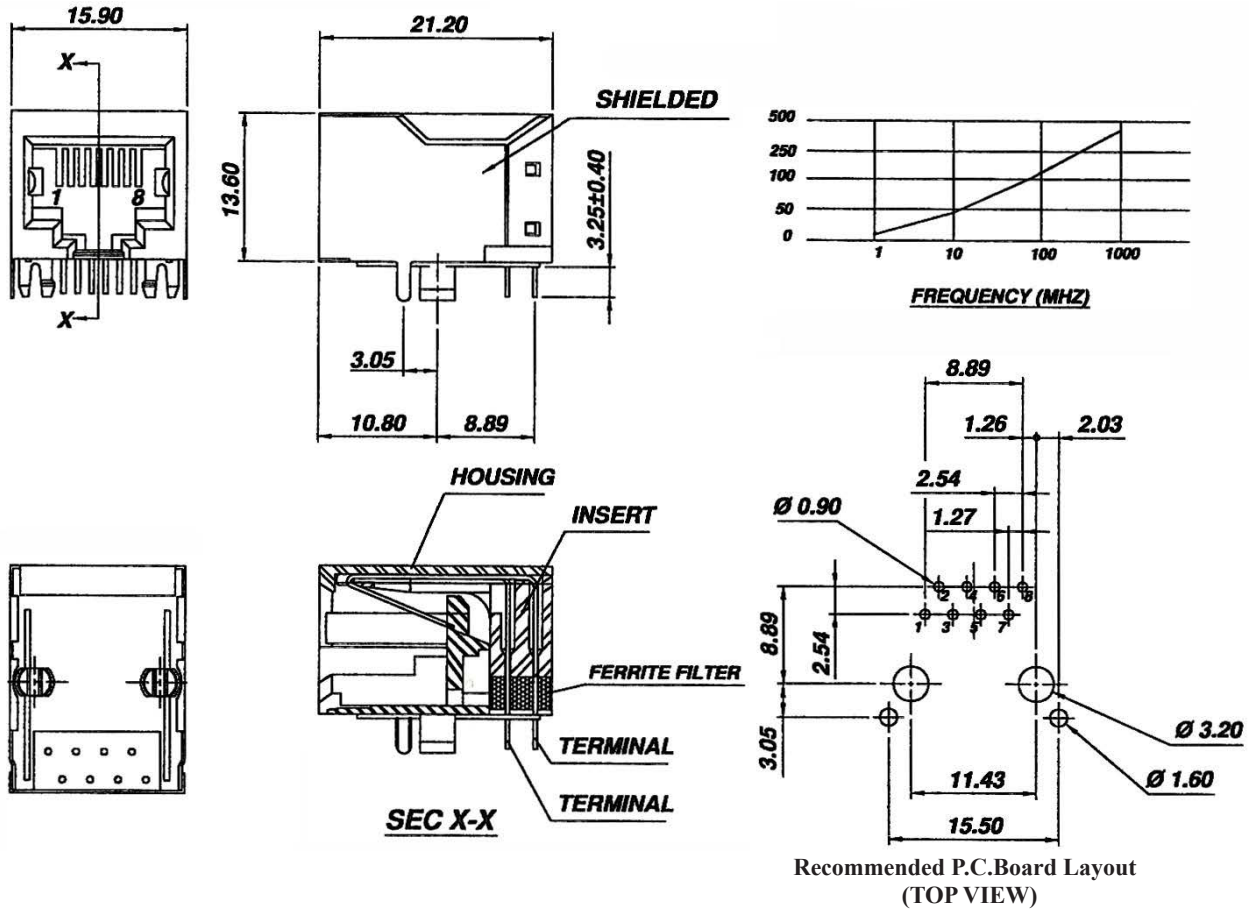
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ76- $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJ76HT-88xB FOR HIGH TEMP. VERSION
 NOTE 2: 3.05MM SPACING BEFORE PEG

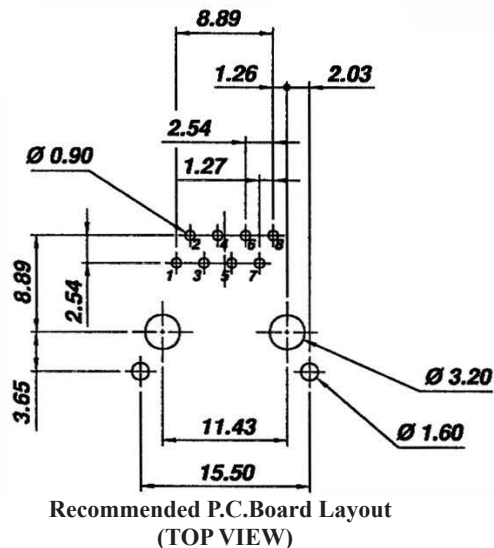
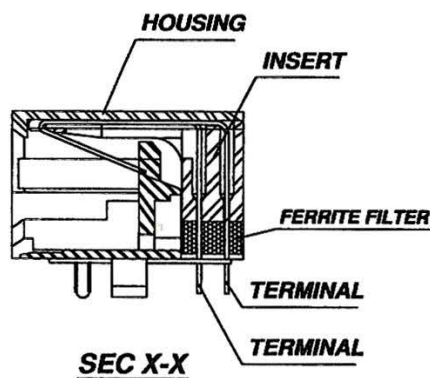
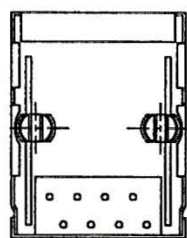
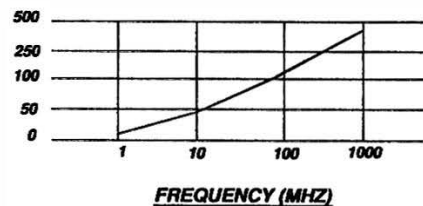
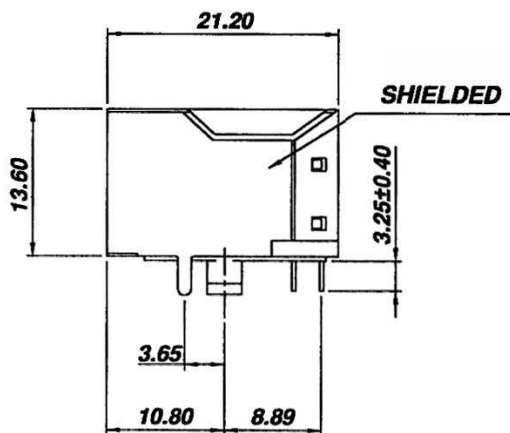
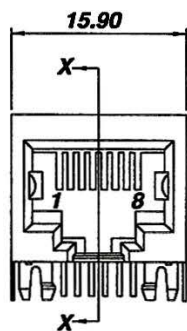
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ77- $\frac{88}{1}$ $\frac{x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJ77HT-88xB FOR HIGH TEMP. VERSION
 NOTE 2: 3.65MM SPACING BEFORE PEG

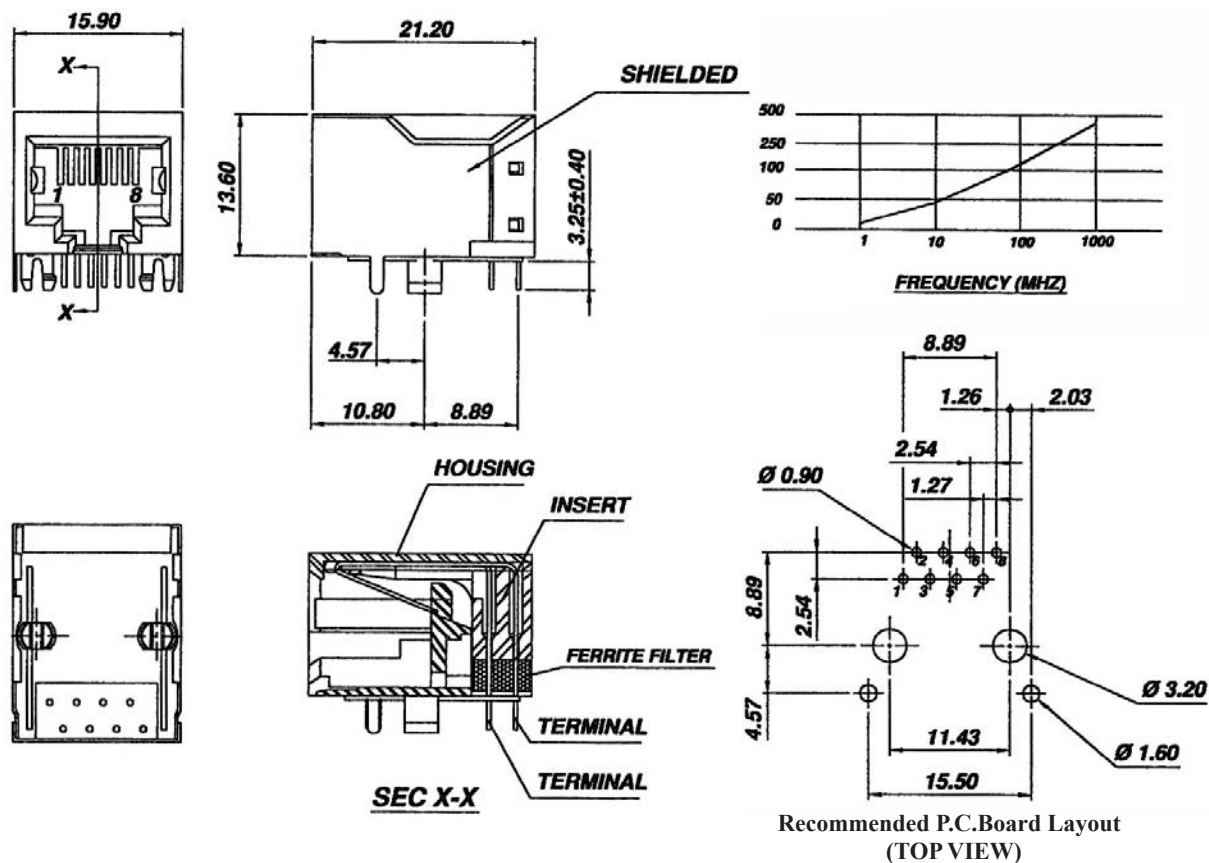
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ53 - $\frac{88 \times B}{T 2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: P/N MJ53HT-88xB FOR HIGH TEMP. VERSION
 NOTE 2: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

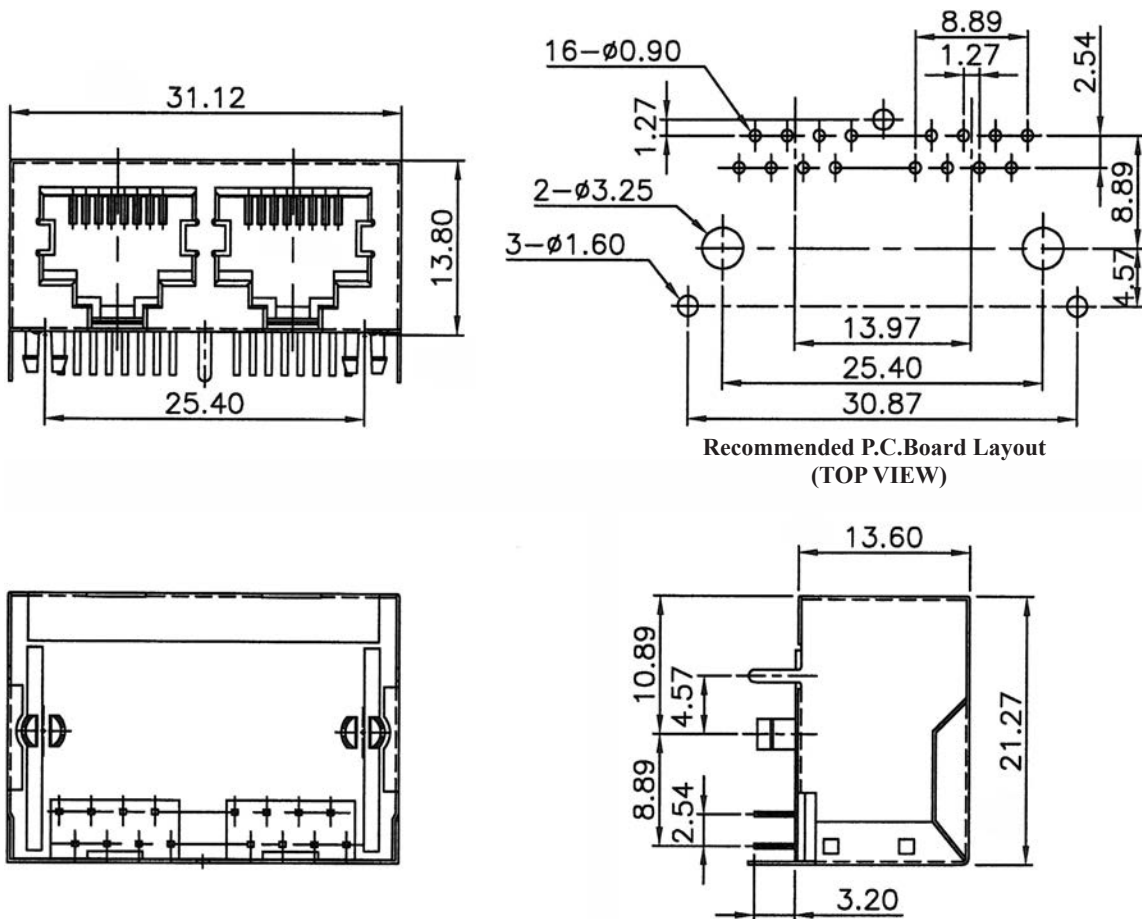
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ8E - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
02

NOTE: 4.57MM SPACING BEFORE PEG

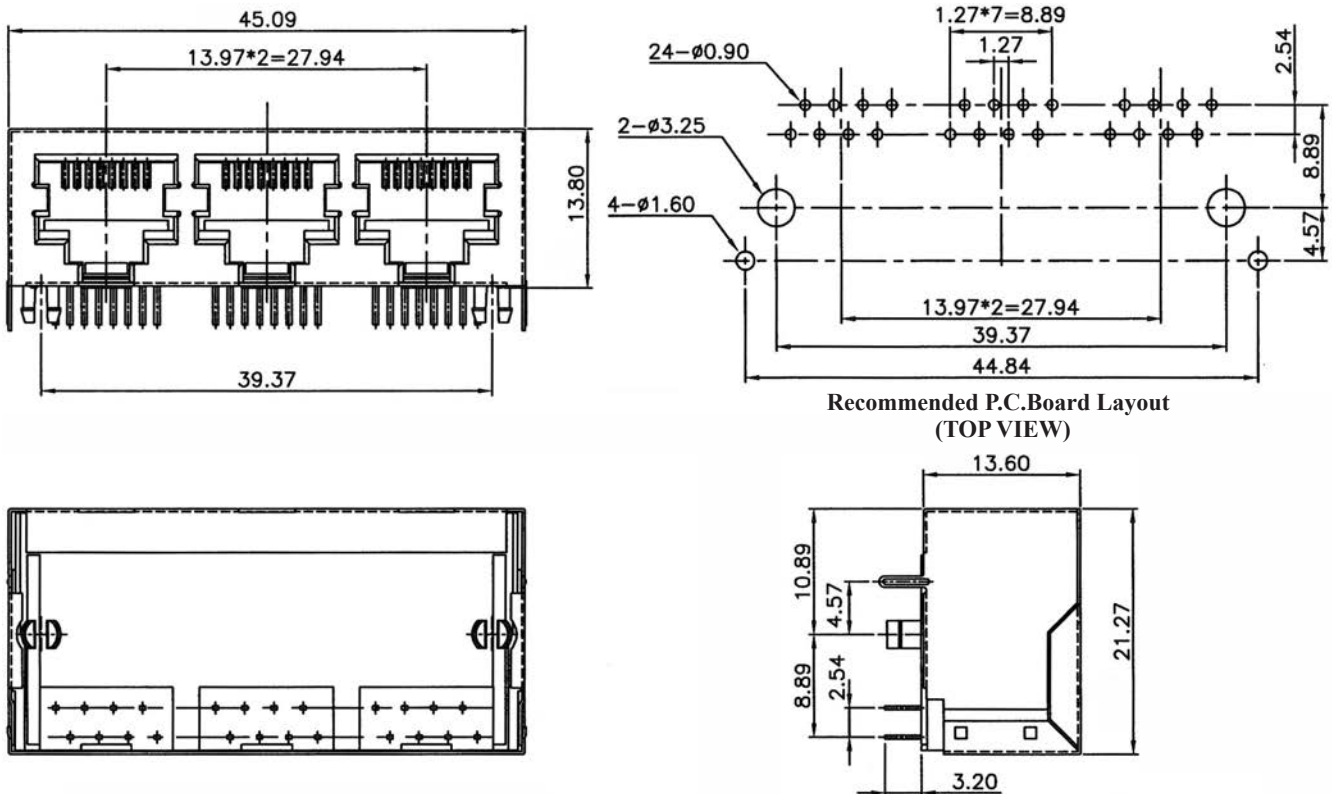
SIDE ENTRY 3-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 8 E - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 3$

- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 03

NOTE: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

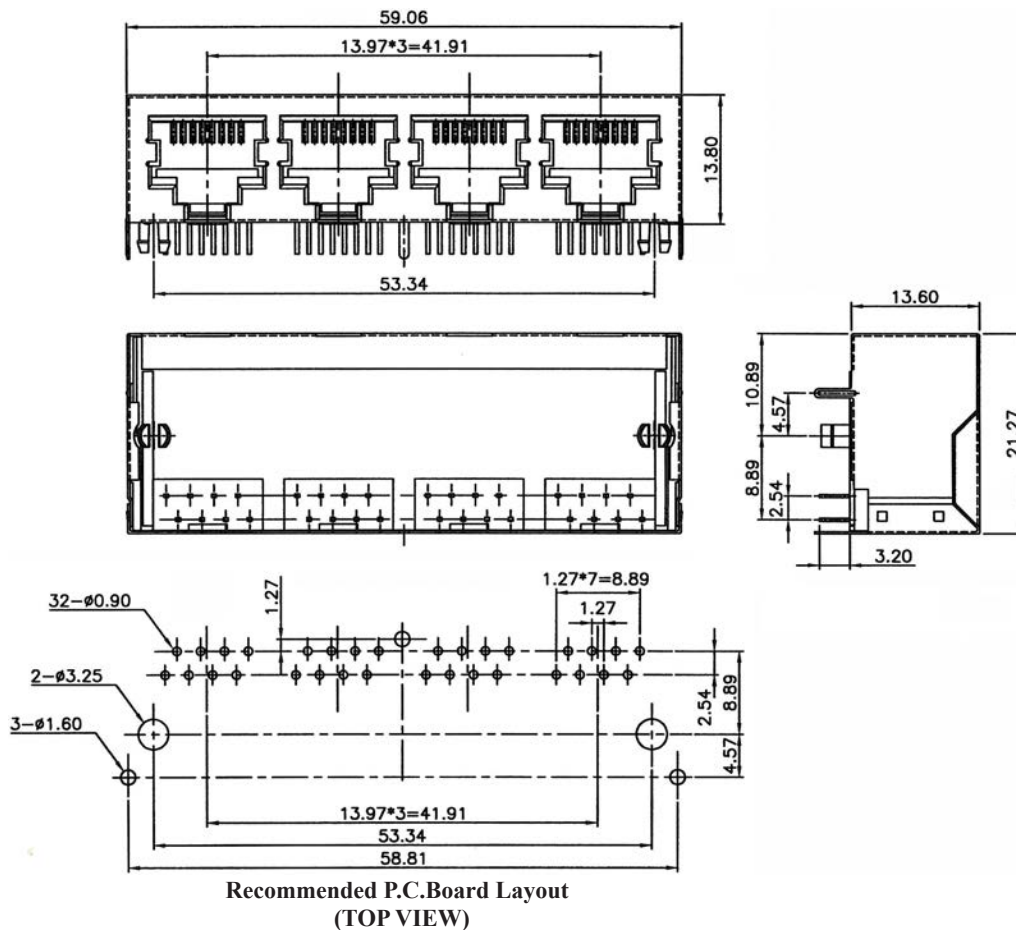
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 8 E - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 04$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 5-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

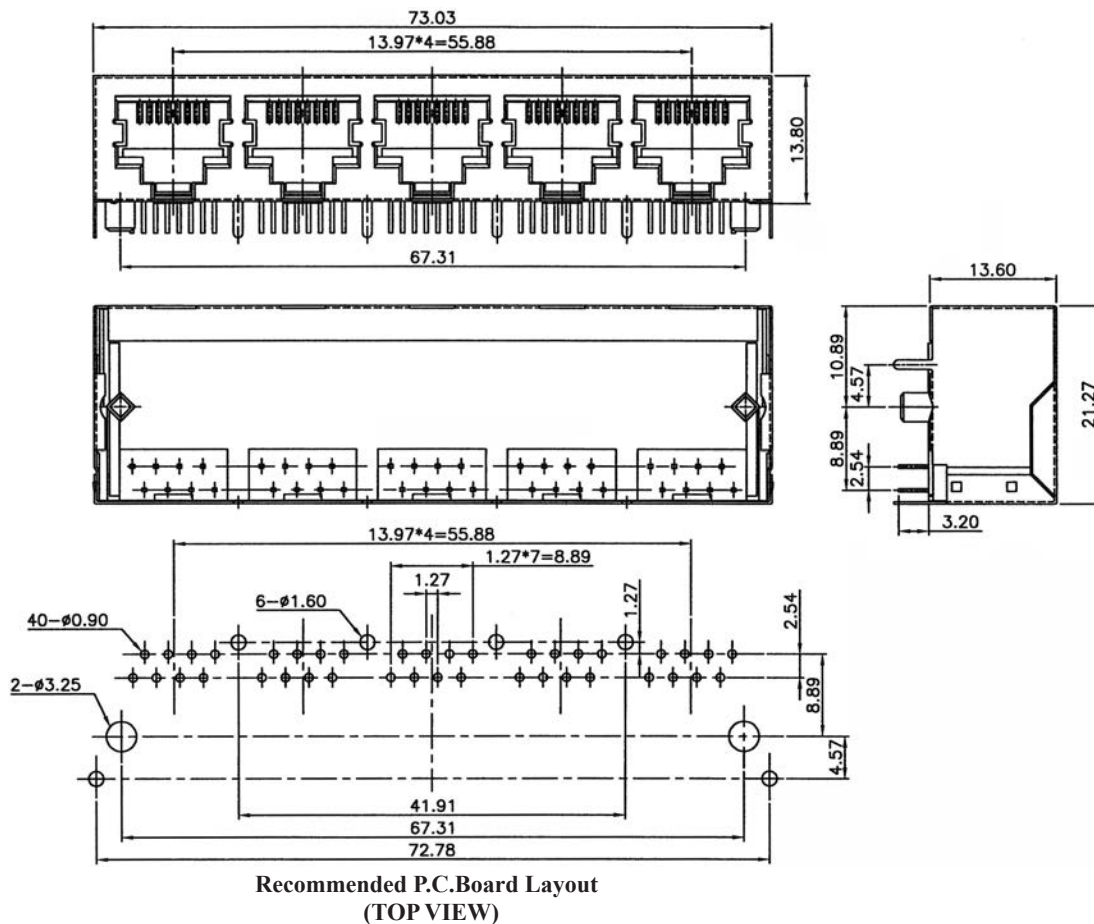
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ8E - $\frac{88}{1} \times \frac{B}{2} \frac{05}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
05

NOTE: 4.57MM SPACING BEFORE PEG

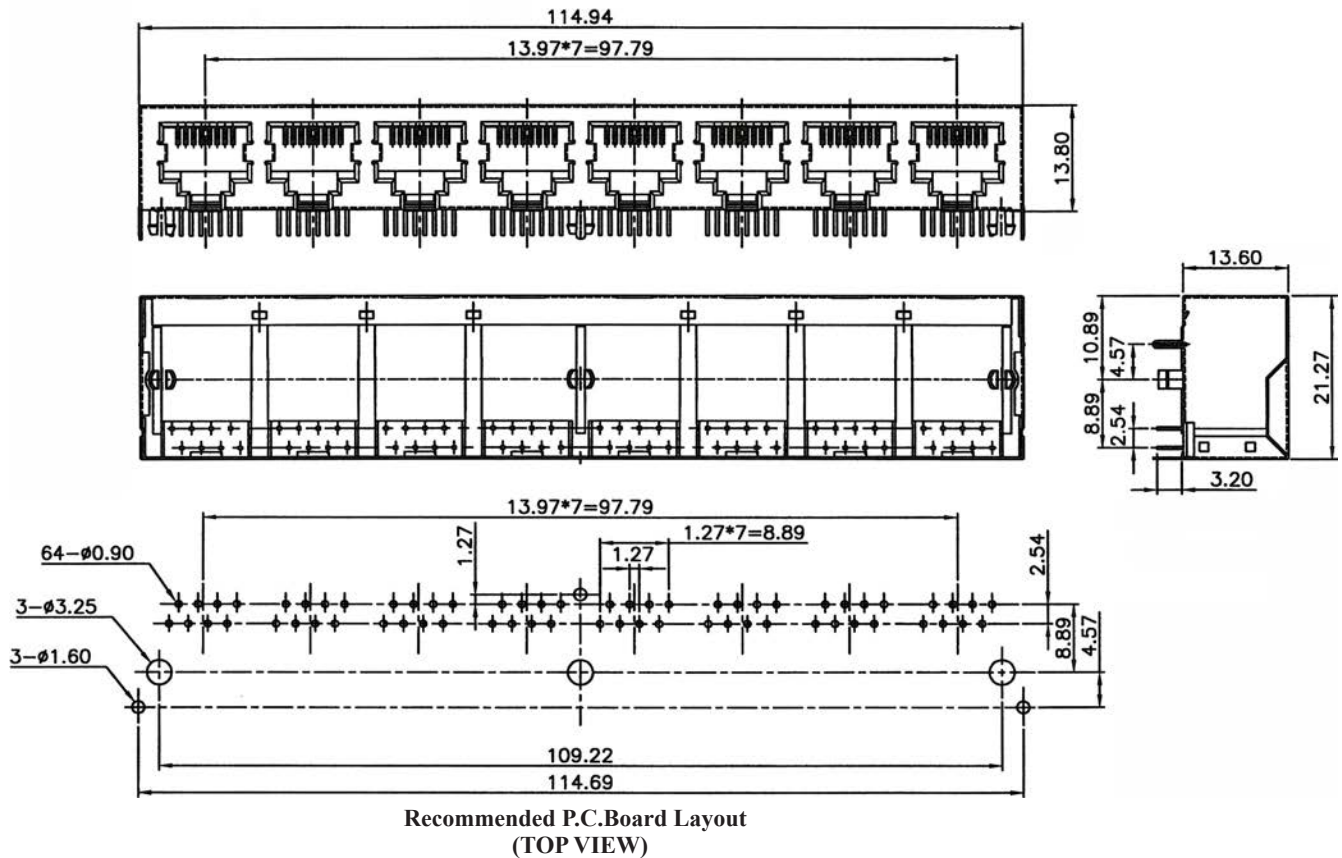
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ 8 E - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
08

NOTE: 4.57MM SPACING BEFORE PEG

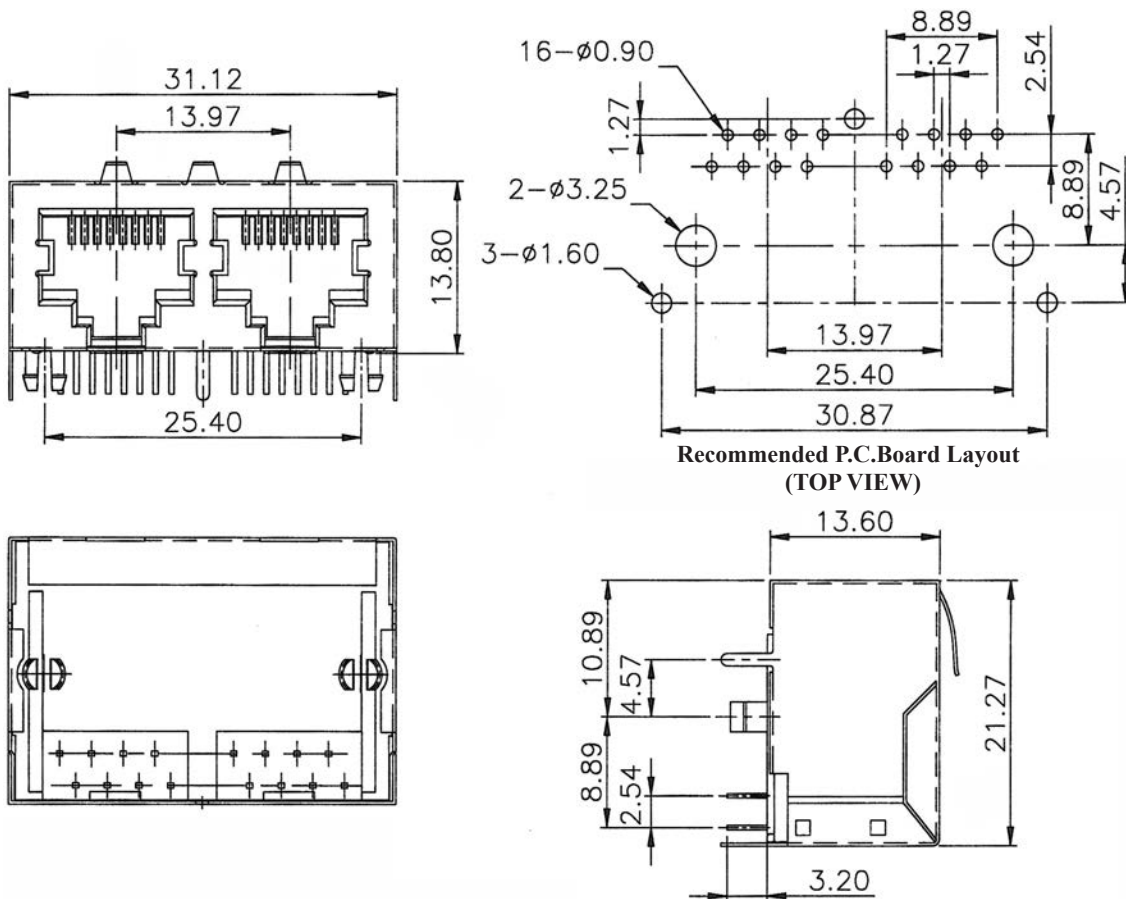
SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{23} B \frac{02}{4}$

1. CATEGORY TYPE:
"1H" CAT. 3
"Y1" CAT. 5
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. NO. OF PORTS:
02

NOTE: 4.57MM SPACING BEFORE PEG

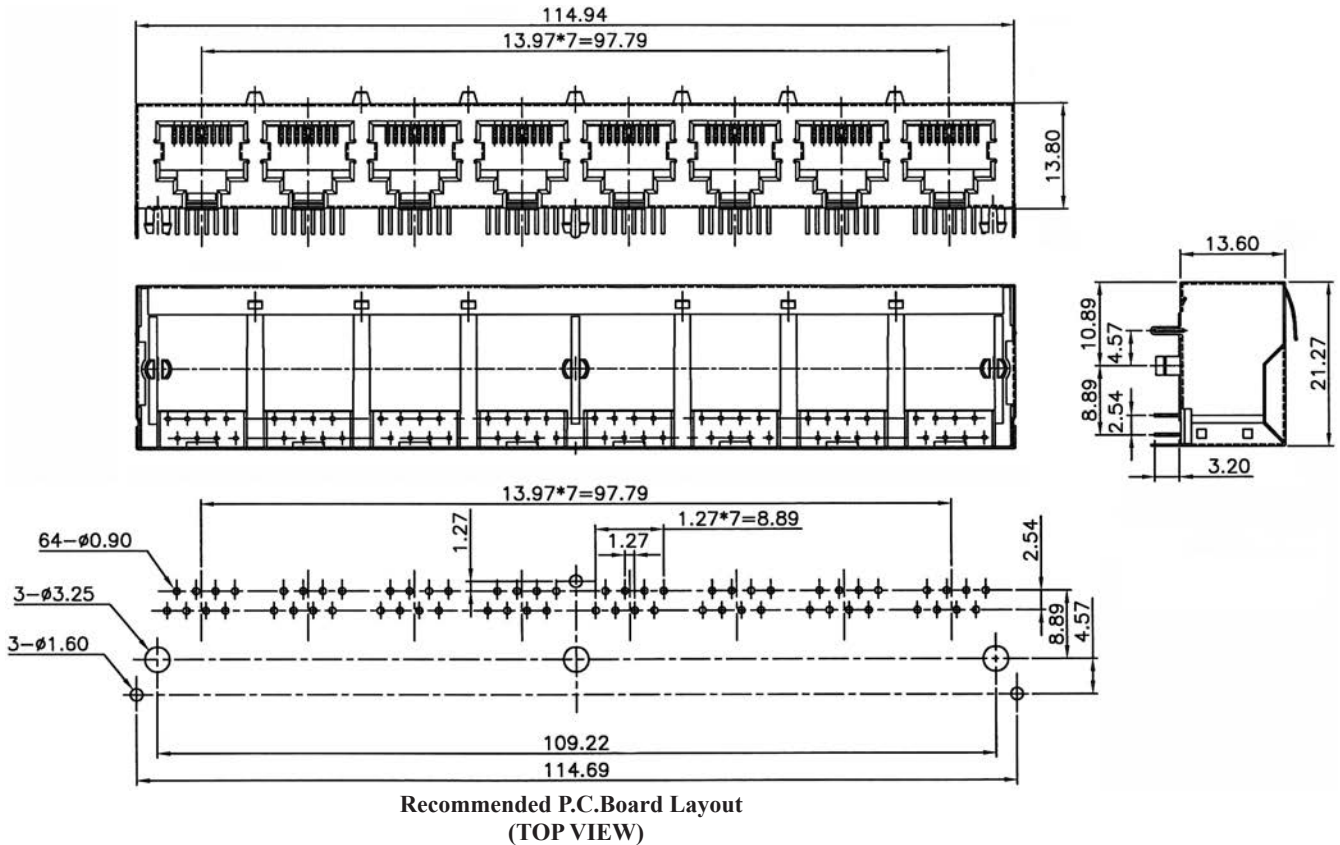
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B $\frac{08}{4}$

1. CATEGORY TYPE:

"1H" CAT. 3
 "Y1" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
 "84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

4. NO. OF PORTS:

08

NOTE: 4.57MM SPACING BEFORE PEG

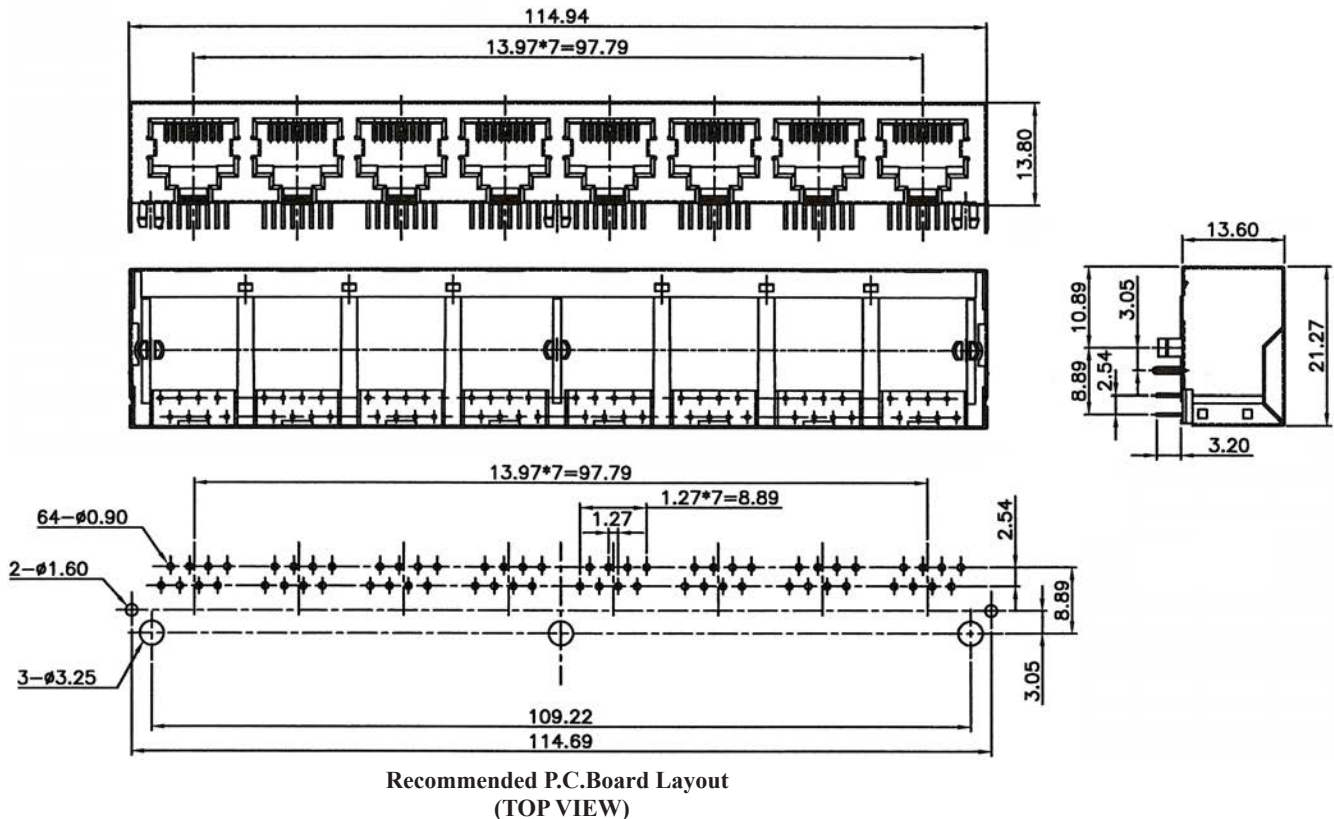
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°c / +85°c
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°c
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1L - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
08

NOTE: 3.05MM SPACING BEHIND PEG

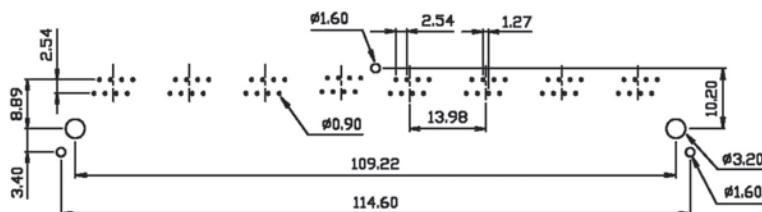
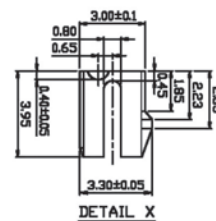
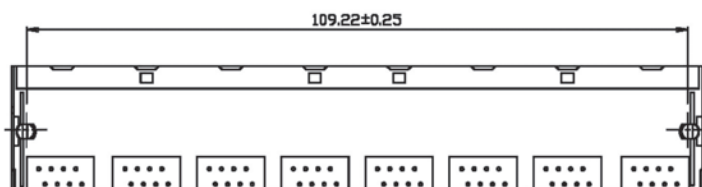
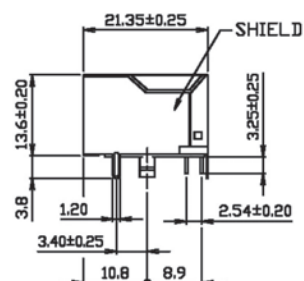
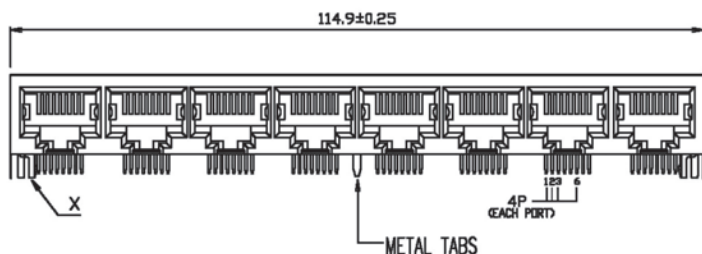
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J N R - 8 8 x B 0 8
 1 2 3 4 5

- MODULAR JACK TYPE:
"NR" 3.40MM SPACING BEFORE PEG
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
08

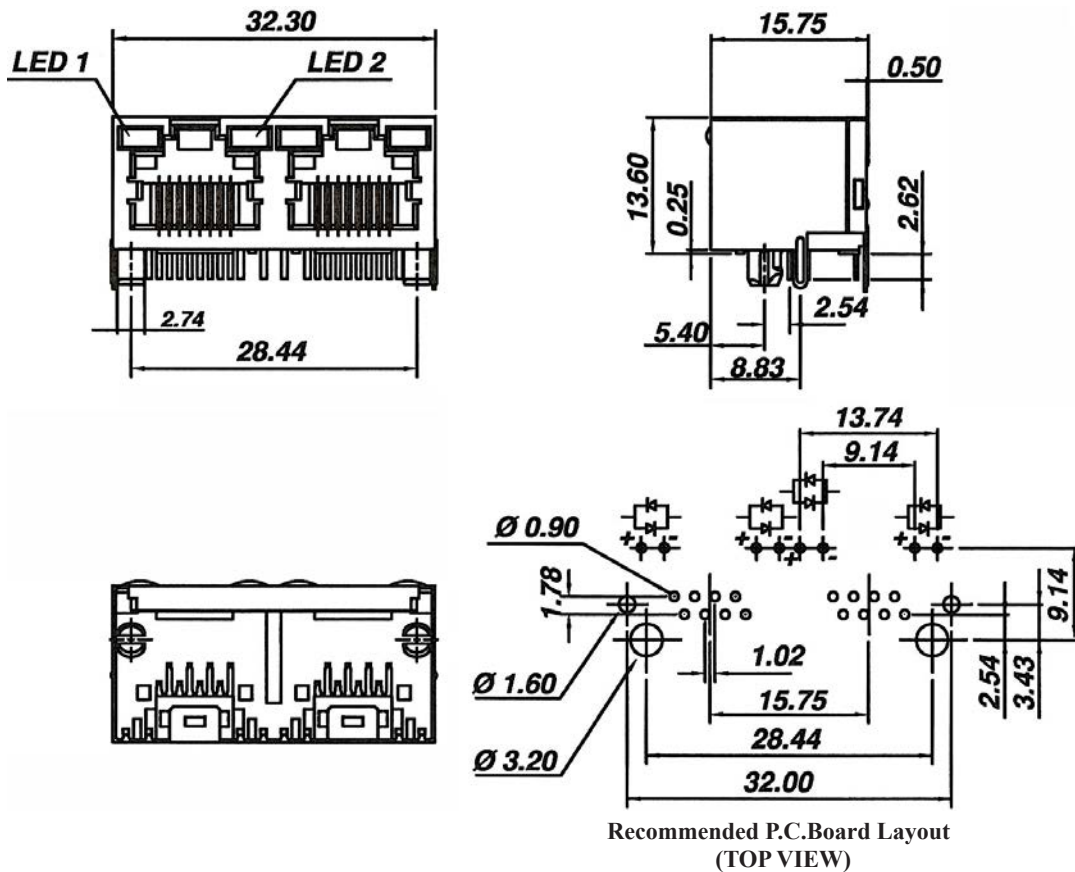
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R R - $\frac{8}{1} \times \frac{8}{2} \times \frac{B}{3} \times \frac{0}{4} \times \frac{0}{5}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
02

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

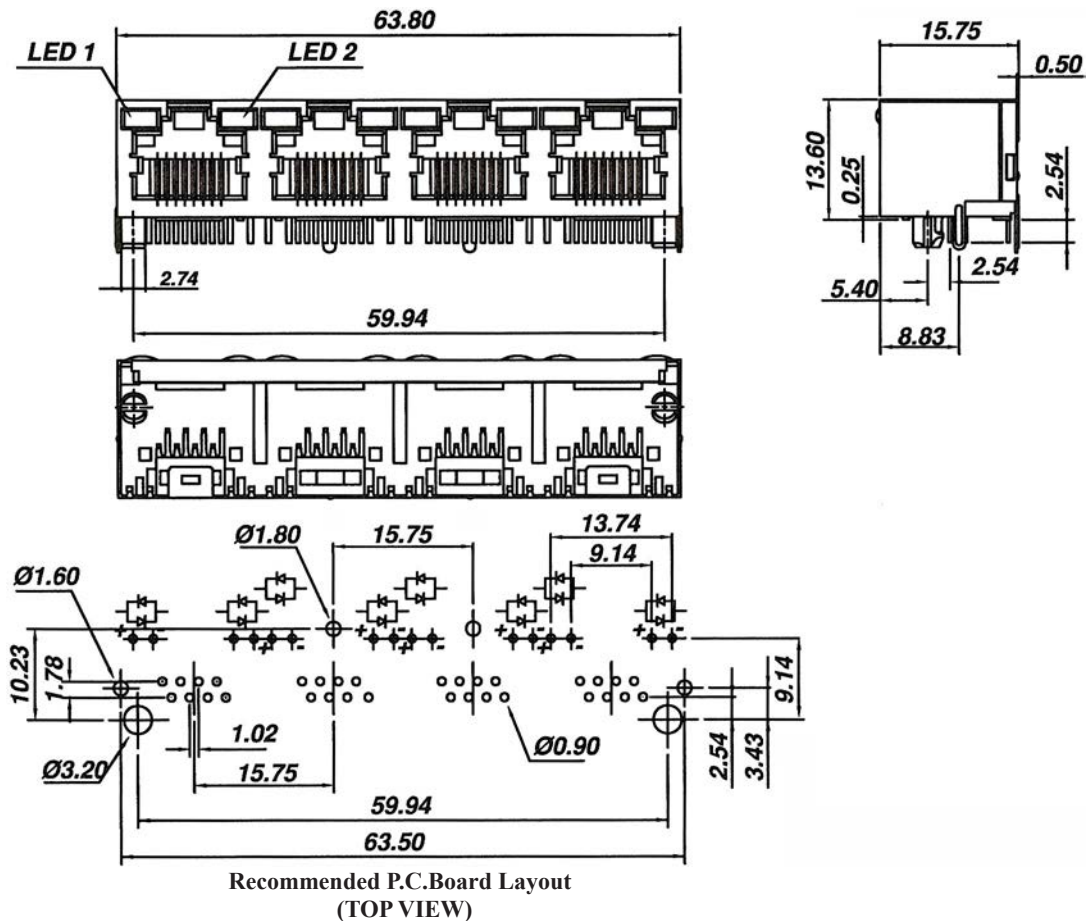
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
 Soldering Temperature: 260°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R R - $\frac{8}{1} \times \frac{8}{2} \times \frac{B}{3} \times \frac{0}{4} \times \frac{4}{5}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
04

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

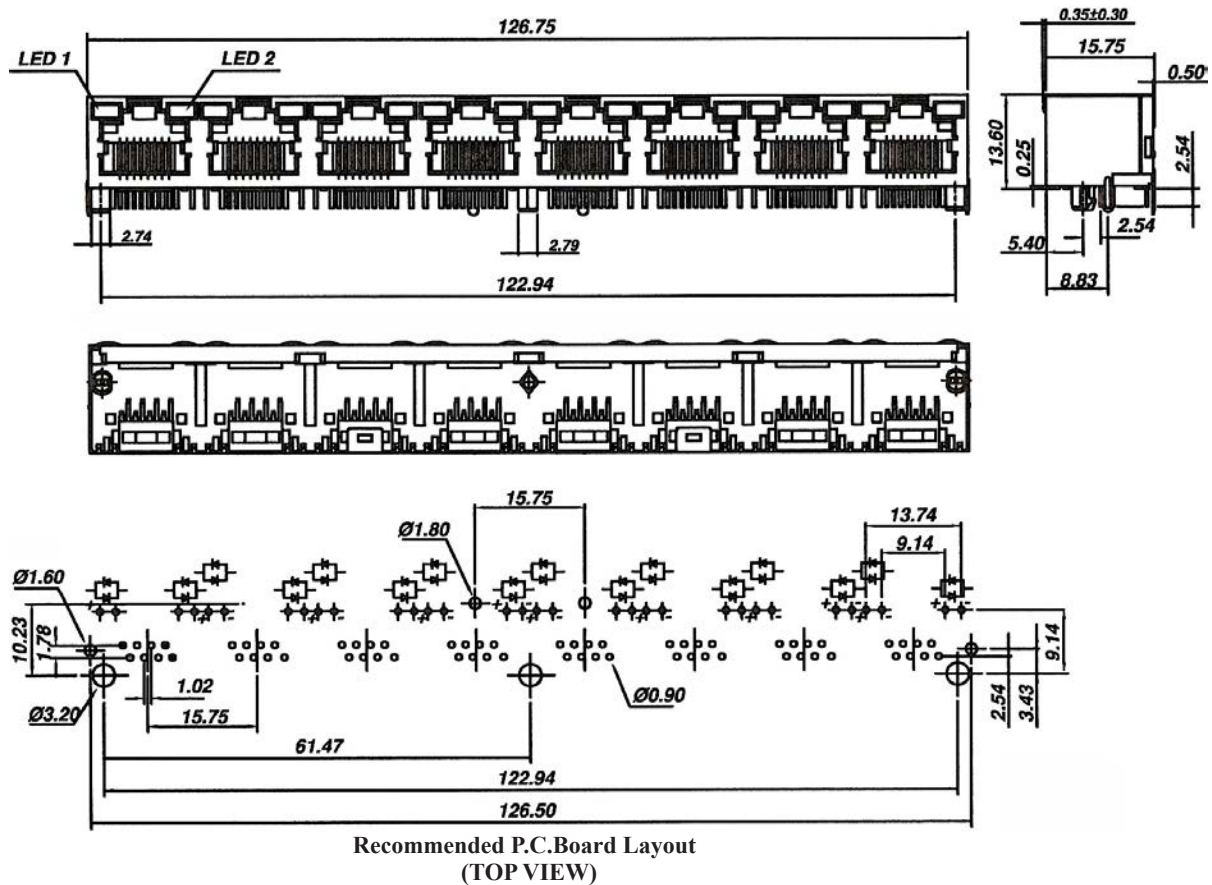
SIDE ENTRY 8-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
 Soldering Temperature: 260°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R R - $\frac{88}{1} \times \frac{B}{2} \times \frac{3}{4} \times \frac{08}{5}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
08

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

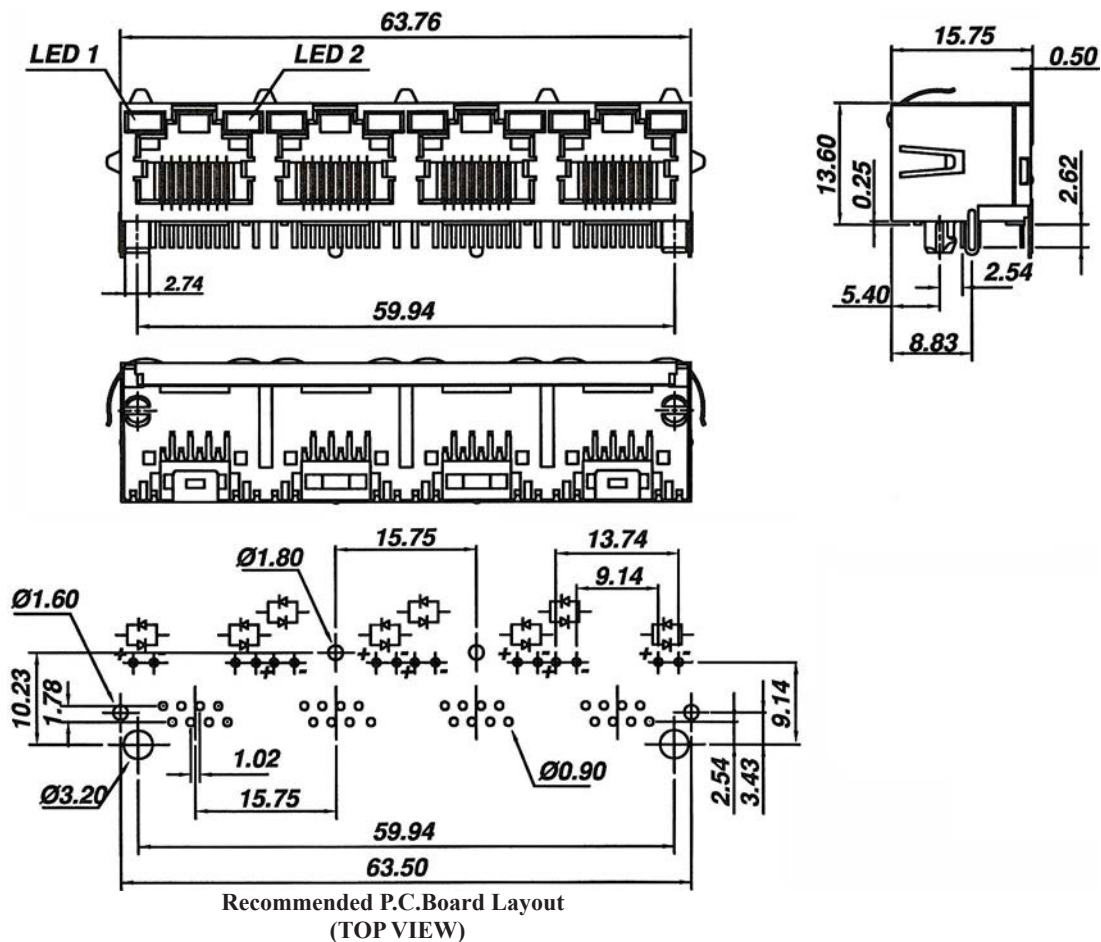
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
 Soldering Temperature: 260°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R S - $\frac{88}{1} \times \frac{B}{2} \times \frac{X}{3} \times \frac{X}{4} \times \frac{04}{5}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
04

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

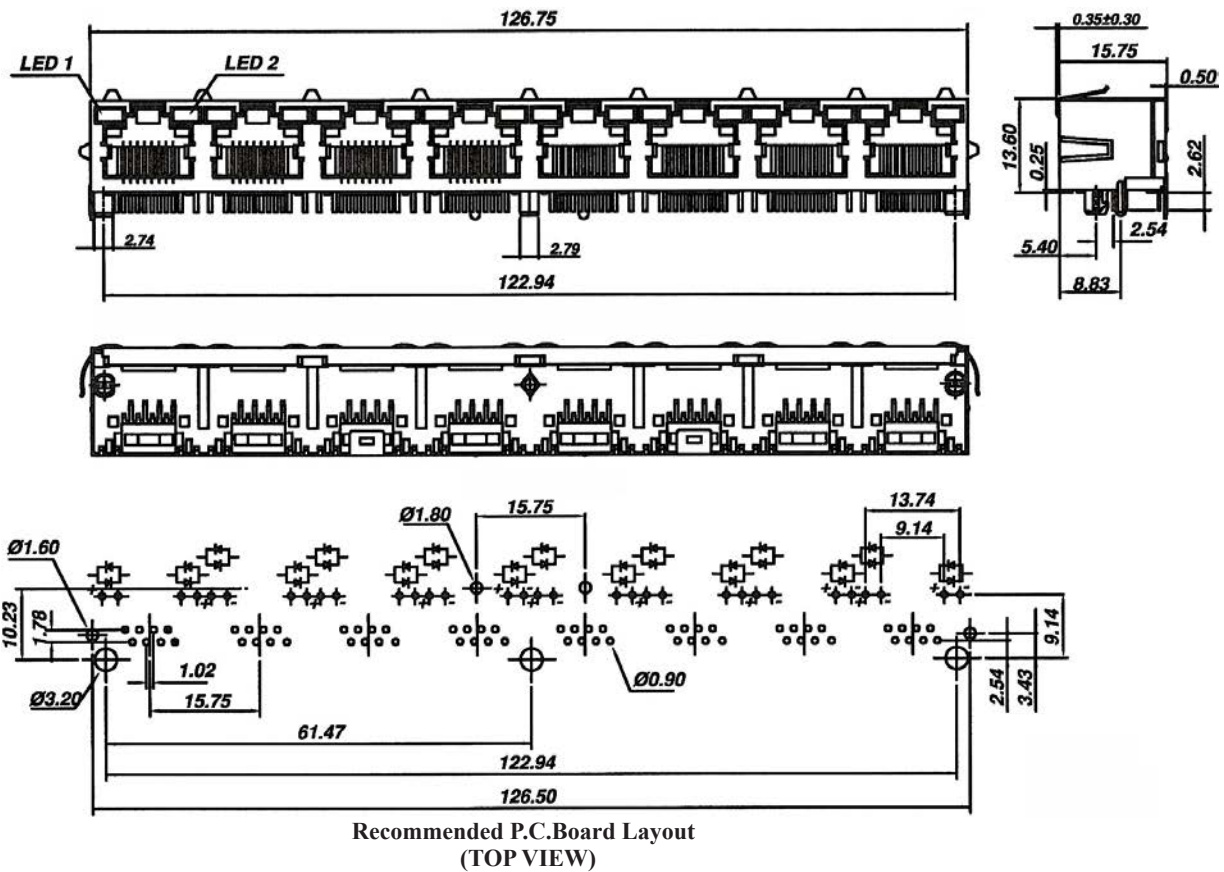
SIDE ENTRY 8-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
 Soldering Temperature: 260°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R S - $\frac{88}{1} \times \frac{B}{2} \times \frac{X}{3} \times \frac{X}{4} \times \frac{08}{5}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
08

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

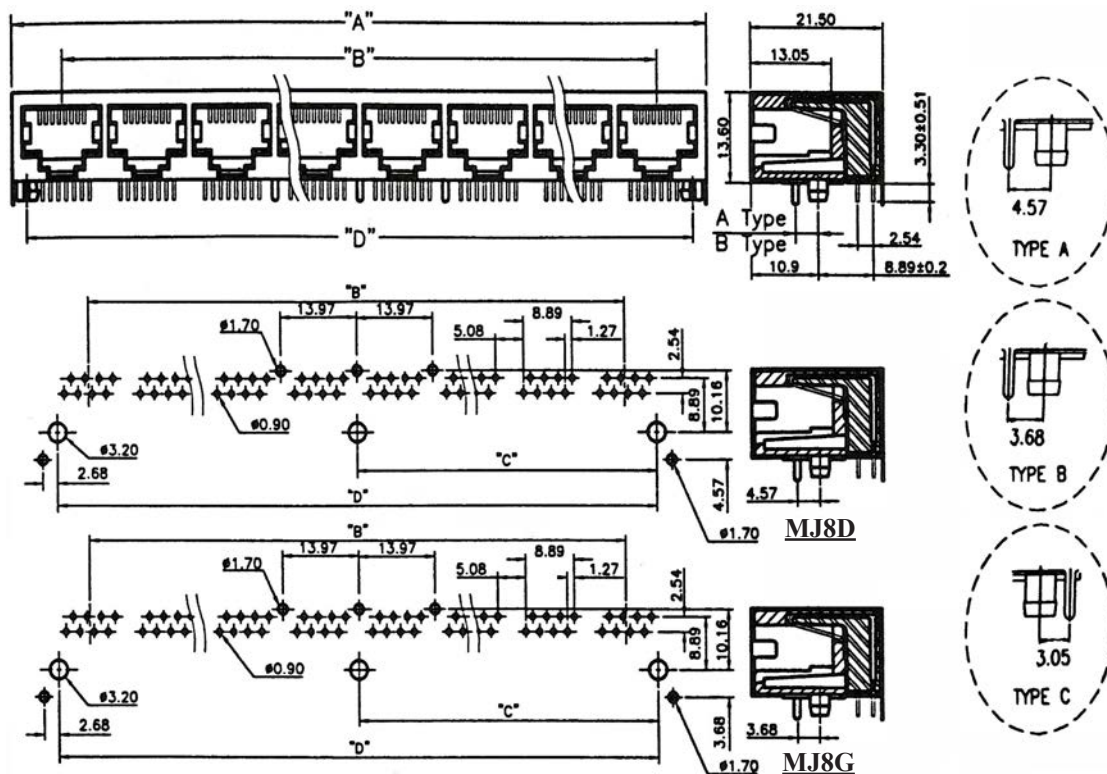
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



No. of Ports	DIM "A" ±0.25	DIM "B" ±0.20	DIM "C" ±0.10	DIM "D" ±0.15
02	31.24	13.97	----	25.40
04	59.18	41.91	26.67	53.34
06	87.12	69.85	40.64	81.28
08	115.06	97.79	54.61	109.22

ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B $\frac{x}{4}$

- TYPE OF PIN SPACING:
 "8D" TYPE A
 "8G" TYPE B
 "8X" TYPE C
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 02, 04, 05, 06, 08

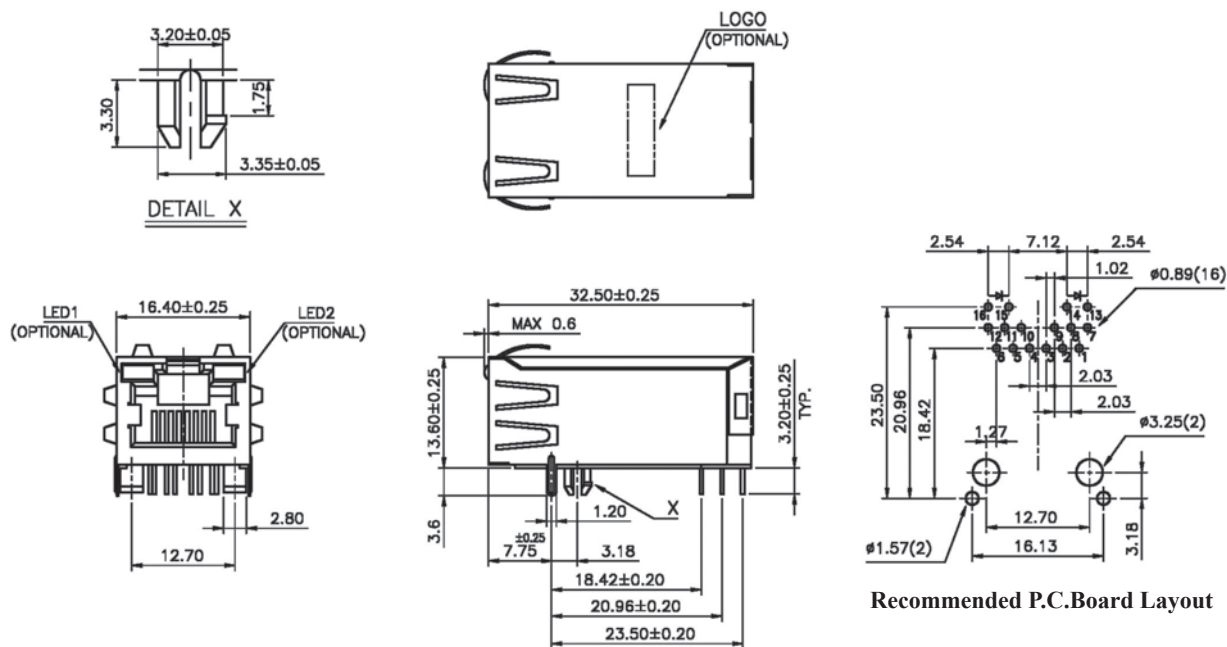
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J H A - $\frac{88}{1} \times \frac{B}{2} \times \frac{XX}{3} \times \frac{XX}{4}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. HOUSING COLOR:
"B" BLACK

4. COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

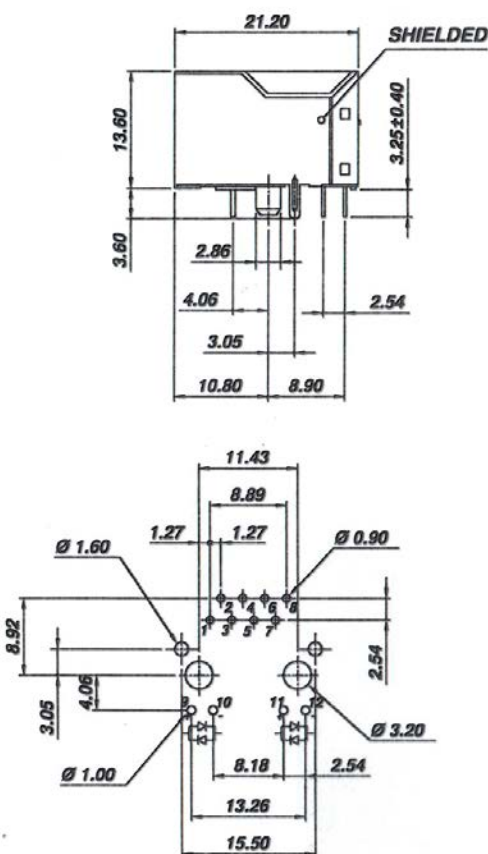
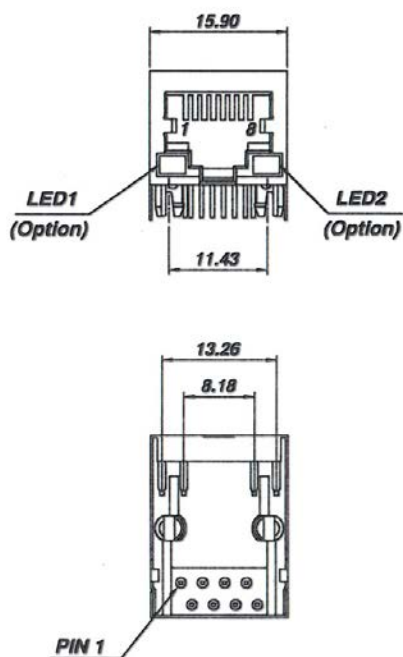
SIDE ENTRY MODULAR PCB JACK WITH LED 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C To +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled UL 94V-0, Black
 Contacts: Phosphor Bronze
 Spring Wire: 0.35mm Phosphor Bronze Gold Plated
 over Nickel
 Shield: Brass Plating Nickel
 *RoHS & REACH compliant.



Recommended P.C.Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J S P - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- TYPE OF LED POLARITY:
(LED PIN DIRECTION FROM LEFT TO RIGHT)
1N, 1Y, 1Z, 55, 58, 5Q, 85, MM, MY, MZ, N5, NN,
NY, NZ, Q5, Y1, Y2, YM, YN, Z1, Z2, ZM, ZN

NOTE: 3.05MM SPACING BEHIND PEG

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

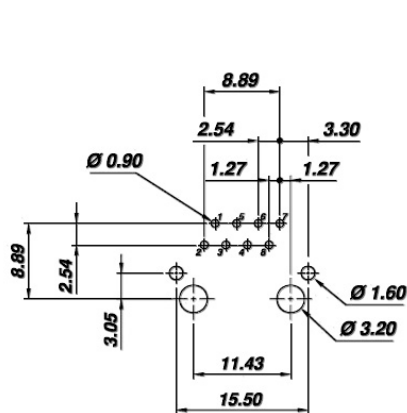
SIDE ENTRY CAT. 5 MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

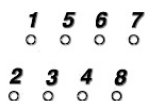
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

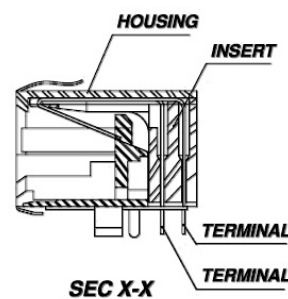
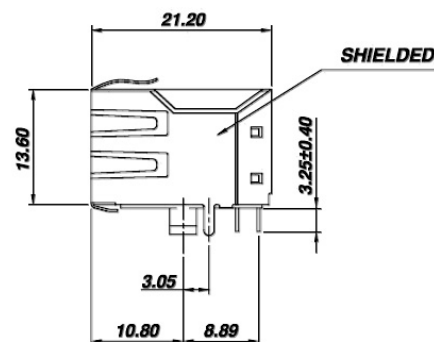
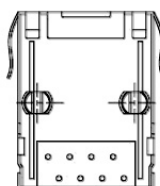
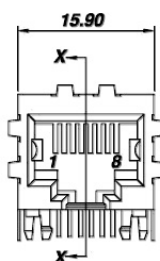
Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(Top View)



**CATEGORY 5
PCB LAYOUT**



ORDERING INFORMATION:

P/N M J S M - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEHIND PEG

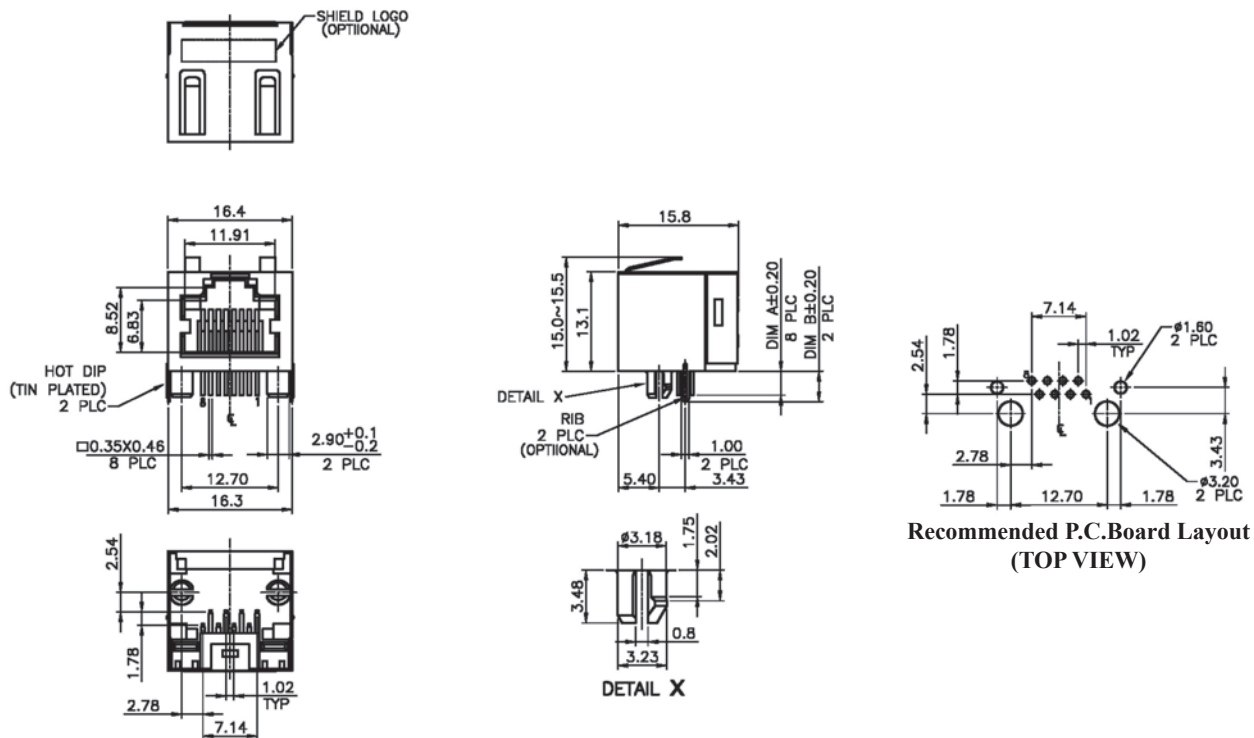
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N $\frac{M}{1} \frac{J}{2} \frac{HX}{3} - \frac{88}{4} \times \frac{B}{34}$

1. MODULAR JACK TYPE:
"HX" WITH TOP PANEL GROUND
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

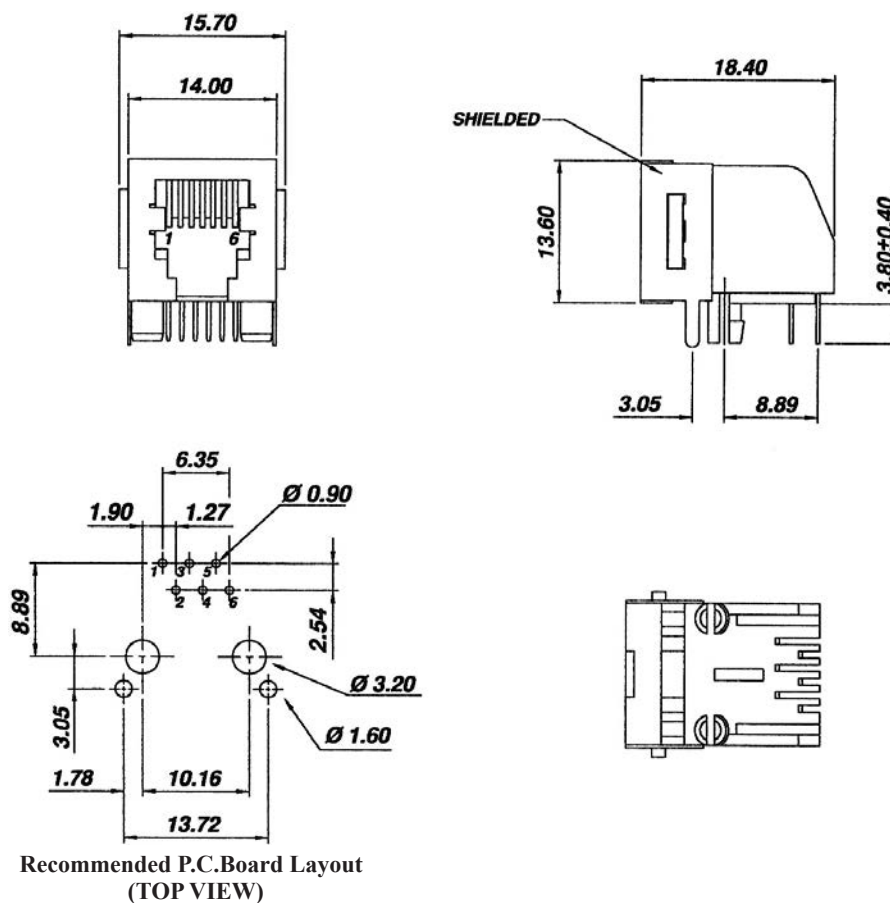
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R H - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJRHHT-6xxB for High Temp. Version

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

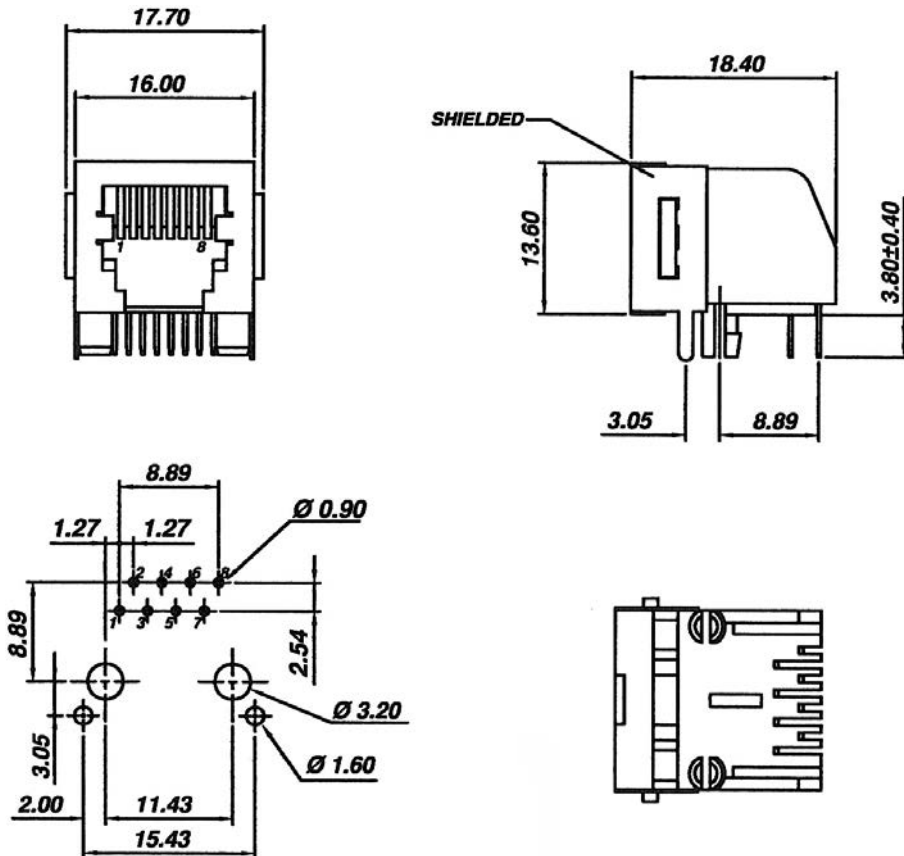
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J R H - $\frac{8}{1} \frac{8}{2} \times \frac{B}{3} \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION:

" " WITHOUT KEY

"K" WITH KEY

NOTE: P/N MJRHHT-88xB FOR HIGH TEMP. VERSION

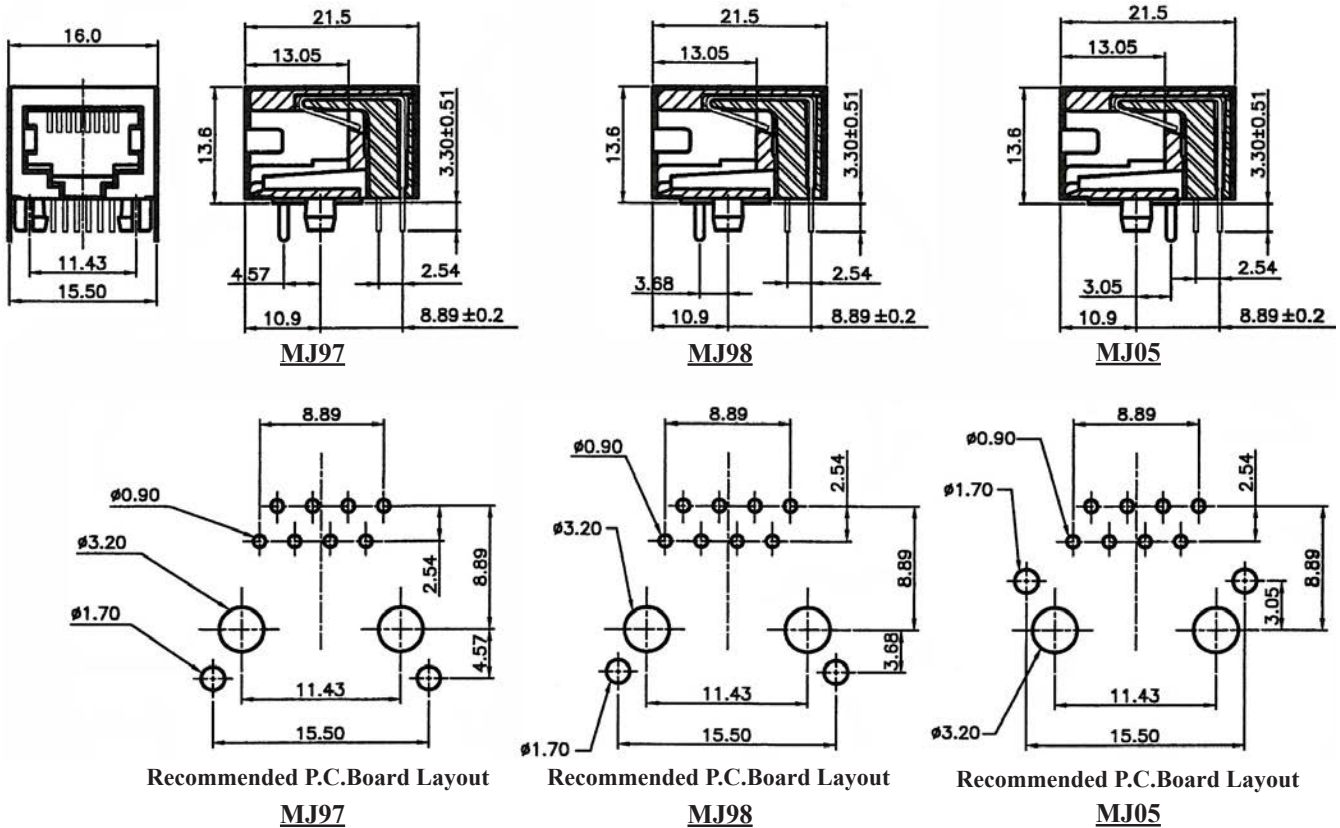
SIDE ENTRY MODULAR PCB JACK WITH ROUND PINS 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B

1. TYPE OF JACKS:
 "97" A TYPE
 "98" B TYPE
 "05" C TYPE
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

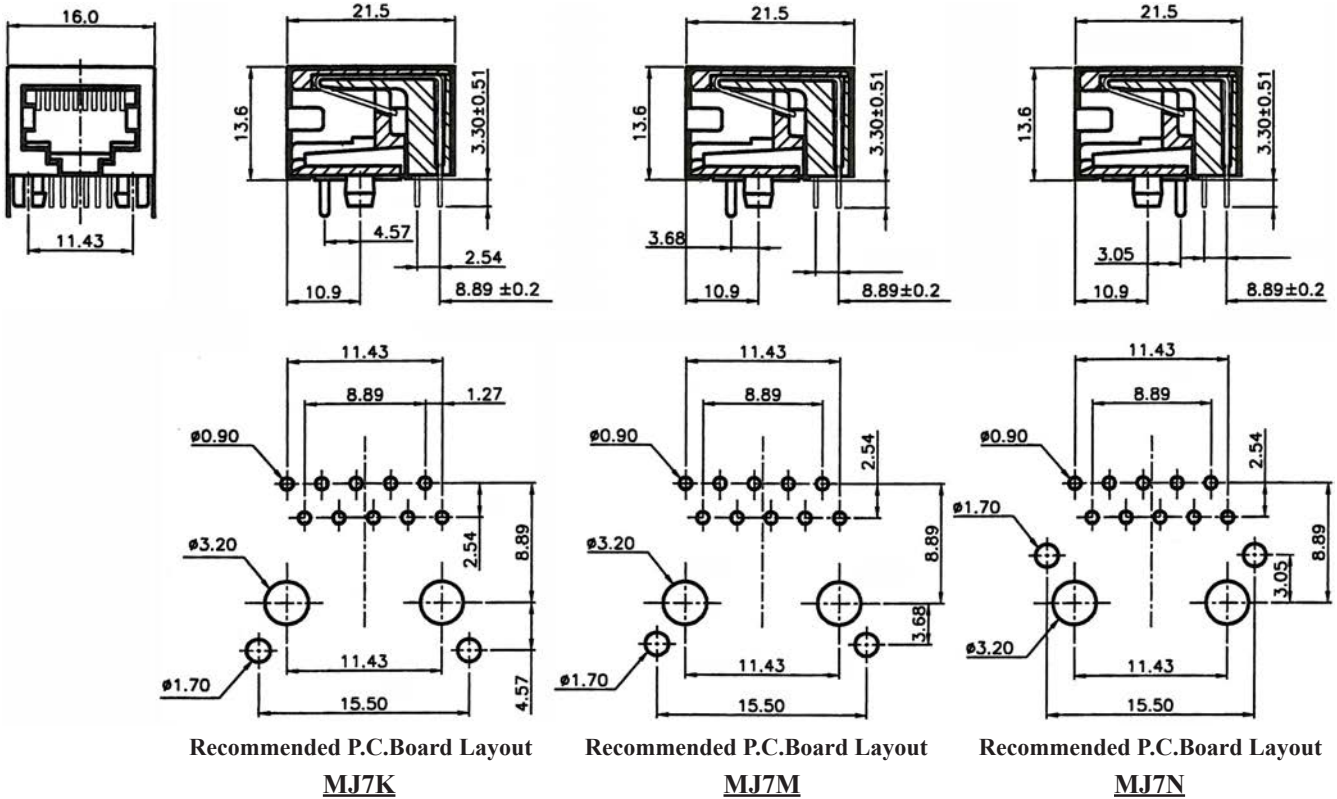
SIDE ENTRY MODULAR PCB JACK WITH ROUND PINS 10P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{x}{2}$ $\frac{x}{3}$ B

1. TYPE OF JACKS:
 "7K" A TYPE
 "7M" B TYPE
 "7N" C TYPE
2. NO. OF POSITIONS & CONTACTS:
 "00" 10P10C
 "08" 10P8C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

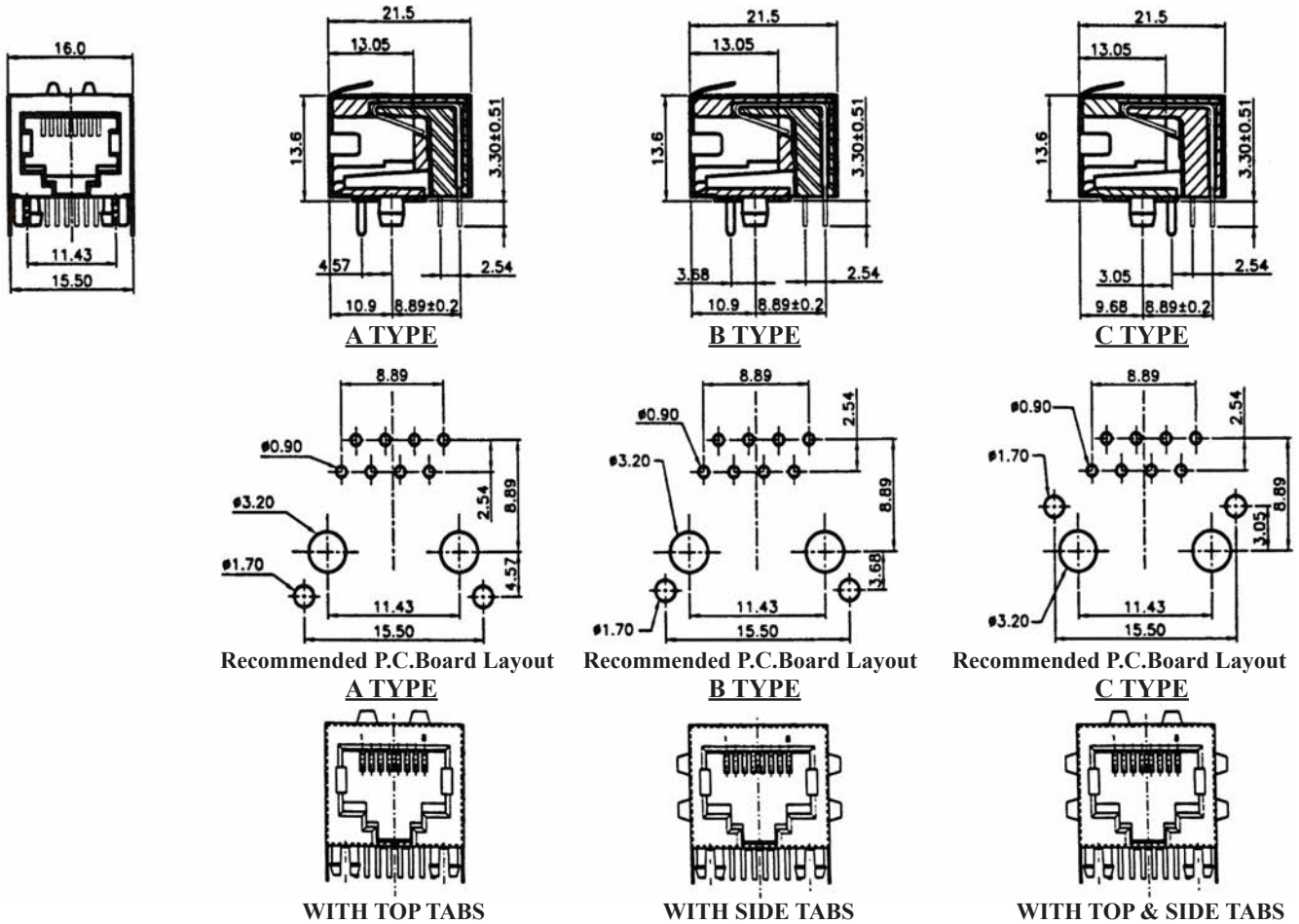
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.60MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B

- CONTACT & PANEL GROUND (TAB) TYPE:
 95, 96, 06, 1A, 1B, 1C, 1D, 1E, 1F
 V1, V2, V3, V4, V5, V6, V7, V8, V9
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

	STANDARD TYPE			CATEGORY 5		
CONTACT TYPE	A	B	C	A	B	C
WITH TOP TABS	95	96	06	V1	V2	V3
WITH SIDE TABS	1A	1B	1C	V4	V5	V6
WITH TOP & SIDE TABS	1D	1E	1F	V7	V8	V9

NOTE: P/N MJxxHT-88xB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

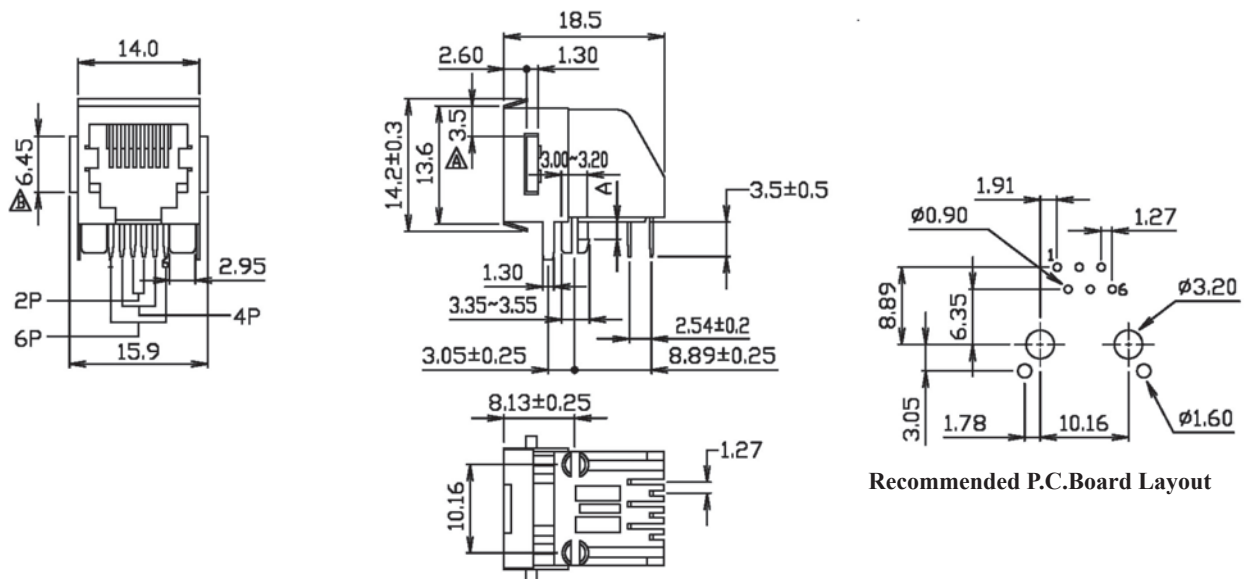
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{H}{1} U - \frac{x}{2} \frac{x}{3} \frac{x}{4} B$

1. MODULAR JACK TYPE:
"HU" PANEL GROUND TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

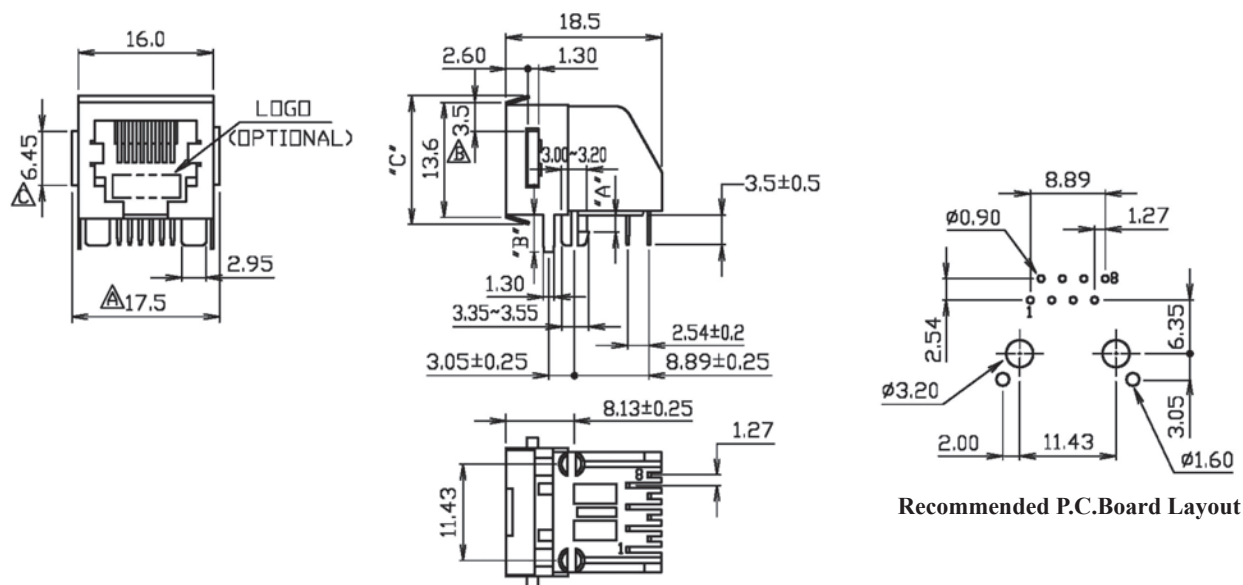
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°c / +85°c
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°c
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{H}{1}$ U - $\frac{88}{2}$ x $\frac{B}{34}$

1. MODULAR JACK TYPE:
"HU" PANEL GROUND TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

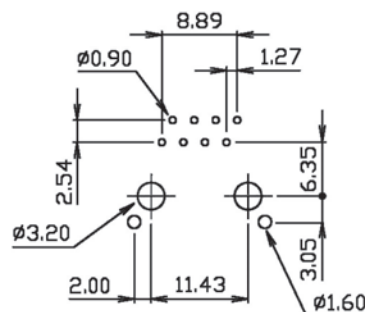
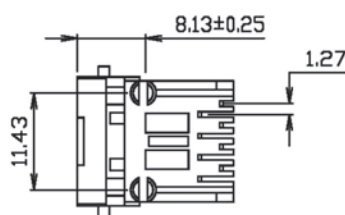
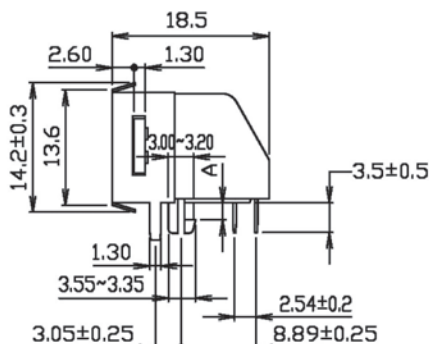
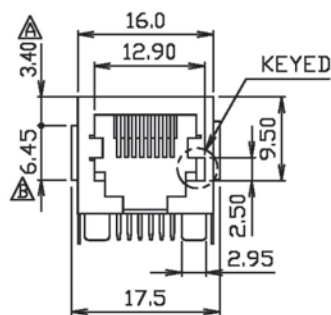
SIDE ENTRY MODULAR PCB JACK 8P WITH KEY PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J H V - 88 x B K
 1 2 3 4 5

1. MODULAR JACK TYPE:
"HV" PANEL GROUND TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. KEY OPTION:
"K" KEYED

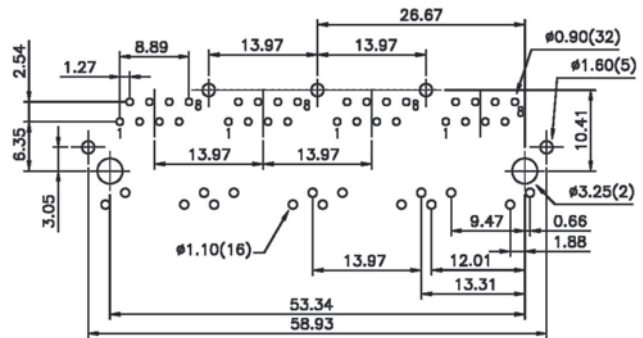
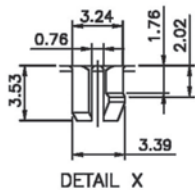
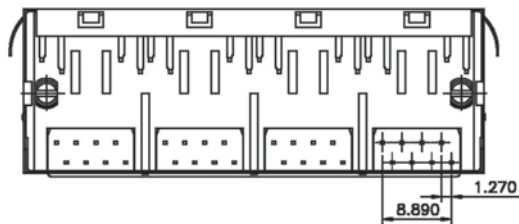
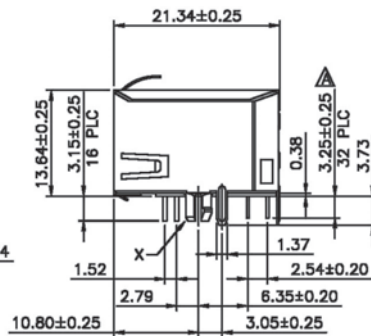
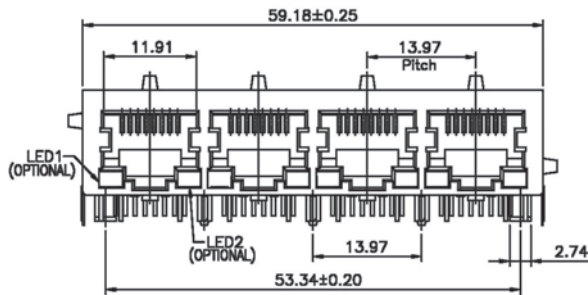
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P WITH LED PROFILE=13.64MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J K N - 8 8 x B x x 0 4
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"KN" WITH 3 SIDE PANEL GROUNDS & LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1/2 = GREEN/GREEN
"NY" LED1/2 = GREEN/YELLOW
"YN" LED1/2 = YELLOW/GREEN
"YY" LED1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
04

NOTE: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

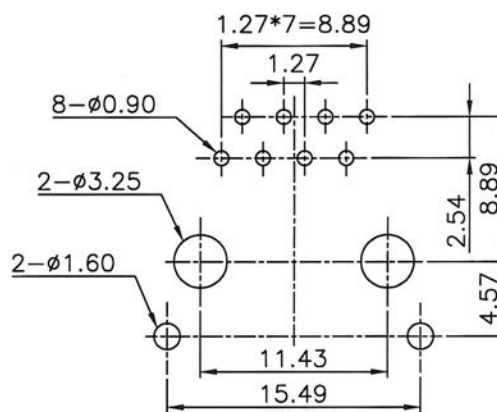
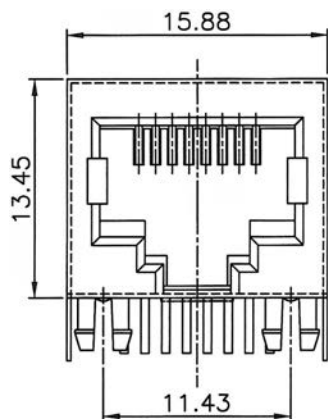
Color: Black

Spring Wire: Phosphor Bronze

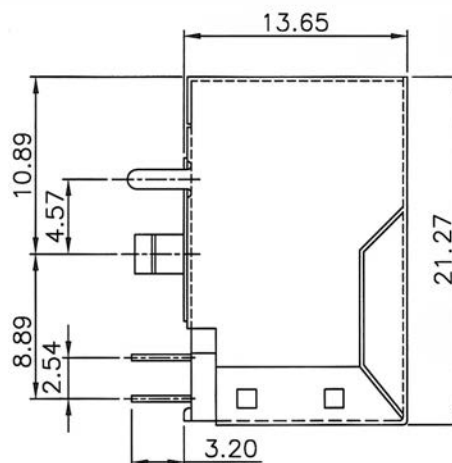
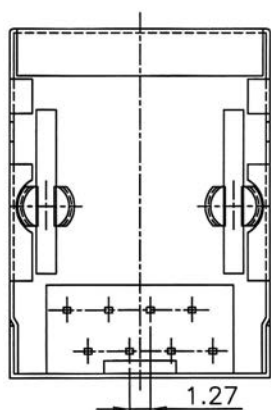
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{X}{3} B$

1. CATEGORY TYPE:

"8T" CAT. 3

"W1" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 4.57MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

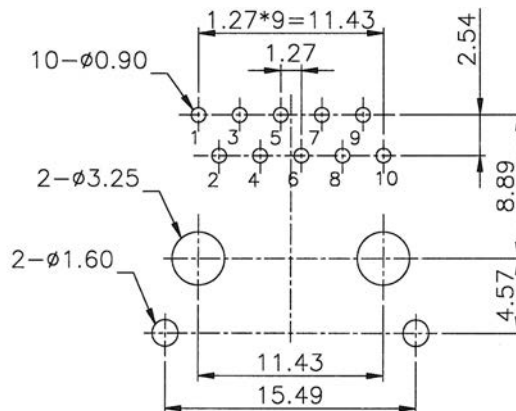
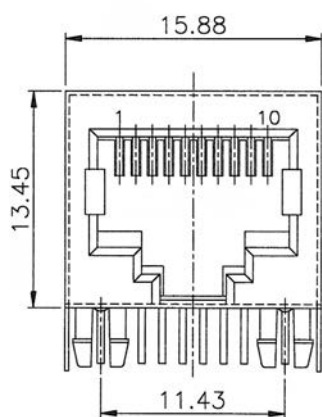
Color: Black

Spring Wire: Phosphor Bronze

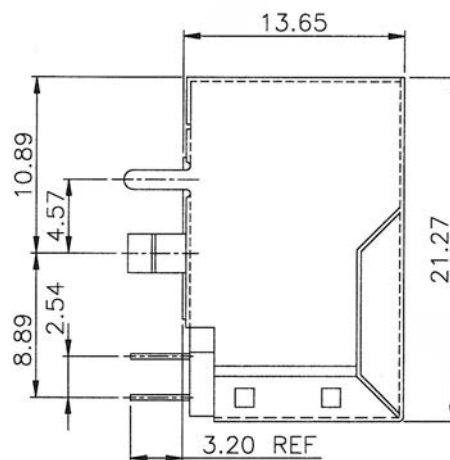
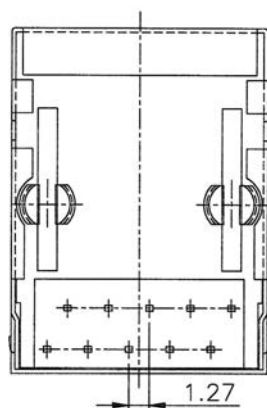
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJ8T-00 $\frac{x}{2}$ B

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=4.57MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

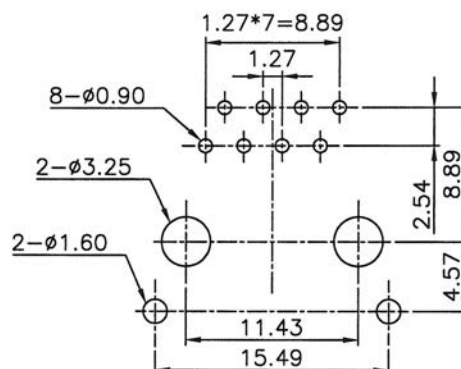
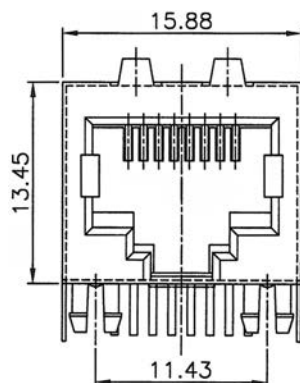
Color: Black

Spring Wire: Phosphor Bronze

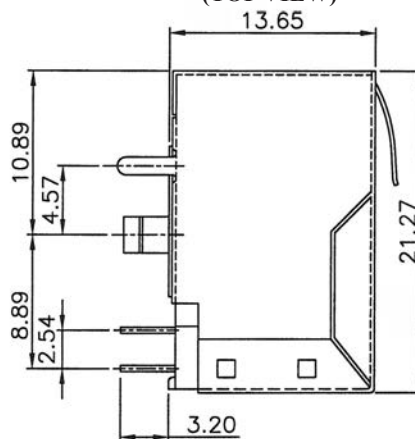
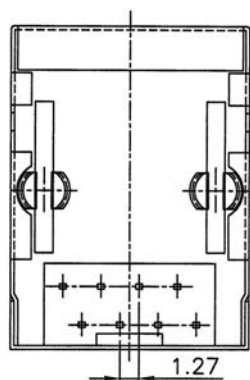
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{B}{3}$

1. CATEGORY TYPE:

"5M" CAT. 3

"V1" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=4.57MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

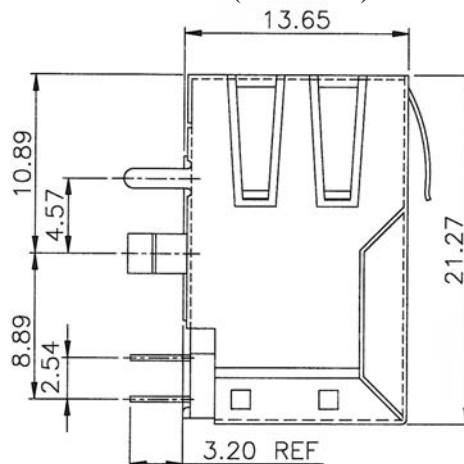
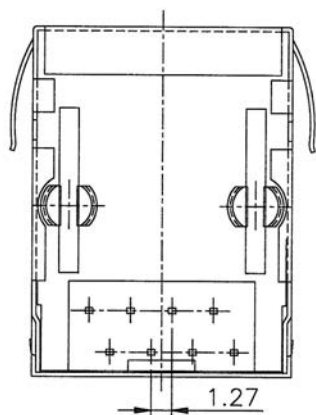
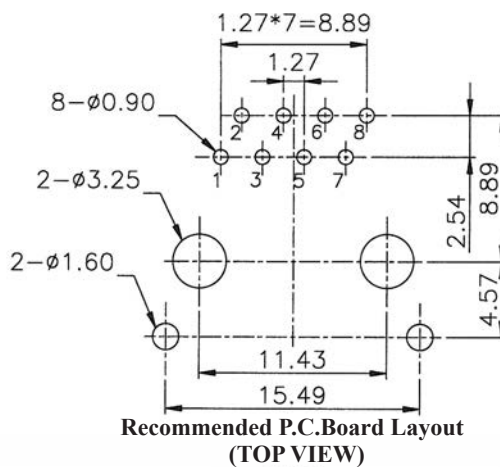
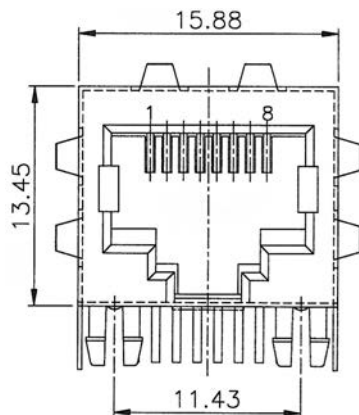
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B

1. CATEGORY TYPE:

"5X" CAT. 3

"V7" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=4.57MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

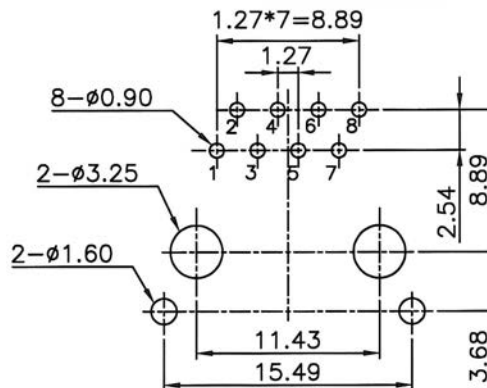
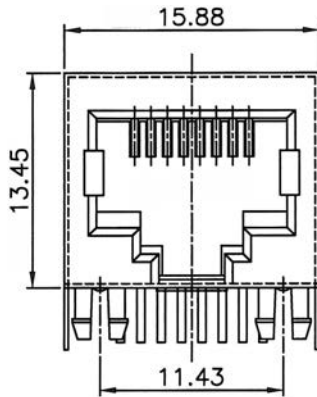
Color: Black

Spring Wire: Phosphor Bronze

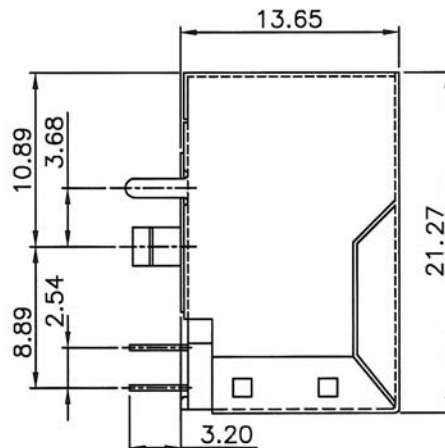
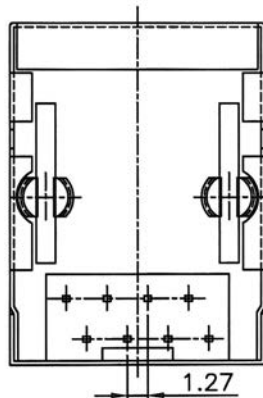
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XXX}{2}$ $\frac{X}{3}$ B

1. CATEGORY TYPE:

"8U" CAT. 3

"W2" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 3.68MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

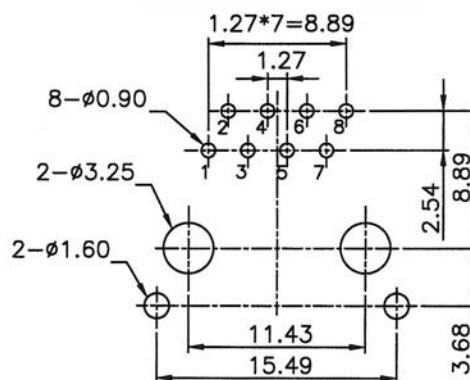
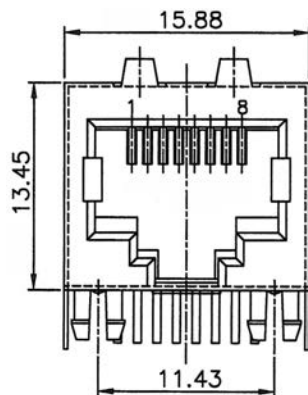
Color: Black

Spring Wire: Phosphor Bronze

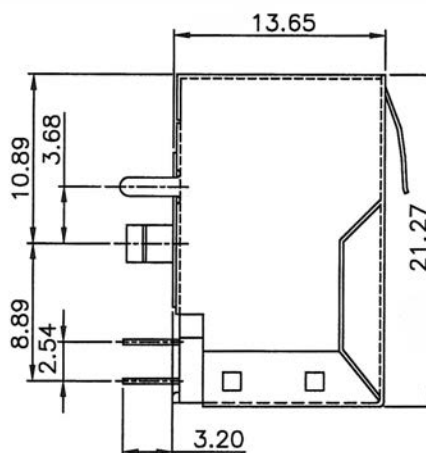
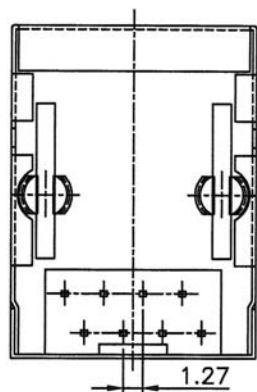
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XX}{2} \frac{X}{3} B$

1. CATEGORY TYPE:

"5N" CAT. 3

"V2" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.68MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

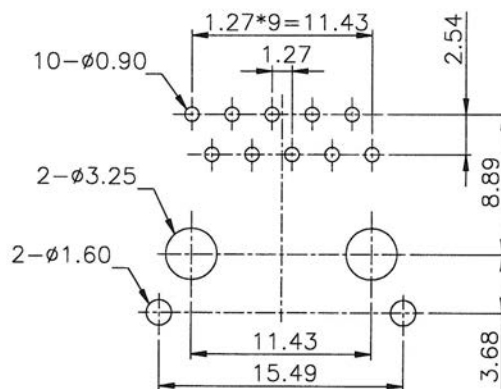
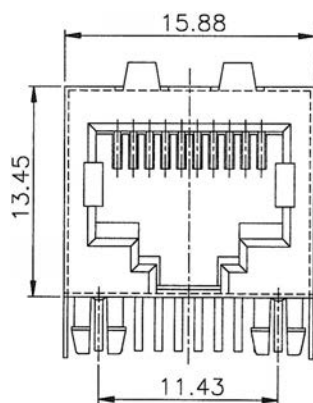
Color: Black

Spring Wire: Phosphor Bronze

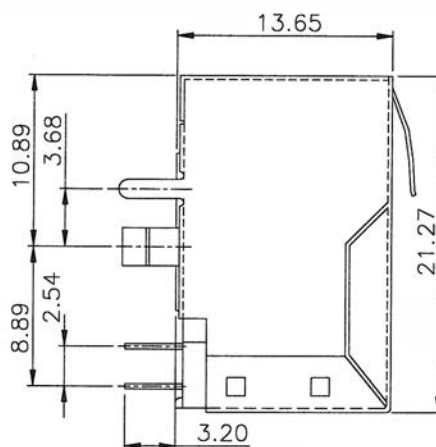
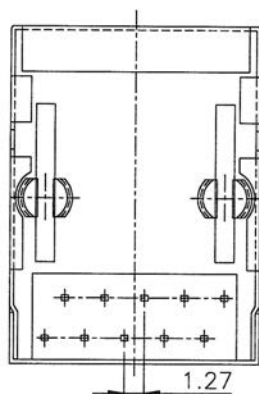
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJ5N - $\frac{00}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.68MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

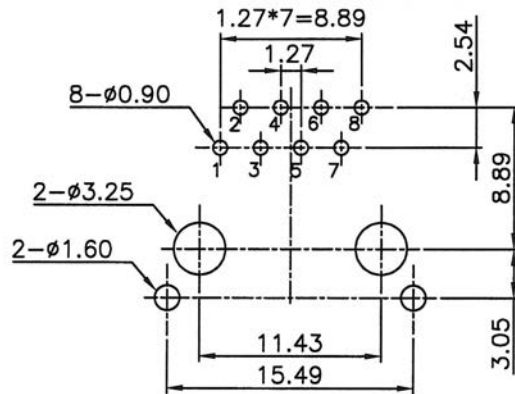
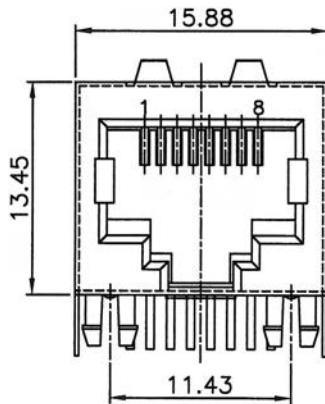
Color: Black

Spring Wire: Phosphor Bronze

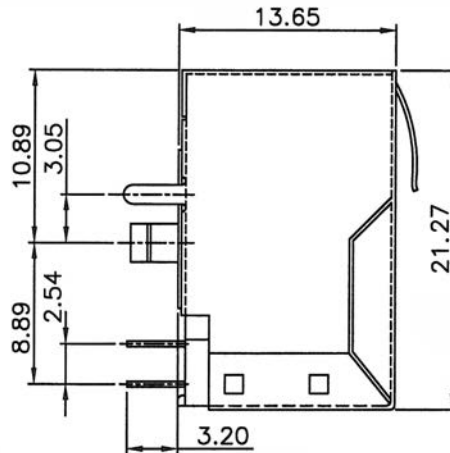
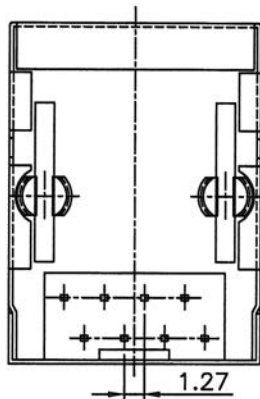
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B

1. CATEGORY TYPE:

"5J" CAT. 3

"W4" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.05MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

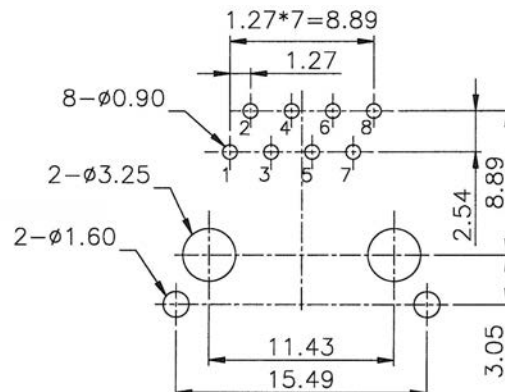
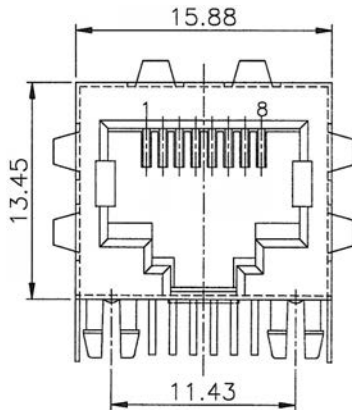
Color: Black

Spring Wire: Phosphor Bronze

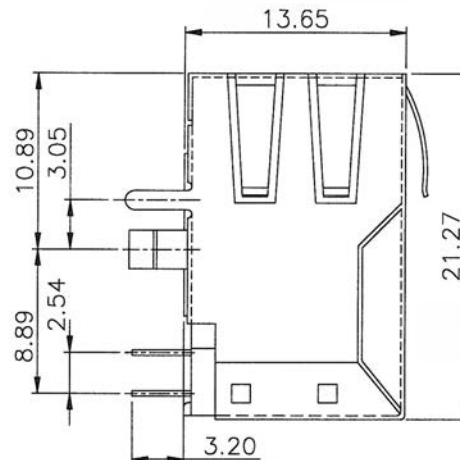
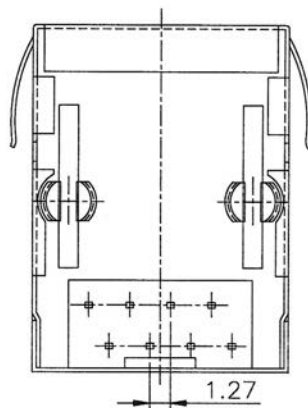
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{X}{3} B$

1. CATEGORY TYPE:

"5U" CAT. 3

"W5" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.05MM BEFORE PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

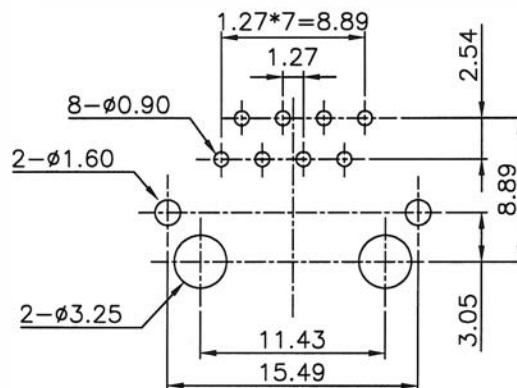
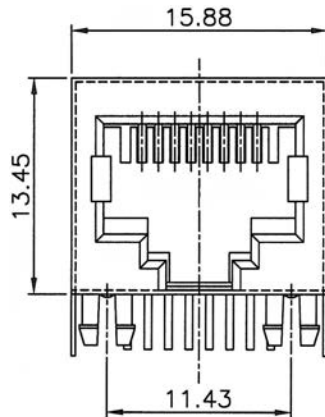
Color: Black

Spring Wire: Phosphor Bronze

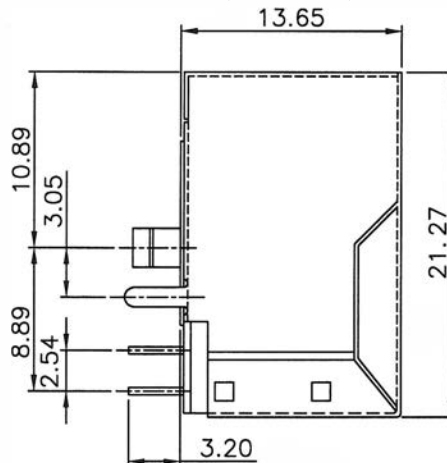
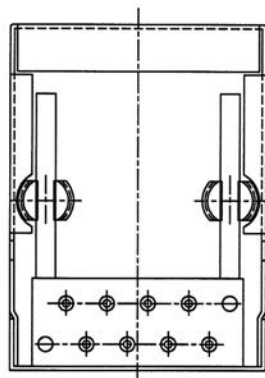
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{X X}{1} - \frac{X X X}{2 3} B$

1. CONTACT TYPE:

"05" ROUND PINS

"8V" STAMPED PINS

"W3" CAT. 5 STAMPED PINS

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 3.05MM BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

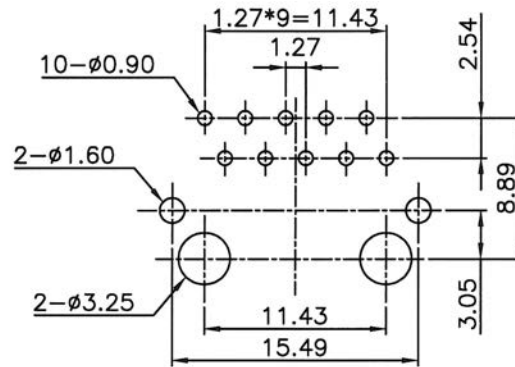
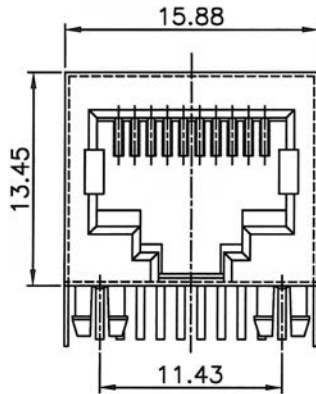
Color: Black

Spring Wire: Phosphor Bronze

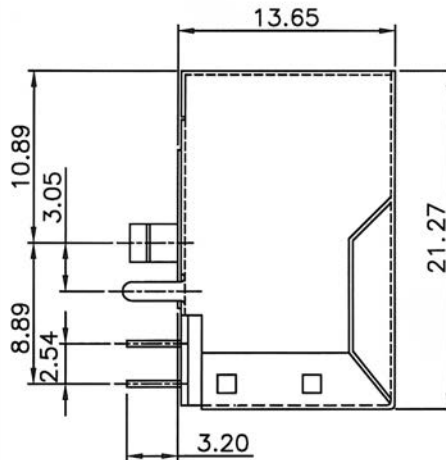
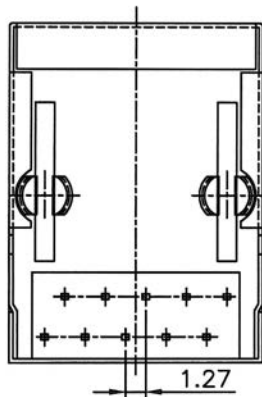
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J 8 V - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 3.05MM BEHIND PEG

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

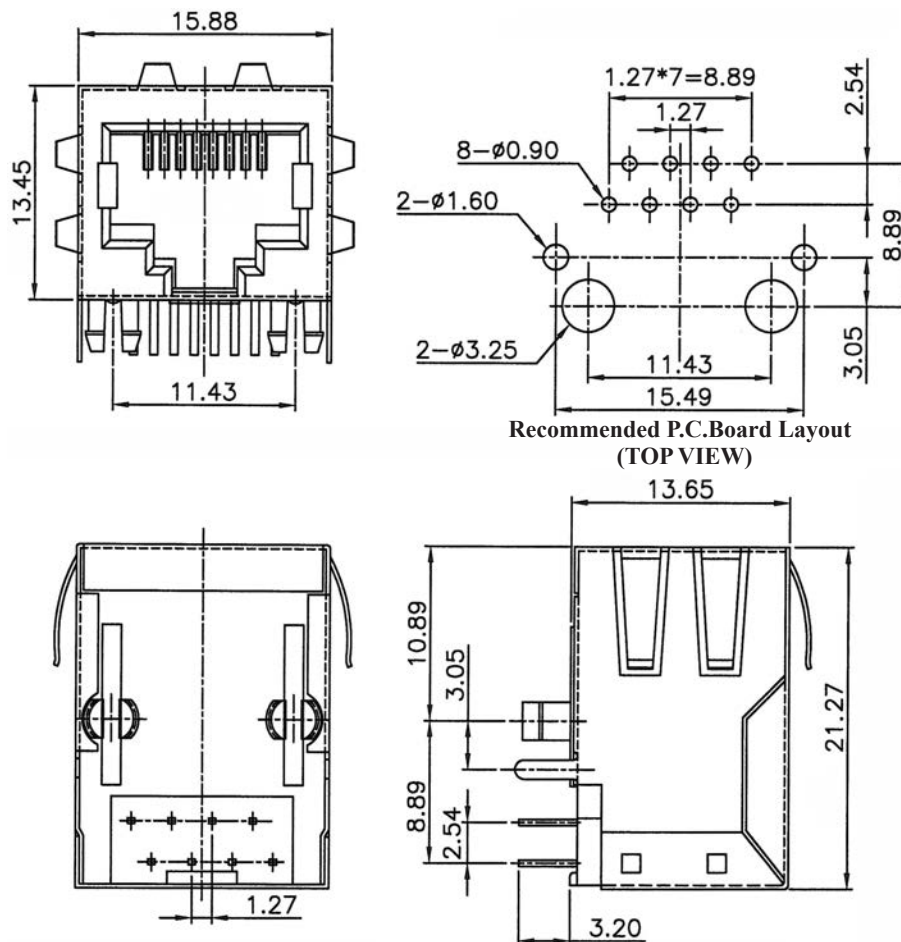
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B

1. CATEGORY TYPE:

"5Z" CAT. 3

"V9" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING= 3.05MM BEHIND PEG

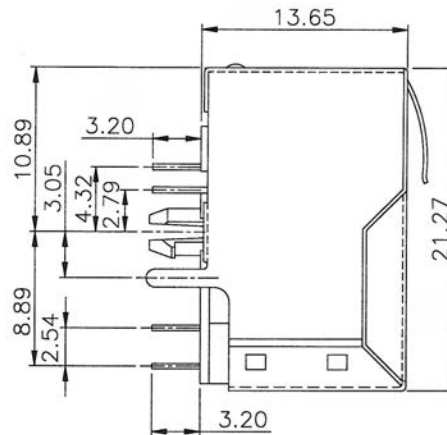
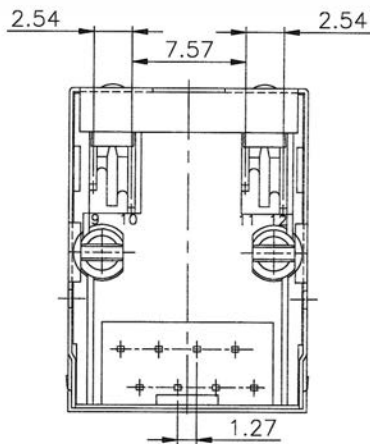
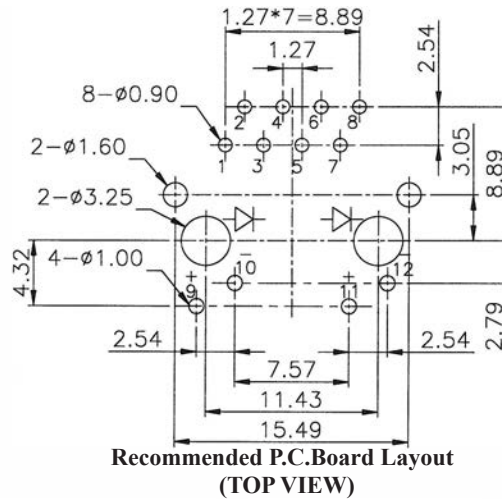
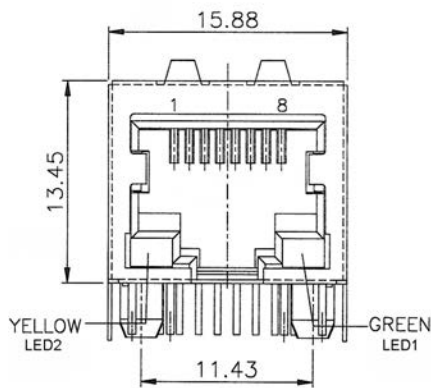
SIDE ENTRY MODULAR PCB JACK WITH LED 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1Y-88 x B x x
T 2 3 4

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

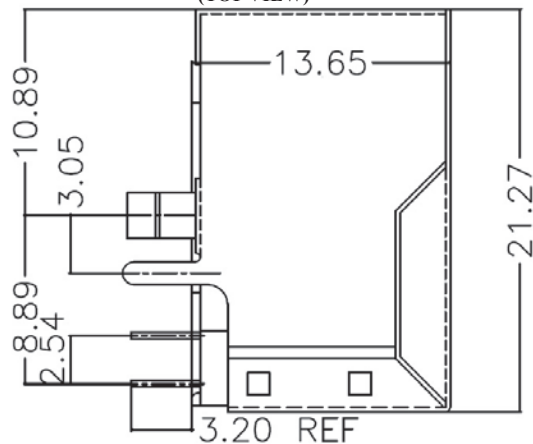
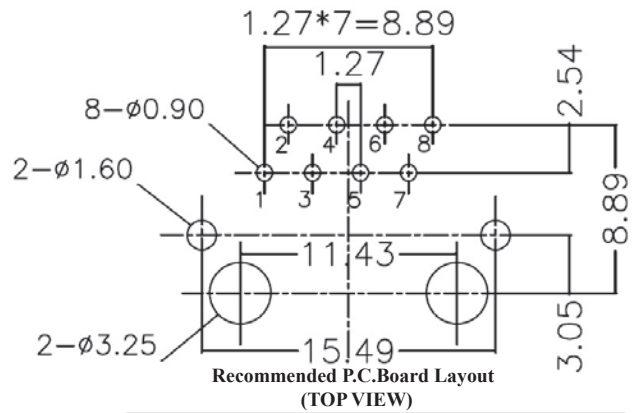
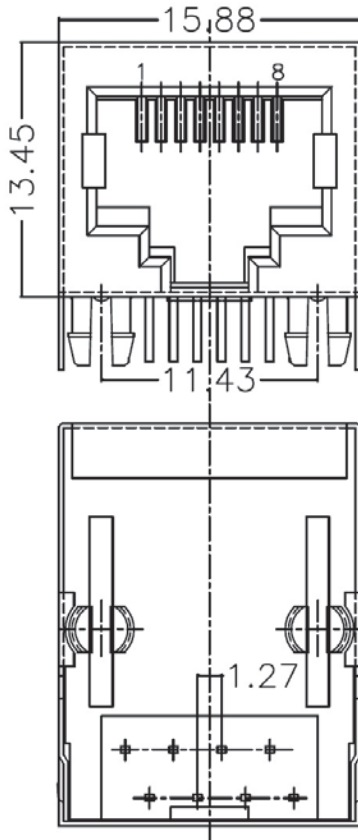
MATERIALS

Plastic Housing: Engineering Thermoplastic
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N **M J 8 V J- 88 x B**
 1 2 3

1. MODULAR JACK TYPE:
"8VJ" 3.05MM SPACING BEHIND PEG
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE 1: IT CAN BE USED FOR REPLACING P/N MJ8V-88xB.

NOTE 2: 3.05MM SPACING BEHIND PEG

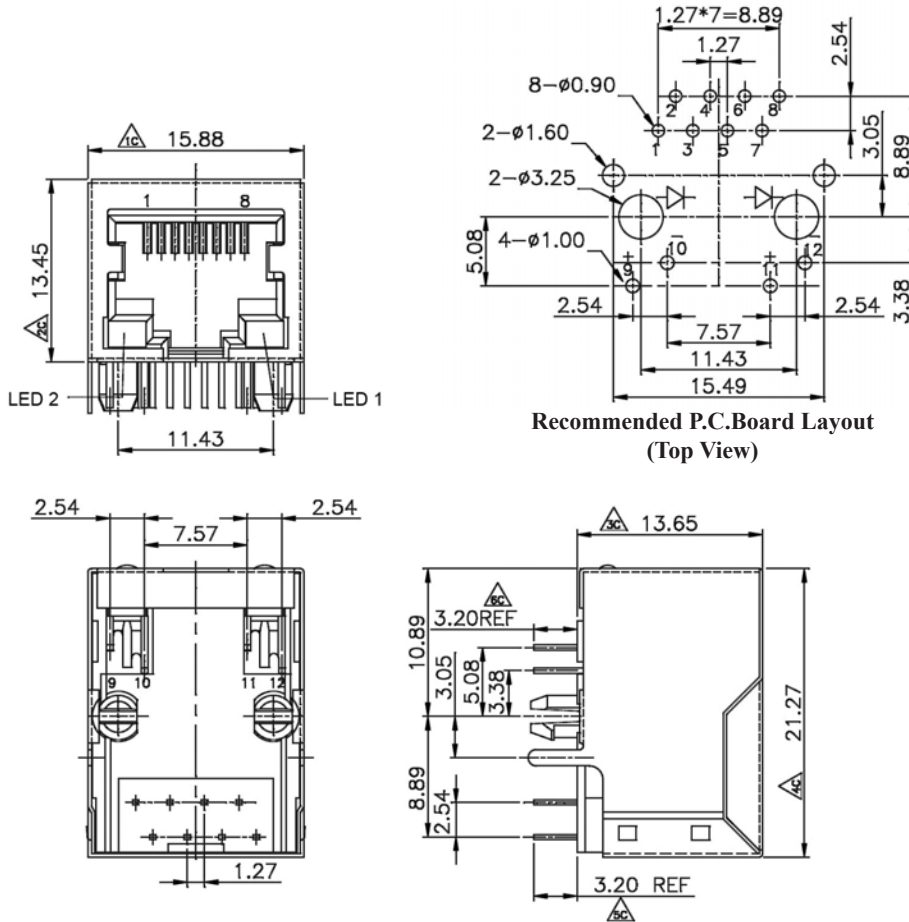
SIDE ENTRY MODULAR PCB JACK WITH LED 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

- Insulation Resistance: 500MΩ Min.
- Contact Resistance: 20mΩ Max.
- Rating Current: 1.5A Max.
- Rating Voltage: 120V AC.
- Dielectric Voltage: 1000 Vrms 60 Sec. Min.
- Temperature Range: -40°C / +85°C
- Durability: 500 Mating cycles Min.

MATERIALS

- Housing: PBT Glass Filled (UL 94V-0)
- Soldering Temperature: 235°C
- Color: Black
- Spring Wire: Phosphor Bronze
Gold plating Over Nickel
- Shield: Brass plating Nickel Alloy
- *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 X - $\frac{88}{T} \times \frac{B}{2} \times \frac{X}{34}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

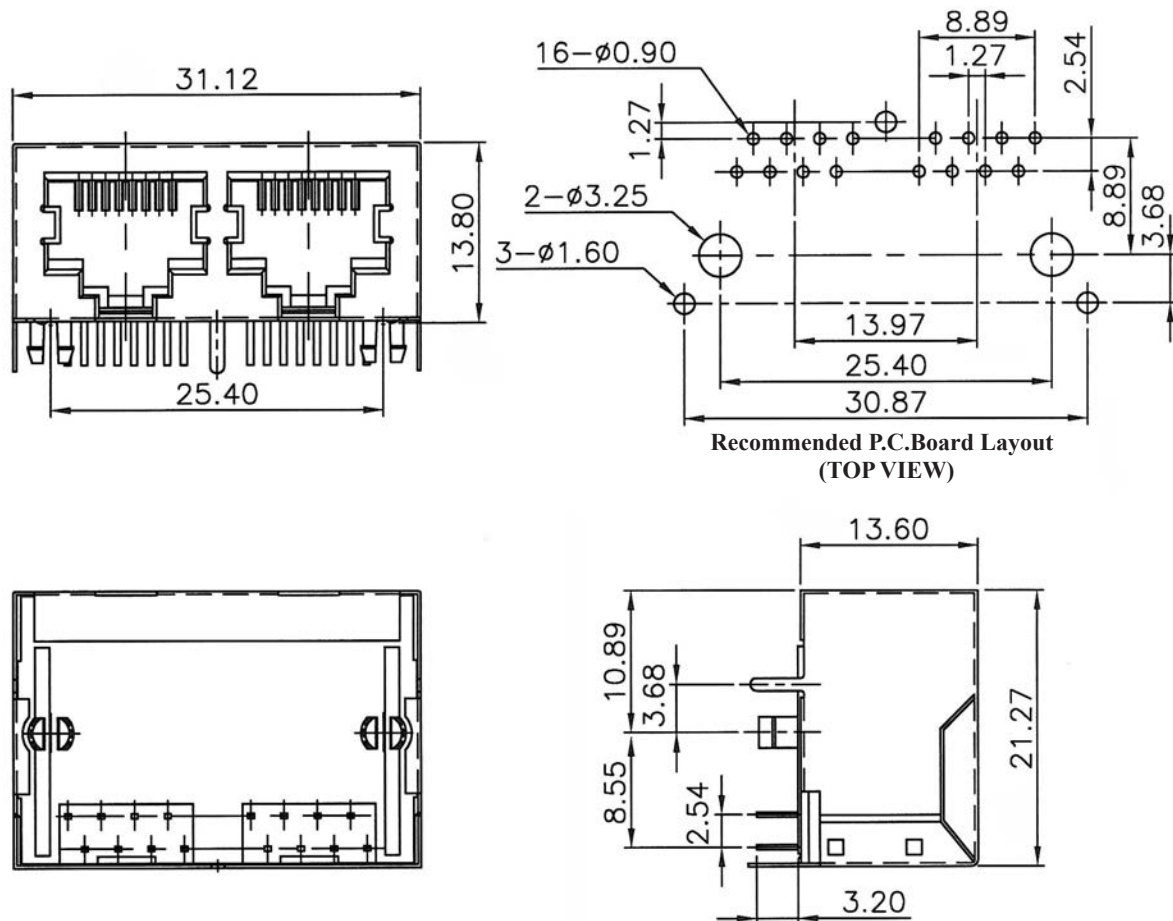
SIDE ENTRY 2-PORT CAT. 3 & 5 MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{23} B \frac{02}{4}$

- CATEGORY TYPE:
"24" CAT. 3
"Y3" CAT. 5
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- NO. OF PORTS:
02

NOTE: 3.68MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT CAT. 3 & 5 MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

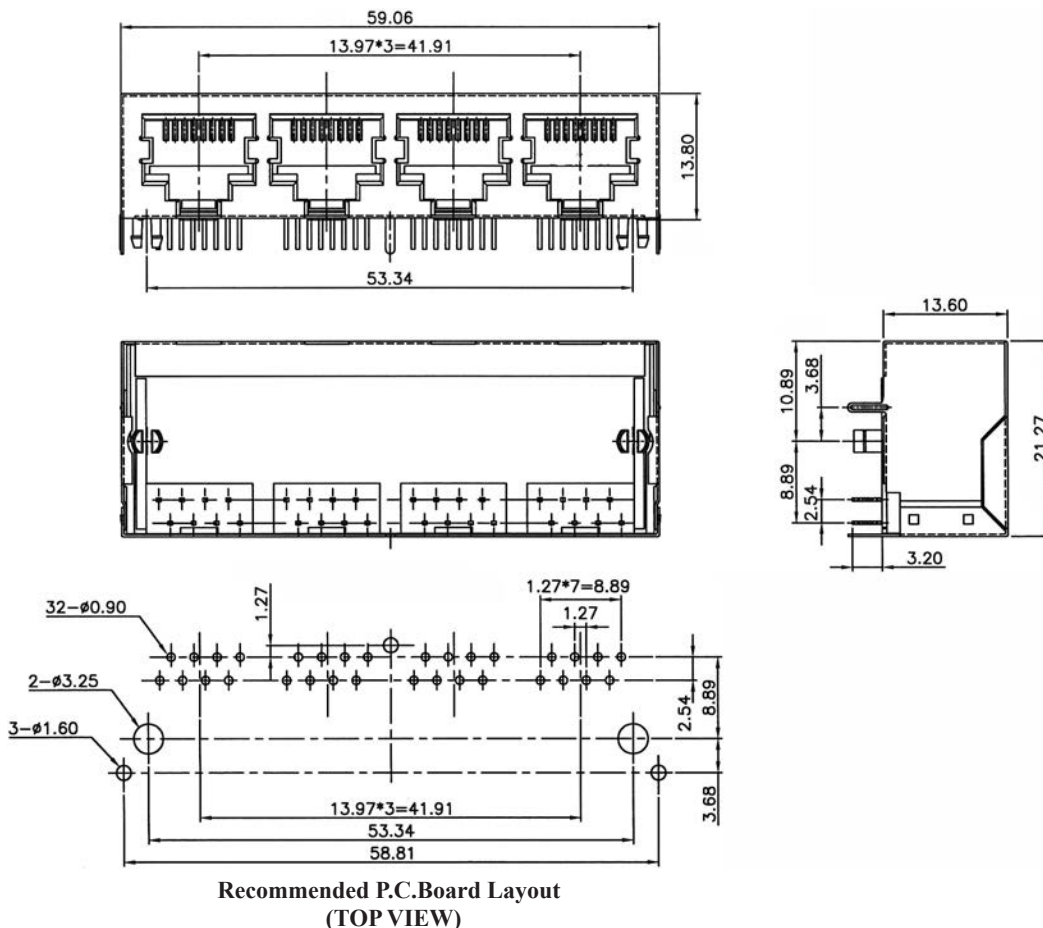
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B $\frac{04}{4}$

1. CATEGORY TYPE:

"24" CAT. 3

"Y3" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

4. NO. OF PORTS:

04

NOTE: 3.68MM SPACING BEFORE PEG

SIDE ENTRY 5-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

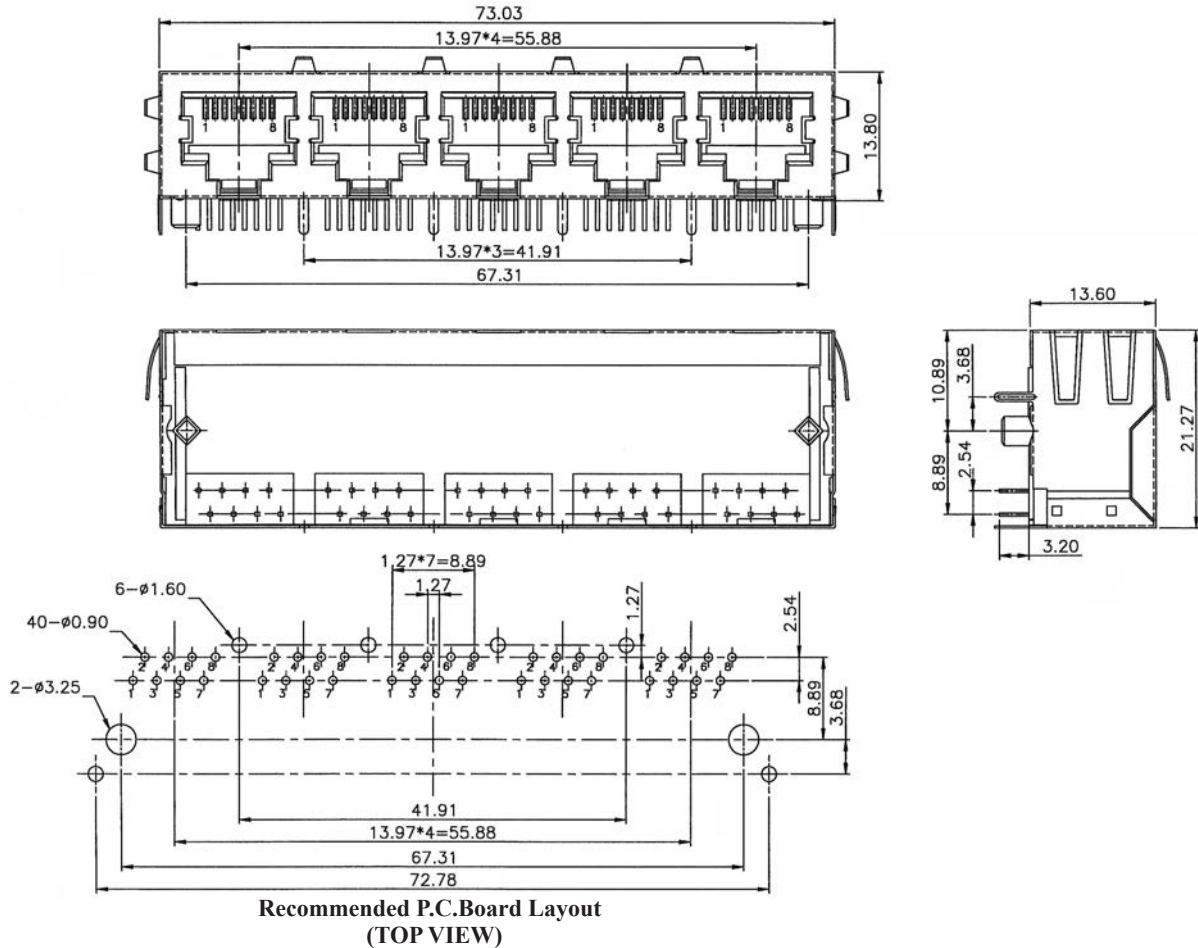
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B $\frac{05}{4}$

1. CATEGORY TYPE:

"25" CAT. 3

"Y2" CAT. 5

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

4. NO. OF PORTS:

05

NOTE: 3.68MM SPACING BEFORE PEG

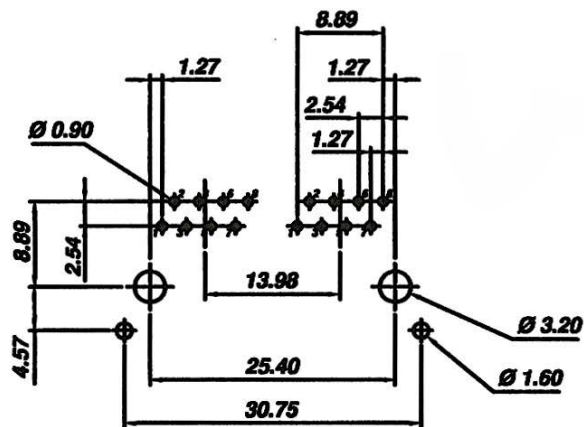
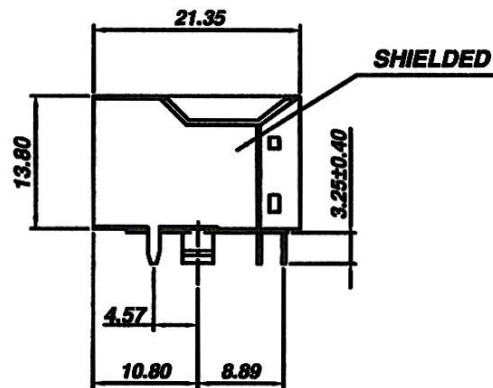
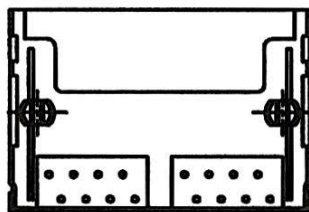
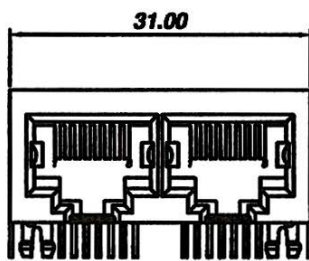
SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJSJ - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
02

NOTE 1: P/N MJSJHT-88xB02 FOR HIGH TEMP. VERSION
NOTE 2: 4.57MM SPACING BEFORE PEG

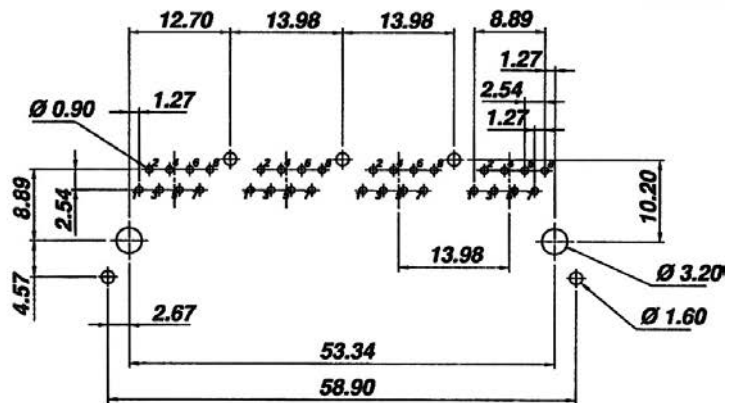
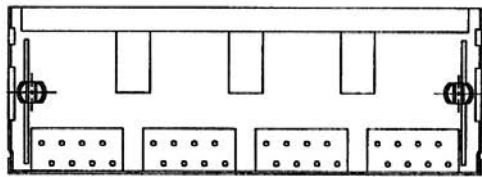
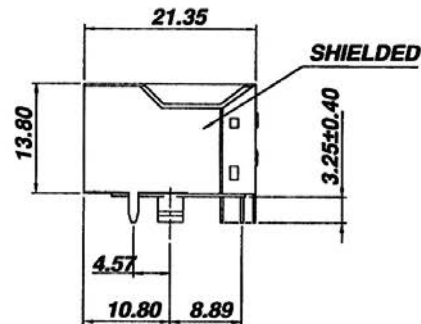
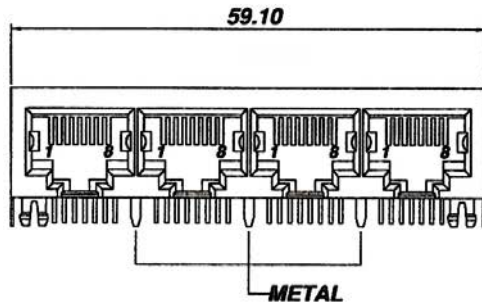
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJSJ - $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
04

NOTE 1: P/N MJSJHT-88xB04 FOR HIGH TEMP. VERSION
NOTE 2: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 5-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

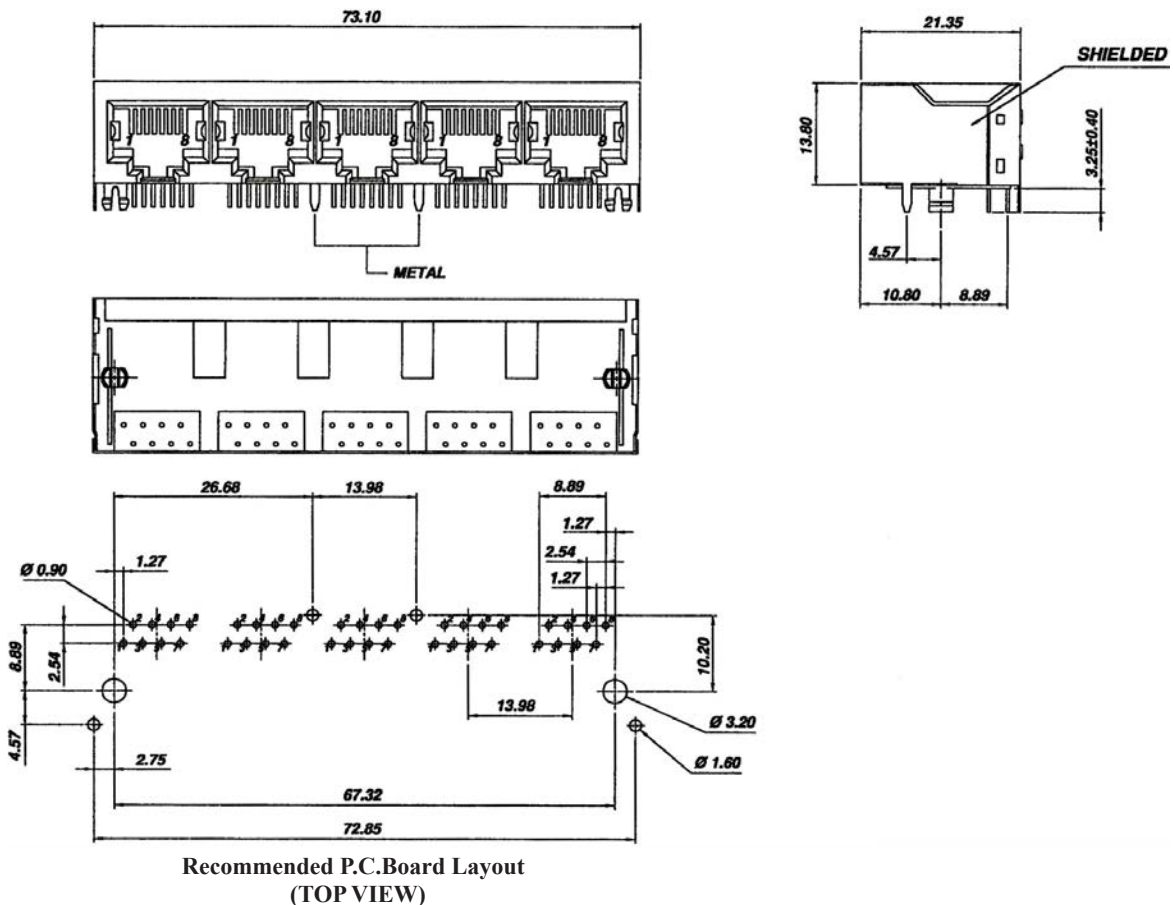
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJSJ - $\frac{88}{1} \times \frac{B}{2} \frac{05}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

05

NOTE 1: P/N MJSJHT-88xB05 FOR HIGH TEMP. VERSION

NOTE 2: 4.57MM SPACING BEFORE PEG

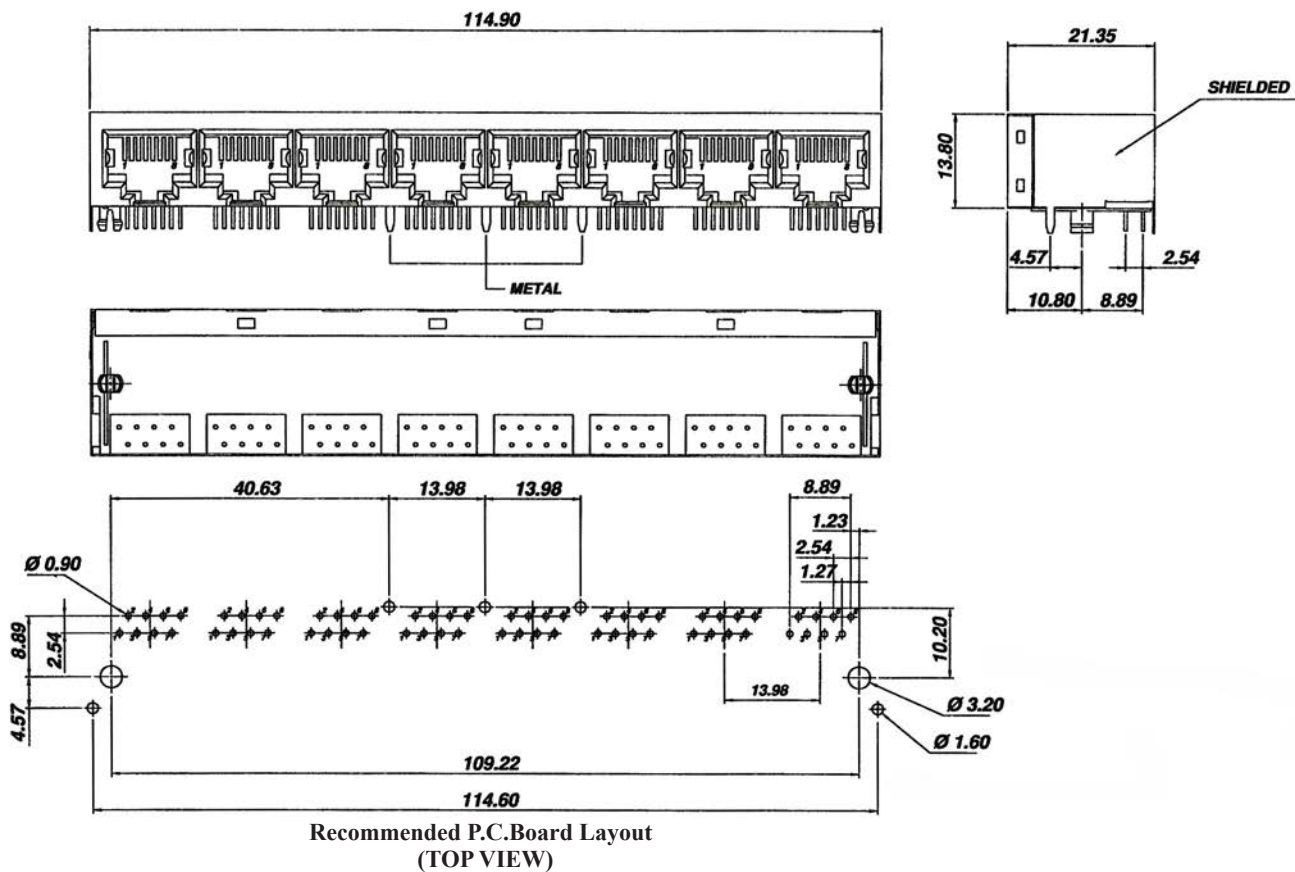
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJSJ - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
08

NOTE 1: P/N MJSJHT-88xB08 FOR HIGH TEMP. VERSION
 NOTE 2: 4.57MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

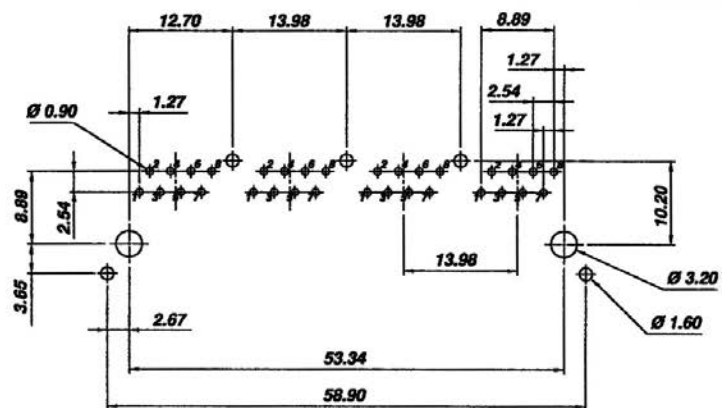
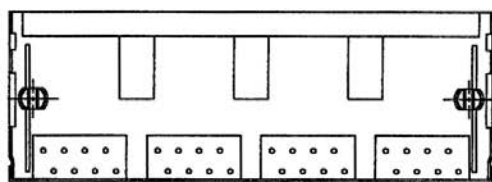
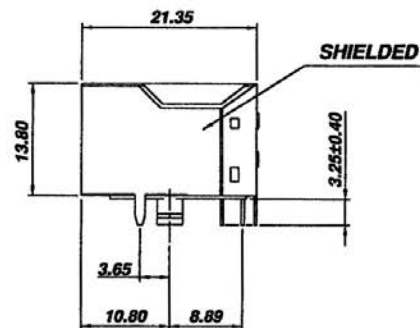
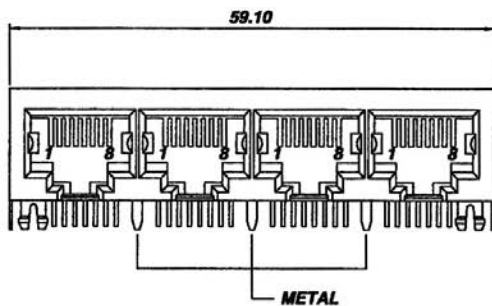
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJSK - $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE 1: P/N MJSKHT-88xB04 FOR HIGH TEMP. VERSION

NOTE 2: 3.65MM SPACING BEFORE PEG

SIDE ENTRY 6-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

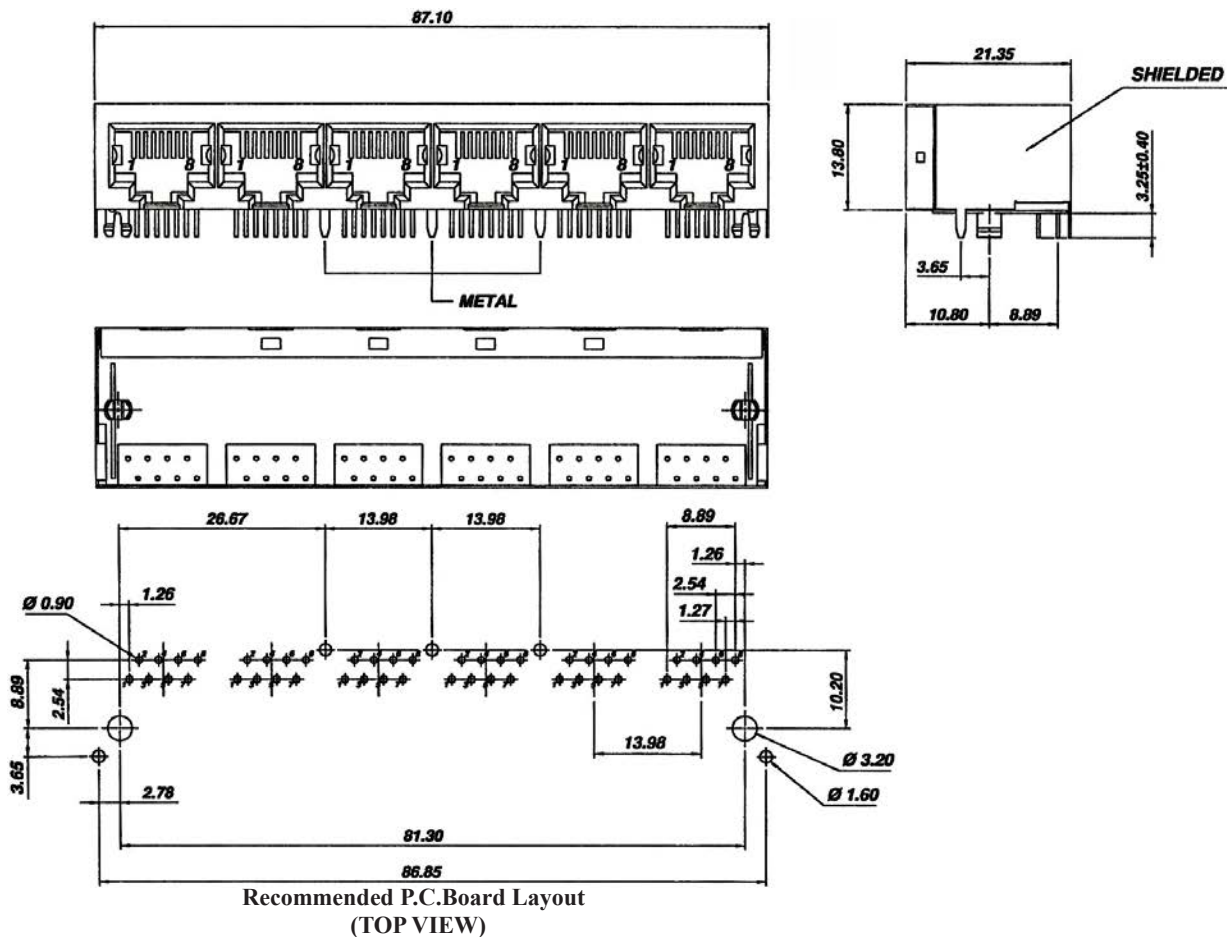
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S K - $\frac{88}{1} \times \frac{B}{2} \frac{06}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

06

NOTE 1: P/N MJSKHT-88xB06 FOR HIGH TEMP. VERSION

NOTE 2: 3.65MM SPACING BEFORE PEG

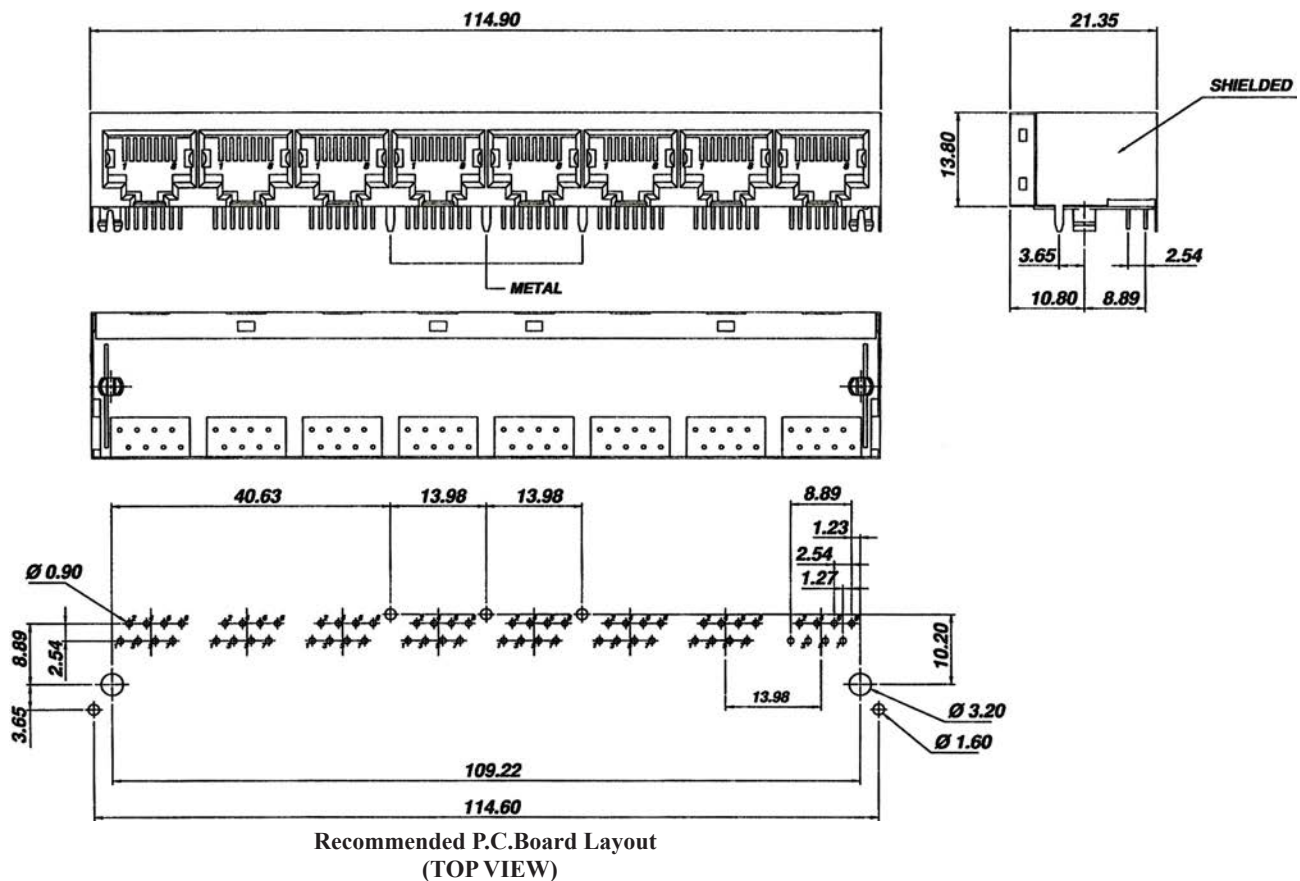
SIDE ENTRY 8-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S K - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
08

NOTE 1: P/N MJSKHT-88xB08 FOR HIGH TEMP. VERSION
 NOTE 2: 3.65MM SPACING BEFORE PEG

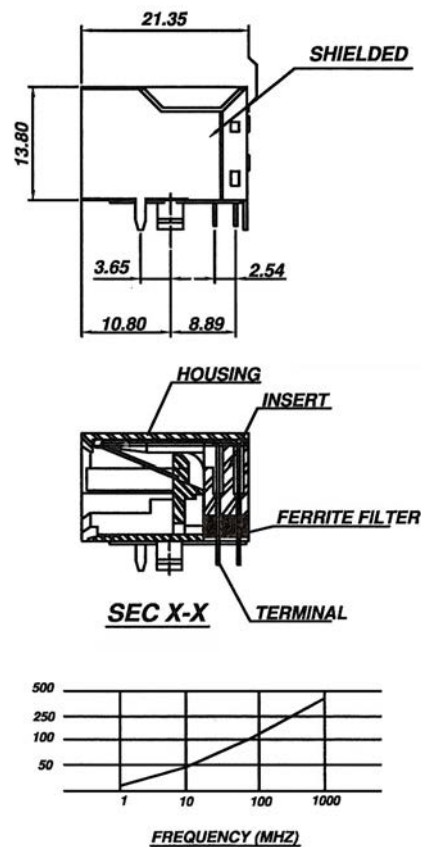
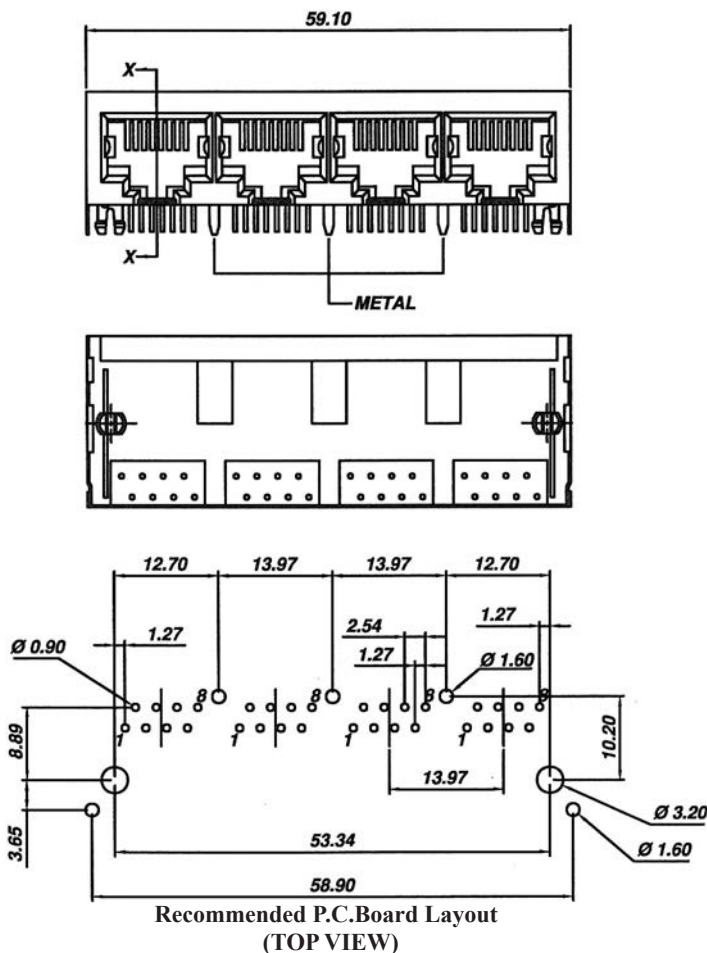
SIDE ENTRY 4-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500M Ω Min.
 Contact Resistance: 20m Ω Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40 $^{\circ}$ c / +85 $^{\circ}$ c
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235 $^{\circ}$ c
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S H - $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
04

NOTE: 3.65MM SPACING BEFORE PEG

SIDE ENTRY 4-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

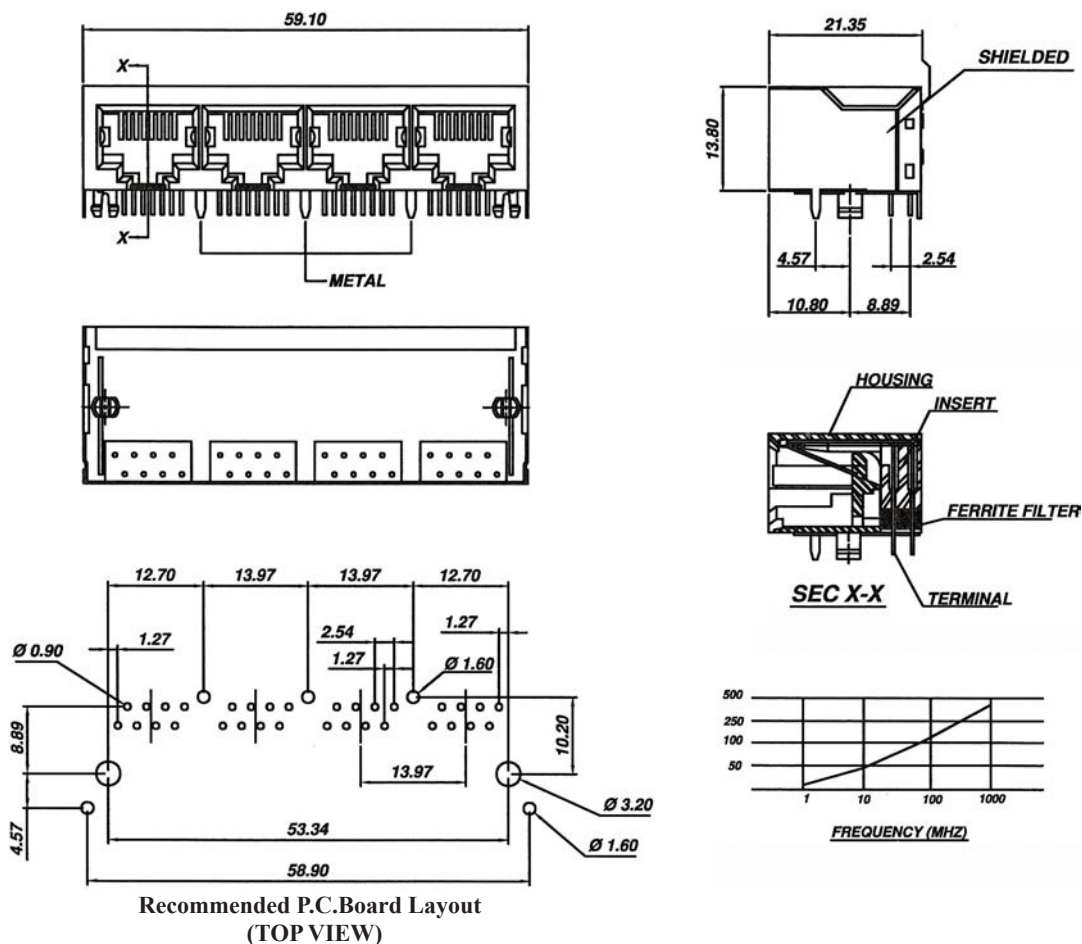
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J S G - $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: 4.57MM SPACING BEFORE PEG

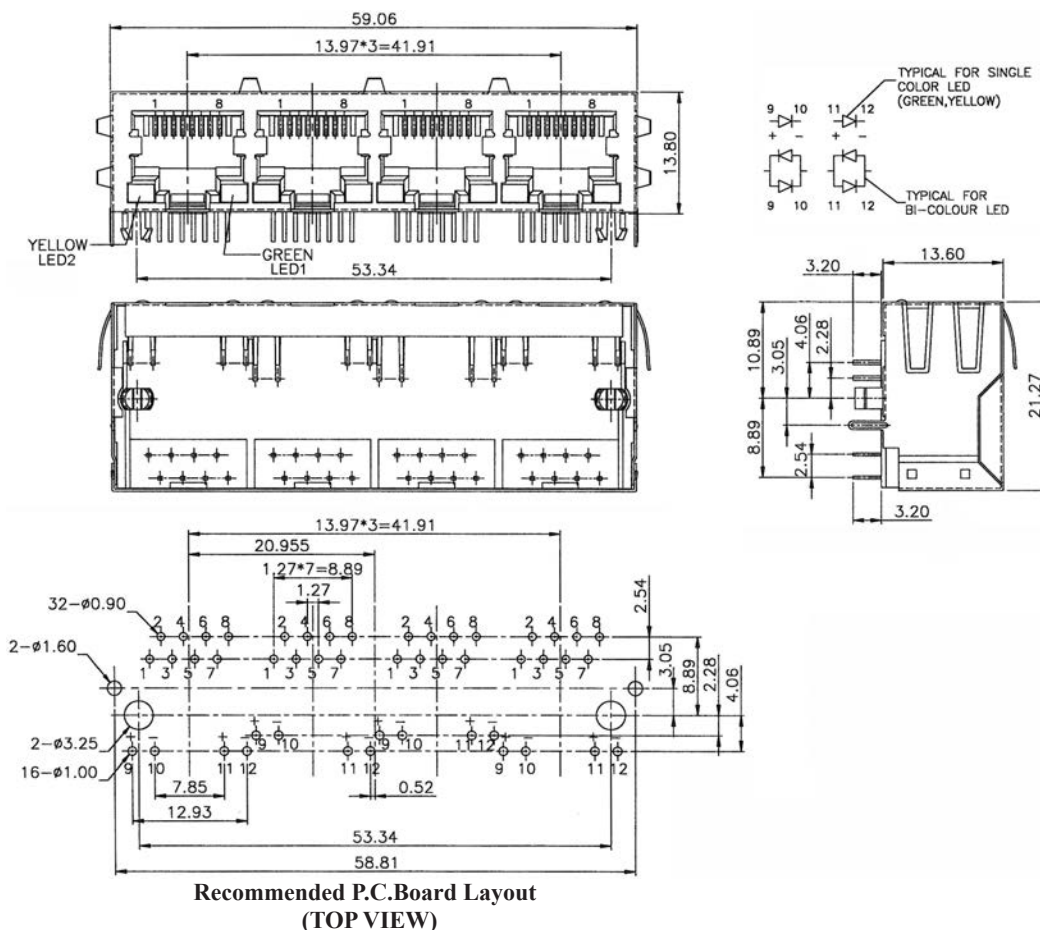
SIDE ENTRY 4-PORT MODULAR PCB JACK WITH LED 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N **M J 1 Z - 88 x B x x 04**
1 2 3 4 5

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- NO. OF PORTS:
04

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE 1: LED 1 = RIGHT LED &
LED 2 = LEFT LED

NOTE 2: 3.05MM SPACING BEHIND PEG

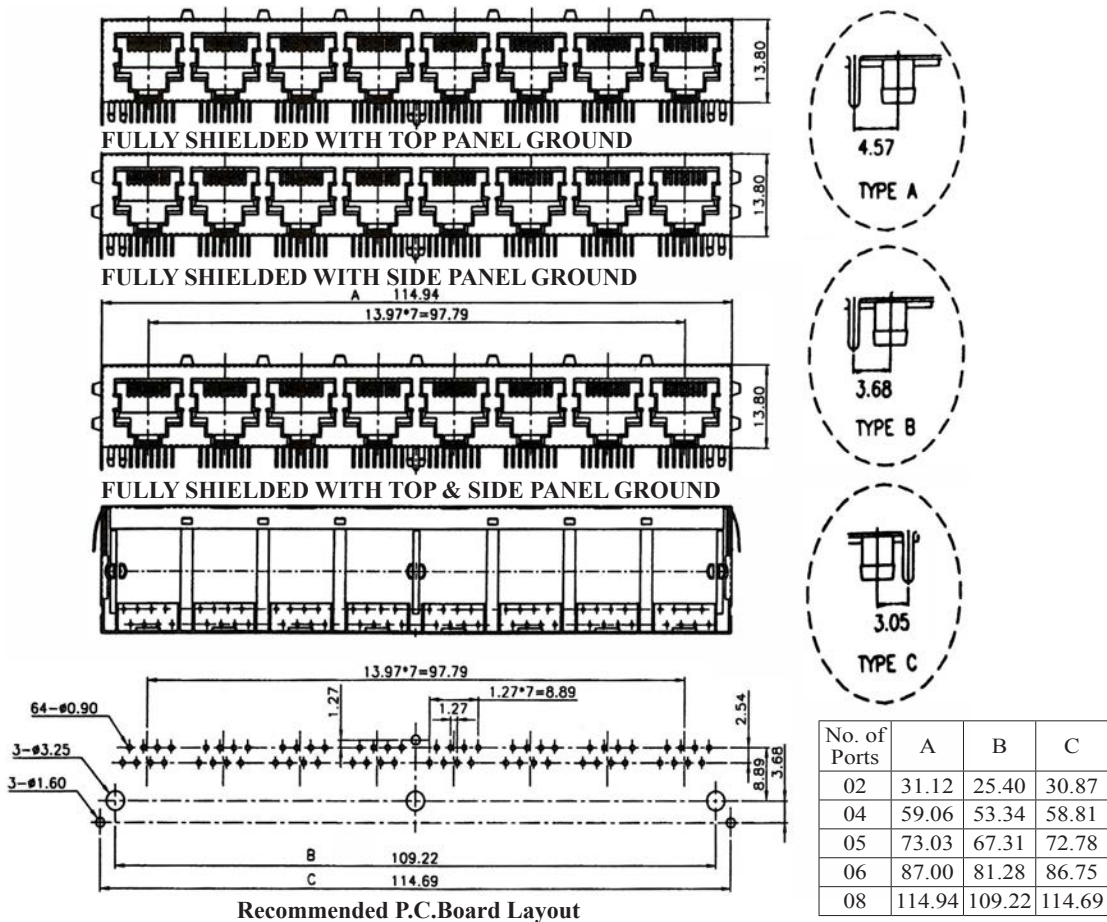
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 8P+10P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XX}{2} \frac{XX}{3} B \frac{XX}{4}$

1. CONTACT & PANEL GROUND TYPE:

WITH TOP PANEL GROUNDS:

"7G" TYPE A
 "7P" TYPE B
 "7Q" TYPE C

WITH SIDE PANEL GROUNDS:

"2E" TYPE A
 "2F" TYPE B
 "2G" TYPE C

WITH TOP & SIDE PANEL GROUNDS:

"2H" TYPE A
 "2K" TYPE B
 "2L" TYPE C

WITHOUT PANEL GROUNDS:

"7A" TYPE A
 "7B" TYPE B
 "3Y" TYPE C

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
 "00" 10P10C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

4. NO. OF PORTS:

02, 04, 05, 06, 08

SIDE ENTRY 2-PORT MODULAR PCB JACK 10P8C PROFILE=13.70MM (FULLY SHIELDED)

SPECIFICATIONS

Current Rating: 1.5 Amp Max.

Dielectric Withstanding: 500 Vac For 1 Min.

Contact Resistance: 30m Ohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc..

Operation Temperature: -40°C To +85°C.

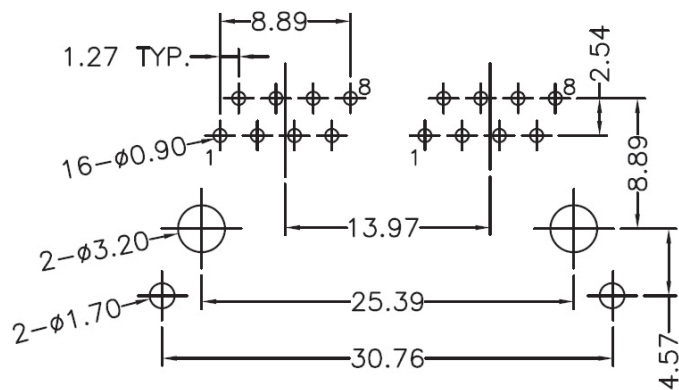
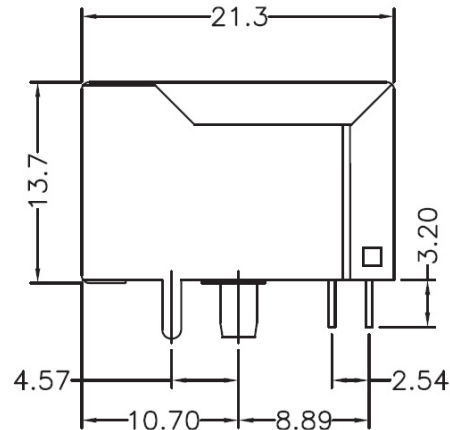
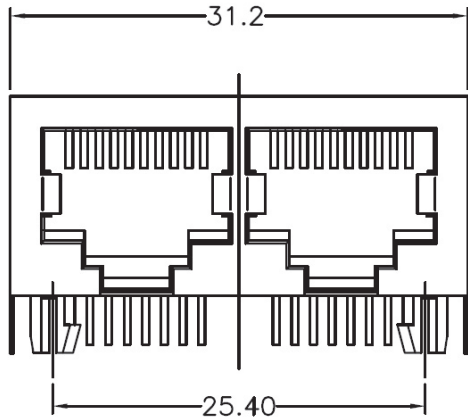
MATERIALS

Housing: PBT(UL 94V-0)

Shell: Copper Alloy,Nickel plating

Terminal: Copper Alloy,Gold Plated

* **RoHS & REACH compliant.**



**Recommended P.C.Board Layout
(TOP VIEW)**

ORDERING INFORMATION:

P/N MJSJK - $\frac{08}{1} \times \frac{x}{23} \times \frac{02}{4}$

1. NO. OF POSITIONS & CONTACTS:

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"B" BLACK

"W" WHITE

"N" GREEN

"A" GRAY

"R" RED

"Y" YELLOW

4. NO. OF PORTS:

02

NOTE: IT CAN BE USED FOR REPLACING P/N MJSJ-88xB02.

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

MATERIALS

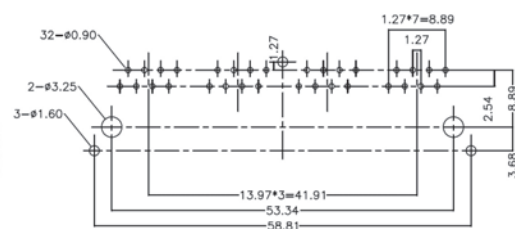
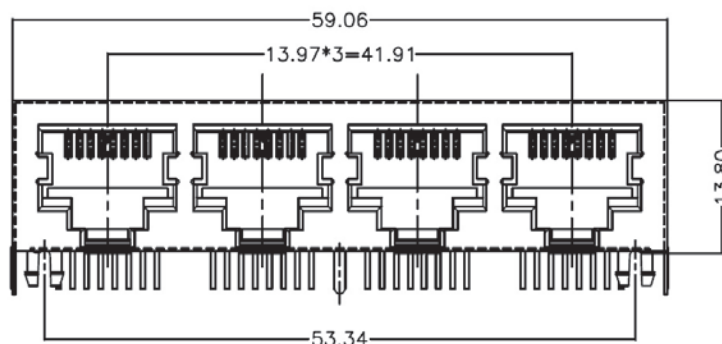
Plastic Housing: Engineering Thermoplastic
Flammability Rating UL 94V-0.

Contacts: 0.35mm Thickness Phosphor Bronze

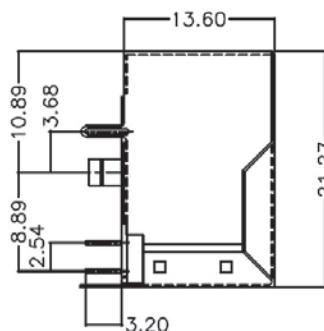
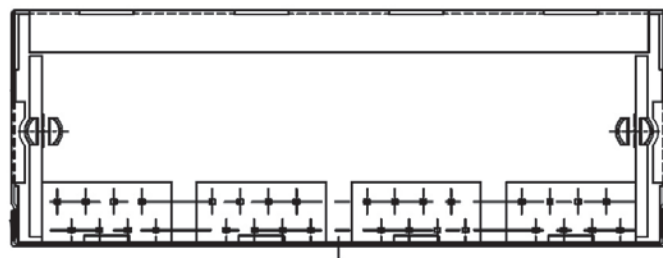
Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shielded: Brass With Nickel Plated.

* RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N **M J $\frac{24}{1}$ J - $\frac{88}{2}$ $\frac{x}{3}$ B $\frac{04}{4}$**

1. MODULAR JACK TYPE:
"24J" F3.68 TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. NO. OF PORTS:
04

NOTE: IT CAN BE USED FOR REPLACING P/N MJ24-88xB04.

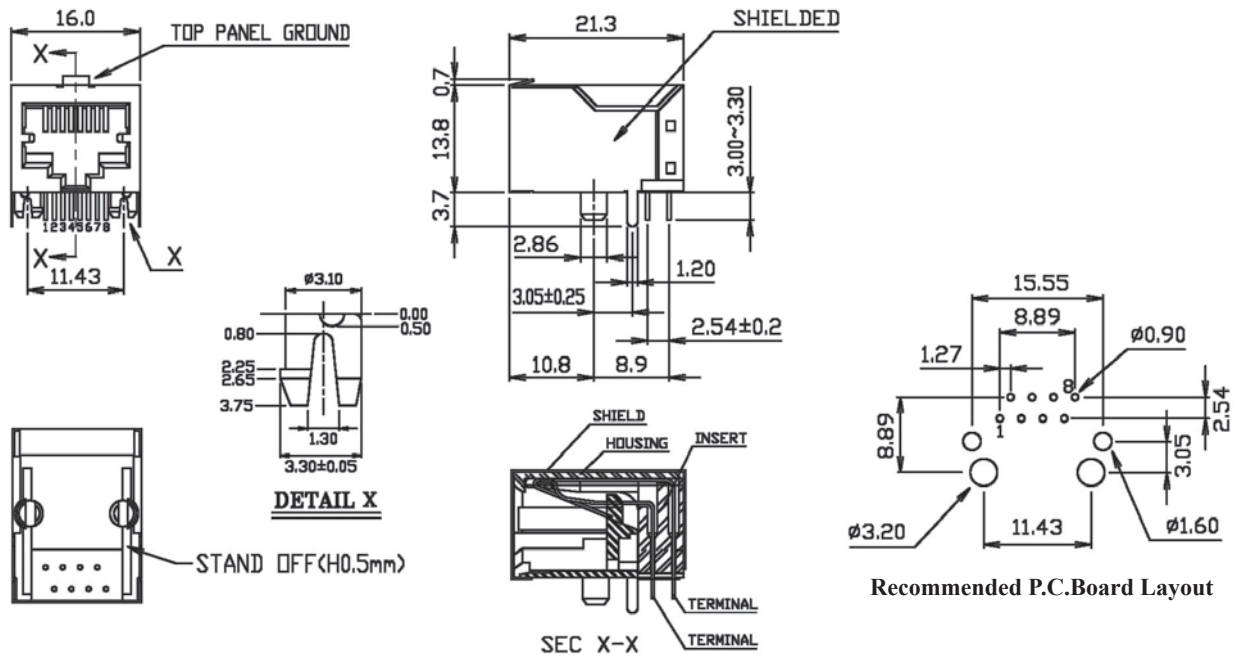
SIDE ENTRY CAT.5 MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J NS - 88 X B
 I 2 3 4

1. MODULAR JACK TYPE:
"NS" CAT.5 JACK
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

NOTE: 3.05MM SPACING BEHIND PEG

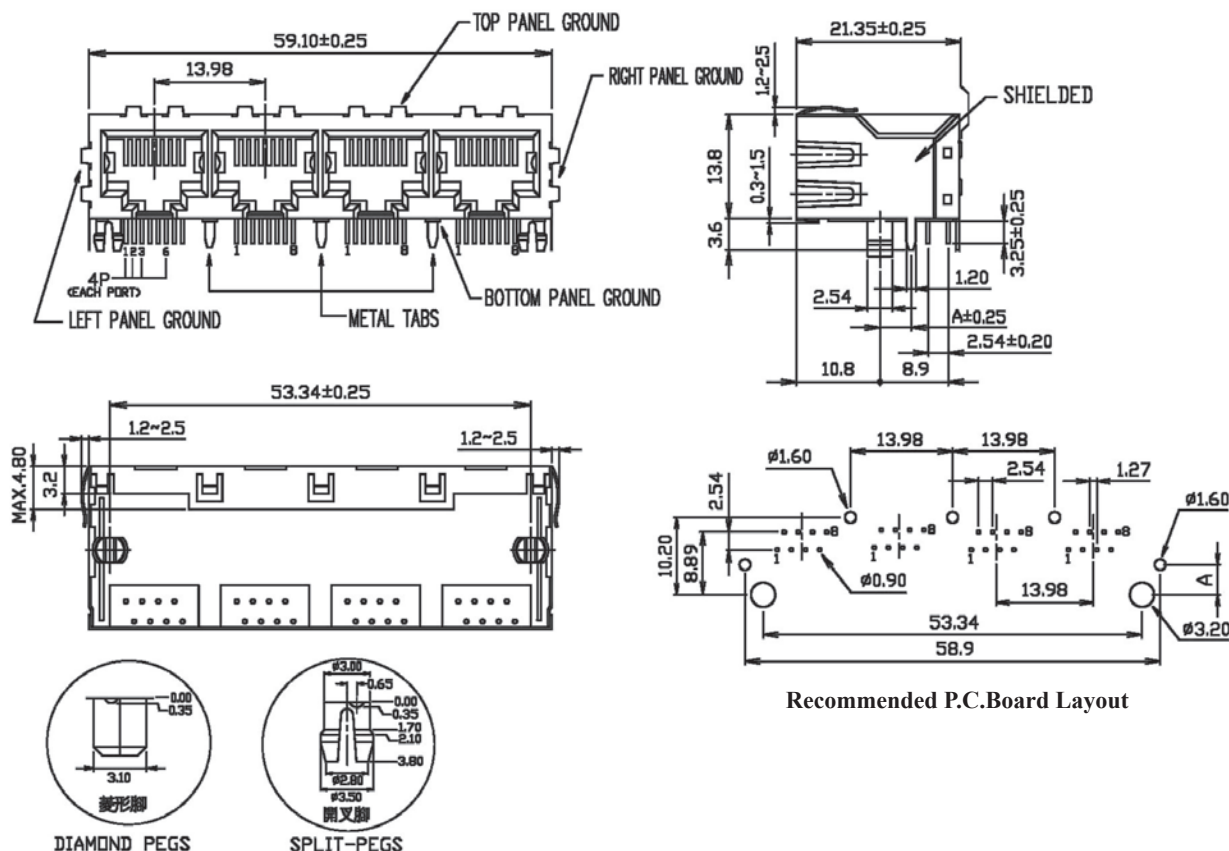
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J K L - 8 8 x B 0 4
 I 2 3 4 5

- MODULAR JACK TYPE:
"KL" DIM. A=3.05MM
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- NO. OF PORTS:
04

NOTE: 3.05MM SPACING BEHIND PEG

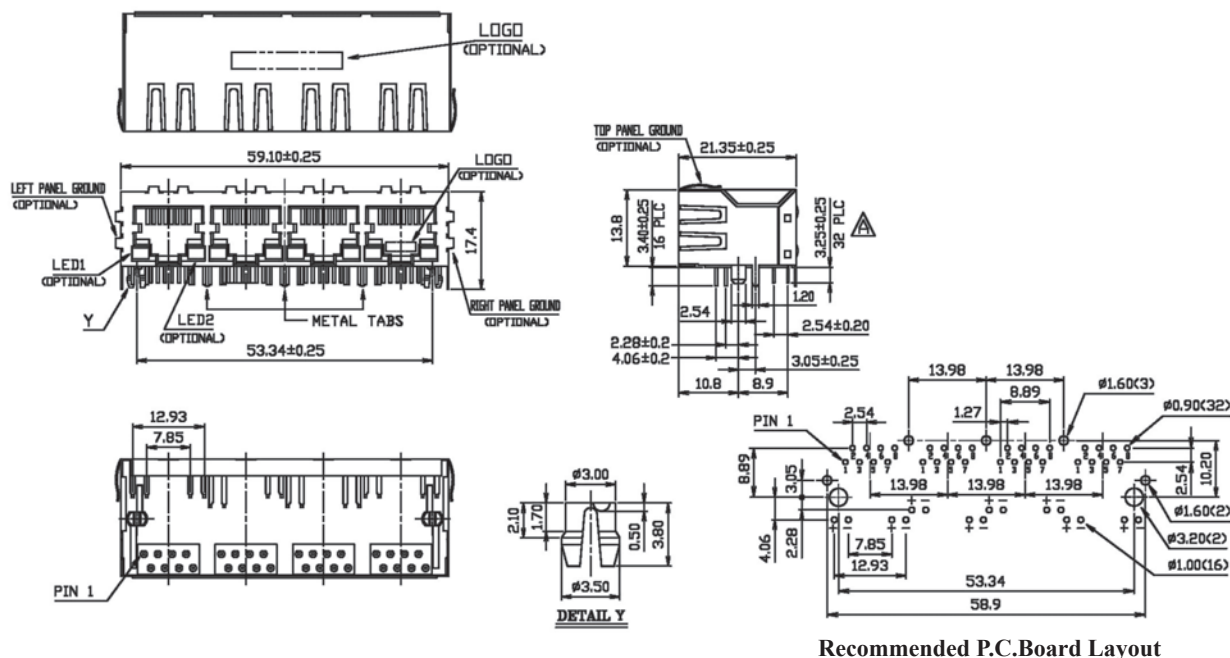
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P WITH LED PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{X X}{1} - \frac{8 8}{2} \frac{X B}{3 4} \frac{X X}{5} \frac{0 4}{6}$

- MODULAR JACK TYPE:
 "WE" WITH TOP/RIGHT/LEFT SIDE TABS
 "WF" WITH RIGHT/LEFT TABS
 "WG" WITH TOP SIDE TABS
 "WH" WITHOUT GROUNDING TABS
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- COLORS OF LED:
 "NN" LED1/2 = GREEN/GREEN
 "NY" LED1/2 = GREEN/YELLOW
 "YN" LED1/2 = YELLOW/GREEN
 "YY" LED1/2 = YELLOW/YELLOW
 "XX" WITHOUT LED
- NO. OF PORTS:
 04

NOTE: 3.05MM SPACING BEHIND PEG

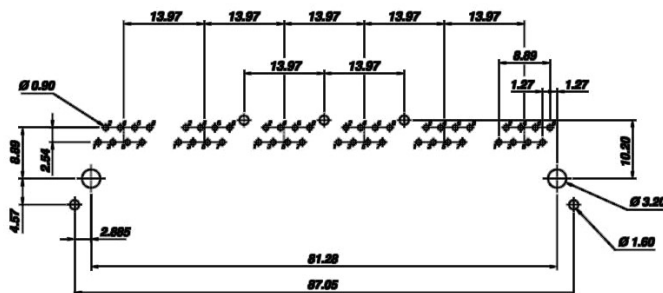
SIDE ENTRY 6-PORT MODULAR PCB JACK 8P PROFILE=13.80MM (FULLY SHIELDED)

SPECIFICATIONS

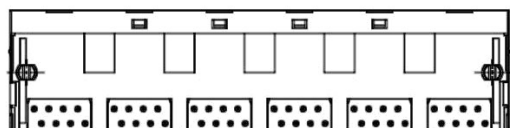
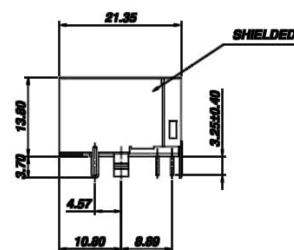
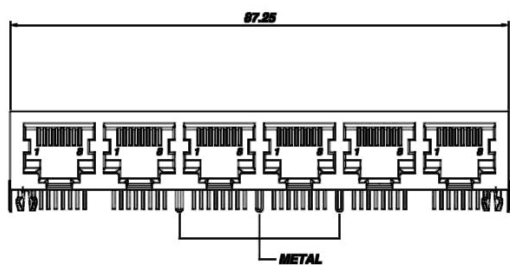
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(Top View)



ORDERING INFORMATION:

P/N M J S J A - $\frac{88}{1} \times \frac{B}{2} \frac{0.6}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
06

NOTE: 4.57MM SPACING BEFORE PEG

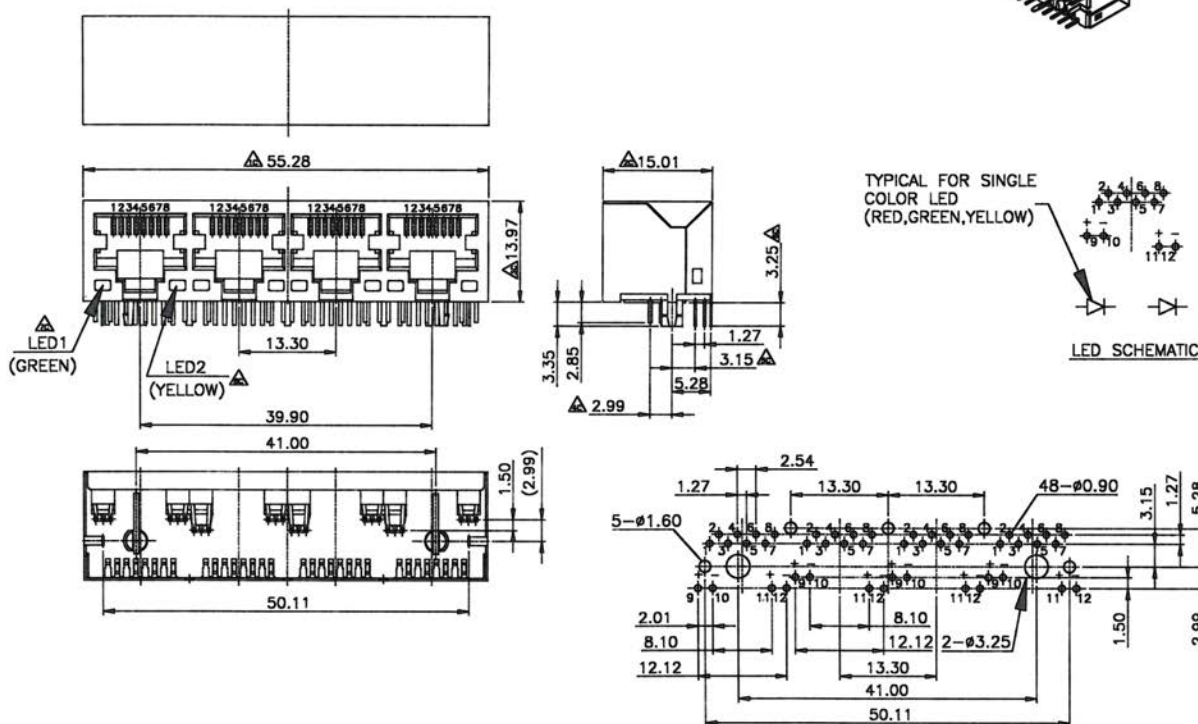
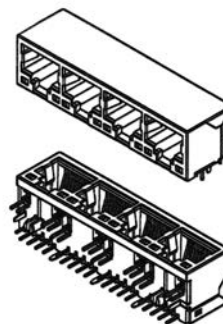
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P WITH LED PROFILE=13.97MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout (TOP VIEW)

ORDERING INFORMATION:

P/N M J Y N - 8 8 x B x x 0 4
 1 2 3 4 5

- MODULAR JACK TYPE:
"YN" 4-PORT JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

- COLORS OF LED:
"NN" LED1: GREEN & LED2: GREEN
"NY" LED1: GREEN & LED2: YELLOW
"YN" LED1: YELLOW & LED2: GREEN
"YY" LED1: YELLOW & LED2: YELLOW
"XX" W/O LED
- NO. OF PORTS:
04

NOTE: OTHER LED COLORS UPON REQUEST!

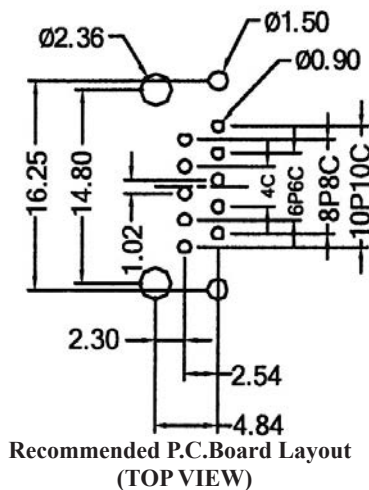
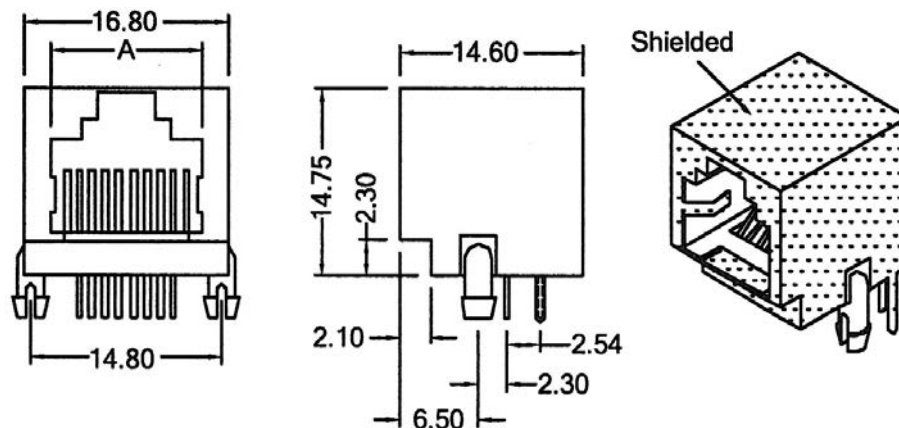
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P+8P+10P PROFILE=14.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



No. of Positions	No. of Contacts	A
6P(8P)	4C/6C	9.90
8P	8C	11.90
10P	10C	11.90

ORDERING INFORMATION:

P/N M J R 9 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

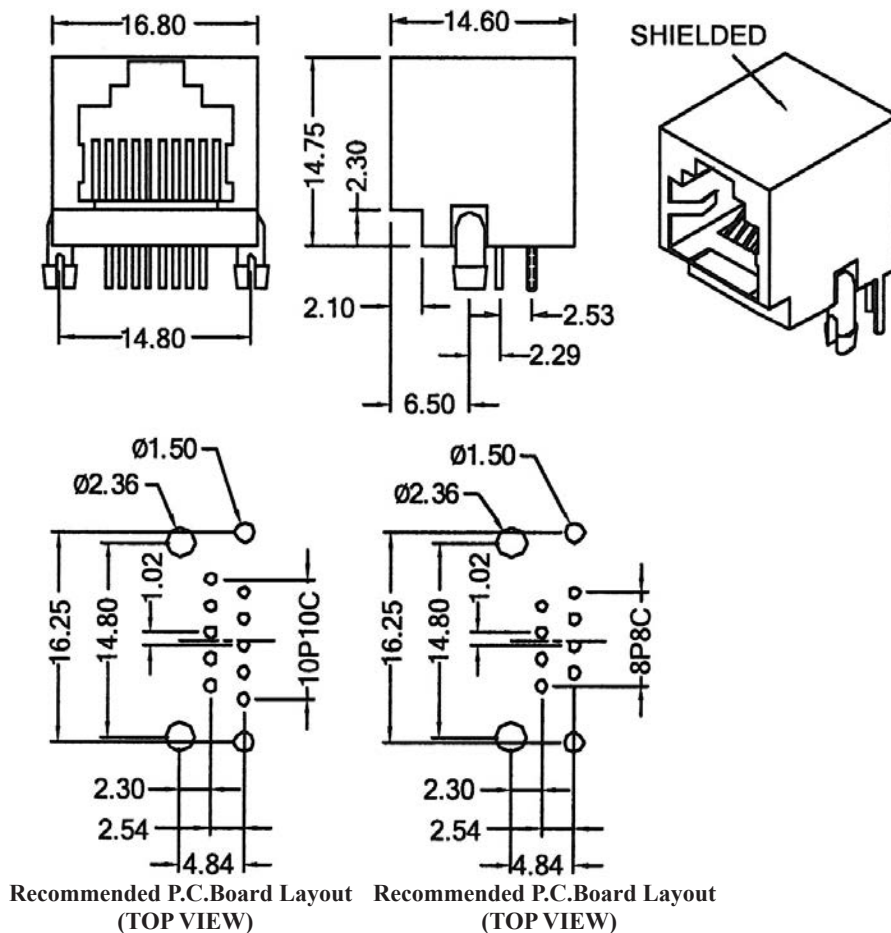
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJS 2 - $\frac{x}{1} \frac{x}{2} \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "00" 10P10C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. HOUSING COLOR:
 "A" GRAY
 "B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=14.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

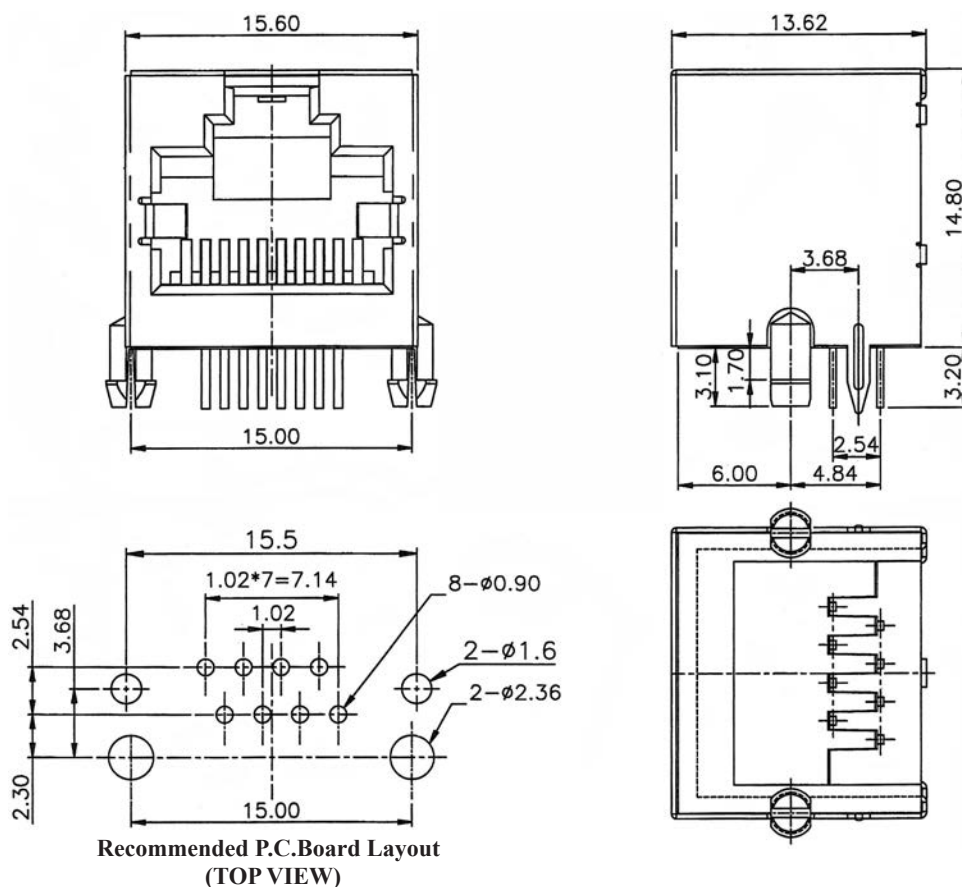
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 M - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

SIDE ENTRY UP LATCH MODULAR PCB JACK PIN REVERSED TYPE 8P PROFILE=14.80MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

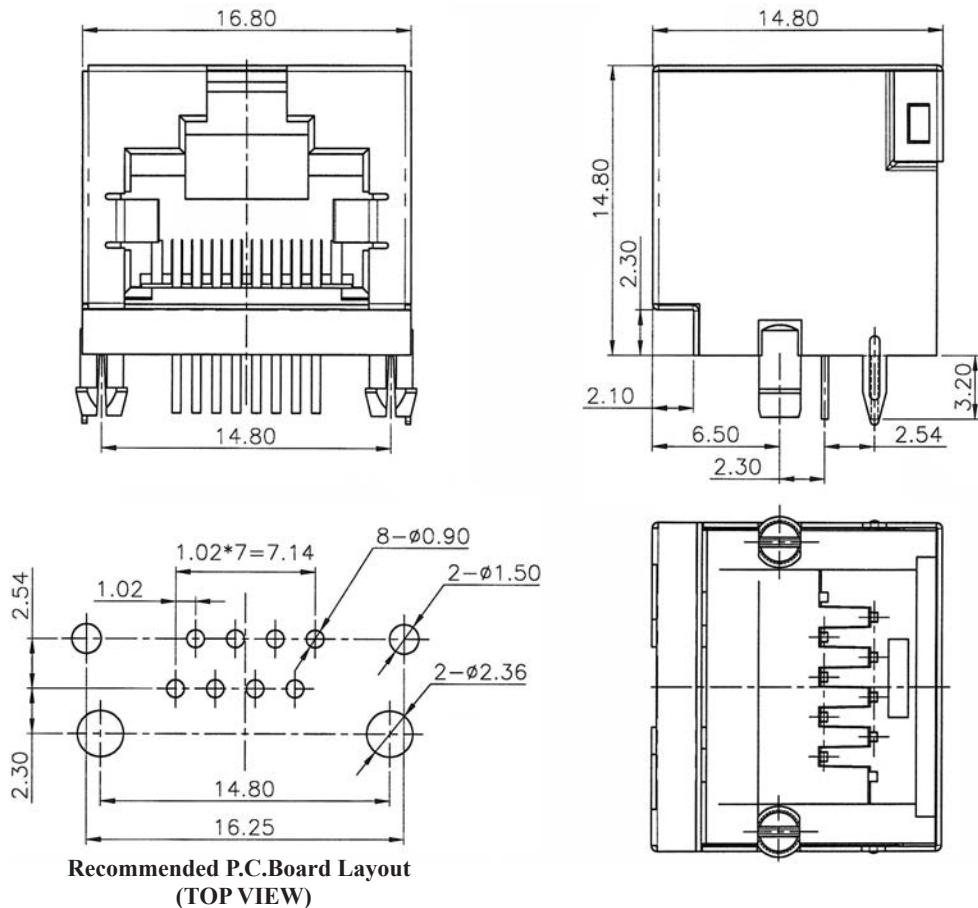
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 1 S - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: PIN REVERSED TYPE

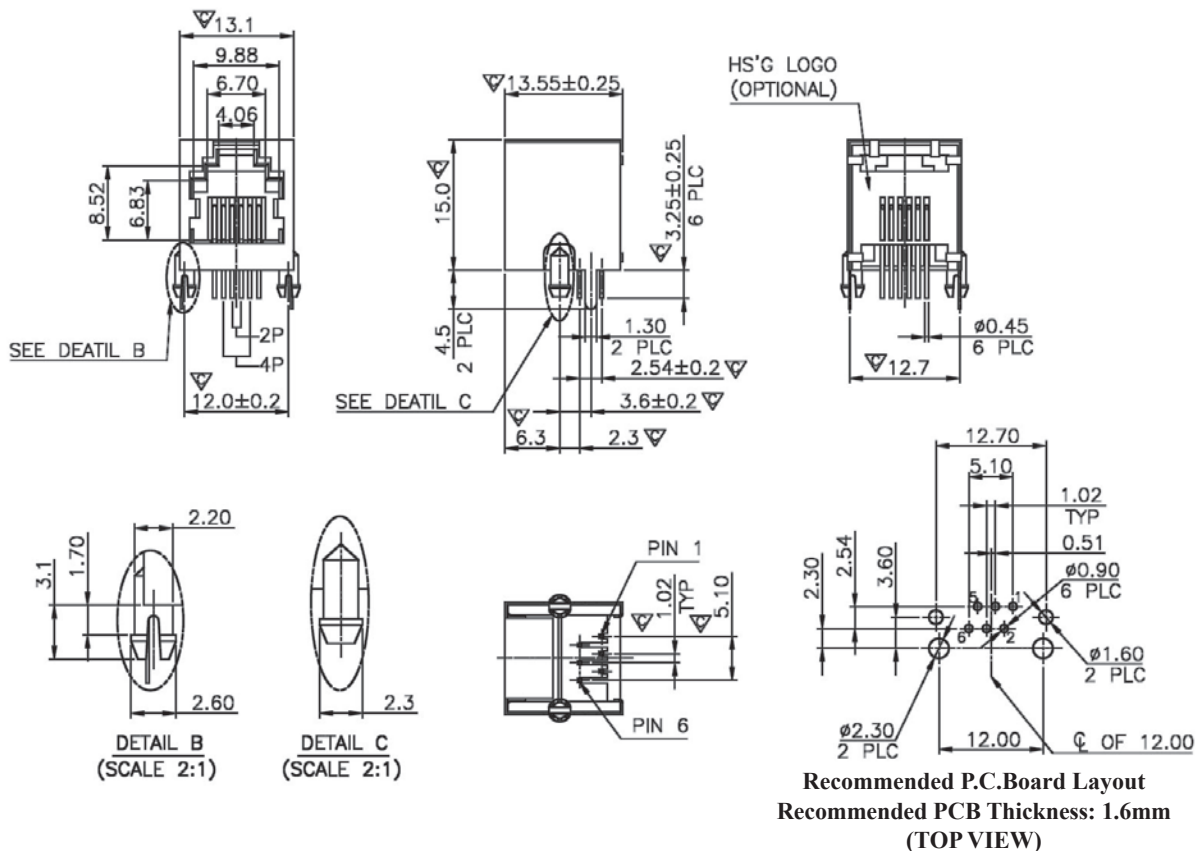
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=15.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{VY}{I} - \frac{66}{2} \frac{x}{3} \frac{x}{4}$

- MODULAR JACK TYPE:
"VY" MINI LOW PROFILE TYPE WITH SHELL
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

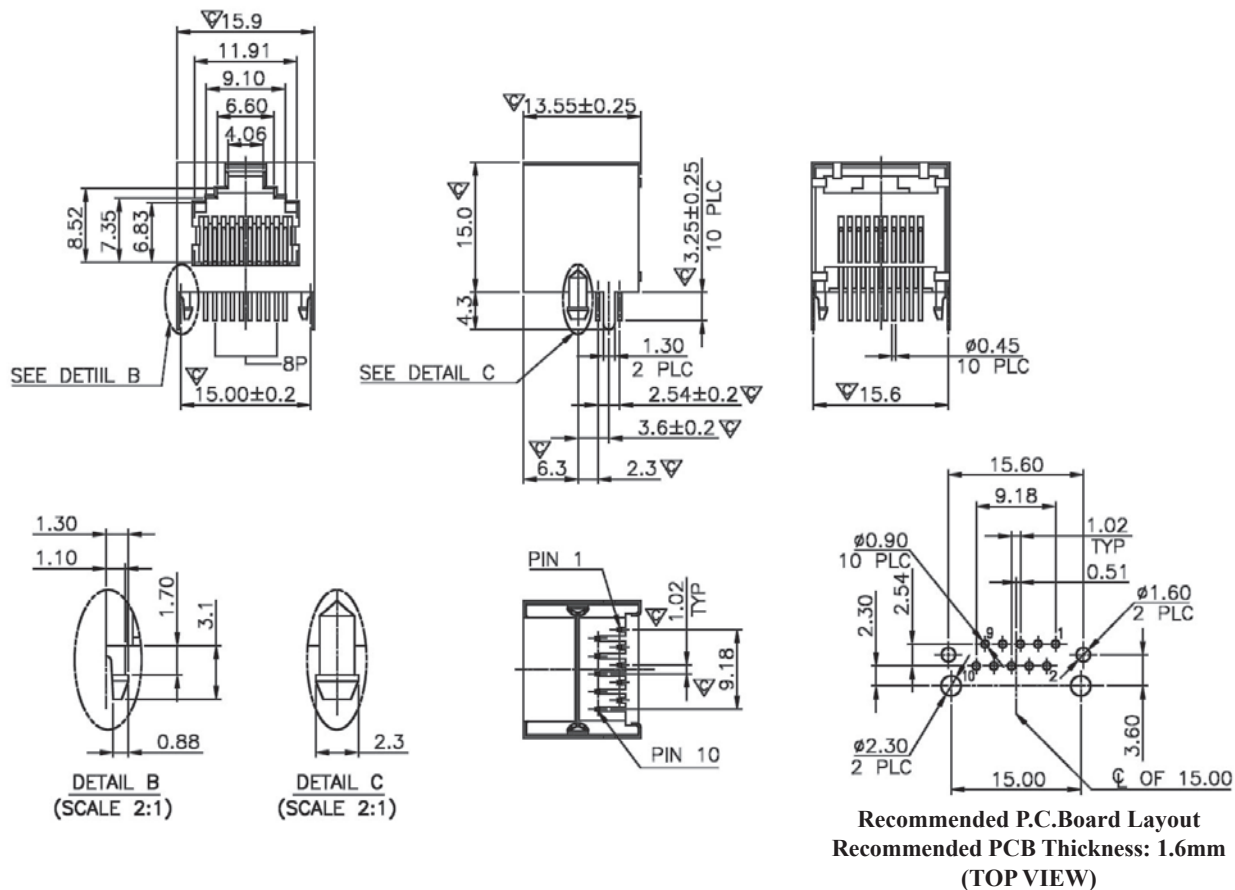
SIDE ENTRY UP LATCH MODULAR PCB JACK 10P PROFILE=15.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{VY}{1} - \frac{00}{2} \frac{x}{3} \frac{x}{4}$

- MODULAR JACK TYPE:
"VY" MINI LOW PROFILE TYPE WITH SHELL
- NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

SIDE ENTRY MODULAR PCB JACK 8P+6P PROFILE=21.50MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

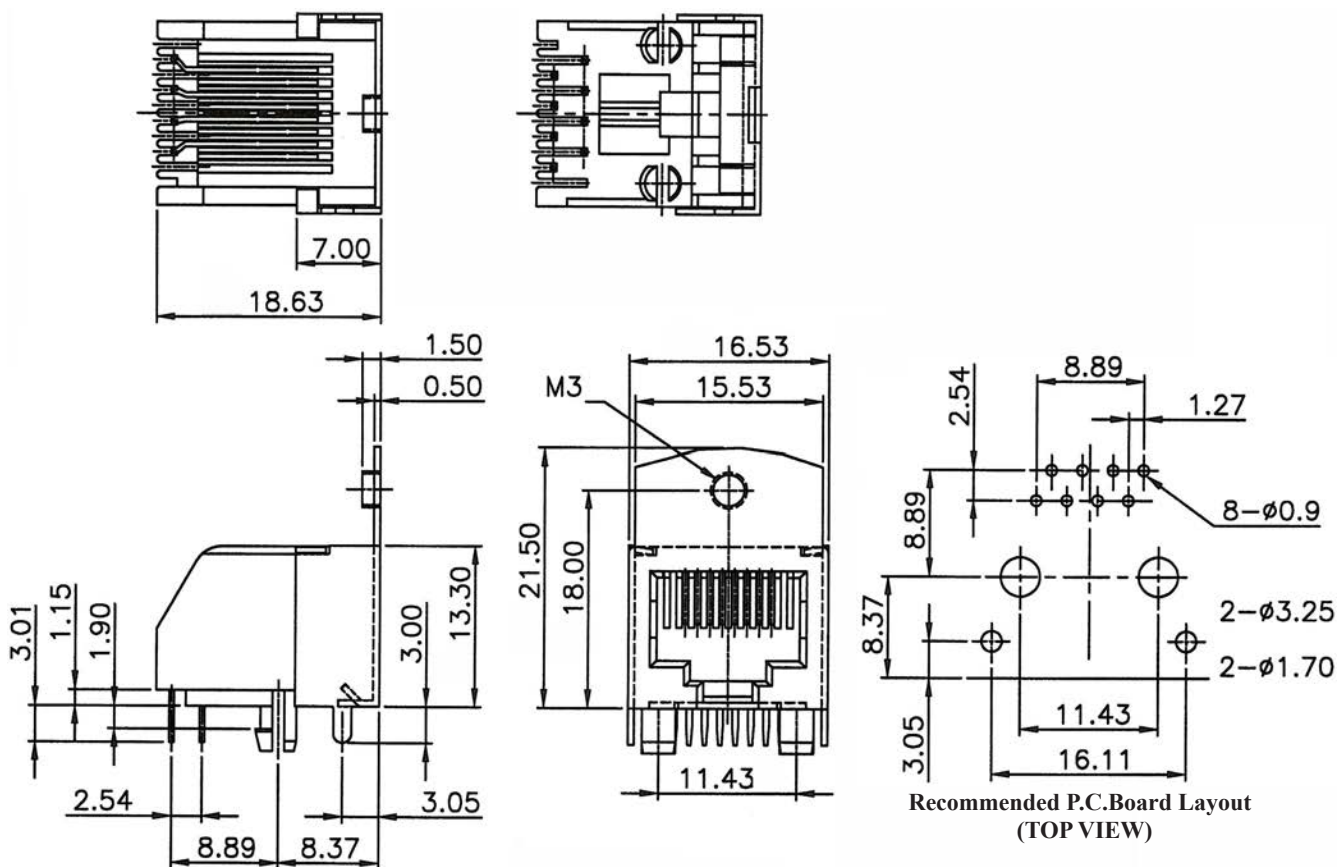
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 6 W - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"66" 6P6C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION (FOR 8P ONLY):

" " W/O KEYWAY

"K" WITH KEYWAY

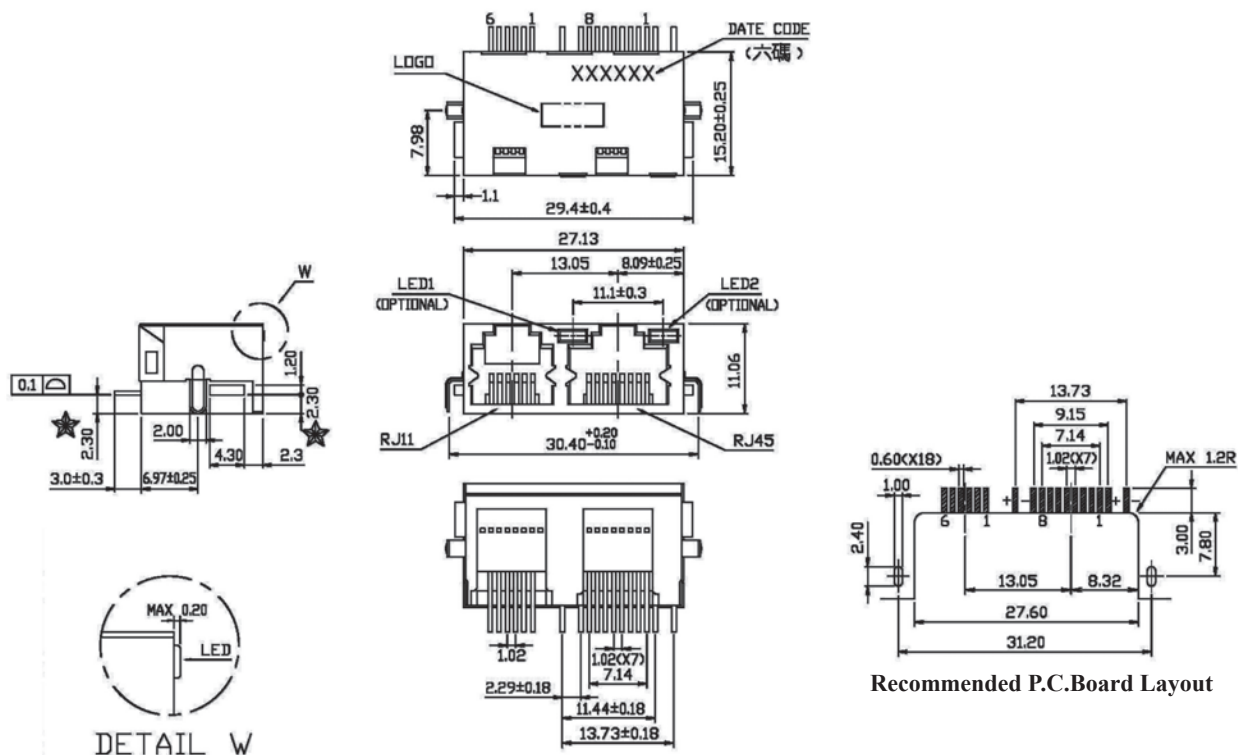
SIDE ENTRY 2-PORT EMBEDDED STANDARD MOUNT MODULAR SMT JACK 6P+8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J F U - 6 8 x B x x 0 2

 1 2 3 4 5

- | | |
|--|---|
| <p>1. MODULAR JACK TYPE:
"FU" EMBEDDED SMT TYPE (2.30MM)</p> <p>2. NO. OF POSITIONS & CONTACTS:
"68" 6P (RJ12) + 8P (RJ45)</p> <p>3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD</p> <p>4. HOUSINH COLOR:
"B" BLACK</p> | <p>5. LED COLORS:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW
"XX" WITHOUT LED</p> <p>6. NO. OF PORTS:
02</p> <p>NOTE: OTHER LED COLORS UPOM REQUEST!</p> |
|--|---|

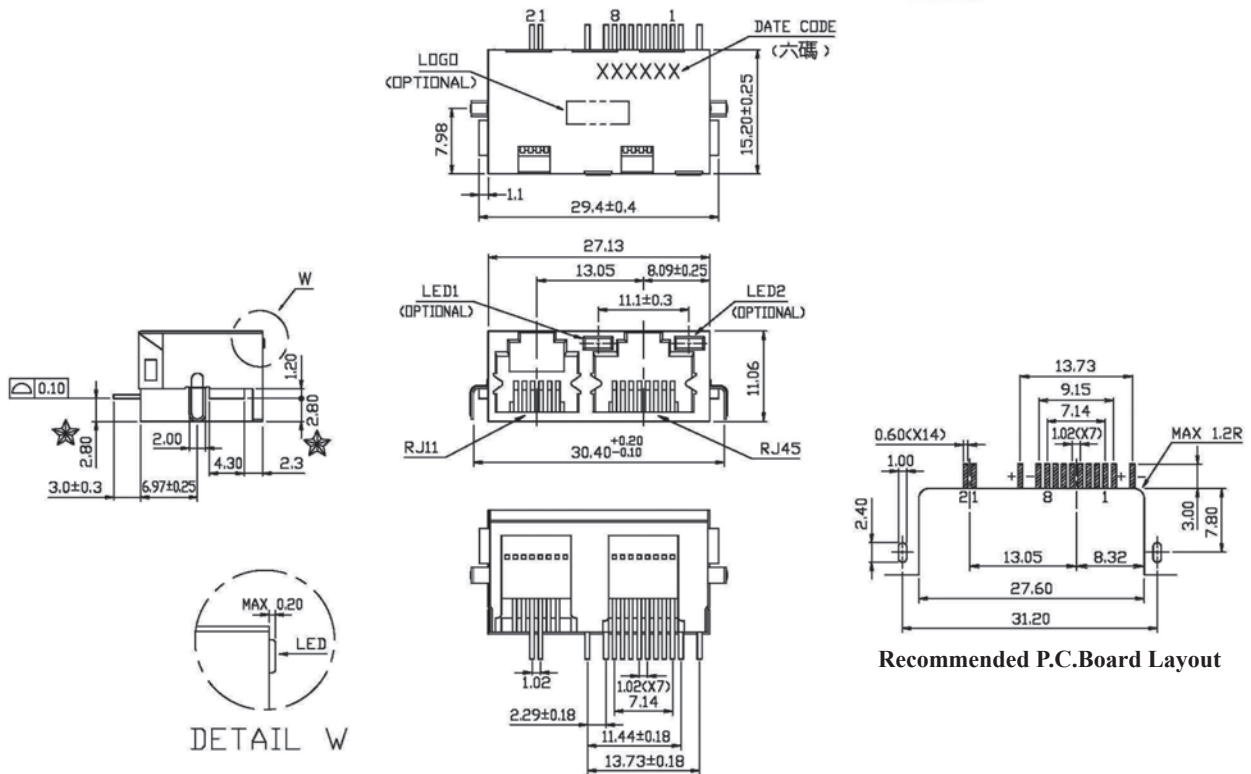
SIDE ENTRY 2-PORT EMBEDDED STANDARD MOUNT MODULAR SMT JACK 6P+8P WITH LED PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * **RoHS & REACH compliant.**



DETAIL W

ORDERING INFORMATION:

P/N M J FV - 68 X B X X 02
 1 2 3 4 5

- MODULAR JACK TYPE:
"FV" EMBEDDED SMT TYPE (2.80MM)
- NO. OF POSITIONS & CONTACTS:
"68" 6P (RJ12) + 8P (RJ45)
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- LED COLORS:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW
"XX" WITHOUT LED
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPOM REQUEST!

SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=11.06MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

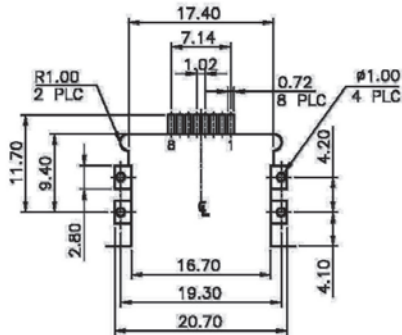
Color: Black

Spring Wire: Phosphor Bronze

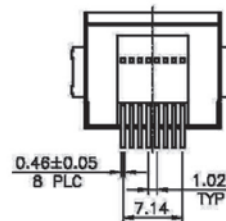
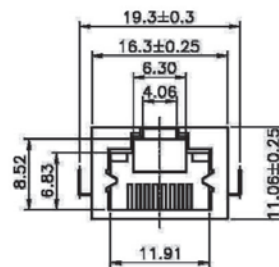
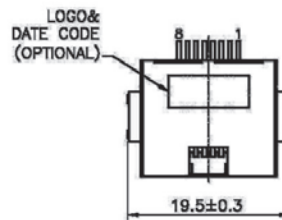
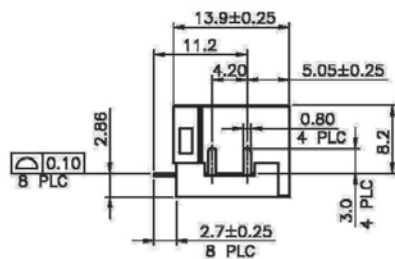
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J $\frac{FR}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"FR" EMBEDDED SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

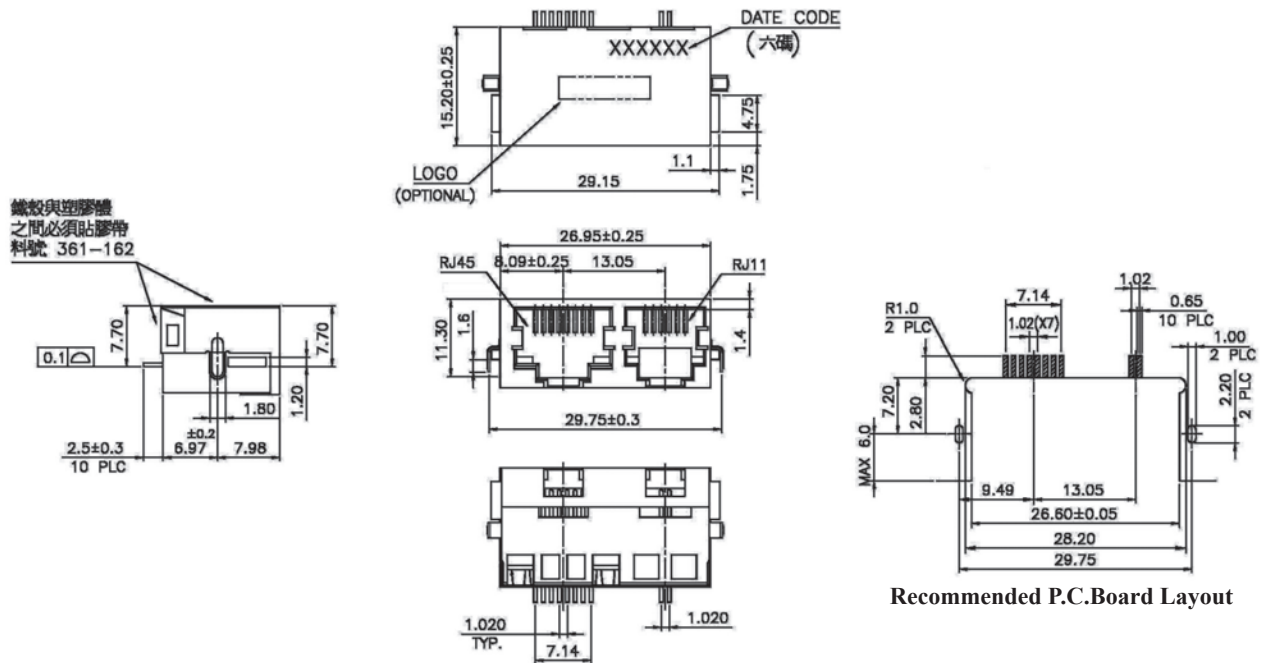
SIDE ENTRY 2-PORT EMBEDDED REVERSE MOUNT MODULAR SMT JACK 6P+8P PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * **RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{FS}{1}$ - $\frac{68}{2}$ x $\frac{B}{3}$ $\frac{02}{4}$

- MODULAR JACK TYPE:
"FS" EMBEDDED SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"68" 6P (RJ12) + 8P (RJ45)
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK
- NO. OF PORTS:
02

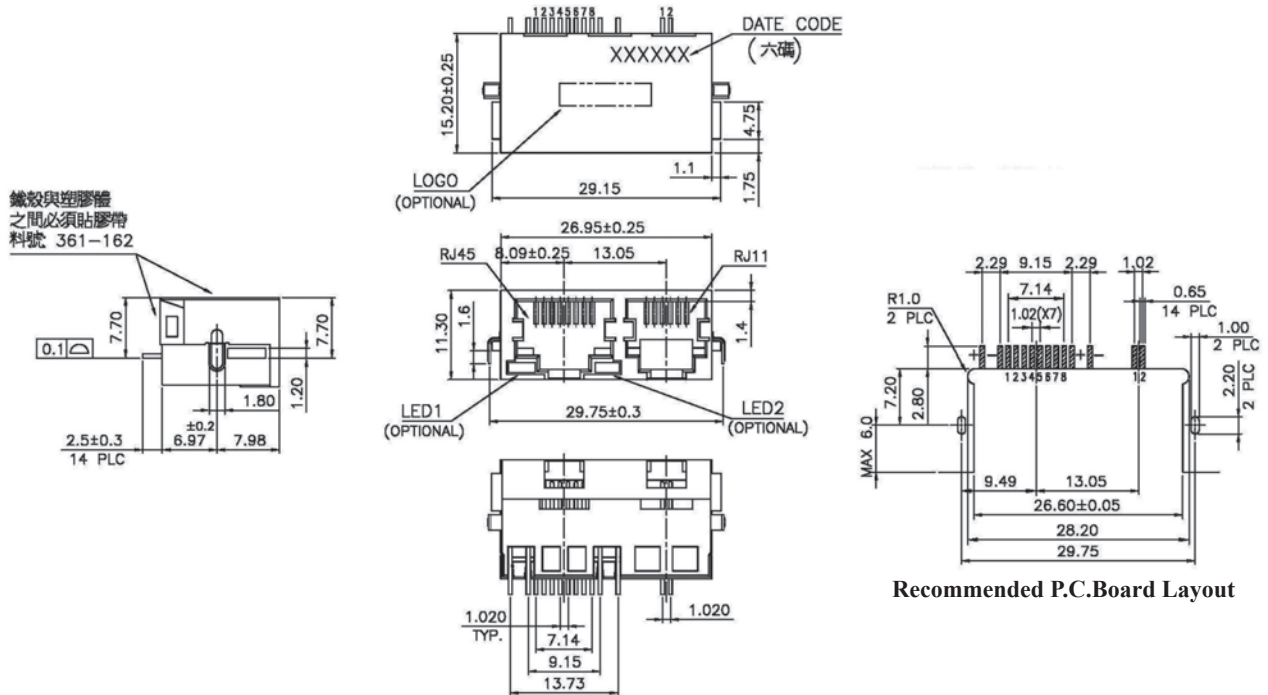
SIDE ENTRY 2-PORT EMBEDDED REVERSE MOUNT MODULAR SMT JACK 6P+8P WITH LED PROFILE=11.30MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * **RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{FT}{1}$ - $\frac{68}{2}$ x $\frac{B}{3}$ x $\frac{x}{4}$ x $\frac{02}{5}$

- MODULAR JACK TYPE:
"FT" EMBEDDED SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"68" 6P (RJ12) + 8P (RJ45)
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- LED COLORS:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW
- NO. OF PORTS:
02

NOTE: OTHER LED COLORS UPOM REQUEST!

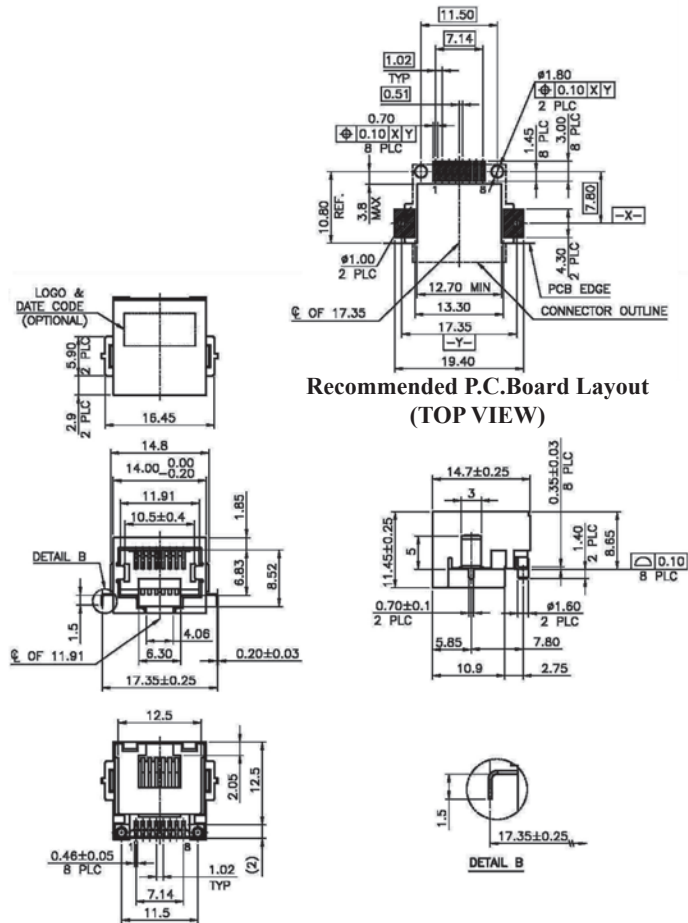
SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J $\frac{FW}{1}$ - $\frac{88}{2}$ $\frac{X}{3}$ B - $\frac{X}{4}$

1. MODULAR JACK TYPE:
"FW" EMBEDDED SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

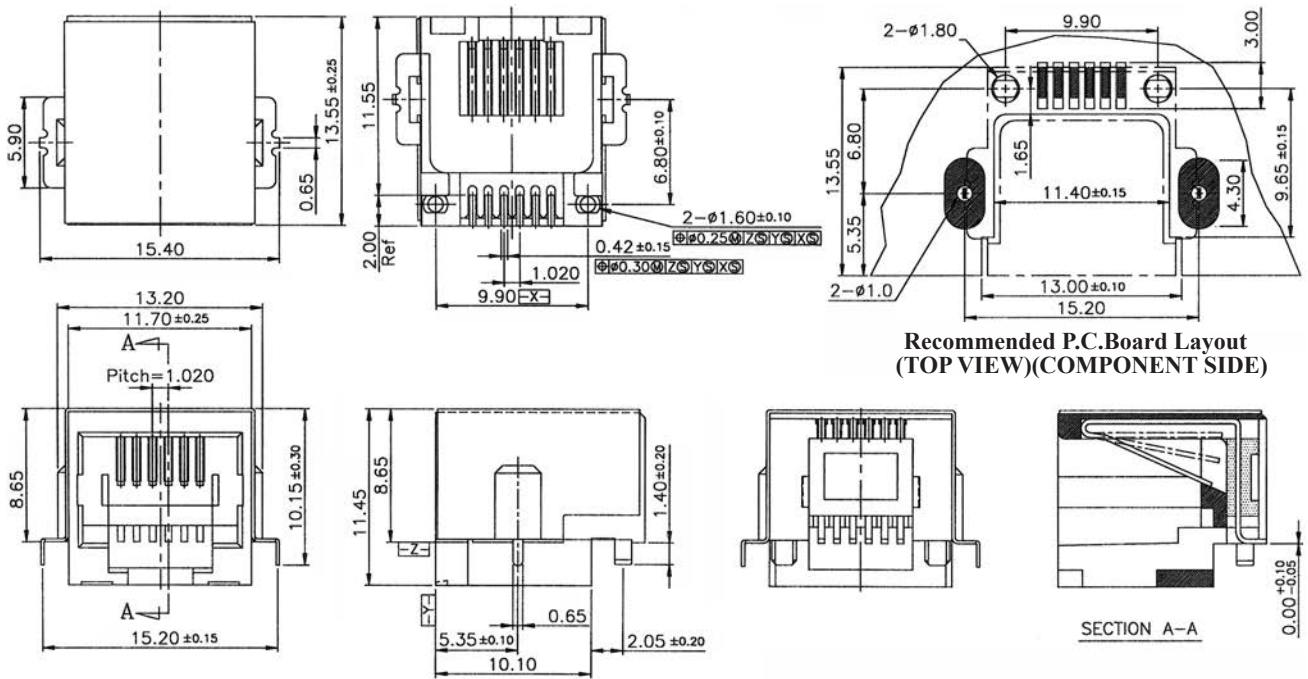
SIDE ENTRY EMBEDDED MODULAR SMT JACK 6P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 Z - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- PACKAGE OPTION:
 " " TRAY
 "R" TAPE & REEL

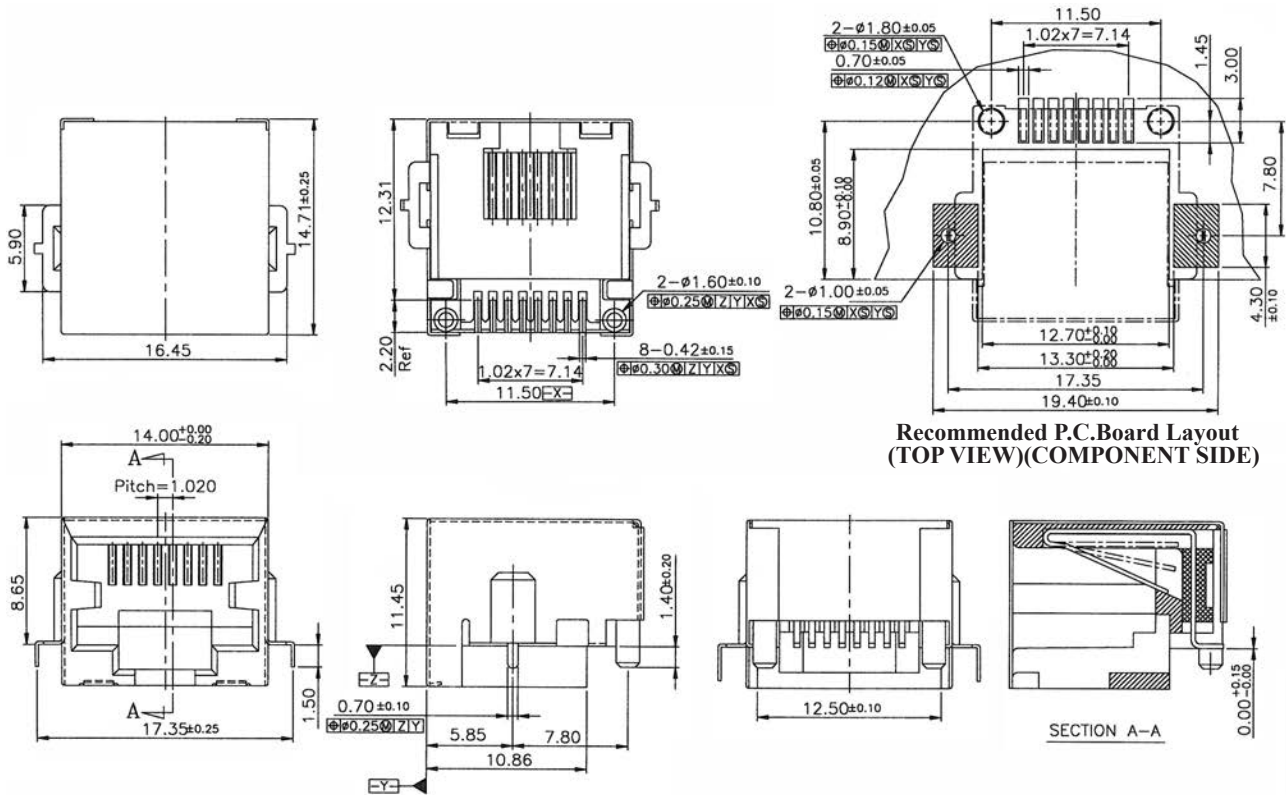
SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ4Z - $\frac{88}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" GOLD FLASH
- PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

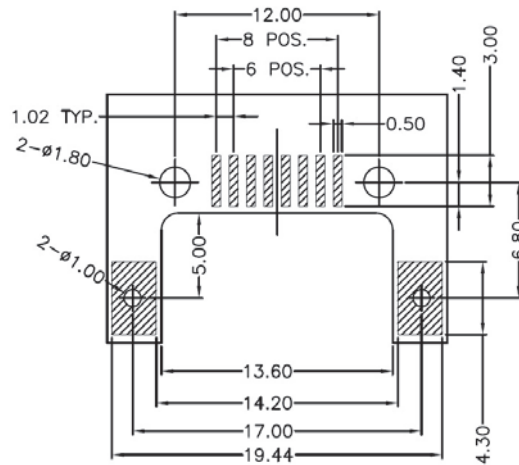
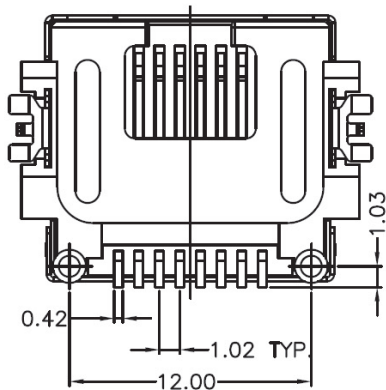
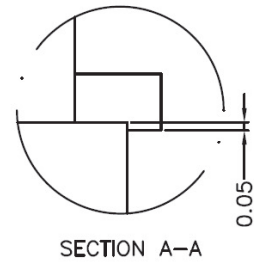
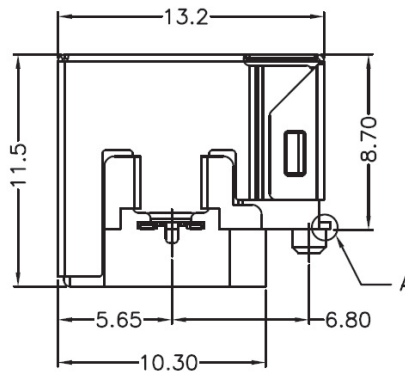
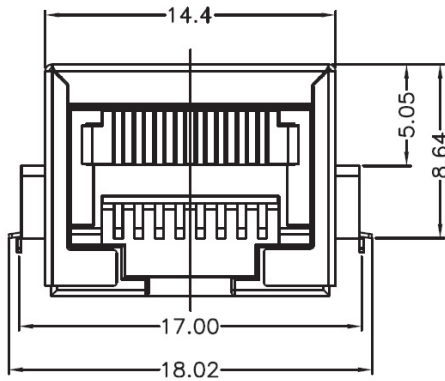
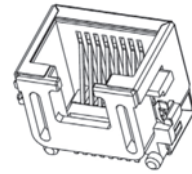
SIDE ENTRY MODULAR SMT JACK REVERSE MOUNT TYPE 8P PROFILE=11.50MM (FULLY SHIELDED)

SPECIFICATIONS

- Current Rating:** 1.5 Amp Max.
- Dielectric Withstanding:** 500 Vac For 1 Min.
- Contact Resistance:** 30m Ohms Max.
- Insulation Resistance:** 1000 Megohms Min @500 Vdc..
- Operation Temperature:** -40°C To +85°C.

MATERIALS

- Housing:** High Temp. Plastic(UL 94V-0)
- Shell:** Copper Alloy,Nickel plating
- Peg:** Copper Alloy,Tin Plated
- Terminal:** Copper Alloy,Gold Plated
- * RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 9S- xx xx xx
1 2 3 4

1. MODULAR JACK TYPE:
"9S" BOARD CUT REVERSE MOUNT TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" GOLD FLASH

4. HOUSING COLOR:
"B" BLACK
"W" WHITE
"N" GREEN
"A" GRAY
"P" PINK
"O" ORANGE

SIDE ENTRY EMBEDDED MODULAR SMT JACK 6P PROFILE=11.50MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

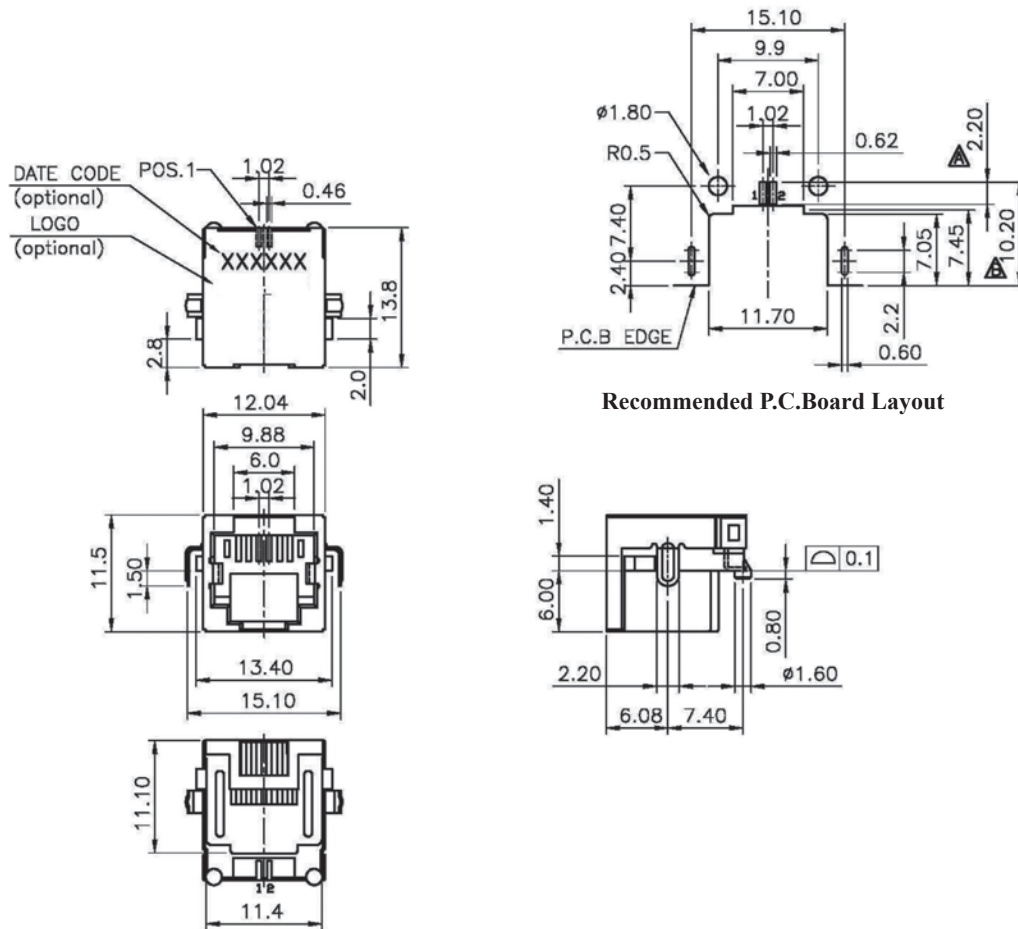
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{FW}{1} - \frac{62}{2} \frac{x}{3} B - \frac{x}{4}$

1. MODULAR JACK TYPE:
"FW" EMBEDDED SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"62" 6P2C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

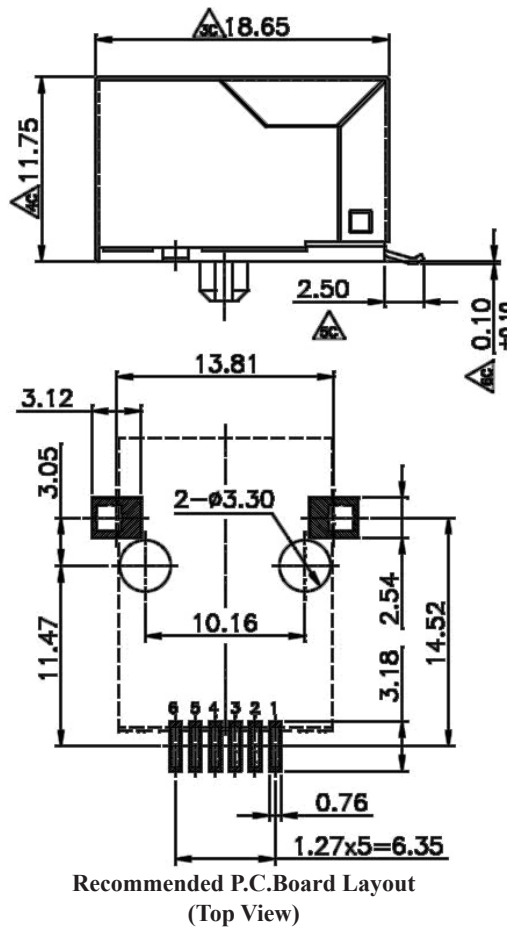
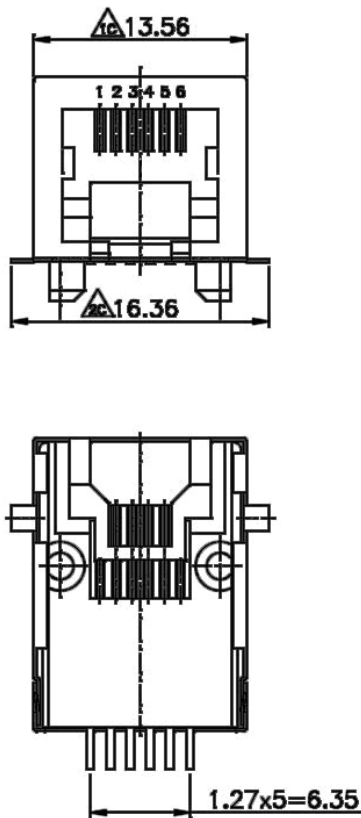
SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ19 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
"66" 6P6C
"64" 6P4C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

NOTE 1: P/N MJ19-66xB9T WITH INSULATOR PA-9T
NOTE 2: 3.05MM SPACING BEFORE PEG

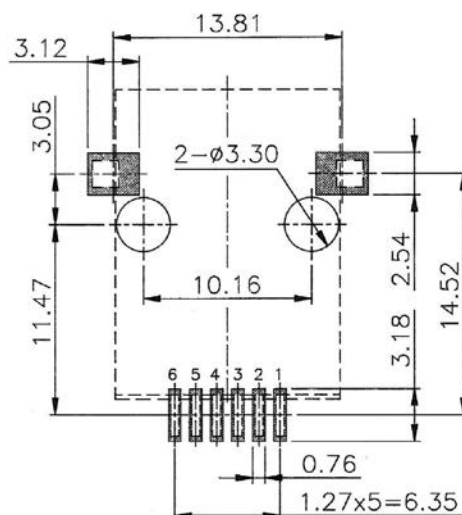
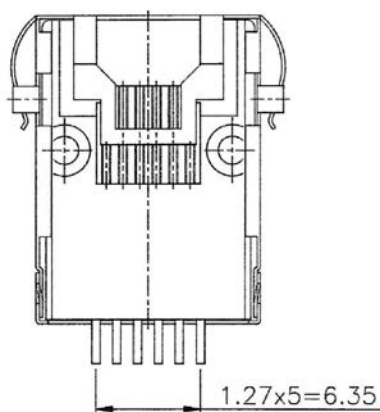
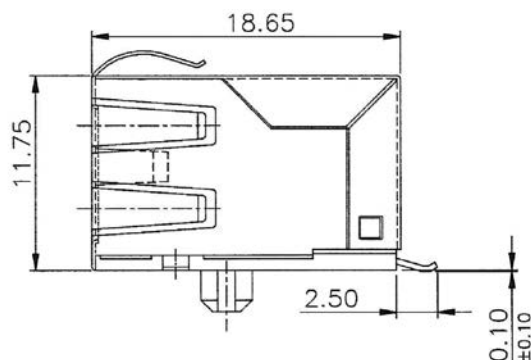
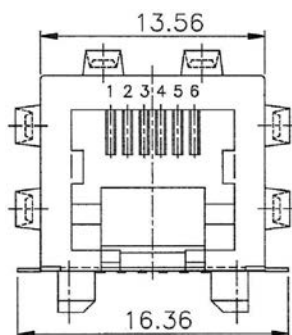
SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J 2 Z - $\frac{x x x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

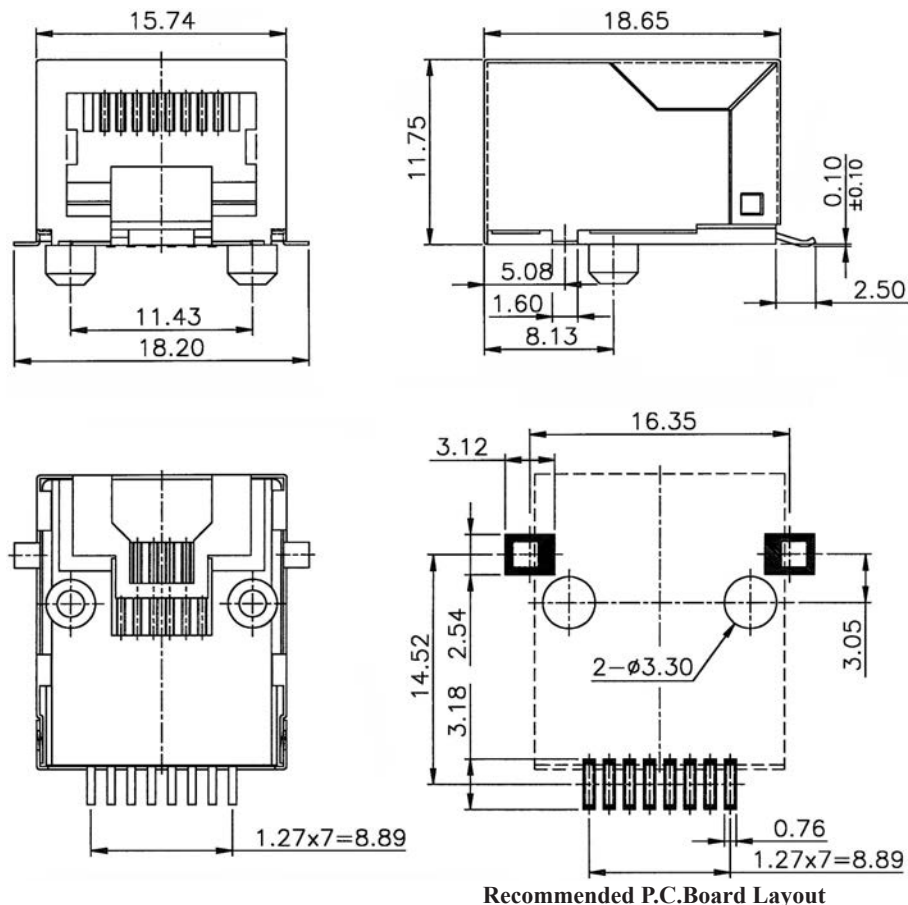
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 9 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

IR Reflow Soldering Temperature: 255°C To 265°C(5~10 Seconds)

MATERIALS

Plastic Housing: High Temp. Thermoplastic

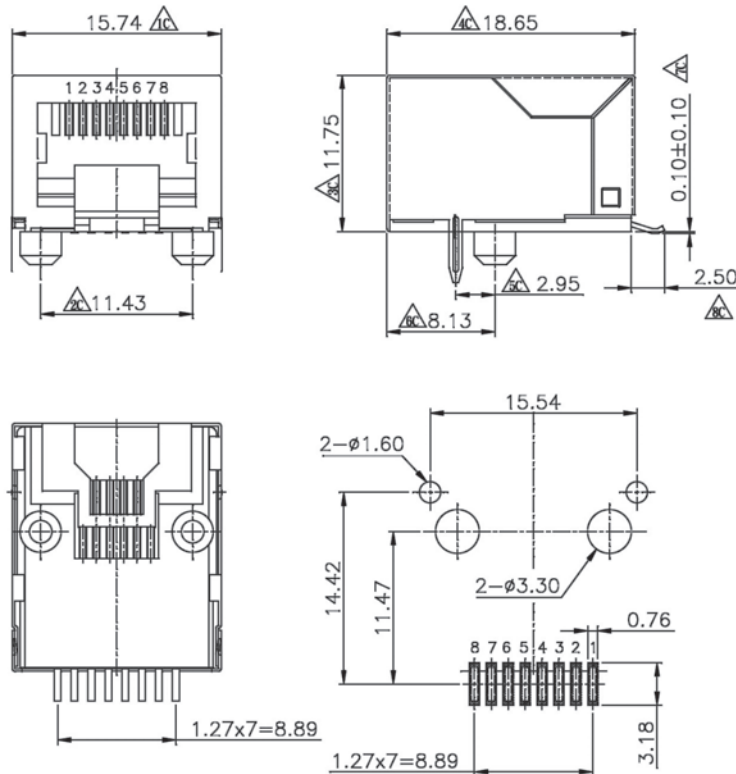
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{6}{1}$ G - $\frac{8}{2}$ $\frac{8}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"6G" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

NOTE: 2.95MM SPACING BEFORE PEGS

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

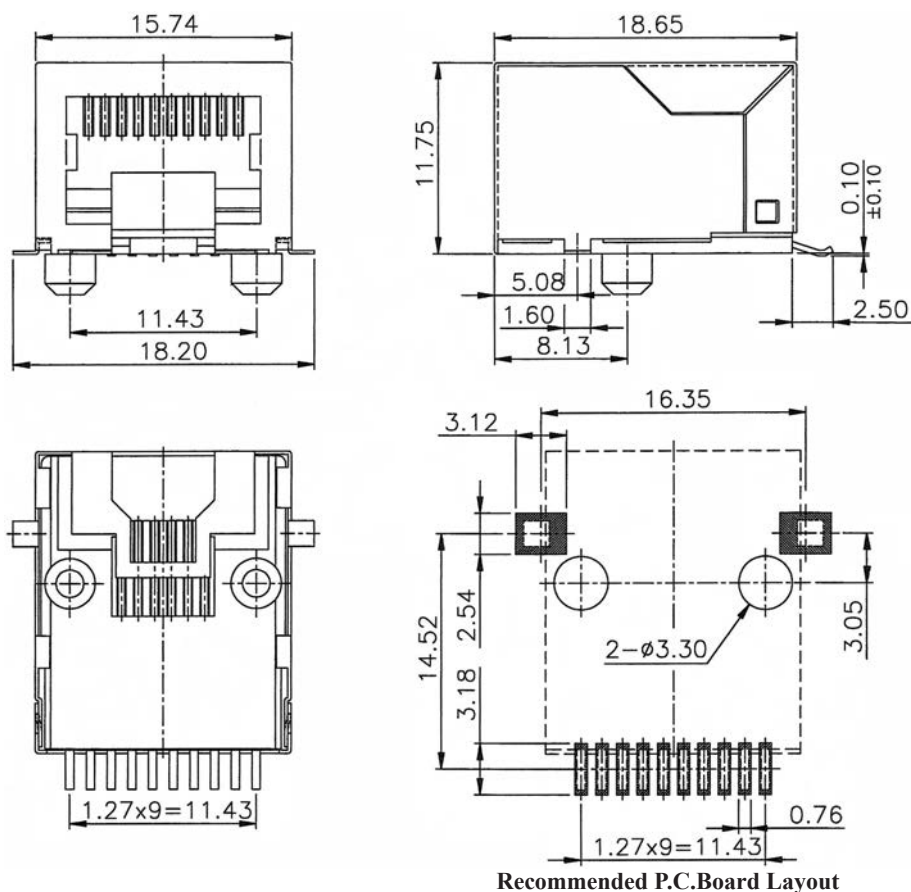
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 9 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

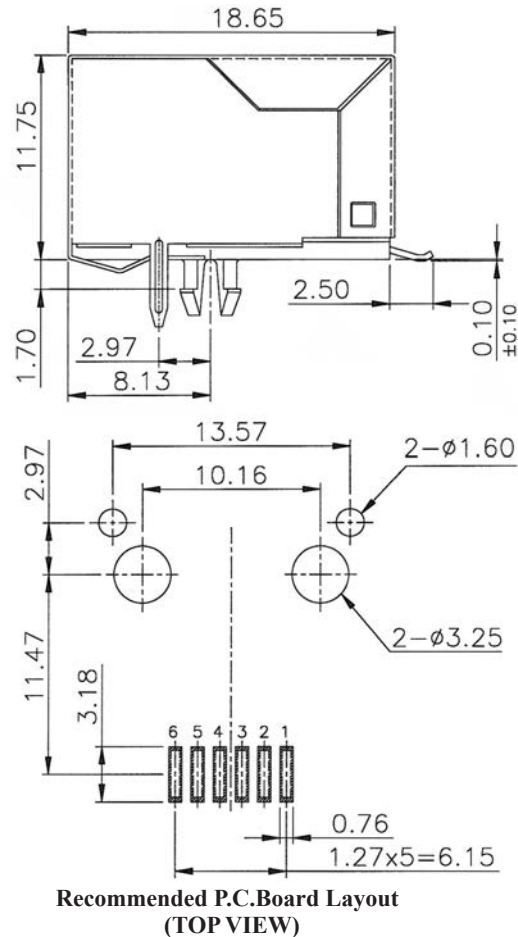
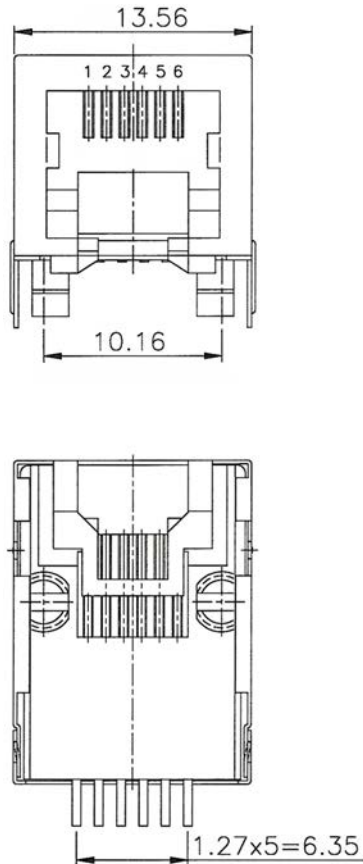
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 S - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

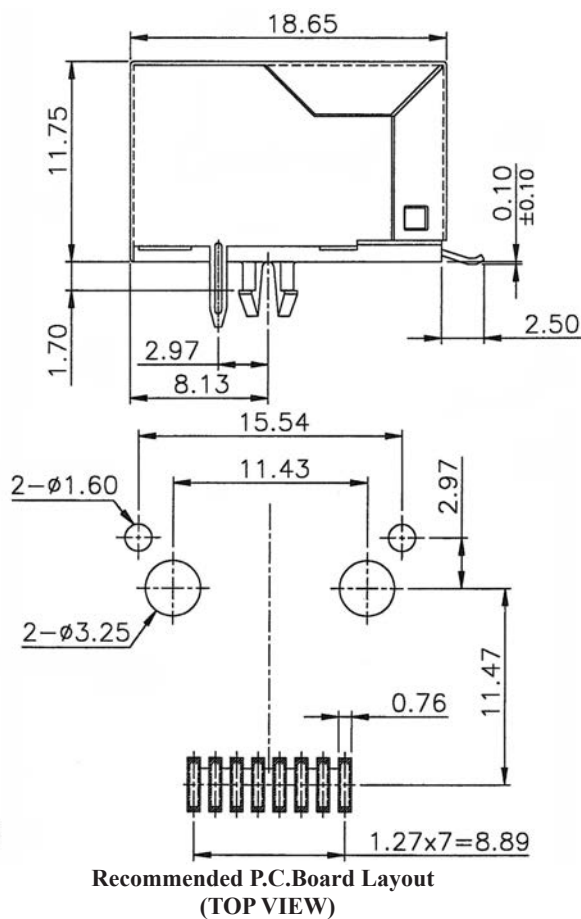
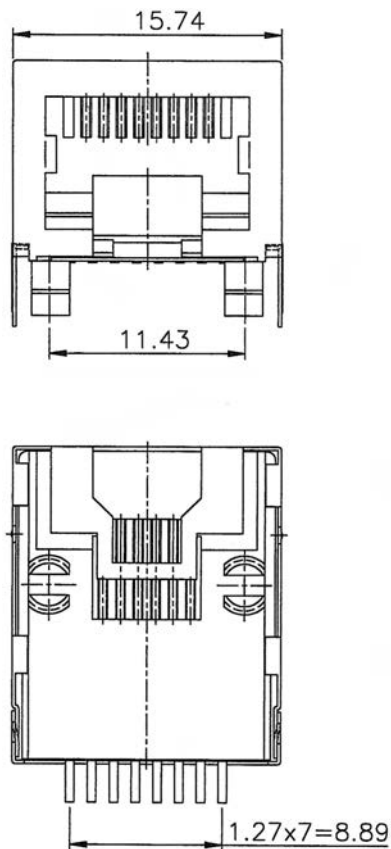
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 6 S - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

IR Reflow Soldering Temperature: 255°C To 265°C(5~10 Seconds)

MATERIALS

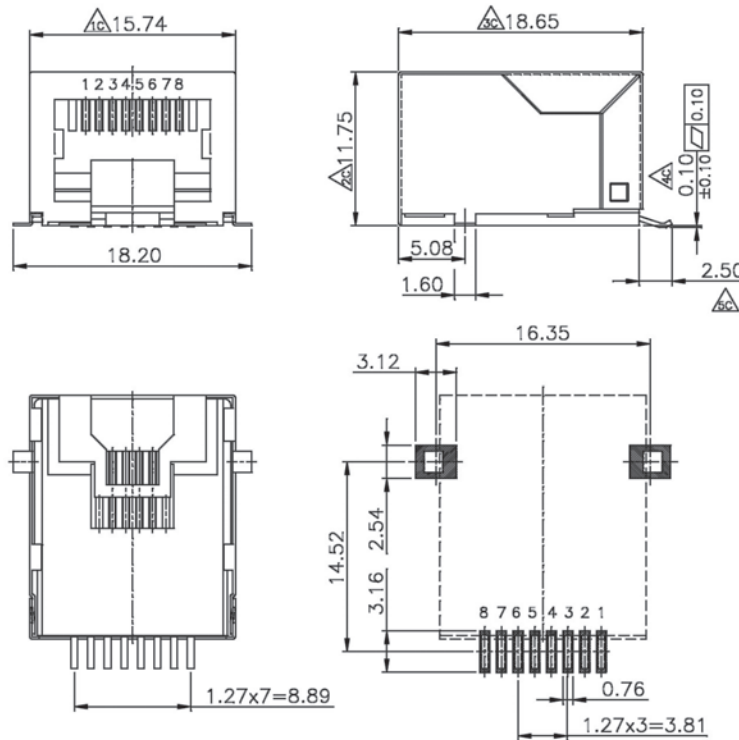
Plastic Housing: High Temp. Thermoplastic
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

Shield: Brass Plating Nickel Alloy.

* RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{6F}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"6F" SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

NOTE: WITHOUT LOCATING PEGS

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

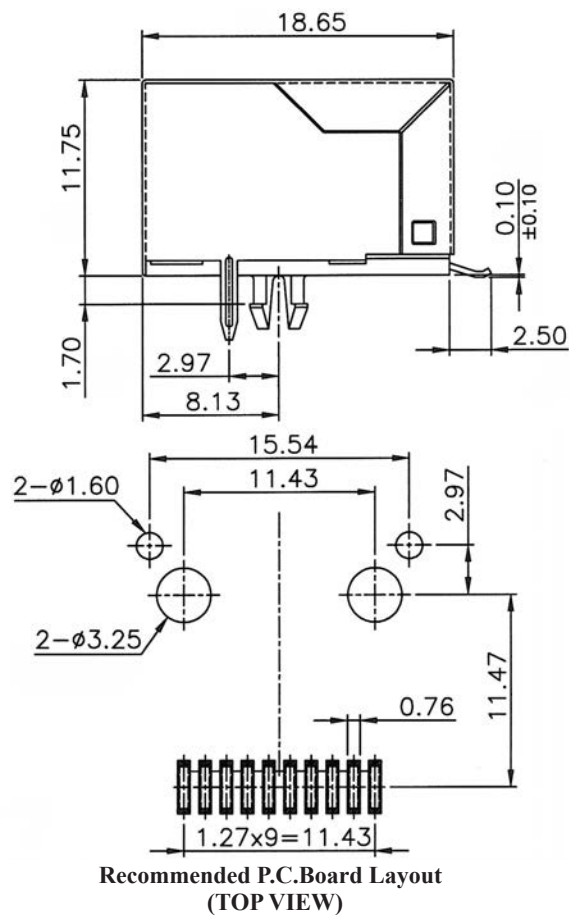
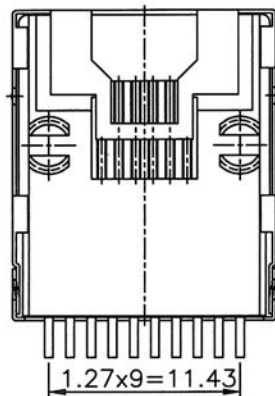
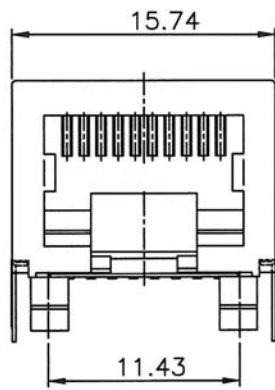
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 6 S - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

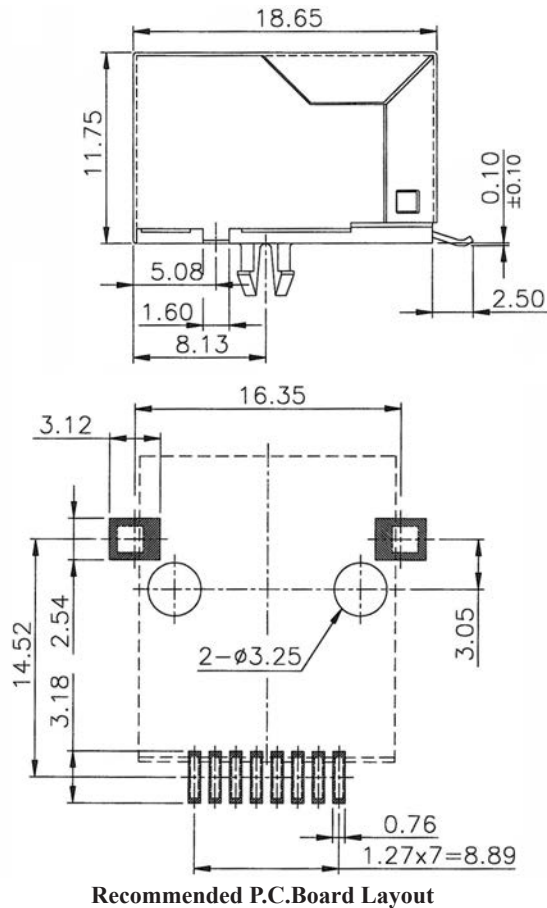
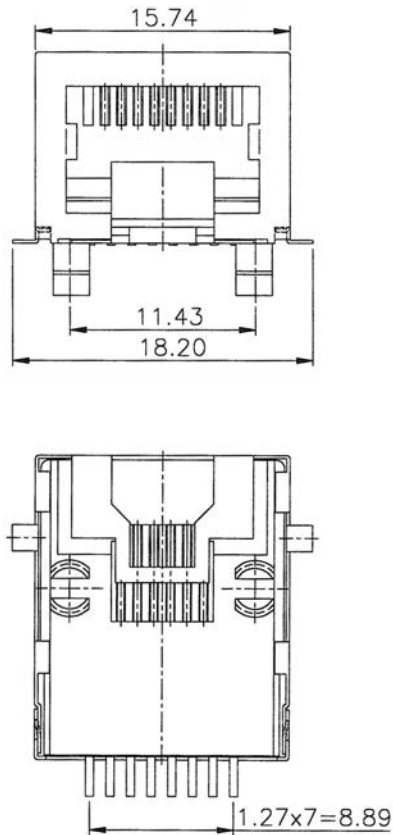
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 8 N - $\frac{88}{1} \frac{x}{2} \frac{B}{3} \frac{x}{4}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

4. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

NOTE: 3.05MM SPACING BEFORE PEG

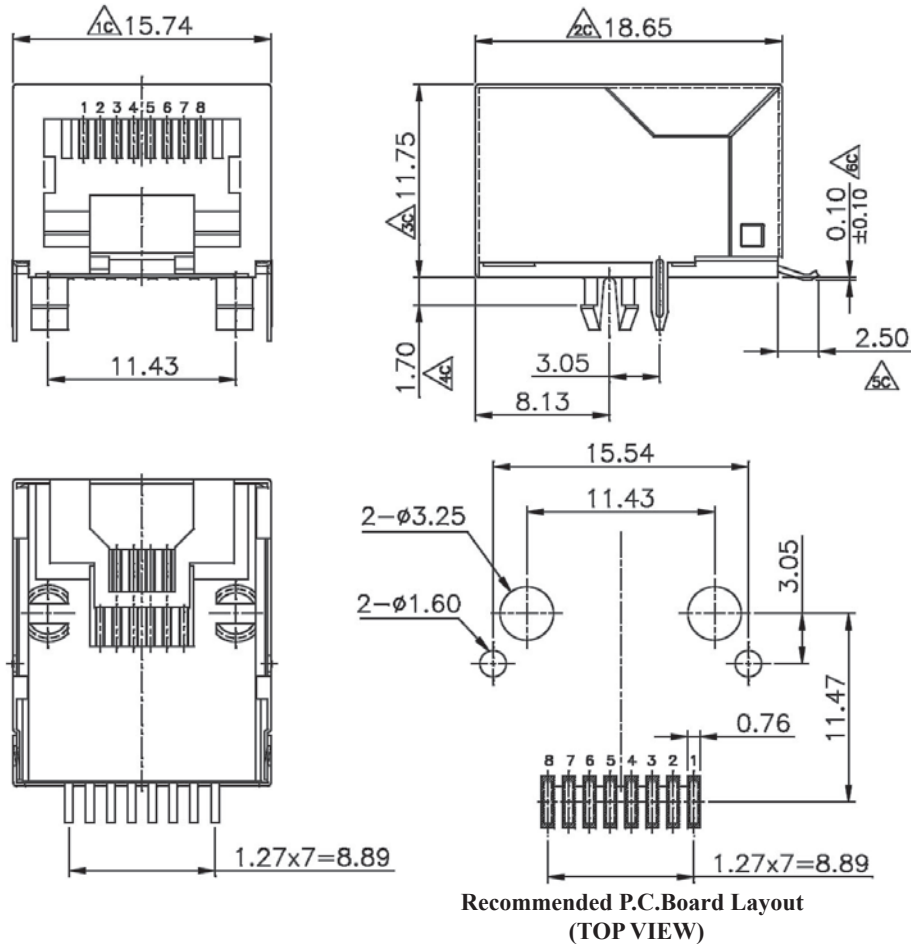
SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{6}{1}$ H - $\frac{88}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"6H" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

NOTE: 3.05MM SPACING BEHIND PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

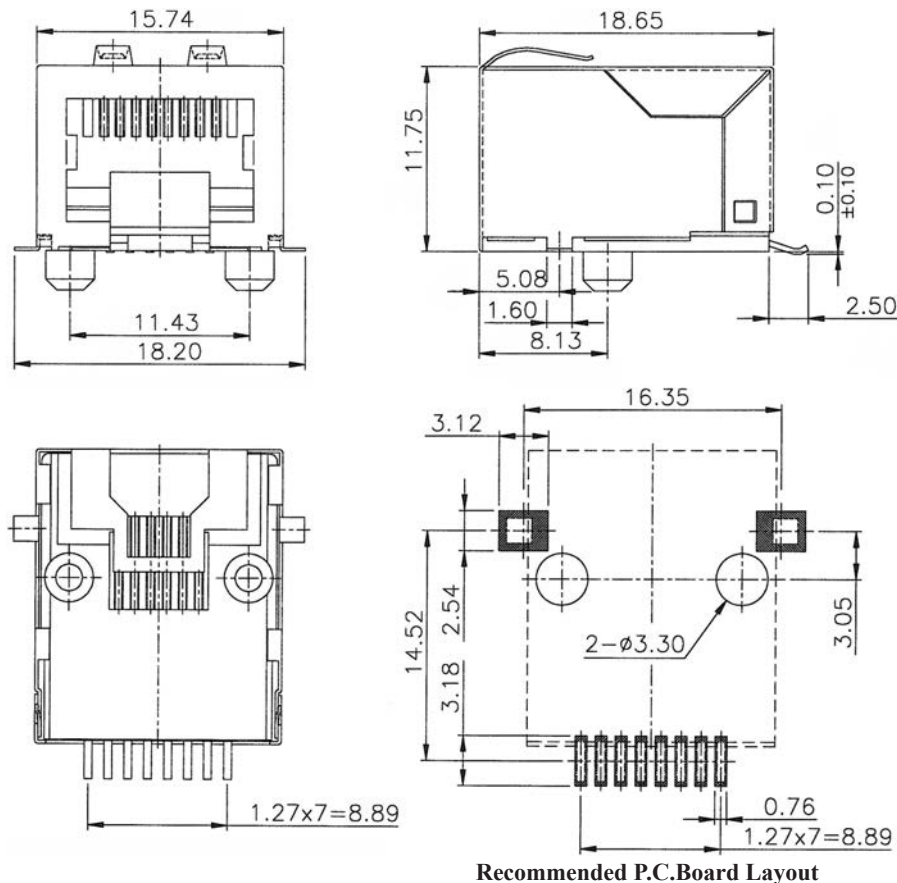
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 W - $\frac{88}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

NOTE: 3.05MM SPACING BEFORE PEG

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

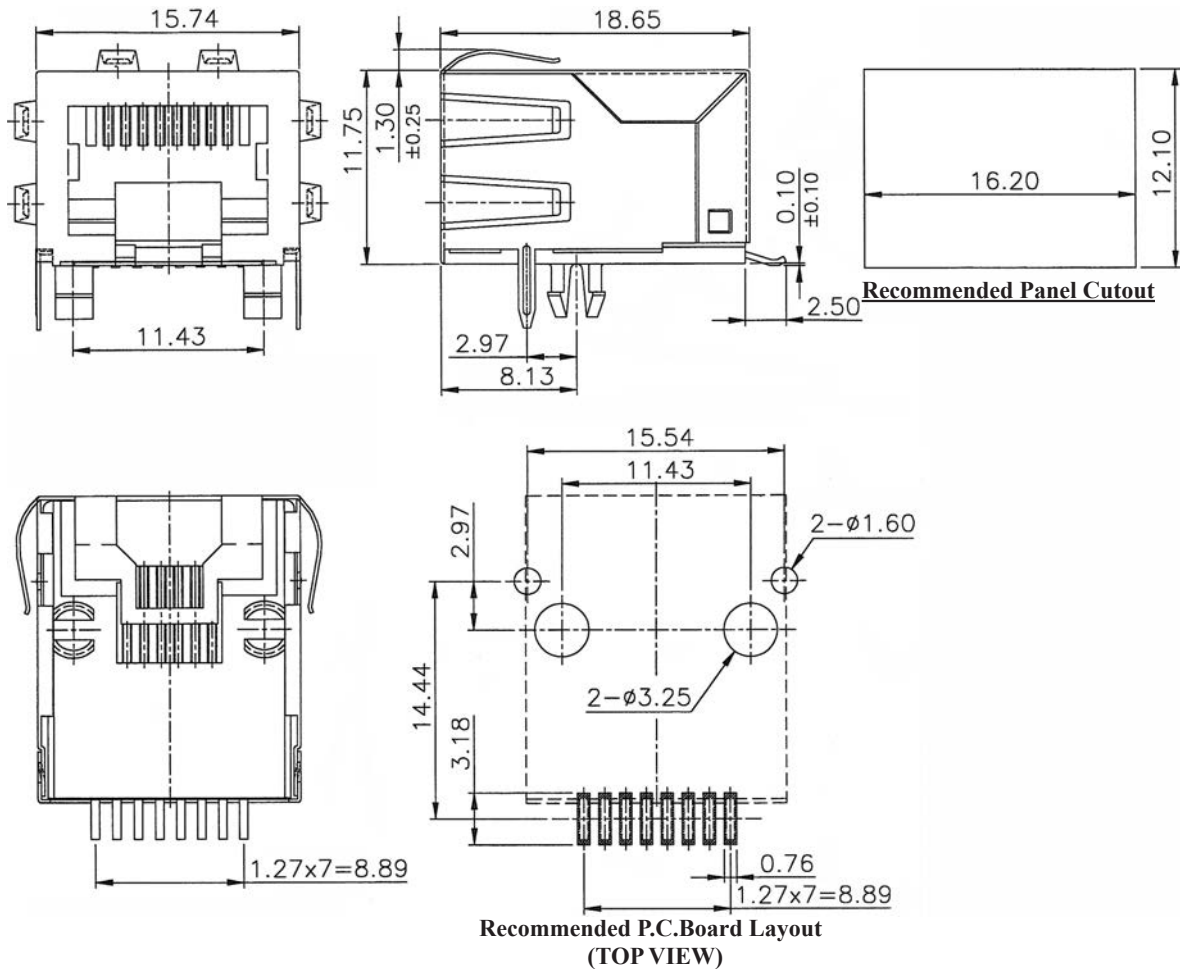
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 Y - $\frac{x}{1} \frac{x}{2} \frac{x}{3}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

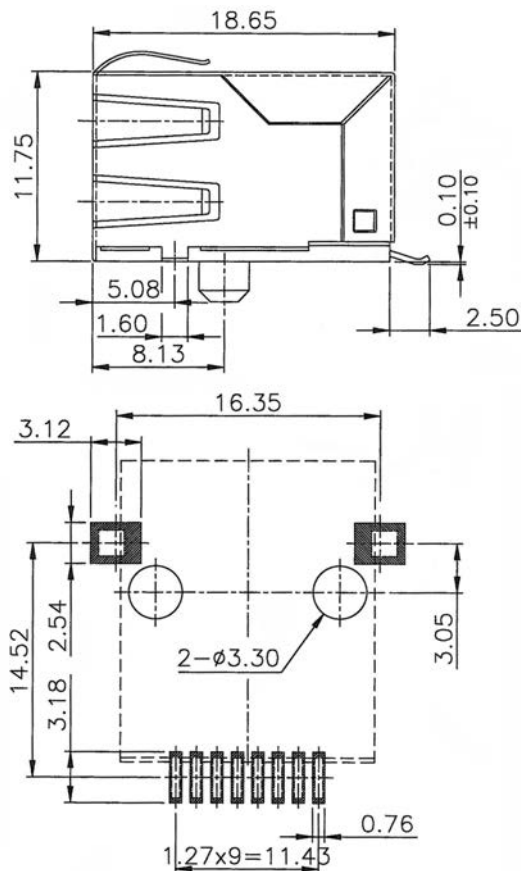
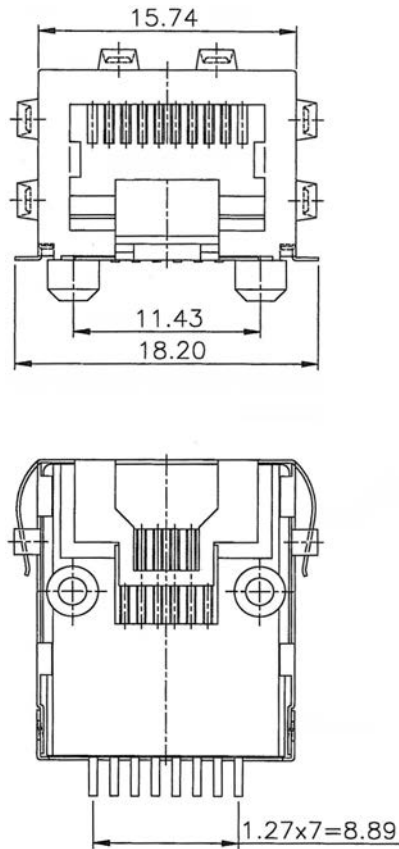
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J 2 Z - $\frac{x}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

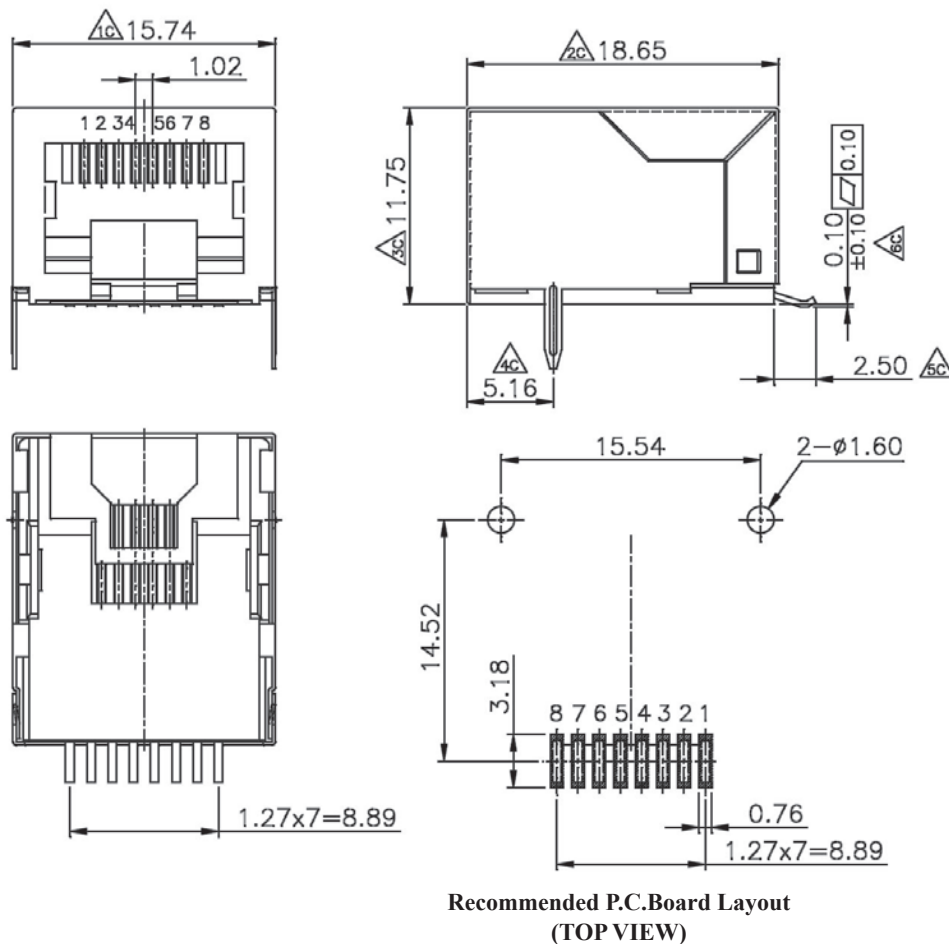
SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.75MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 6 K - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.90MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500 Megohms Min

Contact Resistance: 20 Milliohms Max.

Current Rating: 1.5 A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C To +85°C.

Operating: 500 Cycles Min.

MATERIALS

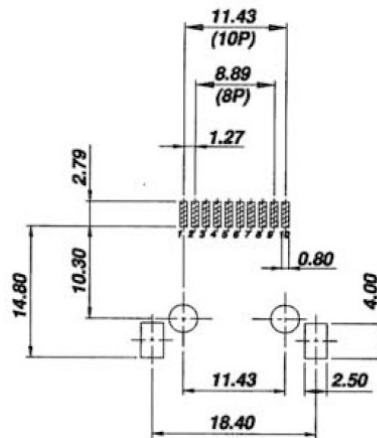
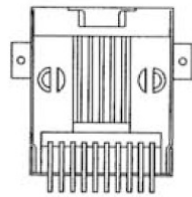
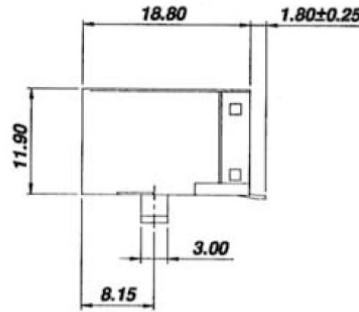
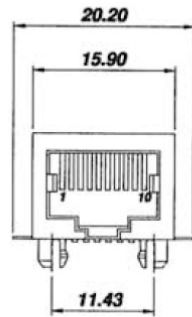
Housing: Nylon(UL 94V-0), Soldering Temperature:260°C

Color: Black

Spring Wire: 0.35mm Thickness Phosphor Bronze Over Nickel

Shield: Brass Plating Nickel

* RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J L Q - $\frac{x}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"08" 10P8C
"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.90MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

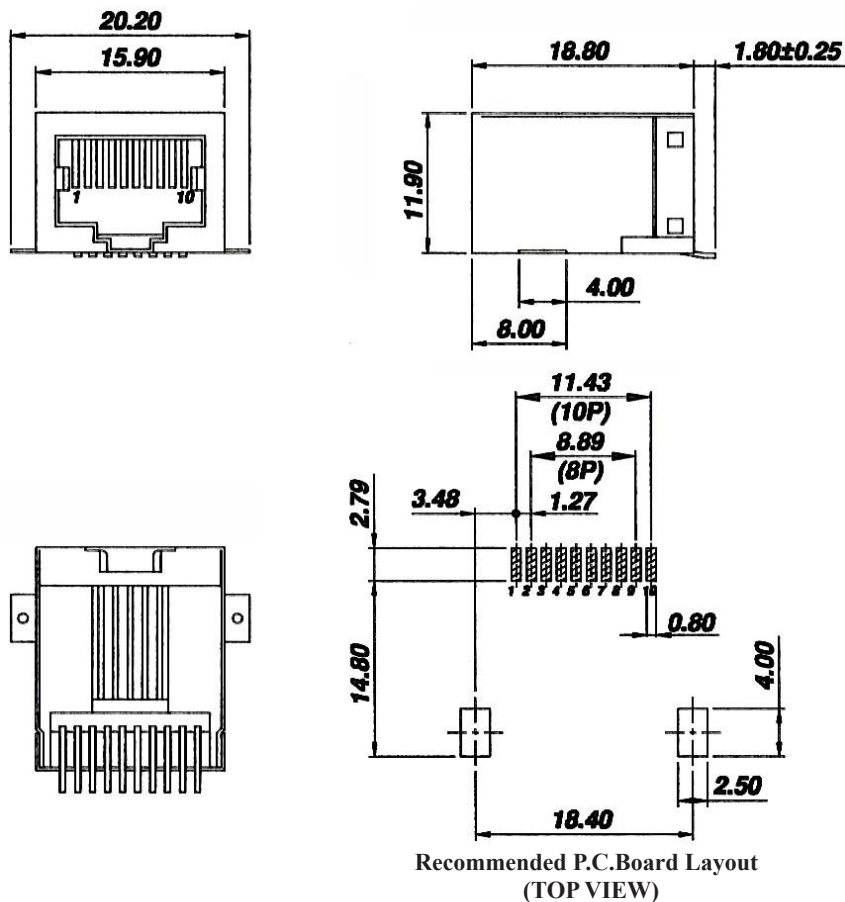
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R Z - $\frac{x}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.90MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500 Megohms Min

Contact Resistance: 20 Milliohms Max.

Current Rating: 1.5 A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C To +85°C.

Operating: 500 Cycles Min.

MATERIALS

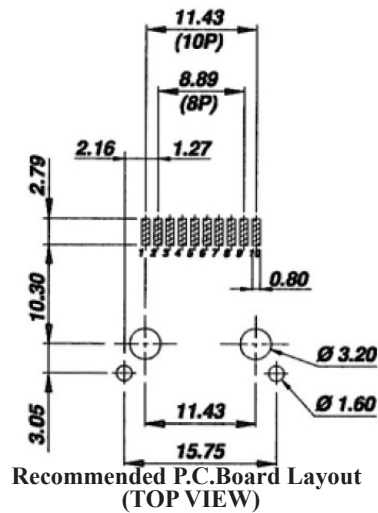
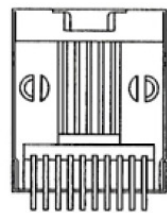
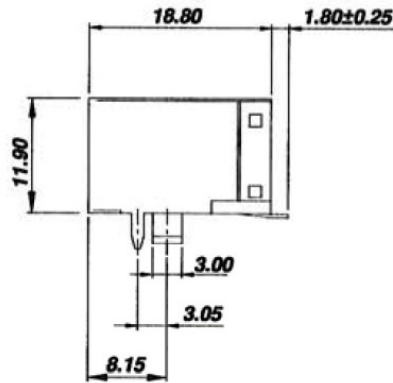
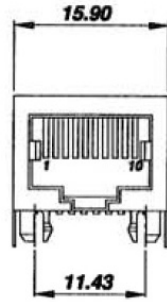
Housing: Nylon(UL 94V-0), Soldering Temperature:260°C

Color: Black

Spring Wire: 0.35mm Thickness Phosphor Bronze Over Nickel

Shield: Brass Plating Nickel

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J L R - $\frac{x}{T} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

- "08" 10P8C
- "00" 10P10C

2. CONTACT FINISH:

- "A" 6 MICROINCH GOLD
- "B" 15 MICROINCH GOLD
- "C" 30 MICROINCH GOLD
- "D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

- " " TRAY
- "R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

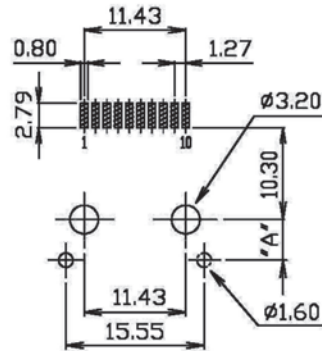
Color: Black

Spring Wire: Phosphor Bronze

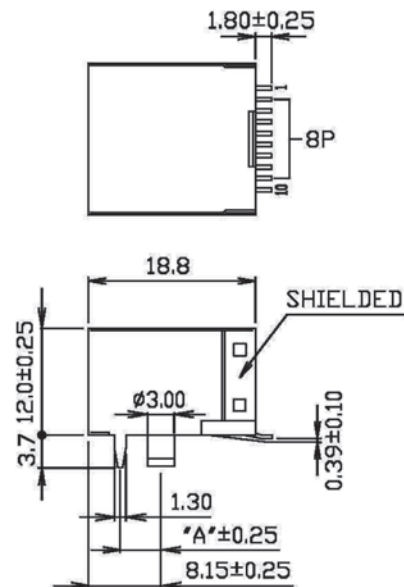
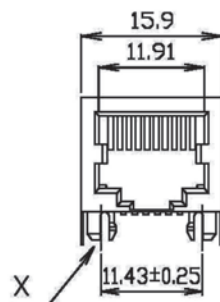
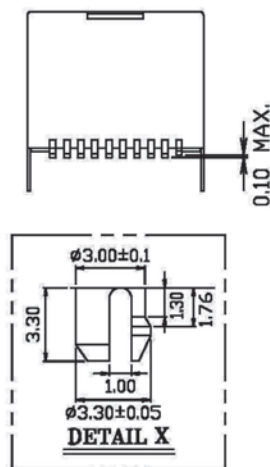
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J $\frac{F}{1}$ $\frac{G}{2}$ - 00 $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"FG" LOW PROFILE SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P8C PROFILE=12.00MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

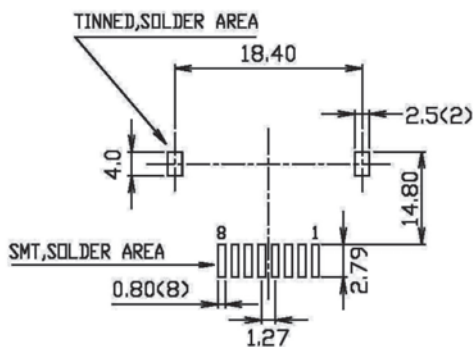
Color: Black

Spring Wire: Phosphor Bronze

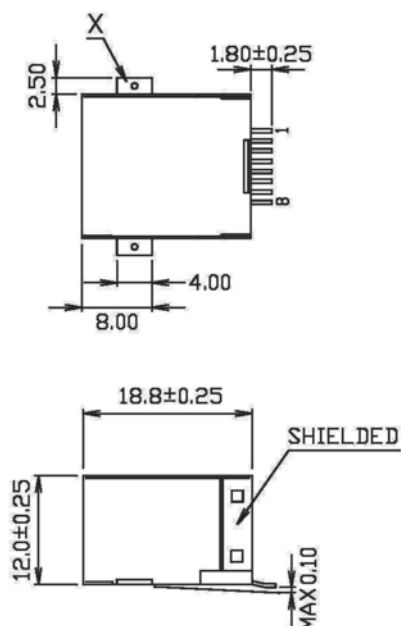
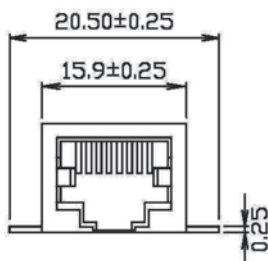
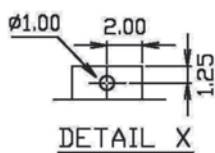
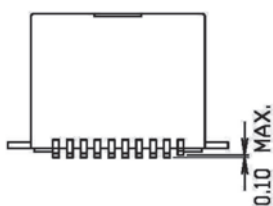
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C. Board Layout



ORDERING INFORMATION:

P/N M J $\frac{FH}{1}$ - $\frac{08}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

- MODULAR JACK TYPE:
"FH" LOW PROFILE SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK
- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

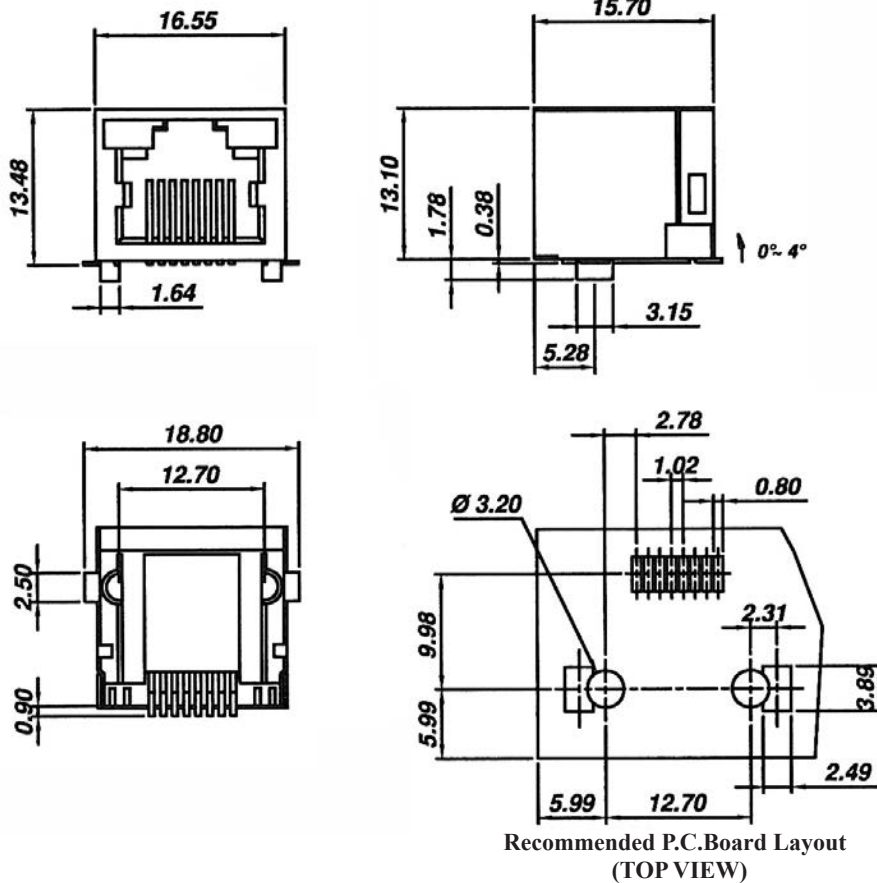
SIDE ENTRY UP LATCH MODULAR SMT JACK 8P PROFILE=13.10MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J R P - $\frac{88}{T} \times \frac{B}{2} - \frac{X}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

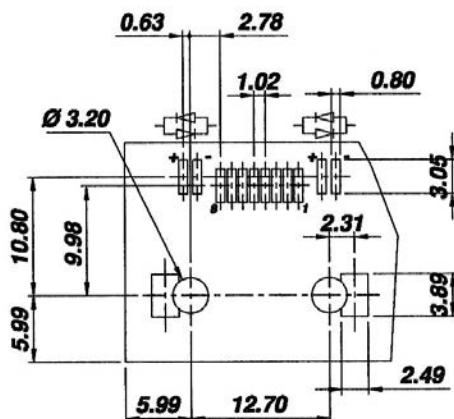
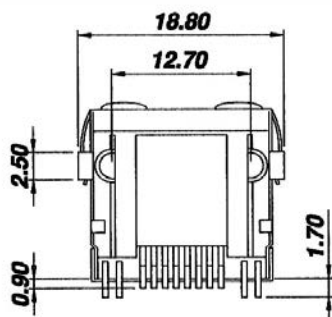
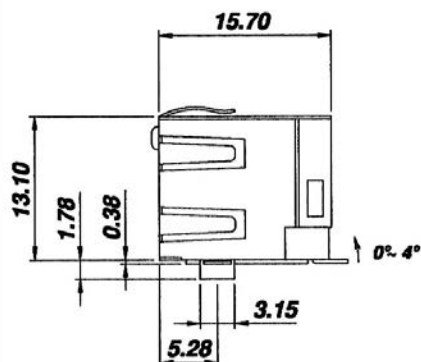
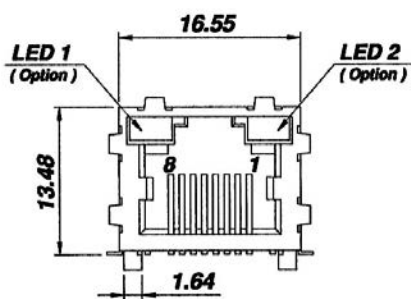
SIDE ENTRY UP LATCH MODULAR SMT JACK WITH LED 8P PROFILE=13.10MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
 *RoHS & REACH compliant.



Recommended P.C.Board Layout (TOP VIEW)

ORDERING INFORMATION:

P/N M J R Q - $\frac{88}{1}$ $\frac{x}{2}$ $\frac{B}{3}$ $\frac{x}{4}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
- CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=13.19MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

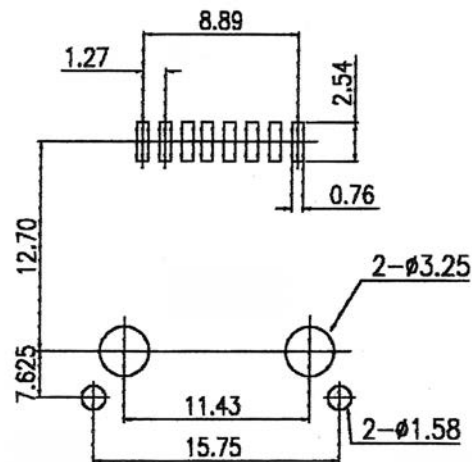
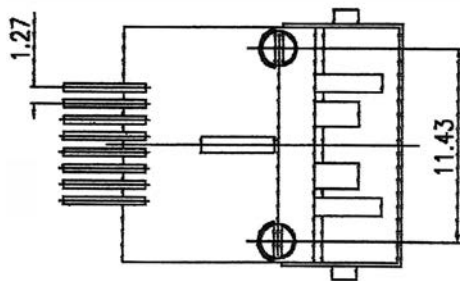
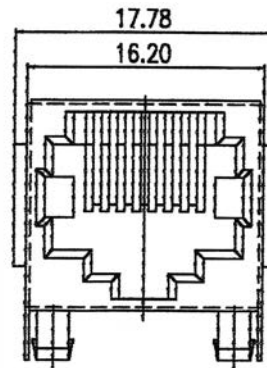
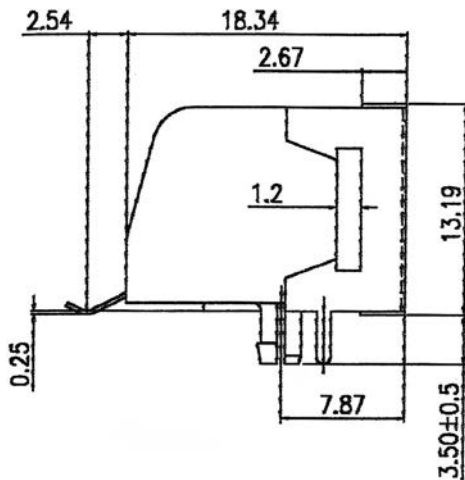
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

*RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J 3 0 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"86" 8P6C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

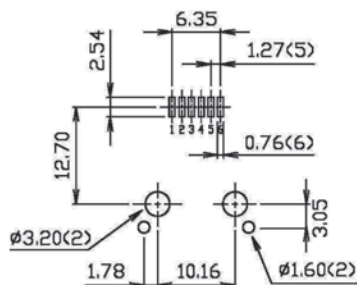
SIDE ENTRY MODULAR SMT JACK 6P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

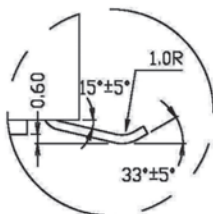
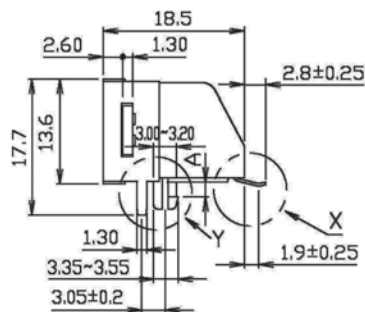
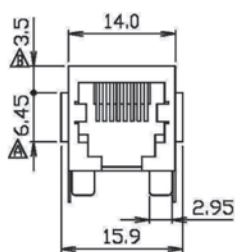
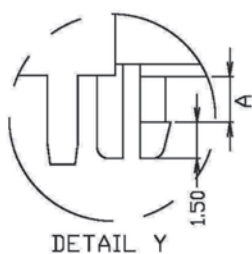
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

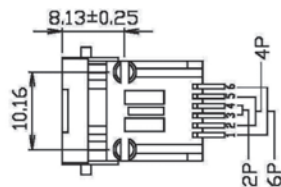
Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass Plating Nickel Alloy
 * RoHS & REACH compliant.



Recommended P.C.Board Layout



DETAIL X



ORDERING INFORMATION:

P/N M J $\frac{F M}{1}$ - $\frac{66}{2}$ $\frac{x}{3}$ B

- MODULAR JACK TYPE:
"FM" HALF SHIELDED SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=13.60MM (HALF SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

Soldering Temperature: 260°C

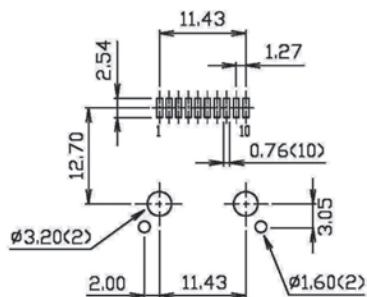
Color: Black

Spring Wire: Phosphor Bronze

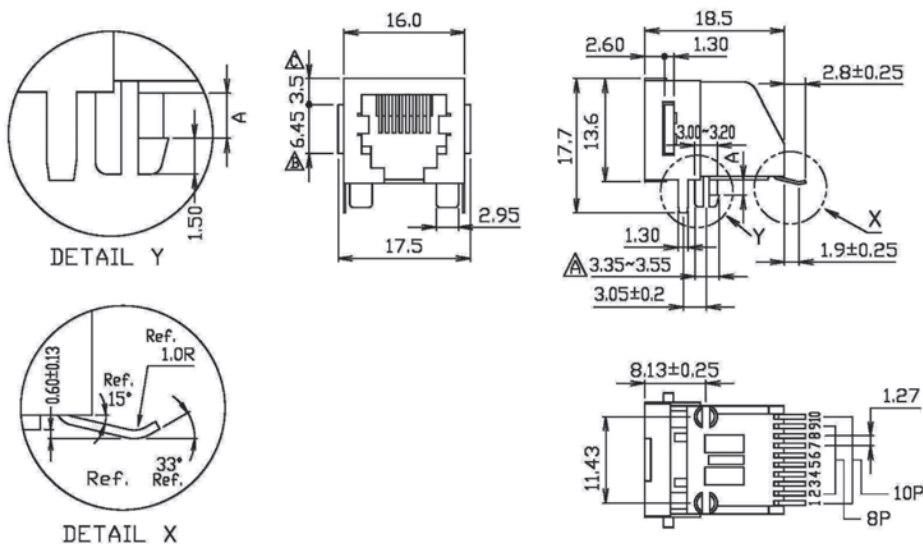
Gold plating Over Nickel

Shield: Brass Plating Nickel Alloy

* RoHS & REACH compliant.



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J $\frac{F}{1} \frac{M}{2} - \frac{x}{3} \frac{x}{3} \frac{x}{3} B$

1. MODULAR JACK TYPE:
"FM" HALF SHIELDED SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK

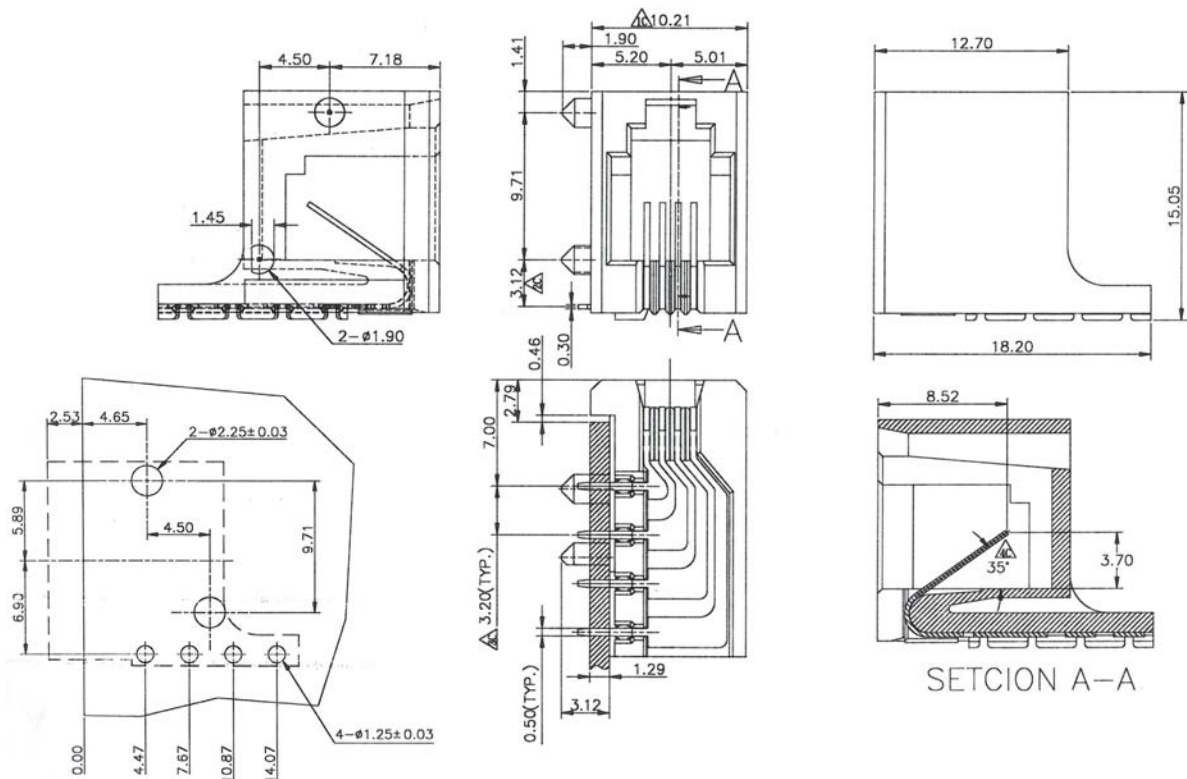
SIDE ENTRY MODULAR PCB JACK 4P NORTEL TYPE PROFILE=10.21MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J Y J - 44 C B
 1 2 3 4

1. MODULAR JACK TYPE:
"YJ" NORTEL 4P4C JACK
2. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
3. CONTACT FINISH:
"C" 30 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

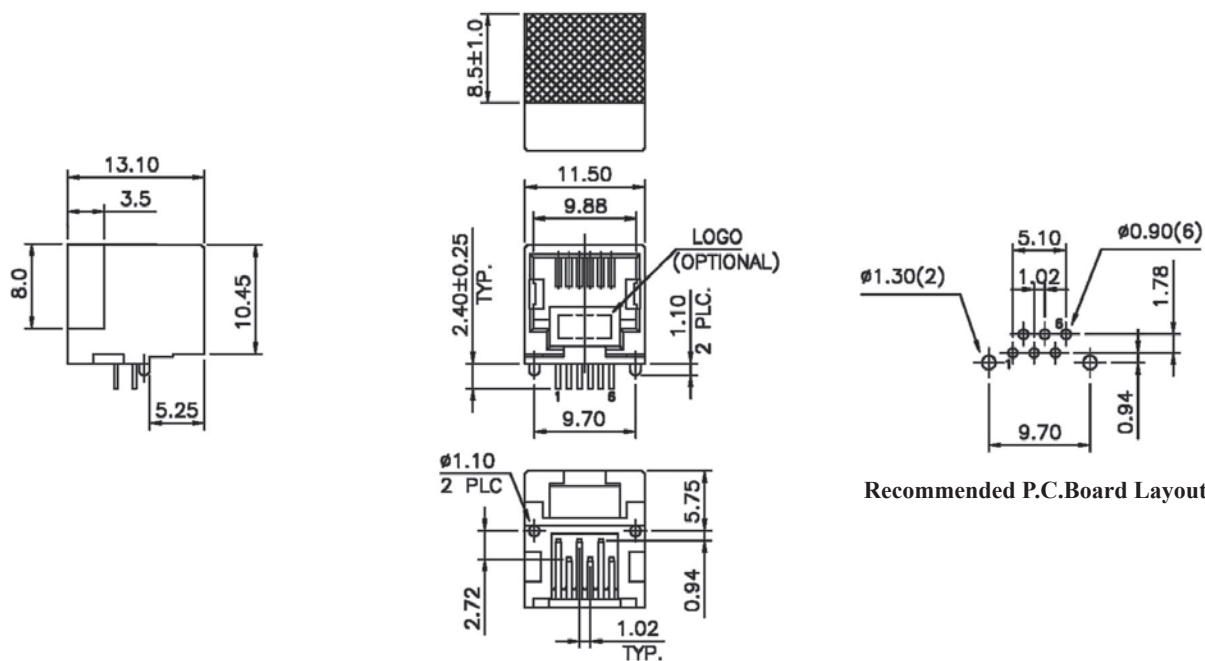
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=10.45MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J Y E - 6 6 x B
I 2 3 4

1. MODULAR JACK TYPE:
"YE" RJ11 JACK
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

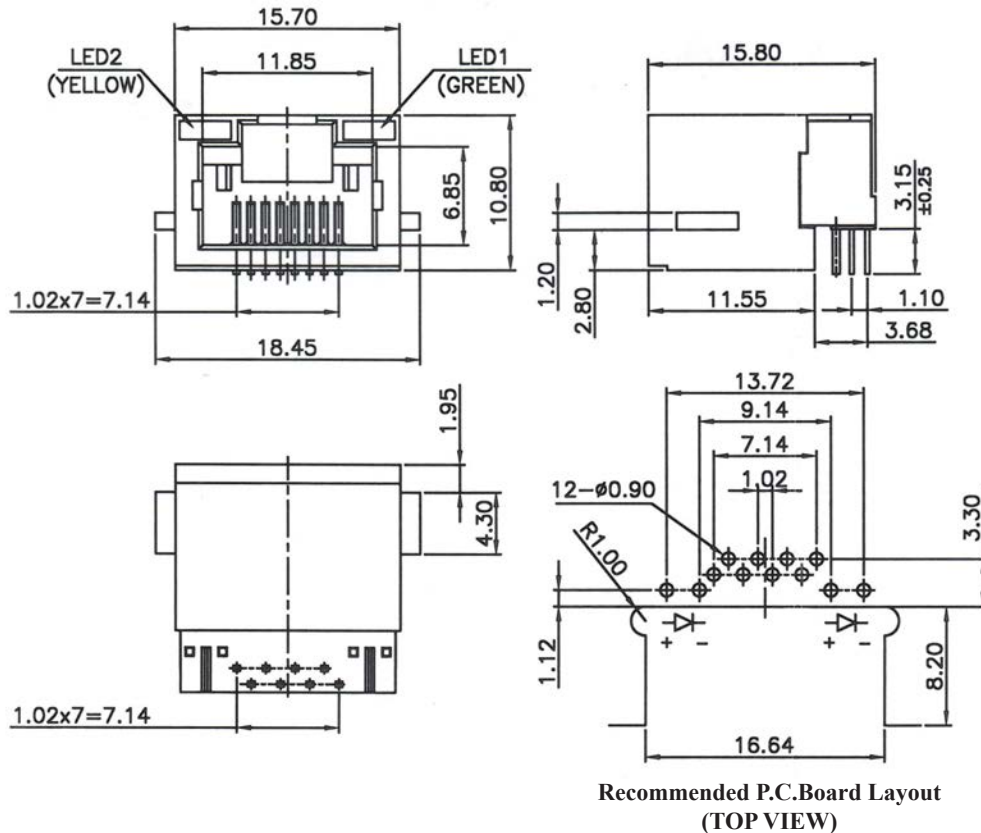
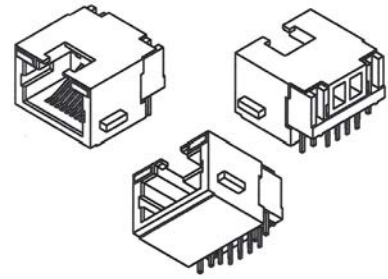
SIDE ENTRY EMBEDDED MODULAR PCB JACK 8P PROFILE=10.80MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J B 8 - 8 8 X B X X
1 2 3 4

1. MODULAR JACK TYPE:
"B8" EMBEDDED PCB JACK
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. COLORS OF LED:
"NY" LED 1/2: GREEN/YELLOW
"YN" LED 1/2: YELLOW/GREEN

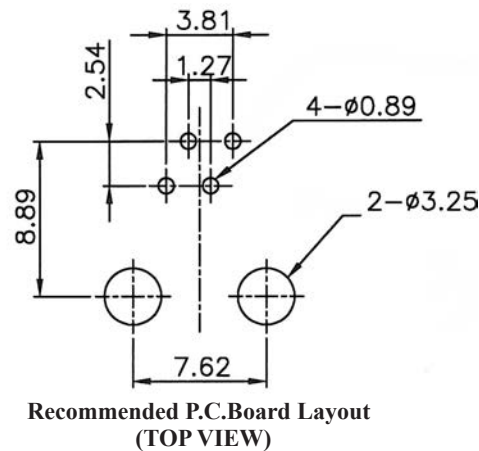
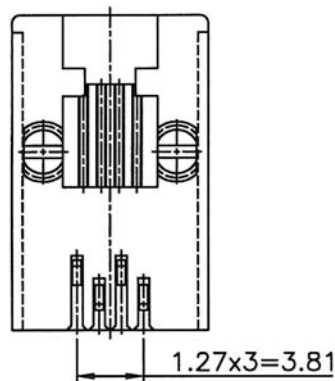
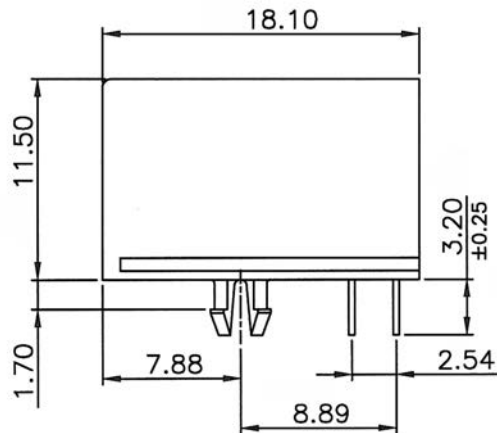
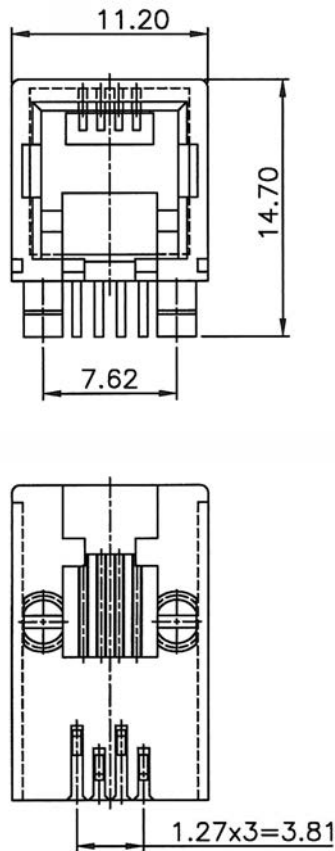
SIDE ENTRY MODULAR PCB JACK 4P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 6 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
"44" 4P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" GOLD FLASH
- HOUSING COLOR:
"B" BLACK (STANDARD)
"W" WHITE

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

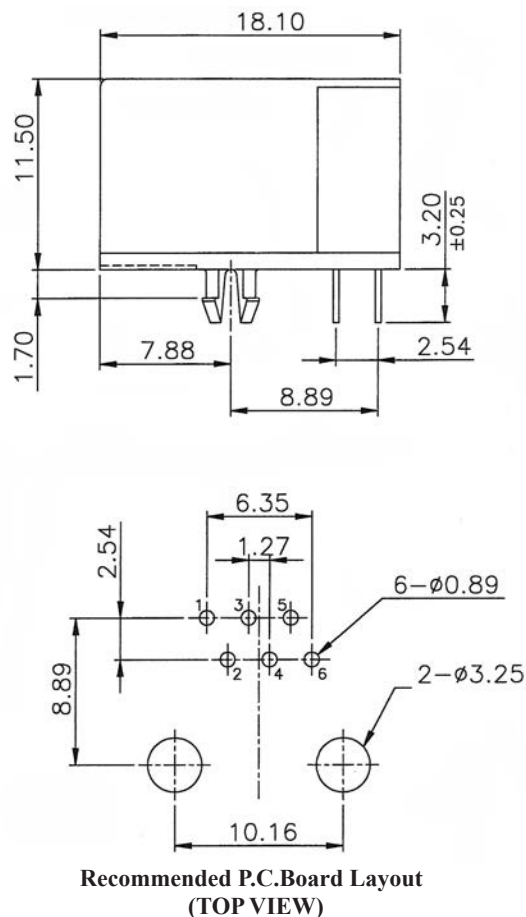
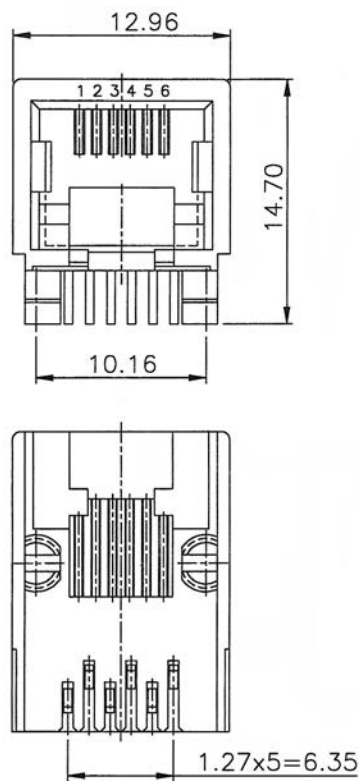
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 6 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"B" BLACK (STANDARD)

"A" GRAY

NOTE: P/N MJ16HT-66xx FOR HIGH TEMP. VERSION

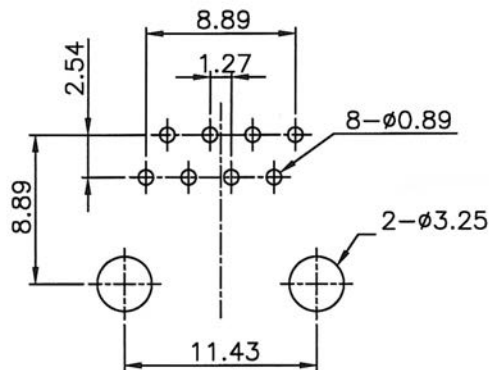
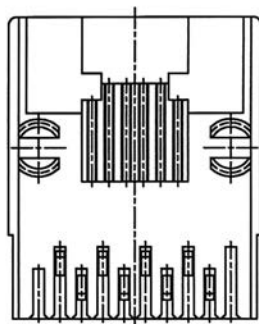
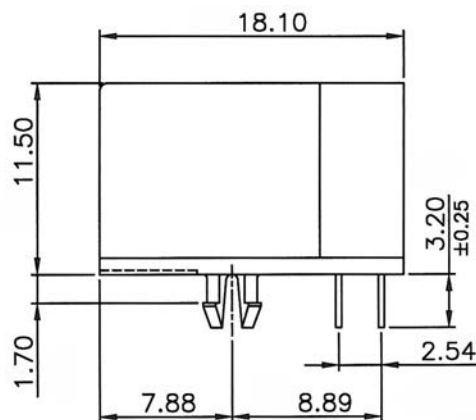
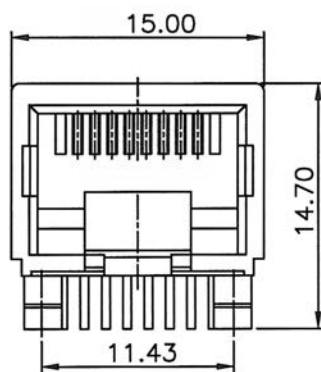
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ 16 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4}$ B $\frac{x}{1} \frac{x}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
 "84" 8P4C
 "86" 8P6C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"B" BLACK (STANDARD)
 "A" GRAY
 "Y" YELLOW
 "N" GREEN
 "R" RED

4. KEY OPTION:

" " NON-KEYED
 "K" KEYED

NOTE: P/N MJ16HT-88xx FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

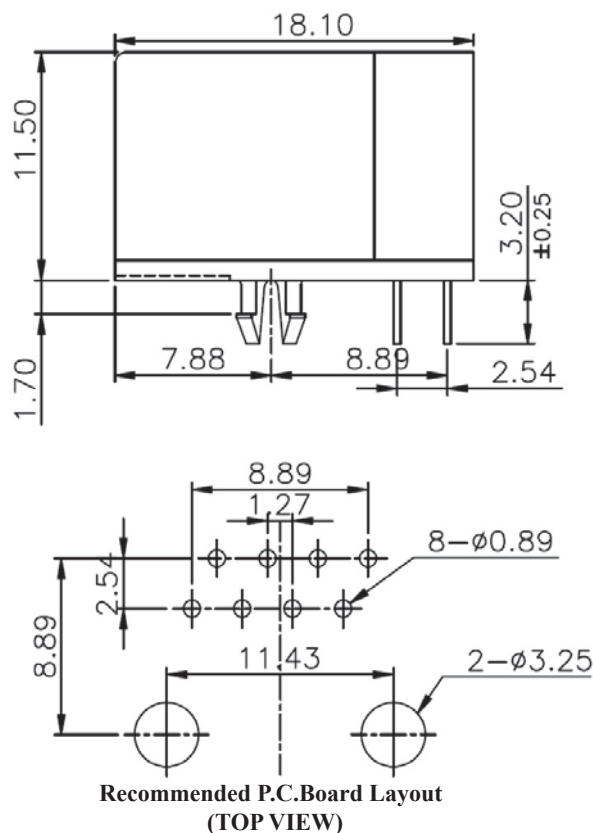
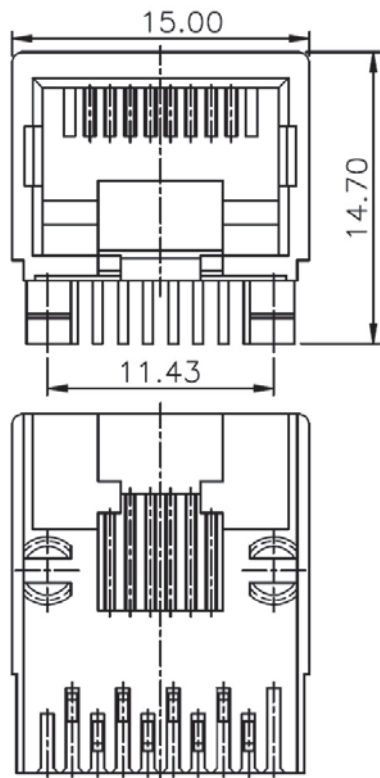
MATERIALS

Plastic Housing: Engineering Thermoplastic
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,
Tin Plating Over Nickel In Solder Area.

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ $\frac{16J}{1} - \frac{88}{2} \times \frac{B}{3}$

1. MODULAR JACK TYPE:
"16J" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: IT CAN BE USED FOR REPLACING P/N MJ16-88xB.

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

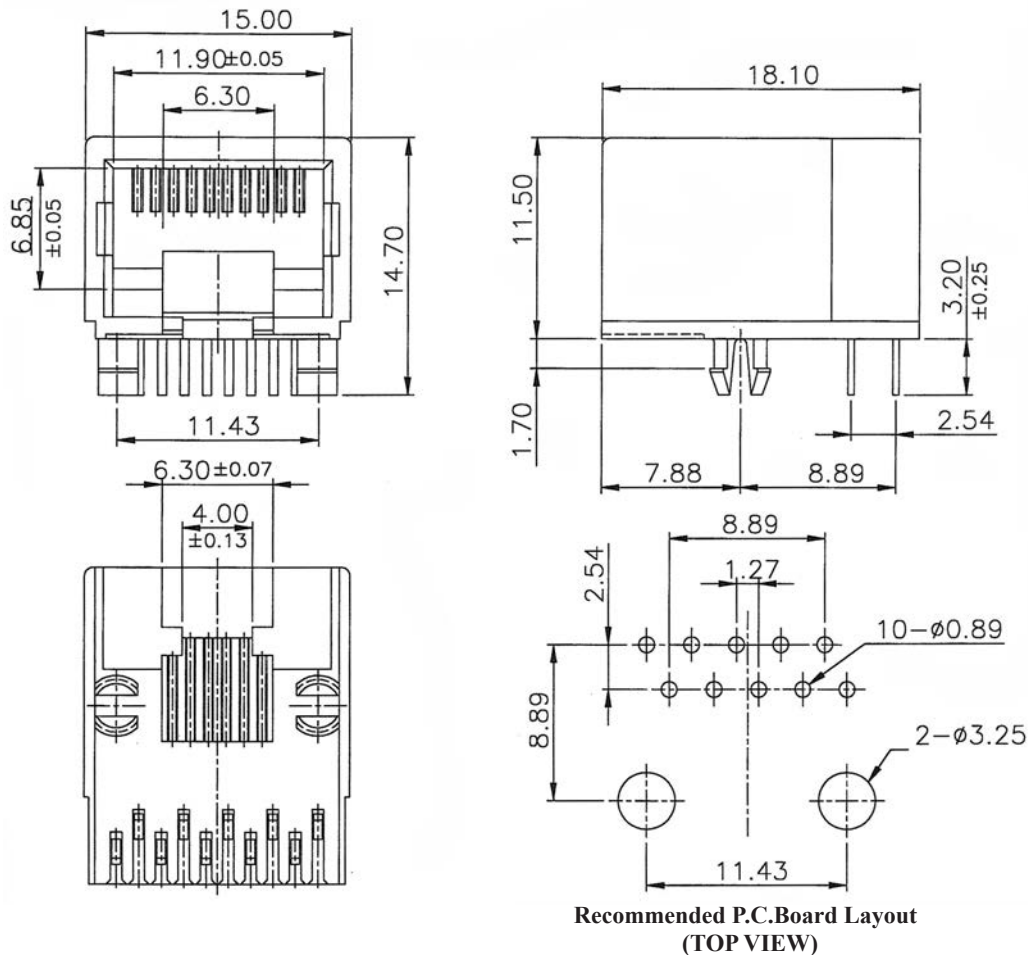
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 6 - $\frac{x x x B}{T 2}$

1. NO. OF POSITIONS & CONTACTS:

"08" 10P8C

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

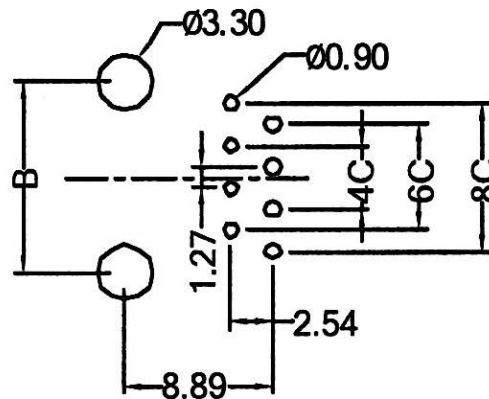
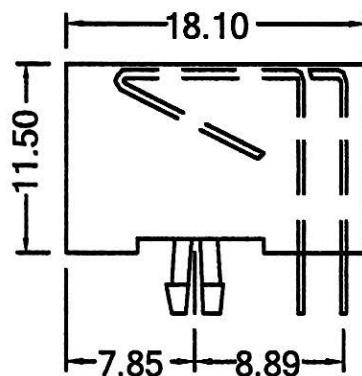
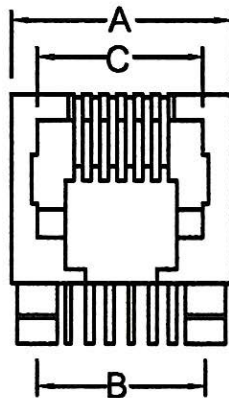
SIDE ENTRY MODULAR PCB JACK 4P+6P+8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

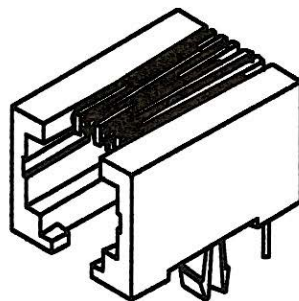
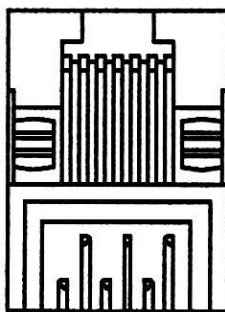
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)



No. of Positions	No. of Contacts	A	B	C
4P	4C	11.00	7.62	7.90
6P	2C/4C/6C	13.20	10.16	9.90
8P	8C	15.30	11.43	12.00

ORDERING INFORMATION:

P/N M J 2 2 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
 "E" GOLD FLASH

SIDE ENTRY MODULAR PCB JACK 4P+6P+8P+10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

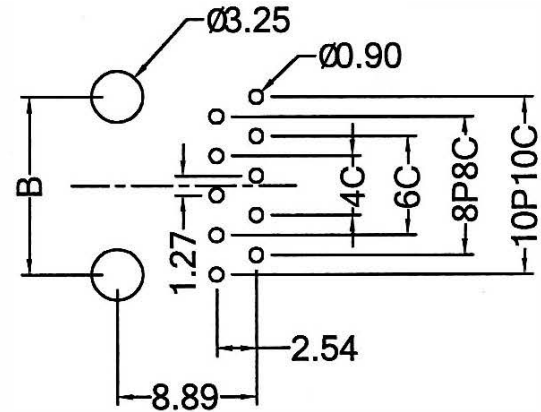
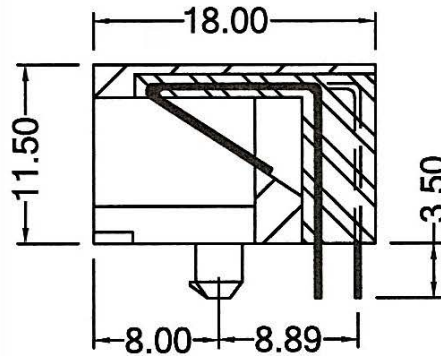
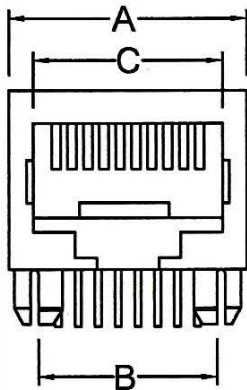
Soldering Temperature: 235°C

Color: Black

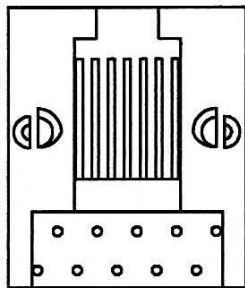
Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)



No. of Positions	No. of Contacts	A	B	C
4P	4C	11.20	7.62	7.80
6P	2C/4C/6C	13.20	10.16	10.00
8P	8C	15.20	11.43	12.00
10P	10C	15.20	11.43	12.00

ORDERING INFORMATION:

P/N M J L G - $\frac{xx}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

- "66" 6P6C
- "64" 6P4C
- "88" 8P8C
- "84" 8P4C
- "00" 10P10C
- "08" 10P8C
- "44" 4P4C

2. CONTACT FINISH:

- "A" 6 MICROINCH GOLD
- "B" 15 MICROINCH GOLD
- "C" 30 MICROINCH GOLD
- "D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

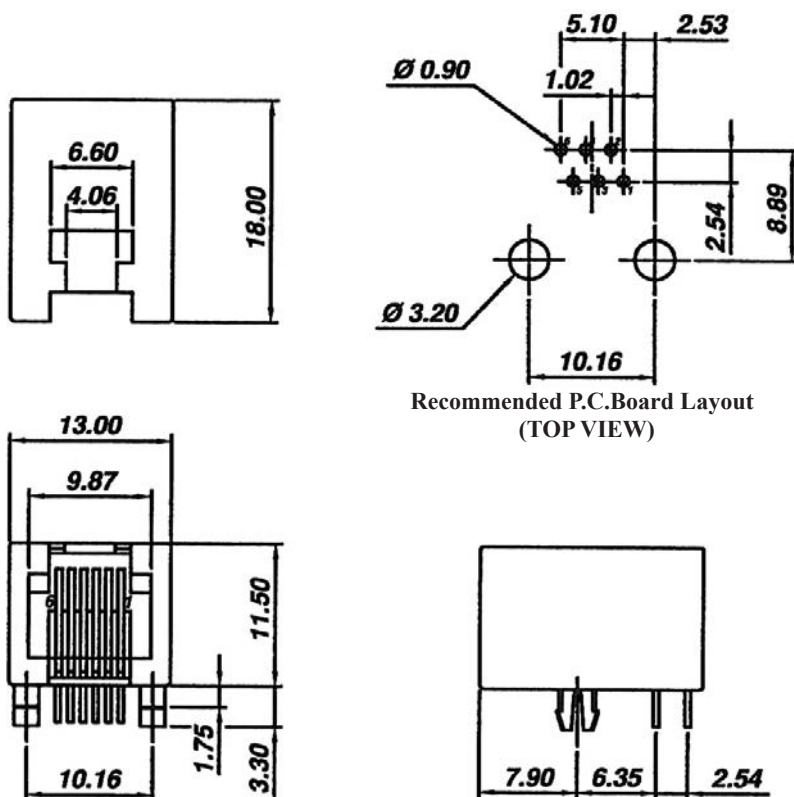
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ74 - $\frac{x}{1} \frac{x}{2} x$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJ74HT-xxx B FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

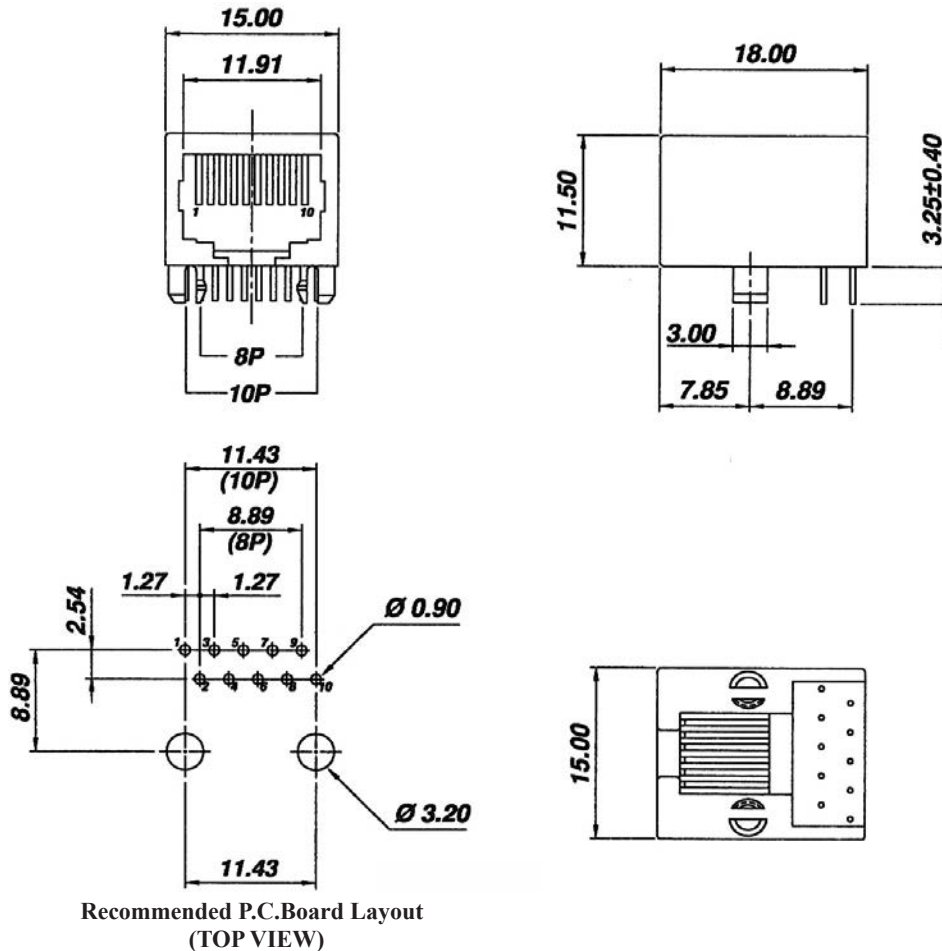
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJLA - $\frac{00}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLAHT-00xB FOR HIGH TEMP. VERSION

SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

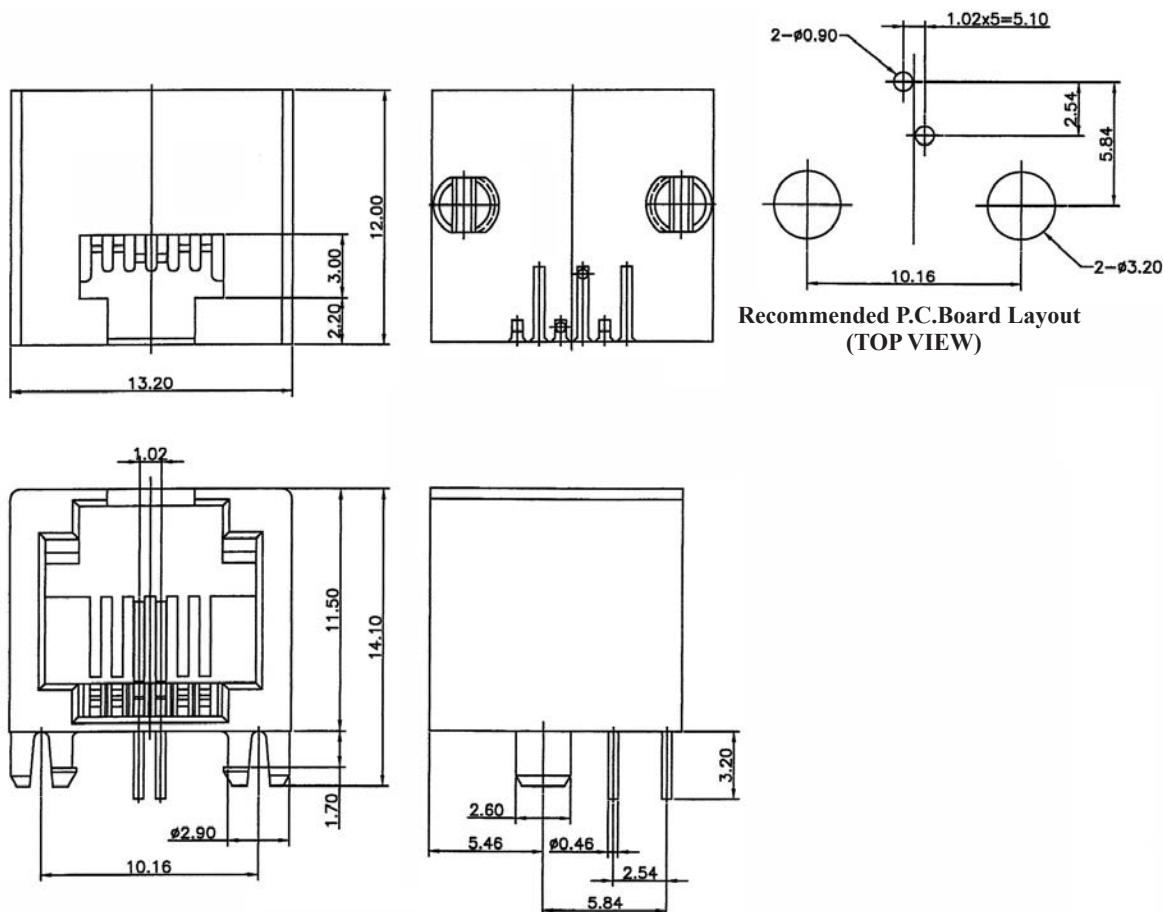
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ3T - $\frac{X X X}{T 2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

"62" 6P2C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

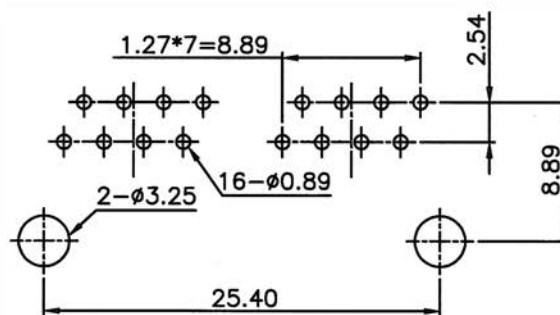
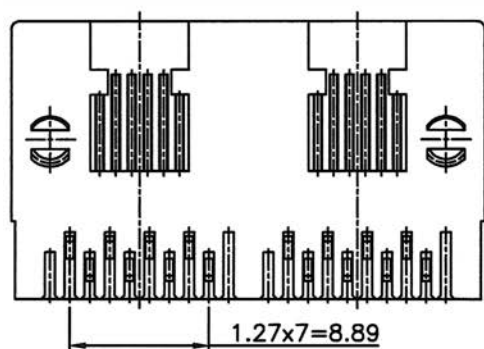
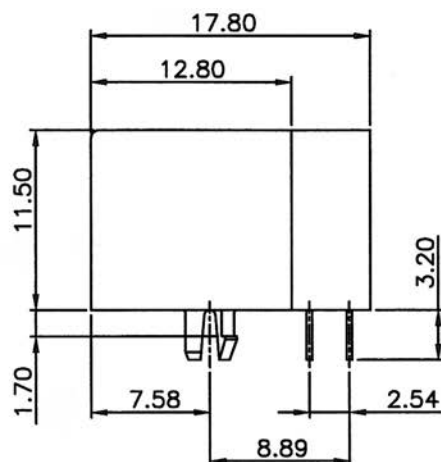
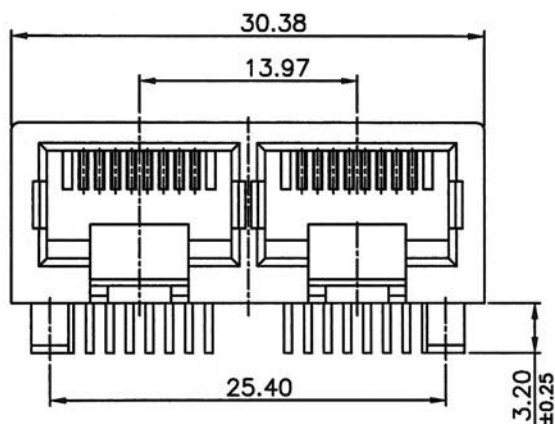
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 2 N - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 2$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

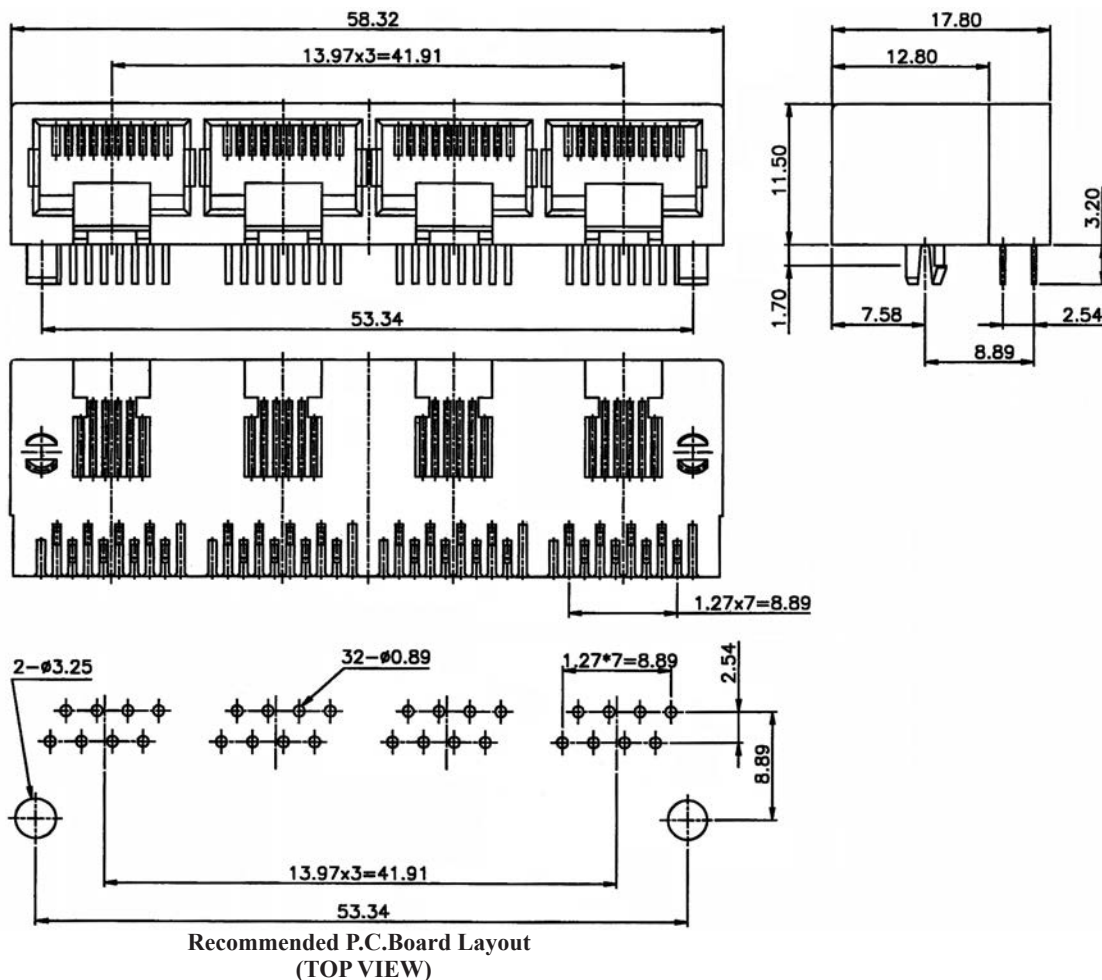
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 N - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} \frac{4}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

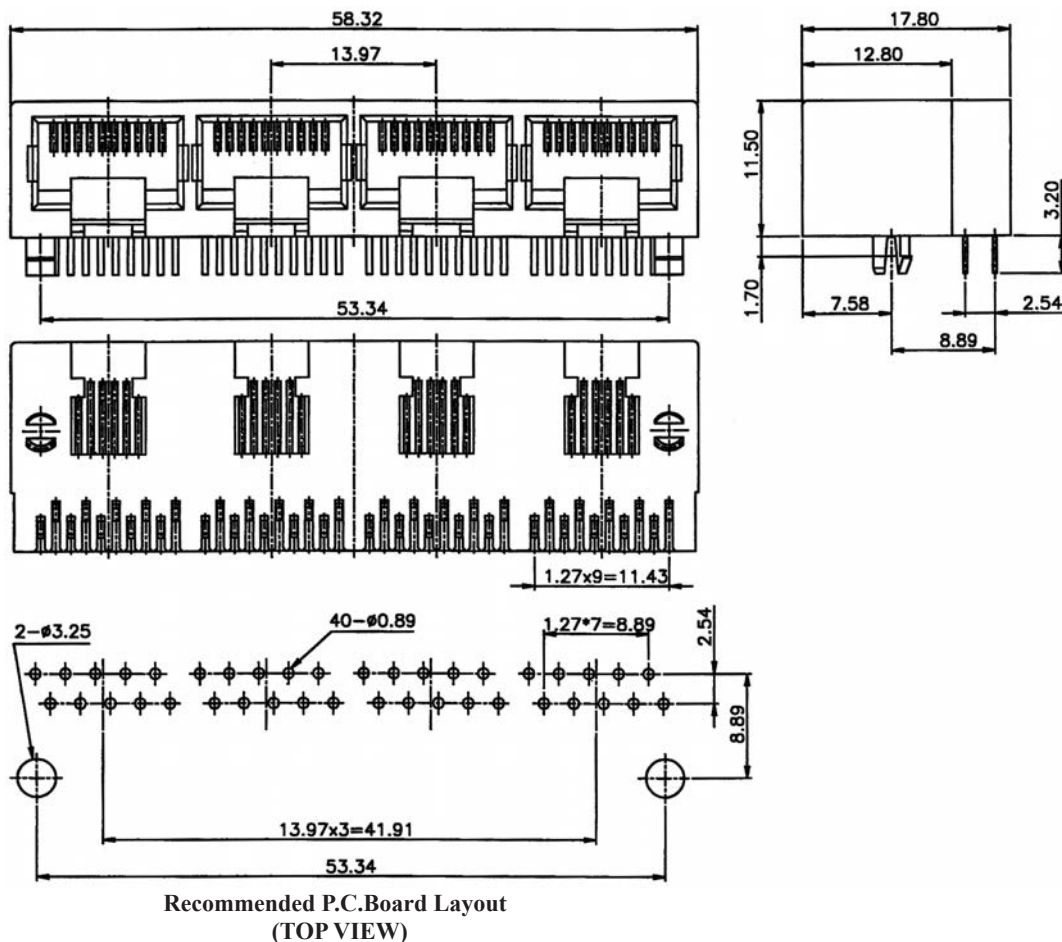
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 N - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} 4$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

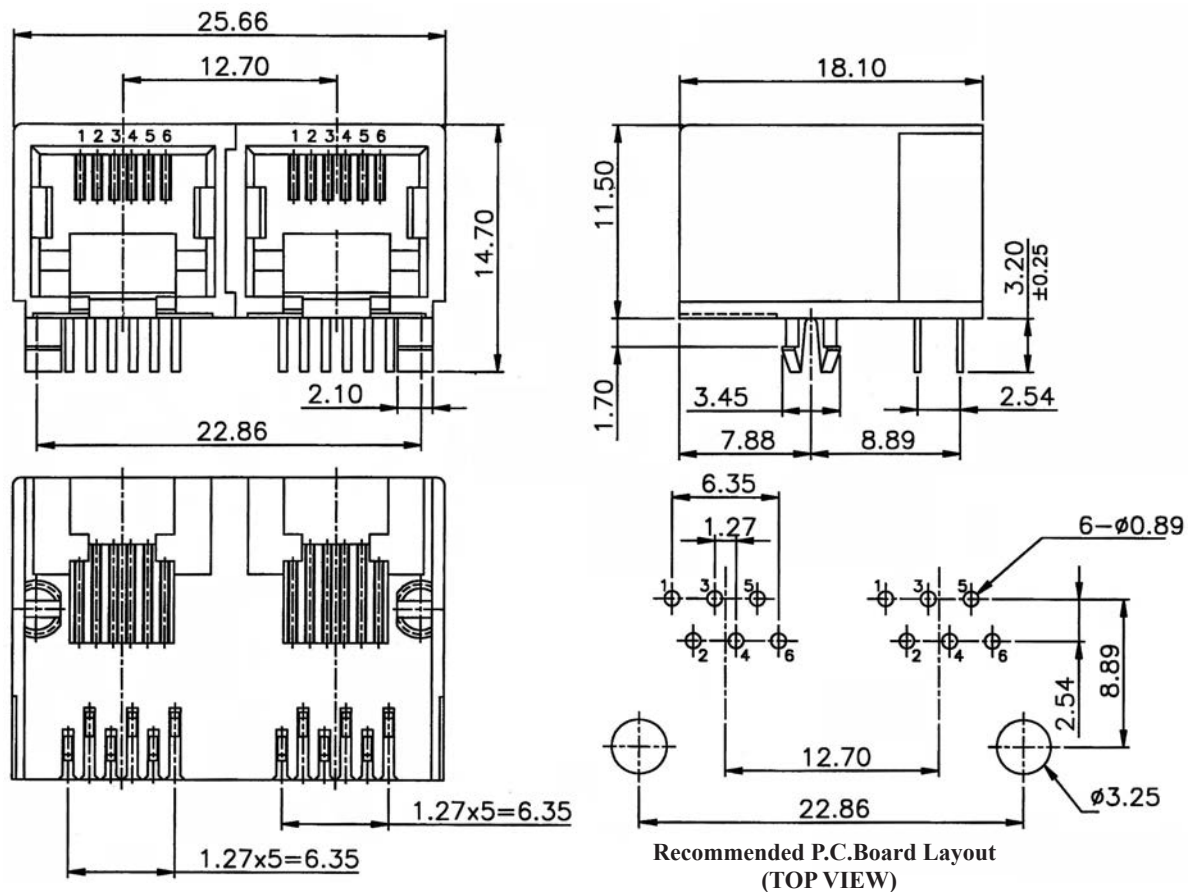
SIDE ENTRY 2-PORT MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ 69 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{2}$

- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 02

SIDE ENTRY 3-PORT MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

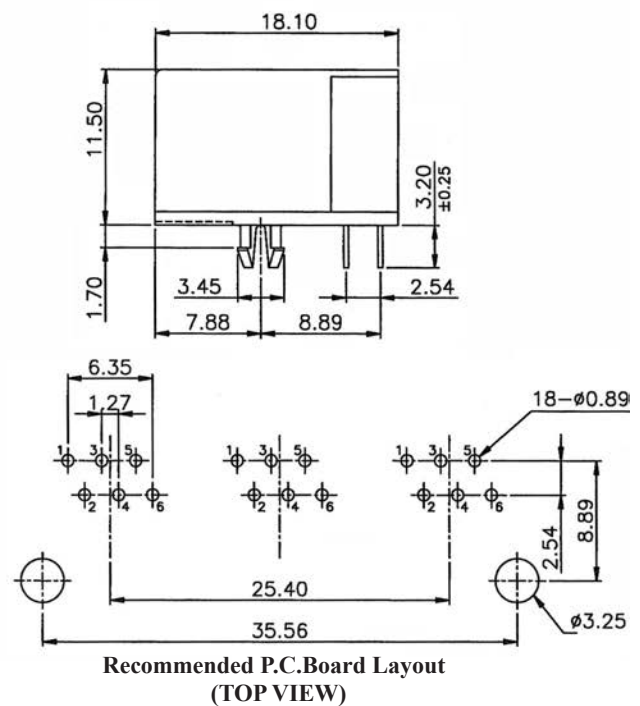
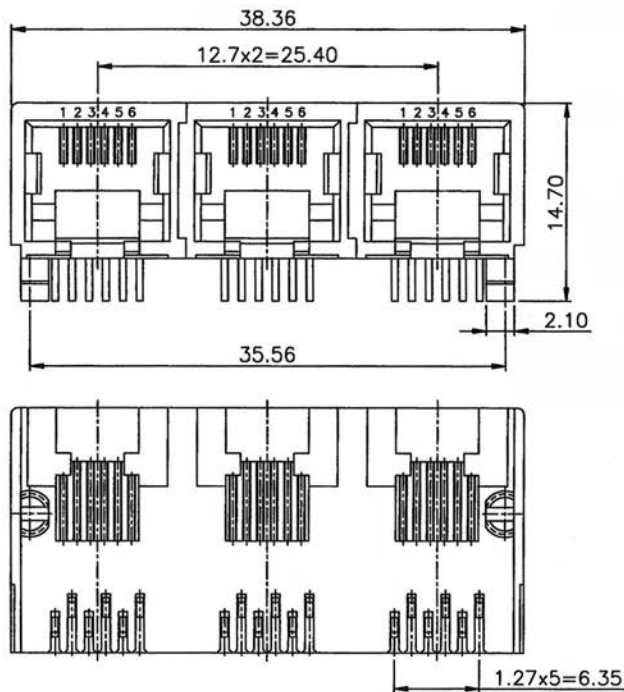
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 6 9 - $\frac{x}{1} \frac{x}{2} \frac{B}{3} \frac{03}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

03

SIDE ENTRY 4-PORT MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

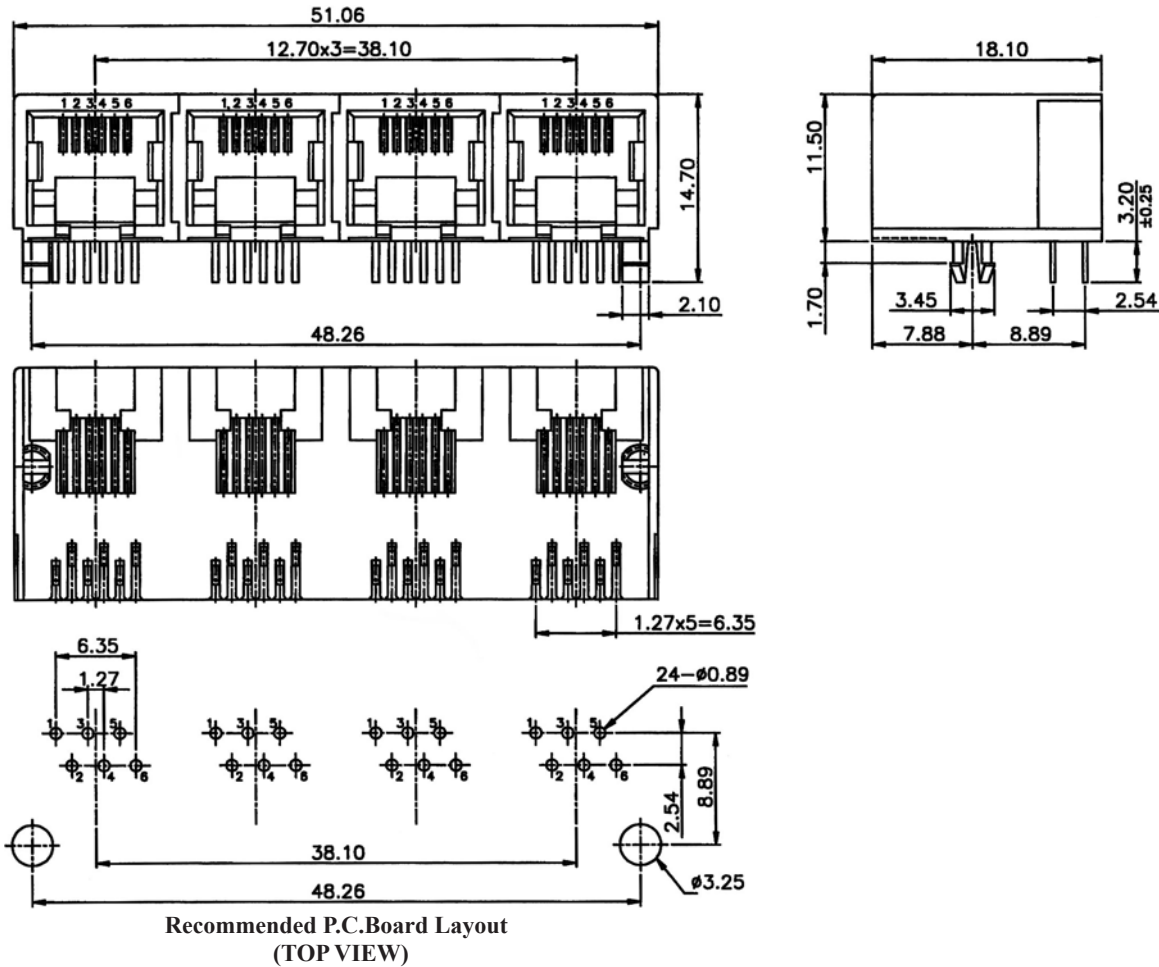
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 6 9 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 4$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

SIDE ENTRY 5-PORT MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

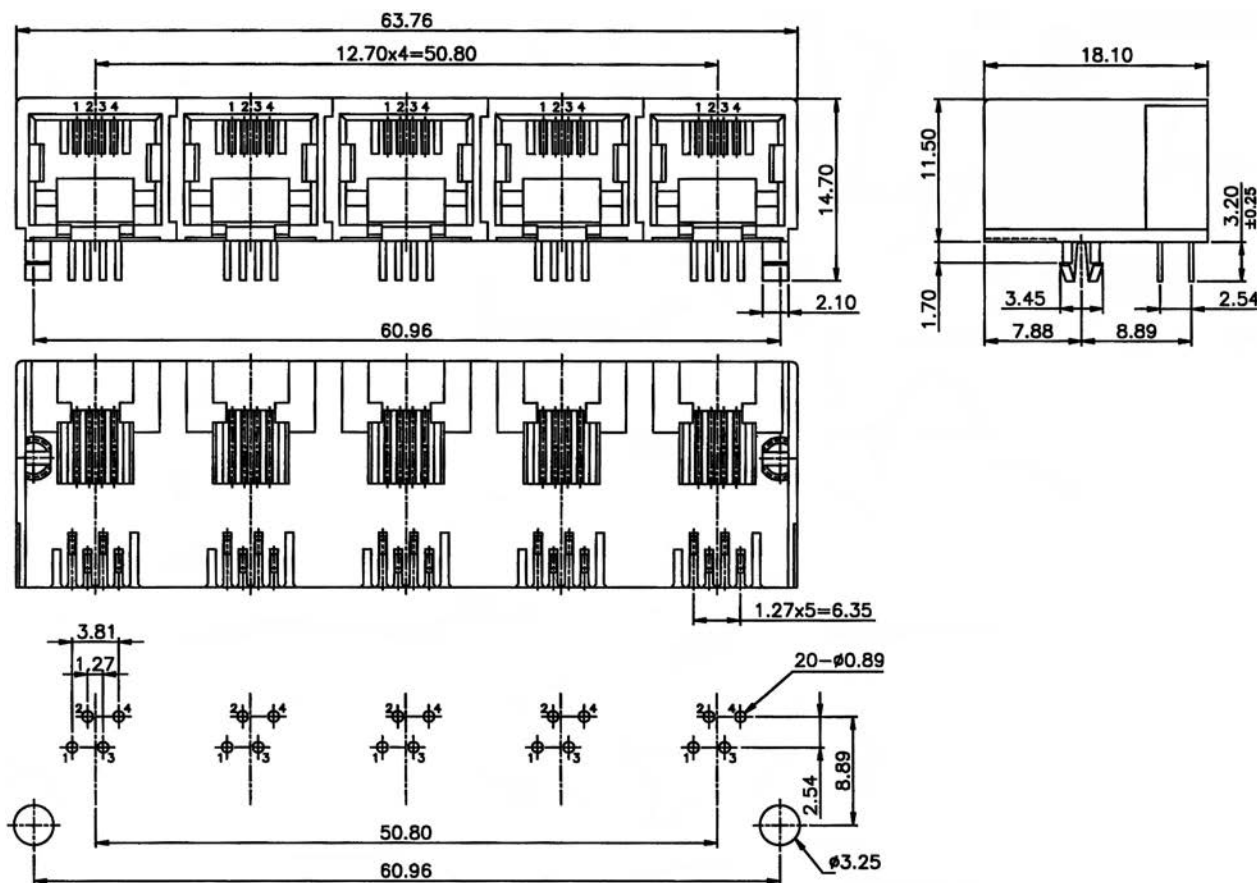
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ69 - $\frac{XX}{1} \frac{X}{2} \frac{B05}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

05

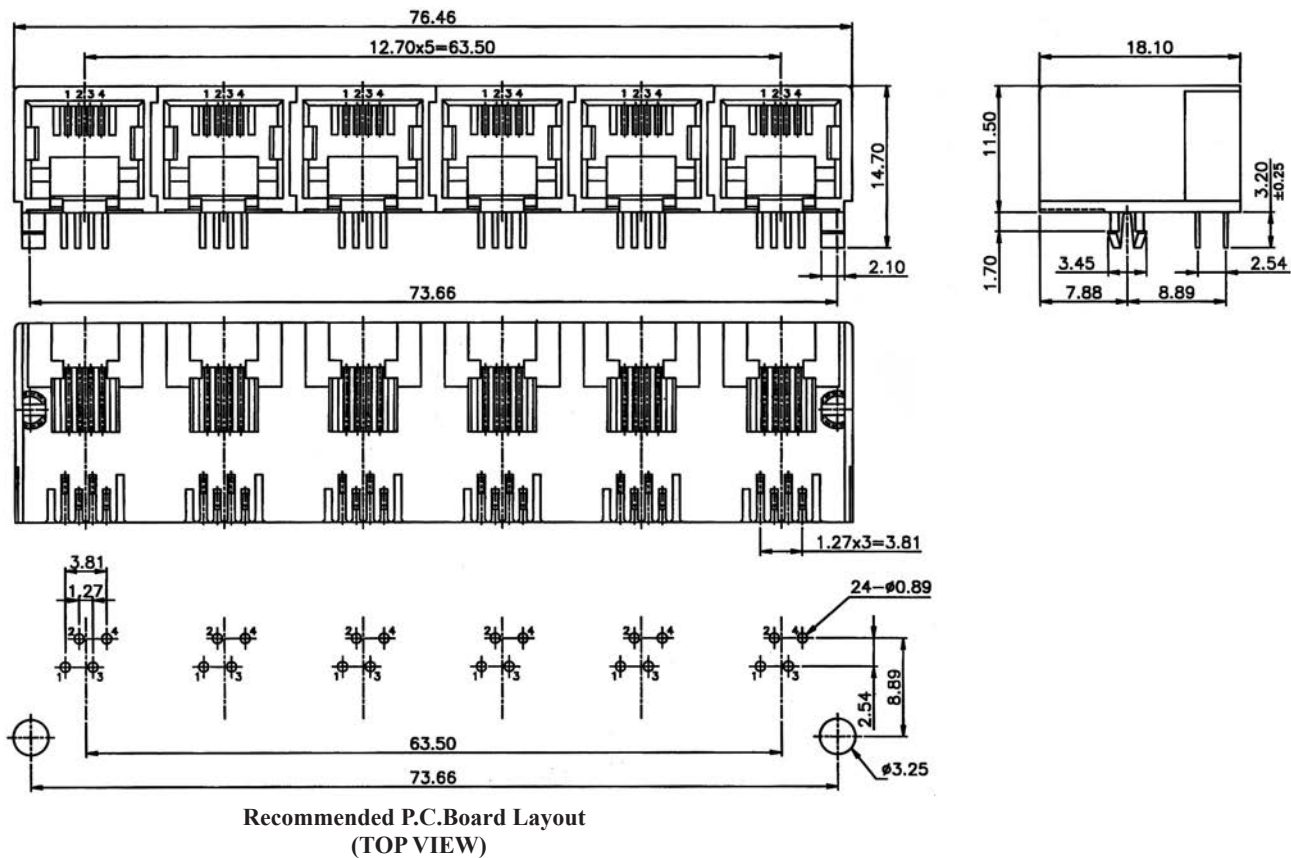
SIDE ENTRY 6-PORT MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ69 - $\frac{x}{1} \frac{x}{2} \frac{B}{3} 06$

1. NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. NO. OF PORTS:
 06

SIDE ENTRY 8-PORT MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

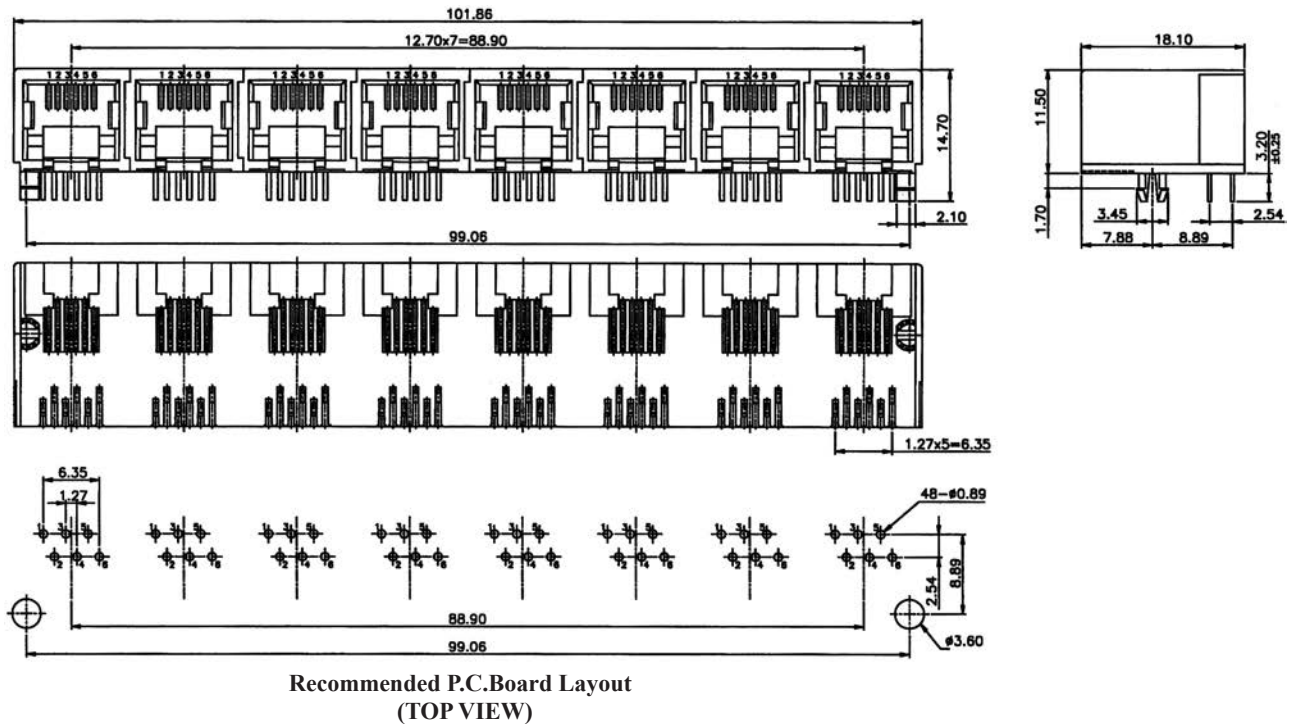
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ69 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 08$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

08

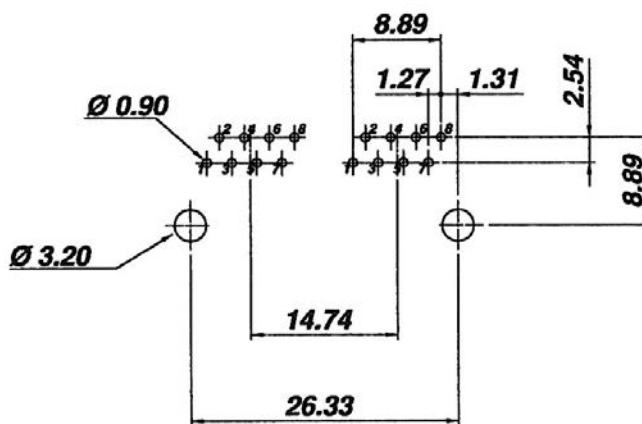
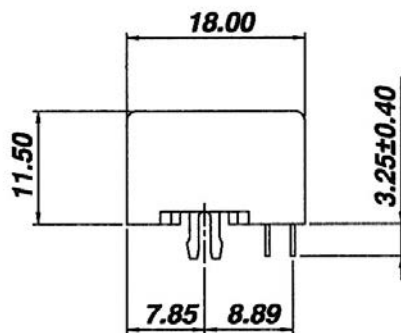
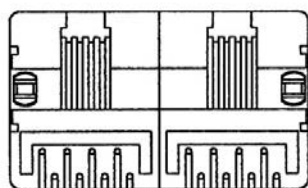
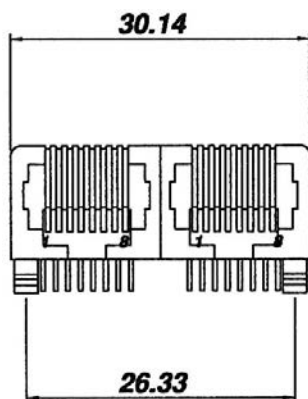
SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ6N - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
02

NOTE: MJ6NHT-88xB02 FOR HIGH TEMP. VERSION

SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

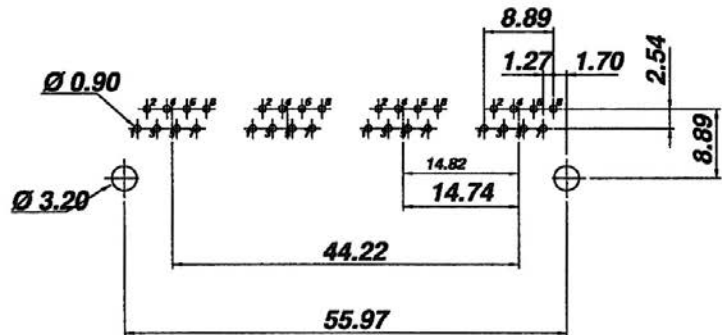
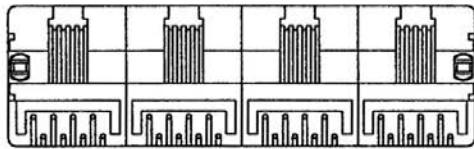
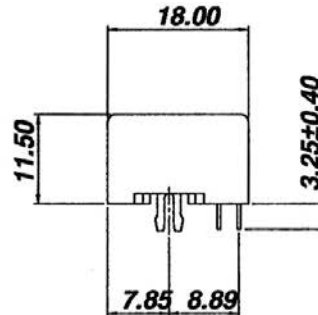
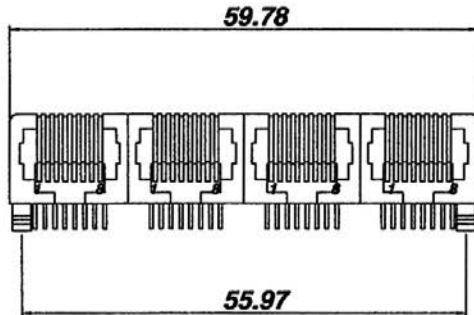
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ6N - $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: MJ6NHT-88xB04 FOR HIGH TEMP. VERSION

SIDE ENTRY 6-PORT MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

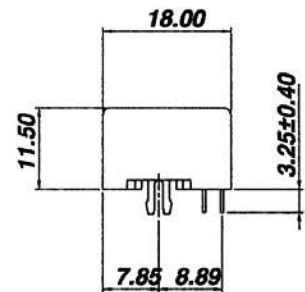
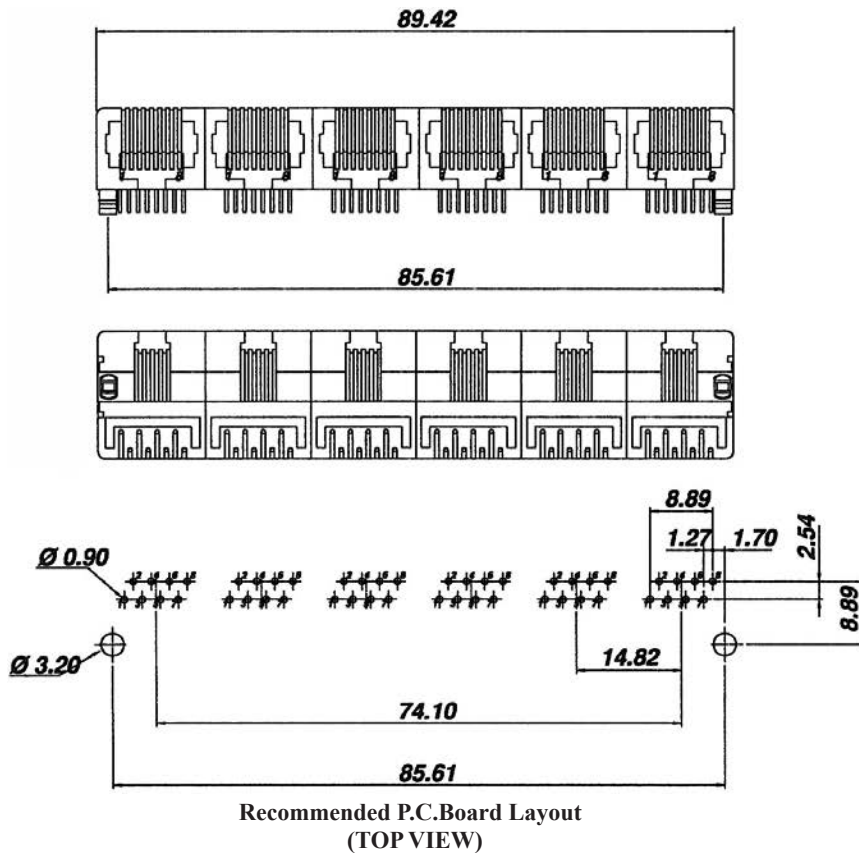
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ6N - $\frac{88}{1} \times \frac{B}{2} \frac{0.6}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

06

NOTE: MJ6NHT-88xB06 FOR HIGH TEMP. VERSION

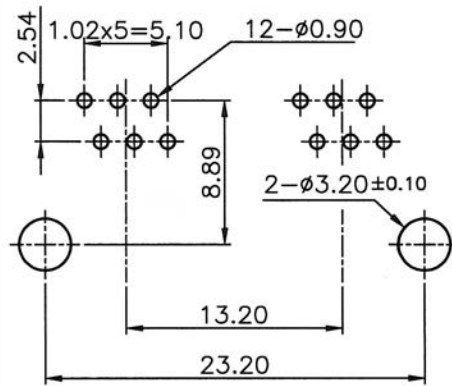
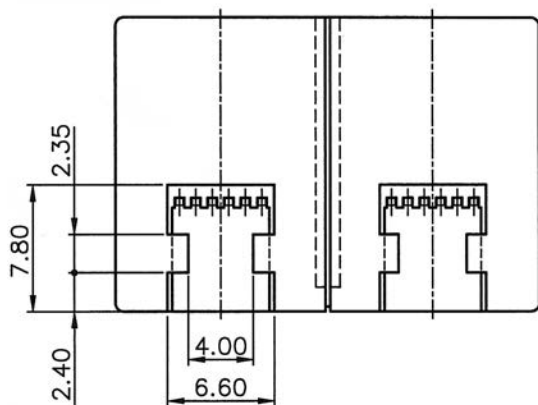
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

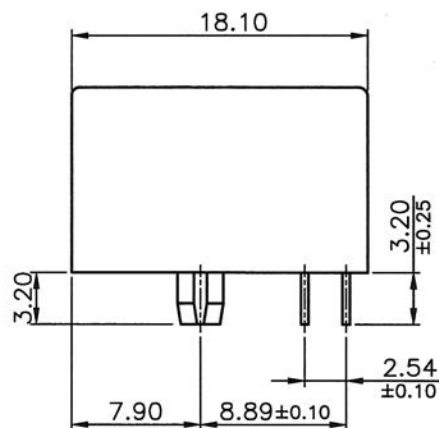
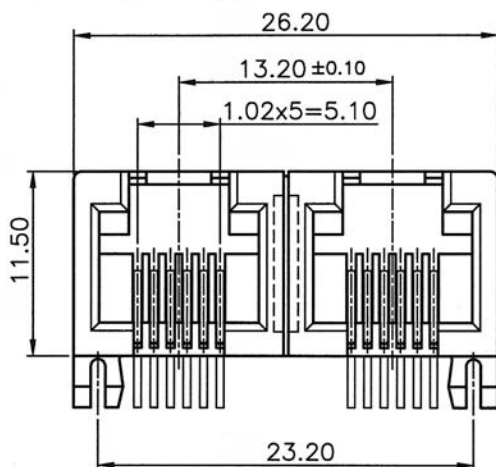
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout (TOP VIEW)



ORDERING INFORMATION:

P/N MJ3W - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 2$

1. NO. OF POSITIONS & CONTACTS:
 - "66" 6P6C
 - "64" 6P4C
2. CONTACT FINISH:
 - "A" 6 MICROINCH GOLD
 - "B" 15 MICROINCH GOLD
 - "C" 30 MICROINCH GOLD
 - "D" 50 MICROINCH GOLD
 - "E" GOLD FLASH
3. NO. OF PORTS:
 - 02

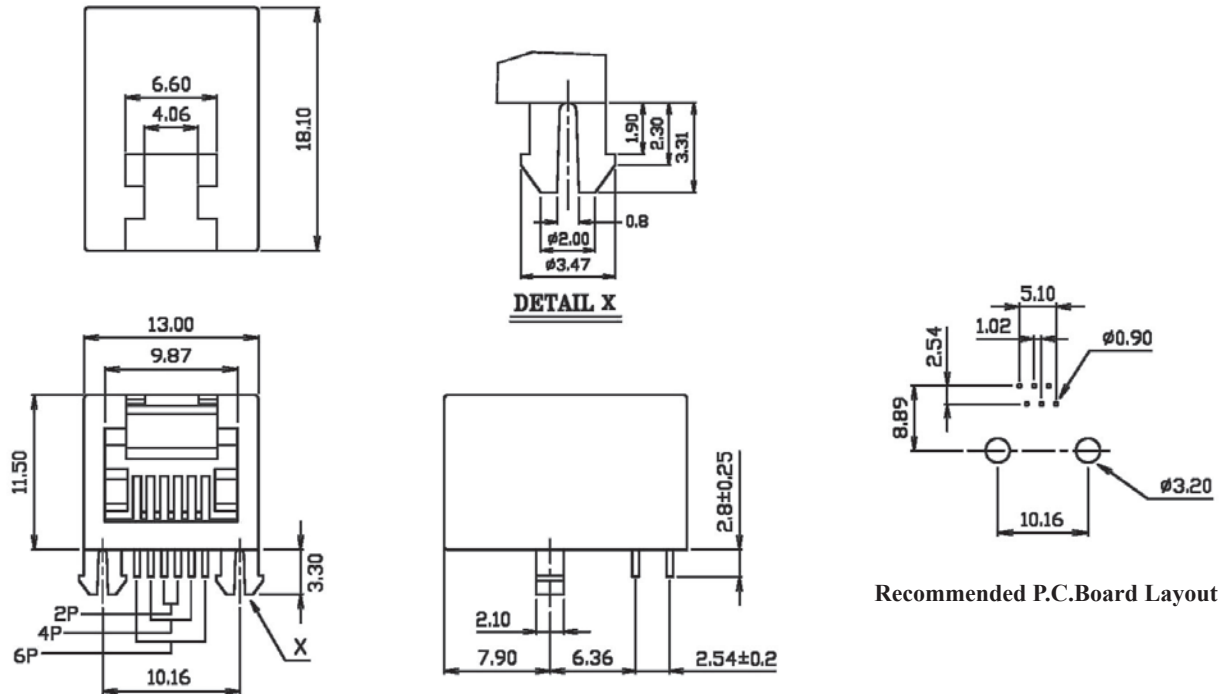
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{H}{I}$ Z - $\frac{6}{2}$ $\frac{6}{3}$ x $\frac{B}{4}$

- MODULAR JACK TYPE:
"HZ" LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

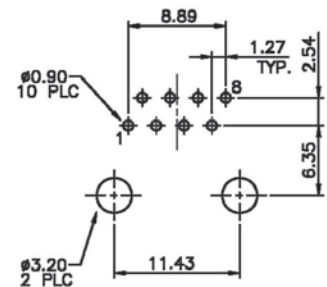
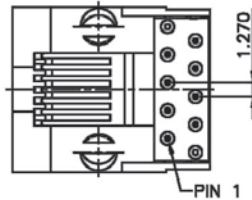
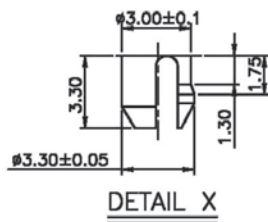
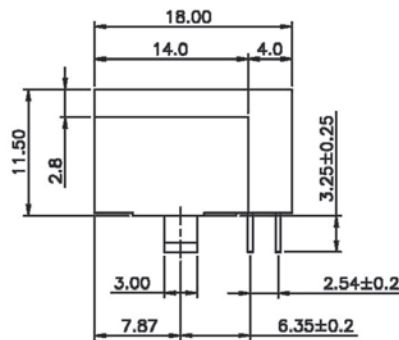
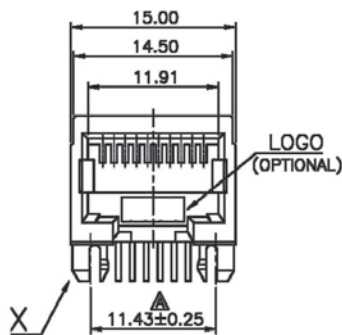
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{NN}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{B}{4}$

1. MODULAR JACK TYPE:
"NN" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

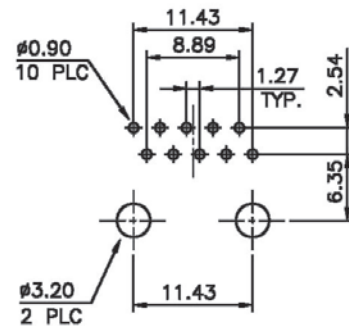
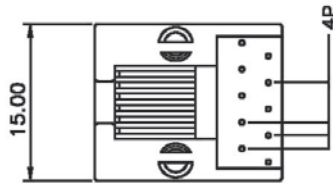
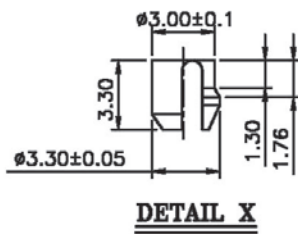
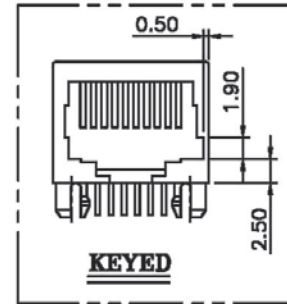
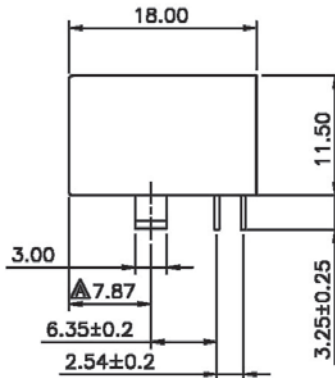
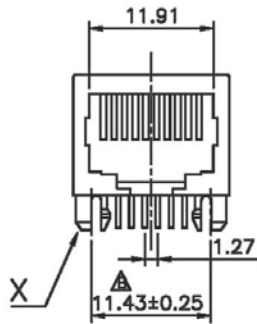
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{N}{1}$ $\frac{N}{2}$ - $\frac{x}{3}$ $\frac{x}{4}$ $\frac{B}{5}$ x

- MODULAR JACK TYPE:
"NN" VERY LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- KEY OPTION:
" " WITHOUT KEY
"K" KEYED

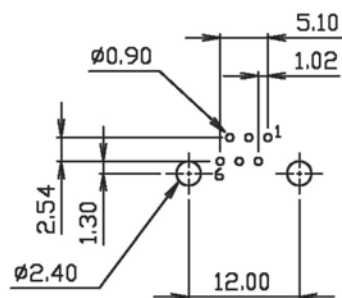
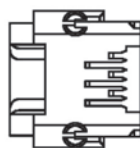
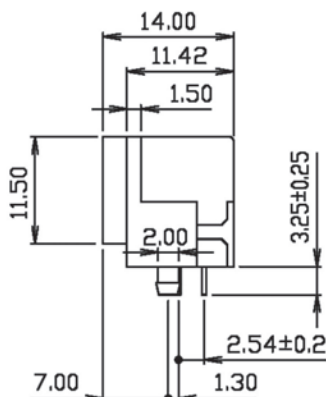
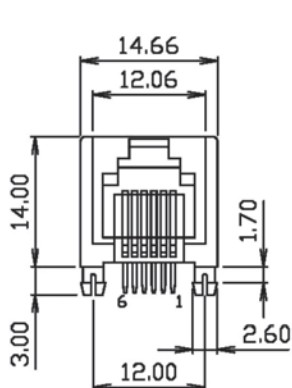
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N **M J V S - 6 6 x x**
1 2 3 4

1. MODULAR JACK TYPE:
"VS" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"A" GRAY
"B" BLACK

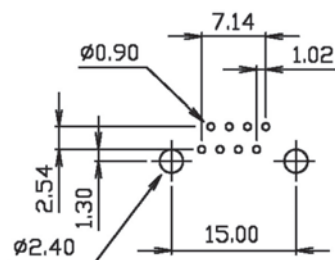
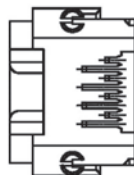
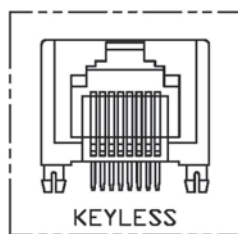
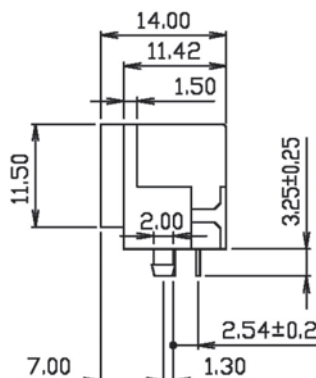
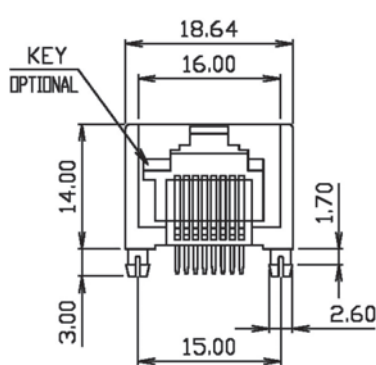
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J V S - 88 X X X
 1 2 3 4 5

1. MODULAR JACK TYPE:
 "VS" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. HOUSING COLOR:
 "A" GRAY
 "B" BLACK

5. KEY OPTION:
 " " KEYLESS
 "K" WITH KEY

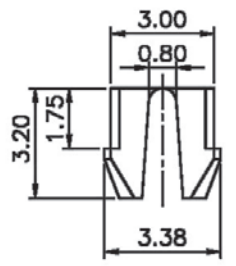
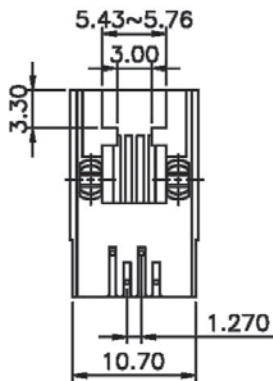
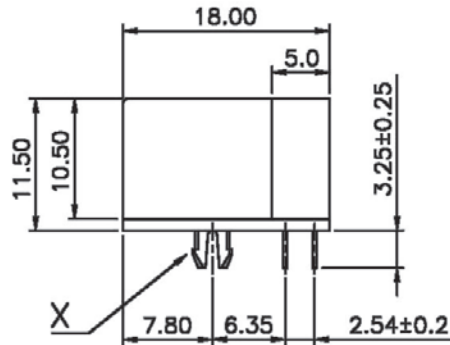
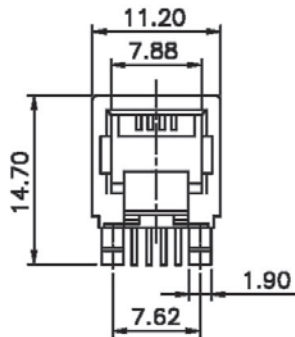
SIDE ENTRY MODULAR PCB JACK 4P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

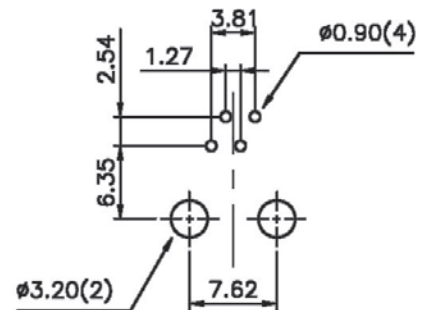
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



DETAIL X



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N **M J Q C - 44 x B**
_{1 2 3 4}

1. MODULAR JACK TYPE:
"QC" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

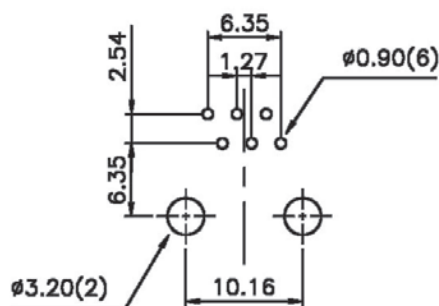
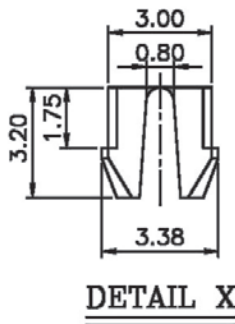
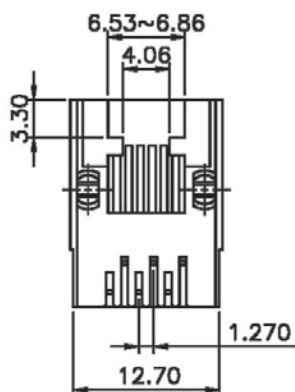
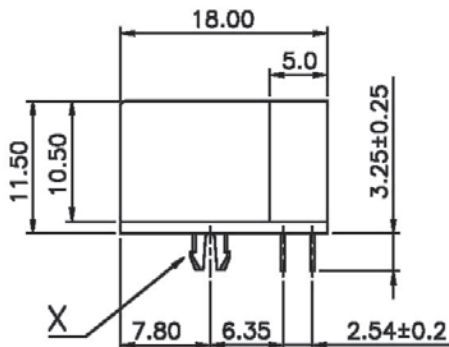
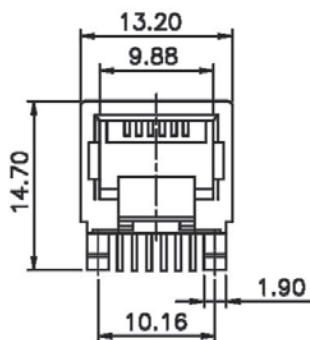
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N **M J Q C - 6 6 x B**
 1 2 3 4

1. MODULAR JACK TYPE:
"QC" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

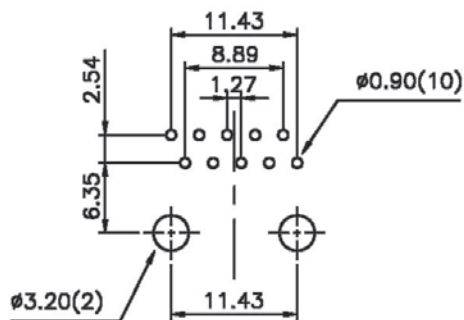
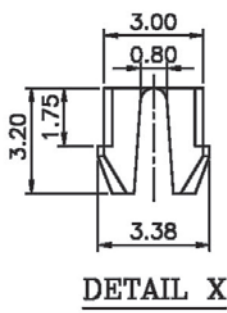
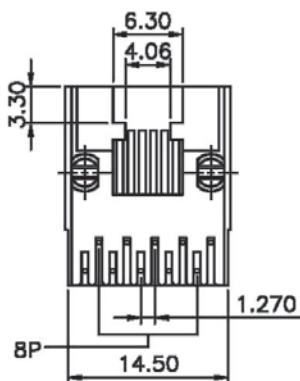
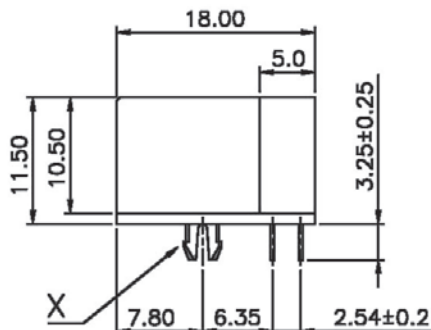
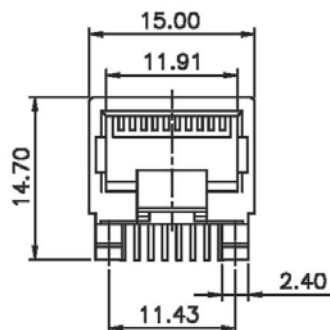
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J Q C - 00 x B
 1 2 3 4

1. MODULAR JACK TYPE:
"QC" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

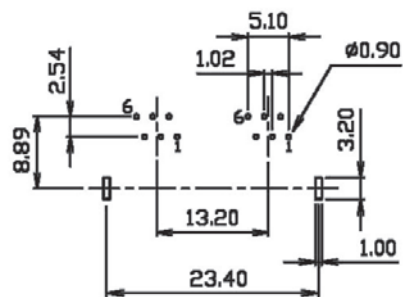
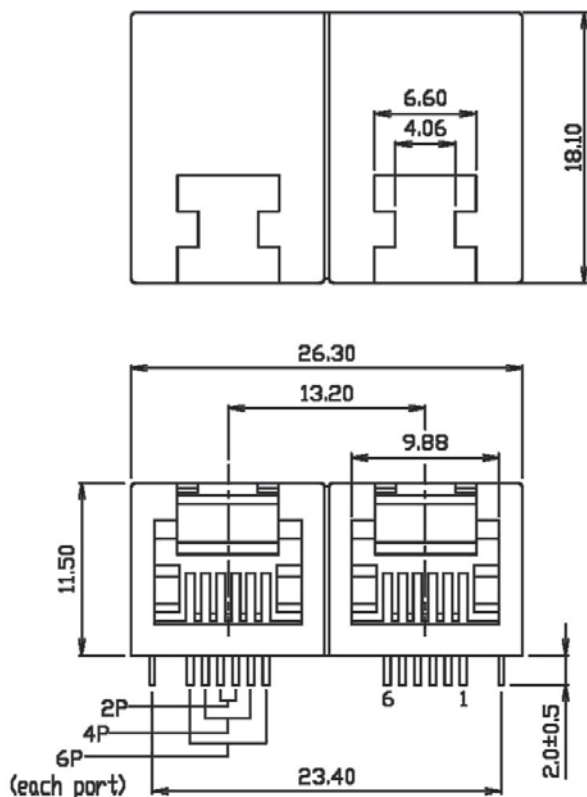
SIDE ENTRY 2-PORT MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

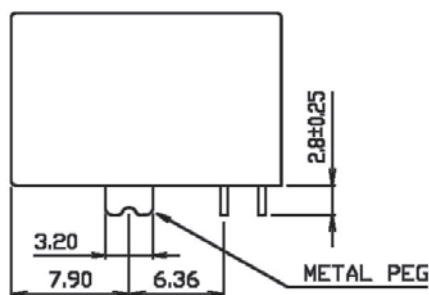
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J Q D - 6 6 x B 0 2
1 2 3 4 5

- MODULAR JACK TYPE:
"QD" 2 PORTS WITH METAL PEGS
- NO. OF POSITIONS & CONTACTS:
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
02

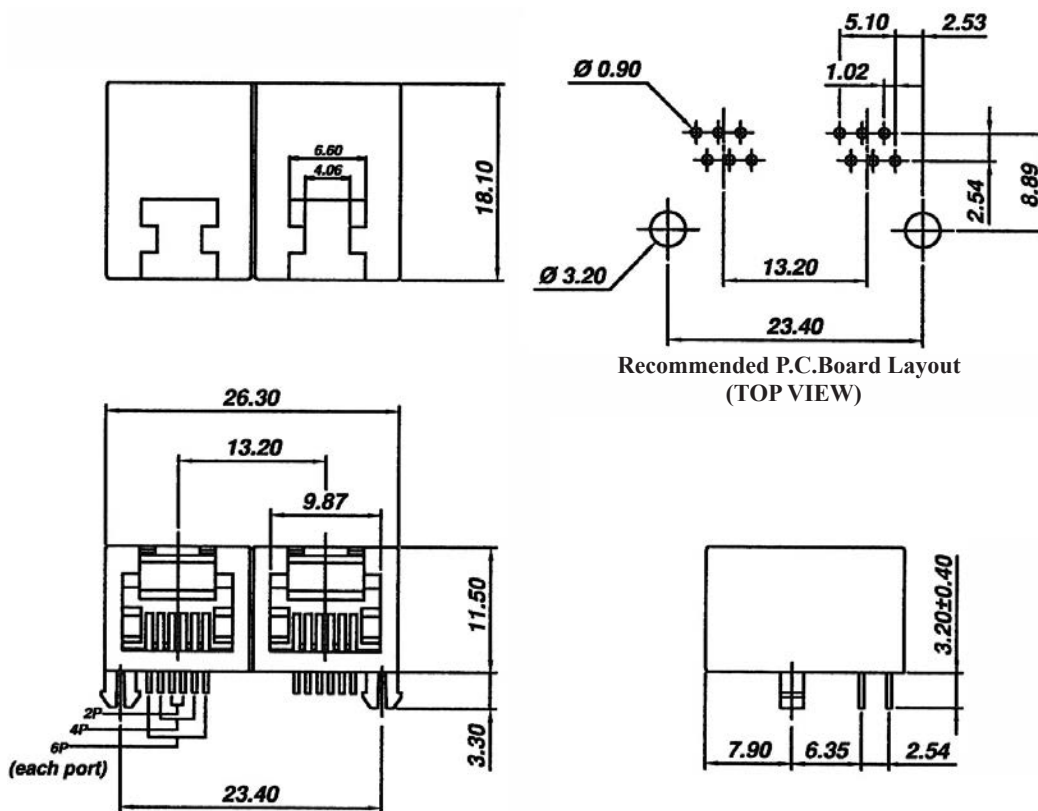
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ65 - $\frac{xx}{1} \frac{xx}{2} \frac{B02}{3}$

- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 02

NOTE: P/N MJ65HT-xxxB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 8P+10P PROFILE=11.55MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

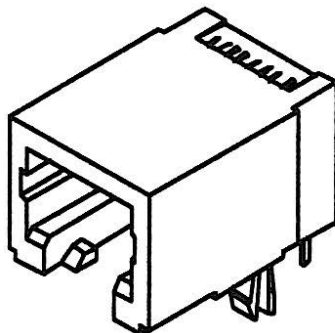
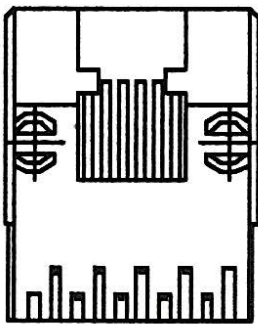
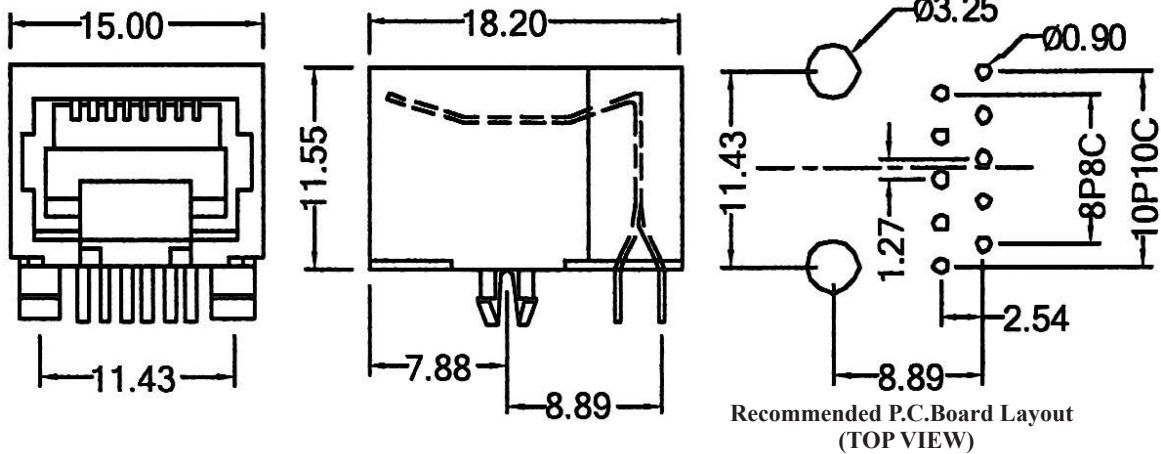
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJS 5 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

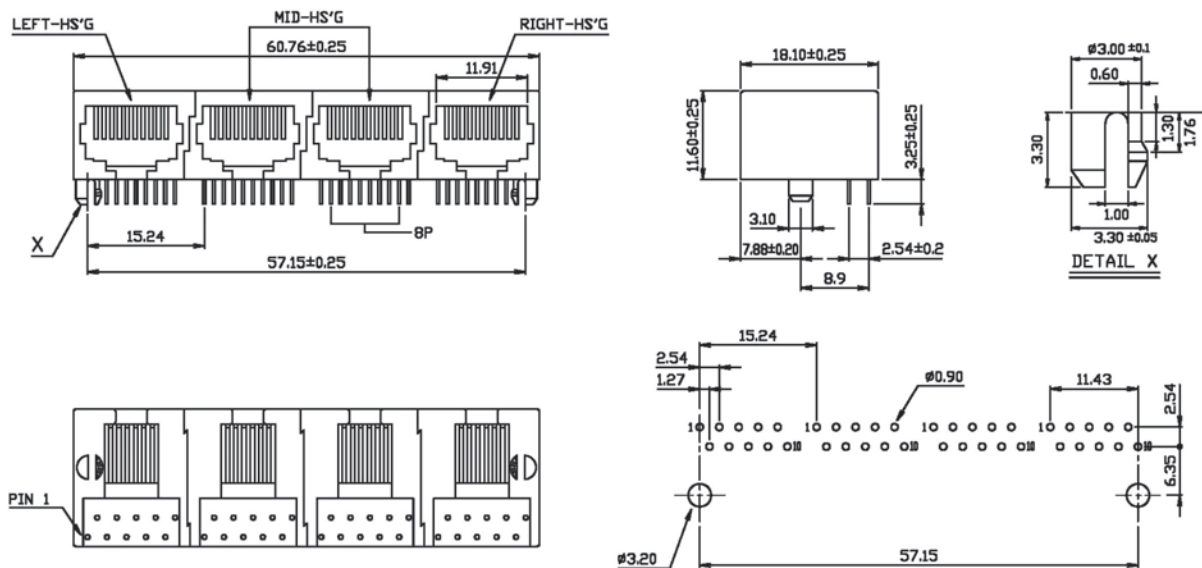
SIDE ENTRY 4-PORT MODULAR PCB JACK 10P PROFILE=11.60MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N **M J Q B - 00 x B 04**
 1 2 3 4 5

1. MODULAR JACK TYPE:
"QB" VERY LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK
5. NO. OF PORTS:
04

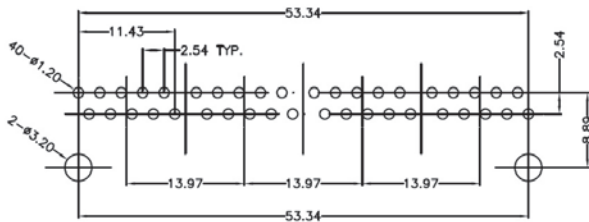
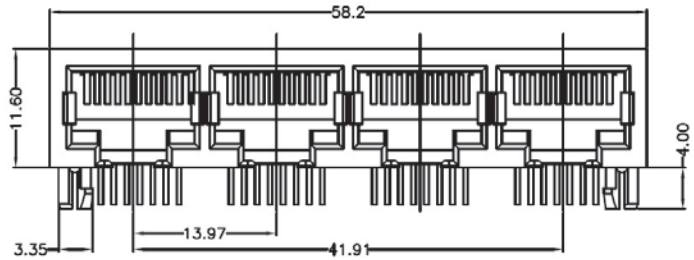
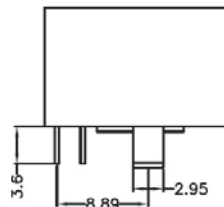
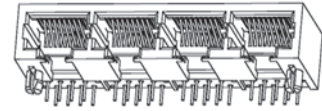
SIDE ENTRY 4-PORT MODULAR PCB JACK 10P PROFILE=11.60MM (UNSHIELDED)

SPECIFICATIONS

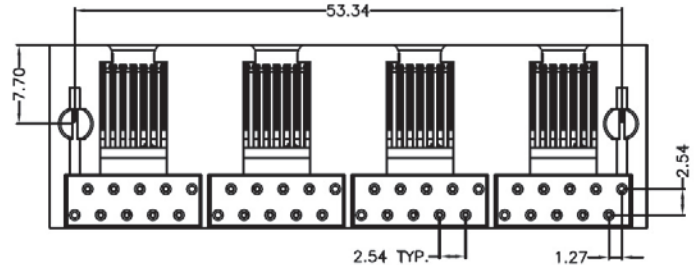
- Current Rating:** 1.5 Amp Max.
- Dielectric Withstanding:** 500 Vac For 1 Min.
- Contact Resistance:** 30m Ohms Max.
- Insulation Resistance:** 1000 Megohms Min @500 Vdc..
- Operation Temperature:** -40°C To +85°C.

MATERIALS

- Housing:** PBT(UL 94V-0)
- Terminal:** Copper Alloy,Gold Plated
- * RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJ2NK - $\frac{xx}{1} \frac{xx}{2} \frac{xx}{3} \frac{04}{4}$

1. NO. OF POSITIONS & CONTACTS:

- "00" 10P10C
- "08" 10P8C

2. CONTACT FINISH:

- "A" 6 MICROINCH GOLD
- "B" 15 MICROINCH GOLD
- "C" 30 MICROINCH GOLD
- "D" 50 MICROINCH GOLD
- "E" GOLD FLASH

3. HOUSING COLOR:

- "B" BLACK
- "W" WHITE

4. NO. OF PORTS:

04

NOTE: IT CAN BE USED FOR REPLACING P/N MJ2N-xxxB04.

SIDE ENTRY MODULAR PCB JACK 4P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

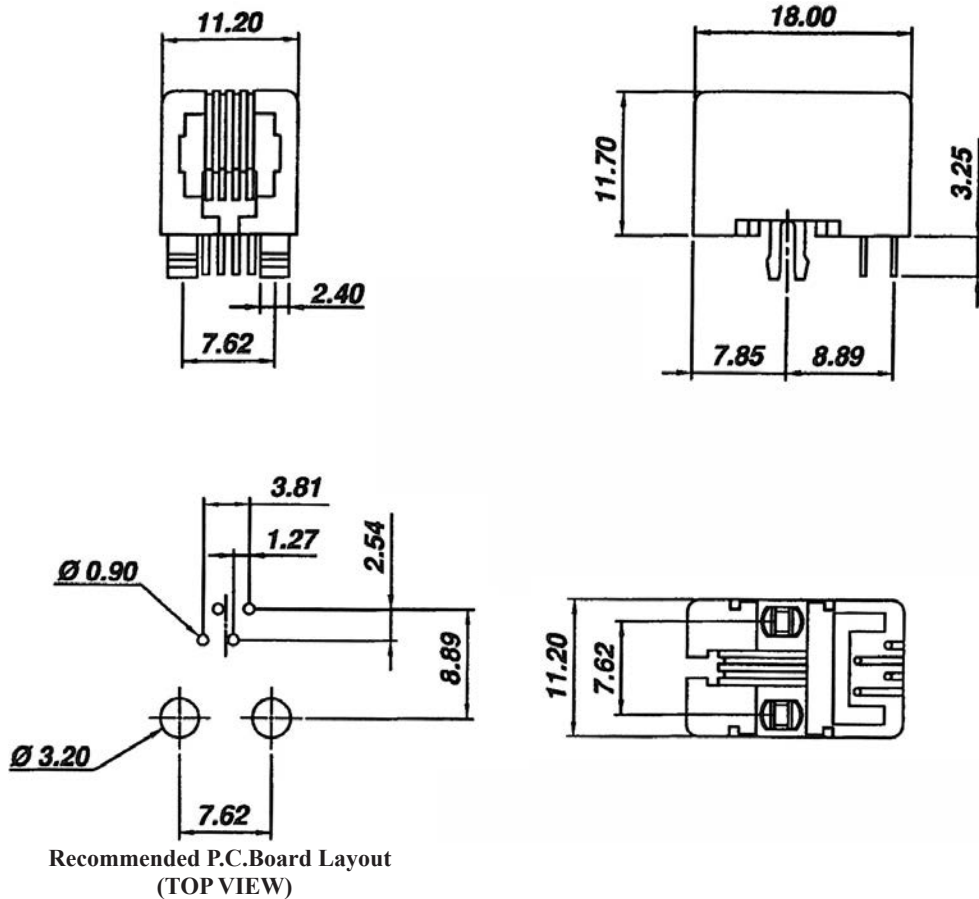
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J L A - $\frac{x x x}{1 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

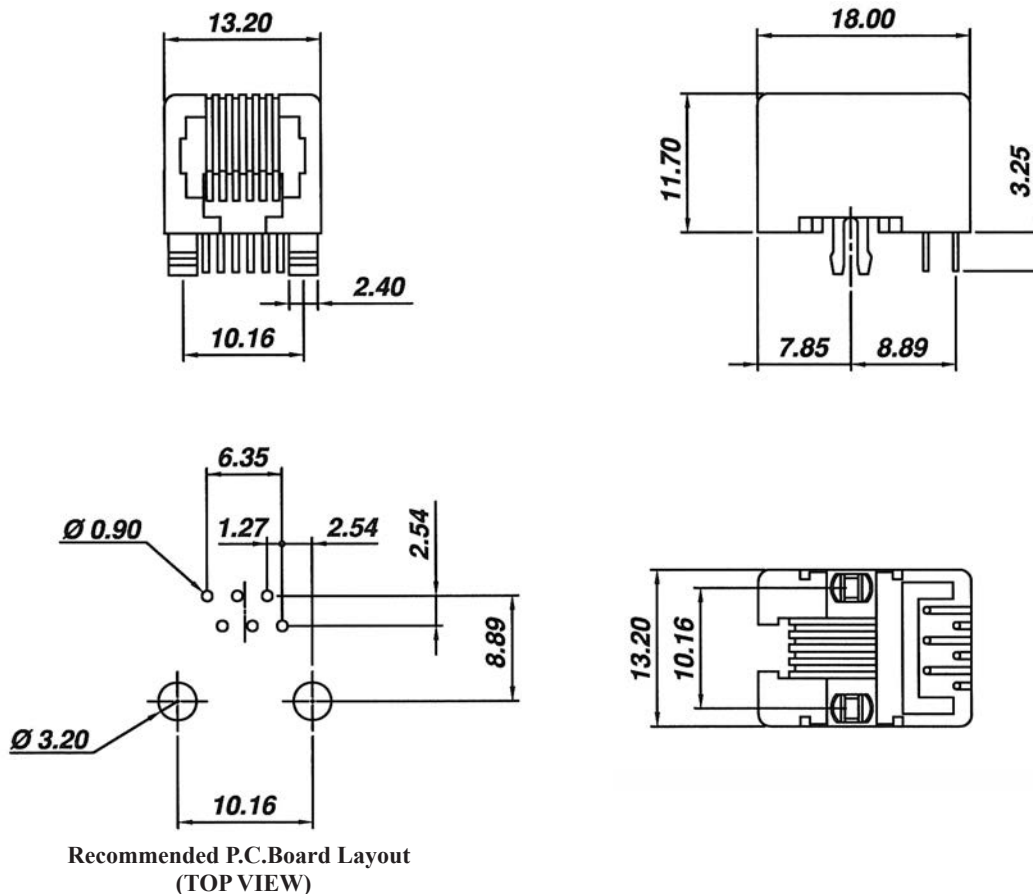
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J L A - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: PEG SPACING= 10.16MM

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

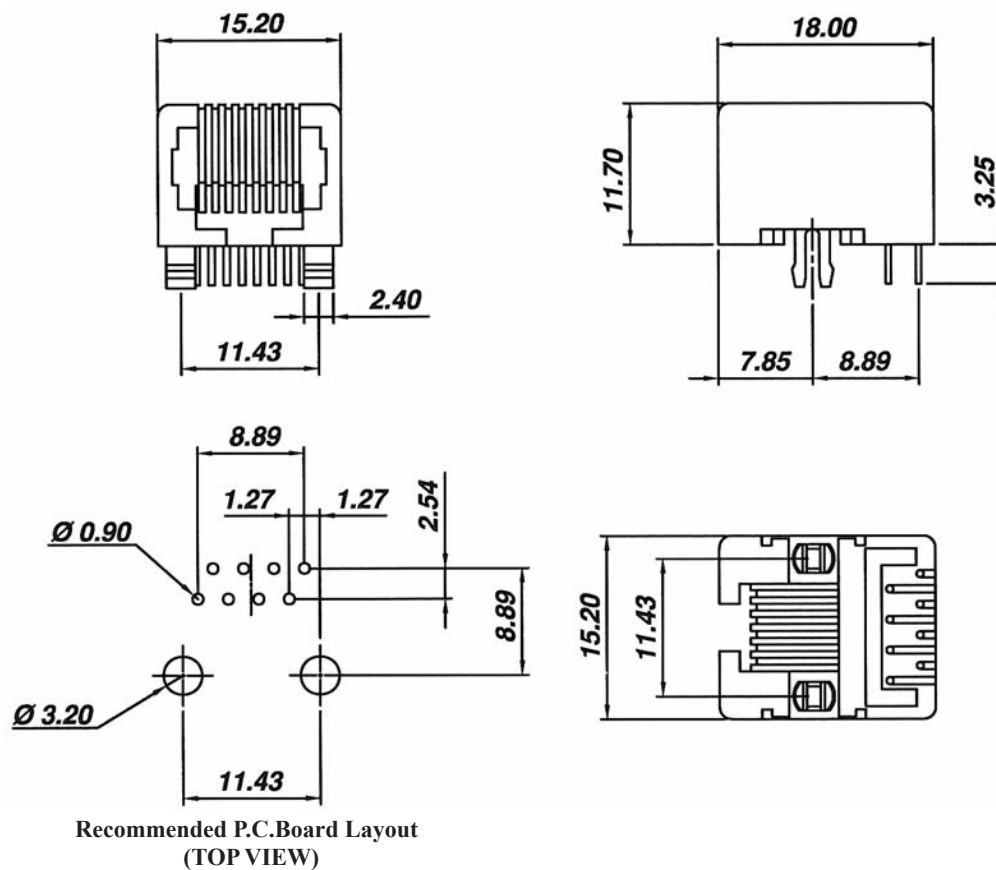
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J L A - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

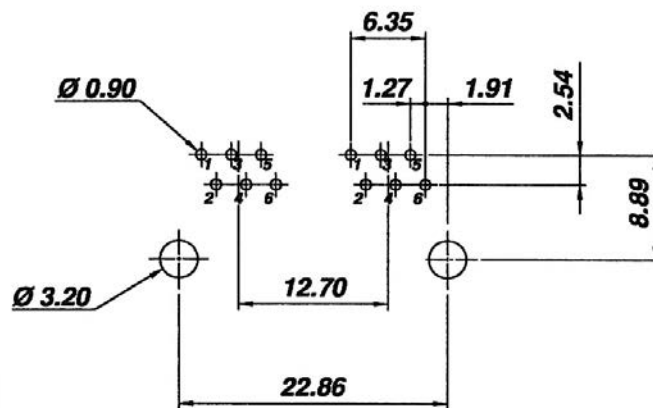
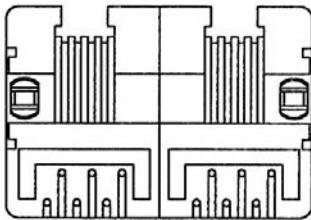
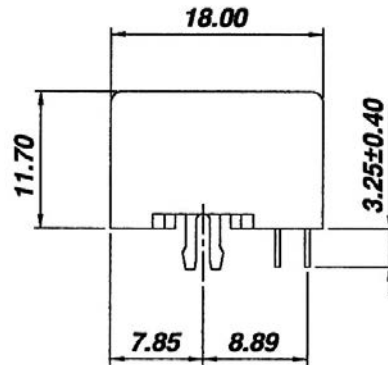
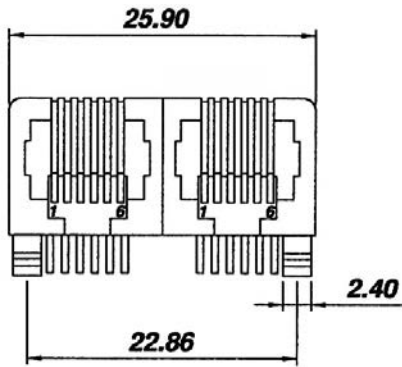
SIDE ENTRY 2-PORT MODULAR PCB JACK 6P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ6N - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{2}$

1. NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. NO. OF PORTS:
 02

NOTE: P/N MJ6NHT-6xxB02 FOR HIGH TEMP. VERSION

SIDE ENTRY 4-PORT MODULAR PCB JACK 6P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

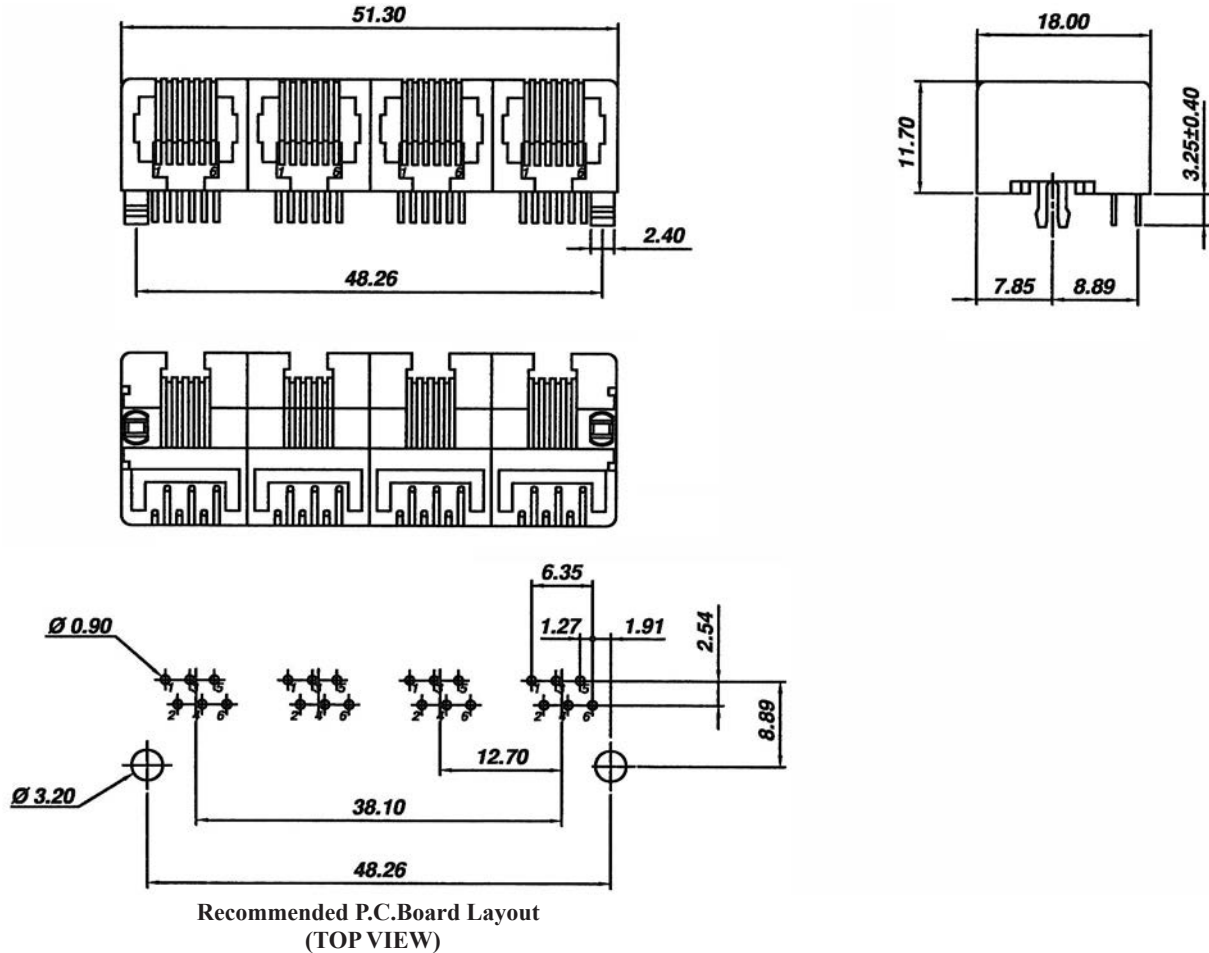
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ6N - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} 4$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: P/N MJ6NHT-6xxB04 FOR HIGH TEMP. VERSION

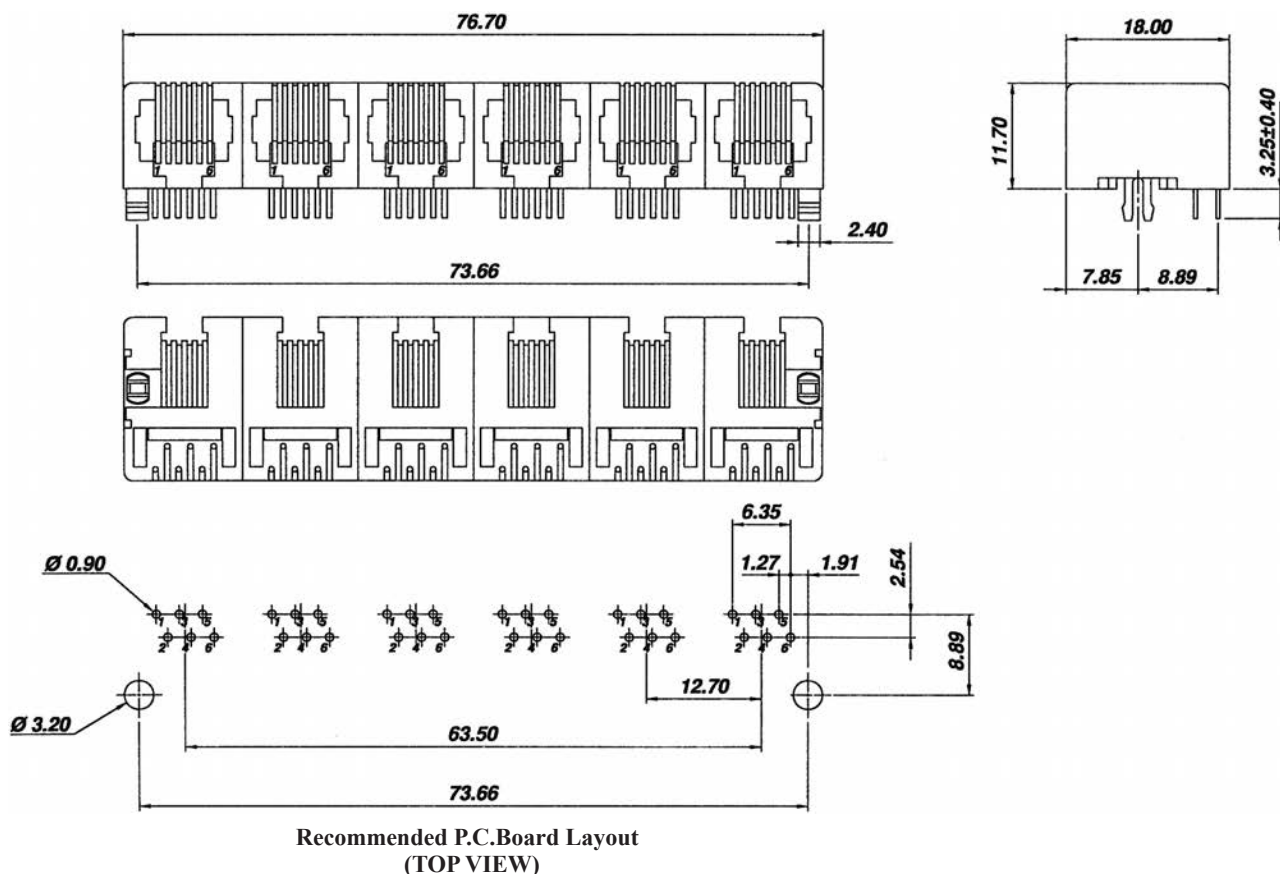
SIDE ENTRY 6-PORT MODULAR PCB JACK 6P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6N - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} 6$

1. NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. NO. OF PORTS:
 06

NOTE: P/N MJ6NHT-6xxB06 FOR HIGH TEMP. VERSION

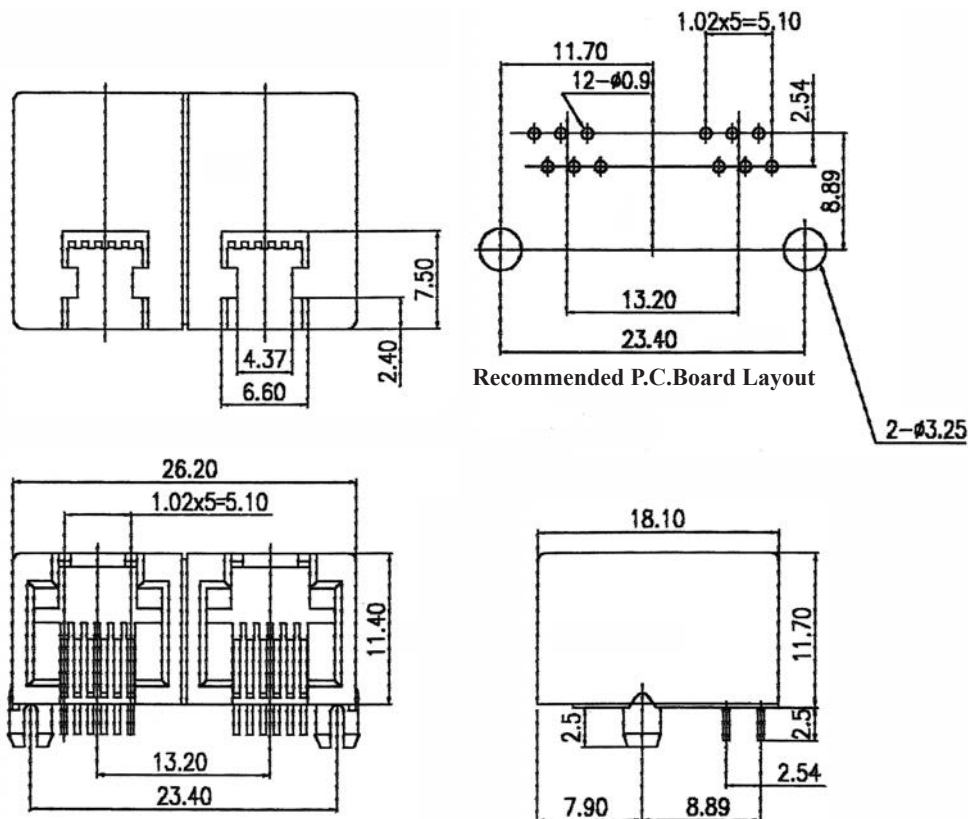
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ3U - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} 2$

- NO. OF POSITIONS & CONTACTS:
 - "66" 6P6C
 - "64" 6P4C
- CONTACT FINISH:
 - "A" 6 MICROINCH GOLD
 - "B" 15 MICROINCH GOLD
 - "C" 30 MICROINCH GOLD
 - "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 - 02

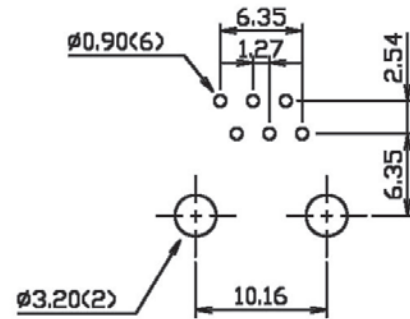
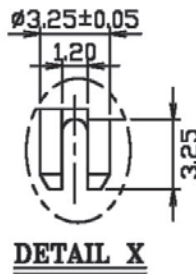
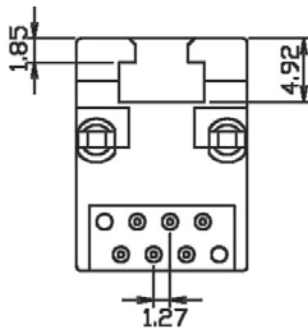
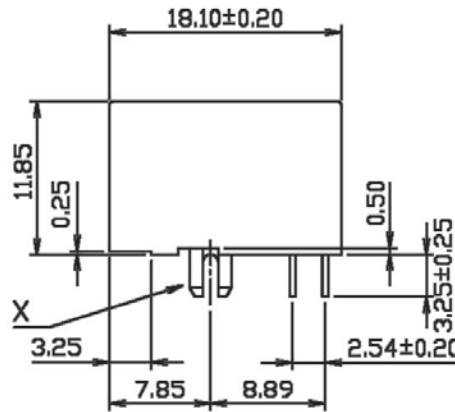
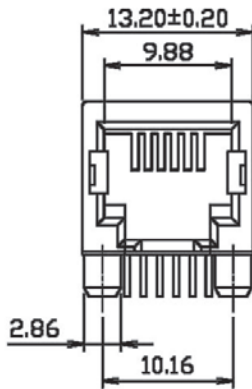
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=11.85MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{K}{1}$ X - $\frac{6}{2}$ $\frac{6}{3}$ $\frac{x}{4}$ B

- MODULAR JACK TYPE:
"KX" VERY LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

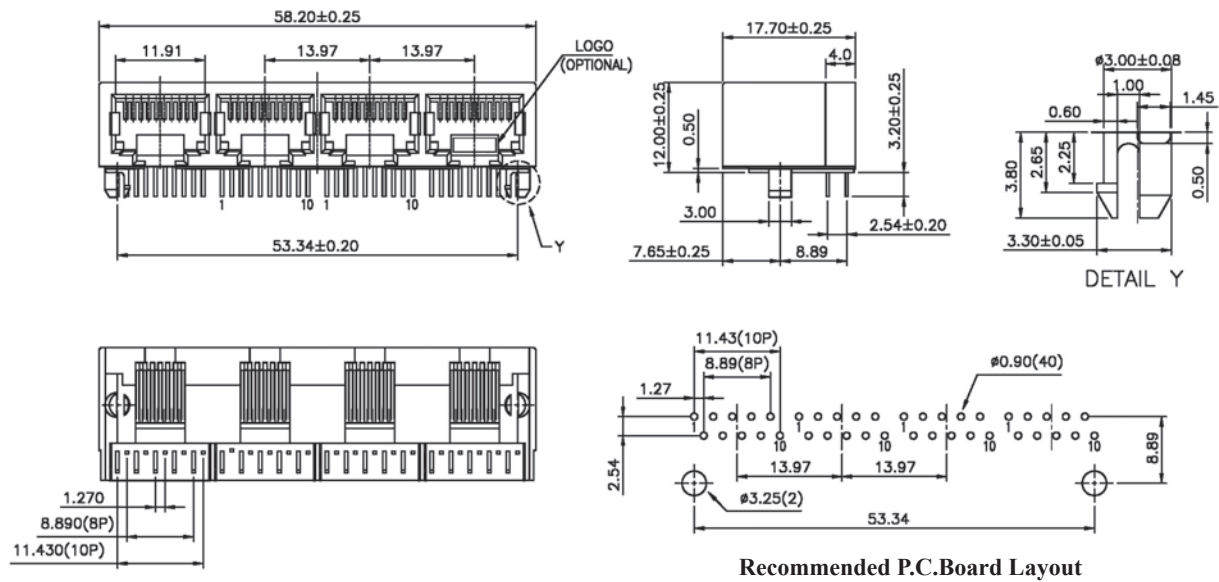
SIDE ENTRY 4-PORT MODULAR PCB JACK 10P PROFILE=12.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J Q E - 0 0 x B 0 4
1 2 3 4 5

1. MODULAR JACK TYPE:
"QE" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK
5. NO. OF PORTS:
04

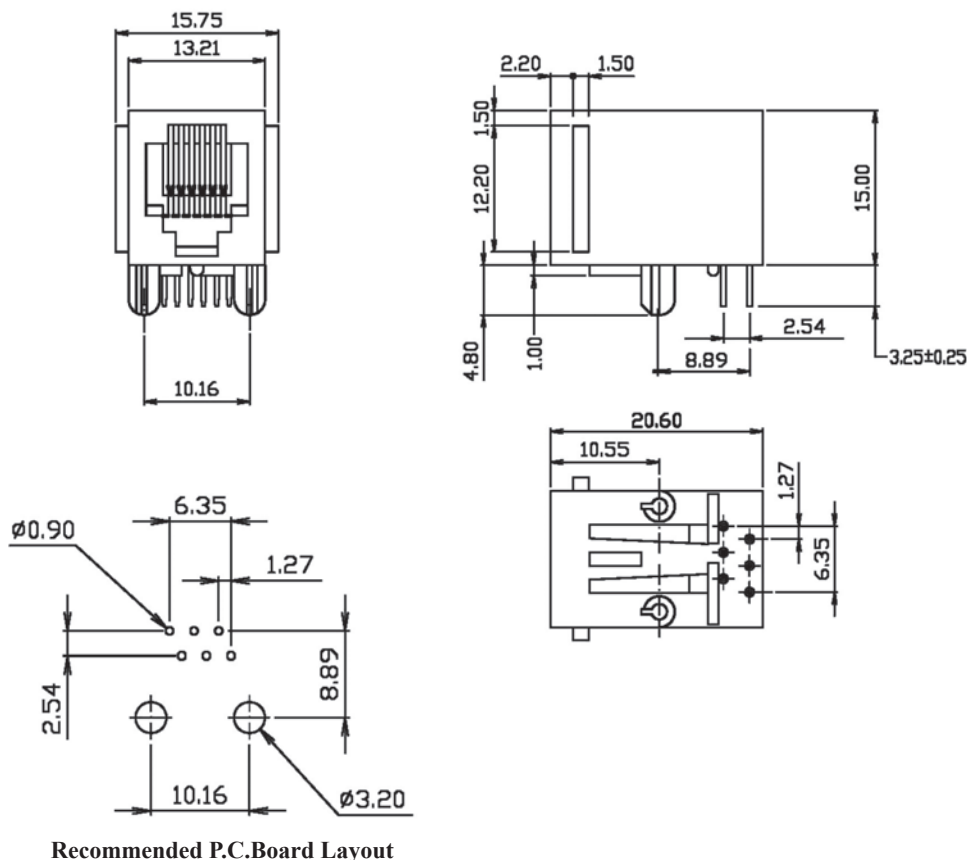
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.20MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{N X}{1}$ - $\frac{6 6}{2}$ x $\frac{B}{3 4}$

1. MODULAR JACK TYPE:
"NX" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

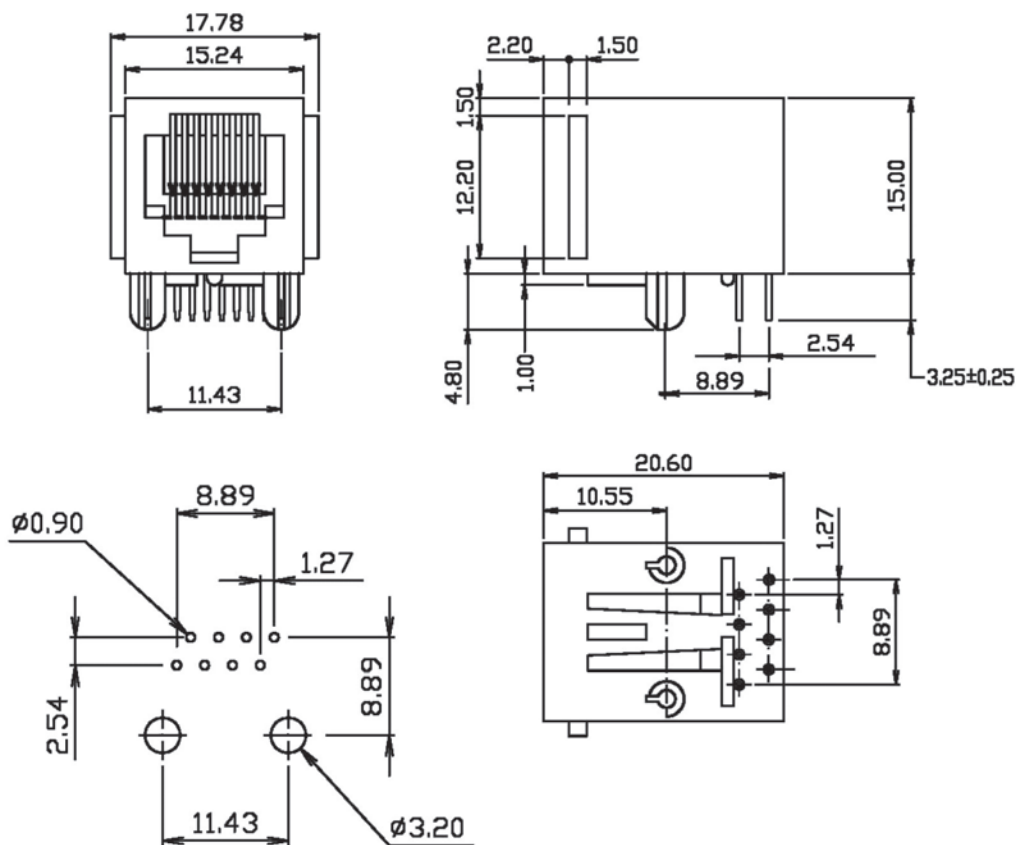
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.20MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{NX}{I}$ - $\frac{88}{2}$ x $\frac{B}{34}$

1. MODULAR JACK TYPE:
"NX" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

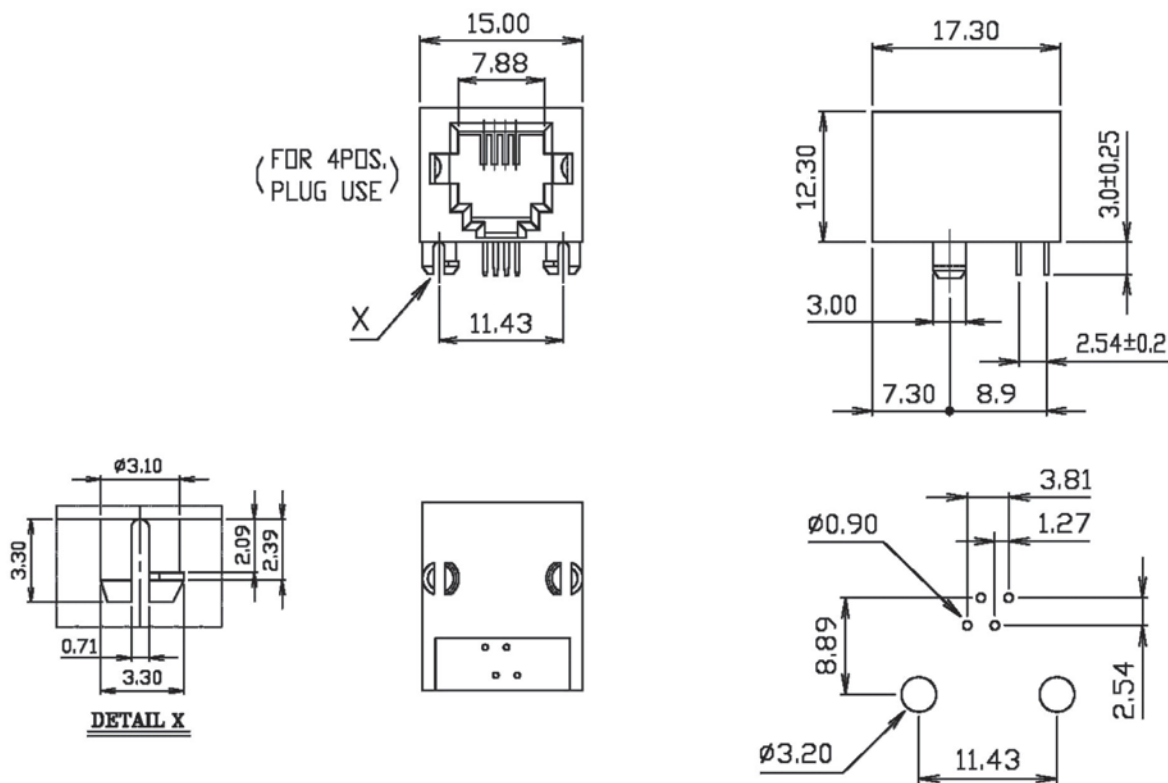
SIDE ENTRY UP LATCH MODULAR PCB JACK 4P PROFILE=12.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J NY - 44 x B
1 2 3 4

1. MODULAR JACK TYPE:
"NY" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

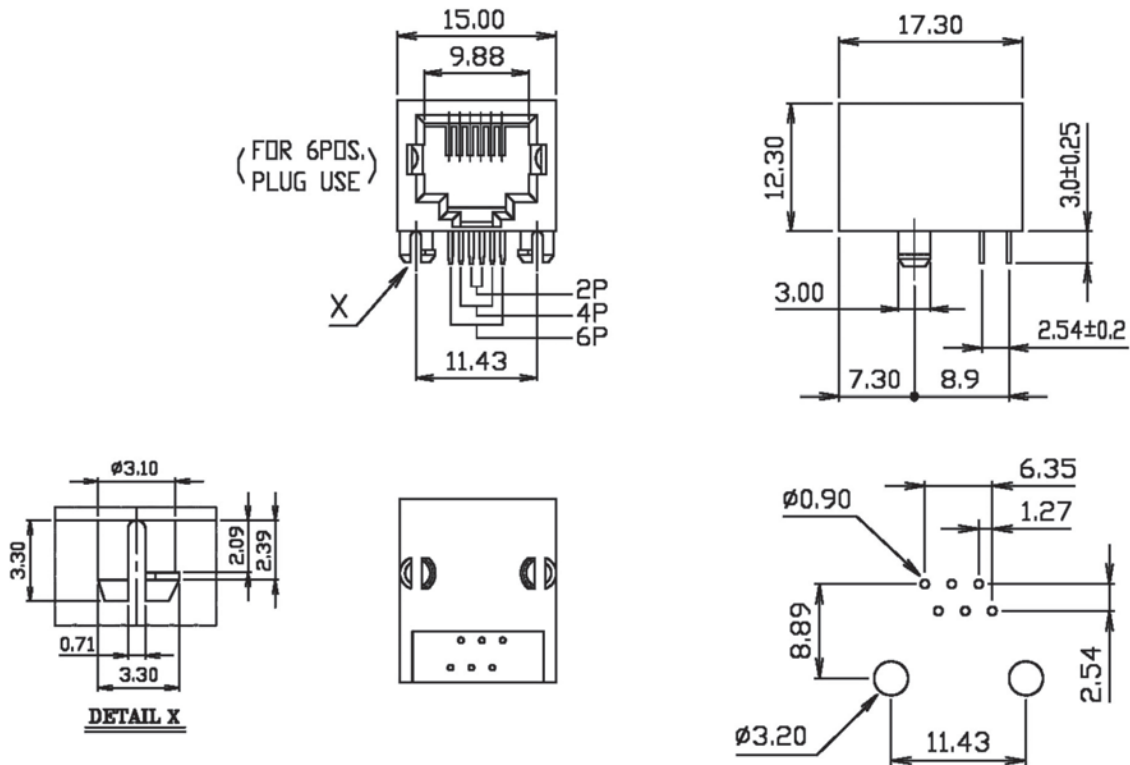
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=12.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J N Y - 6 6 x B
1 2 3 4

- MODULAR JACK TYPE:
"NY" LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

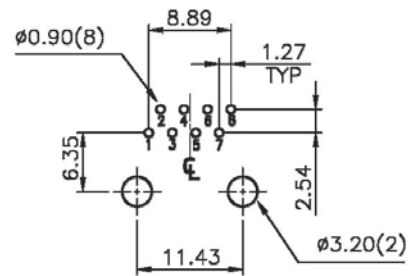
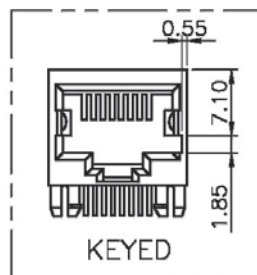
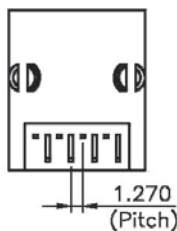
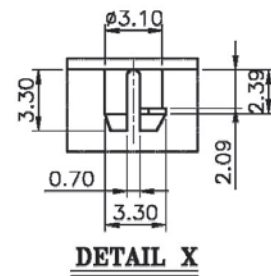
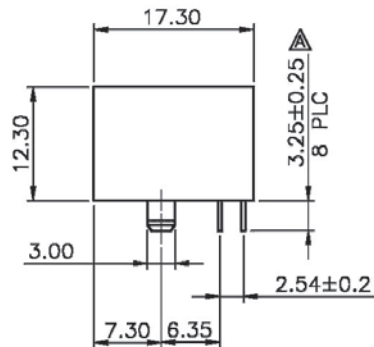
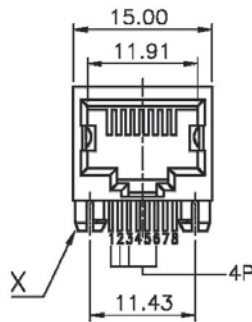
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J NY - 88 x B x

1 2 3 4 5

1. MODULAR JACK TYPE:
"NY" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK
5. KEYED OPTION:
" " WITHOUT KEY
" " KEYED

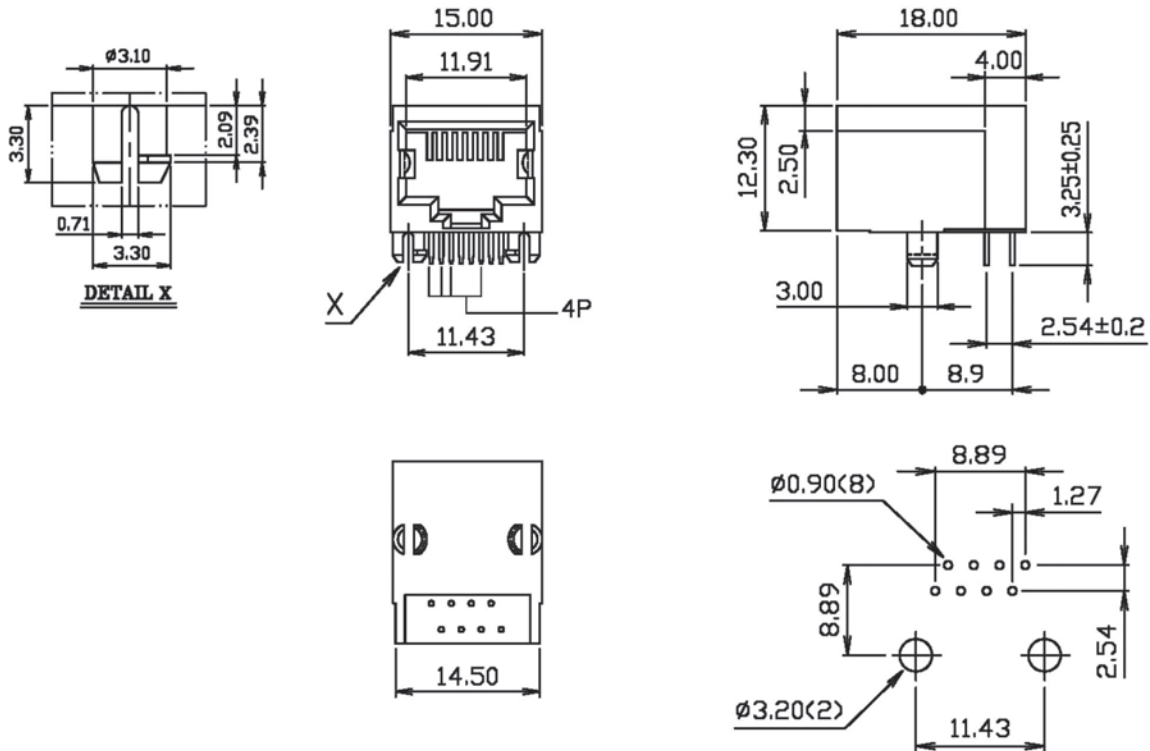
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Q F - 8 8 x B
 1 2 3 4

1. MODULAR JACK TYPE:
"QF" LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

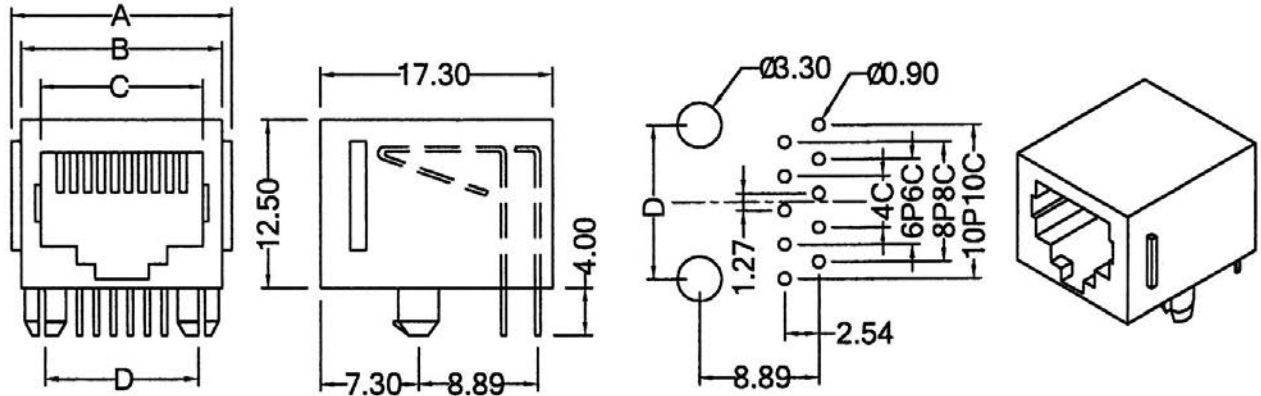
SIDE ENTRY MODULAR PCB JACK 4P+6P+8P+10P PROFILE=12.50MM (UNSHIELDED)

SPECIFICATIONS

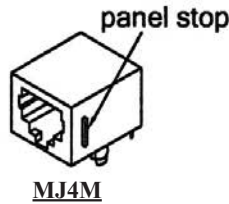
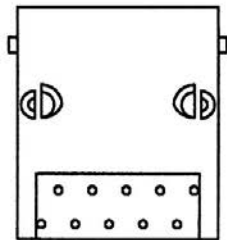
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



No. of Positions	No. of Contacts	A	B	C	D
4P	4C	13.50	11.20	7.80	7.60
6P	2C/4C/6C	15.60	13.20	10.00	10.16
8P	8C	17.60	15.00	11.90	11.43
10P	10C	17.60	15.00	11.90	11.43

ORDERING INFORMATION:

P/N **M J** $\frac{x}{1}$ - $\frac{x}{2}$ $\frac{x}{3}$ **B**

- PANEL STOP OPTION:
 "4M" WITH PANEL STOP
 "4N" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C
 "44" 4P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

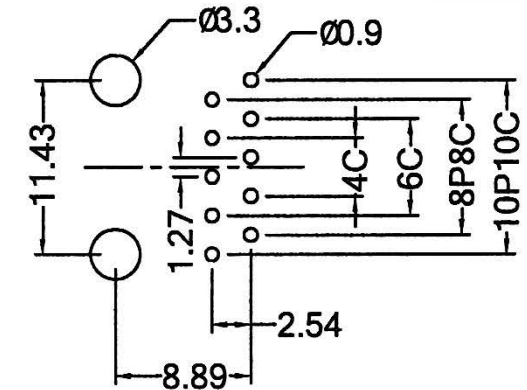
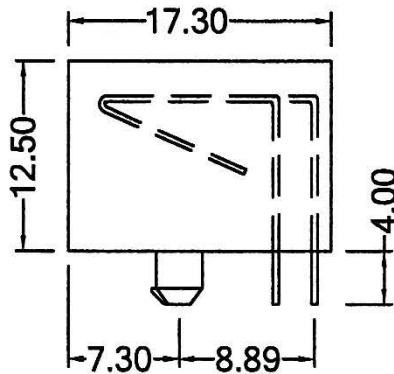
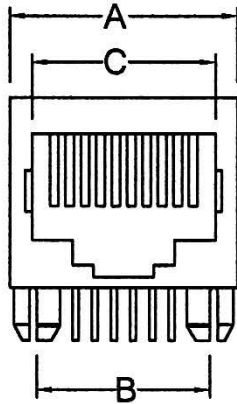
SIDE ENTRY MODULAR PCB JACK 4P+6P+8P+10P PROFILE=12.50MM (UNSHIELDED)

SPECIFICATIONS

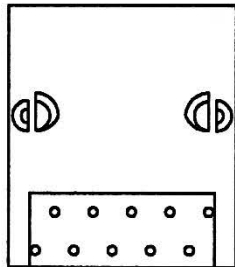
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



No. of Positions	No. of Contacts	A	B	C
4P	4C	15.00	11.43	7.80
6P	2C/4C/6C	15.00	11.43	9.90
8P	4C/6C/8C	15.00	11.43	11.90
10P	10C	15.00	11.43	11.90

ORDERING INFORMATION:

P/N MJ3L - $\frac{XX}{1} \frac{X}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C
 "44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

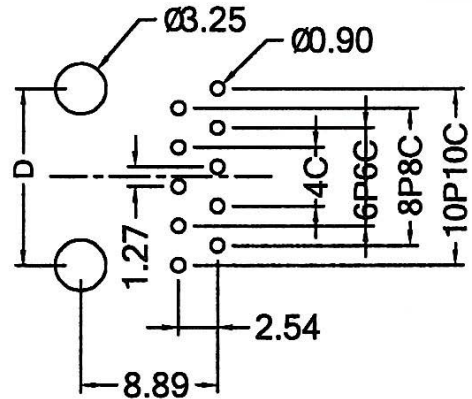
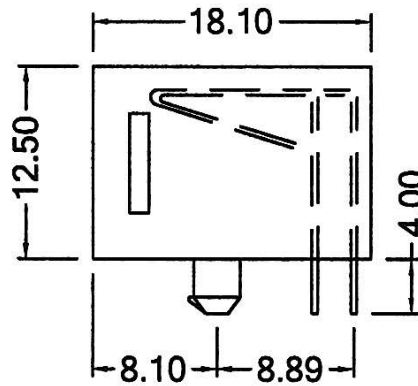
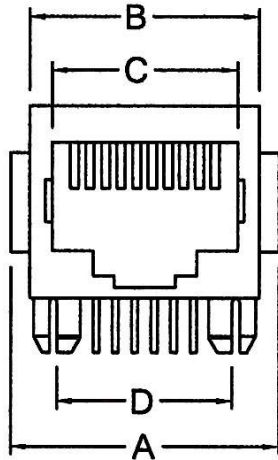
SIDE ENTRY MODULAR PCB JACK 4P+6P+8P+10P PROFILE=12.50MM (UNSHIELDED)

SPECIFICATIONS

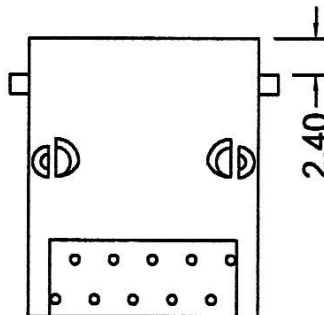
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



No. of Positions	No. of Contacts	A	B	C	D
4P	4C	13.50	11.30	7.80	7.60
6P	2C/4C/6C	15.60	13.20	9.90	10.16
8P	8C	17.50	15.00	12.00	11.43
10P	10C	17.50	15.00	12.00	11.43

ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B

- PANEL STOP OPTION:
 "3C" WITH PANEL STOP
 "3D" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "84" 8P4C
 "00" 10P10C
 "44" 4P4C

- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

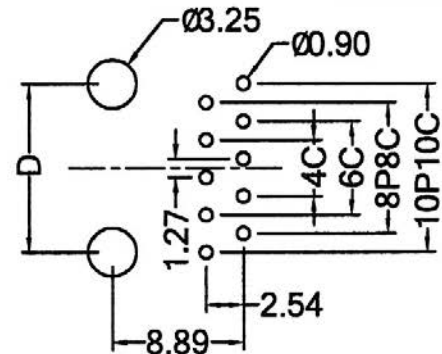
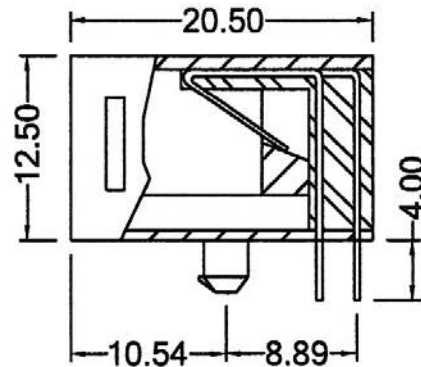
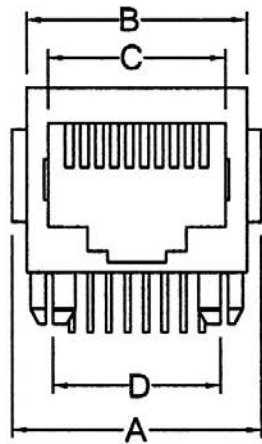
SIDE ENTRY MODULAR PCB JACK 4P+6P+8P+10P PROFILE=12.50MM (UNSHIELDED)

SPECIFICATIONS

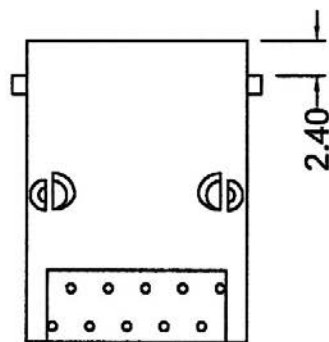
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout (TOP VIEW)



No. of Positions	No. of Contacts	A	B	C	D
4P	4C	13.50	11.20	7.95	7.62
6P	2C/4C/6C	15.60	13.20	10.00	10.16
8P	4C/6C/8C	17.60	15.00	12.00	11.43
10P	10C	17.60	15.00	12.00	11.43

ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{X}{3} B$

- PANEL STOP OPTION:
 "09" WITH PANEL STOP
 "10" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C
 "44" 4P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

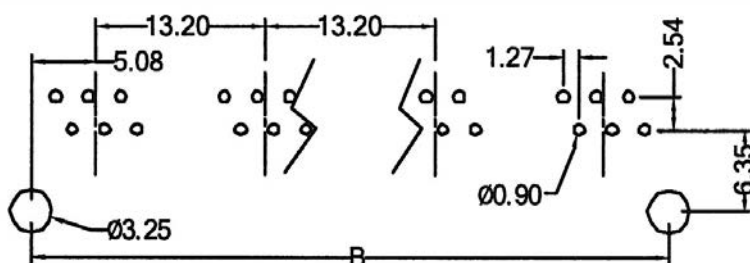
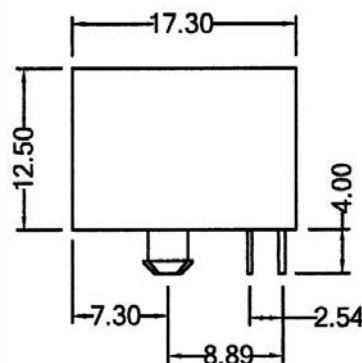
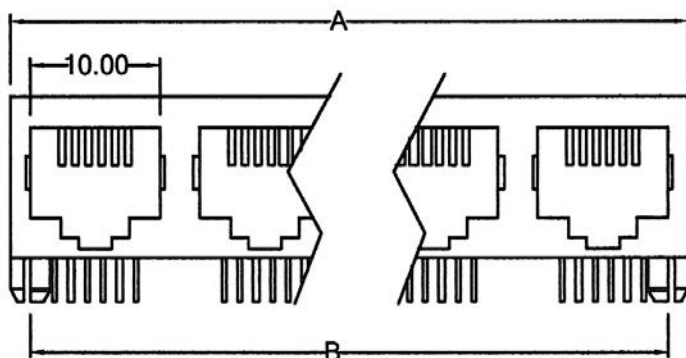
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 6P PROFILE=12.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

Ports	A	B
02	26.40	23.36
03	39.60	36.56
04	52.00	49.76
05	66.00	62.96
06	79.20	76.16
07	92.40	89.36
08	105.60	102.56

ORDERING INFORMATION:

P/N M J 4 L - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 02, 03, 04, 05, 06, 07, 08

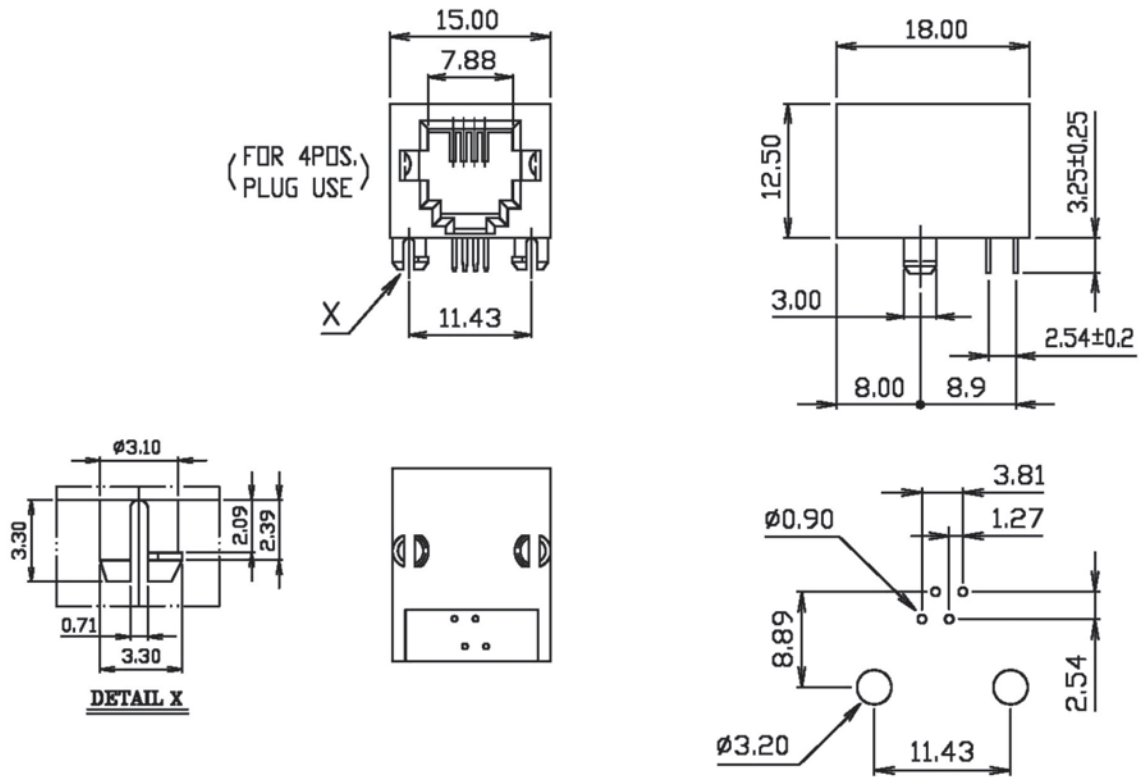
SIDE ENTRY MODULAR PCB JACK 4P PROFILE=12.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N **M J Q G - 44 x B**
 1 2 3 4

- MODULAR JACK TYPE:
"QG" LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"44" 4P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

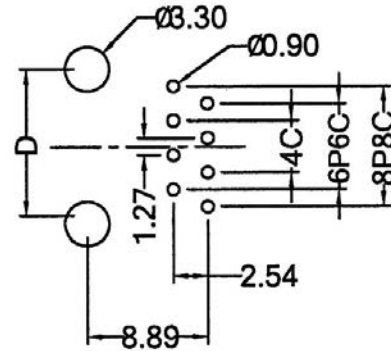
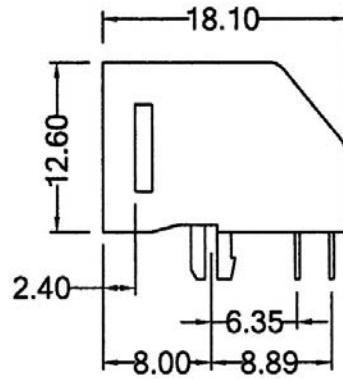
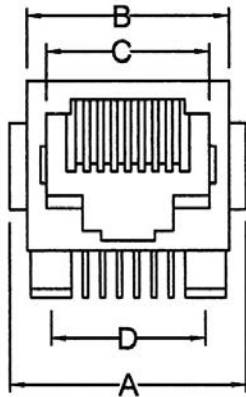
SIDE ENTRY MODULAR PCB JACK 6P+8P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

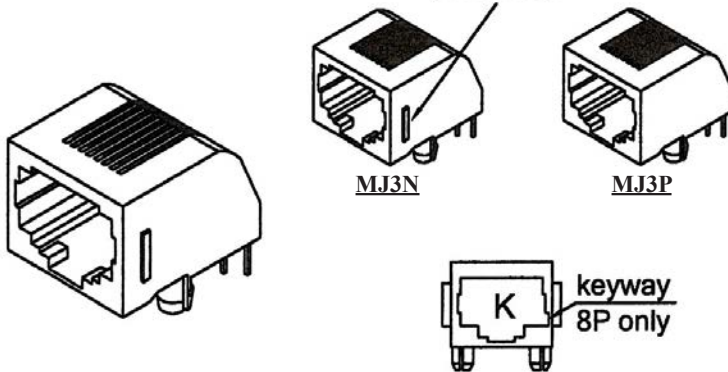
MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)

panel stop



No. of Positions	No. of Contacts	A	B	C	D
6P	4C/6C	15.75	13.20	9.90	10.16
8P	8C	17.75	15.20	11.93	11.43

ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{xx}{2}$ $\frac{x}{3}$ B $\frac{x}{4}$

- PANEL STOP OPTION:
 "3N" WITH PANEL STOP
 "3P" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

- KEYWAY OPTION:
 " " W/O KEYWAY
 "K" WITH KEYWAY

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

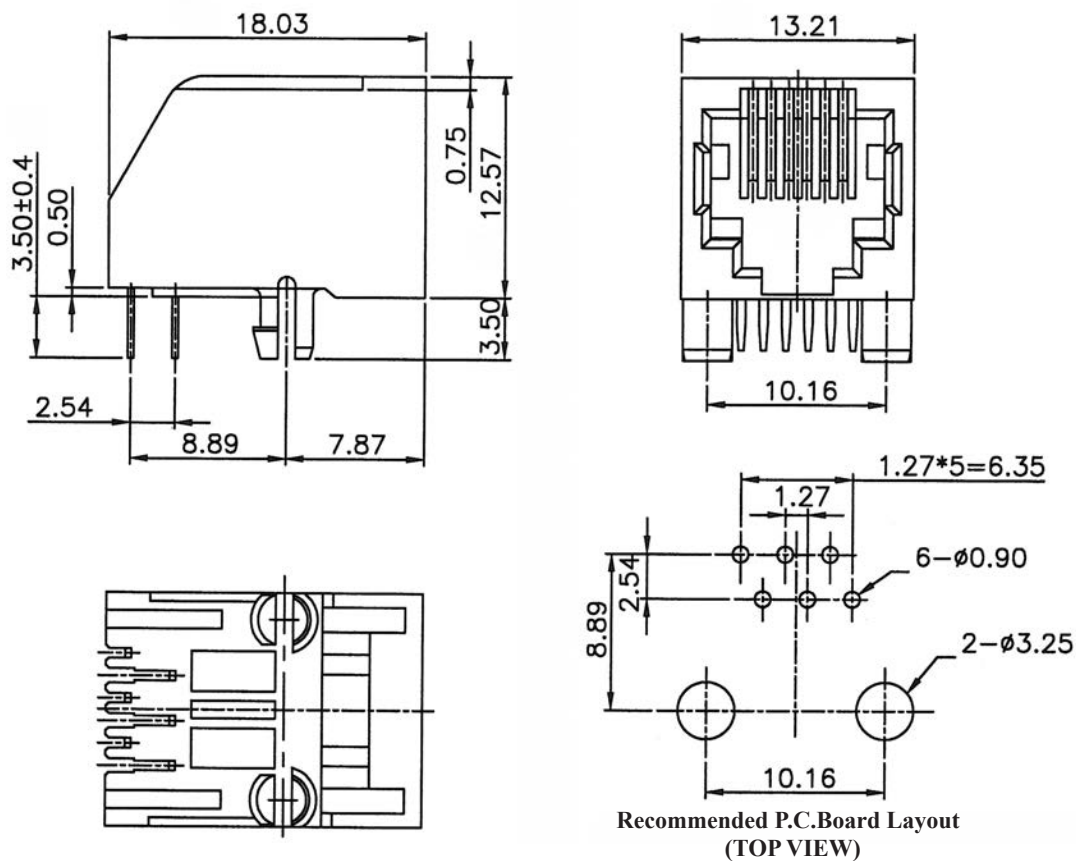
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 2 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

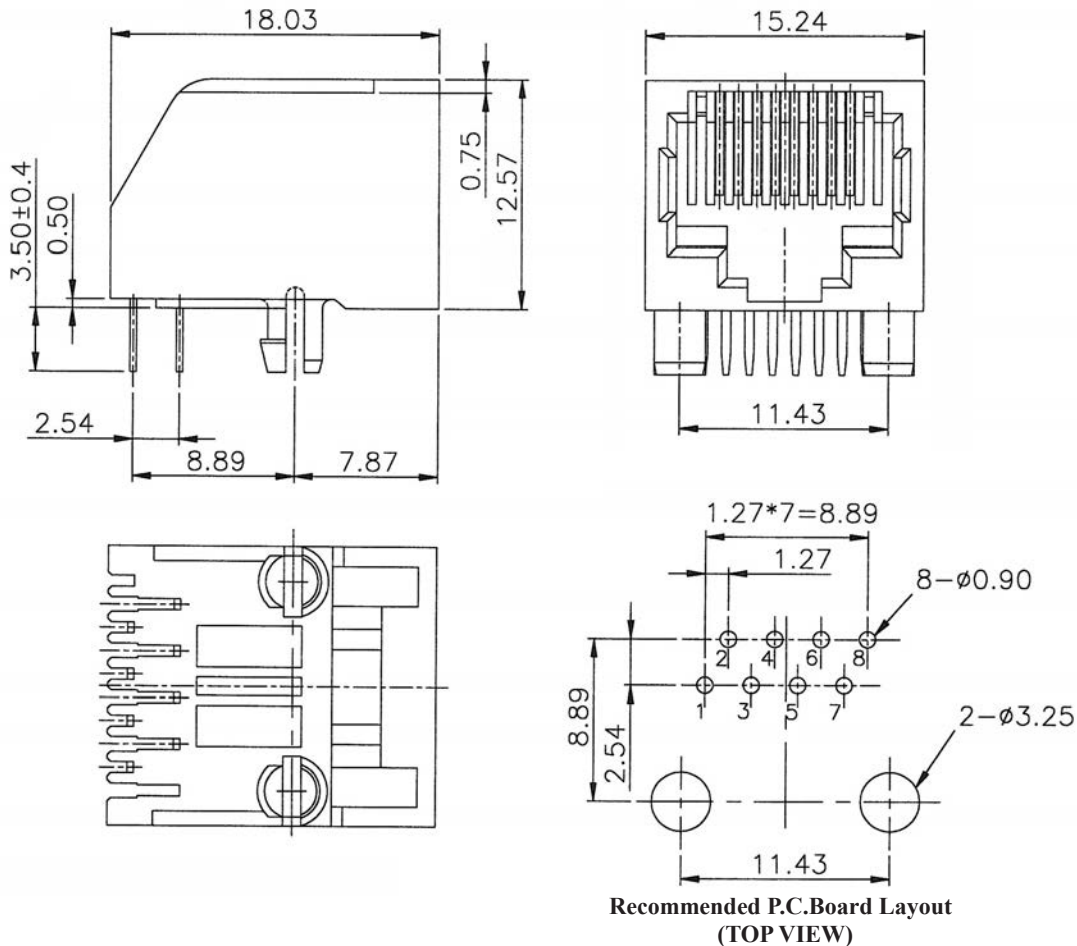
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 2 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

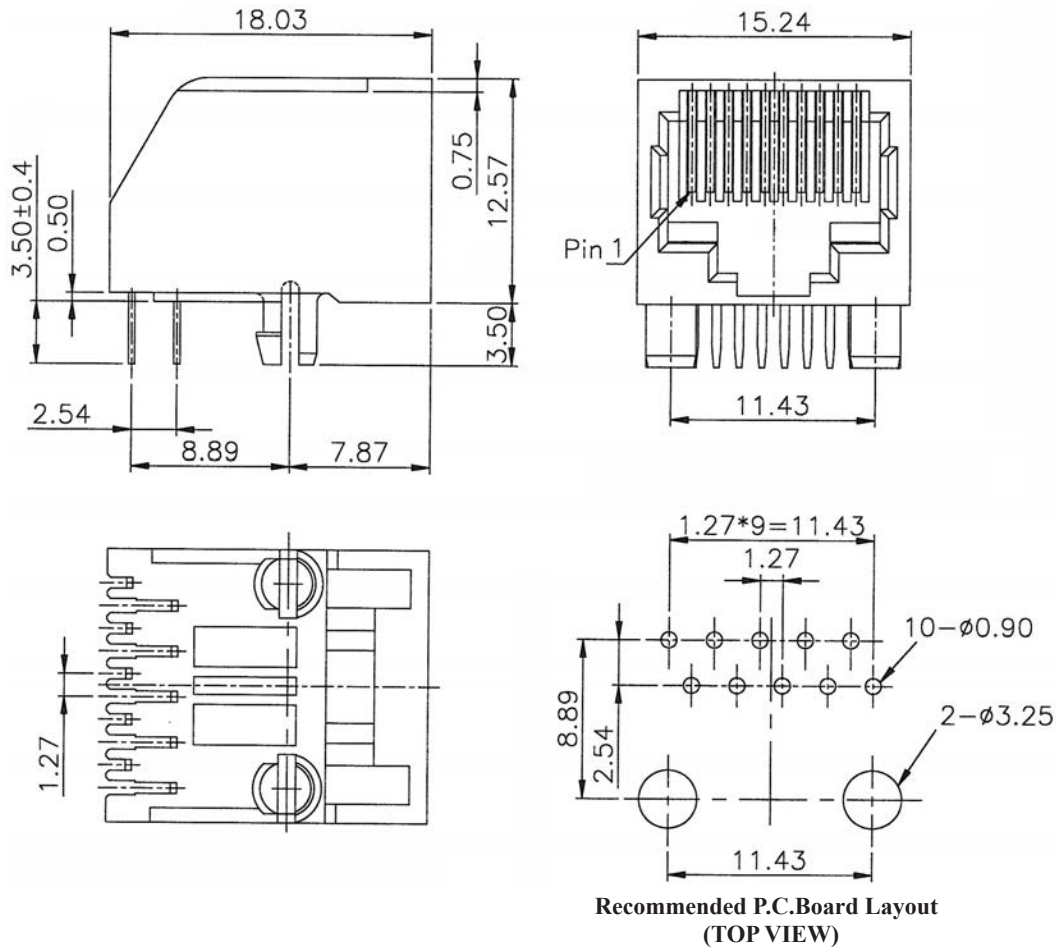
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 2 - $\frac{x x x}{1 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

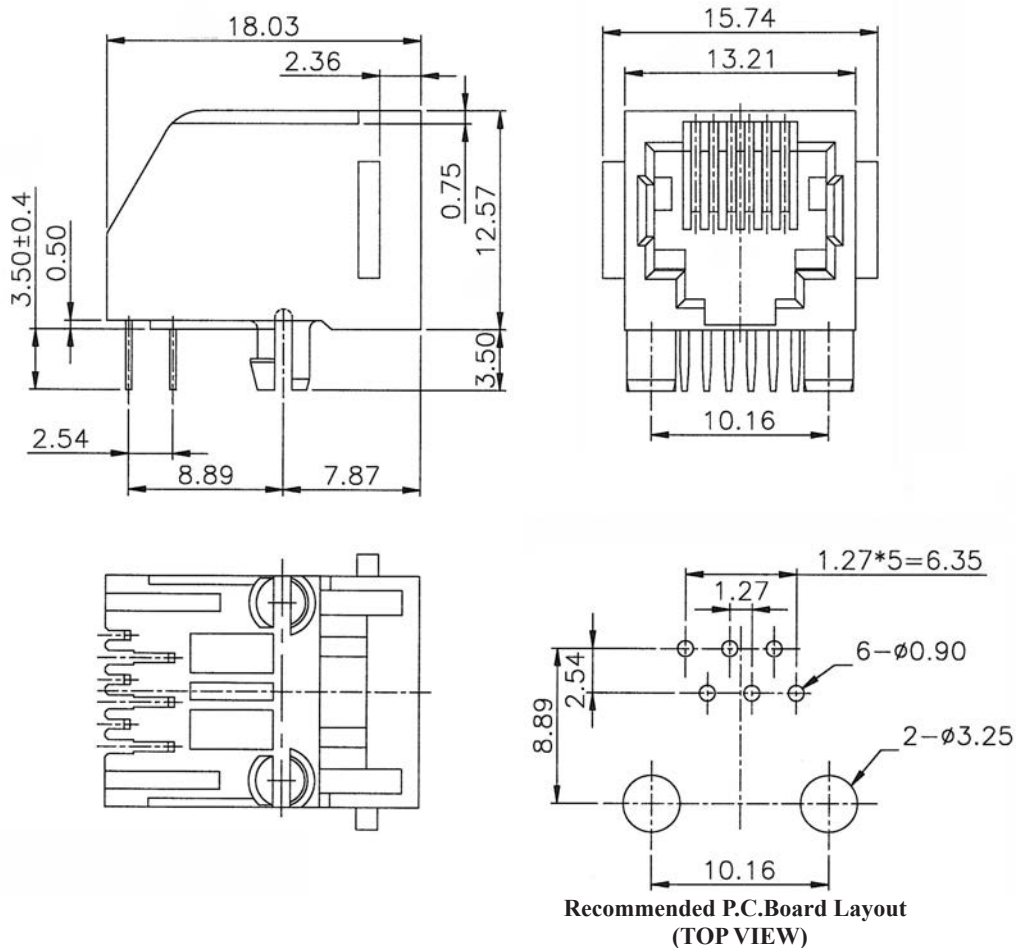
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ11 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

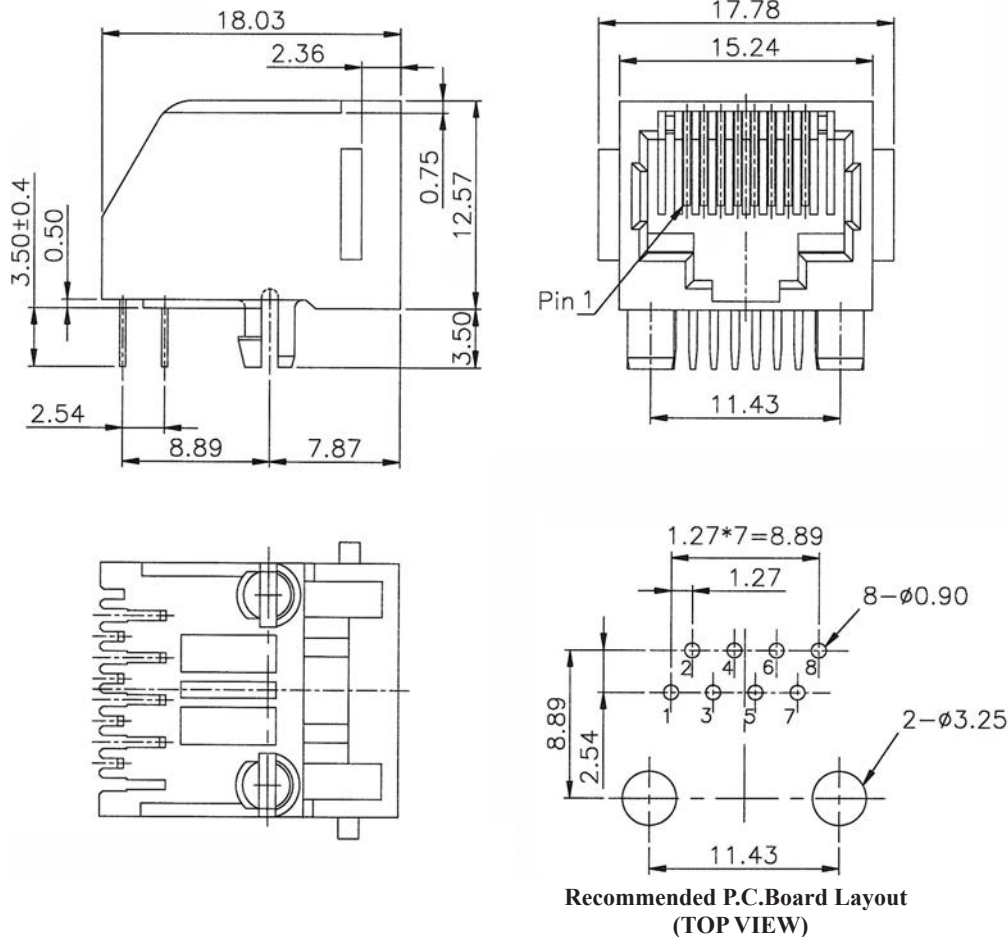
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 1 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. KEYWAY OPTION:

" " W/O KEYWAY

"K" WITH KEYWAY

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

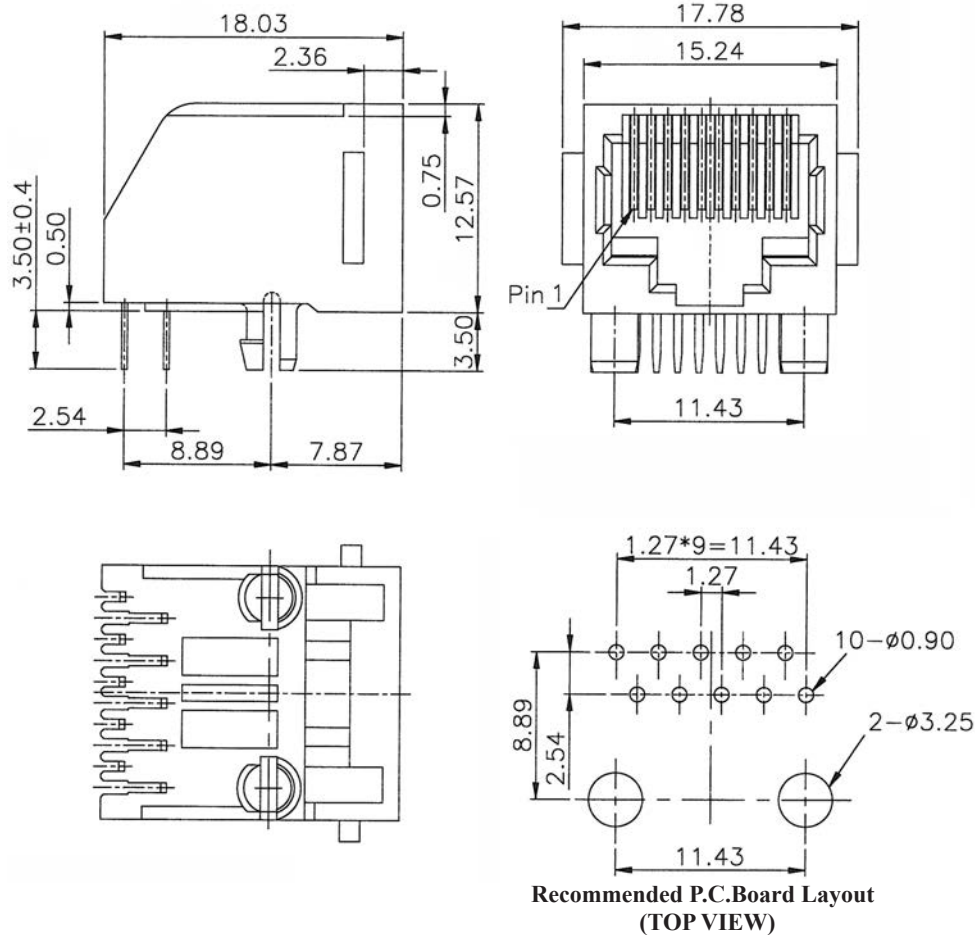
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ11 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

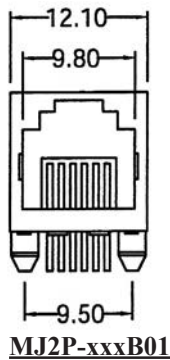
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=12.60MM (UNSHIELDED)

SPECIFICATIONS

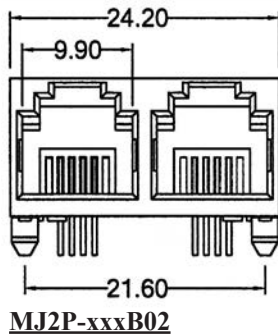
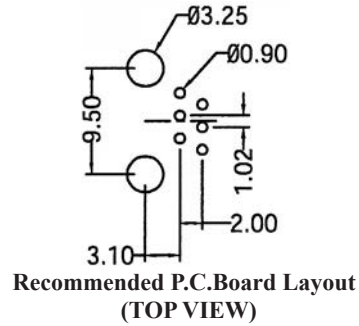
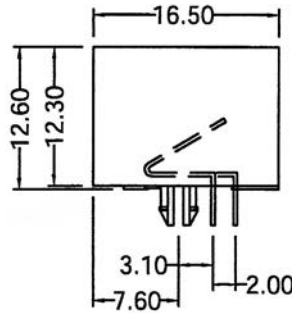
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

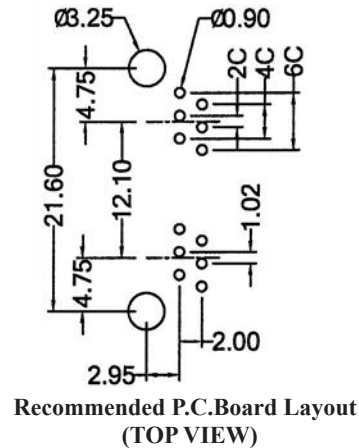
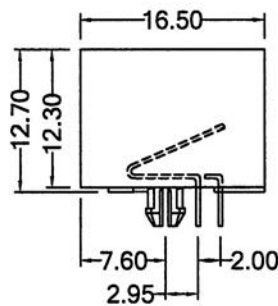
Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



MJ2P-xxxB01



MJ2P-xxxB02



ORDERING INFORMATION:

P/N MJ2P - $\frac{xx}{1} \frac{xx}{2} \frac{B}{3} \frac{xx}{3}$

- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 01, 02

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.65MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

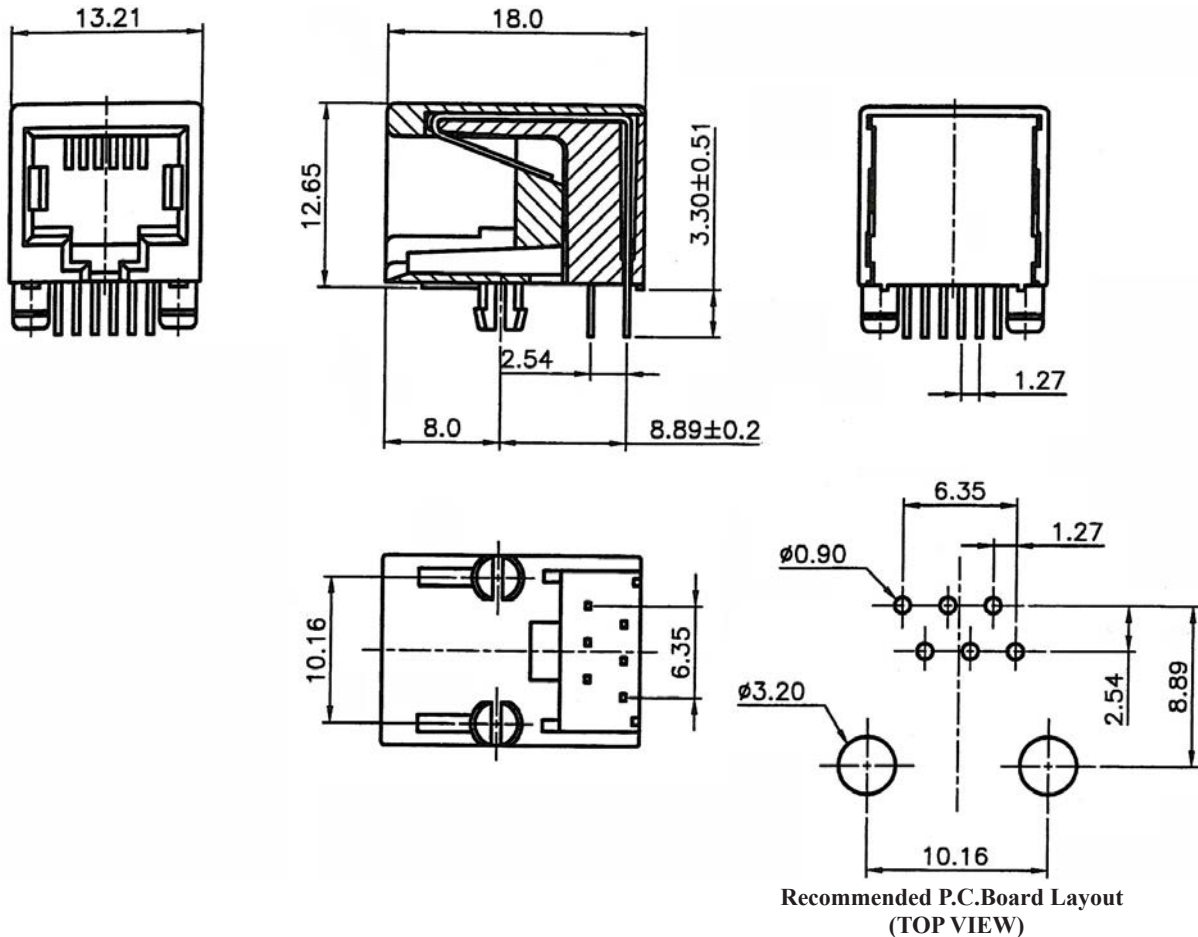
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 4 H - $\frac{x \ x \ x}{T \ 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

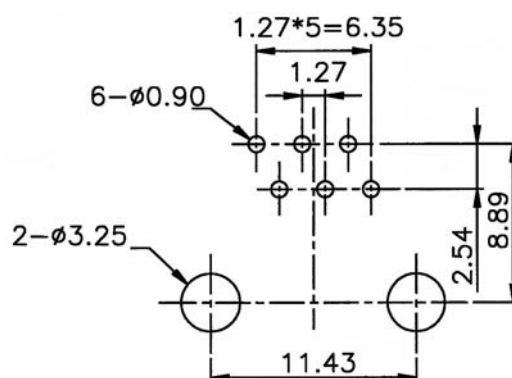
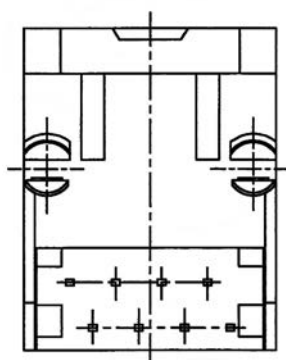
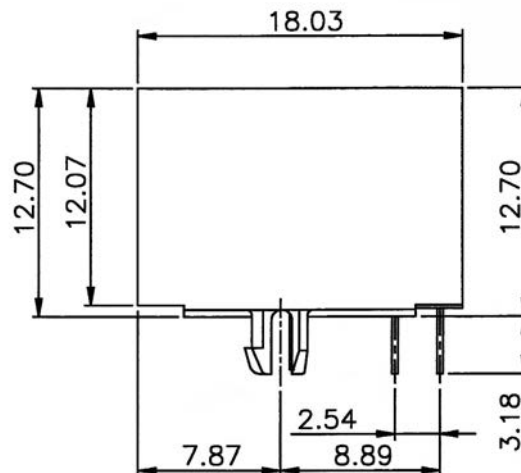
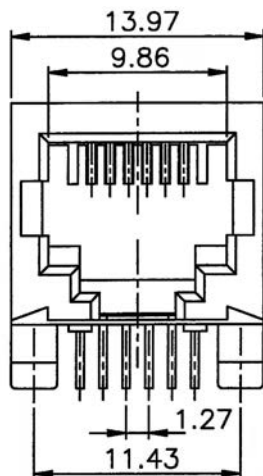
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 0 3 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

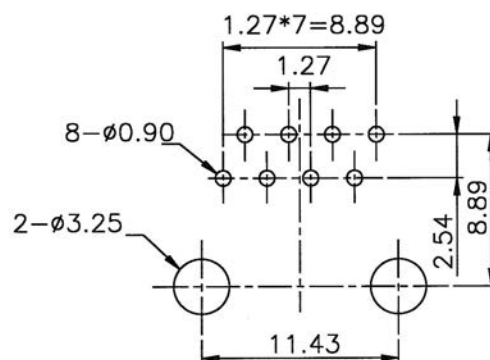
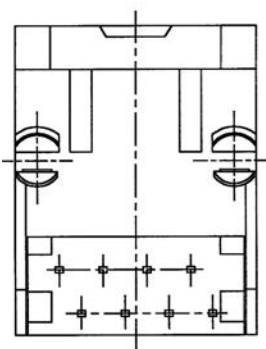
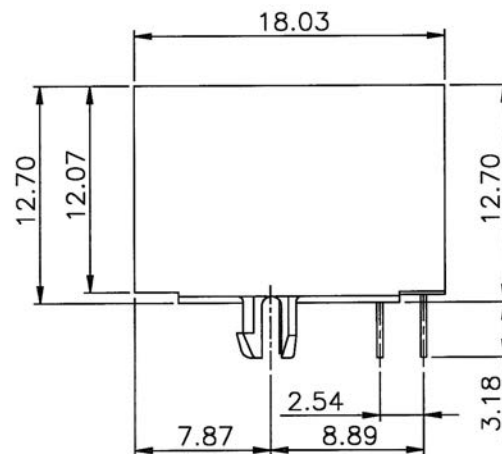
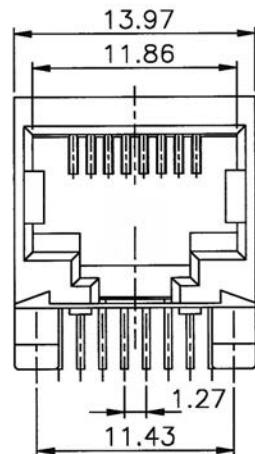
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ03 - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"86" 8P6C

"84" 8P4C

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

SIDE ENTRY MODULAR PCB JACK 4P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

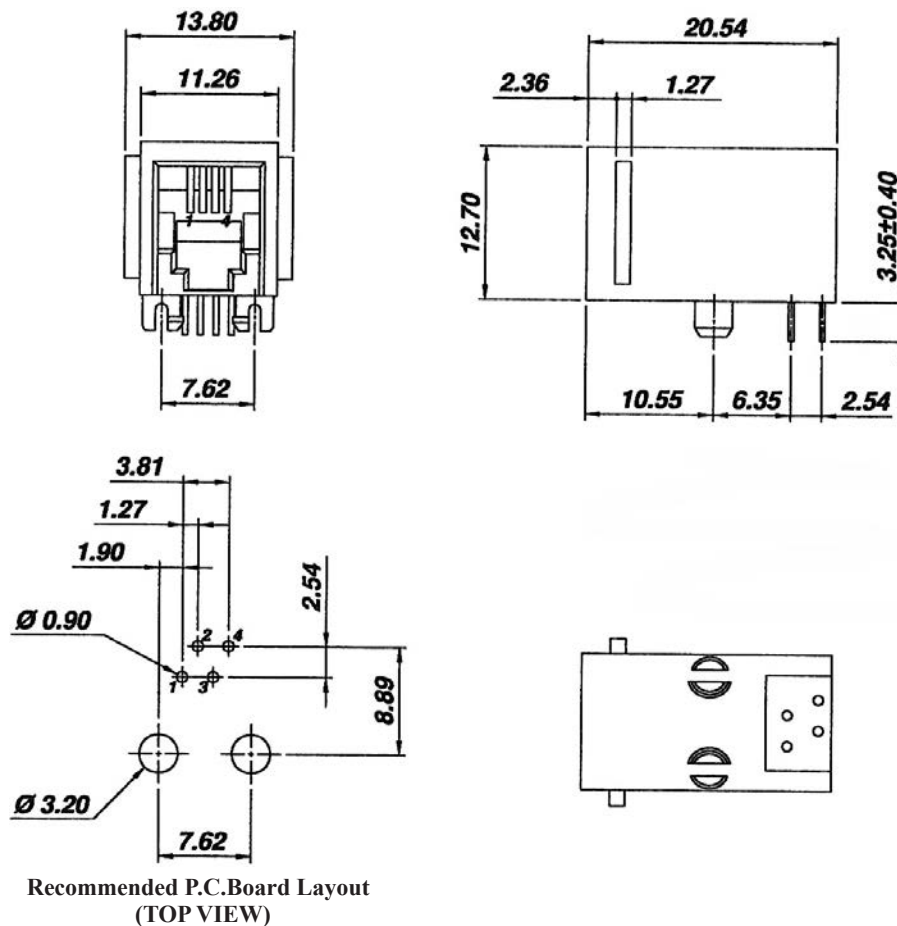
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJLE - $\frac{44}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLEHT-44xB for High Temp. Version

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

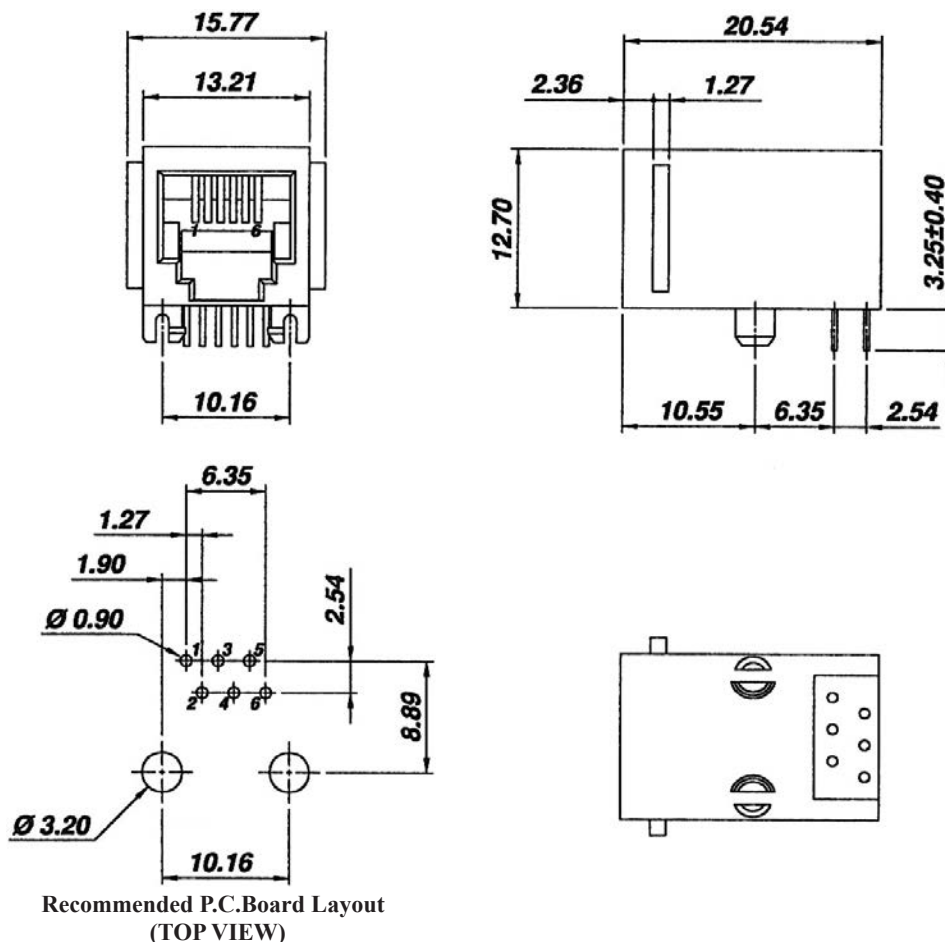
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J L E - $\frac{x x x}{T} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLEHT-6xxB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

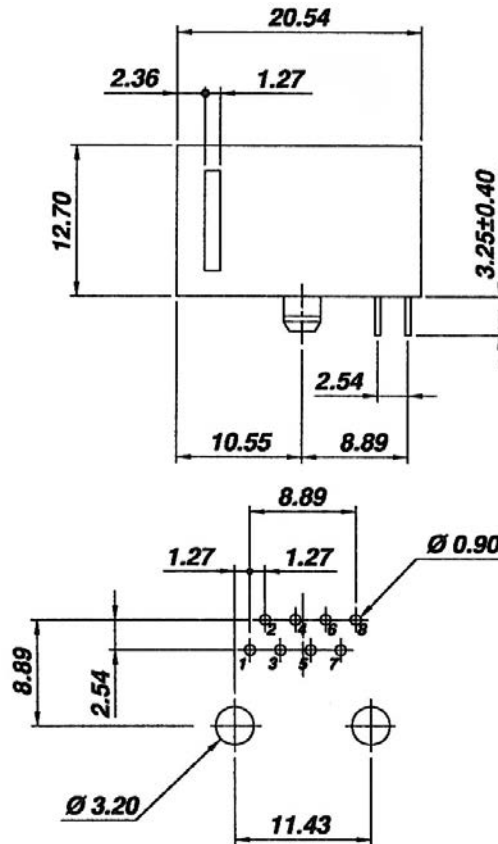
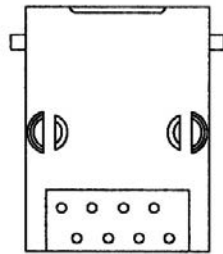
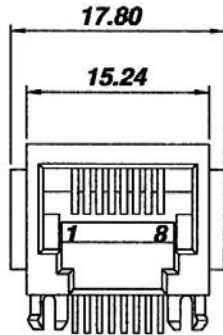
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C. Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJLE - $\frac{88}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLEHT-88xB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 4P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

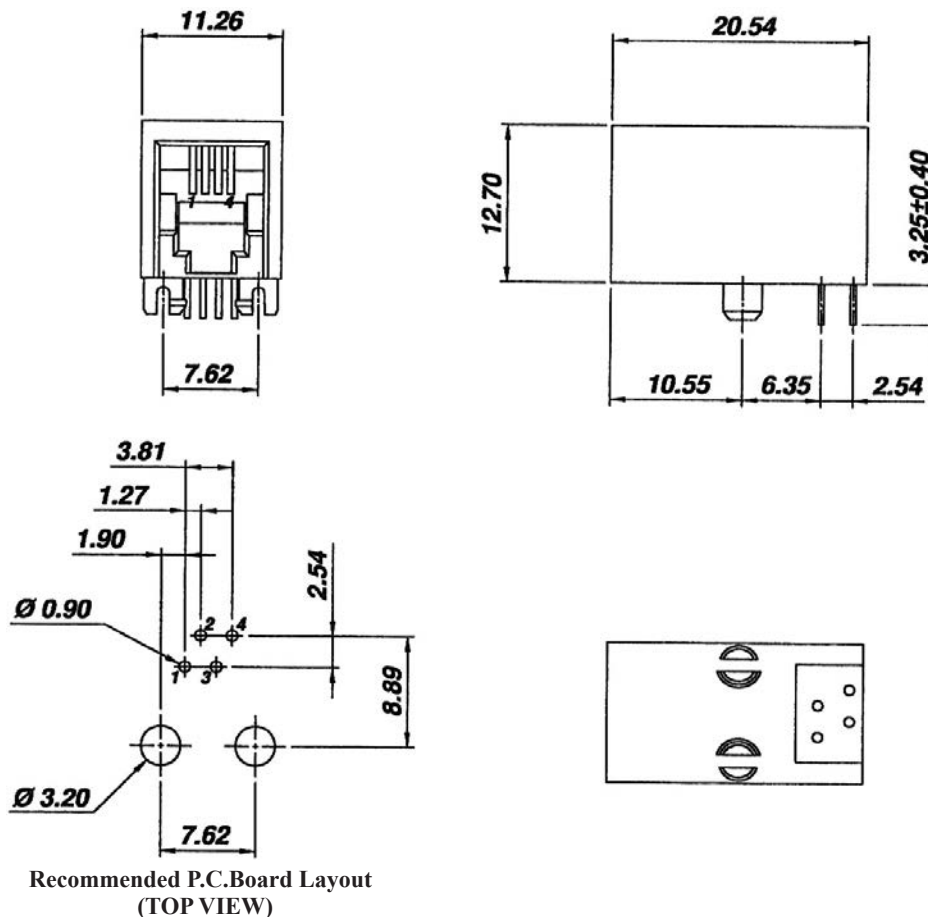
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJLF - $\frac{44}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLFHT-44xB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

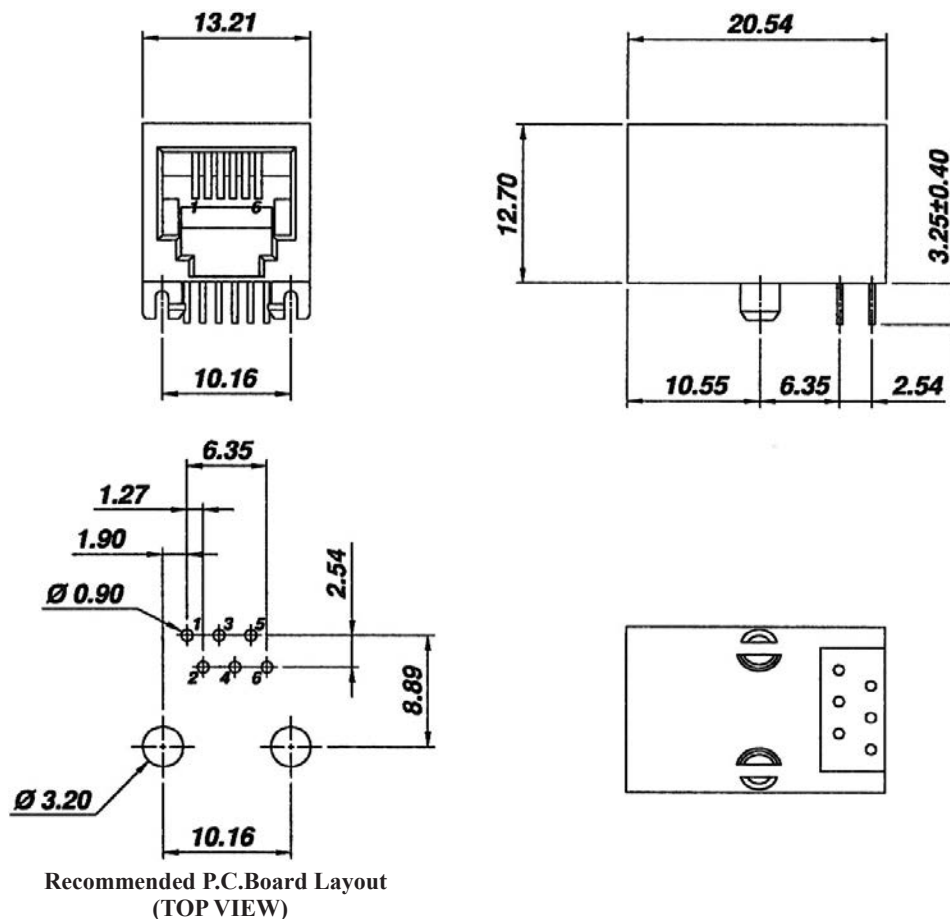
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJLF - $\frac{x \ x \ x}{1 \ 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLFHT-6xxB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

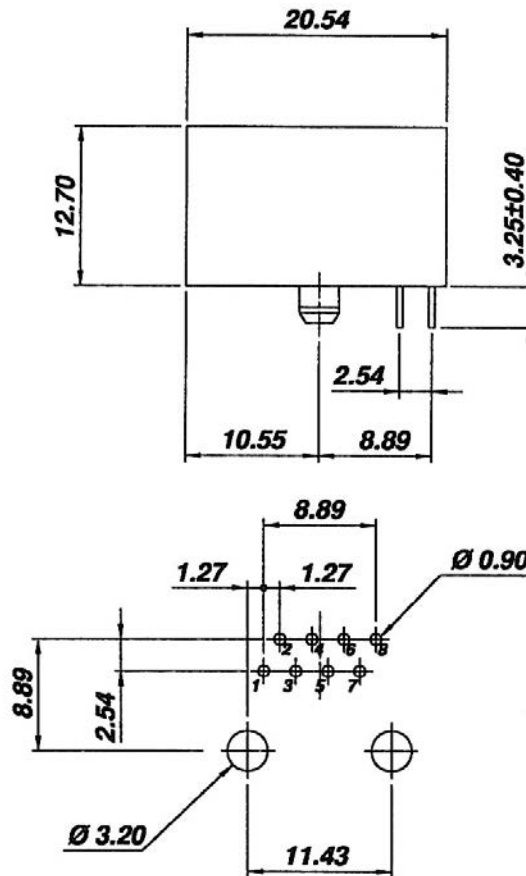
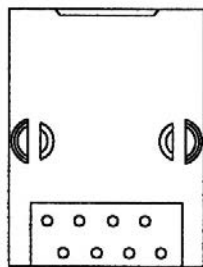
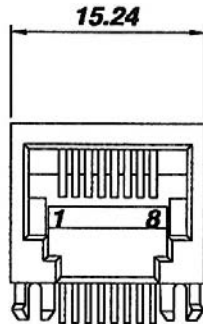
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJLF - $\frac{88 \times B}{1 \ 2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLFHT-88xB FOR HIGH TEMP. VERSION

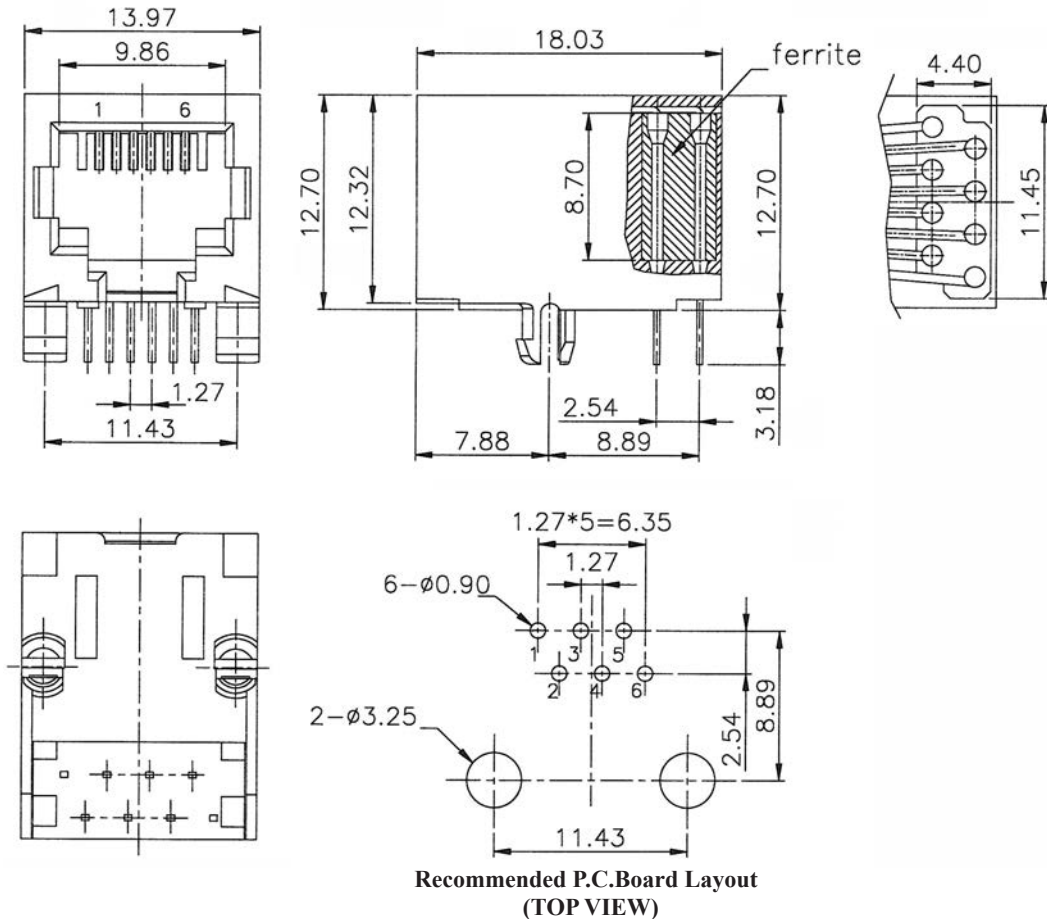
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1U - $\frac{xxxB}{T2}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

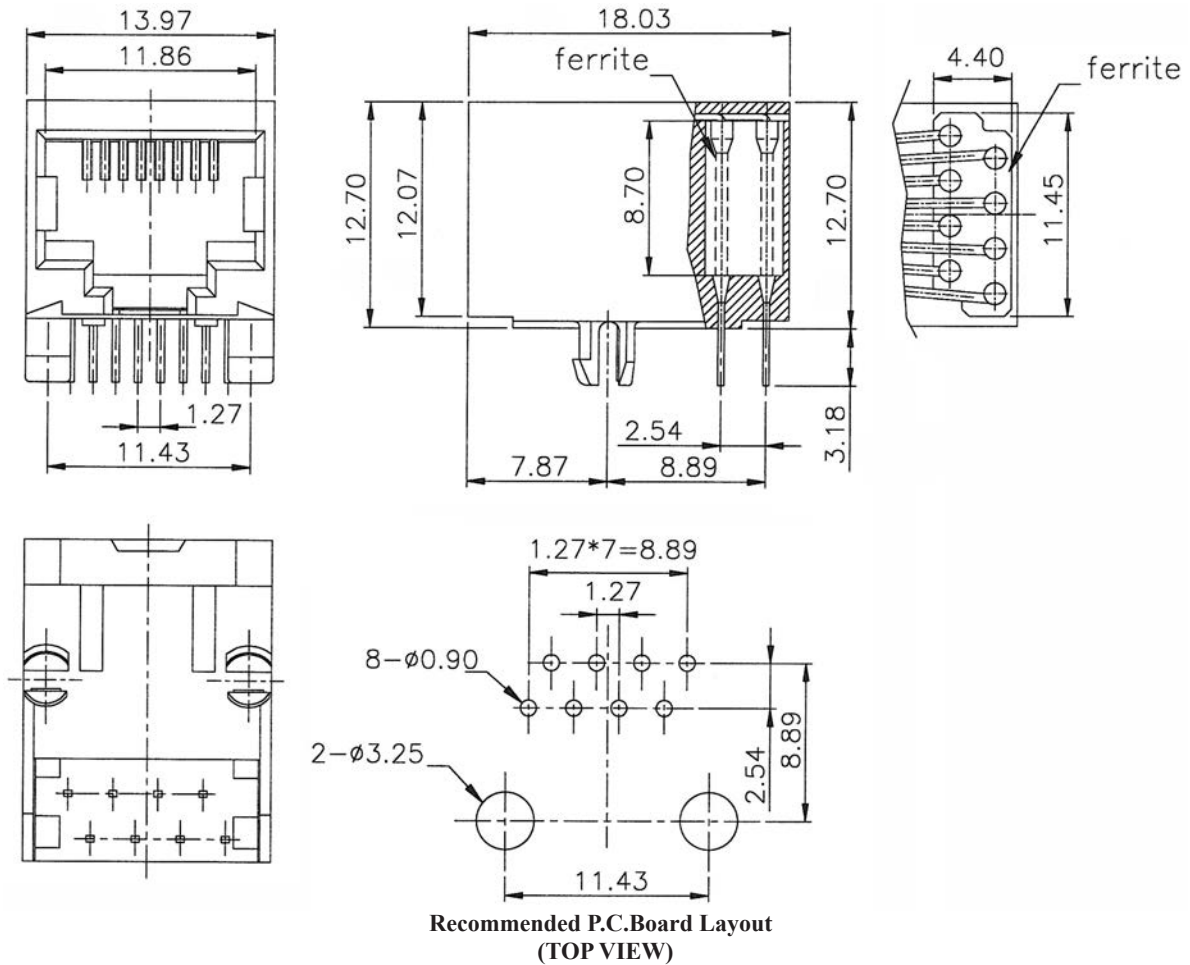
SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1U - $\frac{88}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK WITH FERRITE 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

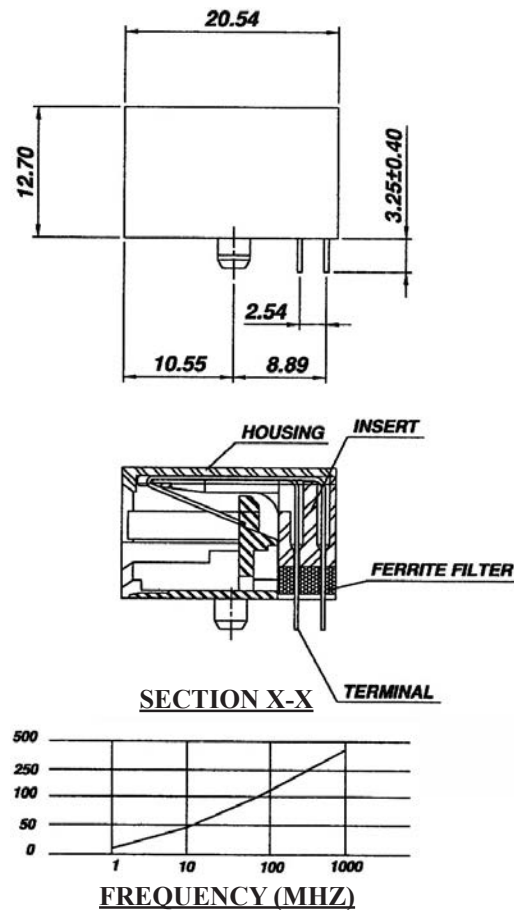
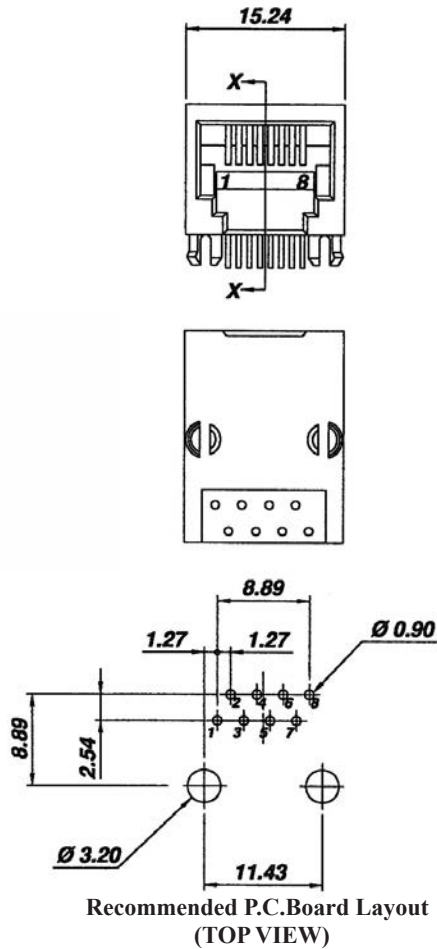
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ52 - $\frac{88}{1} \times \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJ52HT-88xB FOR HIGH TEMP. VERSION

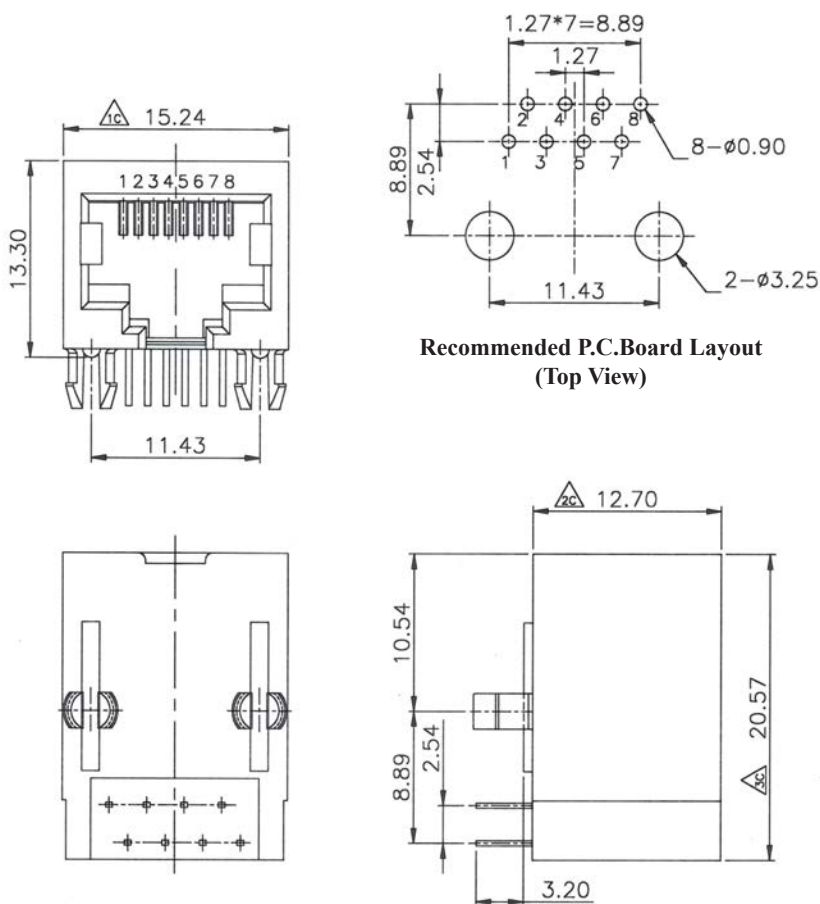
SIDE ENTRY CAT.5 MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J T X - $\frac{x \ x \ x \ B}{1 \ 2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD

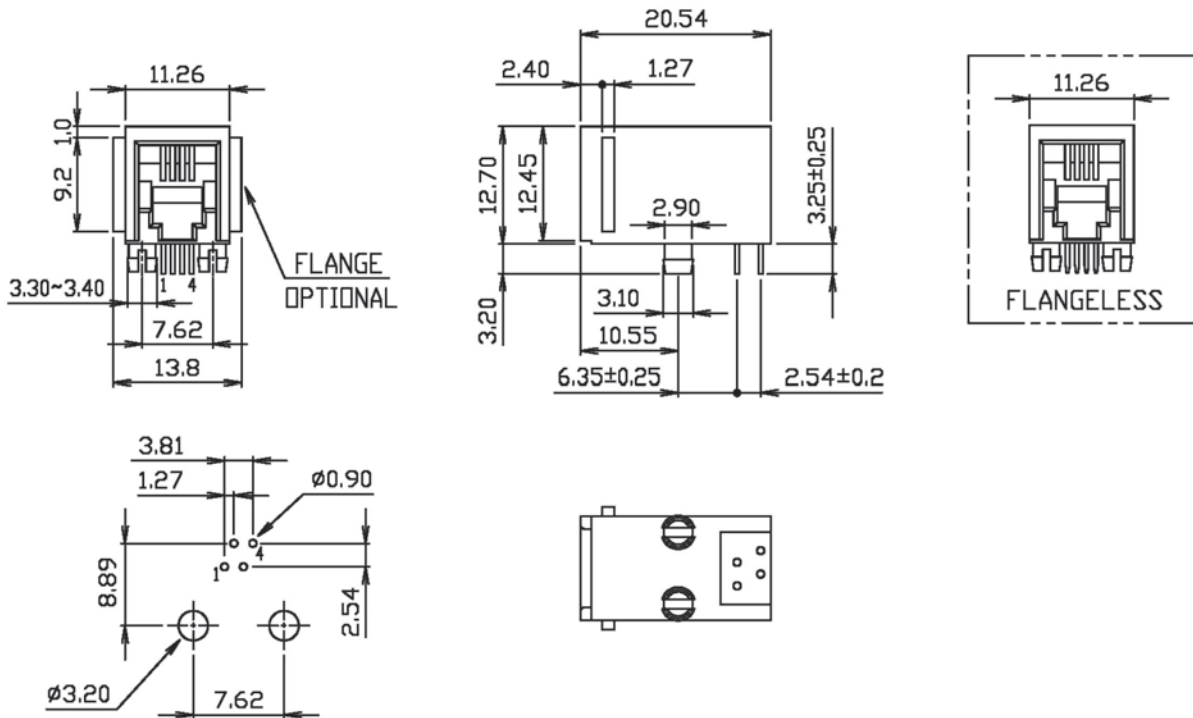
SIDE ENTRY MODULAR PCB JACK 4P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{4}{2}$ $\frac{4}{3}$ $\frac{B}{4}$

- MODULAR JACK TYPE:
 "QK" FLANGED (WITH PANEL STOP)
 "QL" FLANGELESS (W/O PANEL STOP)
- NO. OF POSITIONS & CONTACTS:
 "44" 4P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

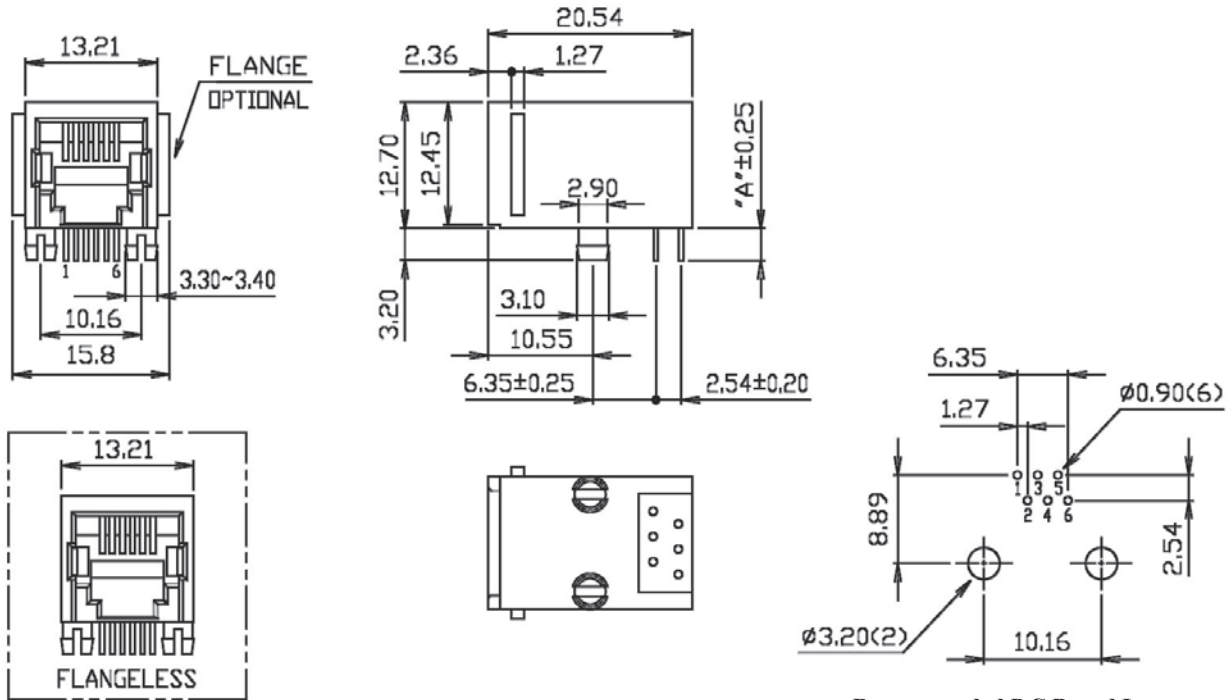
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{6.6}{2}$ $\frac{x}{3}$ $\frac{B}{4}$

1. MODULAR JACK TYPE:
 "QK" FLANGED (WITH PANEL STOP)
 "QL" FLANGELESS (W/O PANEL STOP)
2. NO. OF POSITIONS & CONTACTS:
 "64" 6P4C
 "66" 6P6C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. HOUSING COLOR:
 "B" BLACK

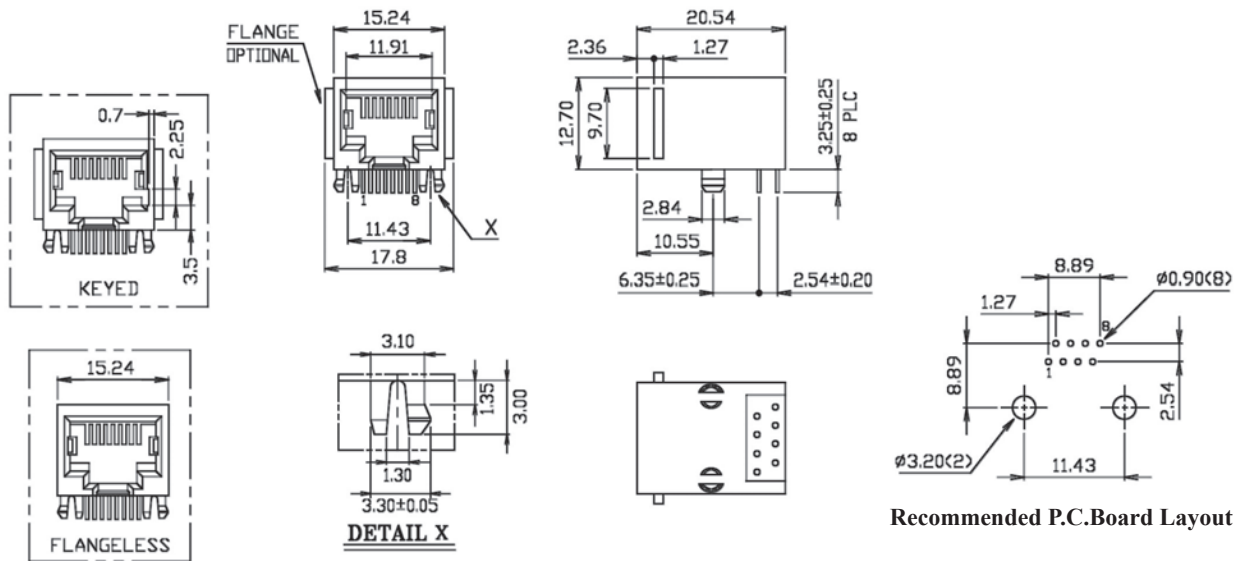
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{B}{4}$ $\frac{x}{5}$

- MODULAR JACK TYPE:
 "QK" FLANGED (WITH PANEL STOP)
 "QL" FLANGELESS (W/O PANEL STOP)
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

- KEY OPTION:
 " " WITHOUT KEY
 "K" KEYED

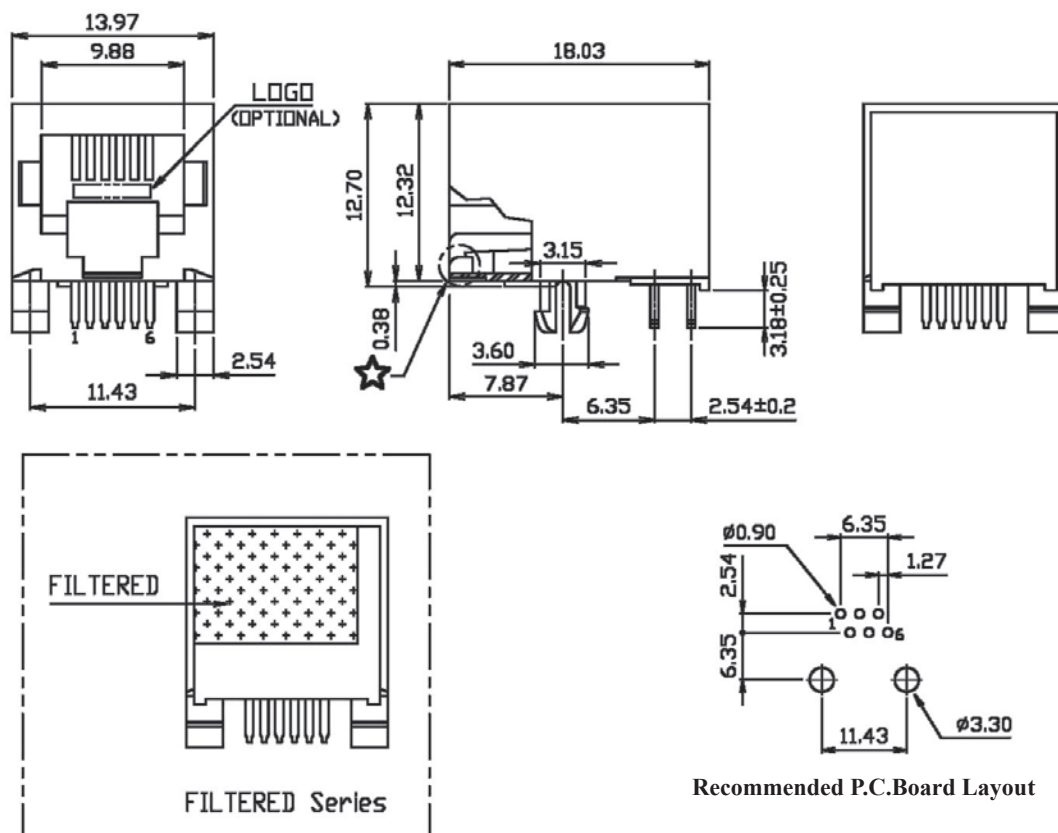
SIDE ENTRY MODULAR PCB JACK 6P WITH FERRITE PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{6}{2}$ $\frac{6}{3}$ $\frac{x}{4}$ B

- MODULAR JACK TYPE:
 "QM" FILTERED (WITH FERRITE)
 "QN" FILTERLESS (W/O FERRITE)
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

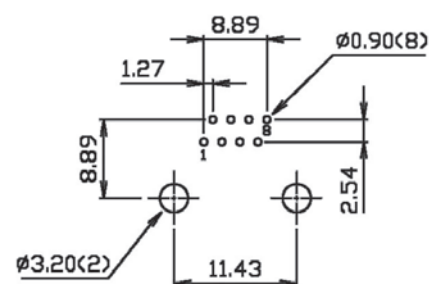
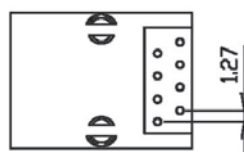
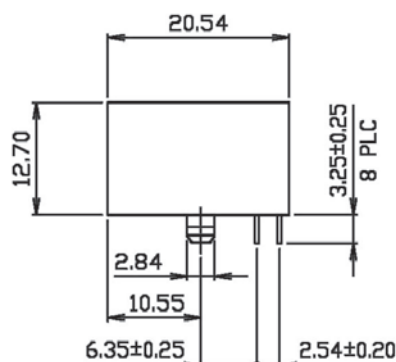
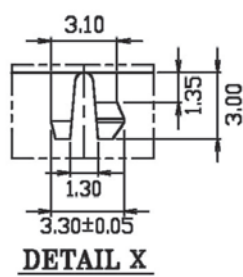
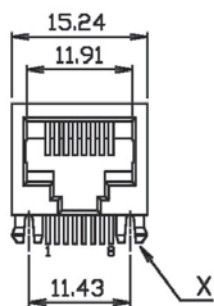
SIDE ENTRY CAT.5 MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N **M J Q H - 8 8 x B**
 1 2 3 4

1. MODULAR JACK TYPE:
"QH" CAT.5 PCB JACK
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

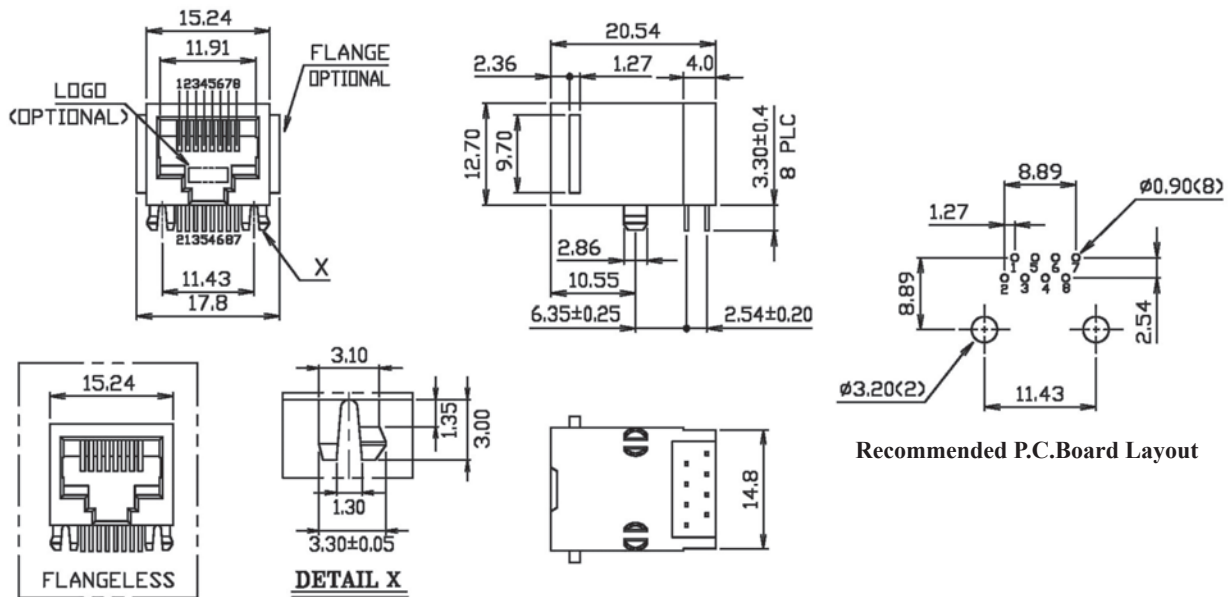
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{B}{4}$

- MODULAR JACK TYPE:
 "QP" FLANGED WITH PIN #21354687
 "QQ" FLANGELESS WITH PIN #21354687
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

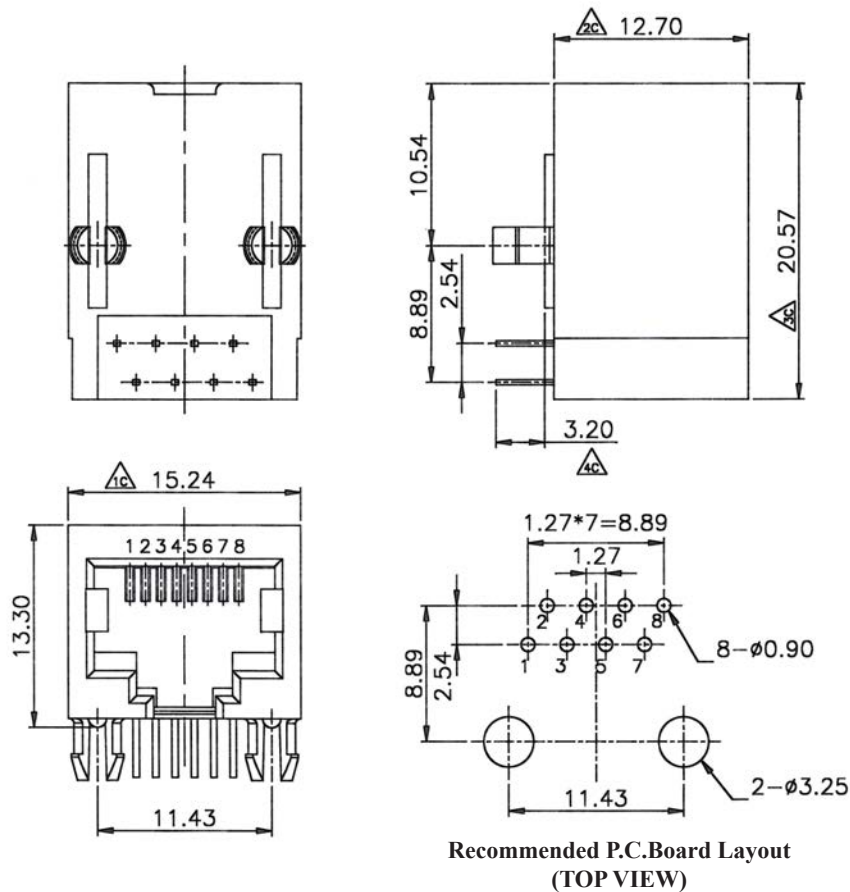
SIDE ENTRY CAT.5 MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J Y F - 88 x B
 1 2 3 4

1. MODULAR JACK TYPE:
"YF" CAT.5 JACK
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

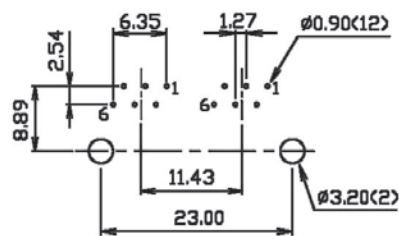
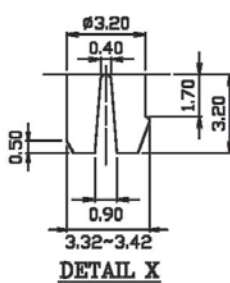
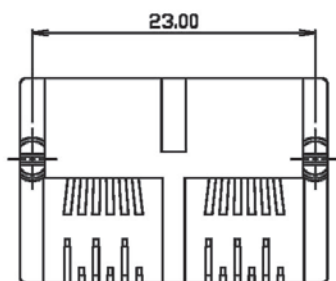
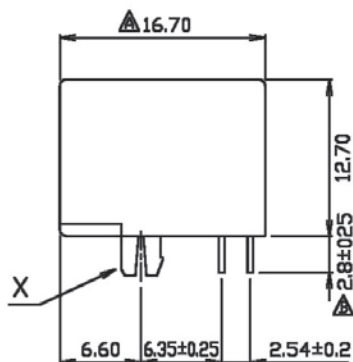
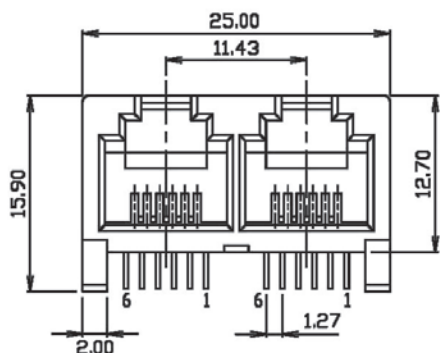
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N **M J Q J - 6 6 x B 0 2**
_{1 2 3 4 5}

- MODULAR JACK TYPE:
"QJ" LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
02

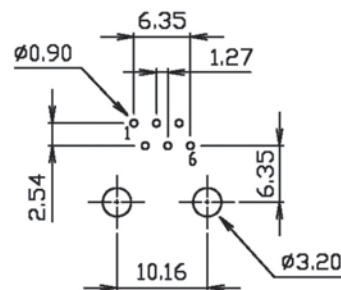
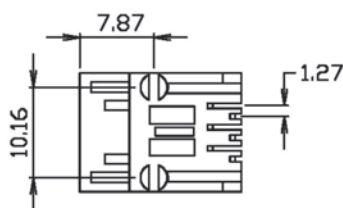
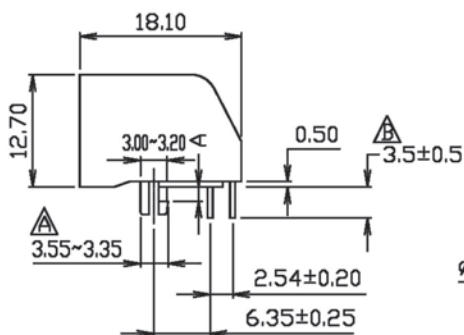
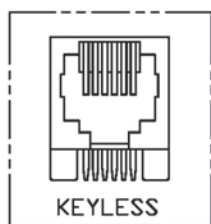
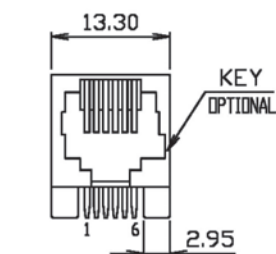
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{VC}{1}$ - $\frac{66}{2}$ x $\frac{B}{3}$ x $\frac{B}{4}$ x $\frac{B}{5}$

- MODULAR JACK TYPE:
"VC" FLANGELESS TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- KEY OPTION:
" " KEYLESS
"K" WITH KEY

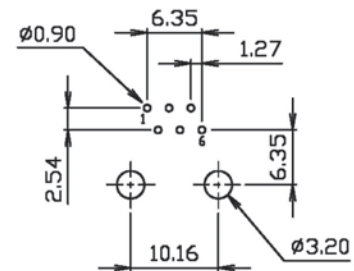
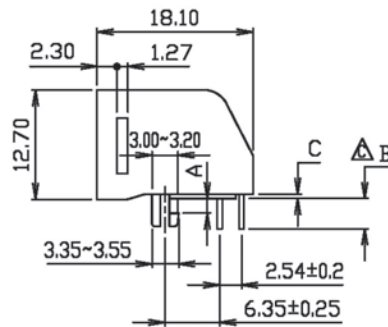
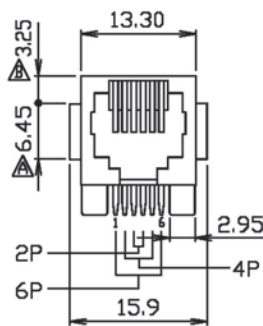
SIDE ENTRY MODULAR PCB JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

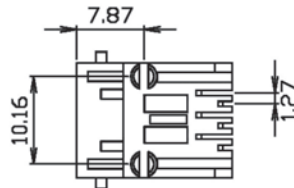
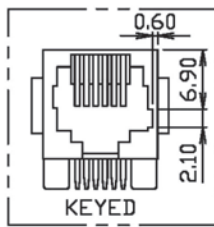
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout



ORDERING INFORMATION:

P/N M J $\frac{VD}{1}$ - $\frac{66}{2}$ x $\frac{B}{3}$ x $\frac{K}{45}$

- MODULAR JACK TYPE:
"VD" FLANGED TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- KEY OPTION:
" " WITHOUT KEY
"K" WITH KEY

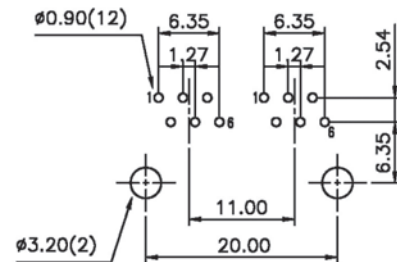
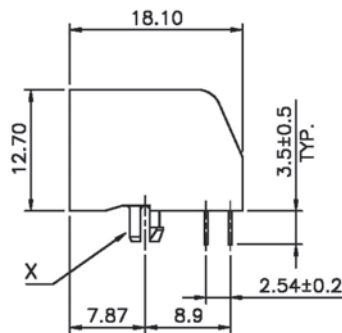
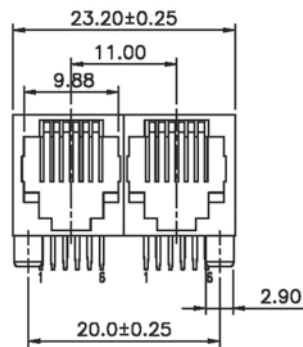
SIDE ENTRY 2-PORT MODULAR PCB JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

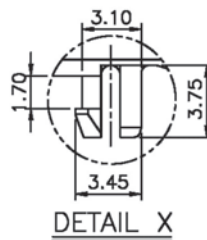
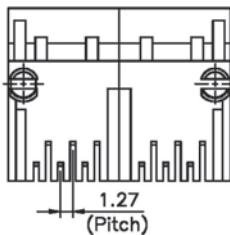
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout



ORDERING INFORMATION:

P/N M J $\frac{VC}{1}$ - $\frac{66}{2}$ x $\frac{B}{34}$ $\frac{02}{5}$

1. MODULAR JACK TYPE:
"VC" FLANGELESS TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK
5. NO. OF PORTS:
02

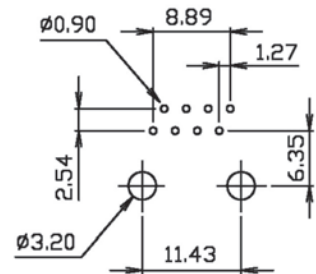
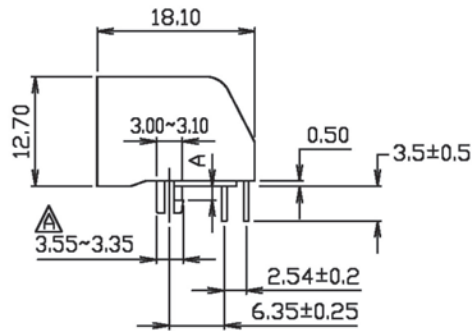
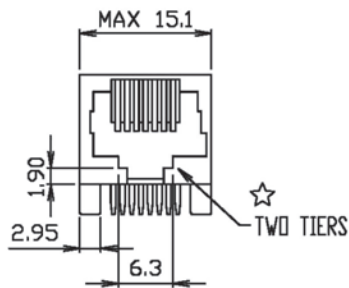
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

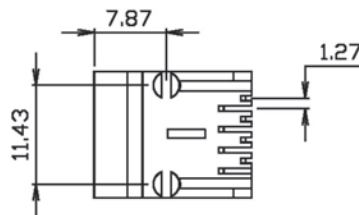
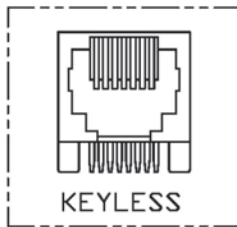
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout



ORDERING INFORMATION:

P/N M J $\frac{V E}{1}$ - $\frac{8 8}{2}$ x $\frac{B}{3}$ x $\frac{B}{4}$ x $\frac{B}{5}$

- MODULAR JACK TYPE:
"VE" FLANGELESS TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- KEY OPTION:
" " KEYLESS
"K" WITH KEY

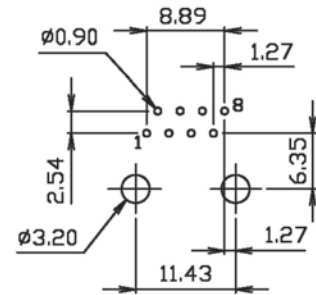
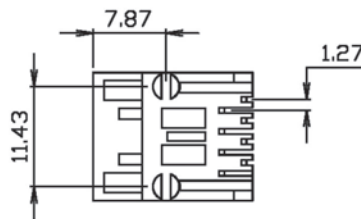
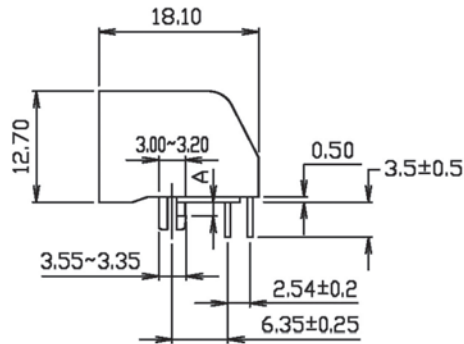
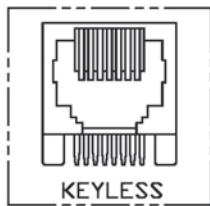
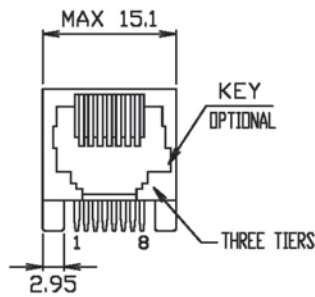
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{VC}{1}$ - $\frac{88}{2}$ x $\frac{B}{3}$ x $\frac{B}{4}$ x $\frac{x}{5}$

- | | |
|--|--|
| <p>1. MODULAR JACK TYPE:
"VC" FLANGELESS TYPE</p> <p>2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C</p> <p>3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD</p> <p>4. HOUSING COLOR:
"B" BLACK</p> | <p>5. KEY OPTION:
" " KEYLESS
"K" WITH KEY</p> |
|--|--|

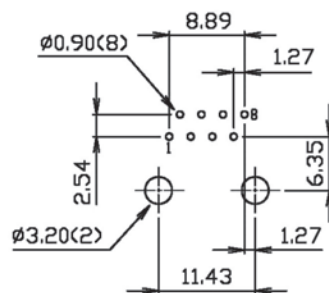
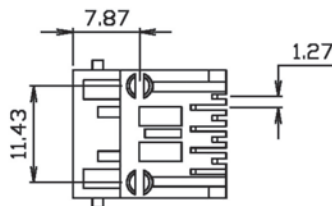
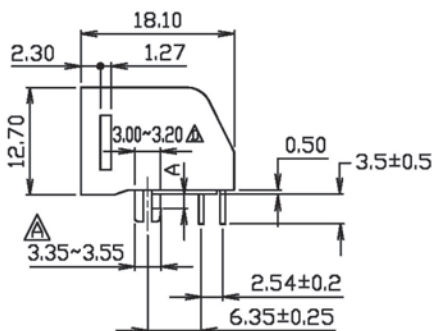
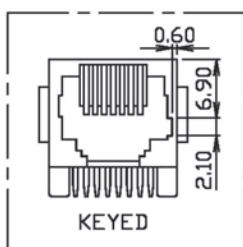
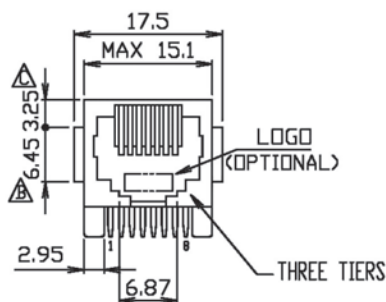
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J V D - 8 8 x B x 3 4 5

- MODULAR JACK TYPE:
"VD" FLANGED TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- KEY OPTION:
" " WITHOUT KEY
"K" WITH KEY

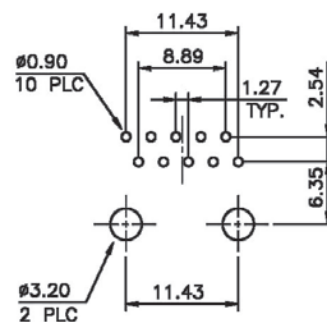
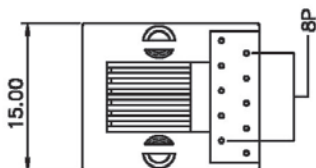
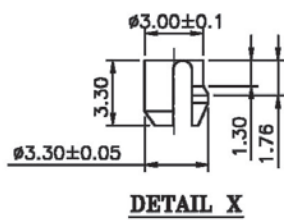
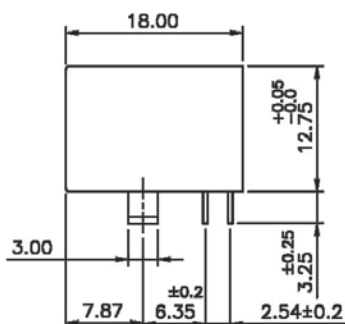
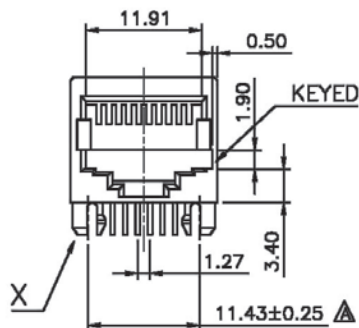
SIDE ENTRY MODULAR PCB JACK 10P WITH KEY PROFILE=12.75MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J Q Z - 8 8 x B K
 1 2 3 4 5

- MODULAR JACK TYPE:
"QZ" LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- KEY OPTION:
"K" KEYED

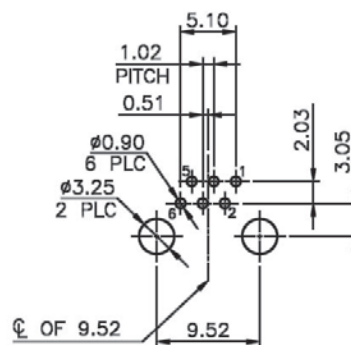
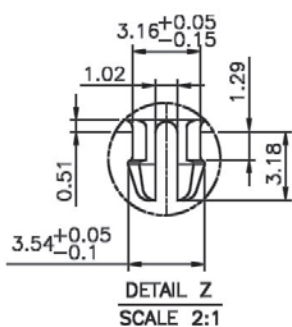
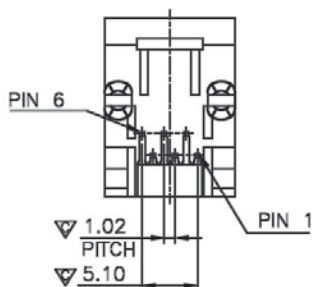
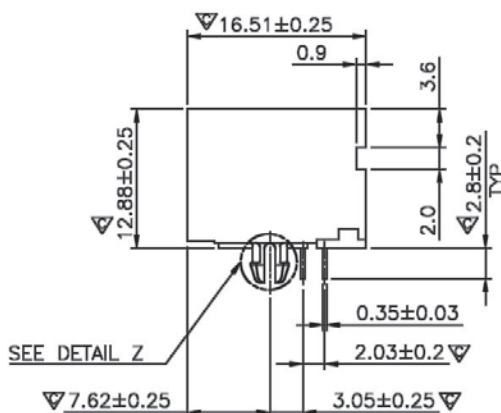
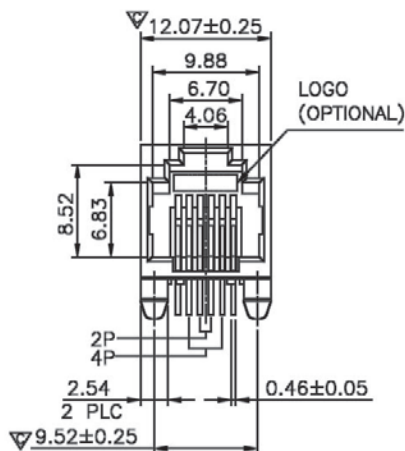
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=12.88MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
Recommended PCB Thickness: 1.6mm
(TOP VIEW)

ORDERING INFORMATION:

P/N M J $\frac{N}{1}$ V - $\frac{6}{2}$ $\frac{6}{3}$ x $\frac{B}{4}$

- MODULAR JACK TYPE:
"NV" LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

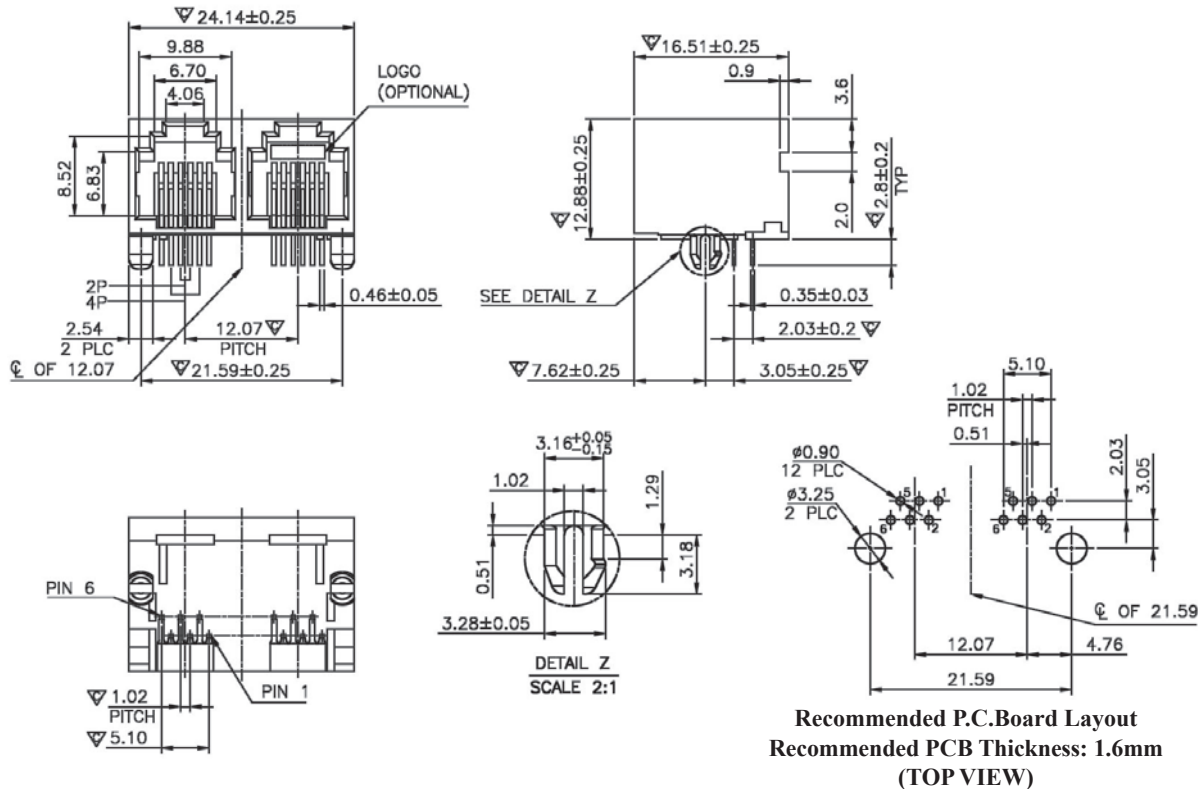
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=12.88MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N **M J N W - 6 6 x B 0 2**
1 2 3 4 5

- MODULAR JACK TYPE:
"NW" LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
02

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

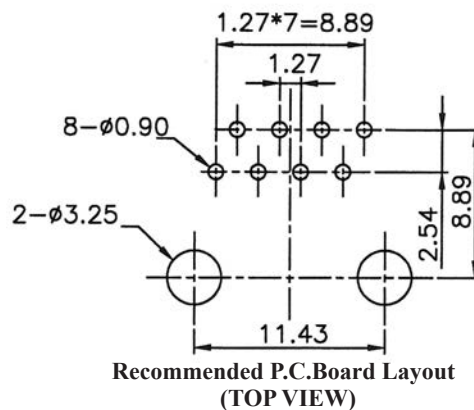
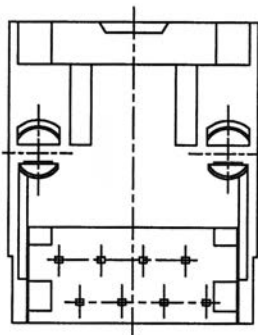
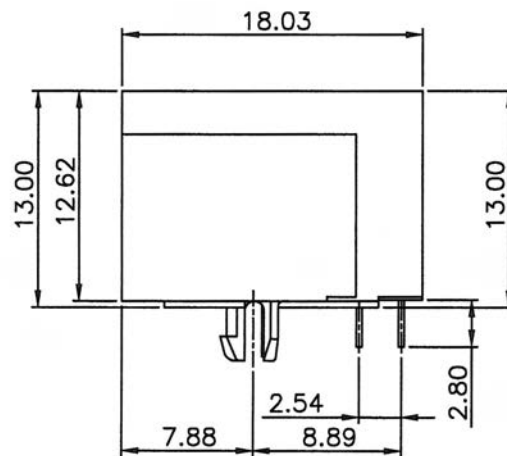
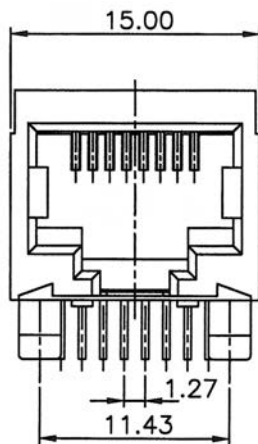
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 W - $\frac{x}{1} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

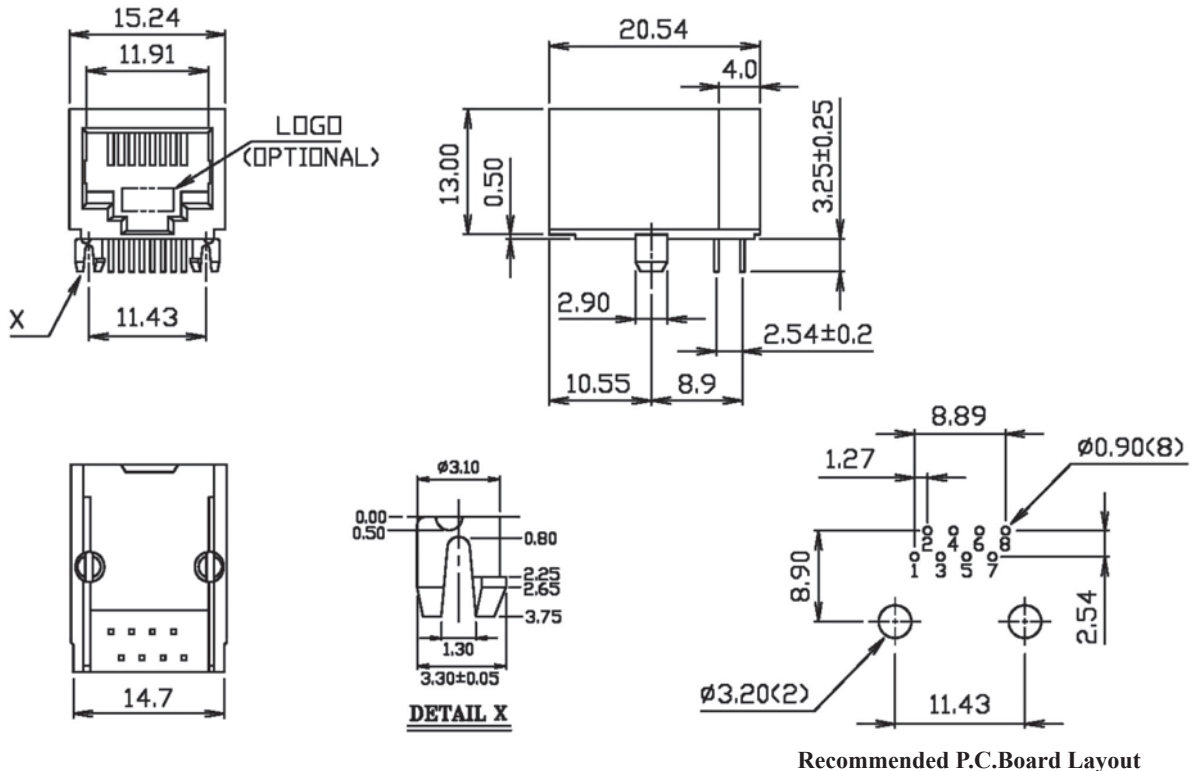
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J Q R - 8 8 x B
1 2 3 4

- MODULAR JACK TYPE:
"QR" 13.00MM x 20.54MM TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

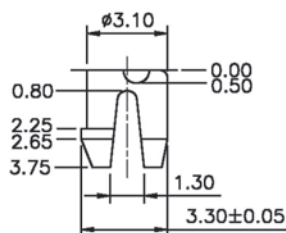
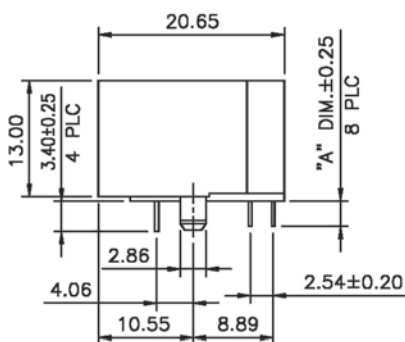
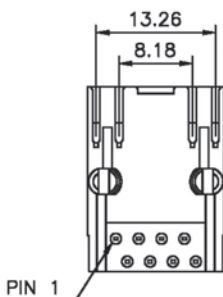
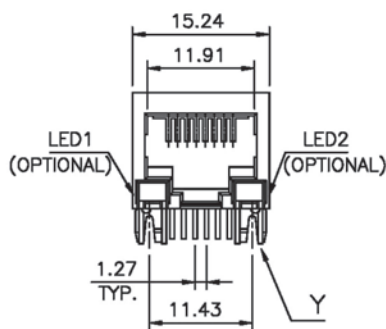
SIDE ENTRY MODULAR PCB JACK 8P WITH LED PROFILE=13.00MM (UNSHIELDED)

SPECIFICATIONS

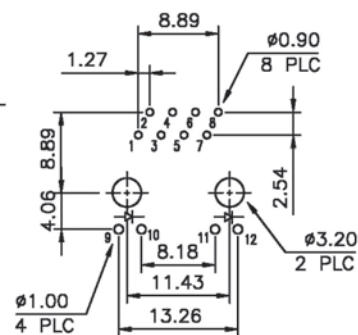
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



DETAIL Y



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J Q S - 8 8 x B x X
 1 2 3 4 5

- MODULAR JACK TYPE:
"QS" H=13.00MM WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED 1/2: GREEN/GREEN
"NY" LED 1/2: GREEN/YELLOW
"YN" LED 1/2: YELLOW/GREEN
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

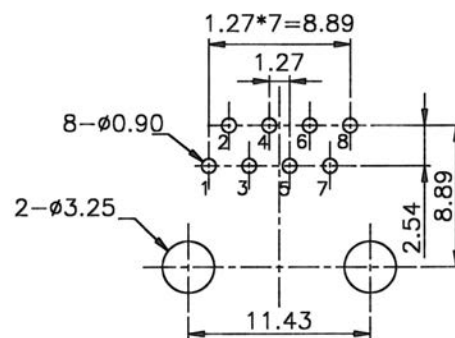
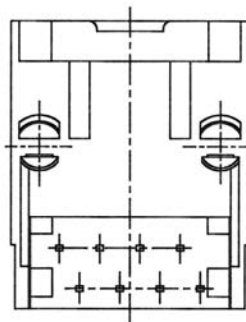
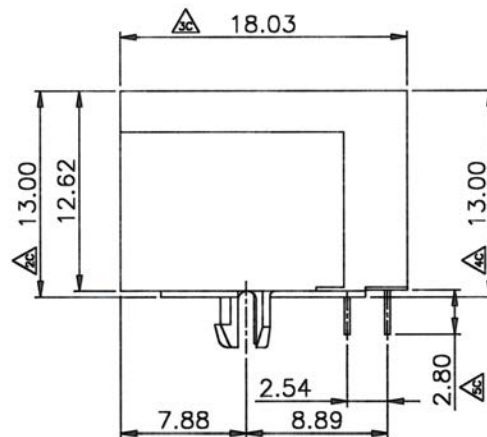
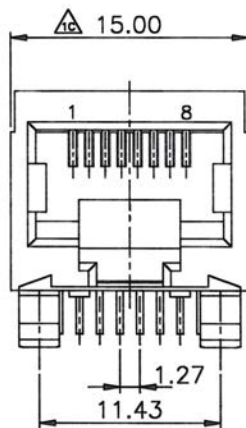
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500M Ω Min.
Contact Resistance: 20m Ω Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40 $^{\circ}$ C / +85 $^{\circ}$ C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235 $^{\circ}$ C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J Y G - 88 x B
I 2 3 4

1. MODULAR JACK TYPE:
"YG" SIDE ENTRY RJ45 JACK
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

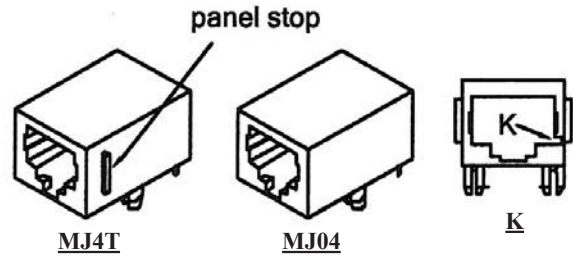
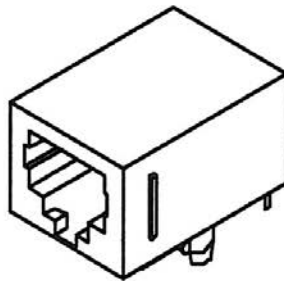
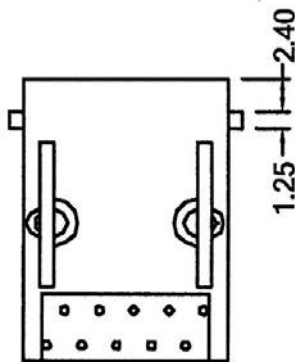
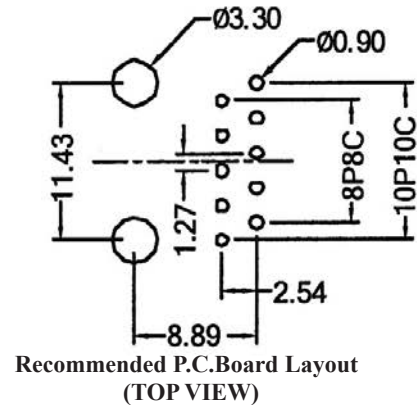
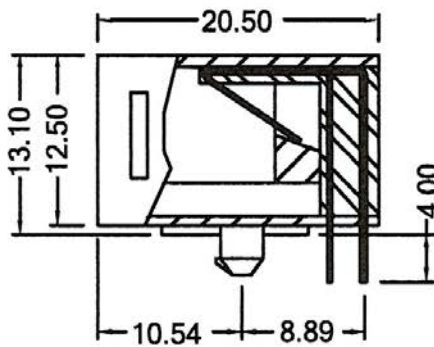
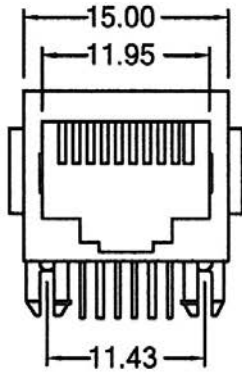
SIDE ENTRY MODULAR PCB JACK 8P+10P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - $\frac{xxx}{2}$ $\frac{x}{3}$ B $\frac{x}{4}$

- PANEL STOP OPTION:
 "4T" WITH PANEL STOP
 "04" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

- KEYWAY OPTION:
 " " W/O KEYWAY
 "K" WITH KEYWAY

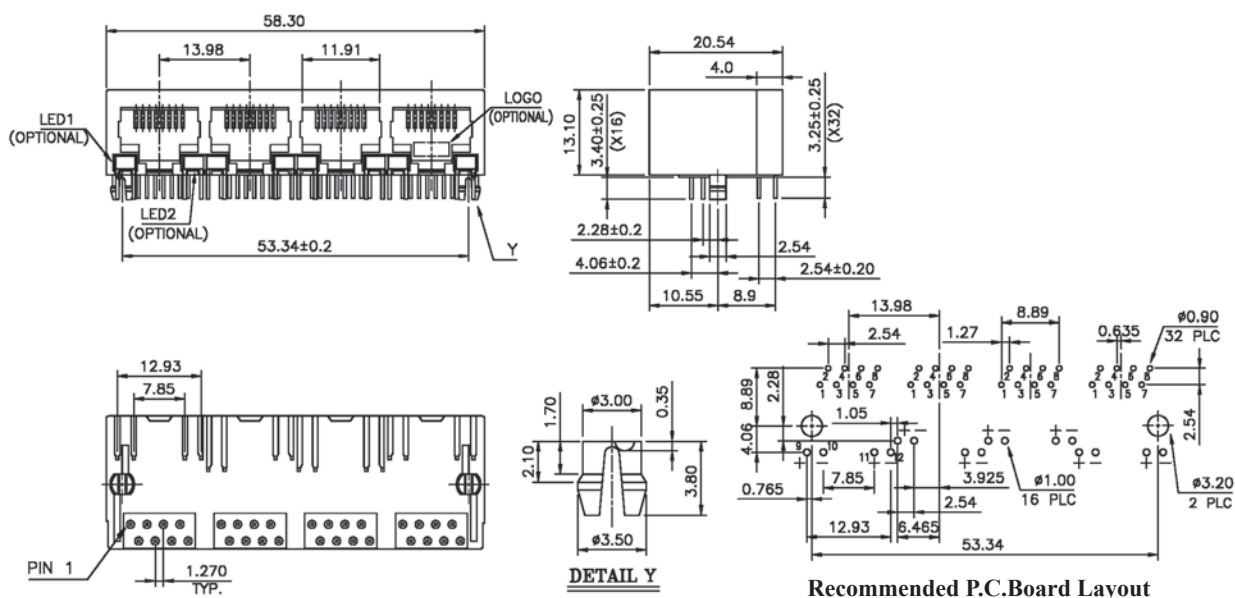
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P WITH LED PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J Q U - 8 8 x B x x 0 4
 1 2 3 4 5 6

- MODULAR JACK TYPE:
"QU" RJ45 JACK WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED 1/2: GREEN/GREEN
"NY" LED 1/2: GREEN/YELLOW
"YN" LED 1/2: YELLOW/GREEN
- NO. OF PORTS:
04

NOTE: OTHER LED COLORS UPON REQUEST!

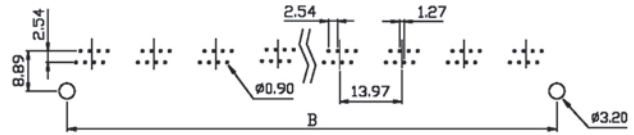
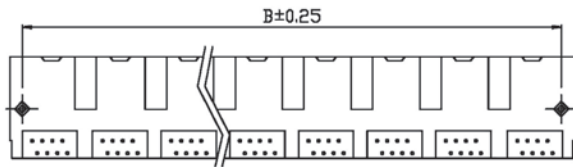
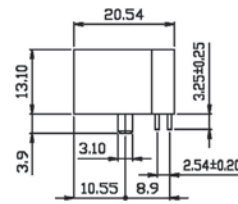
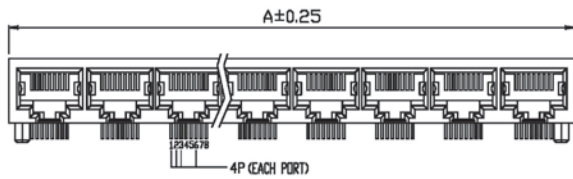
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

PORTS DIM	2	3	4	5	6	7	8	9	10	11	12
A	30.48	44.45	58.30	72.39	86.36	100.33	114.30	128.27	142.24	156.21	170.18
B	25.40	39.37	53.34	67.31	81.28	95.25	109.22	123.19	137.16	151.13	165.10

ORDERING INFORMATION:

P/N M J Q W - 8 8 x B x X
 1 2 3 4 5

1. MODULAR JACK TYPE:

"QW" DIP LENGTH = 3.25MM

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

4. HOUSING COLOR:

"B" BLACK

5. NO. OF PORTS:

02, 03, 04, 05, 06, 07,

08, 09, 10, 11, 12

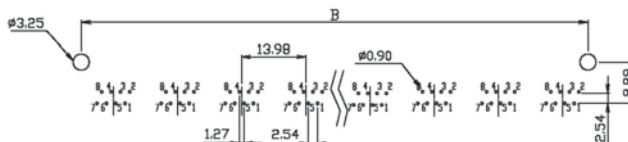
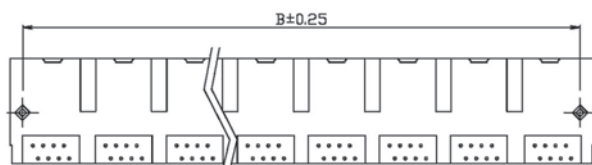
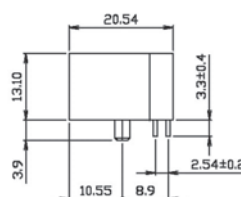
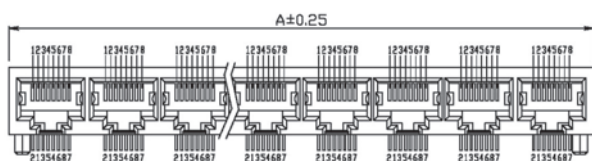
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

PORTS DIM	2	3	4	5	6	7	8	9	10	11	12
A	30.48	44.45	58.30	72.39	86.36	100.33	114.30	128.27	142.24	156.21	170.18
B	25.40	39.37	53.34	67.31	81.28	95.25	109.22	123.19	137.16	151.13	165.10

ORDERING INFORMATION:

P/N M J Q X - 8 8 x B x X
 I 2 3 4 5

- MODULAR JACK TYPE:
"QX" DIP = 3.3MM WITH PIN#21354687
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
02, 03, 04, 05, 06, 07,
08, 09, 10, 11, 12

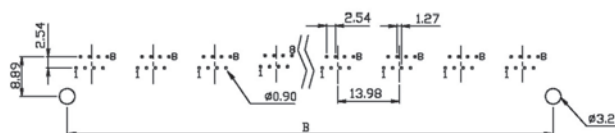
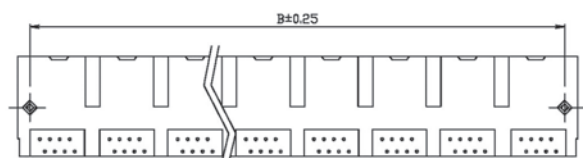
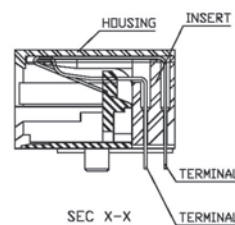
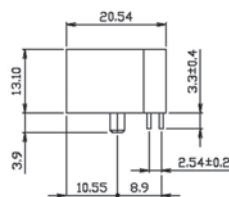
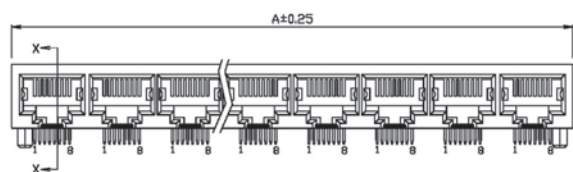
SIDE ENTRY MULTI-PORT CAT.5 MODULAR PCB JACK 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

PORTS DIM	2	3	4	5	6	7	8	9	10	11	12
A	30.48	44.45	58.30	72.39	86.36	100.33	114.30	128.27	142.24	156.21	170.18
B	25.40	39.37	53.34	67.31	81.28	95.25	109.22	123.19	137.16	151.13	165.10

ORDERING INFORMATION:

P/N M J Q V - 8 8 x B x x

 1 2 3 4 5

- MODULAR JACK TYPE:
"QV" CAT.5 GANGED JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- NO. OF PORTS:
02, 03, 04, 05, 06, 07,
08, 09, 10, 11, 12

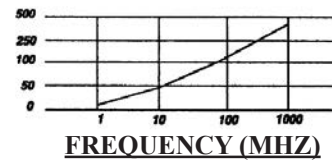
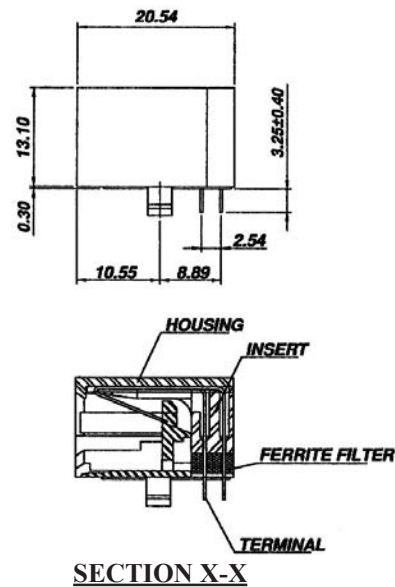
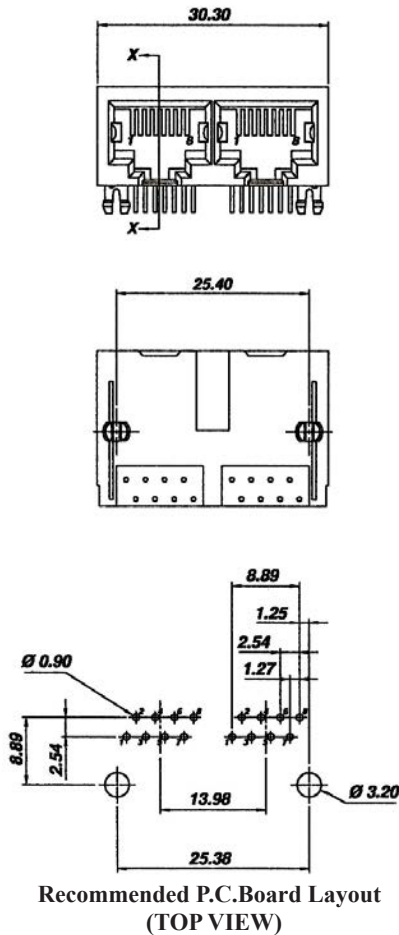
SIDE ENTRY 2-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 8 F - $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
02

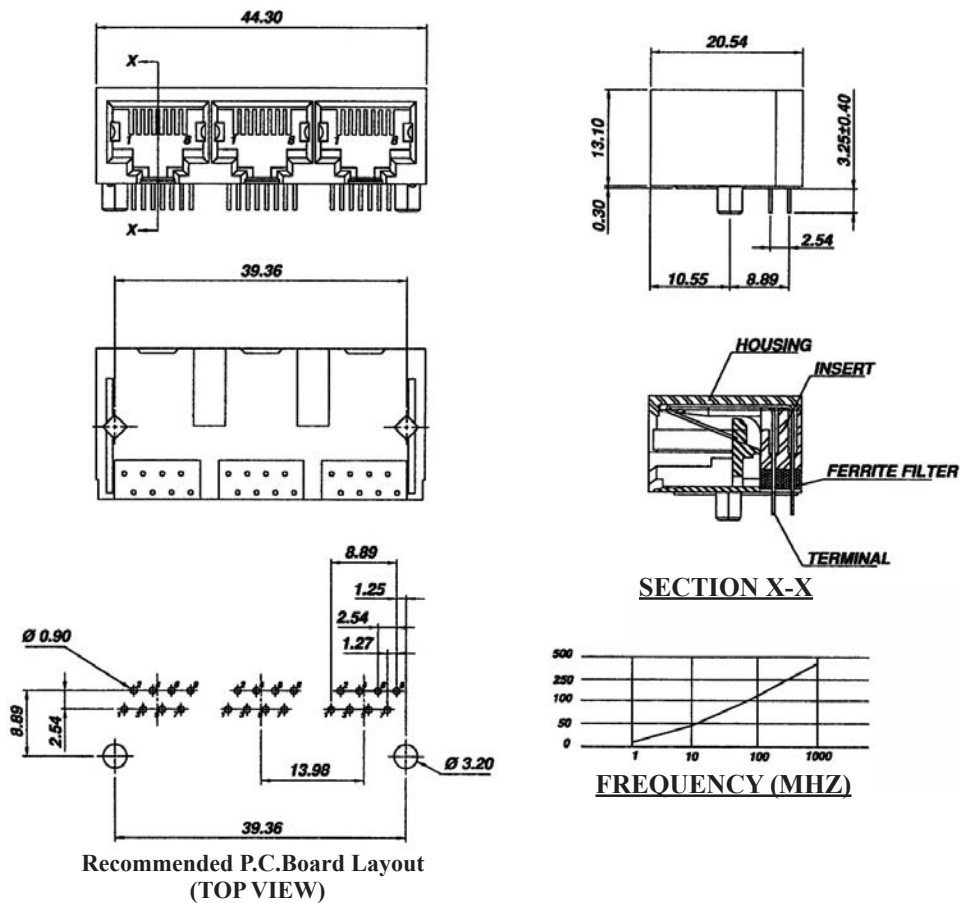
SIDE ENTRY 3-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ8F - $\frac{88}{1} \times \frac{B}{2} \frac{03}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
03

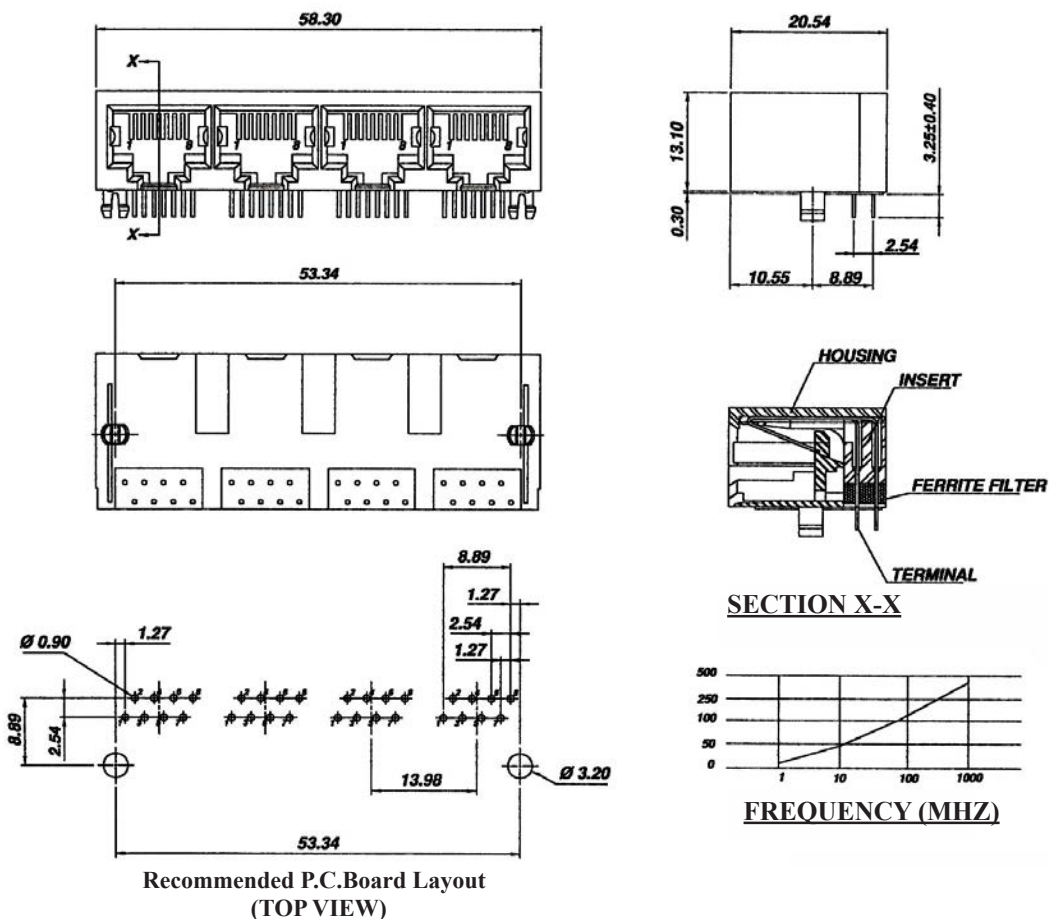
SIDE ENTRY 4-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ8F - $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
04

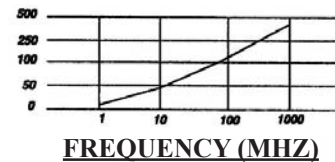
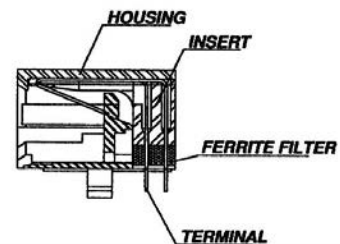
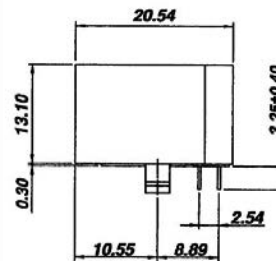
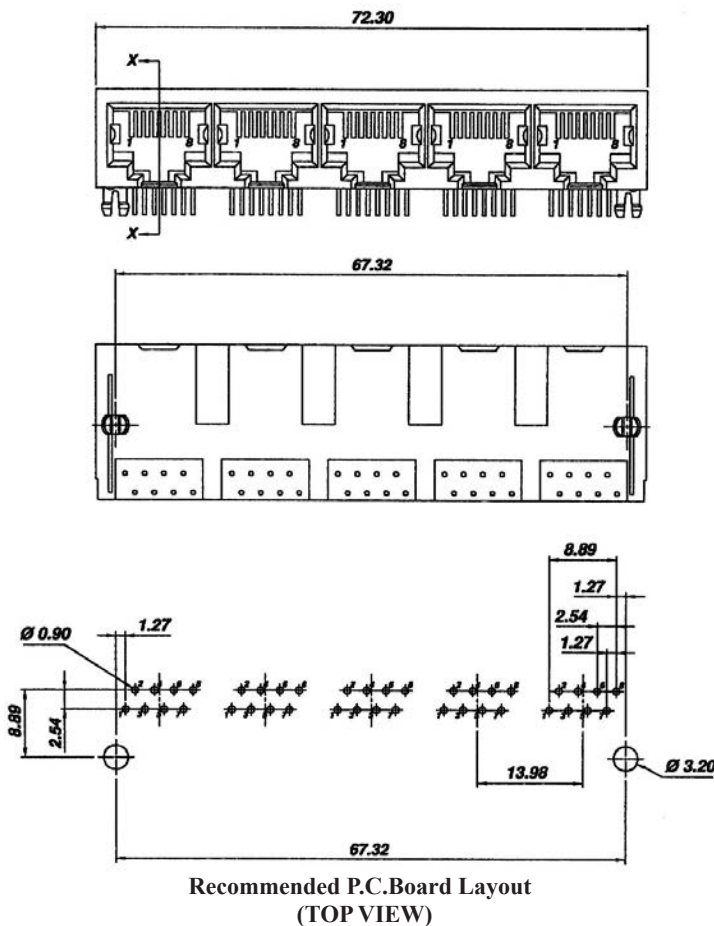
SIDE ENTRY 5-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 8 F - $\frac{88}{1} \times \frac{B}{2} \frac{05}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
05

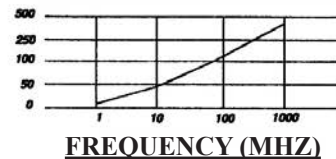
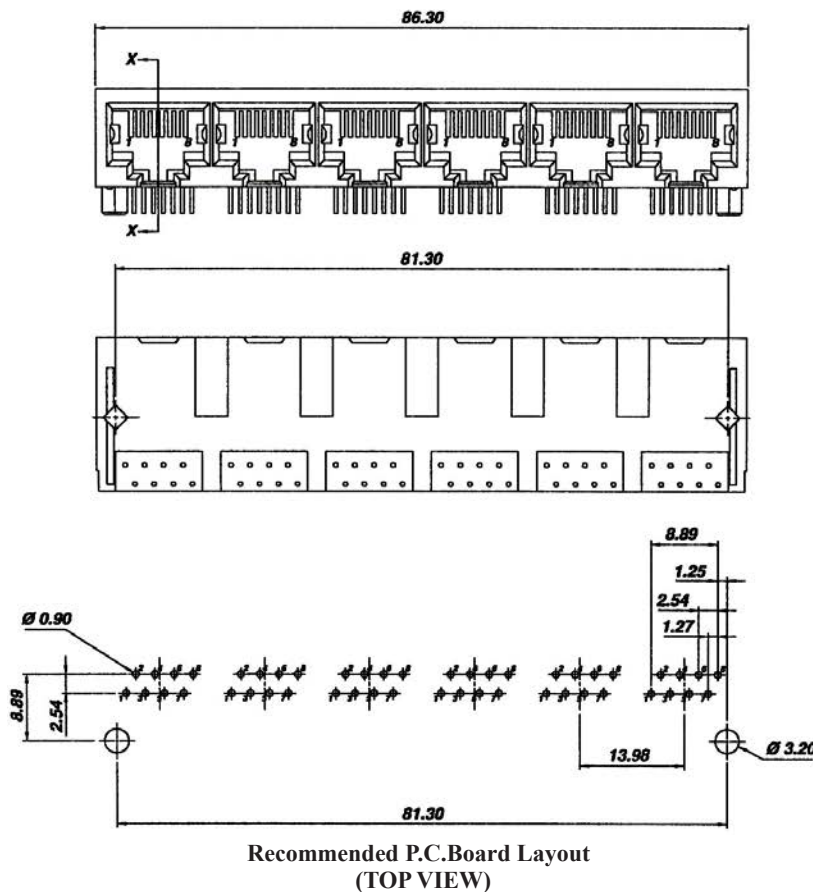
SIDE ENTRY 6-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ8F - $\frac{88}{1} \times \frac{B}{2} \frac{06}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
06

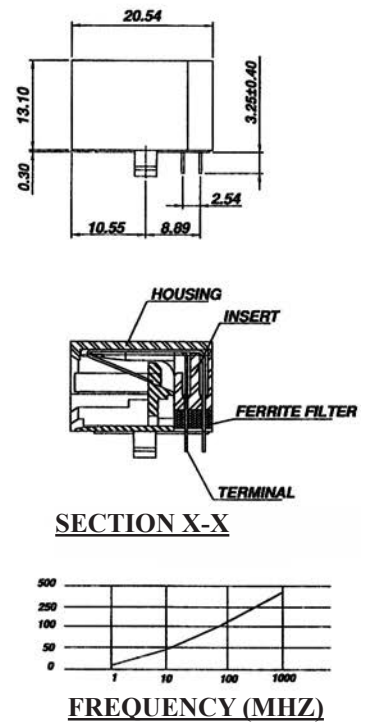
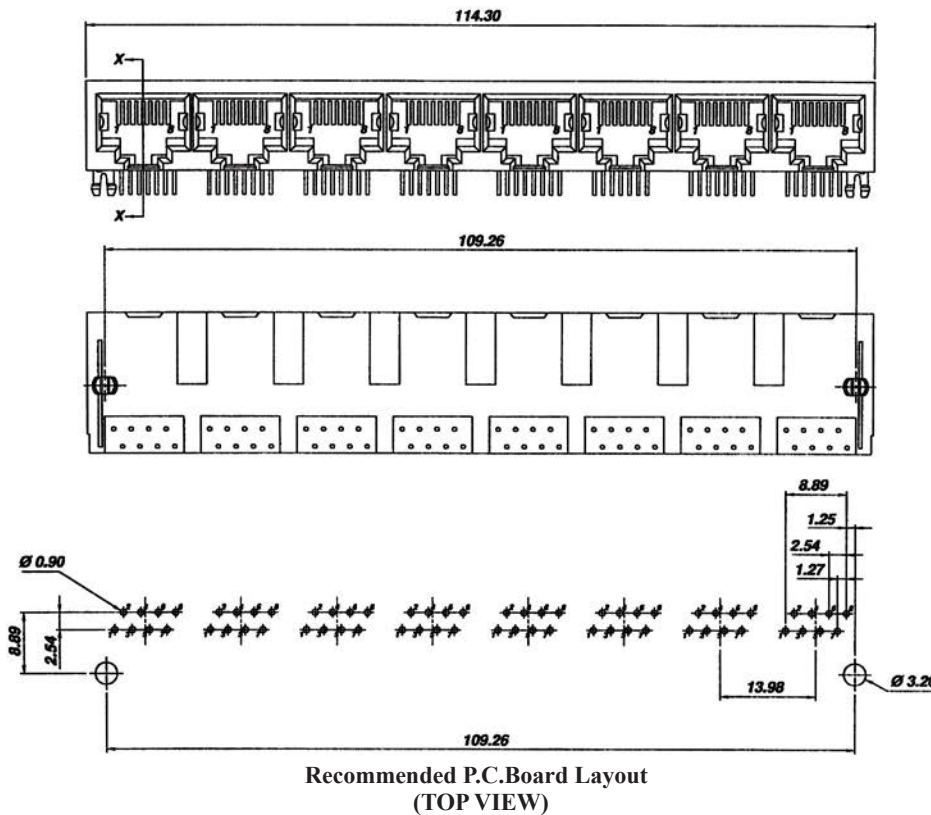
SIDE ENTRY 8-PORT MODULAR PCB JACK WITH FERRITE 8P PROFILE=13.10MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ8F - $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
08

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.15MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

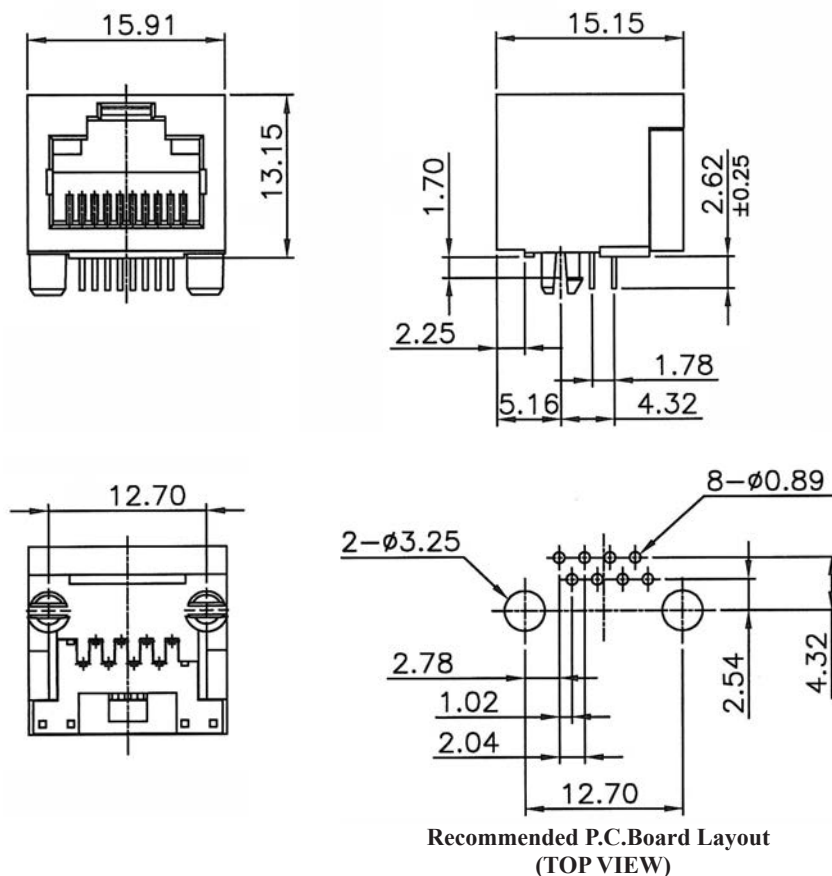
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 X - $\frac{x x x}{1 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

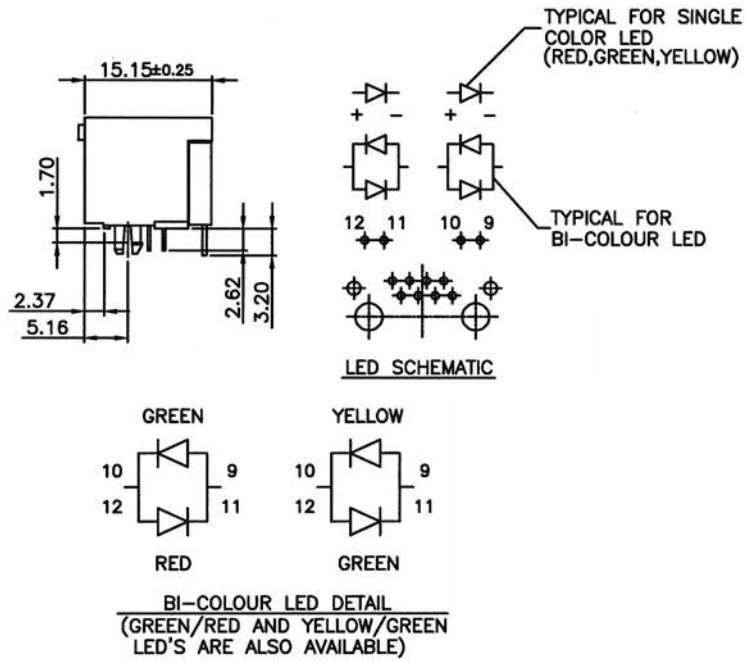
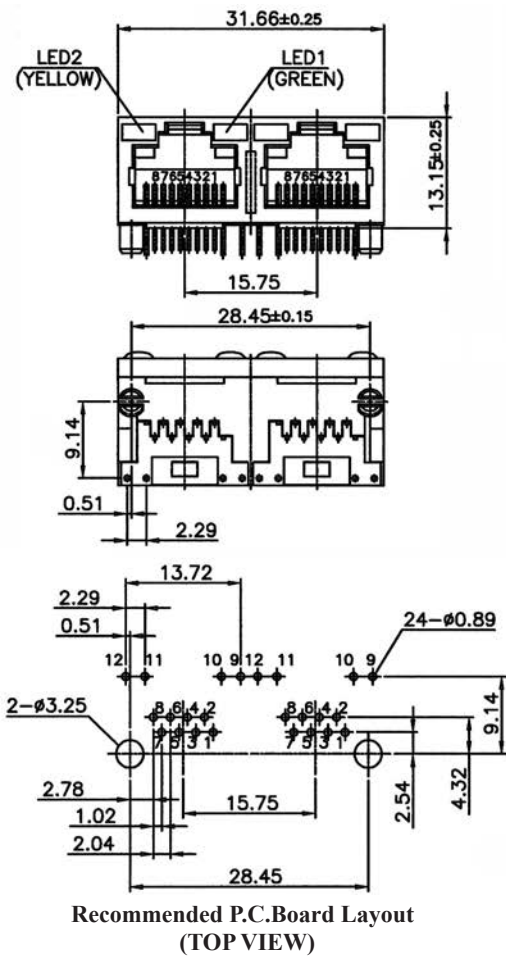
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.15MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 R - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} \frac{x}{5} B \frac{x}{3} \frac{x}{4} \frac{x}{5} 02$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
02

LED Designation:					
Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

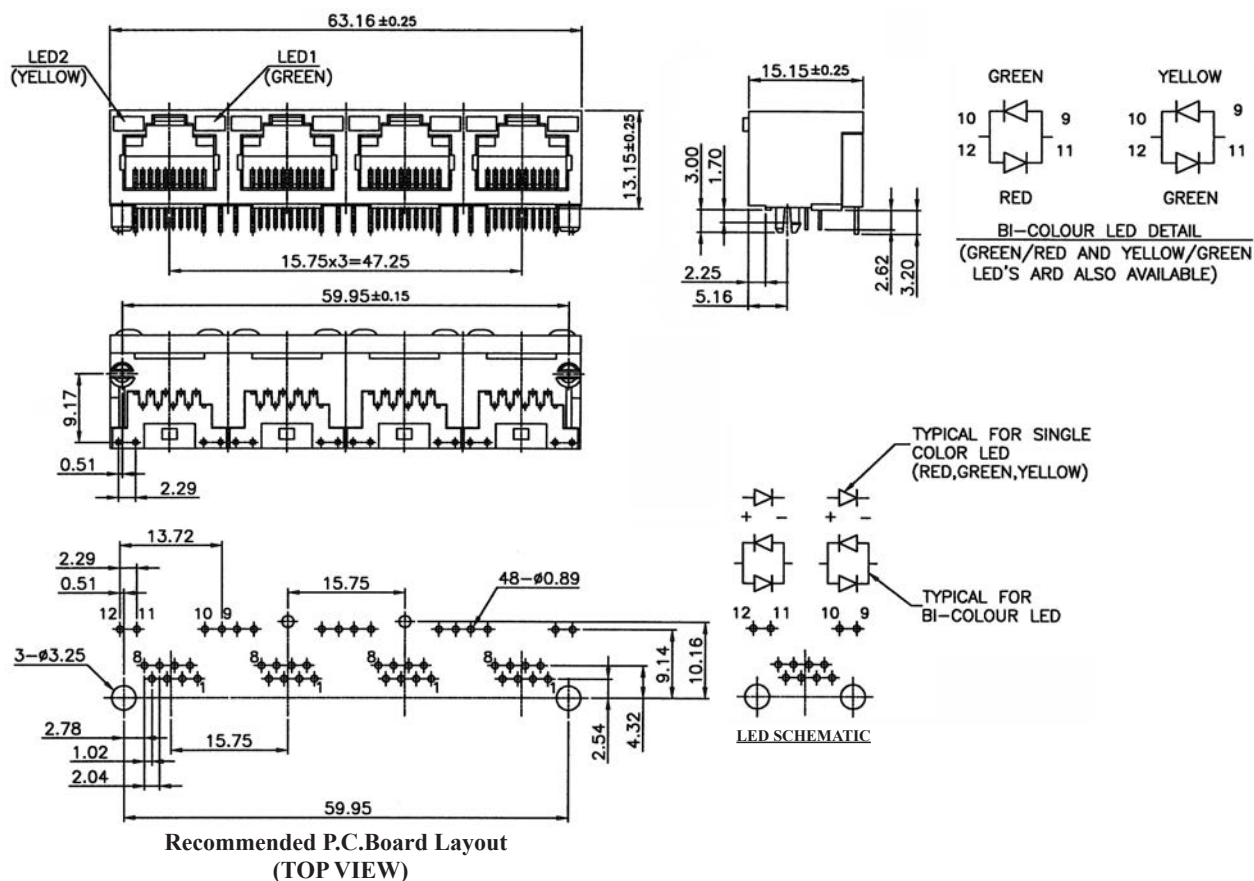
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.15MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 2 R - $\frac{x}{1} \frac{x}{2} \frac{B}{3} \frac{x}{4} \frac{x}{5} 04$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
04

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

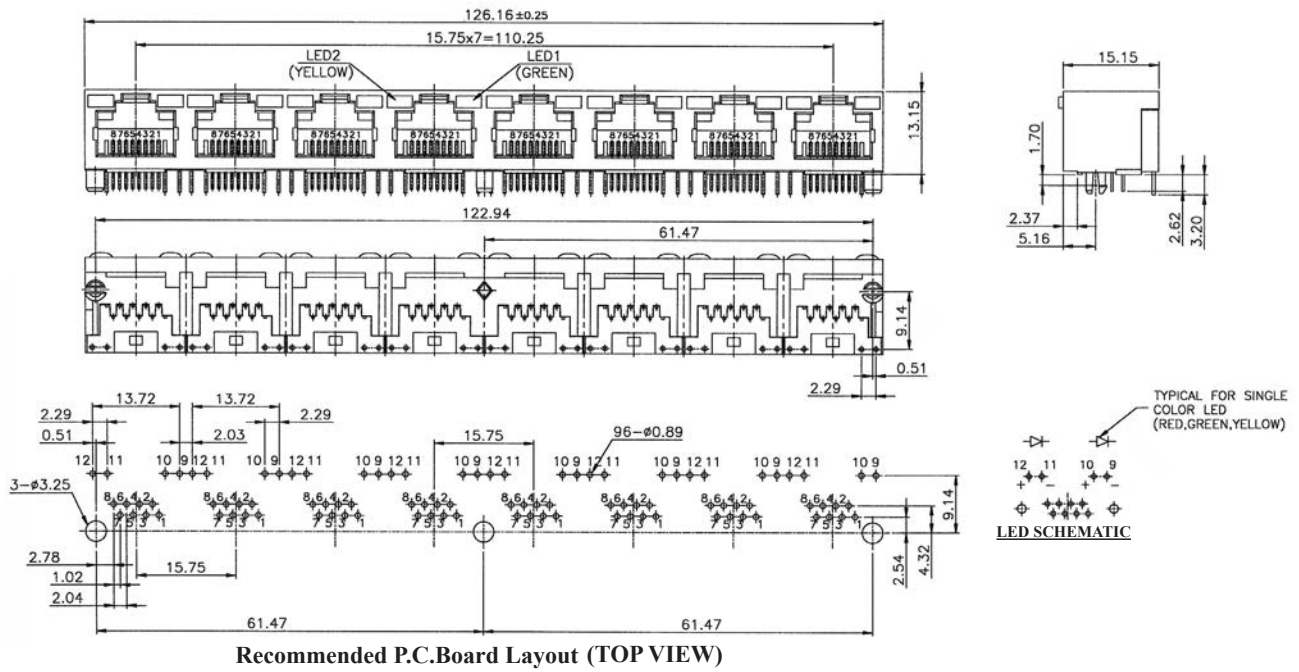
SIDE ENTRY 8-PORT UP LATCH MODULAR PCB JACK WITH LED 8P PROFILE=13.15MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 R - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} \frac{x}{5} B x x 0 8$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. CODE OF LED1 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
4. CODE OF LED2 DESIGNATION:
N, M, Y, Z, 8, Q, 1, 2, 5, 6
5. NO. OF PORTS:
08

LED Designation:

Code	+/-	-/+	Code	+/-	-/+
N	Green	—	M	—	Green
Y	Yellow	—	Z	—	Yellow
8	Orange	—	Q	—	Orange
1	Green	Orange	2	Orange	Green
5	Green	Yellow	6	Yellow	Green

NOTE: LED 1 = RIGHT LED &
LED 2 = LEFT LED

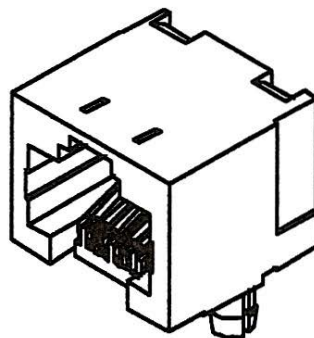
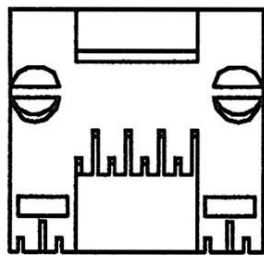
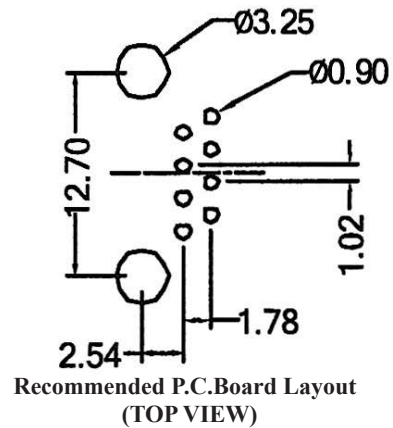
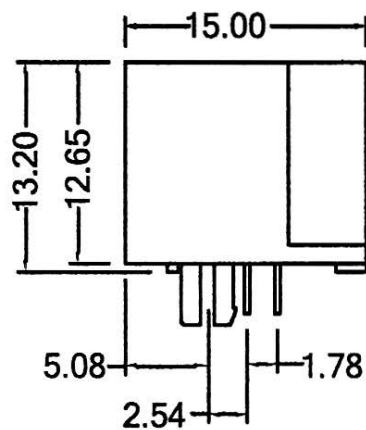
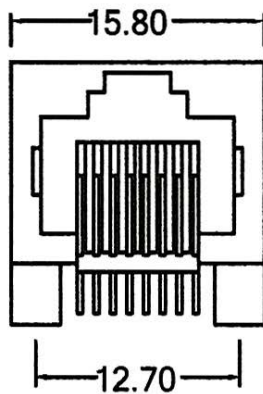
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.20MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J R 3 - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 4P PROFILE=13.20MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

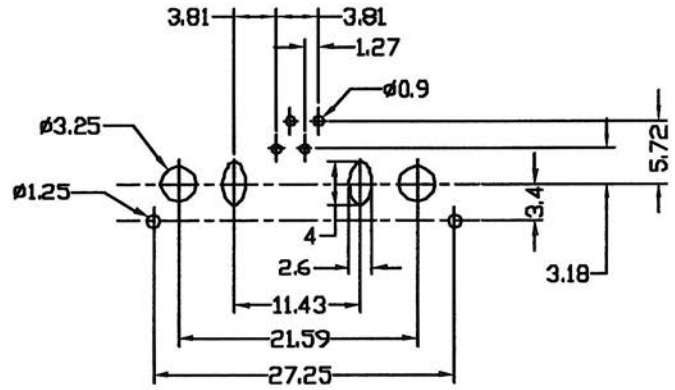
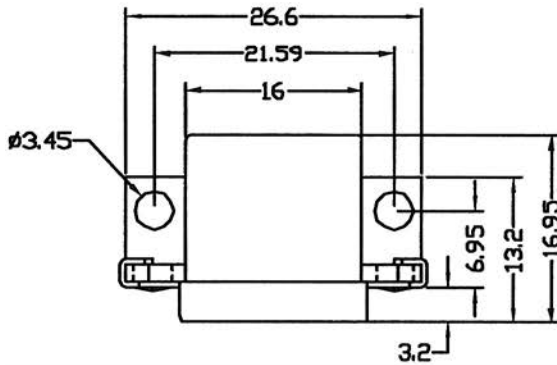
Soldering Temperature: 235°C

Color: Black

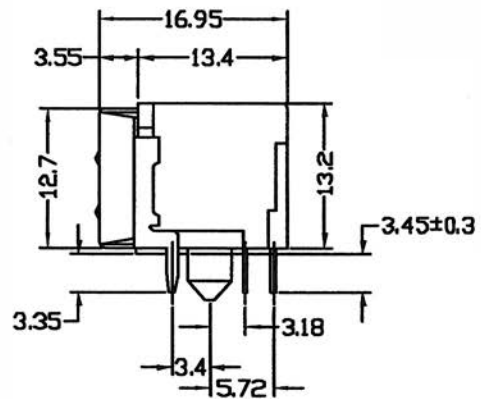
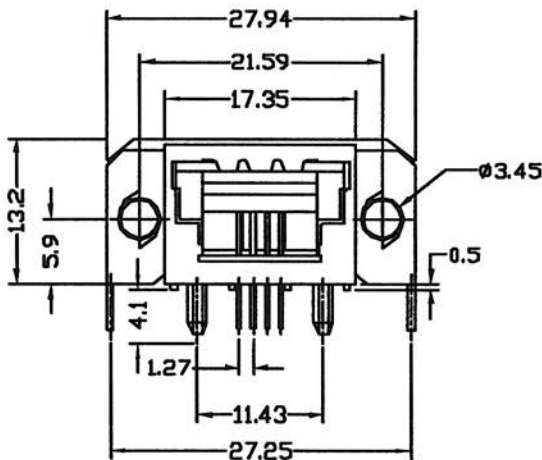
Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJ 4 1 - $\frac{44}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

NOTE: MATES WITH MODULAR PLUGS

P/N MP4S-44FxxA & P/N MP4M-44FxxA

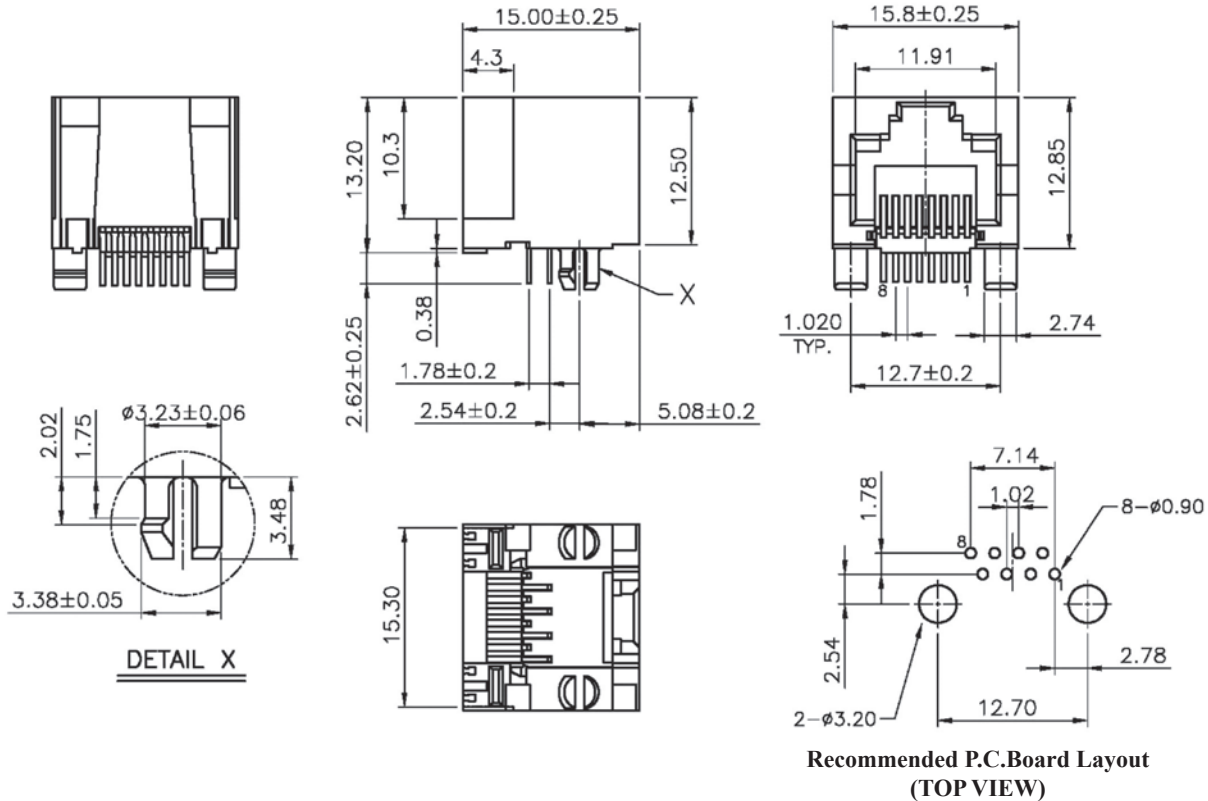
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=13.20MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N **M J G V - 8 8 x B**
1 2 3 4

- MODULAR JACK TYPE:
"GV" WITH LONG PEGS & LONG CONTACT TAILS
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

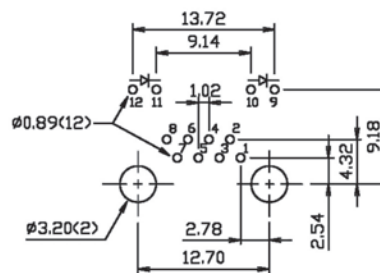
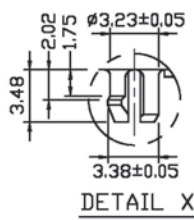
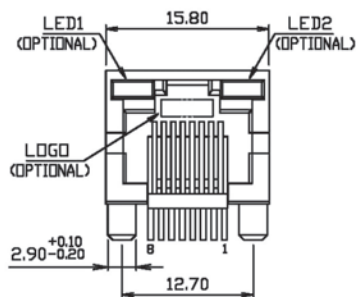
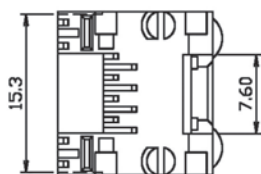
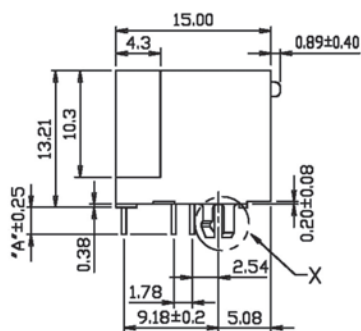
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.20MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J V R - 8 8 X B X X
 1 2 3 4 5

- MODULAR JACK TYPE:
"VR" RJ45 JACK
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED1: GREEN & LED2: GREEN
"NY" LED1: GREEN & LED2: YELLOW
"YN" LED1: YELLOW & LED2: GREEN

NOTE: OTHER LED COLORS UPON REQUEST!

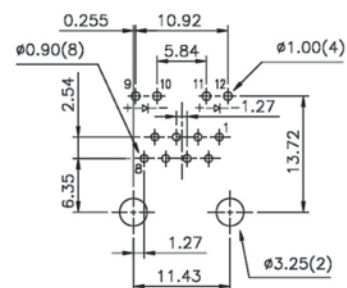
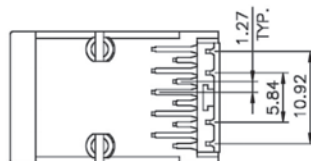
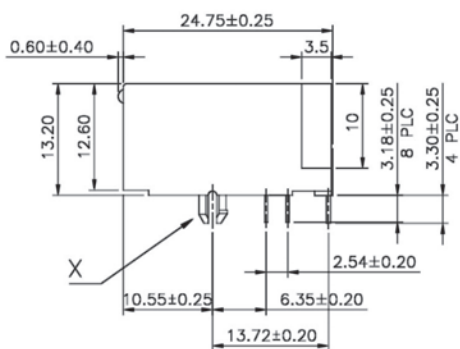
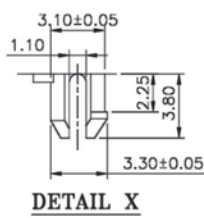
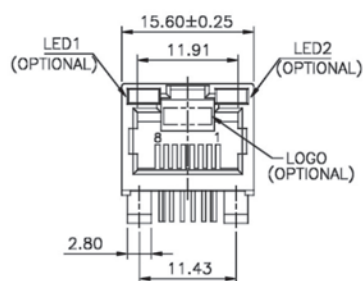
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P WITH LED PROFILE=13.20MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J Q Y - 8 8 x B x x
 1 2 3 4 5

- MODULAR JACK TYPE:
"QY" 13.20MM x 24.75MM TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK

- COLORS OF LED:
"NN" LED 1/2: GREEN/GREEN
"NY" LED 1/2: GREEN/YELLOW
"YN" LED 1/2: YELLOW/GREEN
"XX" WITHOUT LED

NOTE: OTHER LED COLORS UPON REQUEST!

SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

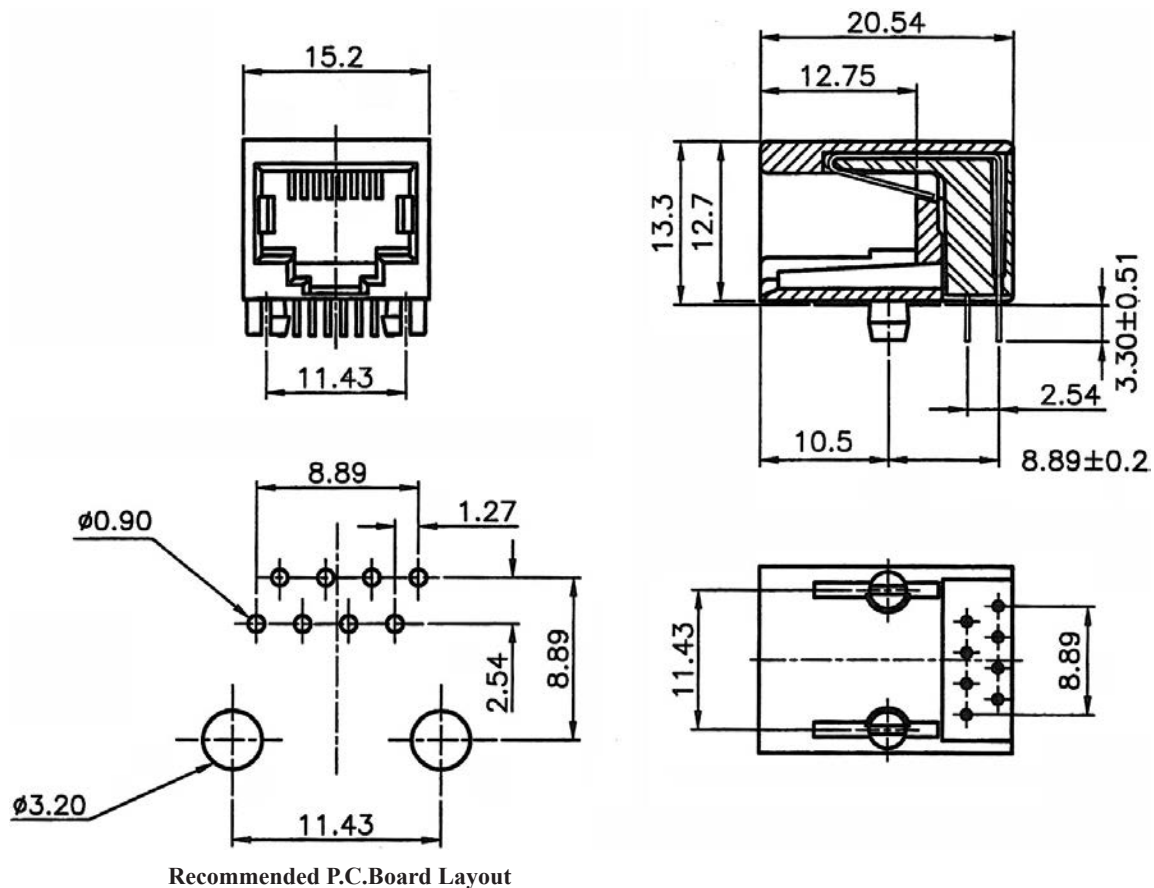
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XXX}{2}$ $\frac{X}{3}$ B

1. TYPE OF CONTACTS:

"39" 0.46MM ROUND PINS

"04" 0.35MM STAMPED PINS

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

SIDE ENTRY MODULAR PCB JACK 10P PROFILE=13.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

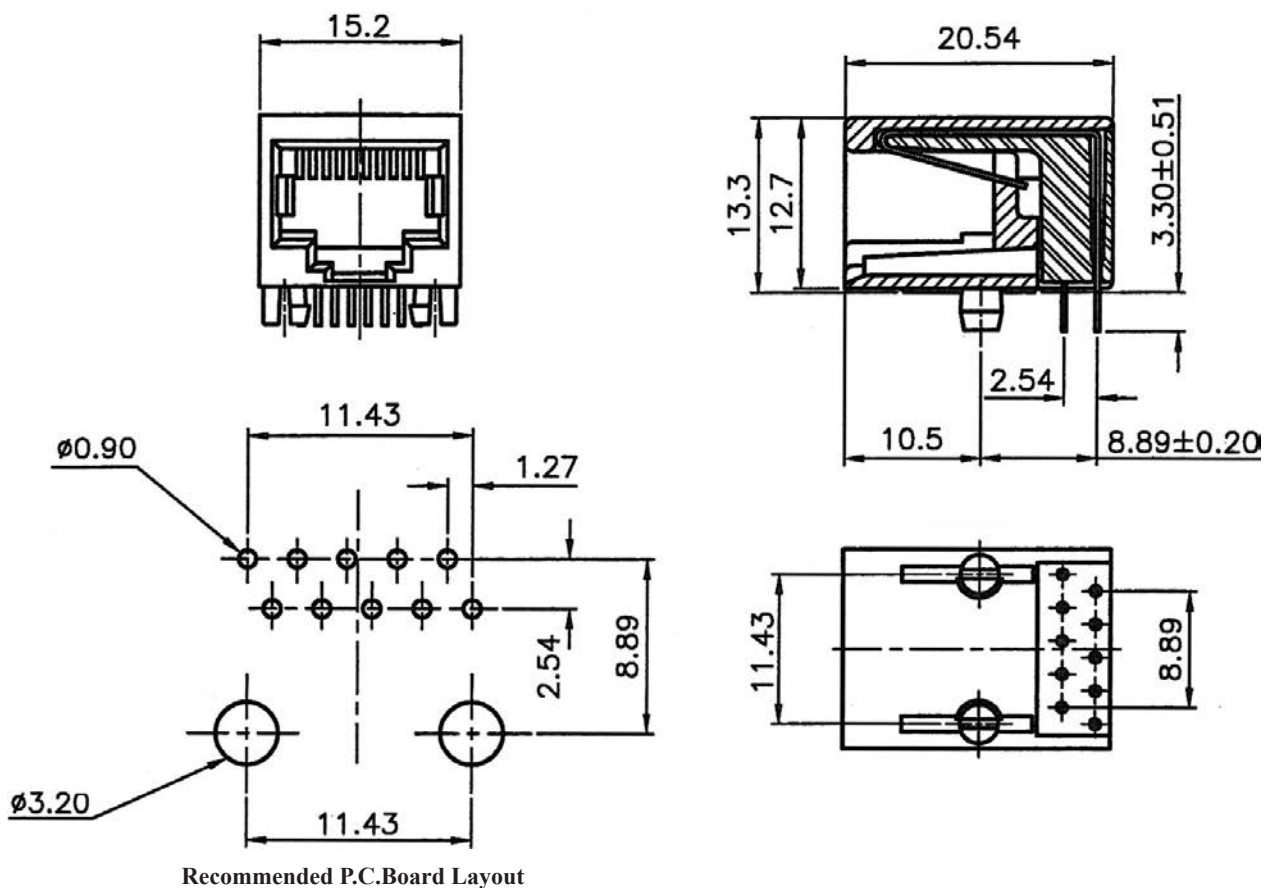
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B

1. TYPE OF CONTACTS:
 "39" 0.46MM ROUND PINS
 "04" 0.35MM STAMPED PINS
2. NO. OF POSITIONS & CONTACTS:
 "00" 10P10C
 "08" 10P8C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

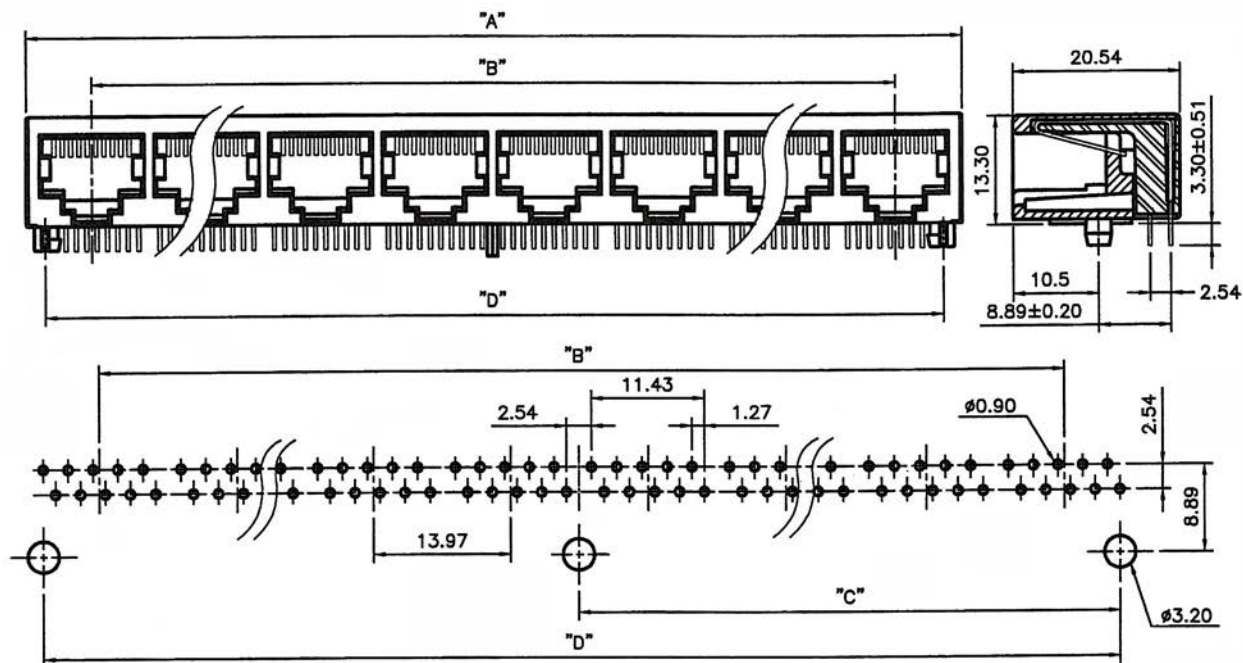
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 10P PROFILE=13.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

No. of Ports	DIM "A" ± 0.25	DIM "B" ± 0.20	DIM "C" ± 0.10	DIM "D" ± 0.15
02	30.48	13.97	-	25.40
04	58.42	41.91	-	53.34
06	86.36	69.85	-	81.28
08	114.30	97.79	54.61	109.22
10	142.24	125.73	68.58	137.16

ORDERING INFORMATION:

P/N MJ6Y - $\frac{xx}{1} \frac{xx}{2} \frac{B}{3} \frac{xx}{3}$

- NO. OF POSITIONS & CONTACTS:
 "00" 10P10C
 "08" 10P8C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 02, 04, 06, 08, 10

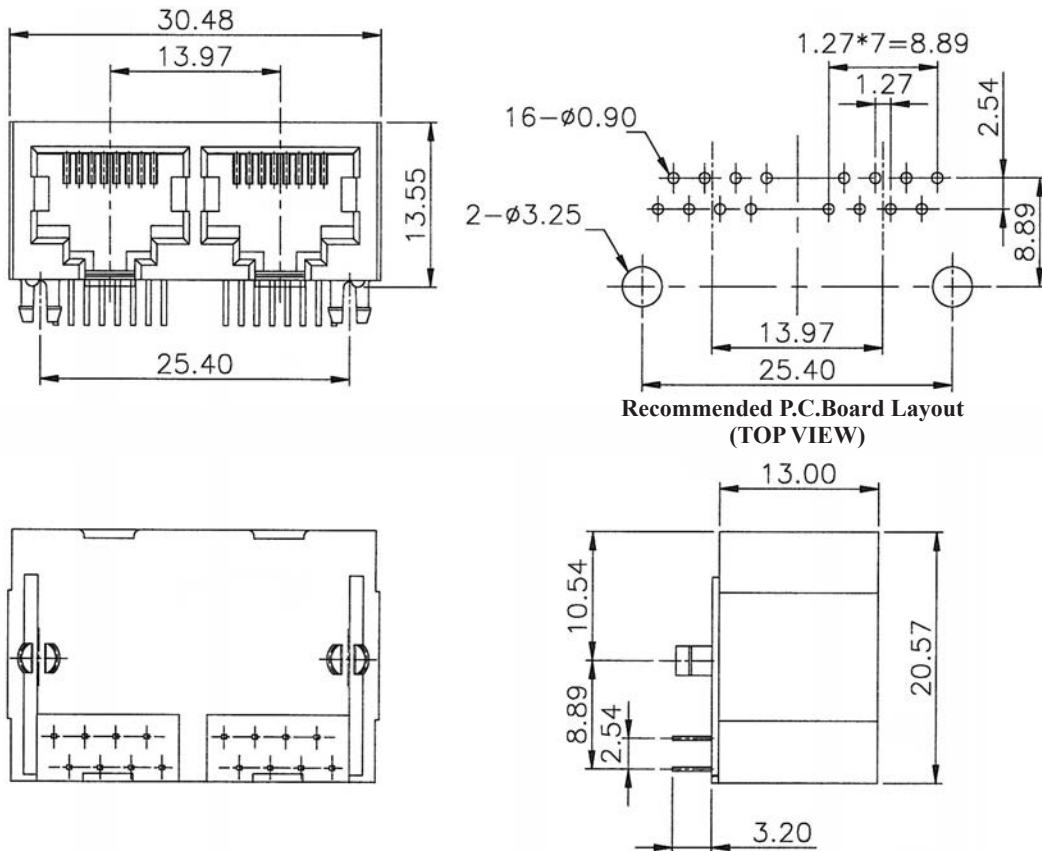
SIDE ENTRY 2-PORT MODULAR PCB JACK 8P PROFILE=13.55MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 3 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 2$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
02

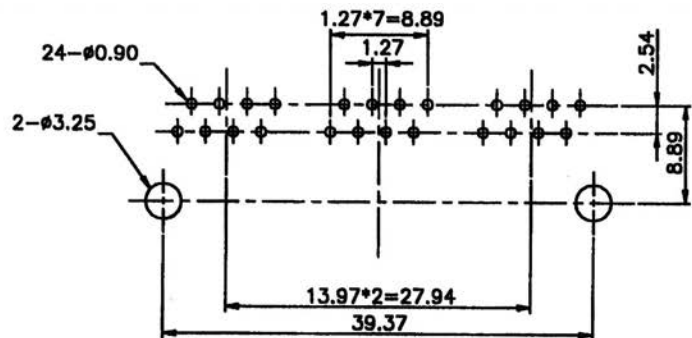
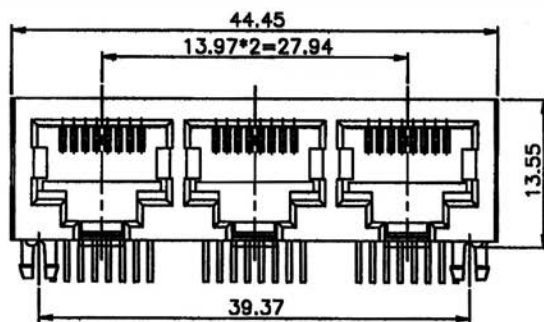
SIDE ENTRY 3-PORT MODULAR PCB JACK 8P PROFILE=13.55MM (UNSHIELDED)

SPECIFICATIONS

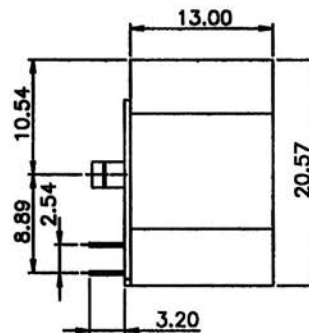
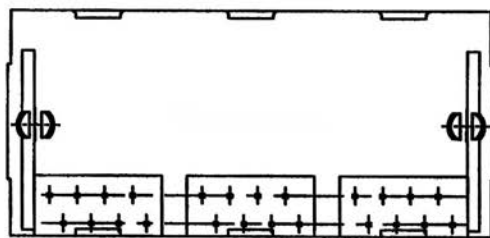
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout (TOP VIEW)



ORDERING INFORMATION:

P/N M J 2 3 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 3$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
03

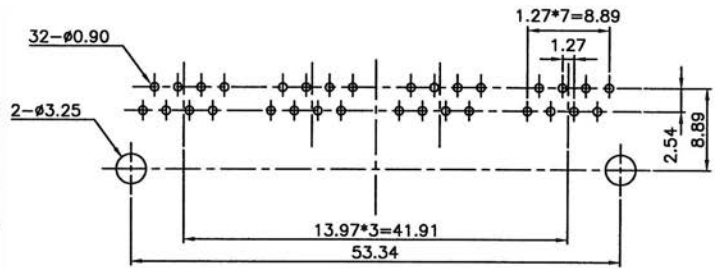
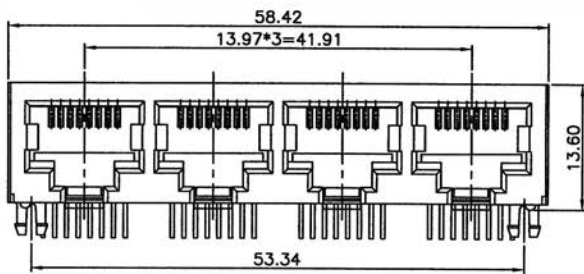
SIDE ENTRY 4-PORT MODULAR PCB JACK 8P PROFILE=13.55MM (UNSHIELDED)

SPECIFICATIONS

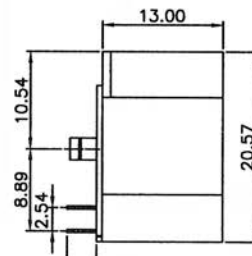
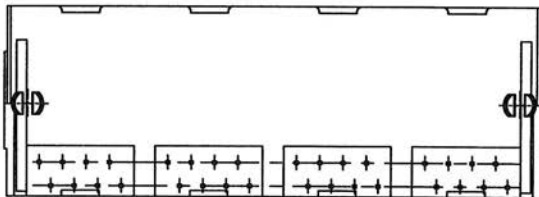
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J 2 3 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 04$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:
04

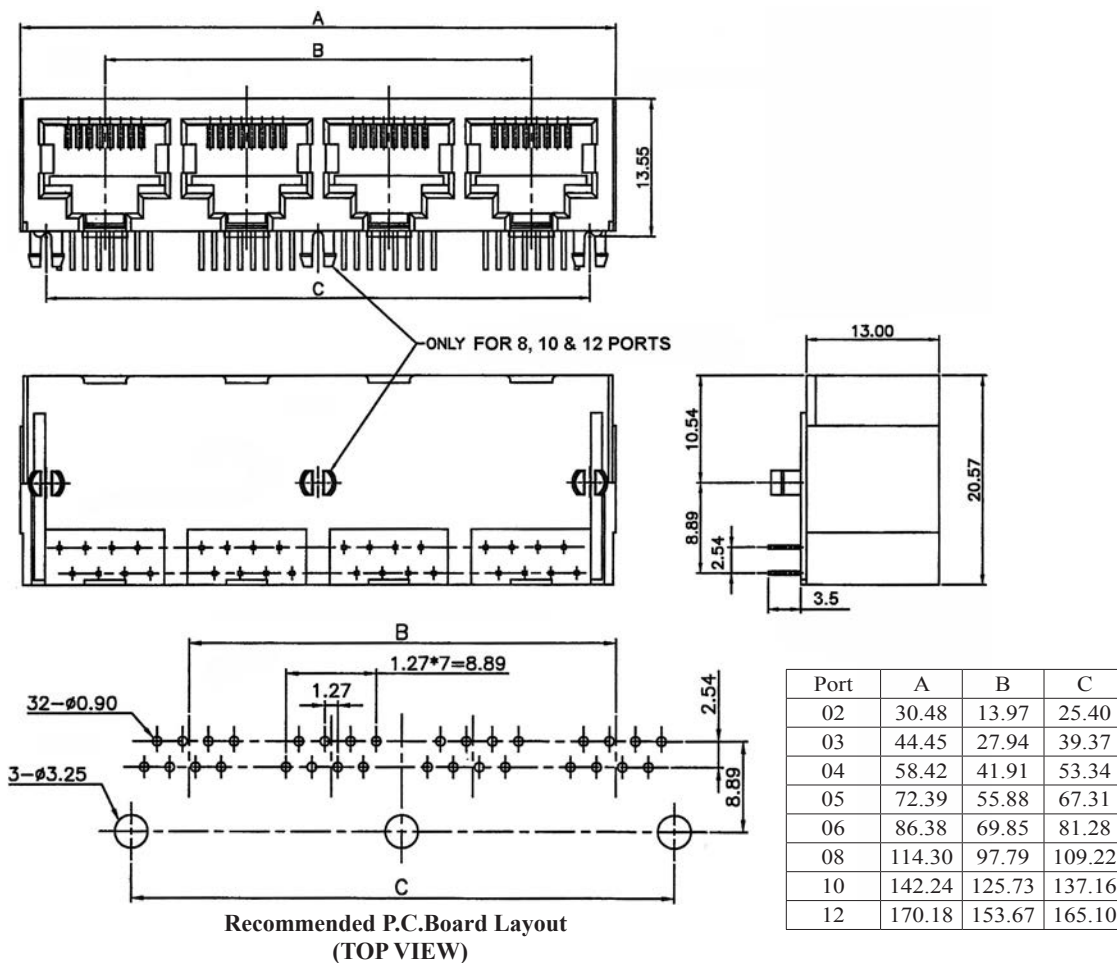
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 8P PROFILE=13.55MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 2 3 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
 - "88" 8P8C
 - "84" 8P4C
- CONTACT FINISH:
 - "A" 6 MICROINCH GOLD
 - "B" 15 MICROINCH GOLD
 - "C" 30 MICROINCH GOLD
 - "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 - 02, 03, 04, 05, 06, 08, 10, 12

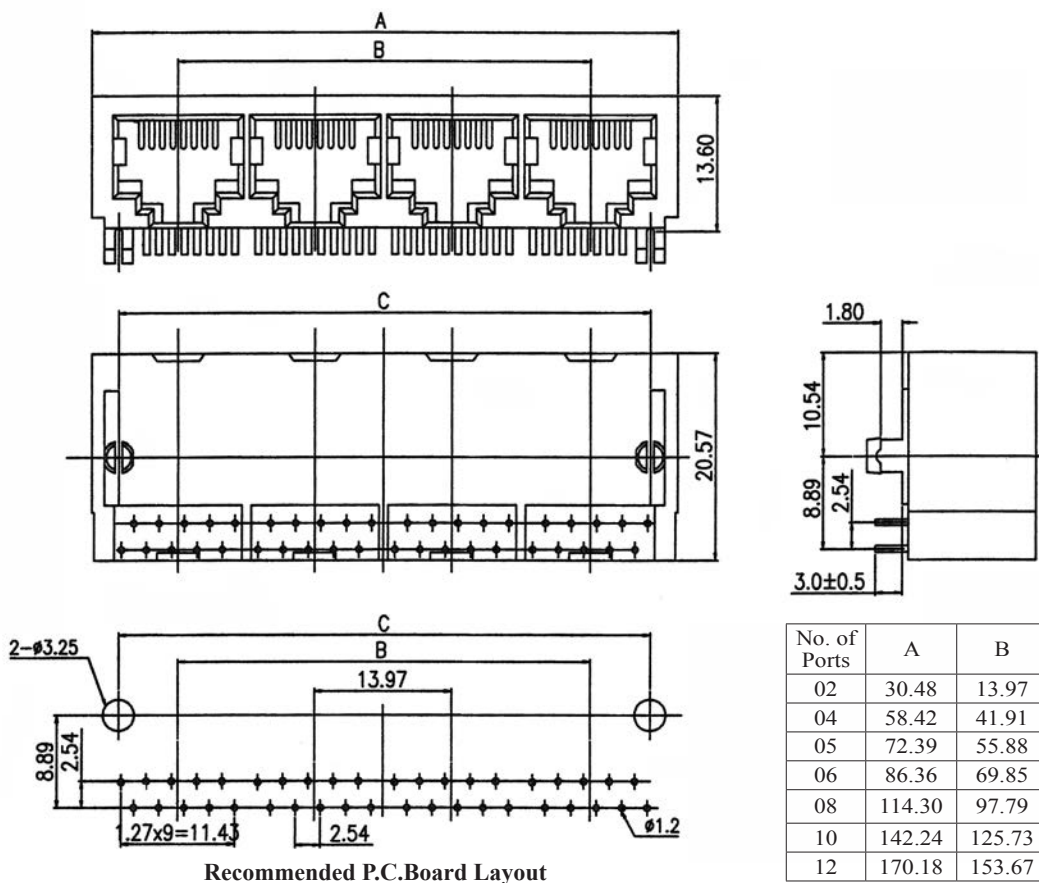
SIDE ENTRY MULTI-PORT MODULAR PCB JACK 8P+10P PROFILE=13.60MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



No. of Ports	A	B	C
02	30.48	13.97	25.40
04	58.42	41.91	53.34
05	72.39	55.88	67.31
06	86.36	69.85	81.28
08	114.30	97.79	109.22
10	142.24	125.73	137.16
12	170.18	153.67	165.10

ORDERING INFORMATION:

P/N MJ3V - $\frac{X}{1} \frac{X}{2} \frac{X}{3} B \frac{X}{3}$

- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- NO. OF PORTS:
 02, 04, 05, 06, 08, 10, 12

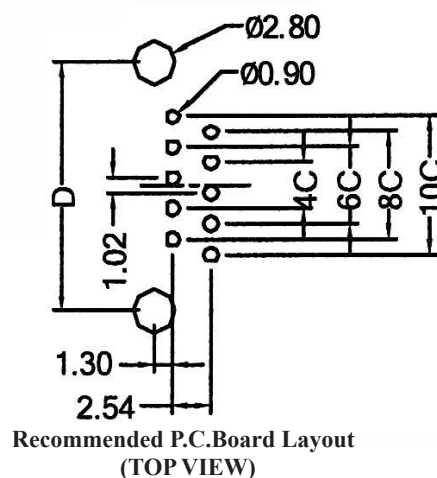
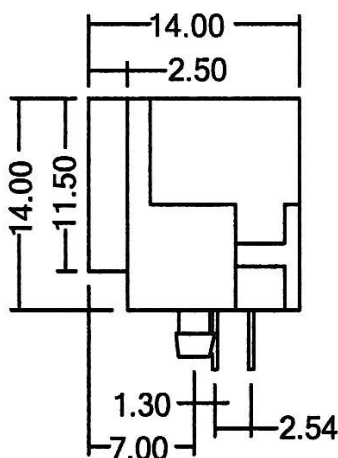
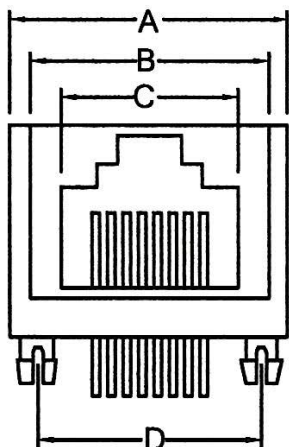
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P+8P+10P PROFILE=14.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



No. of Positions	No. of Contacts	A	B	C	D
6P	2C/4C/6C	14.50	12.00	9.80	12.80
8P	8C	18.50	16.00	12.00	16.50
10P	10C	18.50	16.00	12.00	16.50

ORDERING INFORMATION:

P/N M J R 6 - $\frac{x x x}{T} B$

1. NO. OF POSITIONS & CONTACTS:

- "66" 6P6C
- "64" 6P4C
- "88" 8P8C
- "84" 8P4C
- "00" 10P10C

2. CONTACT FINISH:

- "A" 6 MICROINCH GOLD
- "B" 15 MICROINCH GOLD
- "C" 30 MICROINCH GOLD
- "D" 50 MICROINCH GOLD
- "E" GOLD FLASH

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

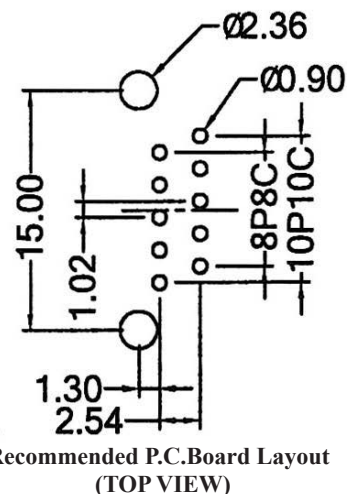
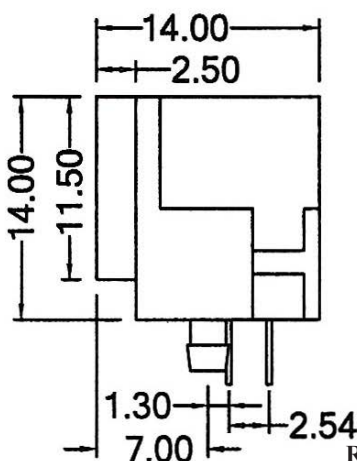
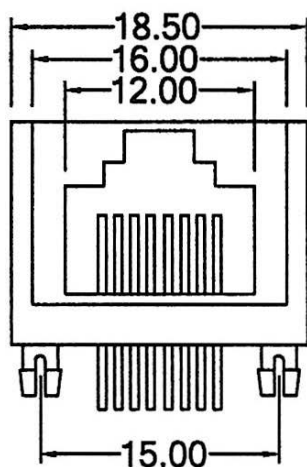
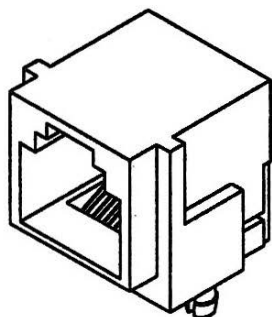
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R 4 - $\frac{x x x}{T} B$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

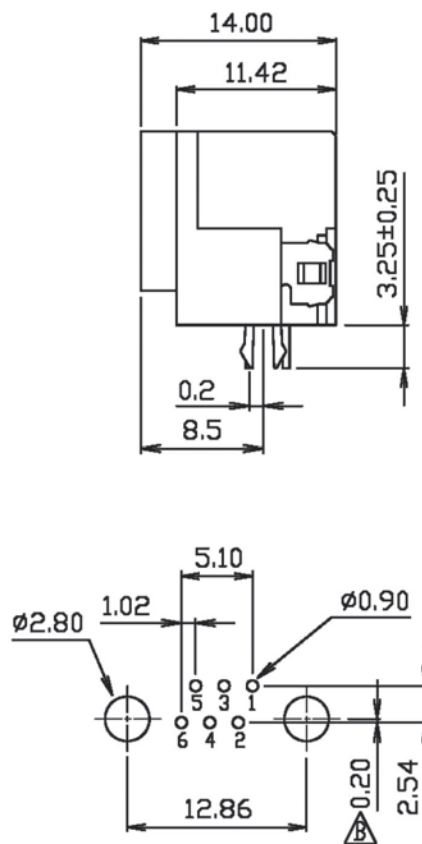
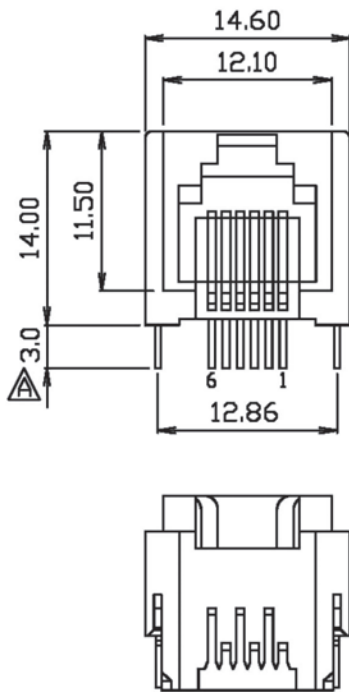
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=14.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J N Z - 6 6 x B
I 2 3 4

1. MODULAR JACK TYPE:
"NZ" WITH METAL PEGS
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

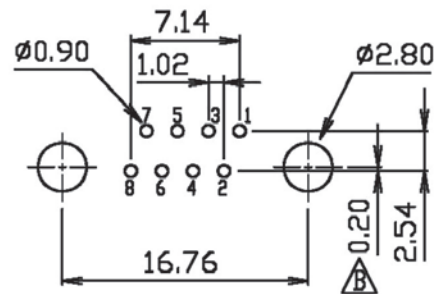
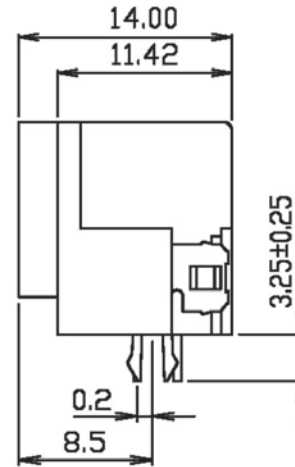
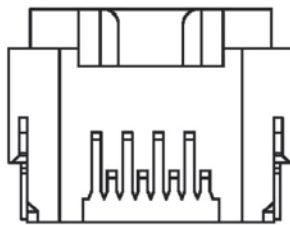
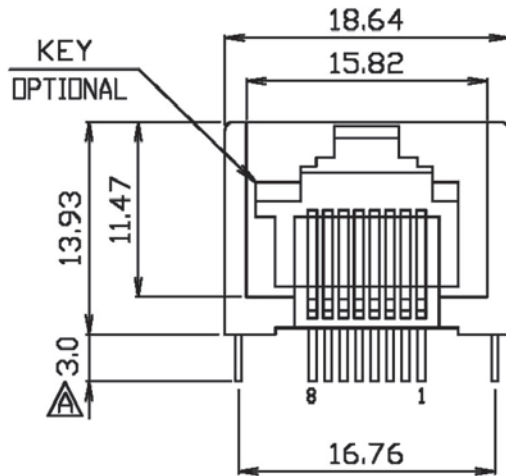
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=14.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J N Z - 8 8 x B x

I 2 3 4 5

1. MODULAR JACK TYPE:
"NZ" WITH METAL PEGS
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK

5. KEY OPTION:
" " WITHOUT KEY
"K" KEYED

SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.25MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

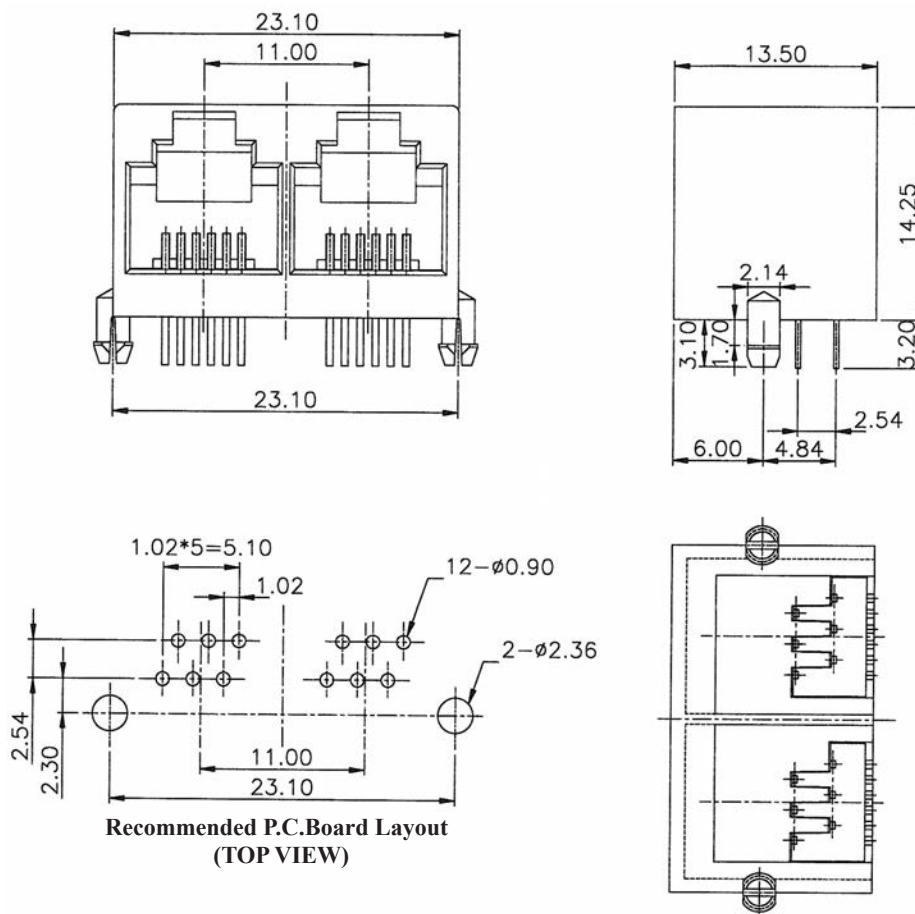
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6C - $\frac{xx}{1} \frac{xx}{23} \frac{xx}{4} 02$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

4. NO. OF PORTS:

02

SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.25MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

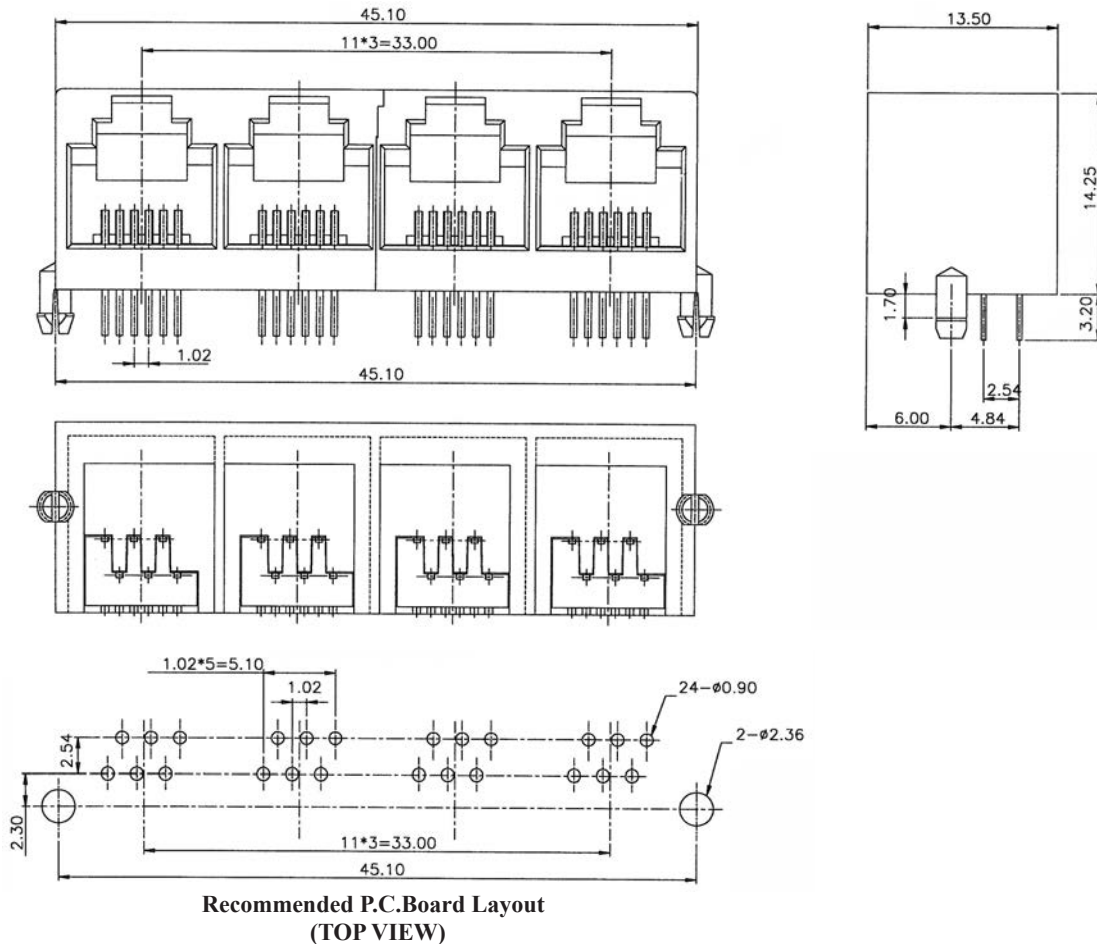
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6C - $\frac{xx}{1} \frac{xx}{2} \frac{xx}{3} \frac{04}{4}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

4. NO. OF PORTS:

04

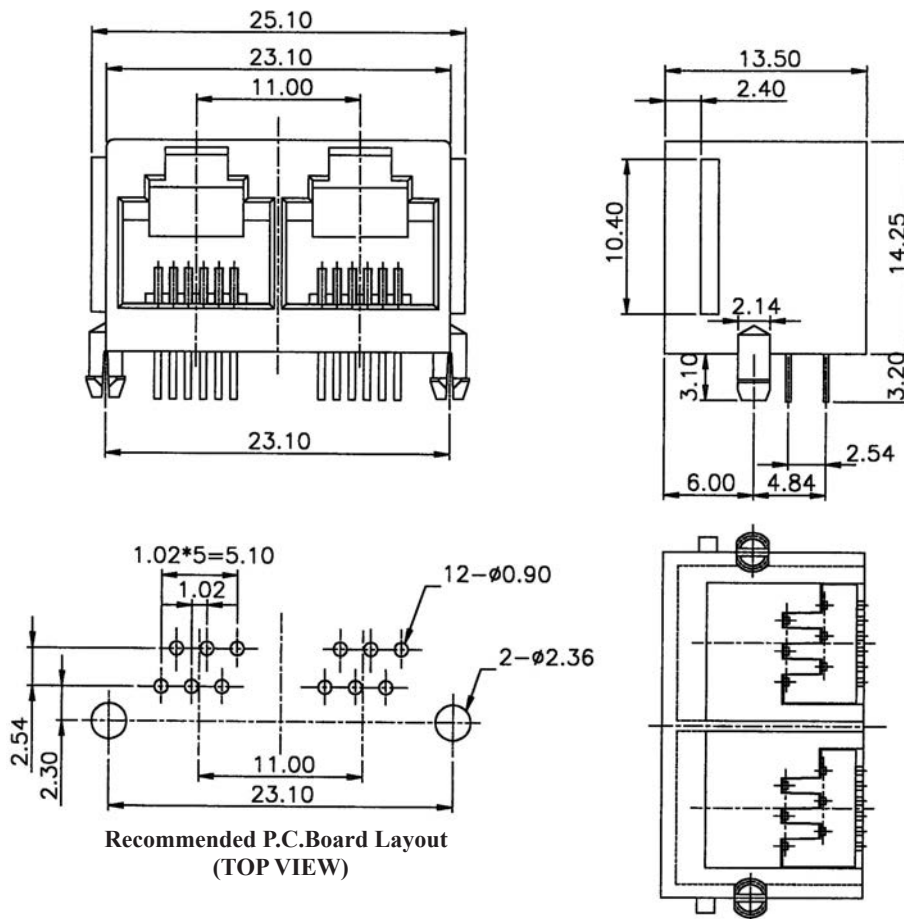
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.25MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 6 V - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} \frac{0}{2}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
 "E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

02

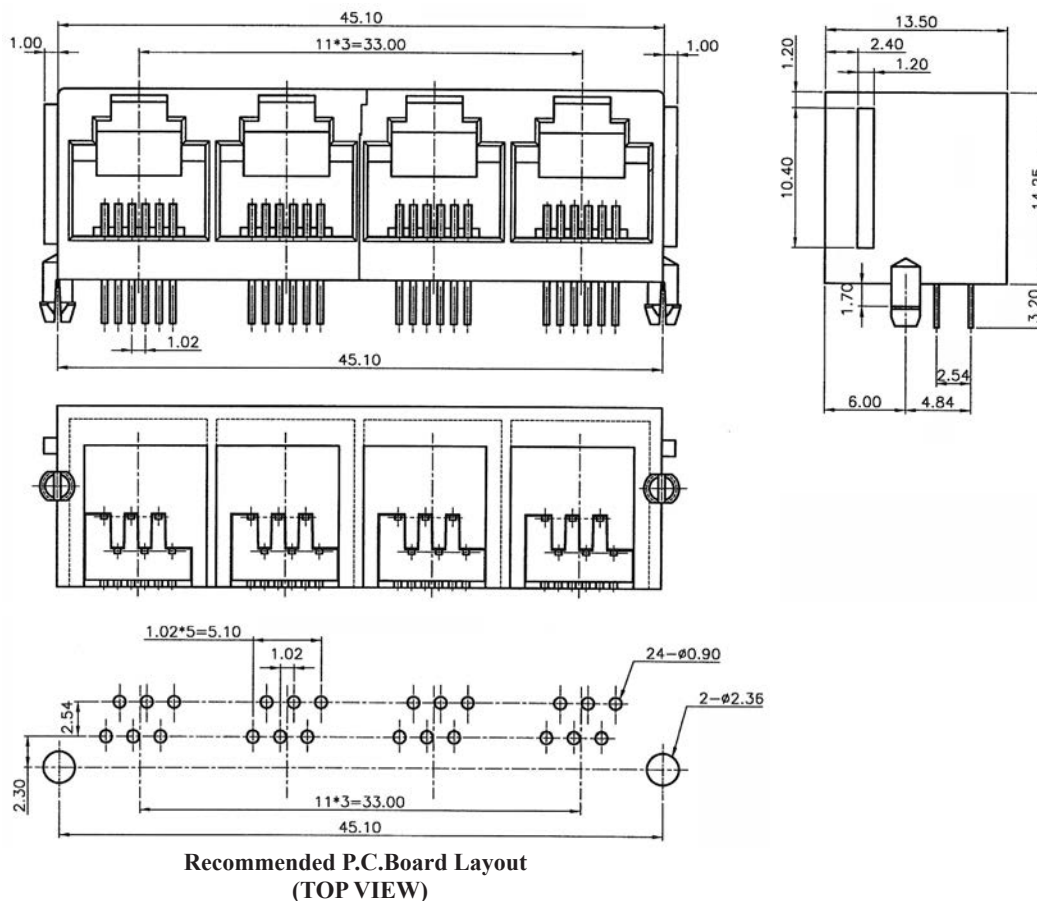
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.25MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6V - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{04}{4}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
 "E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

04

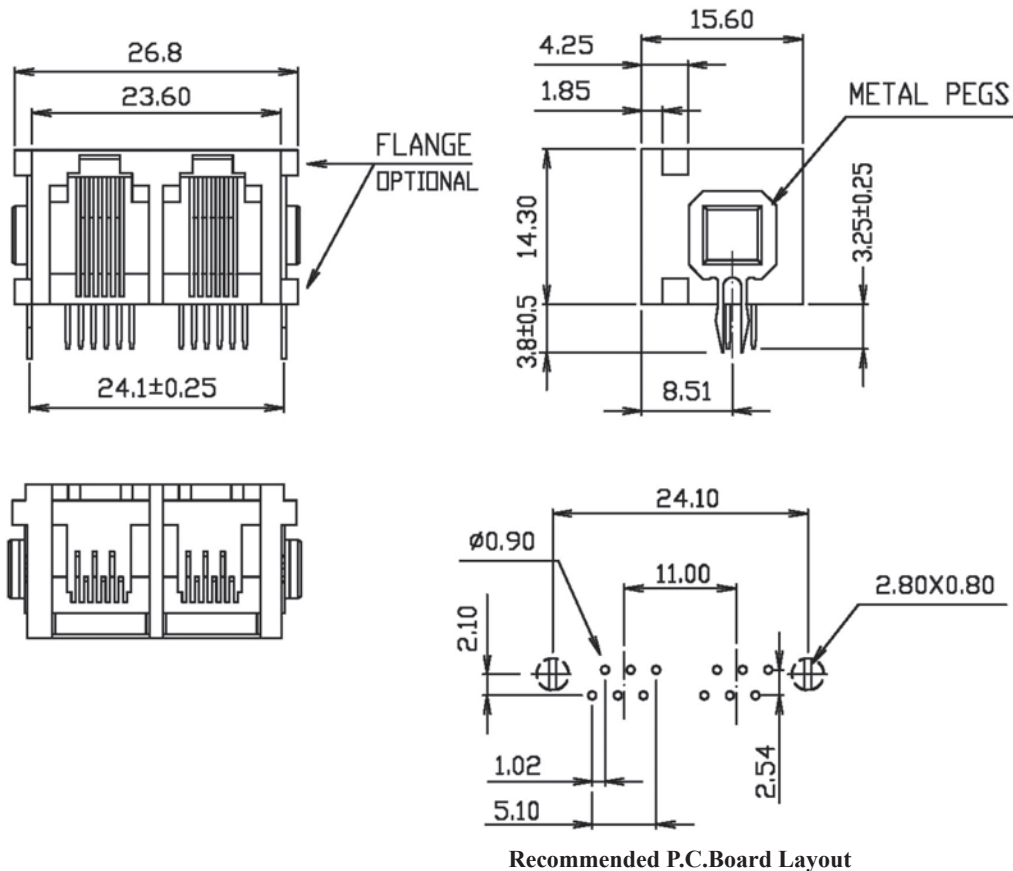
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J V B - 6 6 x B 0 2
 1 2 3 4 5

1. MODULAR JACK TYPE:
"VB" WITH METAL PEGS
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"B" BLACK
5. NO. OF PORTS:
02

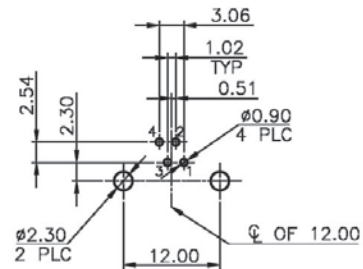
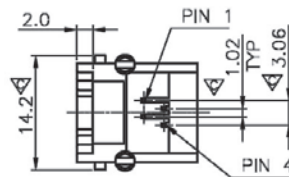
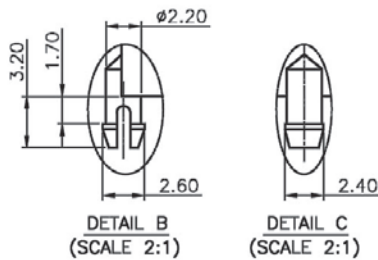
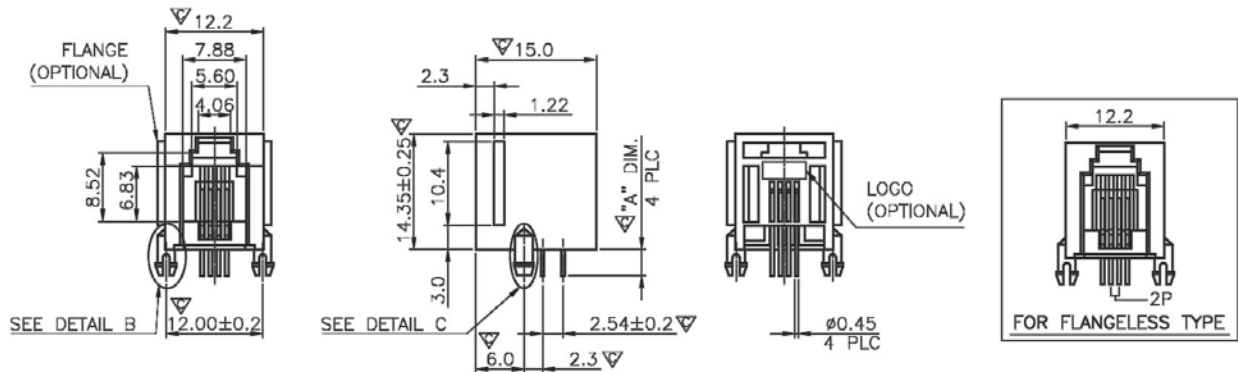
SIDE ENTRY UP LATCH MODULAR PCB JACK 4P PROFILE=14.35MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
Recommended PCB Thickness: 1.6mm
(TOP VIEW)

ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{44}{2} \frac{XX}{34}$

- MODULAR JACK TYPE:
 "VM" FLANGED
 "VN" FLANGELESS
- NO. OF POSITIONS & CONTACTS:
 "44" 4P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "A" GRAY
 "B" BLACK

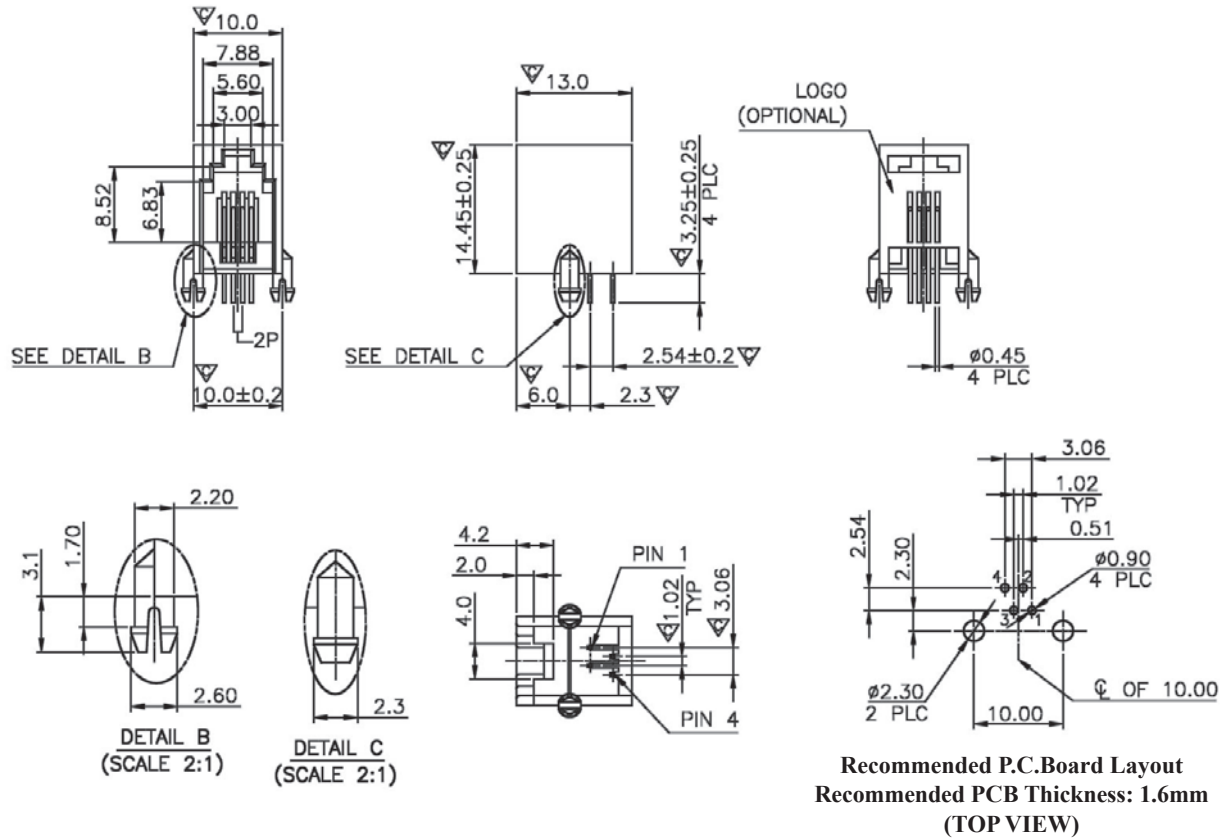
SIDE ENTRY UP LATCH MODULAR PCB JACK 4P PROFILE=14.35MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J V P - 44 x x
I 2 3 4

- MODULAR JACK TYPE:
"VP" MINI LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"44" 4P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

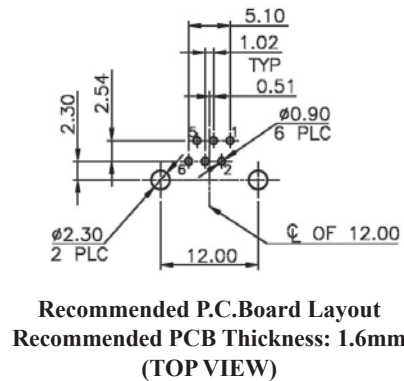
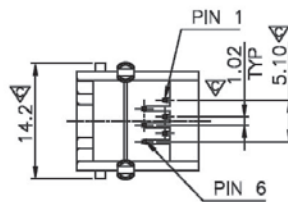
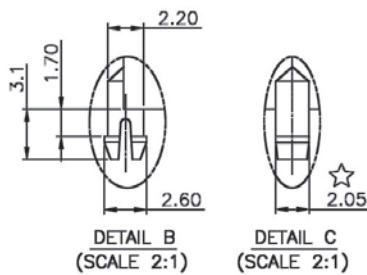
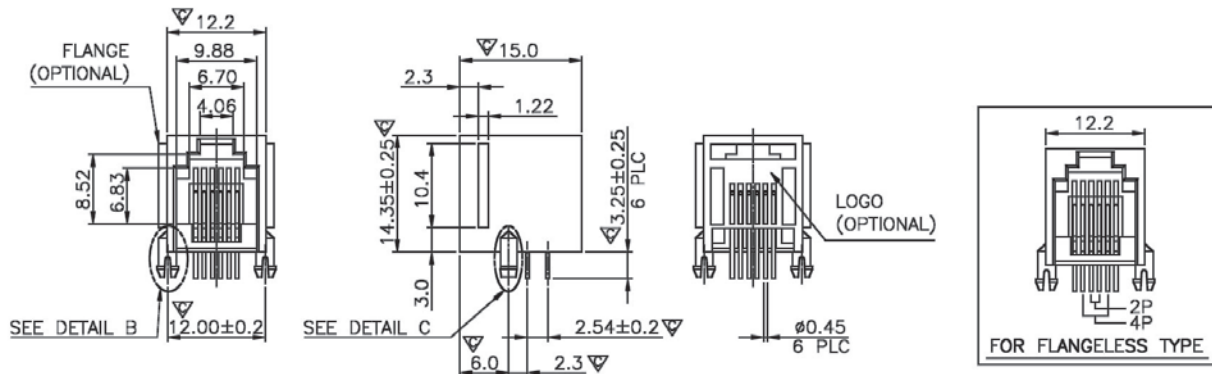
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=14.35MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - $\frac{66}{2}$ $\frac{xx}{34}$

- MODULAR JACK TYPE:
 "VM" FLANGED
 "VN" FLANGELESS
- NO. OF POSITIONS & CONTACTS:
 "64" 6P4C
 "66" 6P6C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "A" GRAY
 "B" BLACK

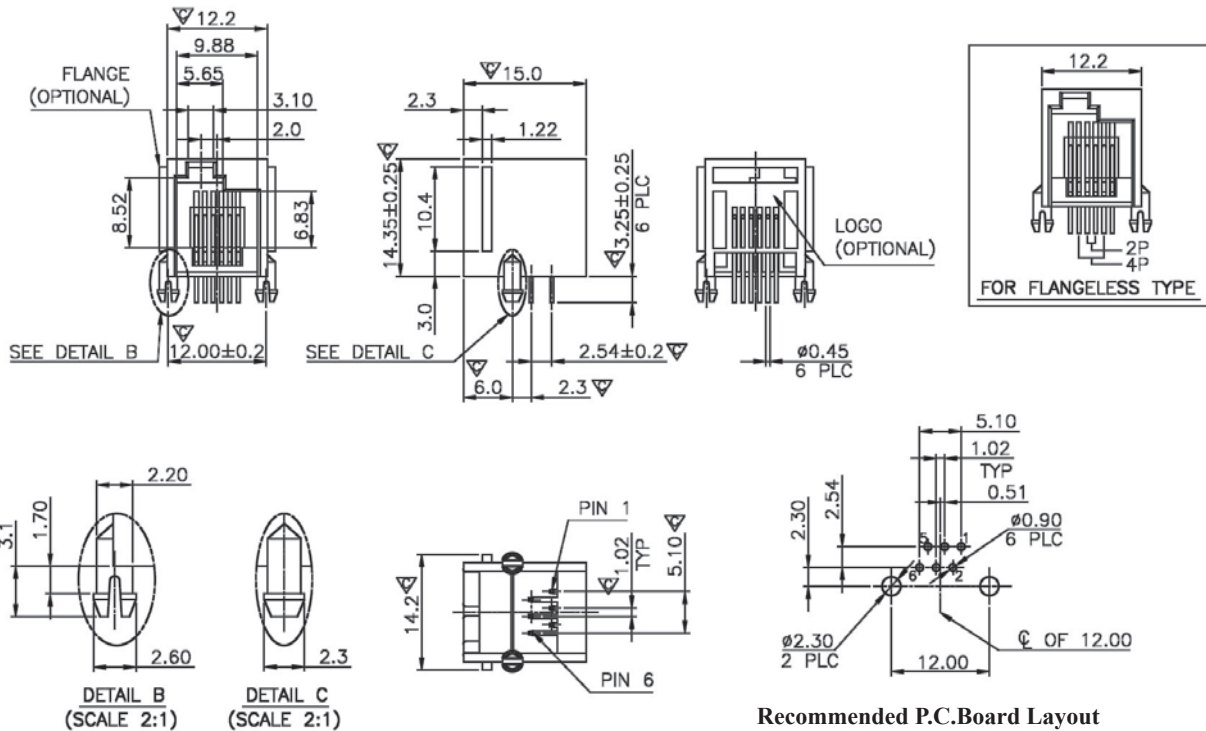
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=14.35MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - 6 6 $\frac{x}{2}$ $\frac{x}{3}$ $\frac{x}{4}$ K

- MODULAR JACK TYPE:
 - "VM" FLANGED WITH OFF-CENTER
 - "VN" FLANGELESS WITH OFF-CENTER
- NO. OF POSITIONS & CONTACTS:
 - "64" 6P4C
 - "66" 6P6C
- CONTACT FINISH:
 - "A" 6 MICROINCH GOLD
 - "B" 15 MICROINCH GOLD
 - "C" 30 MICROINCH GOLD
 - "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 - "A" GRAY
 - "B" BLACK
- KEY TYPE:
 - "K" OFF-CENTER TYPE

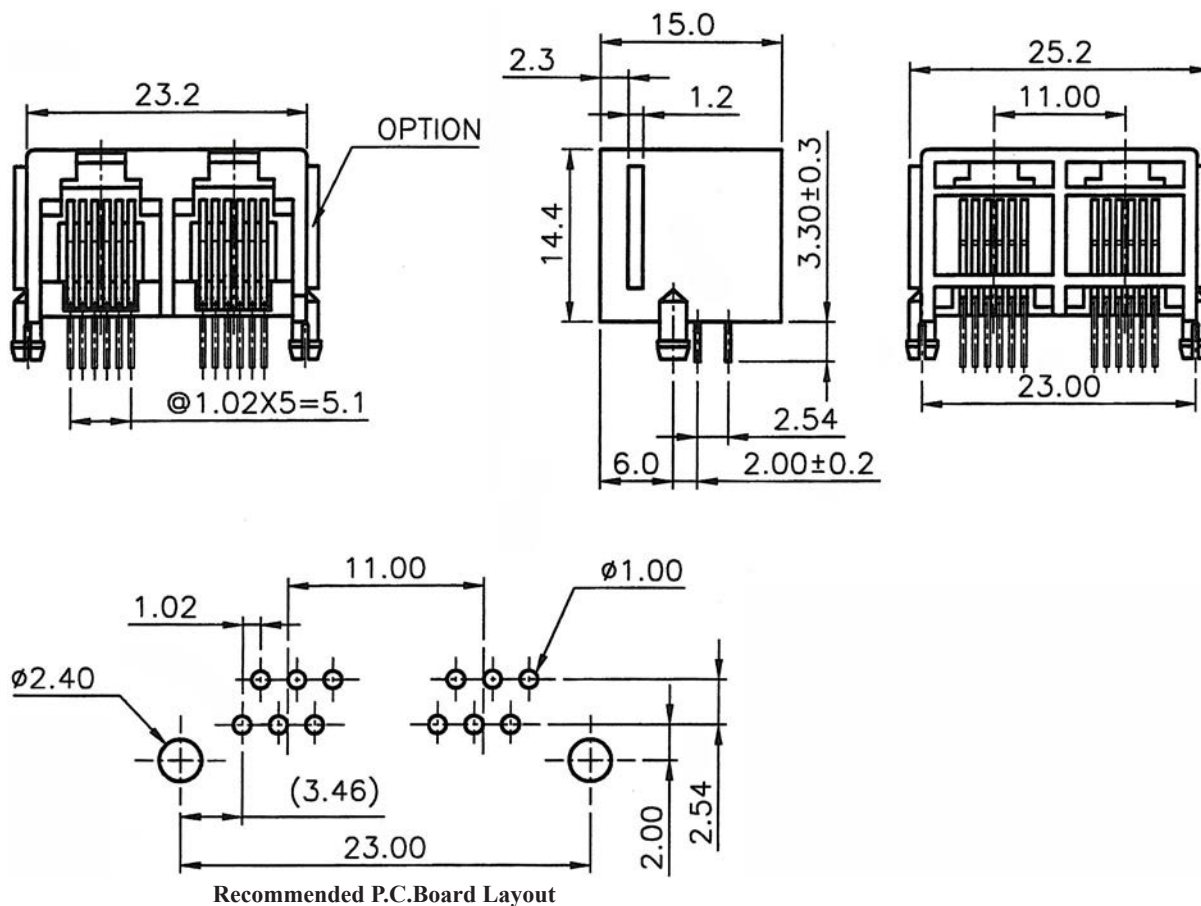
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ08 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} 02$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"B" BLACK (STANDARD)
 "A" GRAY

4. NO. OF PORTS:

02

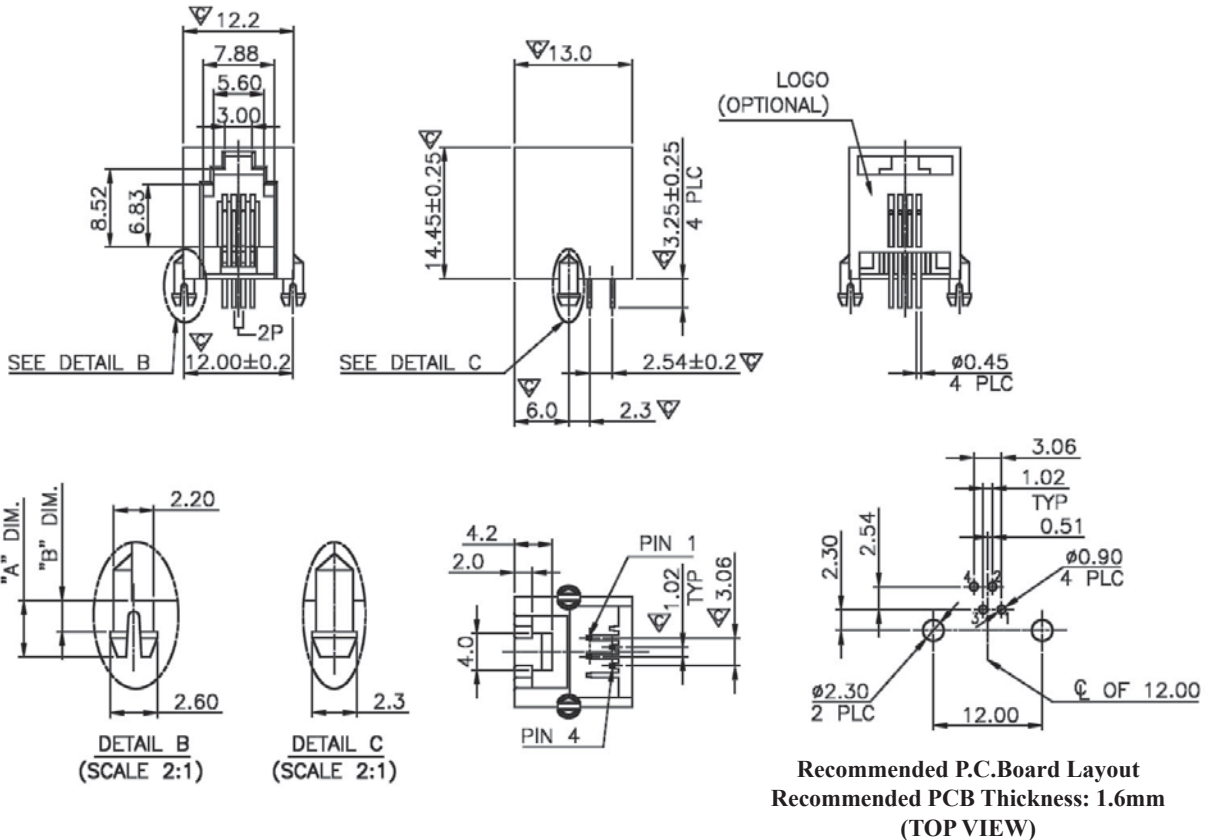
SIDE ENTRY UP LATCH MODULAR PCB JACK 4P PROFILE=14.45MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N **M J V Q - 44 x x**
I 2 3 4

- MODULAR JACK TYPE:
"VQ" MINI LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"44" 4P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

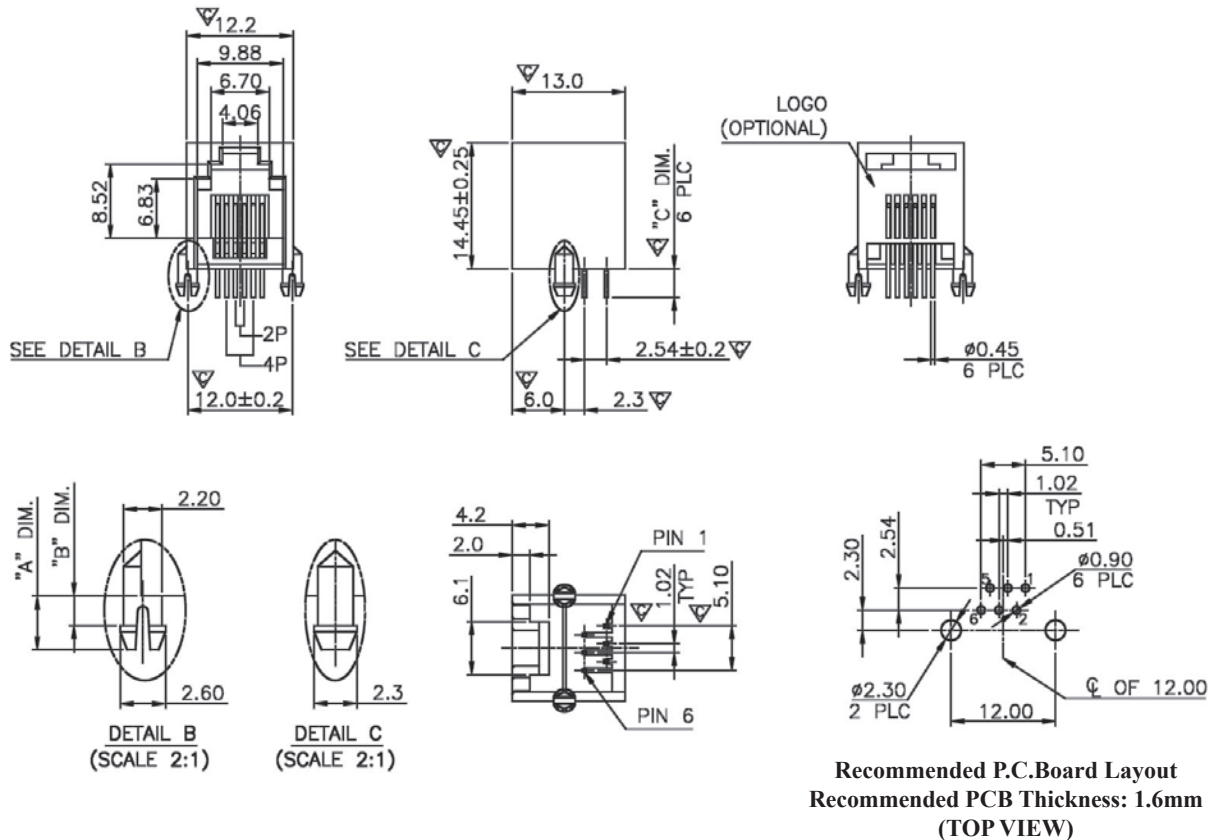
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=14.45MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
Recommended PCB Thickness: 1.6mm
(TOP VIEW)

ORDERING INFORMATION:

P/N M J V P - 66 x x
I 2 3 4

- MODULAR JACK TYPE:
"VP" MINI LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

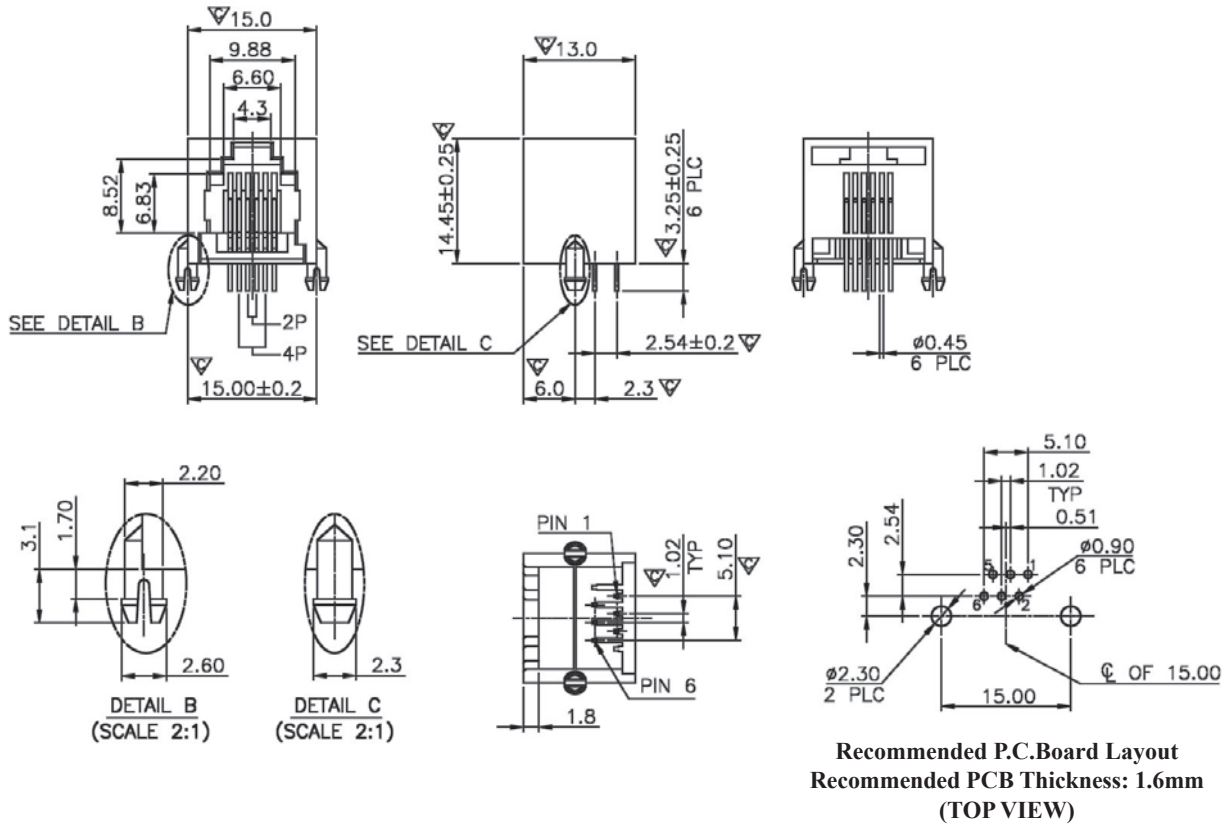
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=14.45MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{V}{1}$ Q - $\frac{66}{2}$ $\frac{x}{3}$ $\frac{x}{4}$

- MODULAR JACK TYPE:
"VQ" MINI LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

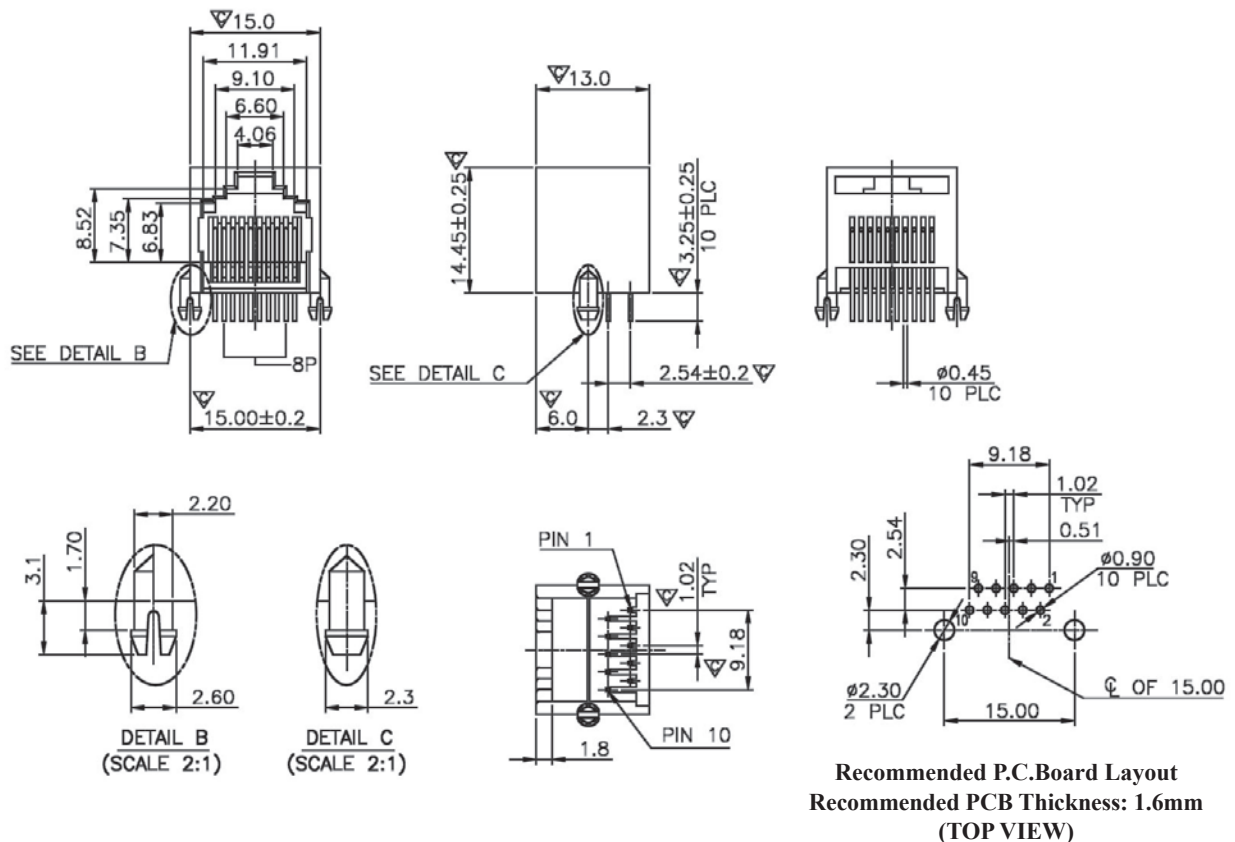
SIDE ENTRY UP LATCH MODULAR PCB JACK 10P PROFILE=14.45MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{V}{I}$ P - $\frac{00}{2}$ $\frac{x}{3}$ $\frac{x}{4}$

- MODULAR JACK TYPE:
"VP" MINI LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

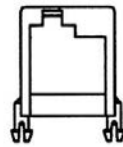
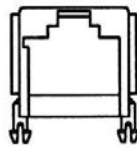
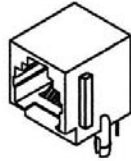
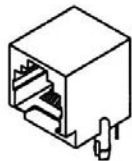
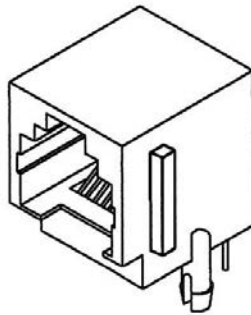
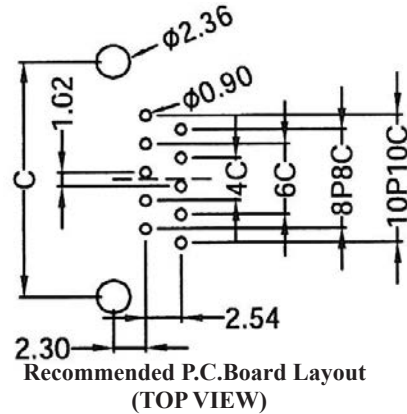
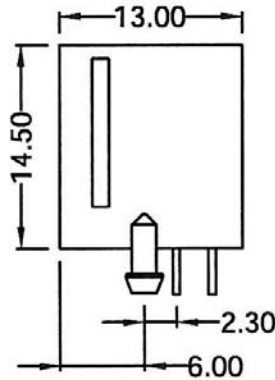
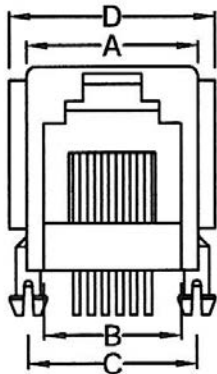
SIDE ENTRY UP LATCH MODULAR PCB JACK 4P+6P+8P+10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



No. of Positions	No. of Contacts	A	B	C	D
4P	4C	10.00	7.85	10.00	12.00
6P	2C/4C/6C	12.20	9.90	12.00	14.20
8P	8C	15.00	11.85	15.00	16.90
10P	10C	15.00	11.85	15.00	16.90

ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{XX}{3}$ $\frac{XX}{4}$ $\frac{XX}{5}$

- PANEL STOP OPTION:
 - "20" WITH PANEL STOP
 - "21" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 - "66" 6P6C
 - "64" 6P4C
 - "88" 8P8C
 - "00" 10P10C
 - "44" 4P4C
- CONTACT FINISH:
 - "A" 6 MICROINCH GOLD
 - "B" 15 MICROINCH GOLD
 - "C" 30 MICROINCH GOLD
- HOUSING COLOR:
 - "B" BLACK
 - "A" GRAY
- KEYWAY & OFFSET OPTION:
 - " " W/O KEYWAY & W/O OFFSET LATCH
 - "K" WITH KEYWAY (8P & 10P)
 - "D" WITH OFFSET LATCH (6P ONLY)

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

4. HOUSING COLOR:

"B" BLACK

"A" GRAY

5. KEYWAY & OFFSET OPTION:

" " W/O KEYWAY & W/O OFFSET LATCH

"K" WITH KEYWAY (8P & 10P)

"D" WITH OFFSET LATCH (6P ONLY)

SIDE ENTRY UP LATCH MODULAR PCB JACK 4P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

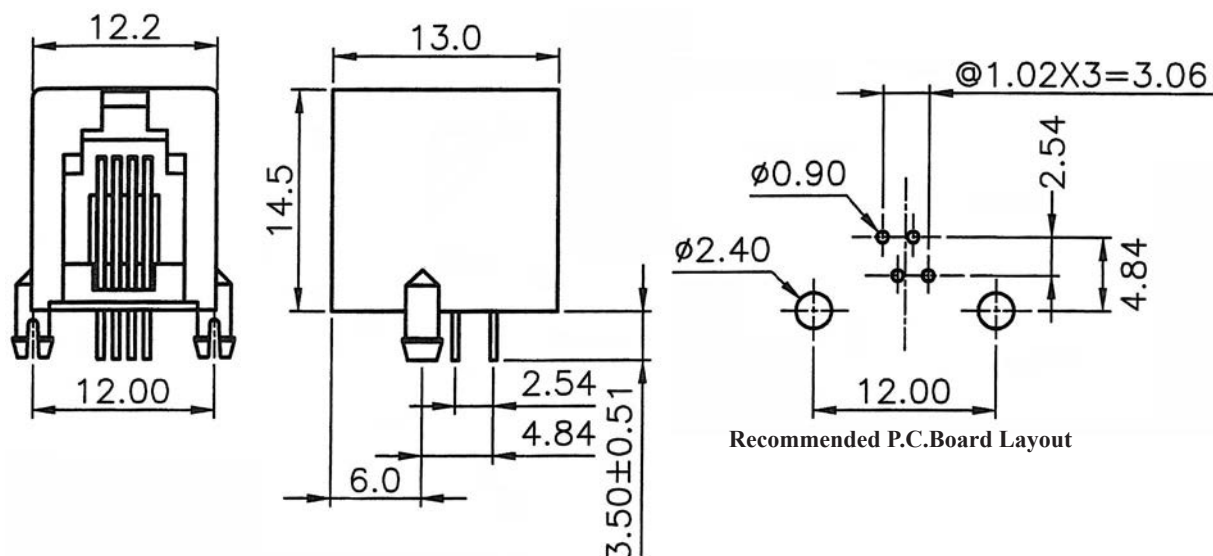
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ6U - $\frac{44 \times \times}{T \ 2 \ 3}$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 4P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

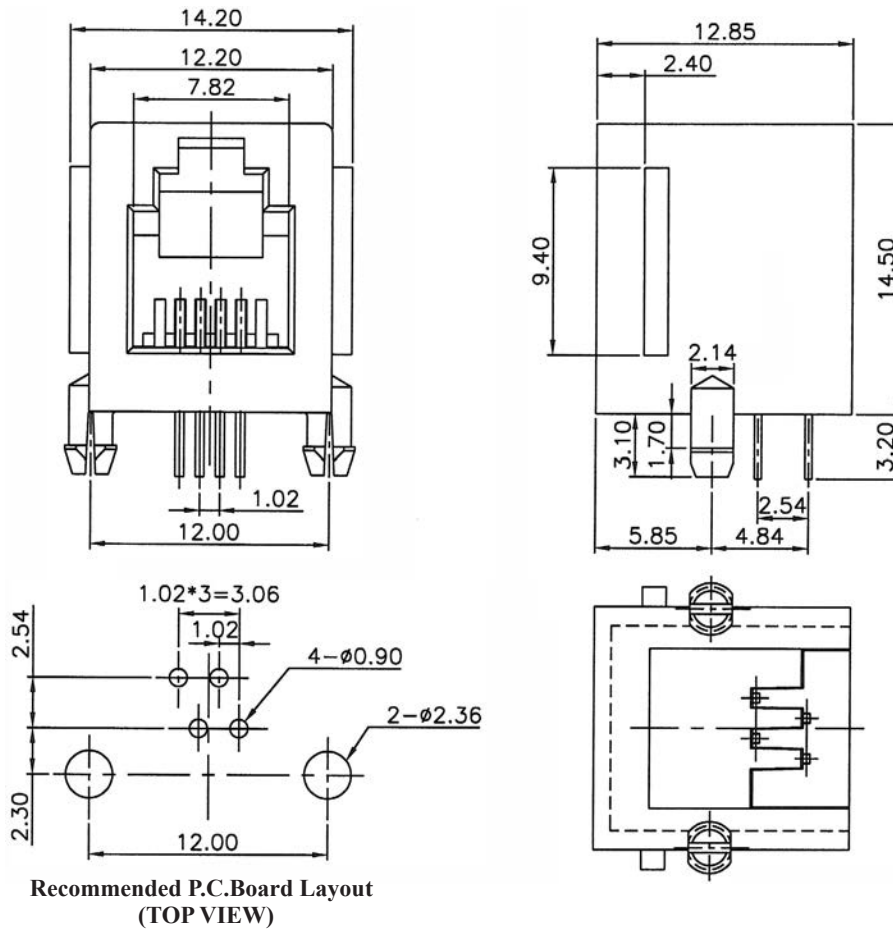
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 P - $\frac{44}{1} \frac{x}{2} \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

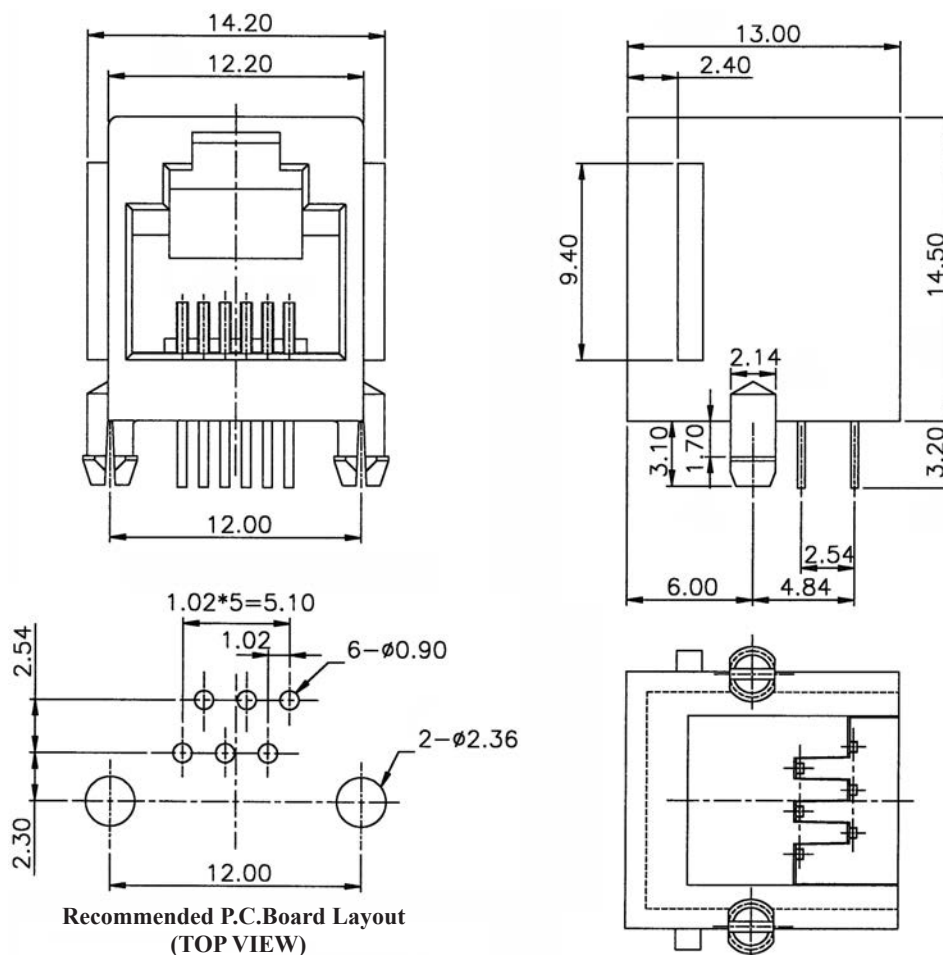
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 P - $\frac{x x x x}{1 2 3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

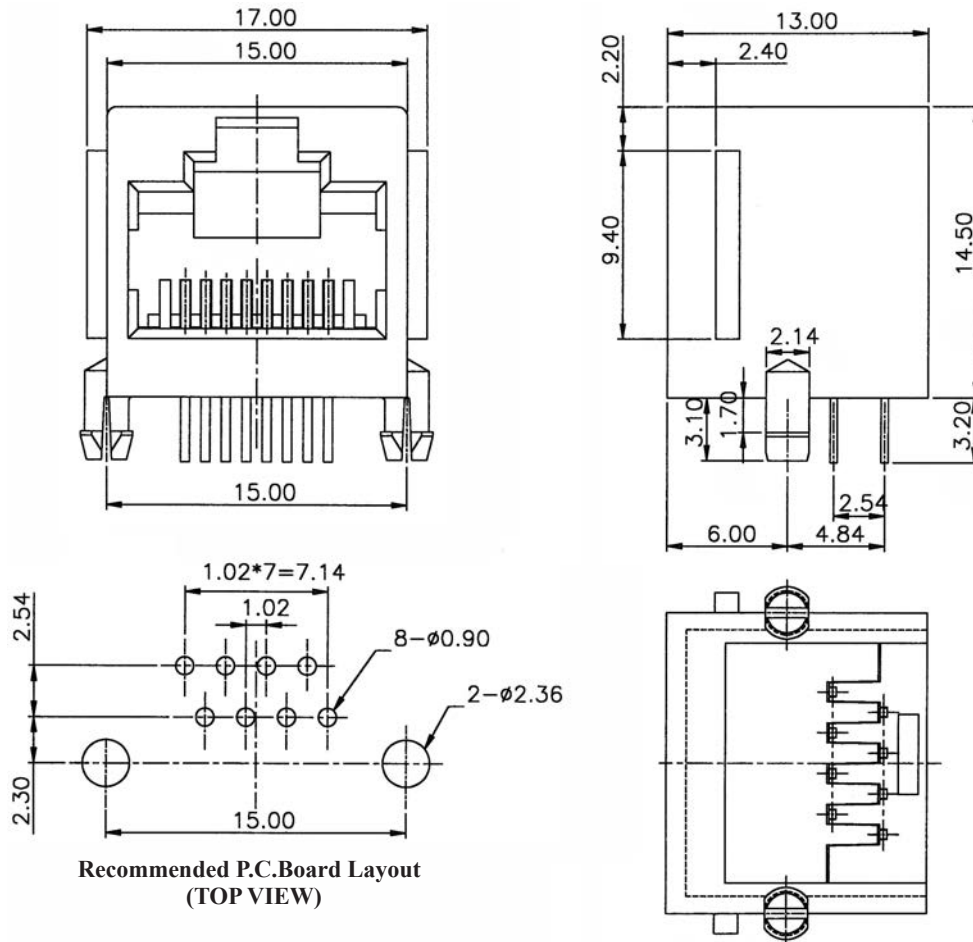
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 P - $\frac{x x x x}{1 2 3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

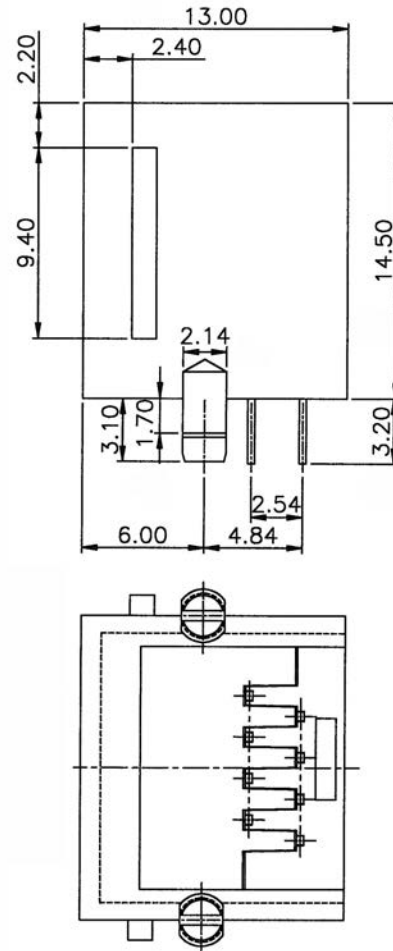
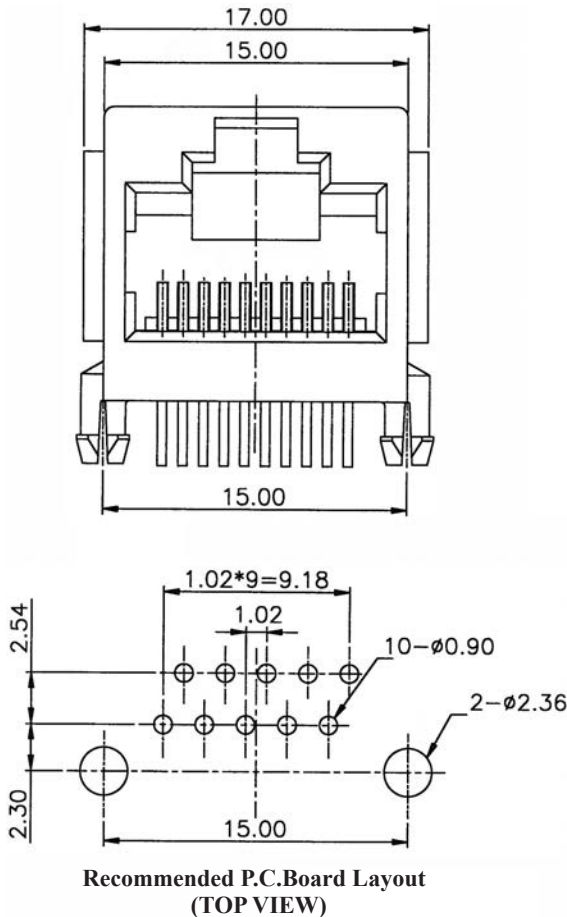
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 P - $\frac{x x x x}{T 2 3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 4P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

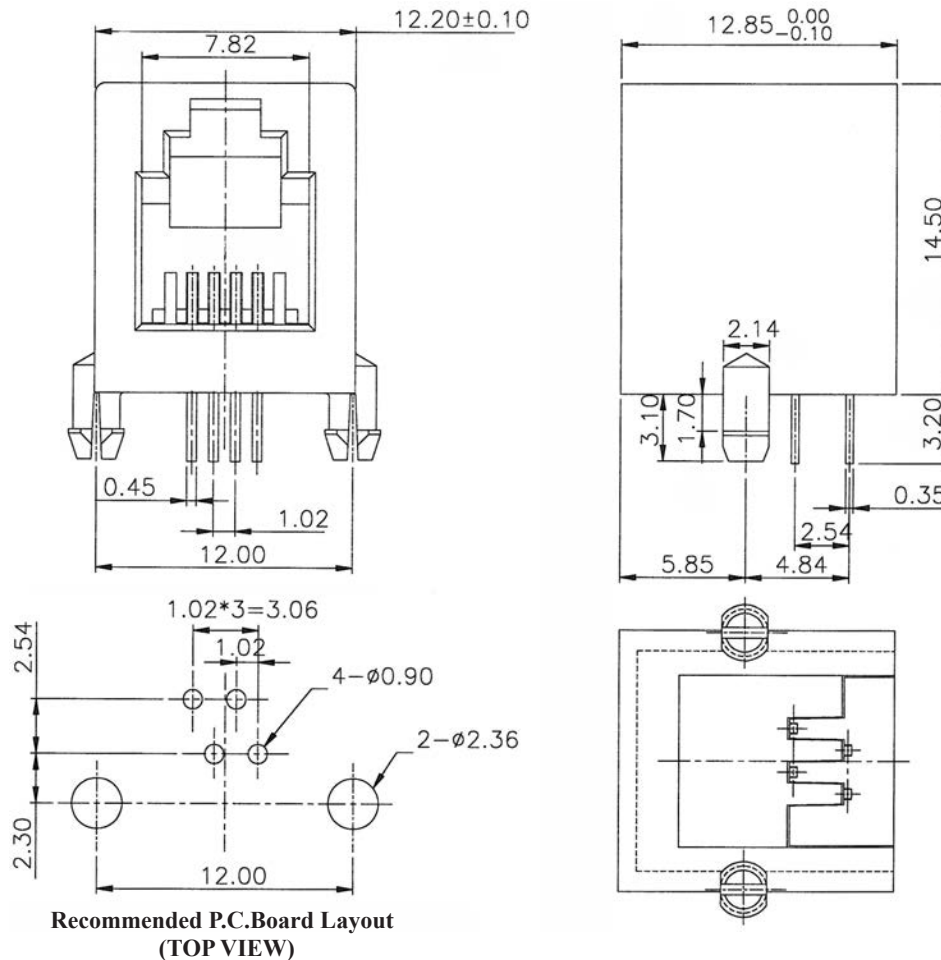
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1Q - $\frac{44}{T} \times \frac{x}{23}$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

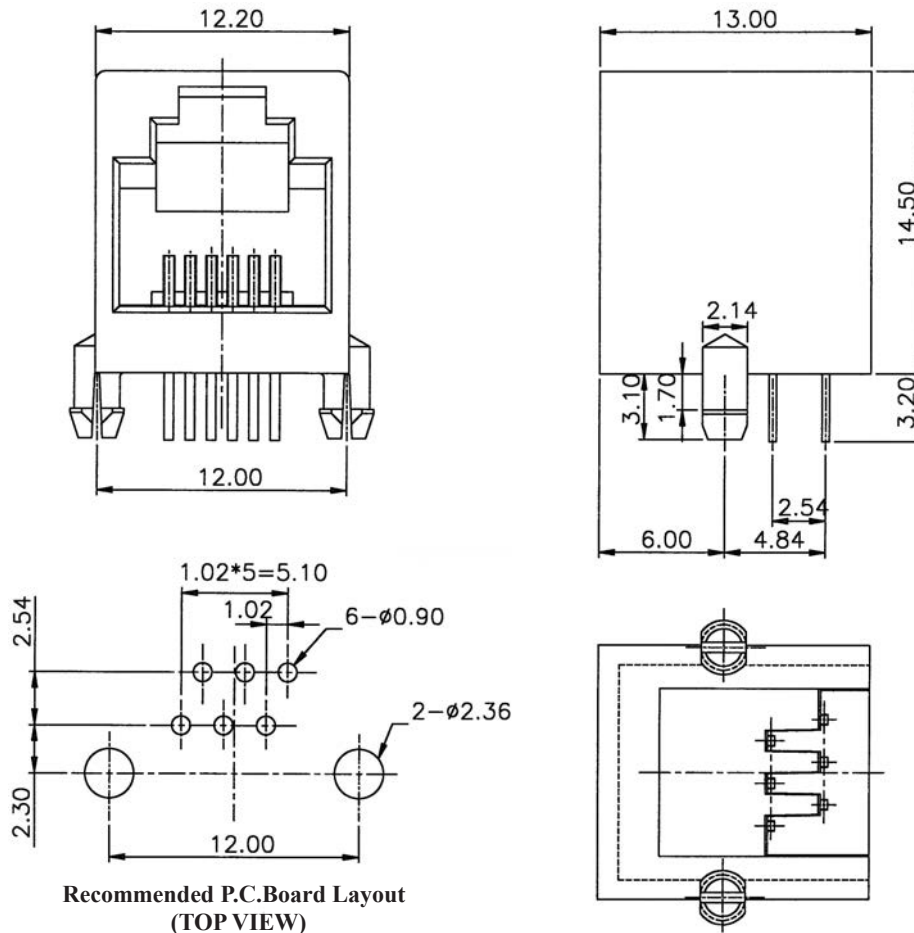
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ1Q - $\frac{XX}{T} \frac{XX}{23}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

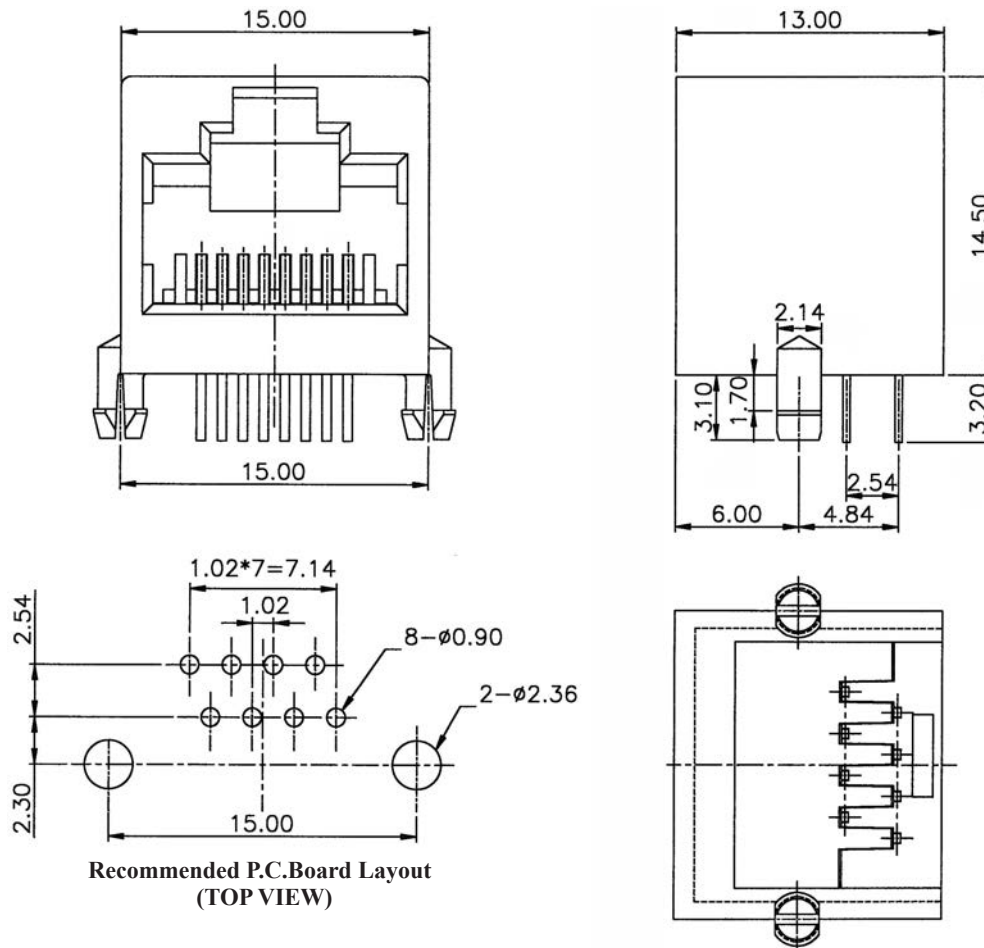
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1Q - $\frac{XX}{T} \frac{XX}{23}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

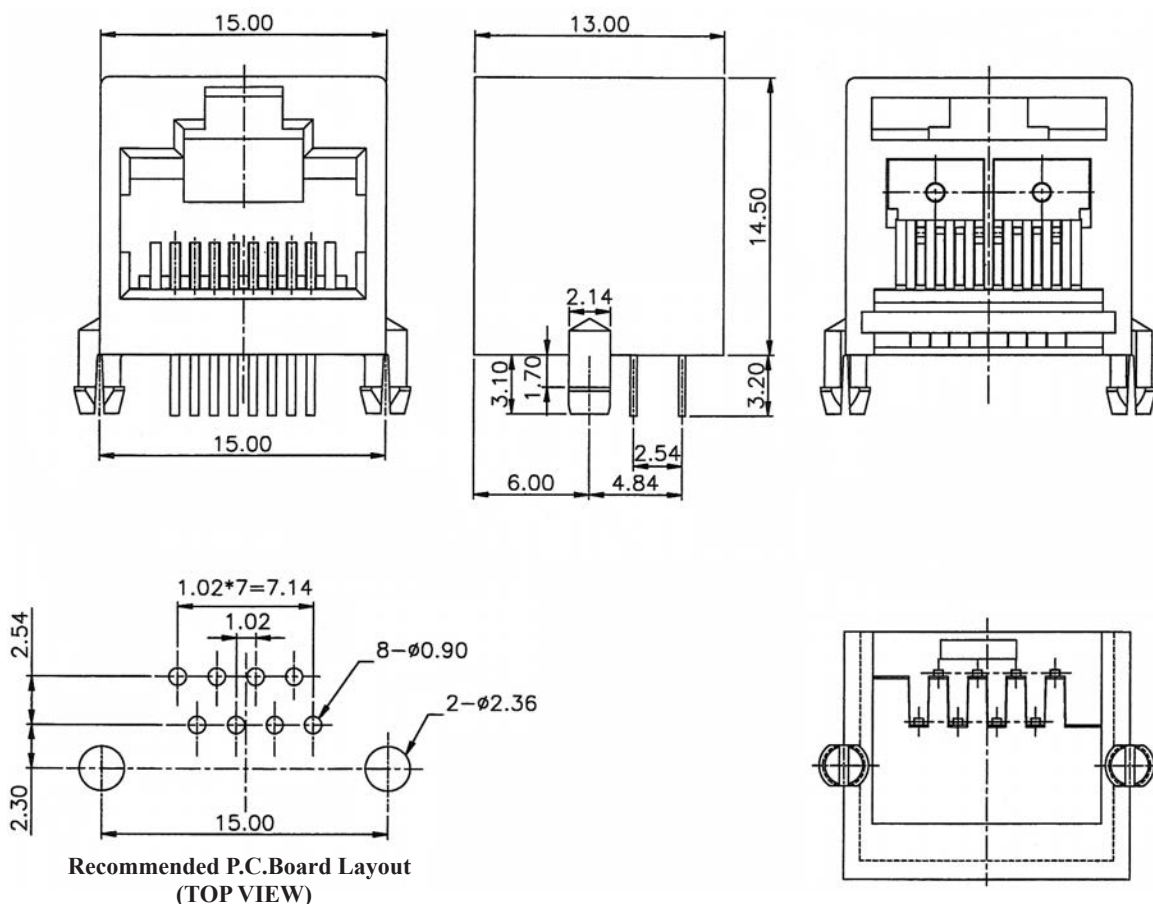
SIDE ENTRY UP LATCH MODULAR PCB JACK WITH PIN 1, 4 & 5, 8 SHORTED 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1N - $\frac{88}{T} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
 "E" GOLD FLASH

SIDE ENTRY UP LATCH MODULAR PCB JACK 10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

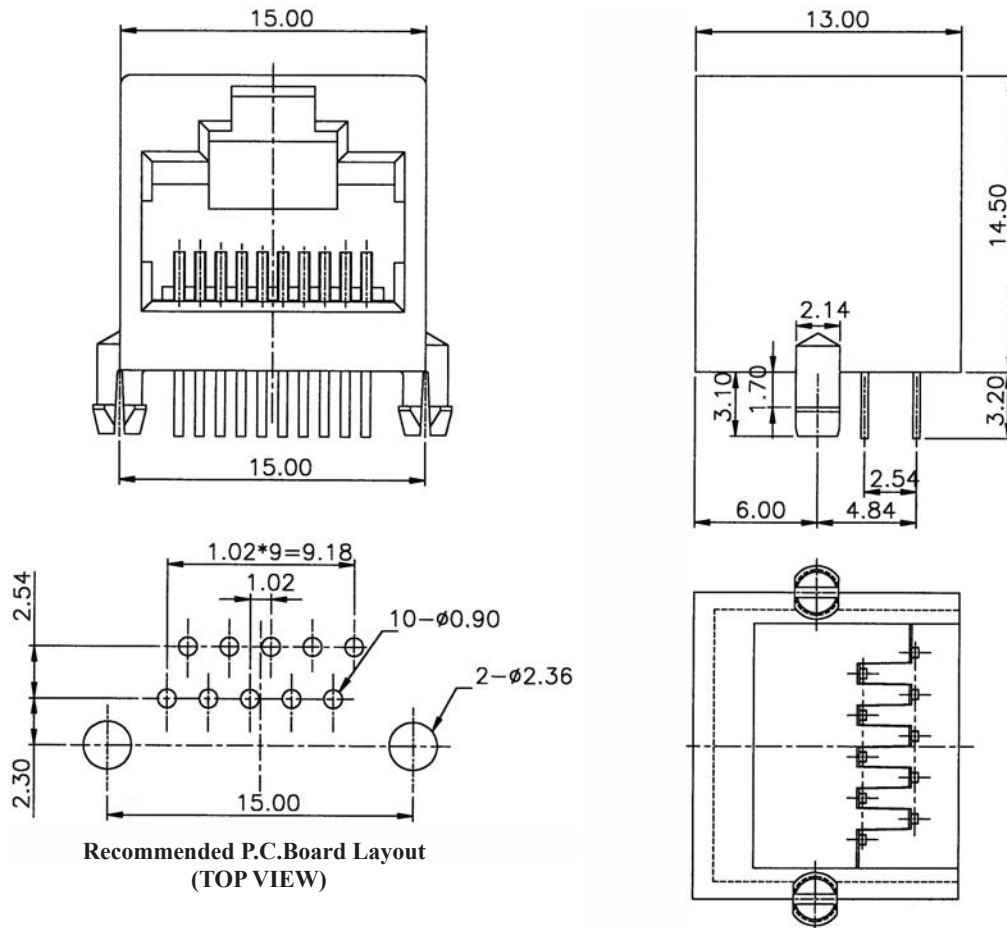
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ1Q - $\frac{XX}{T} \frac{XX}{23}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

SIDE ENTRY UP LATCH MODULAR PCB JACK WITH REVERSED PINS 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

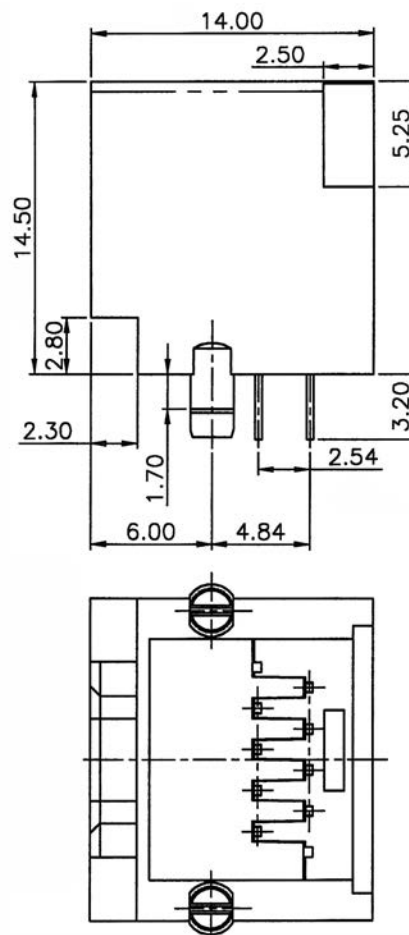
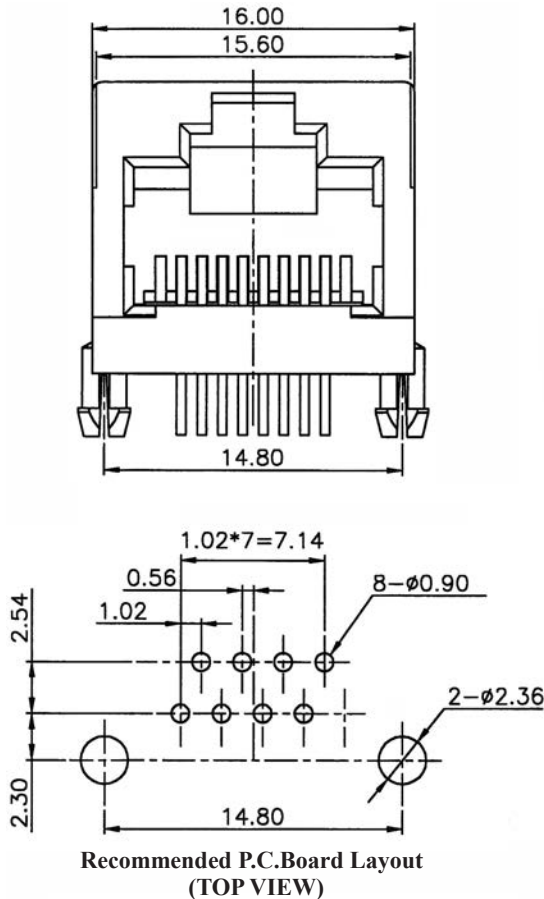
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 R - $\frac{x x x}{T 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

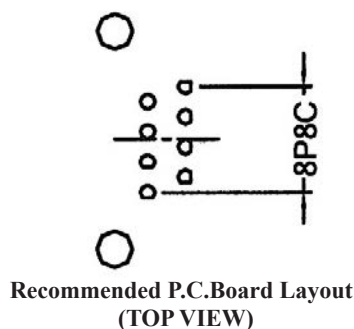
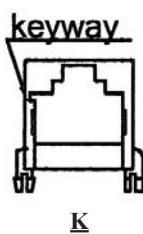
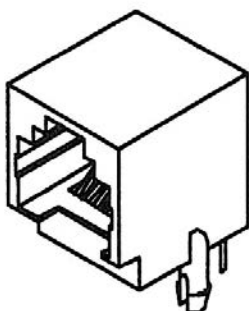
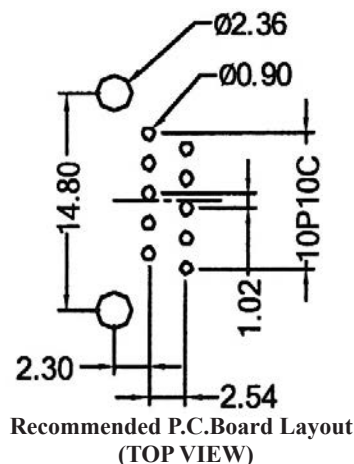
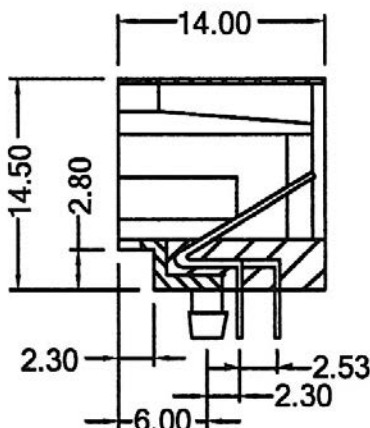
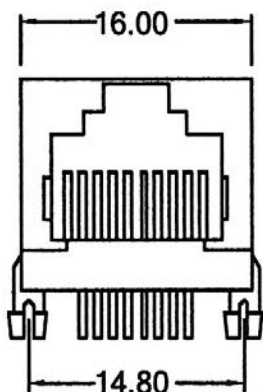
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJS1 - $\frac{X X X X X}{T 2 3 4}$

- NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "A" GRAY
 "B" BLACK
- KEYWAY OPTION:
 " " W/O KEYWAY
 "K" WITH KEYWAY

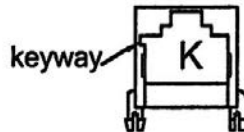
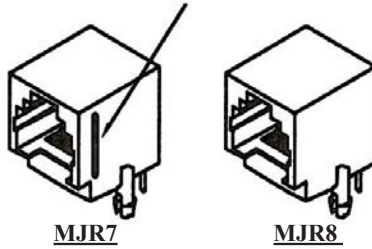
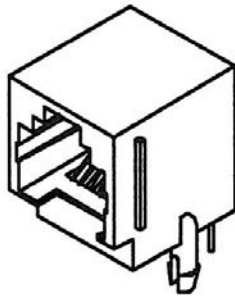
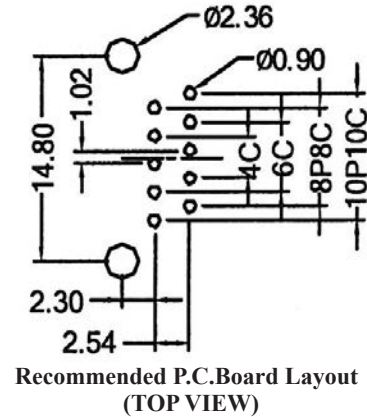
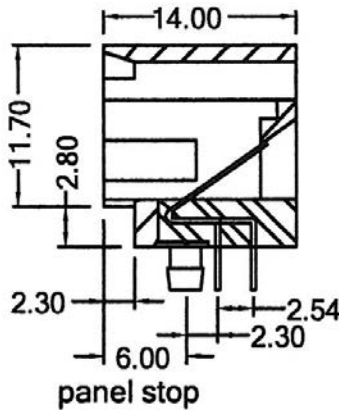
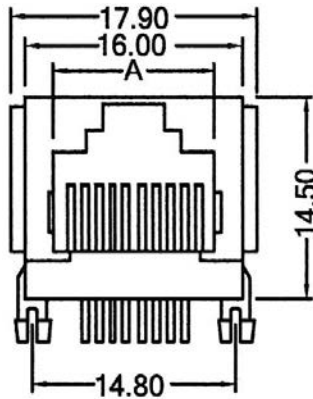
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P+8P+10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



No. of Positions	No. of Contacts	A
(8P)6P	2C/4C/6C	10.00
8P	2C/4C/6C/8C	12.10
10P	10C	12.10

ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{XX}{3}$ $\frac{XX}{4}$ $\frac{XX}{5}$

- PANEL STOP OPTION:
 "R7" WITH PANEL STOP
 "R8" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "A" GRAY
 "B" BLACK
- KEYWAY OPTION:
 " " W/O KEYWAY
 "K" WITH KEYWAY (for 8P & 10P)

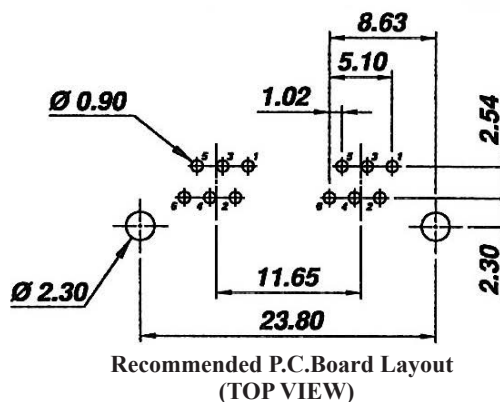
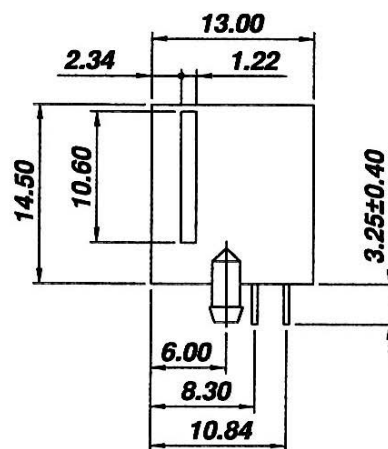
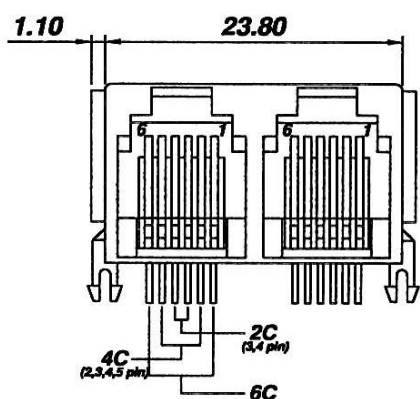
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6T - $\frac{\text{xx}}{1} \frac{\text{xx}}{23} \frac{\text{xx}}{4} \frac{02}{4}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

02

NOTE: P/N MJ6THT-6xxx02 FOR HIGH TEMP. VERSION

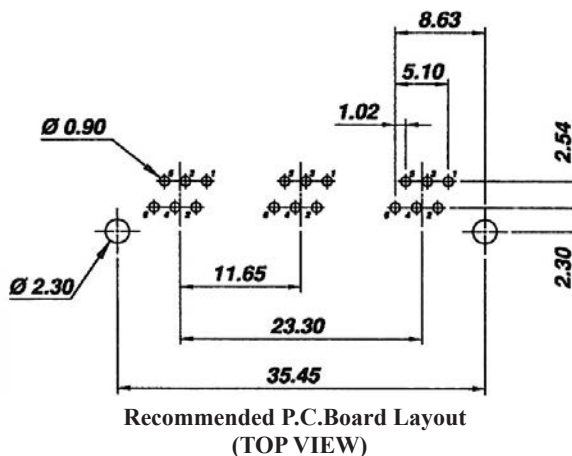
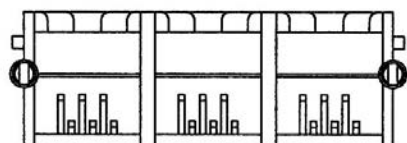
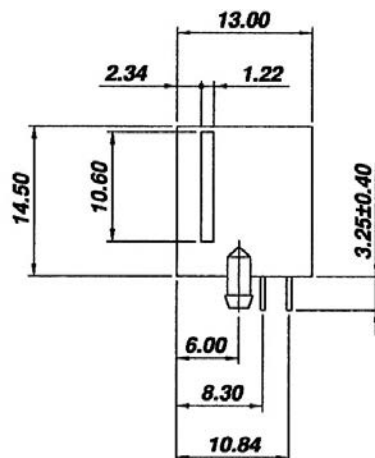
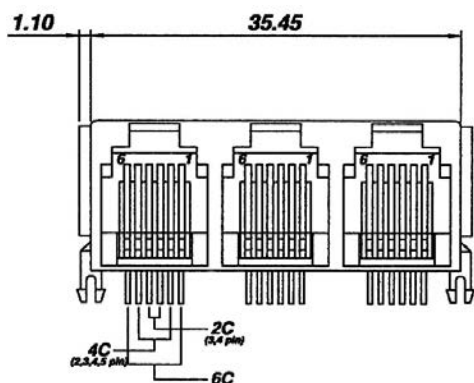
SIDE ENTRY 3-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6T - $\frac{xx}{1} \frac{xx}{23} \frac{03}{4}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

03

NOTE: P/N MJ6THT-6xxx03 FOR HIGH TEMP. VERSION

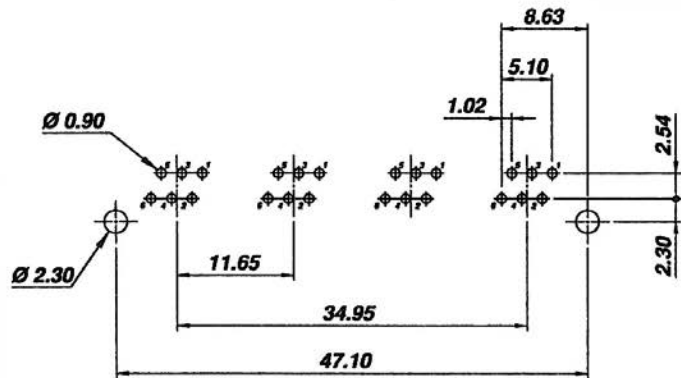
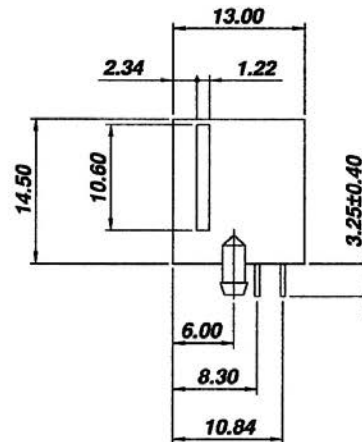
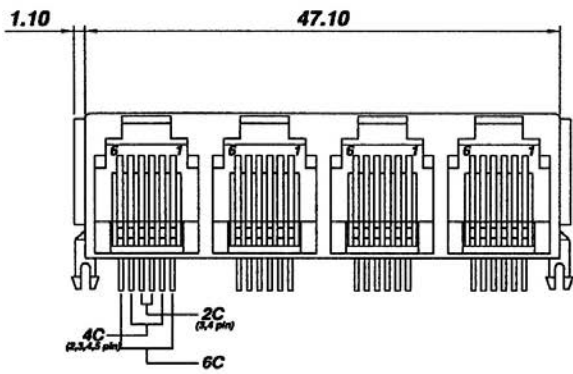
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout (TOP VIEW)

ORDERING INFORMATION:

P/N MJ6T - $\frac{\text{xx}}{\text{1}} \frac{\text{xx}}{\text{23}} \frac{\text{xx}}{\text{4}} \frac{\text{04}}{\text{4}}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

04

NOTE: P/N MJ6THT-6xxx04 FOR HIGH TEMP. VERSION

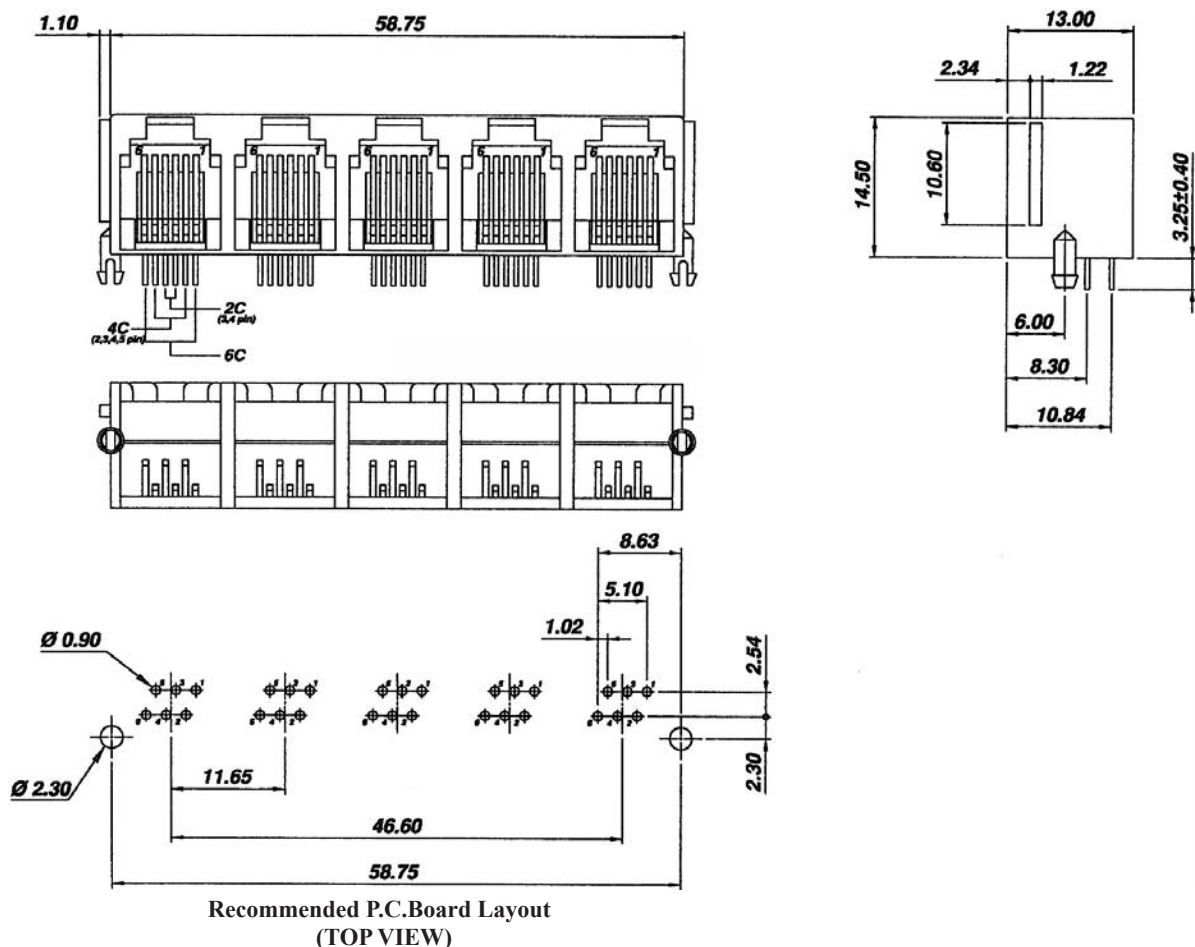
SIDE ENTRY 5-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6T - $\frac{xx}{1} \frac{xx}{23} \frac{xx}{4} \frac{05}{}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

05

NOTE: P/N MJ6THT-6xxx05 FOR HIGH TEMP. VERSION

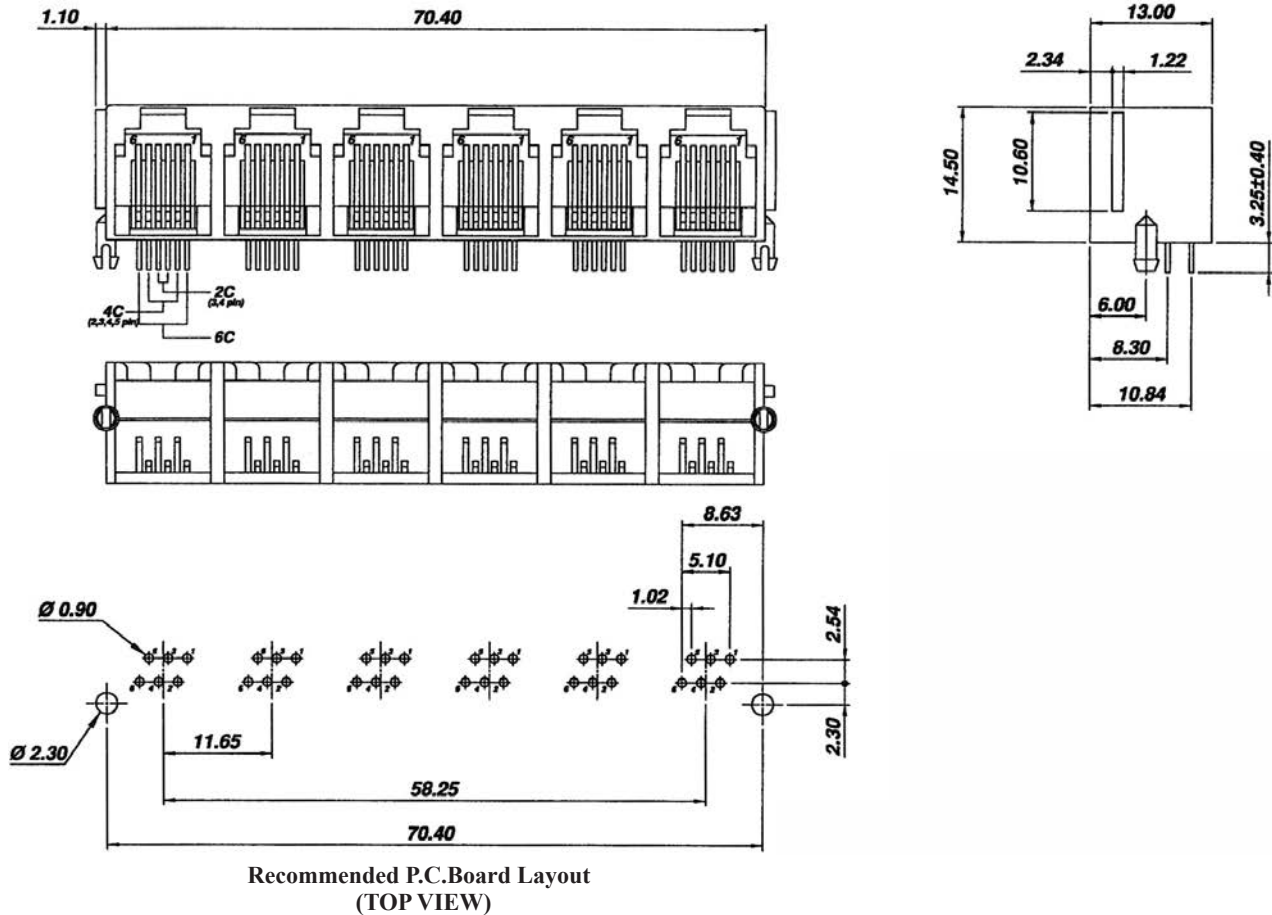
SIDE ENTRY 6-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black & Gray
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ6T - $\frac{xx}{1} \frac{xx}{23} \frac{xx}{4} \frac{06}{}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

4. NO. OF PORTS:

06

NOTE: P/N MJ6THT-6xxx06 FOR HIGH TEMP. VERSION

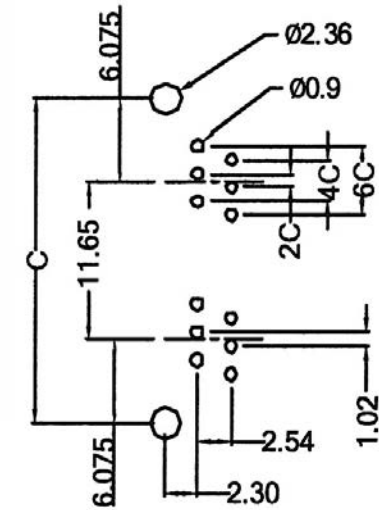
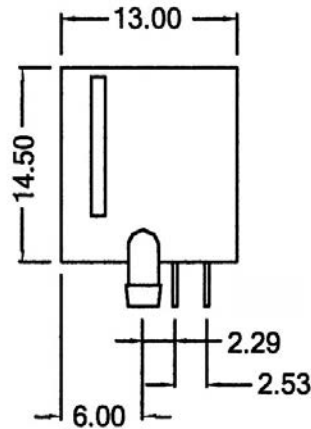
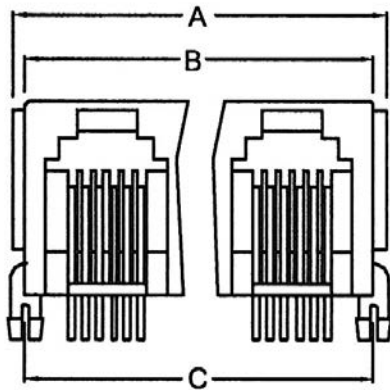
SIDE ENTRY MULTI-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout (TOP VIEW)

$$\begin{aligned}
 A &= 11.65 \times \text{Ports} + 2.50 \\
 B &= 11.65 \times \text{Ports} + 0.70 \\
 C &= 11.65 \times \text{Ports} + 0.50
 \end{aligned}$$

ORDERING INFORMATION:

P/N MJ3R - $\frac{xxxAxx}{1234}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
 "E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY (STANDARD)
 "B" BLACK

4. NO. OF PORTS:

02, 03, 04, 05, 06, 07, 08

SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

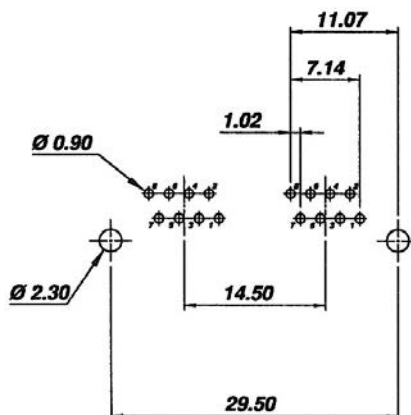
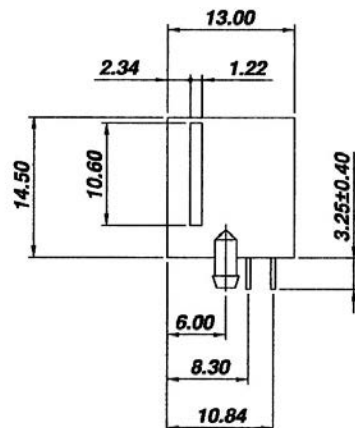
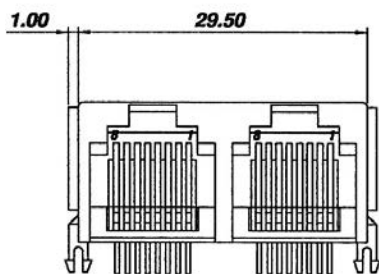
Soldering Temperature: 235°C

Color: Black & Gray

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 T - $\frac{88}{1} \times \frac{x}{23} \times \frac{02}{4}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY

"B" BLACK

4. NO. OF PORTS:

02

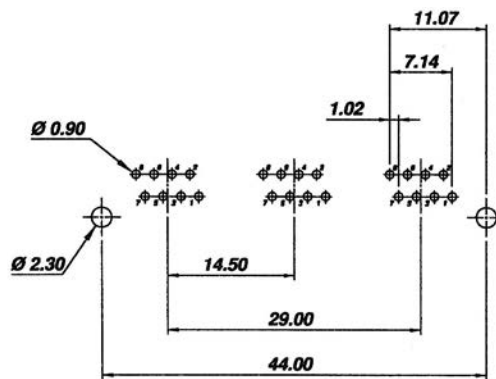
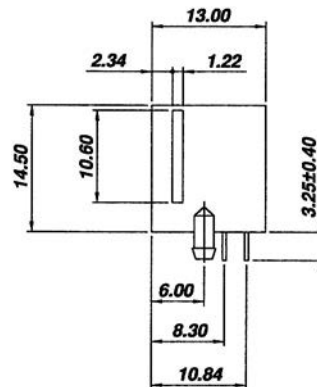
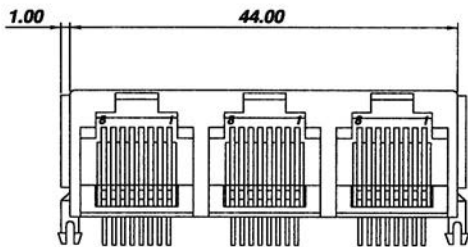
SIDE ENTRY 3-PORT UP LATCH MODULAR PCB JACK 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 T - $\frac{88}{1} \times \frac{x}{23} \times \frac{03}{4}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. HOUSING COLOR:
"A" GRAY
"B" BLACK
4. NO. OF PORTS:
03

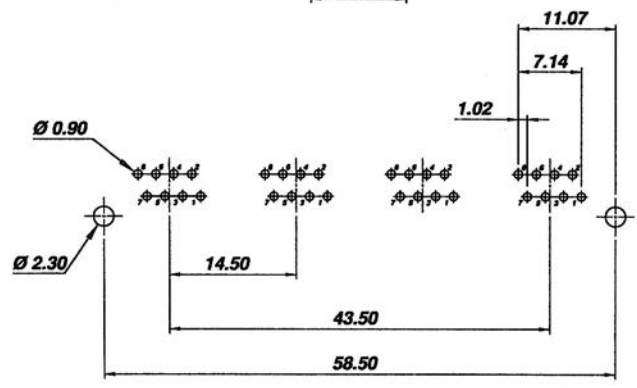
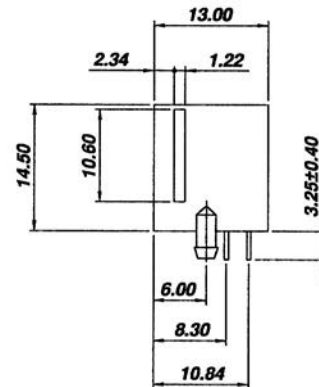
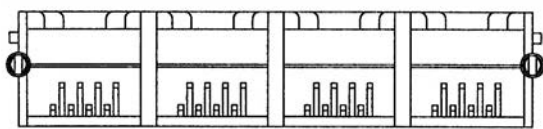
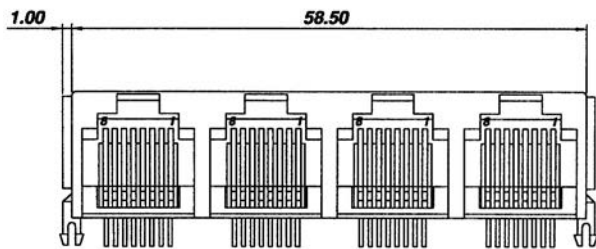
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout (TOP VIEW)

ORDERING INFORMATION:

P/N M J 6 T - $\frac{88}{1} \times \frac{3}{2} \times \frac{04}{4}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. HOUSING COLOR:
"A" GRAY
"B" BLACK
4. NO. OF PORTS:
04

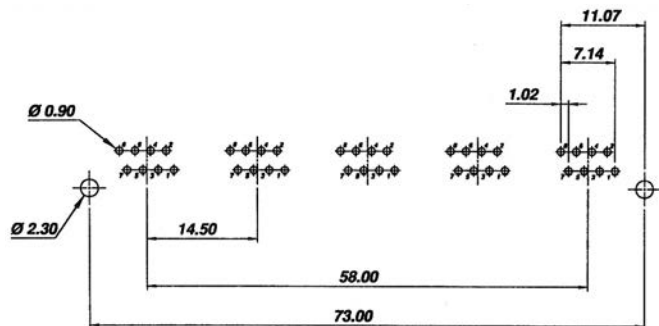
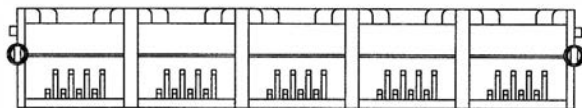
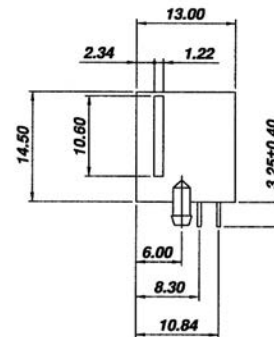
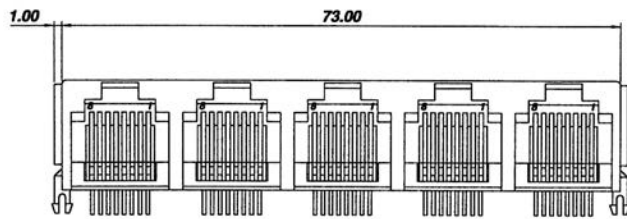
SIDE ENTRY 5-PORT UP LATCH MODULAR PCB JACK 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout (TOP VIEW)

ORDERING INFORMATION:

P/N MJ6T - $\frac{88}{1} \times \frac{3}{2} \times \frac{05}{4}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK
- NO. OF PORTS:
05

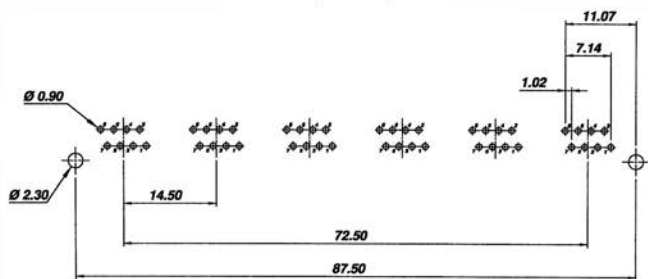
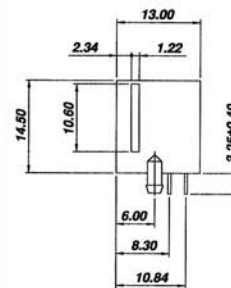
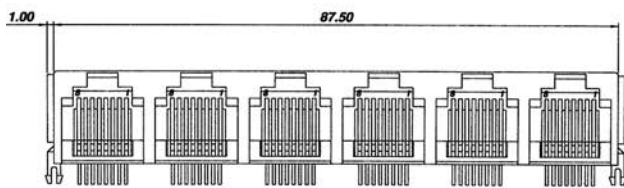
SIDE ENTRY 6-PORT UP LATCH MODULAR PCB JACK 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ6T - $\frac{88}{1} \times \frac{23}{3} \times \frac{06}{4}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. HOUSING COLOR:
"A" GRAY
"B" BLACK
4. NO. OF PORTS:
06

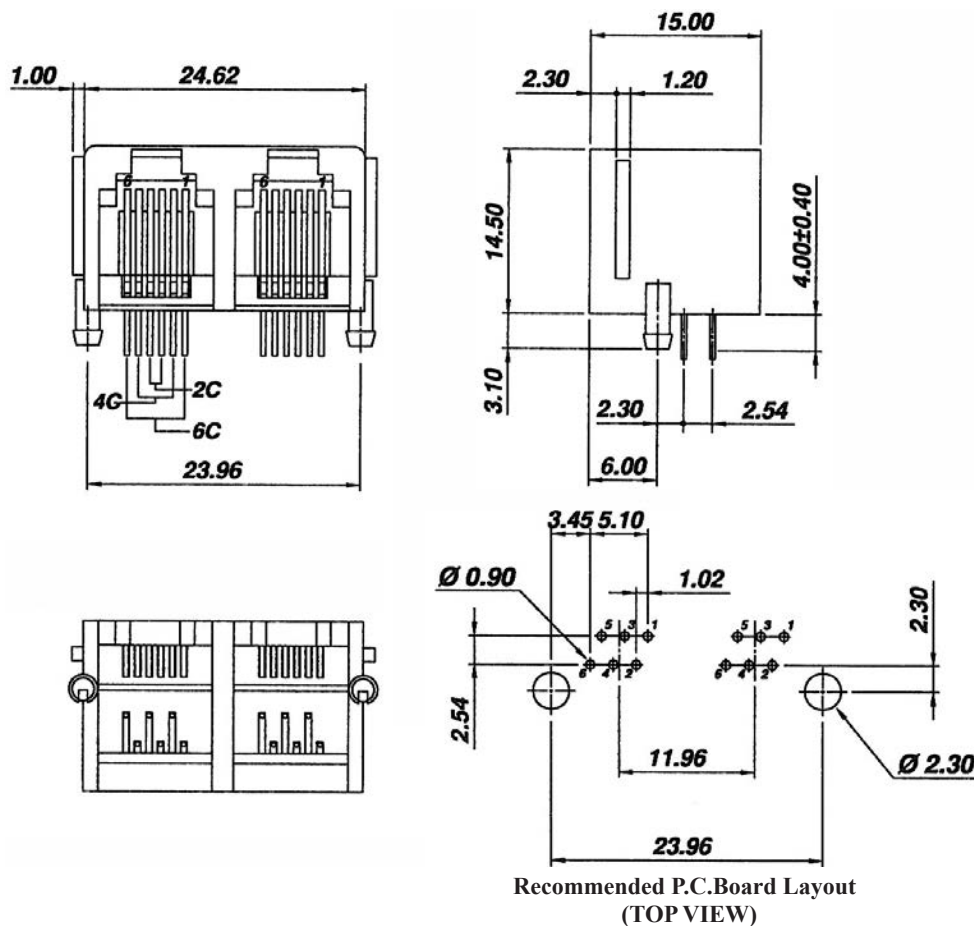
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ29 - $\frac{X}{1} \frac{X}{2} \frac{X}{3} \frac{X}{4} 02$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
"B" BLACK

4. NO. OF PORTS:

02

NOTE: P/N MJ29HT-xxxx02 FOR HIGH TEMP. VERSION

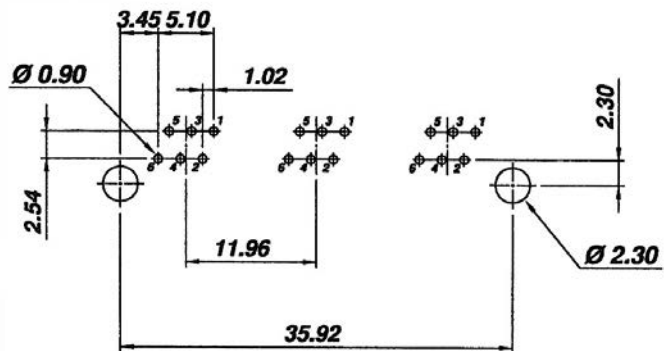
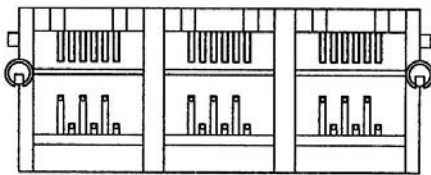
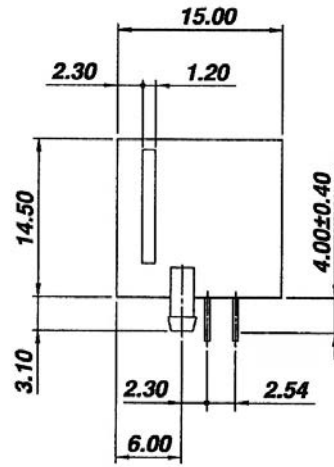
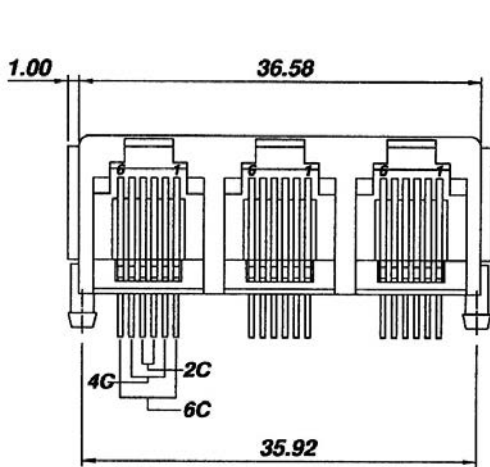
SIDE ENTRY 3-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout (TOP VIEW)

ORDERING INFORMATION:

P/N MJ29 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} 03$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

03

NOTE: P/N MJ29HT-xxxx03 FOR HIGH TEMP. VERSION

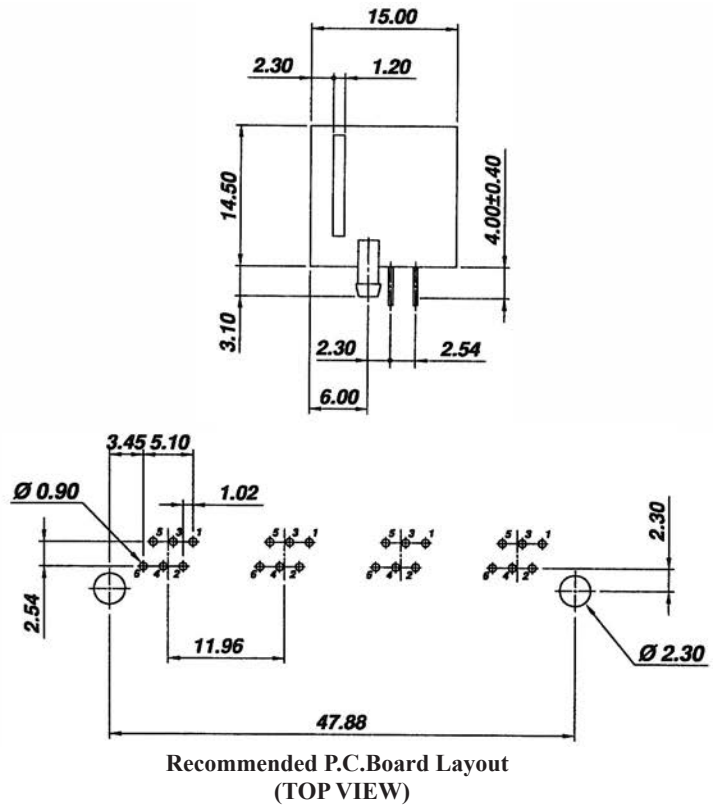
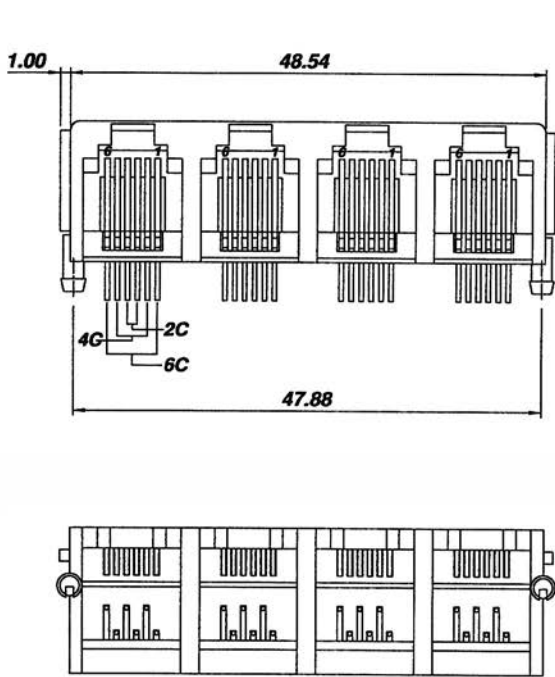
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ29 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{04}{4}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

04

NOTE: P/N MJ29HT-xxxx04 FOR HIGH TEMP. VERSION

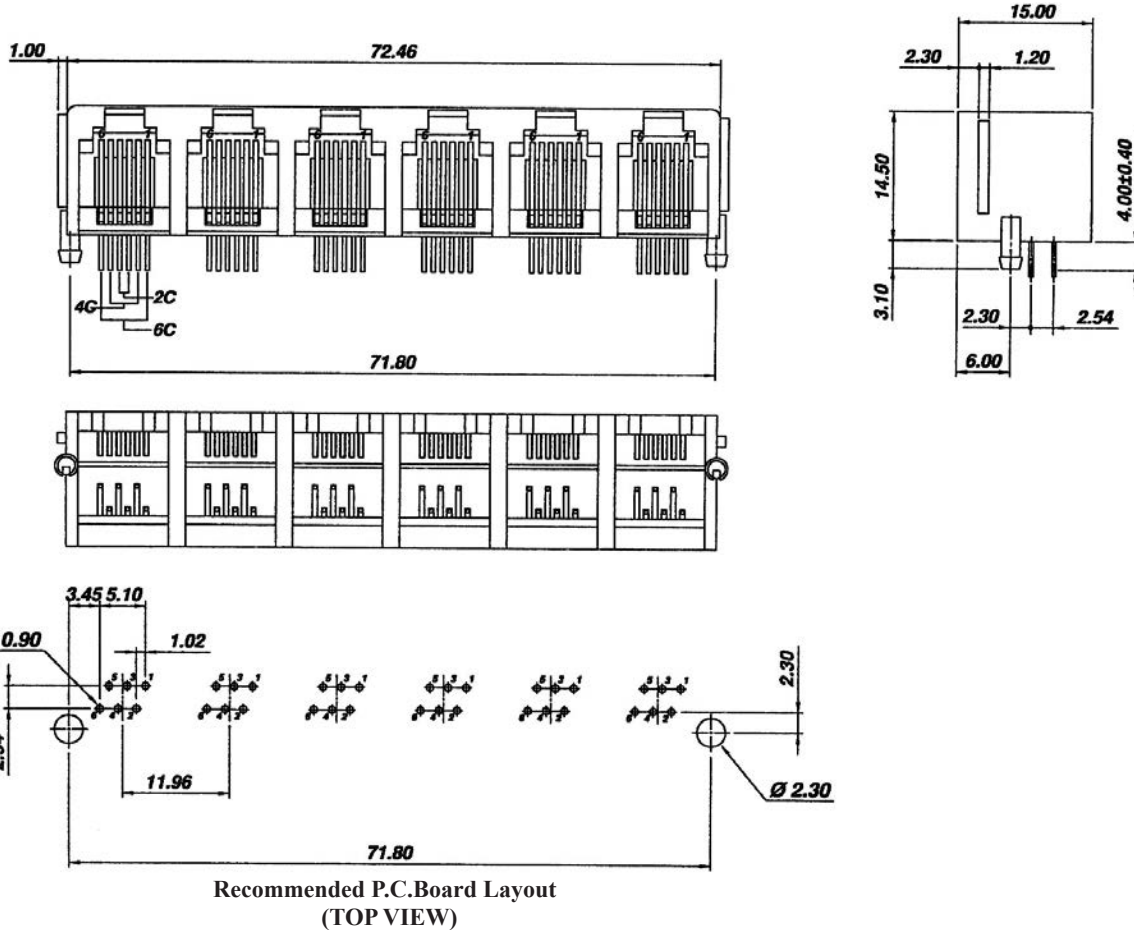
SIDE ENTRY 6-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
 Soldering Temperature: 235°C
 Color: Black & Gray
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ29 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} 06$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

06

NOTE: P/N MJ29HT-xxxx06 FOR HIGH TEMP. VERSION

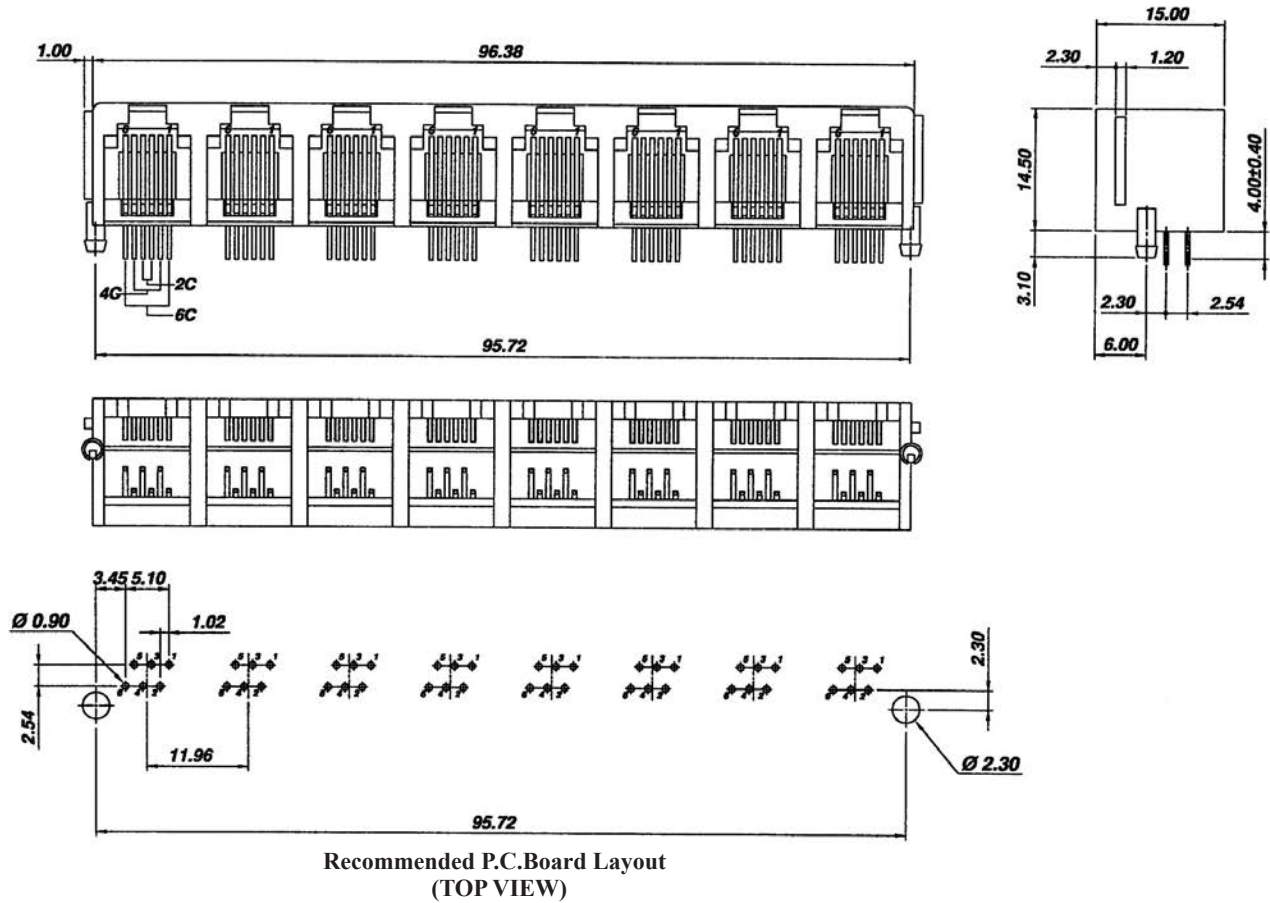
SIDE ENTRY 8-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ29 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} 08$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY
 "B" BLACK

4. NO. OF PORTS:

08

NOTE: P/N MJ29HT-xxxx08 FOR HIGH TEMP. VERSION

SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

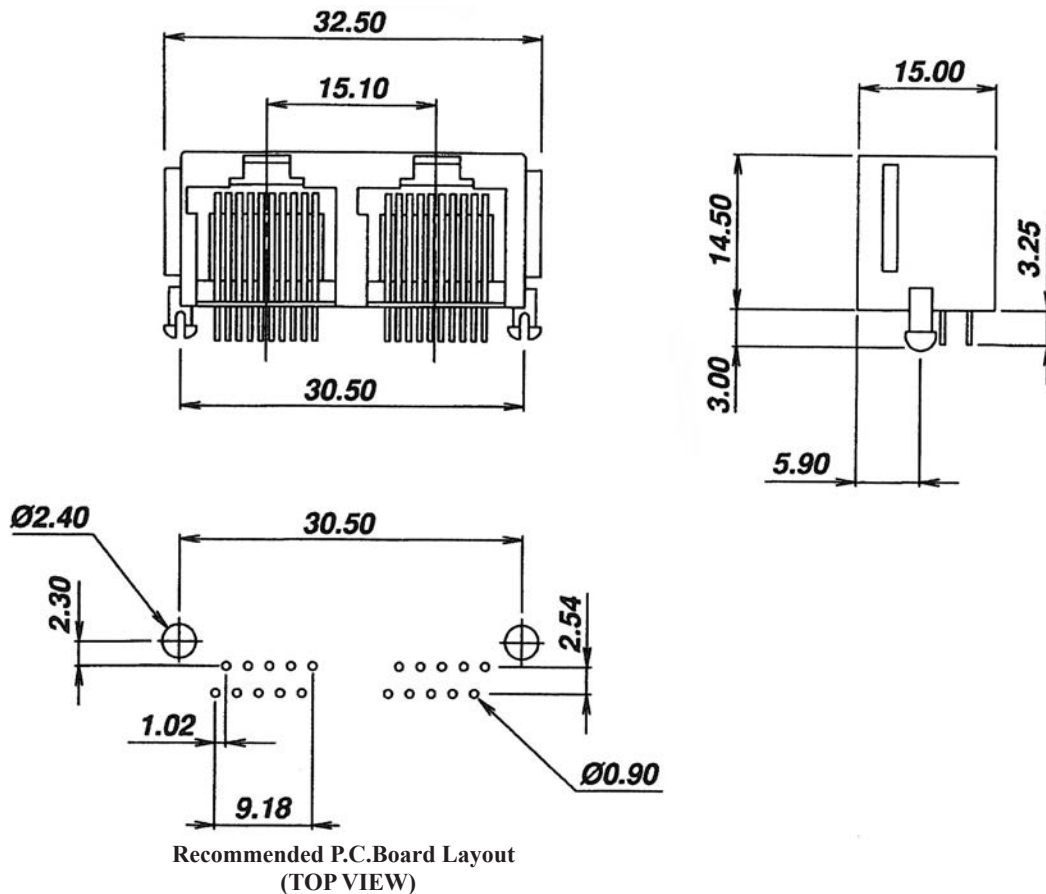
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ29 - $\frac{xx}{1} \frac{xx}{2} \frac{B02}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"88" 8P8C (= 10P8C)

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: P/N MJ29HT-xxxB02 FOR HIGH TEMP. VERSION

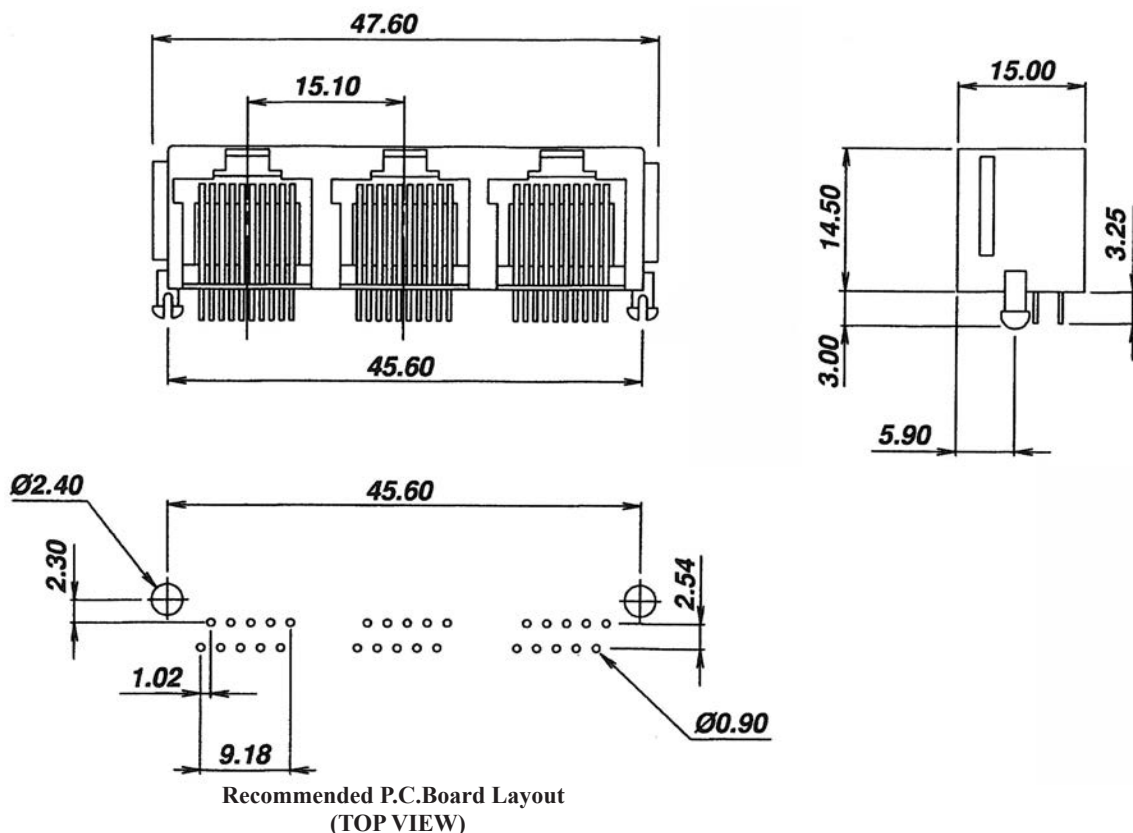
SIDE ENTRY 3-PORT UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ29 - $\frac{xx}{1} \frac{xx}{2} \frac{B}{3} 03$

1. NO. OF POSITIONS & CONTACTS:
 "00" 10P10C
 "88" 8P8C (= 10P8C)
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. NO. OF PORTS:
 03

NOTE: P/N MJ29HT-xxxB03 FOR HIGH TEMP. VERSION

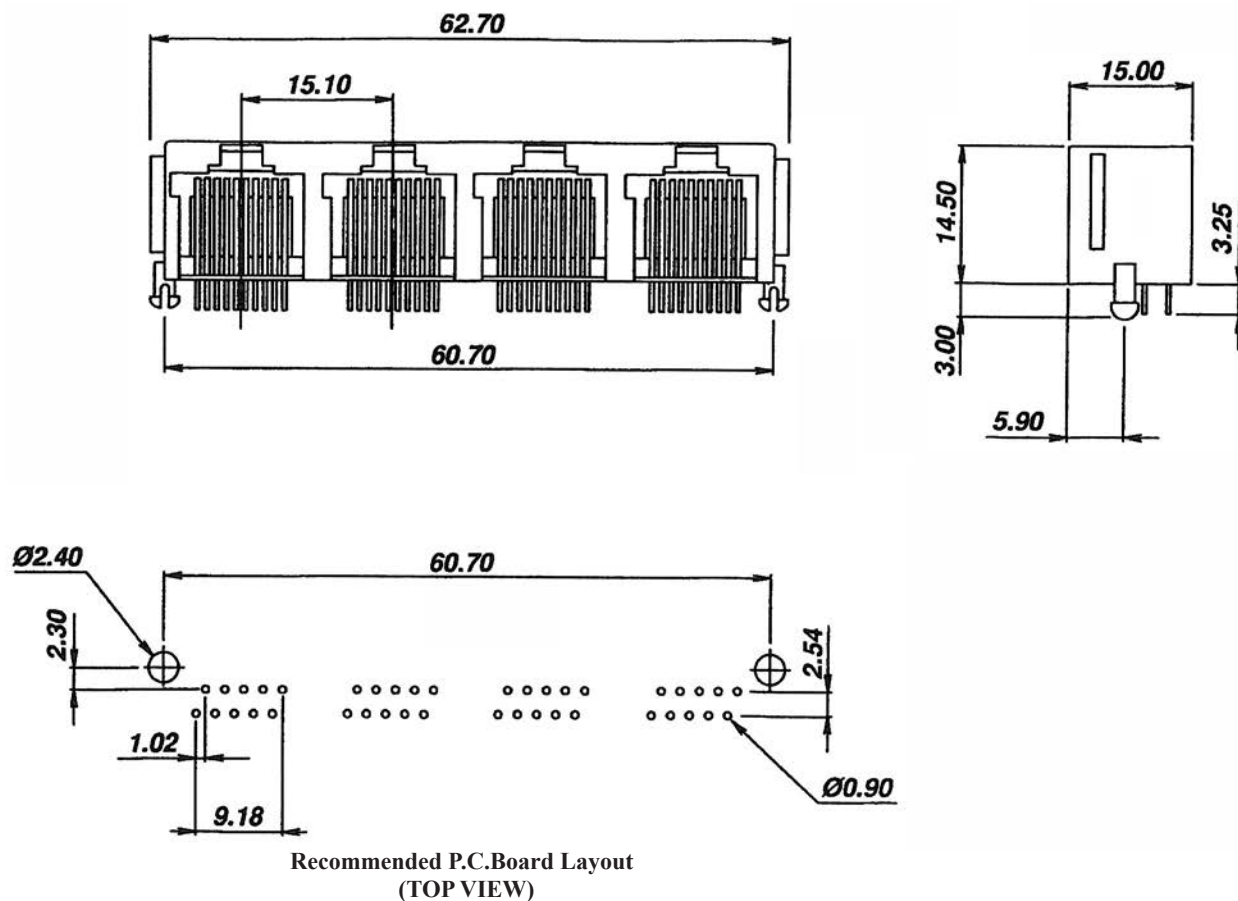
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ29 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B \frac{0}{3} 4$

1. NO. OF POSITIONS & CONTACTS:
 "00" 10P10C
 "88" 8P8C (= 10P8C)
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. NO. OF PORTS:
 04

NOTE: P/N MJ29HT-xxxB04 FOR HIGH TEMP. VERSION

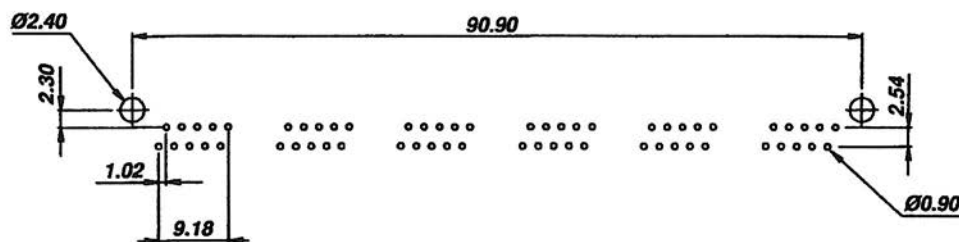
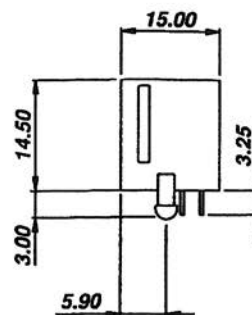
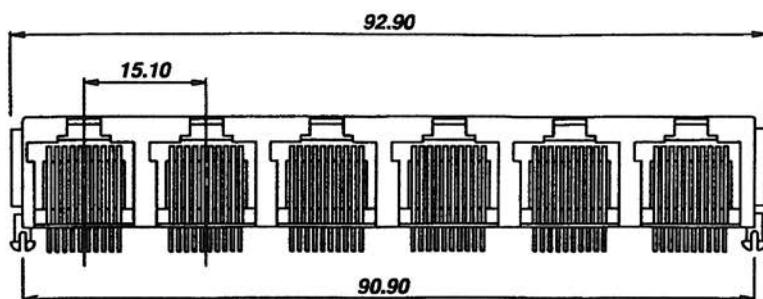
SIDE ENTRY 6-PORT UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ 2 9 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 6$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C
 "88" 8P8C (= 10P8C)

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. NO. OF PORTS:

06

NOTE: P/N MJ29HT-xxxB06 for High Temp. Version

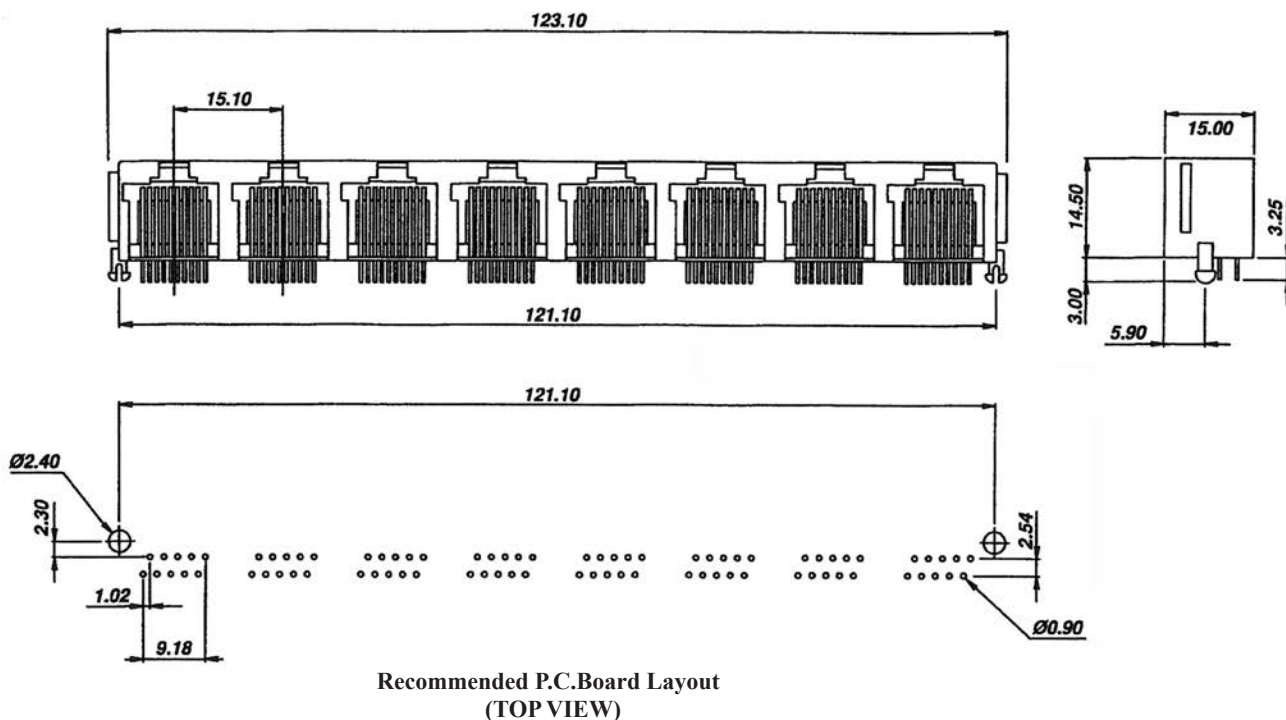
SIDE ENTRY 8-PORT UP LATCH MODULAR PCB JACK 8P+10P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ29 - $\frac{xx}{1} \frac{xx}{2} \frac{B08}{3}$

1. NO. OF POSITIONS & CONTACTS:
 "00" 10P10C
 "88" 8P8C (= 10P8C)
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. NO. OF PORTS:
 08

NOTE: P/N MJ29HT-xxxB08 FOR HIGH TEMP. VERSION

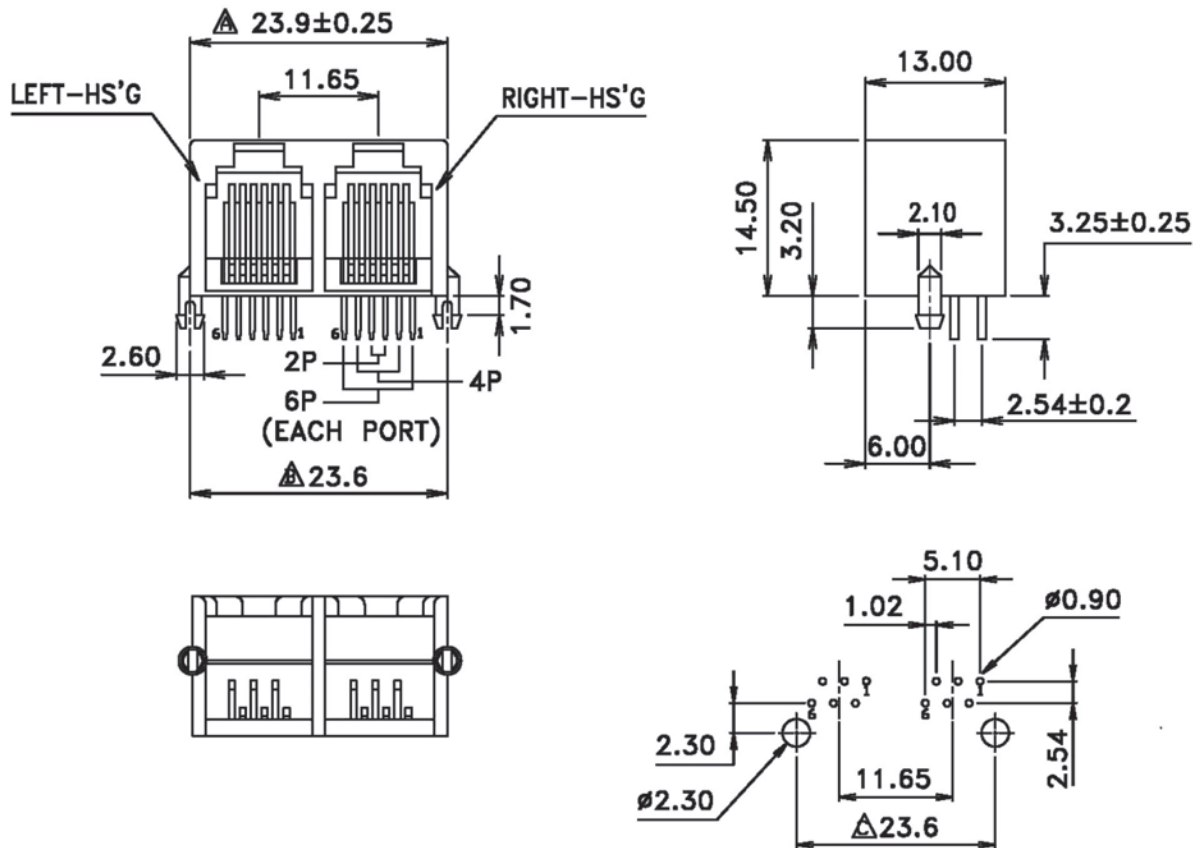
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N $M J \frac{V T}{1} - \frac{66}{2} \times \frac{x}{3} \times \frac{02}{45}$

- | | |
|---|------------------------|
| 1. MODULAR JACK TYPE:
"VT" MINI LOW PROFILE TYPE | 5. NO. OF PORTS:
02 |
| 2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C | |
| 3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD | |
| 4. HOUSING COLOR:
"A" GRAY
"B" BLACK | |

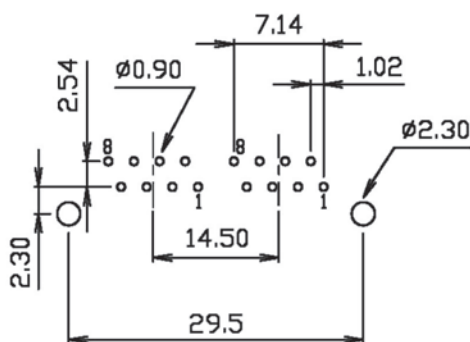
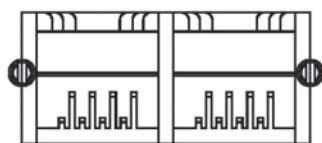
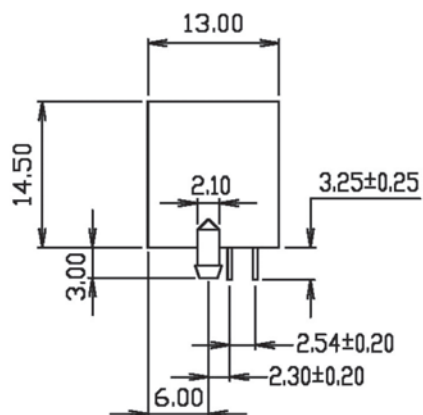
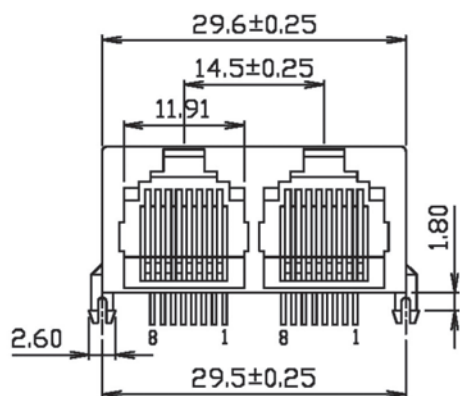
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{VT}{1}$ - $\frac{88}{2}$ $\frac{x}{3}$ $\frac{x}{4}$ $\frac{02}{5}$

- MODULAR JACK TYPE:
"VT" MINI LOW PROFILE TYPE
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
"84" 8P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK

- NO. OF PORTS:
02

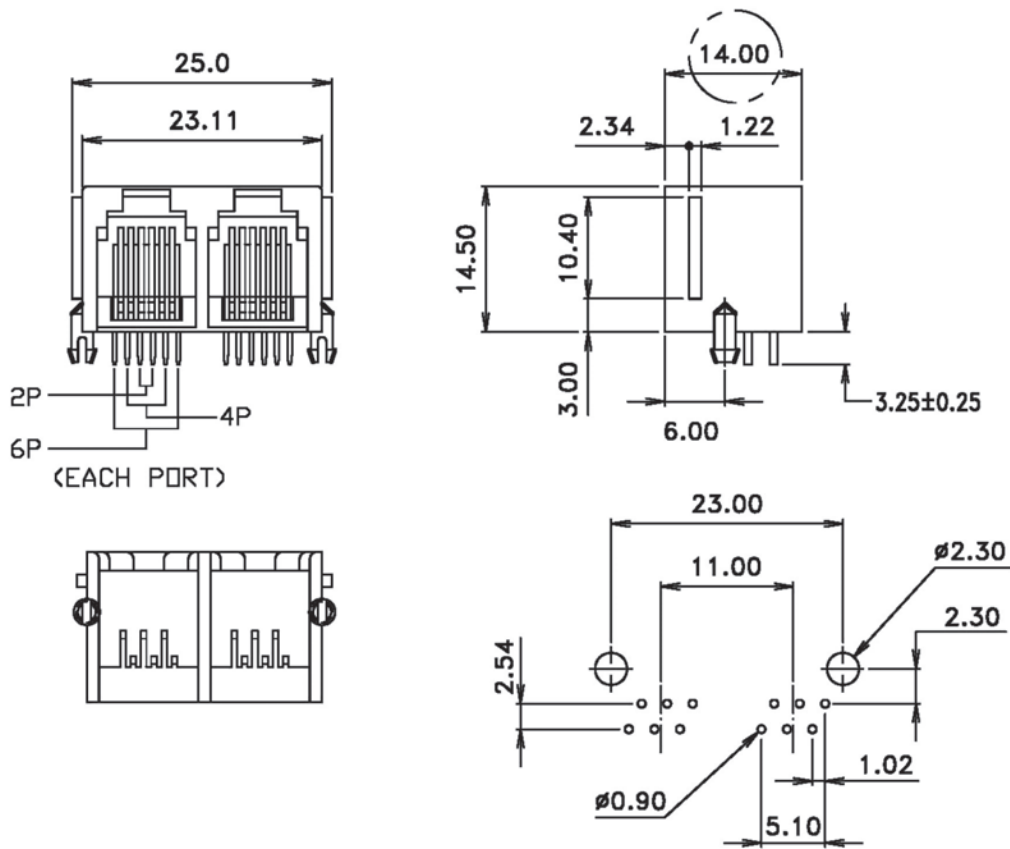
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

- Insulation Resistance:** 500MΩ Min.
- Contact Resistance:** 20mΩ Max.
- Rating Current:** 1.5A Max.
- Rating Voltage:** 120V AC.
- Dielectric Voltage:** 1000 Vrms 60 Sec. Min.
- Temperature Range:** -40°C / +85°C
- Durability:** 500 Mating cycles Min.

MATERIALS

- Housing:** PBT Glass Filled (UL 94V-0)
- Soldering Temperature:** 235°C
- Color:** Black
- Spring Wire:** Phosphor Bronze
Gold plating Over Nickel
- *RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N **M J $\frac{VV}{I} - \frac{66}{2} \times \frac{x}{34} \frac{02}{5}$**

- | | |
|--|---|
| <ol style="list-style-type: none"> 1. MODULAR JACK TYPE:
"VV" MINI LOW PROFILE TYPE W=14.00MM 2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C 3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD 4. HOUSING COLOR:
"A" GRAY
"B" BLACK | <ol style="list-style-type: none"> 5. NO. OF PORTS:
02 |
|--|---|

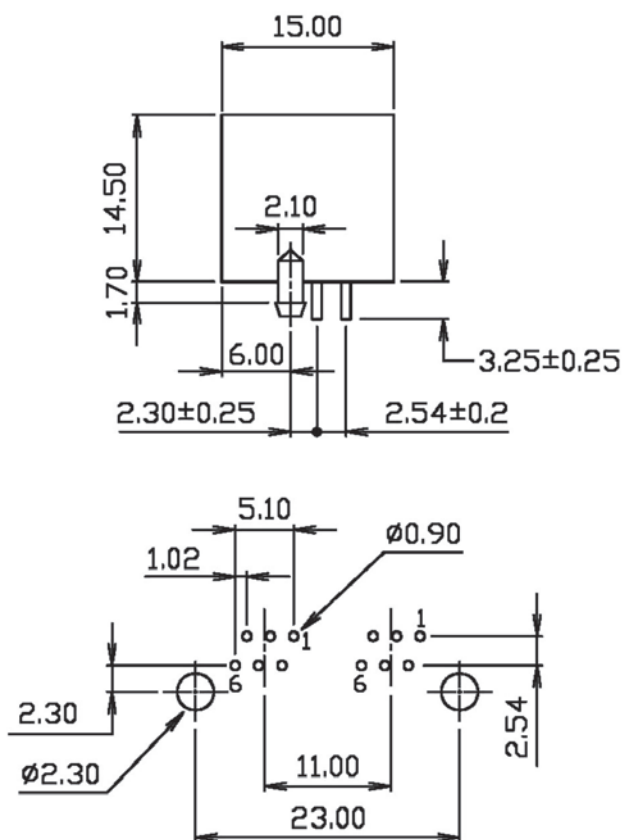
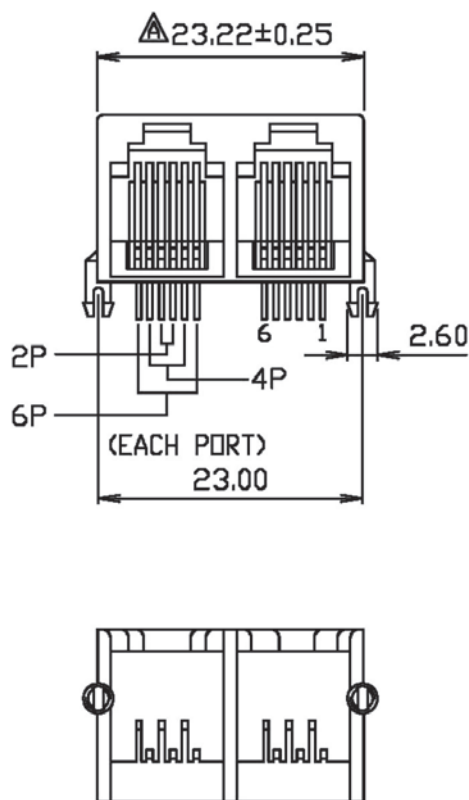
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N **M J V W - 66 x x 02**
 $\frac{1}{2} \frac{3}{4} \frac{5}{5}$

1. MODULAR JACK TYPE:
"VW" FLANGELESS LOW PROFILE TYPE
2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"A" GRAY
"B" BLACK

5. NO. OF PORTS:
02

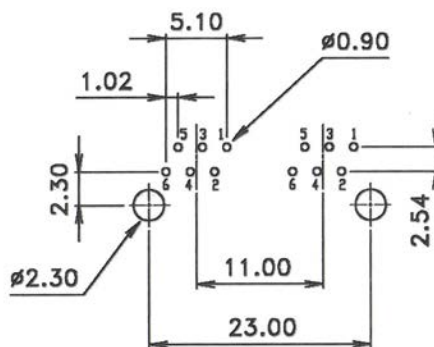
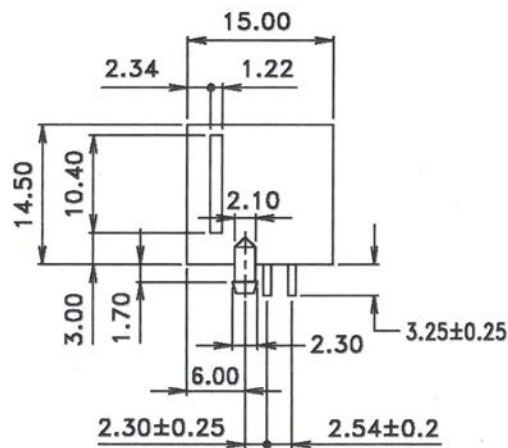
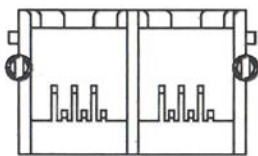
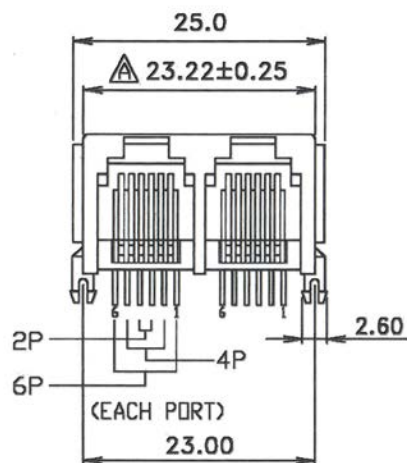
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{V X}{1}$ - $\frac{6 6}{2}$ $\frac{x x}{3 4}$ $\frac{0 2}{5}$

- | | |
|---|------------------------|
| 1. MODULAR JACK TYPE:
"VX" FLANGED LOW PROFILE TYPE | 5. NO. OF PORTS:
02 |
| 2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C | |
| 3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD | |
| 4. HOUSING COLOR:
"A" GRAY
"B" BLACK | |

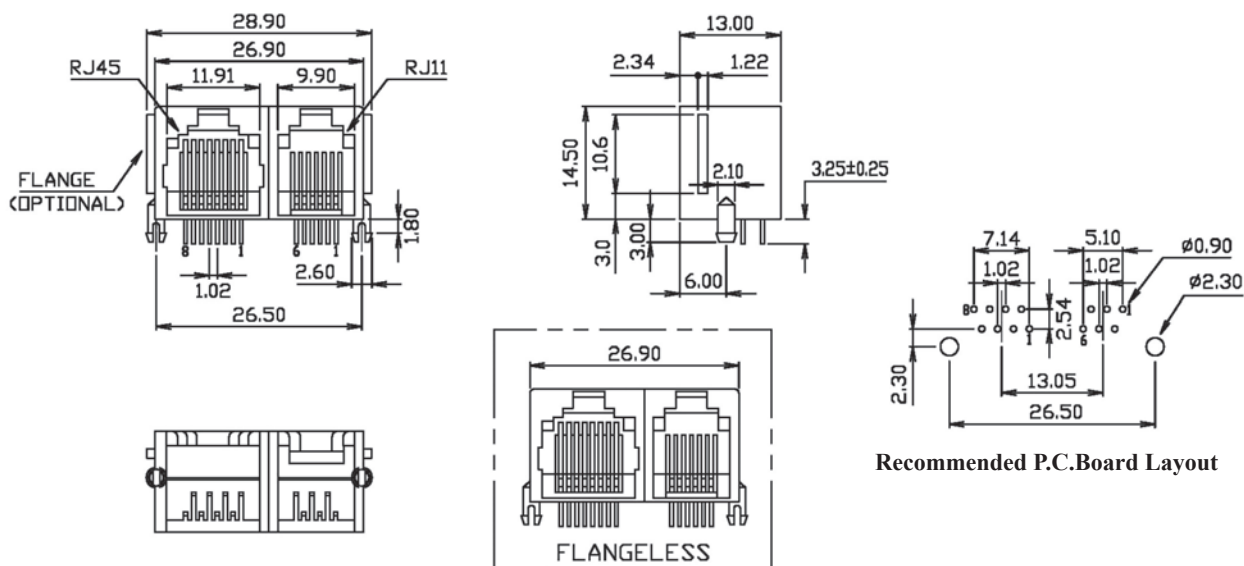
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK 6P+8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - 68 $\frac{xx}{2}$ $\frac{xx}{3}$ $\frac{xx}{4}$ $\frac{02}{5}$

- | | |
|---|------------------------|
| 1. MODULAR JACK TYPE:
"KV" FLANGED
"KW" FLANGELESS | 5. NO. OF PORTS:
02 |
| 2. NO. OF POSITIONS & CONTACTS:
"68" 6P6C + 8P8C | |
| 3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD | |
| 4. HOUSING COLOR:
"A" GRAY
"B" BLACK | |

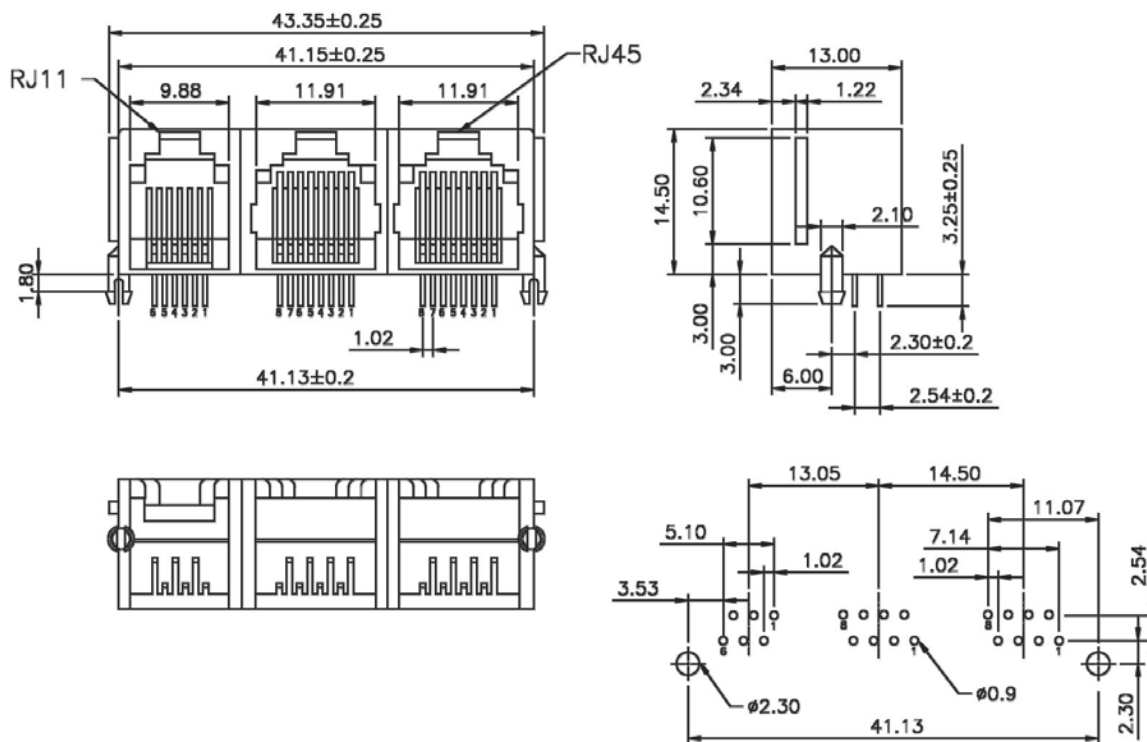
SIDE ENTRY 3-PORT UP LATCH MODULAR PCB JACK 6P+8P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - 68 $\frac{xx}{2}$ $\frac{xx}{3}$ $\frac{03}{4}$ $\frac{5}{5}$

1. MODULAR JACK TYPE:

"KV" FLANGED
"KW" FLANGELESS

2. NO. OF POSITIONS & CONTACTS:

"68" 6P6C + 2 x 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

4. HOUSING COLOR:

"A" GRAY
"B" BLACK

5. NO. OF PORTS:

03

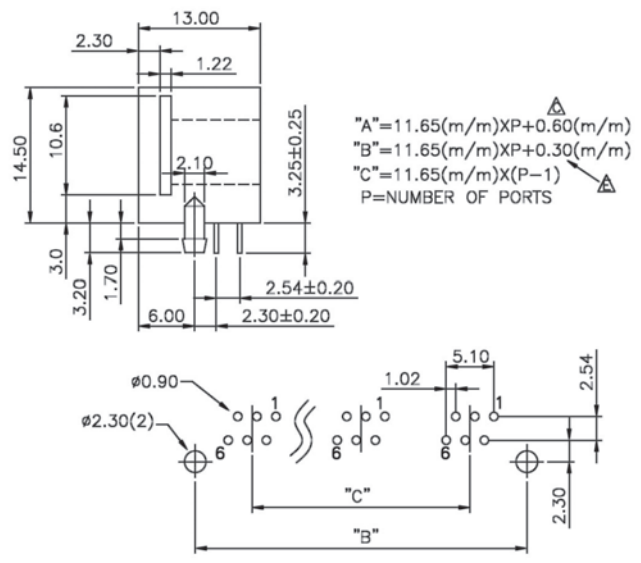
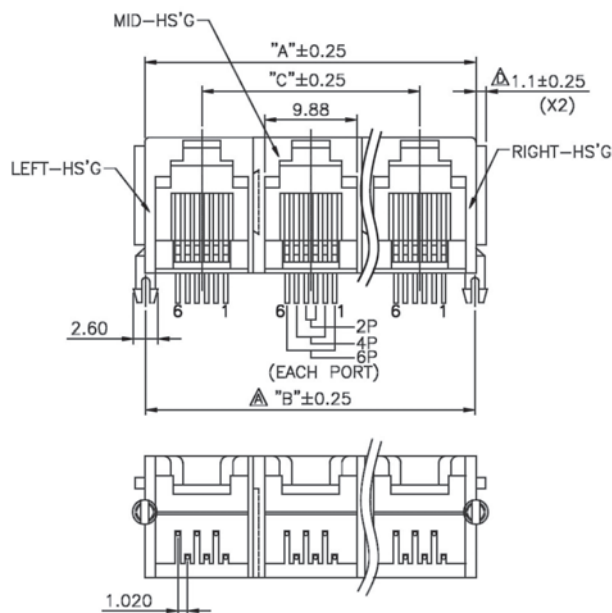
SIDE ENTRY MULTI-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=14.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{V}{1}$ U - $\frac{6}{2}$ $\frac{6}{3}$ $\frac{x}{4}$ $\frac{x}{5}$

- | | |
|--|---|
| <ol style="list-style-type: none"> 1. MODULAR JACK TYPE:
"VU" MINI LOW PROFILE TYPE 2. NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C 3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD 4. HOUSING COLOR:
"A" GRAY
"B" BLACK | <ol style="list-style-type: none"> 5. NO. OF PORTS:
02, 03, 04, 05, 06, 07, 08 |
|--|---|

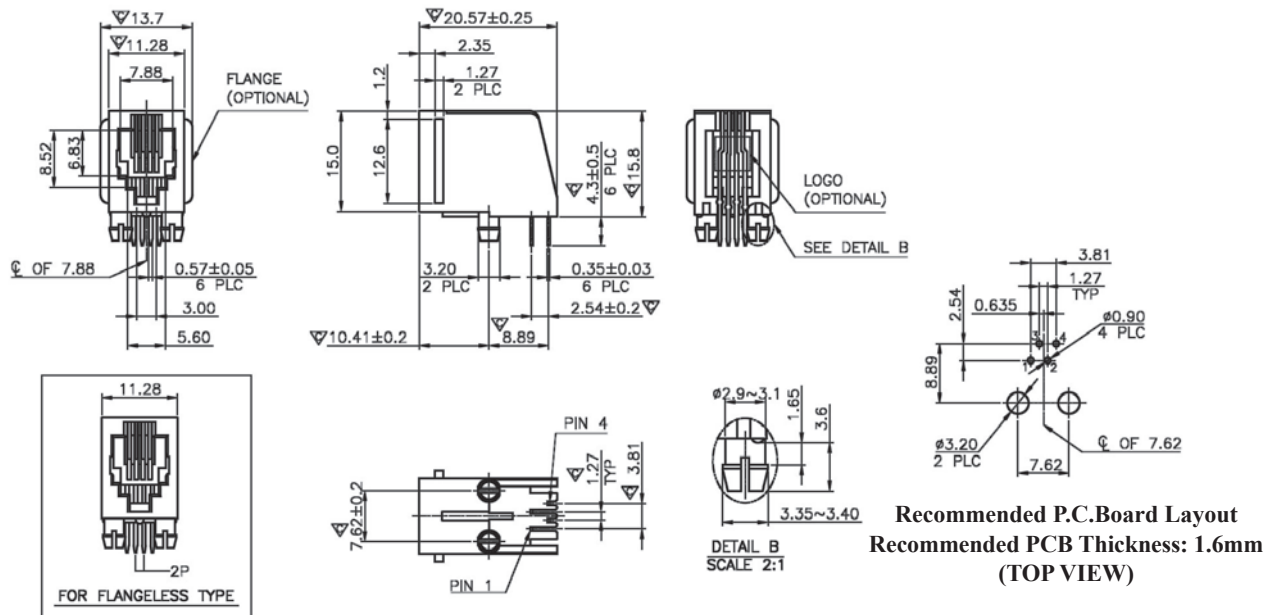
SIDE ENTRY MODULAR PCB JACK 4P PROFILE=15.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
Recommended PCB Thickness: 1.6mm
(TOP VIEW)

ORDERING INFORMATION:

P/N M J $\frac{X X}{1} - \frac{4 4}{2} \frac{X B}{3 4}$

1. MODULAR JACK TYPE:
 "VF" FLANGED WITH SPLIT PEGS
 "VG" FLANGELESS WITH SPLIT PEGS
2. NO. OF POSITIONS & CONTACTS:
 "44" 4P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
4. HOUSING COLOR:
 "B" BLACK

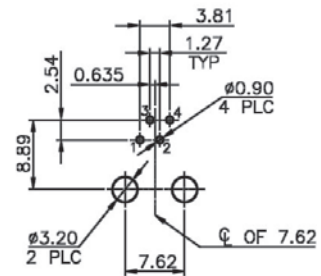
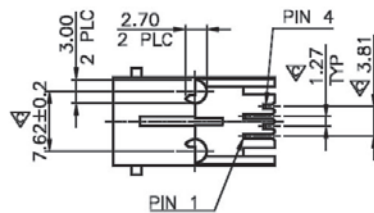
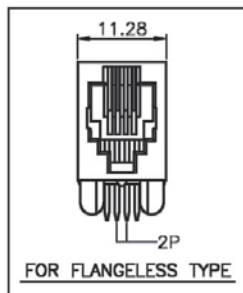
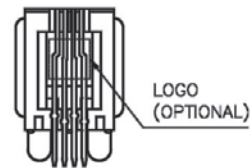
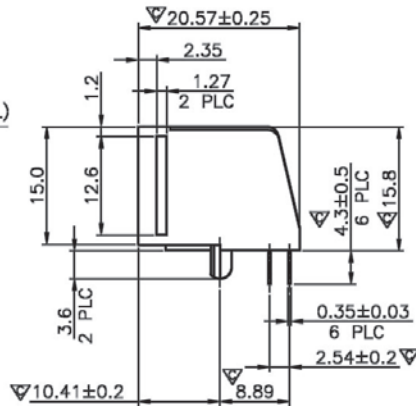
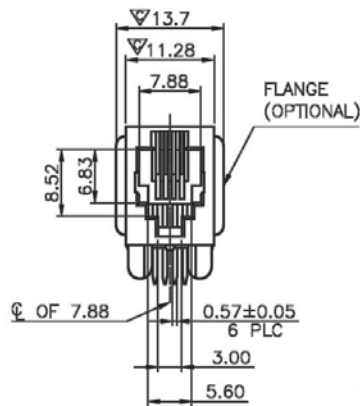
SIDE ENTRY MODULAR PCB JACK 4P PROFILE=15.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout
Recommended PCB Thickness: 1.6mm
(TOP VIEW)

ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - 4 4 $\frac{x}{2}$ $\frac{x}{3}$ $\frac{x}{4}$ B

- MODULAR JACK TYPE:
 "VH" FLANGED WITH ROUND PEGS
 "VJ" FLANGELESS WITH ROUND PEGS
- NO. OF POSITIONS & CONTACTS:
 "44" 4P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- HOUSING COLOR:
 "B" BLACK

SIDE ENTRY MODULAR PCB JACK DEC TYPE 6P PROFILE=15.20MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500M Ω Min.

Contact Resistance: 20m Ω Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40 $^{\circ}$ C / +85 $^{\circ}$ C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

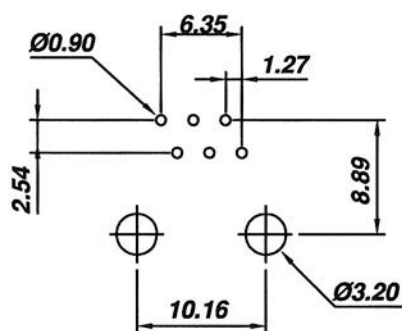
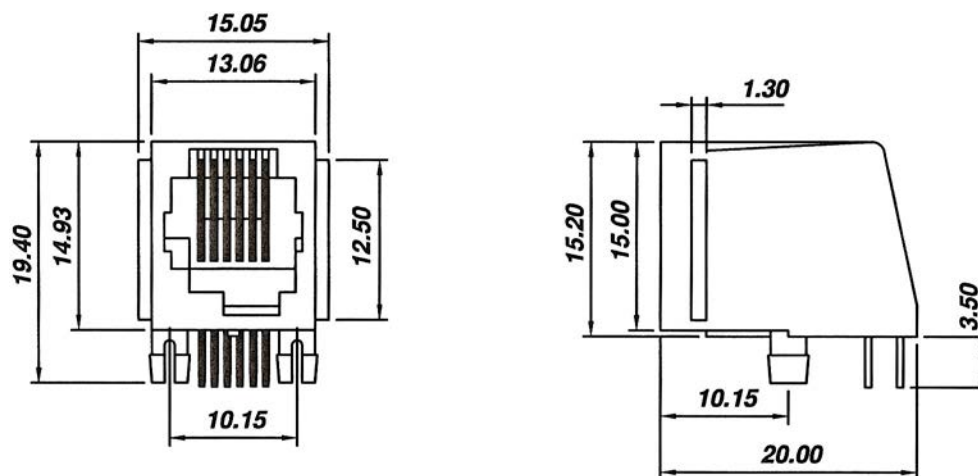
Soldering Temperature: 235 $^{\circ}$ C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J L D - $\frac{x}{T} \frac{x}{2} B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

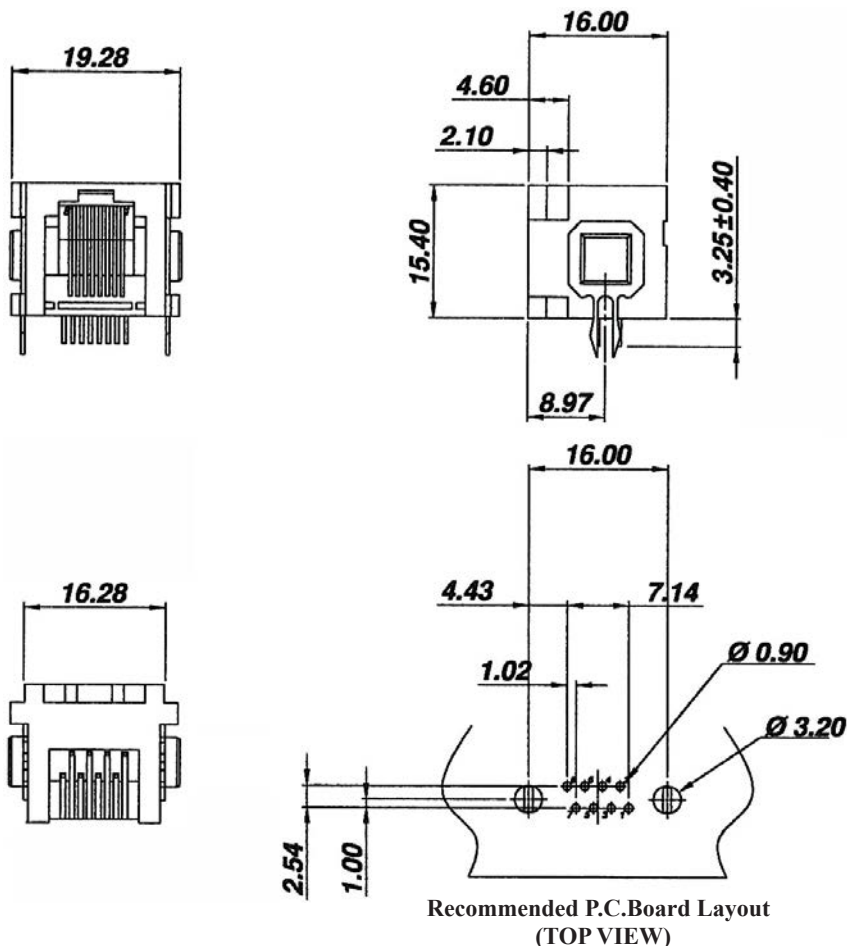
SIDE ENTRY 1-PORT UP LATCH MODULAR PCB JACK WITH METAL PEGS 8P PROFILE=15.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6L - $\frac{88}{1} \times \frac{x}{2} \times \frac{01}{34}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. HOUSING COLOR:
"A" GRAY
"B" BLACK
4. NO. OF PORTS:
01

NOTE: P/N MJ6LHT-88xx01 FOR HIGH TEMP. VERSION

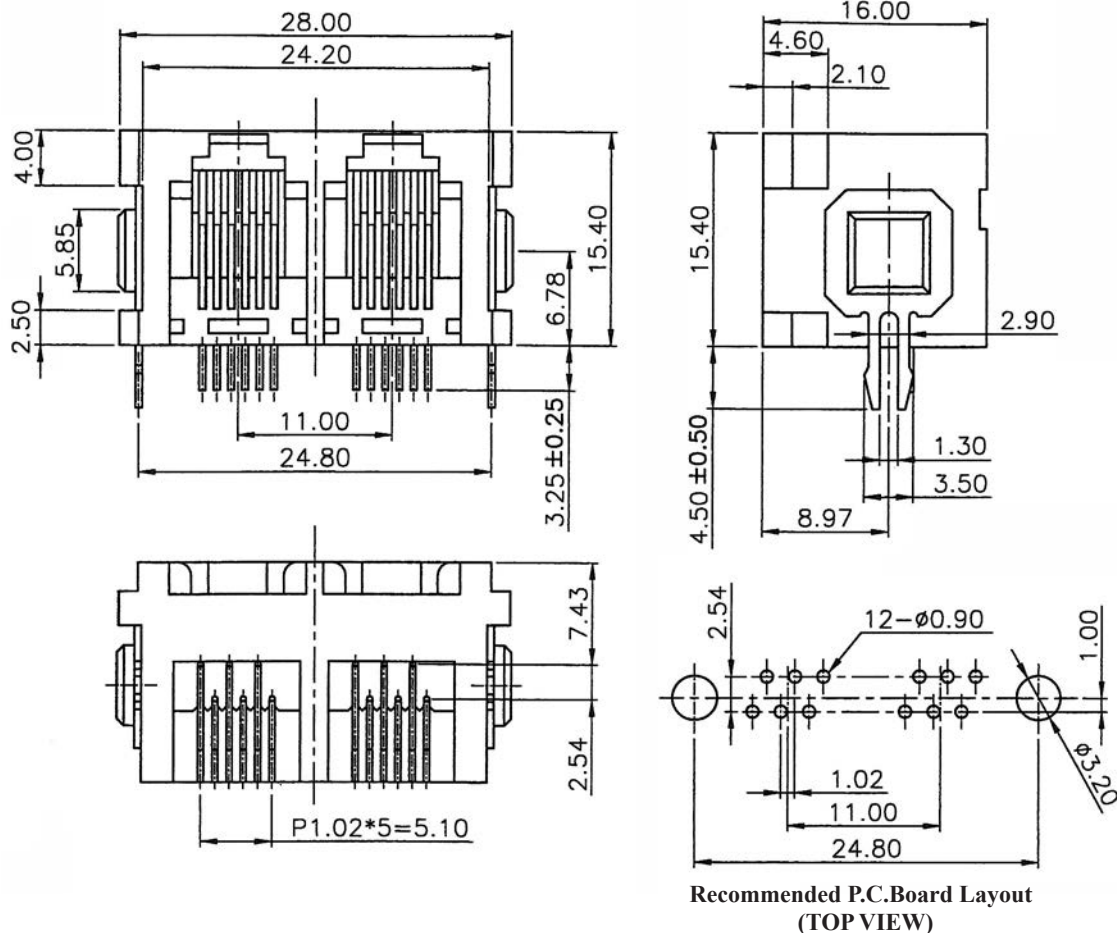
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH METAL PEGS 6P PROFILE=15.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ78 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4} 02$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" GOLD FLASH

3. HOUSING COLOR:

"A" GRAY (STANDARD)
"B" BLACK

4. NO. OF PORTS:

02

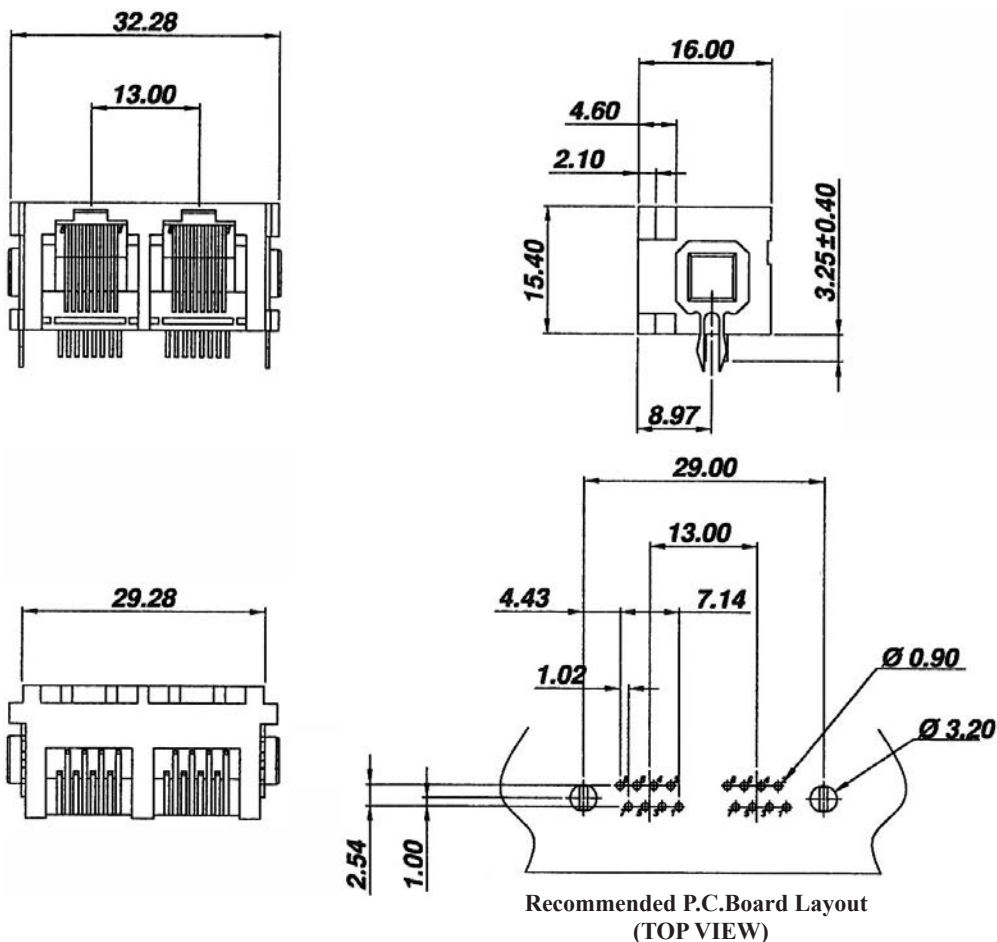
SIDE ENTRY 2-PORT UP LATCH MODULAR PCB JACK WITH METAL PEGS 8P PROFILE=15.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6L - $\frac{88}{1} \times \frac{2}{3} \times \frac{02}{4}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. HOUSING COLOR:
"A" GRAY
"B" BLACK
4. NO. OF PORTS:
02

NOTE: P/N MJ6LHT-88xx02 FOR HIGH TEMP. VERSION

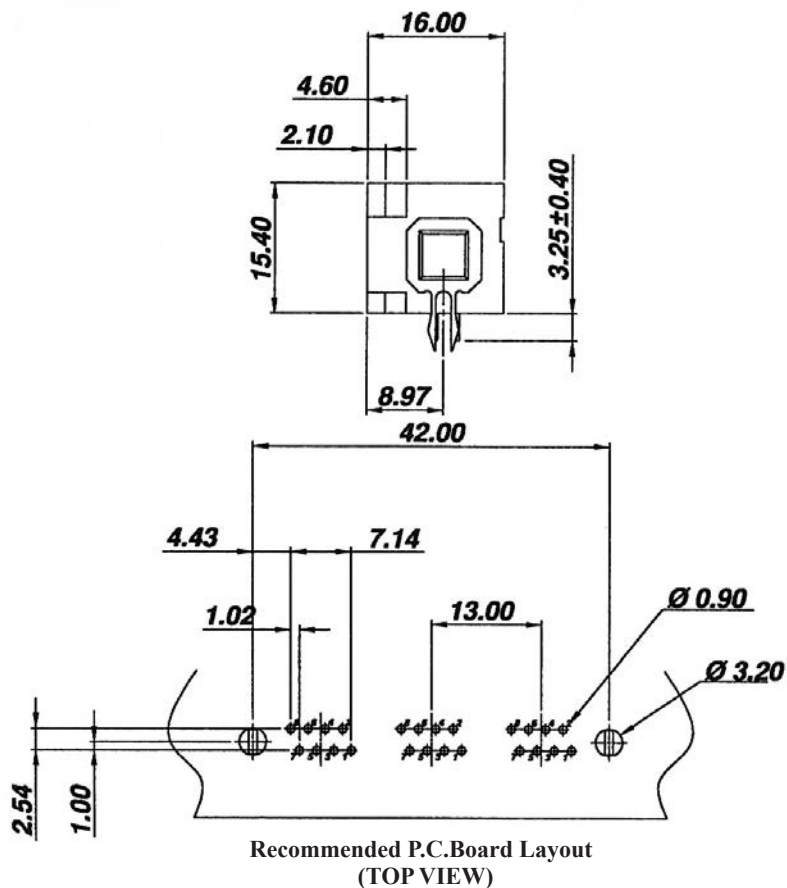
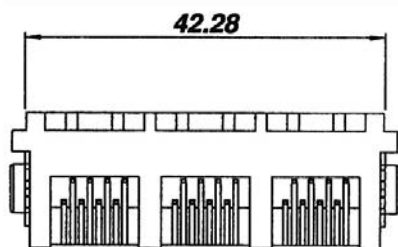
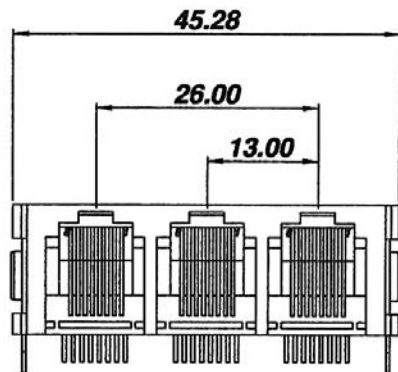
SIDE ENTRY 3-PORT UP LATCH MODULAR PCB JACK WITH METAL PEGS 8P PROFILE=15.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ6L - $\frac{88}{1} \times \frac{x}{2} \times \frac{03}{34}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. HOUSING COLOR:
"A" GRAY
"B" BLACK
4. NO. OF PORTS:
03

NOTE: P/N MJ6LHT-88xx03 FOR HIGH TEMP. VERSION

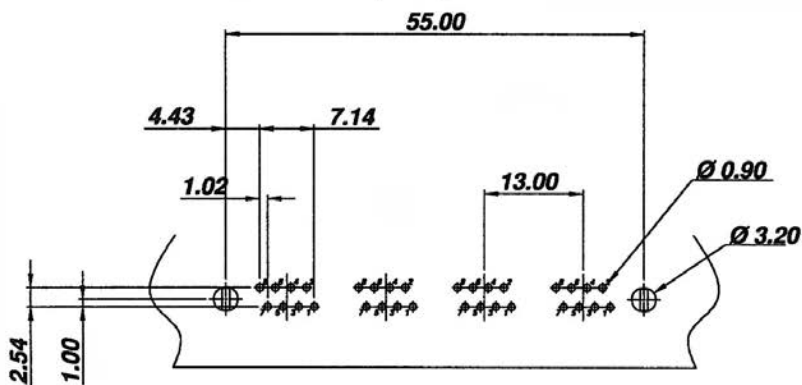
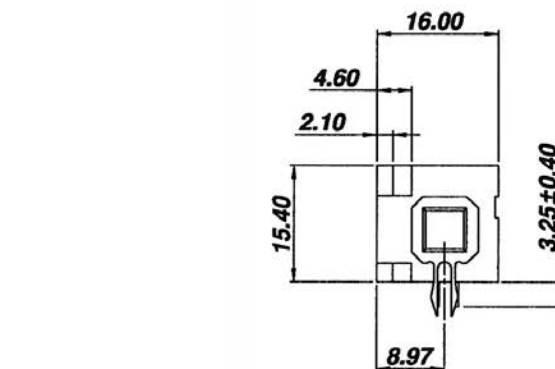
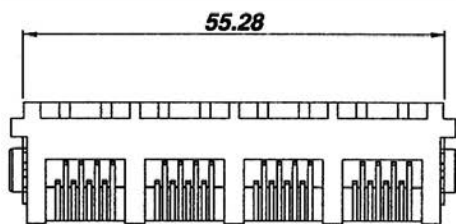
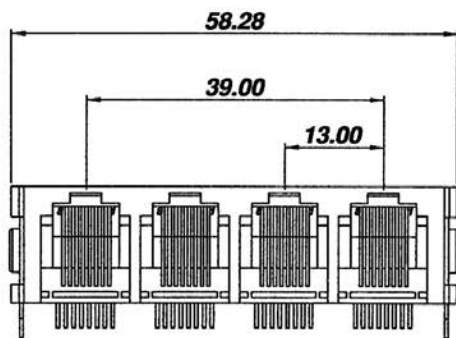
SIDE ENTRY 4-PORT UP LATCH MODULAR PCB JACK WITH METAL PEGS 8P PROFILE=15.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black & Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N MJ6L - $\frac{88}{1} \times \frac{x}{2} \times \frac{04}{34}$

- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"A" GRAY
"B" BLACK
- NO. OF PORTS:
04

NOTE: P/N MJ6LHT-88xx04 FOR HIGH TEMP. VERSION

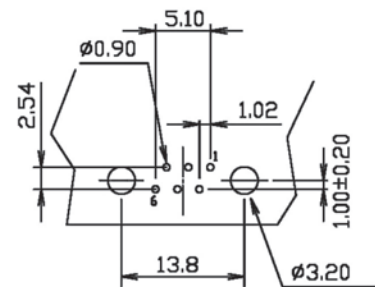
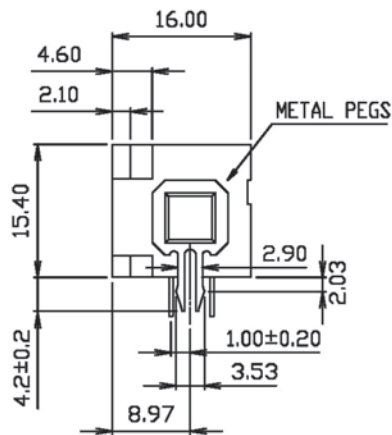
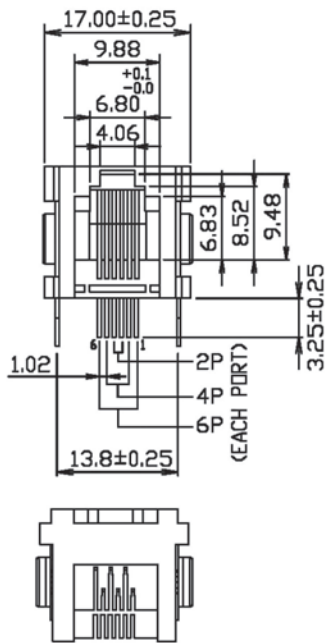
SIDE ENTRY UP LATCH MODULAR PCB JACK 6P PROFILE=15.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N **M J VA - 66 x B 01**

- MODULAR JACK TYPE:
"VA" WITH METAL PEGS
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
01

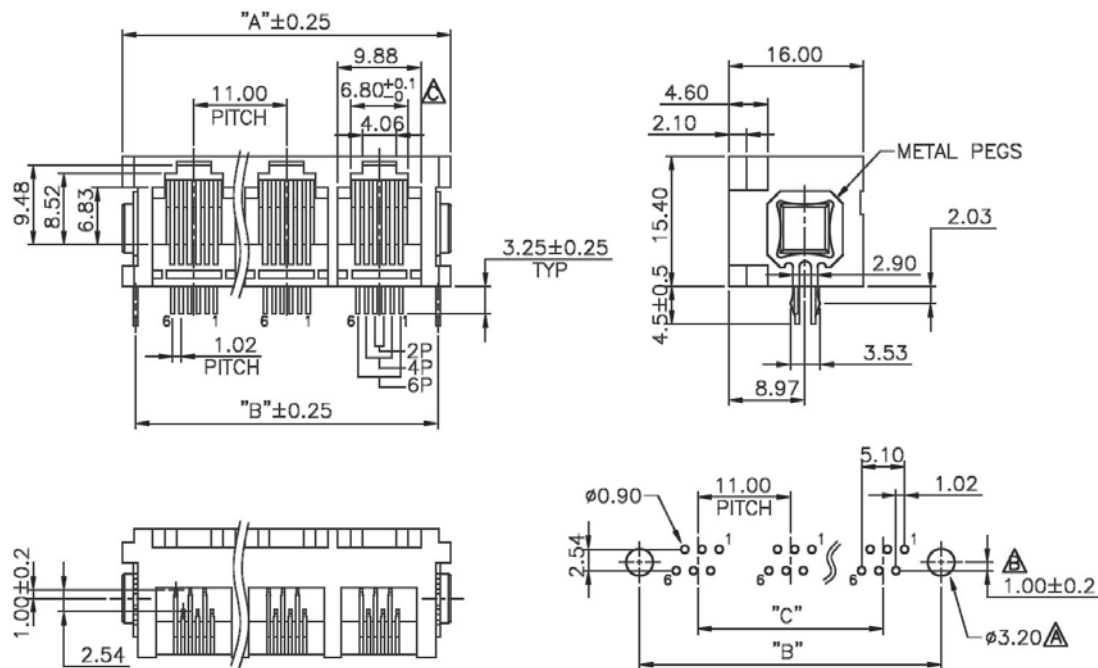
SIDE ENTRY MULTI-PORT UP LATCH MODULAR PCB JACK 6P PROFILE=15.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

DIMENSION	NO. OF PORT							
	1	2	3	4	5	6	7	8
A	17.00	28.00	39.00	50.00	61.00	72.00	83.00	94.00
B	13.8	24.8	35.8	46.8	57.8	68.8	79.8	90.8
C	0	11.00	22.00	33.00	44.00	55.00	66.00	77.00

ORDERING INFORMATION:

P/N M J $\frac{VA}{1} - \frac{66}{2} \times \frac{B}{3} \frac{X}{4} \frac{X}{5}$

- MODULAR JACK TYPE:
"VA" WITH METAL PEGS
- NO. OF POSITIONS & CONTACTS:
"64" 6P4C
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSING COLOR:
"B" BLACK
- NO. OF PORTS:
01, 02, 03, 04, 05, 06, 07, 08

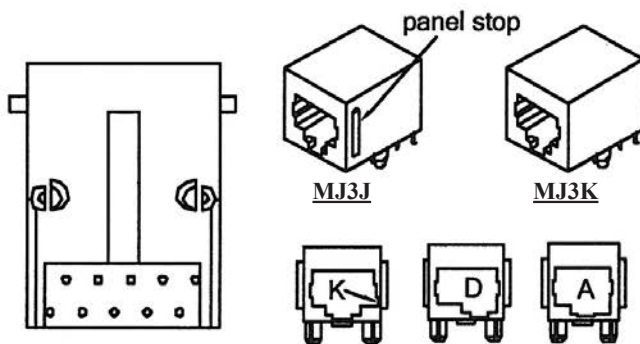
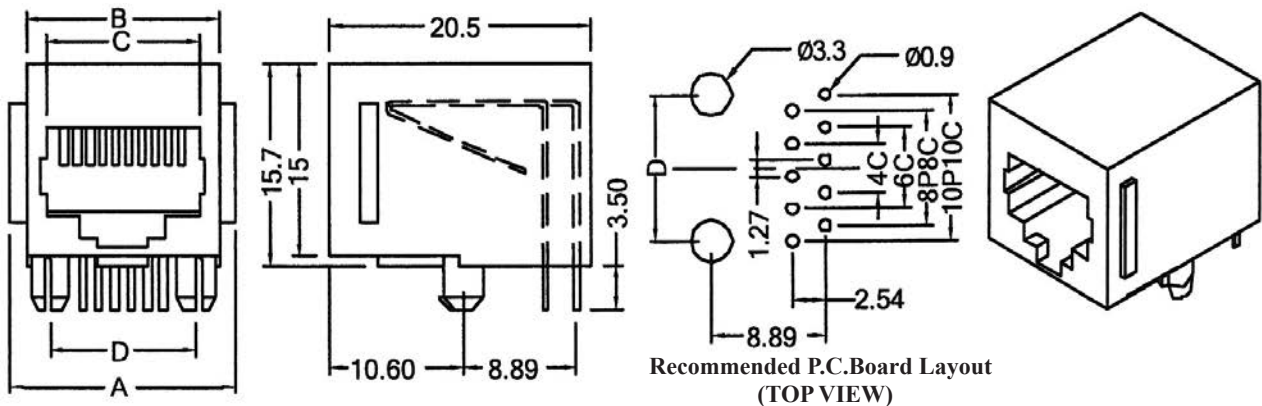
SIDE ENTRY MODULAR PCB JACK 4P+6P+8P+10P PROFILE=15.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



No. of Positions	No. of Contacts	A	B	C	D
4P	4C	13.70	11.20	7.70	7.62
6P	2C/4C/6C	15.75	13.20	9.90	10.16
8P	4C/6C/8C	17.70	15.20	11.95	11.43
10P	10C	17.70	15.20	11.95	11.43

ORDERING INFORMATION:

P/N M J $\frac{xx}{1}$ - $\frac{xxx}{2}$ $\frac{B}{3}$ $\frac{x}{4}$

- PANEL STOP OPTION:
 "3J" WITH PANEL STOP
 "3K" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "00" 10P10C
 "44" 4P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- KEYWAY & OFFSET OPTION:
 " " W/O KEYWAY & W/O OFFSET
 "D" OFFSET LATCH (6P ONLY)
 "A" NORMAL & OFFSET LATCH (6P ONLY)
 "K" WITH KEYWAY (8P & 10P ONLY)

SIDE ENTRY MODULAR PCB JACK 4P PROFILE=16.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

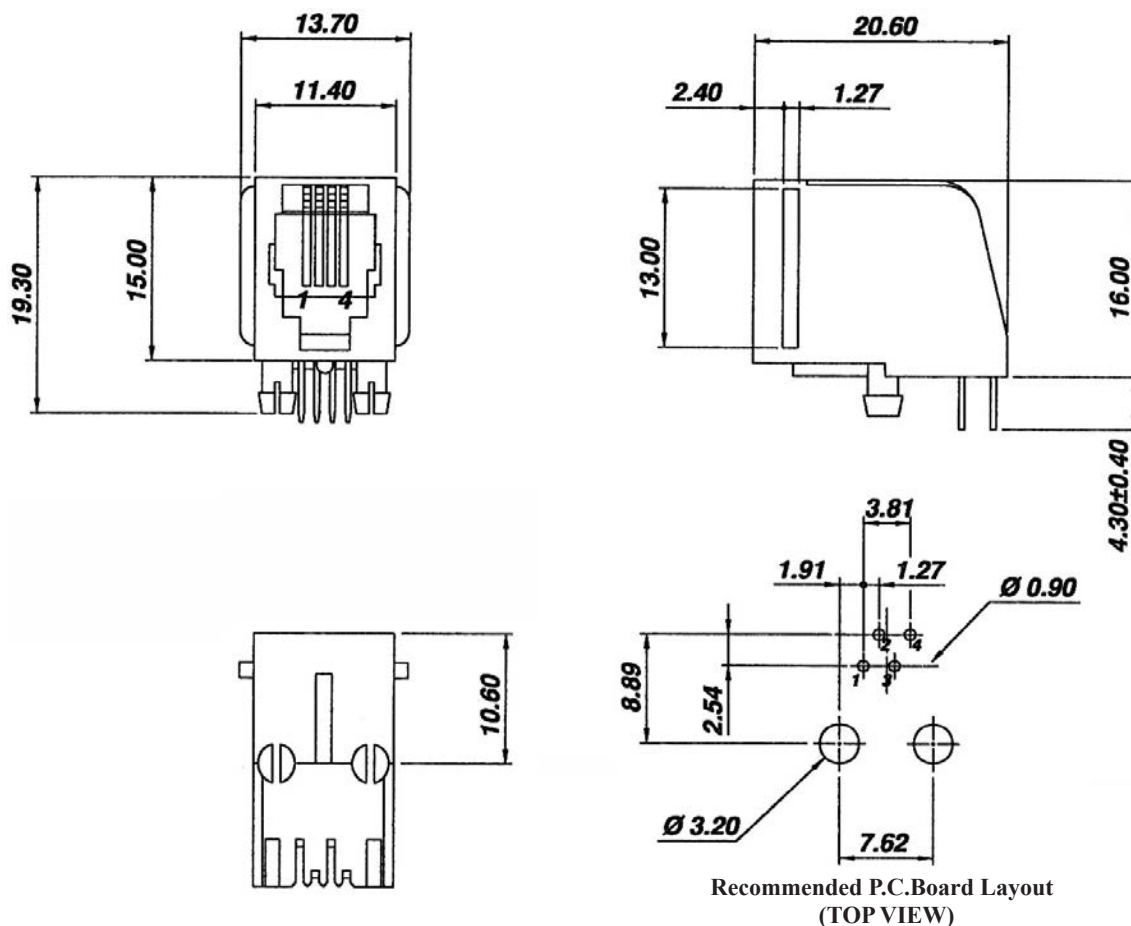
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJLC - $\frac{44 \times B}{T 2}$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLCHT-44xB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK 6P PROFILE=16.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

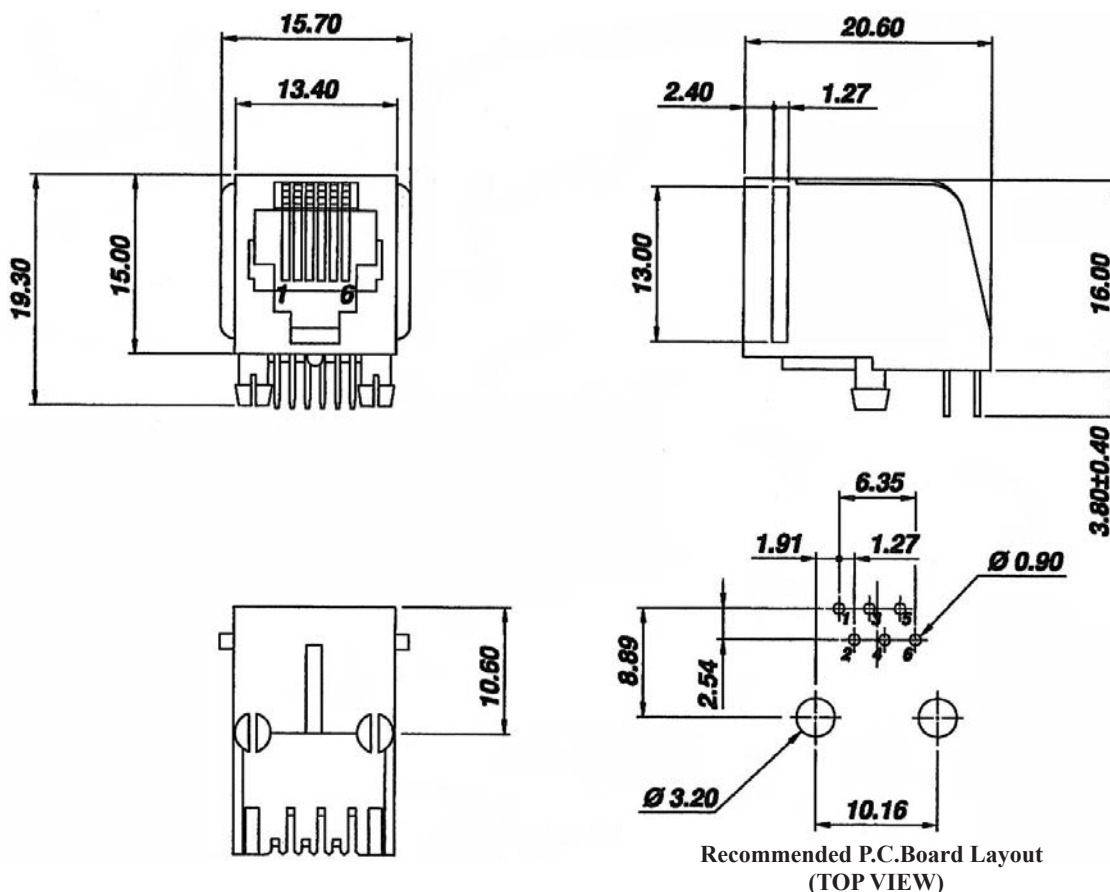
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJLC - $\frac{x \times x}{T} \times B$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

NOTE: P/N MJLCHT-6xxB FOR HIGH TEMP. VERSION

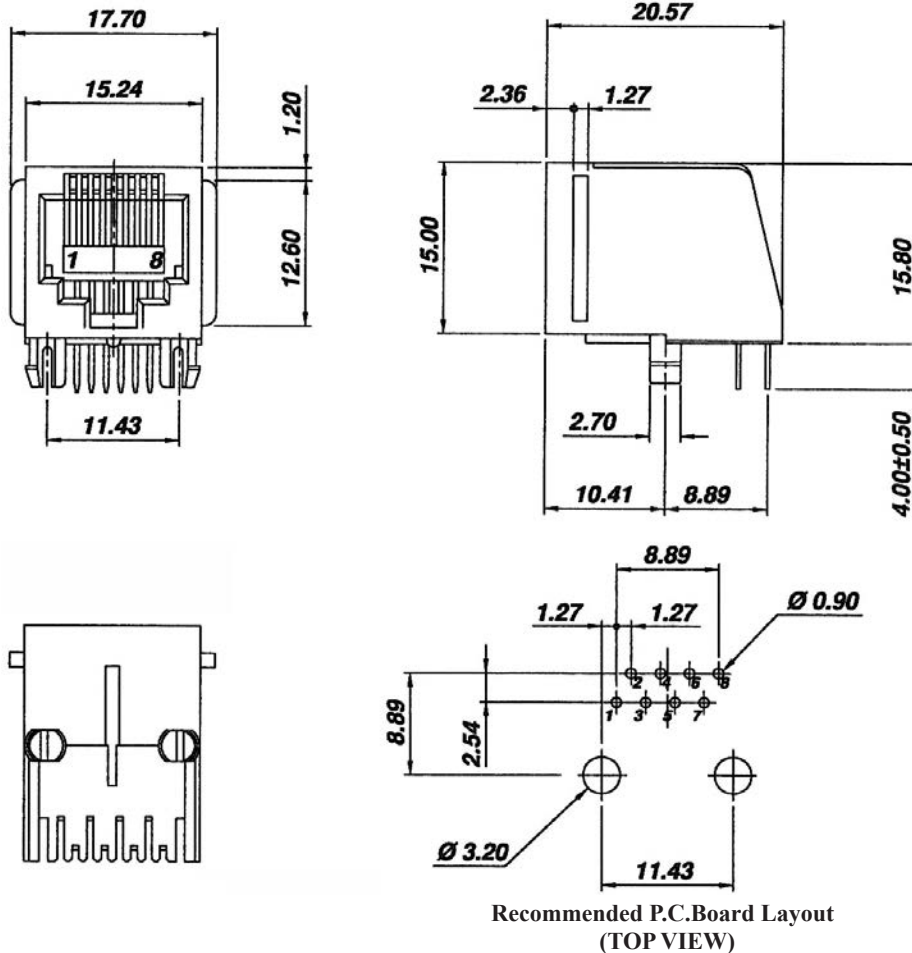
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=16.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJLC - $\frac{88}{T} \times \frac{B}{2} \times \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. KEYWAY OPTION:
" " W/O KEYWAY
"K" WITH KEYWAY

NOTE: P/N MJLCHT-88xB FOR HIGH TEMP. VERSION

SIDE ENTRY MODULAR PCB JACK DEC TYPE 6P PROFILE=16.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

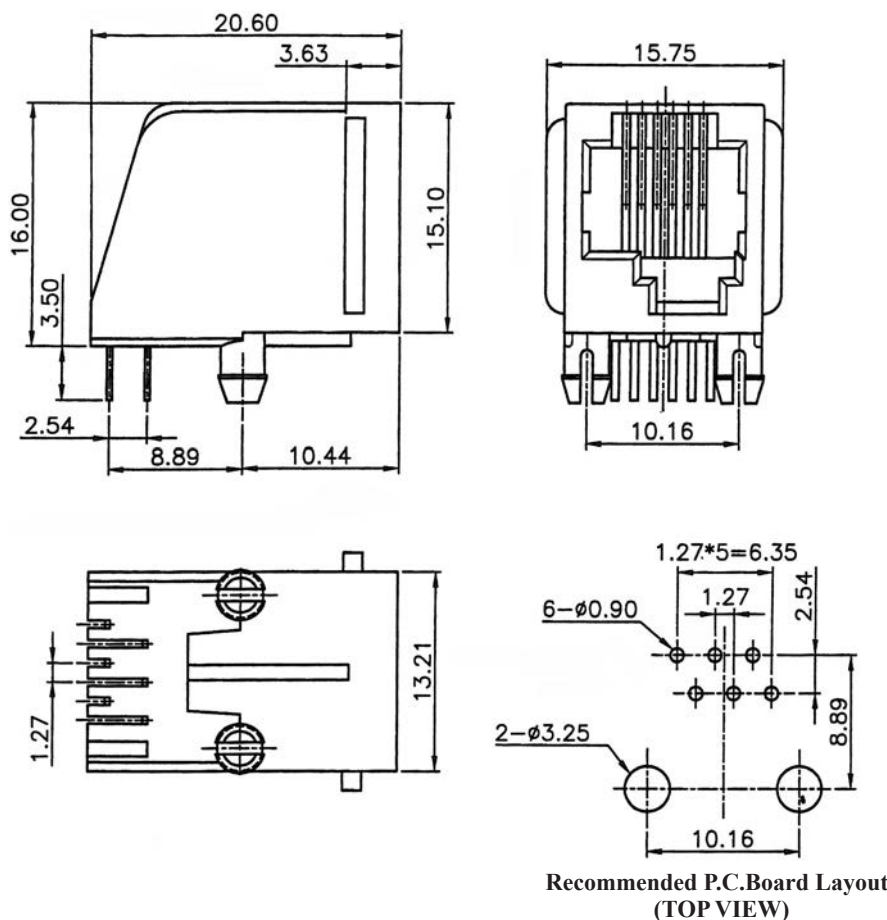
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{XX}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B

- PANEL STOP OPTION:
"8H" WITH PANEL STOP
"8K" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
"66" 6P6C
"64" 6P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" GOLD FLASH

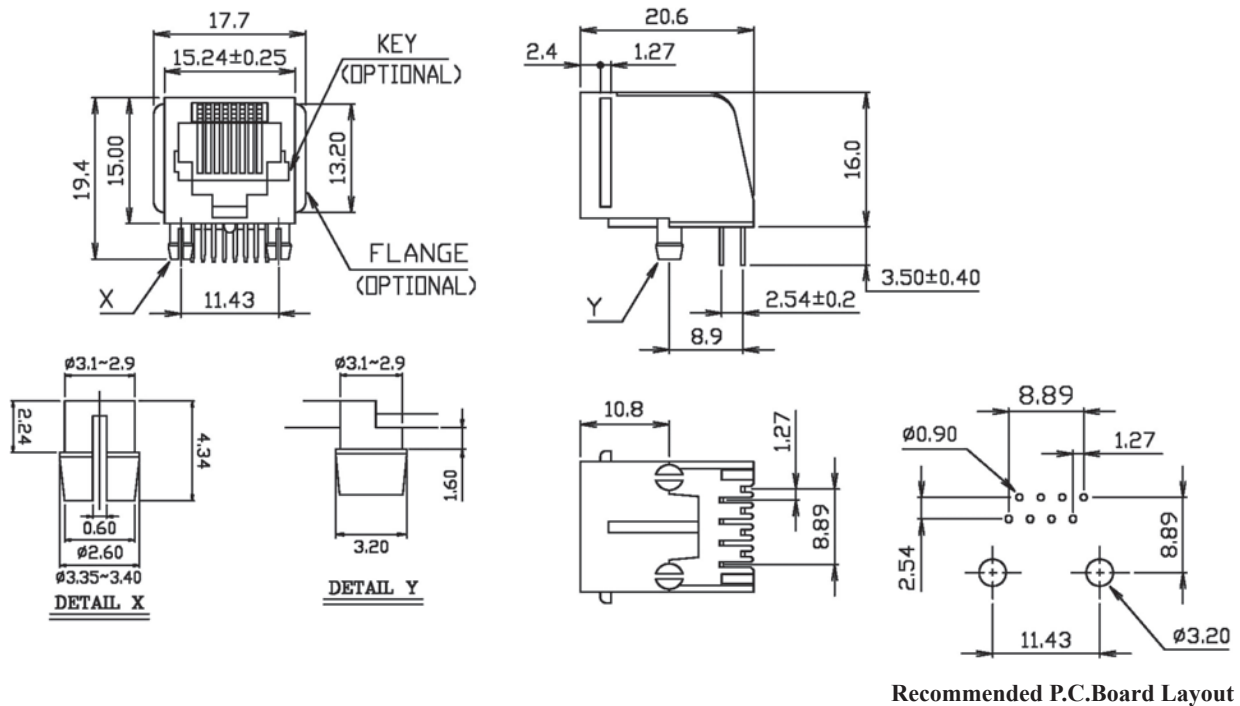
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=16.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{X}{1}$ X - $\frac{8}{2}$ 8 X $\frac{B}{3}$ X $\frac{X}{4}$ 5

1. MODULAR JACK TYPE:

"VK" FLANGED
 "VL" FLANGELESS

2. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

3. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

4. HOUSING COLOR:

"B" BLACK

5. KEY OPTION:

" " WITHOUT KEY
 "K" WITH KEY

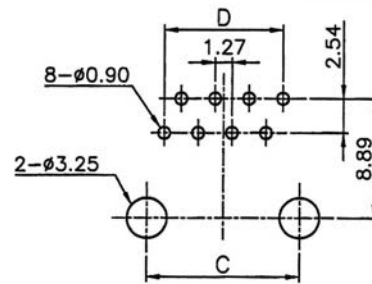
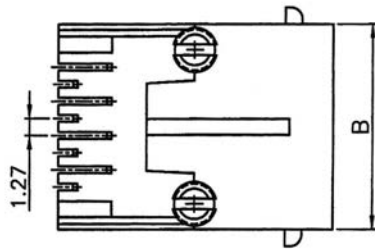
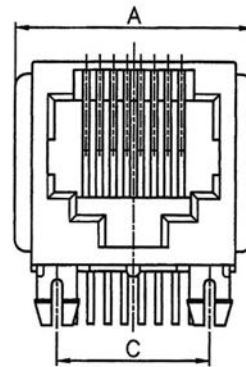
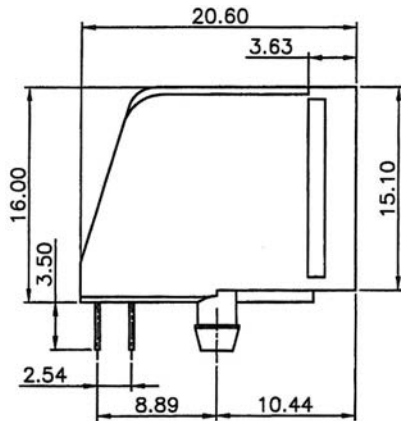
SIDE ENTRY MODULAR PCB JACK 4P+6P+8P PROFILE=16.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C. Board Layout (TOP VIEW)

No. of Positions	Dimensions			
	A	B	C	D
4	13.72	11.18	7.62	3.81
6	15.75	13.21	10.16	6.35
8	17.78	15.24	11.43	8.89

ORDERING INFORMATION:

P/N M J $\frac{xx}{1} - \frac{xxx}{2} \frac{x}{3} B \frac{x}{4}$

- PANEL STOP OPTION:
 "01" WITH PANEL STOP
 "02" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "44" 4P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
 "E" GOLD FLASH
- KEYWAY OPTION:
 " " W/O KEYWAY
 "K" WITH KEYWAY

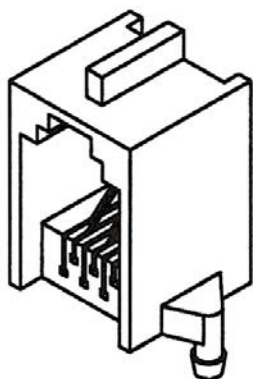
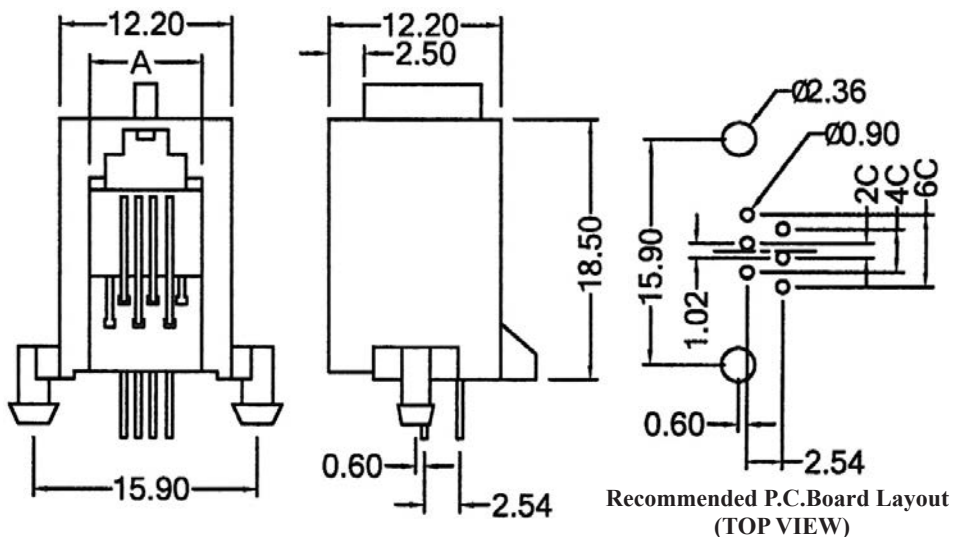
SIDE ENTRY UP LATCH MODULAR PCB JACK 4P+6P PROFILE=18.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Gray
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



No. of Positions	No. of Contacts	A
(6P)4P	4C	7.90
6P	2C/4C/6C	9.90

ORDERING INFORMATION:

P/N M J R 2 - $\frac{x x x A}{T 2 3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C
 "44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. HOUSING COLOR:

"A" GRAY

SIDE ENTRY UP LATCH MODULAR PCB JACK WITHOUT SHORTING BAR 8P PROFILE=19.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

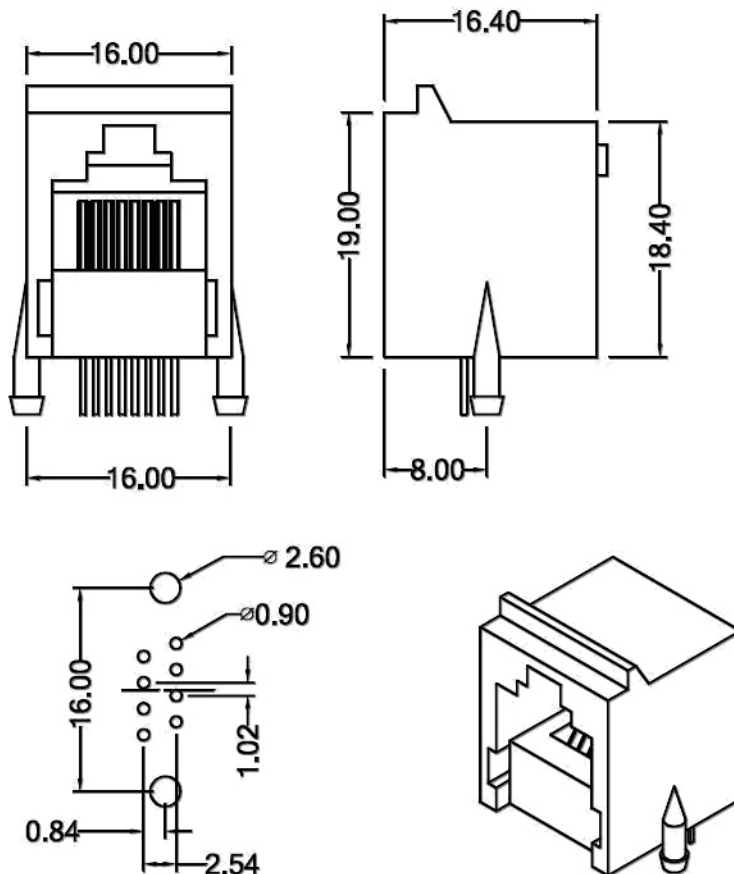
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



Recommended P.C.Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J 6 7 - $\frac{88}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

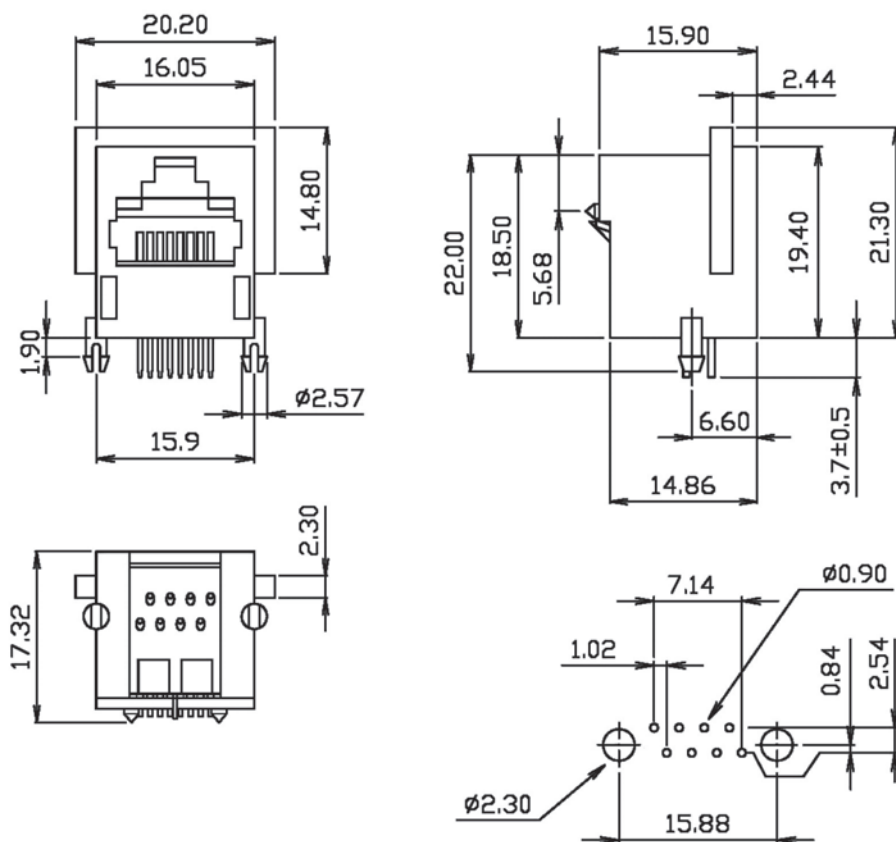
SIDE ENTRY UP LATCH MODULAR PCB JACK 8P PROFILE=21.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J Y D - $\frac{88}{1} \frac{x}{2} \frac{x}{3} \frac{x}{4}$

1. MODULAR JACK TYPE:
"YD" RJ45 JACK WITH FLANGES
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSING COLOR:
"A" GRAY
"B" BLACK

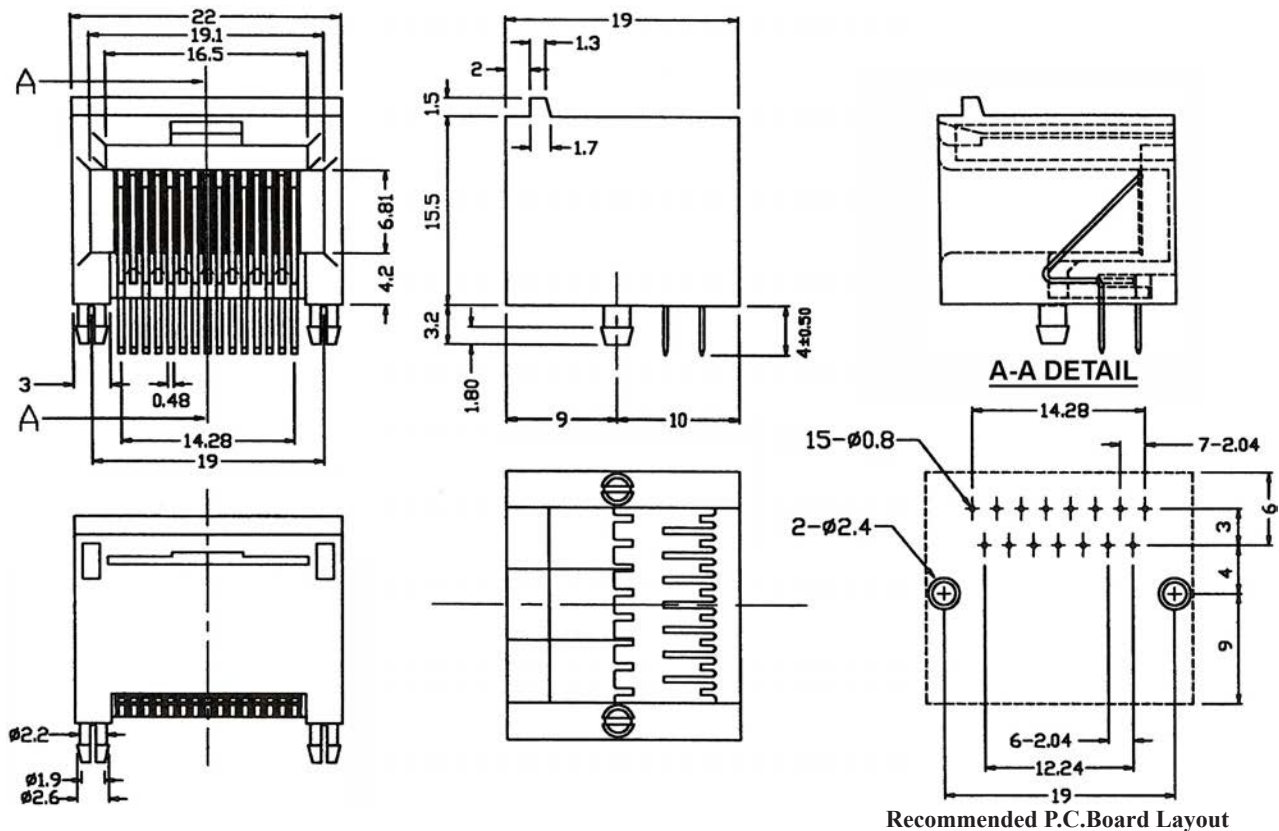
SIDE ENTRY UP LATCH MODULAR PCB JACK 15P FOR CAR TELECOMUNICATION (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J A T - $\frac{15}{1} \times \frac{B}{2} \times \frac{3}{3}$

1. NO. OF POSITIONS & CONTACTS:
"15" 15P15C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" 3 MICROINCH GOLD
3. CONTACT FINISH OPTION:
"S" SELECTIVE GOLD PLATED
"G" FULL GOLD PLATED

NOTE: MATES WITH MODULAR PLUG P/N MPAT-15HxxA

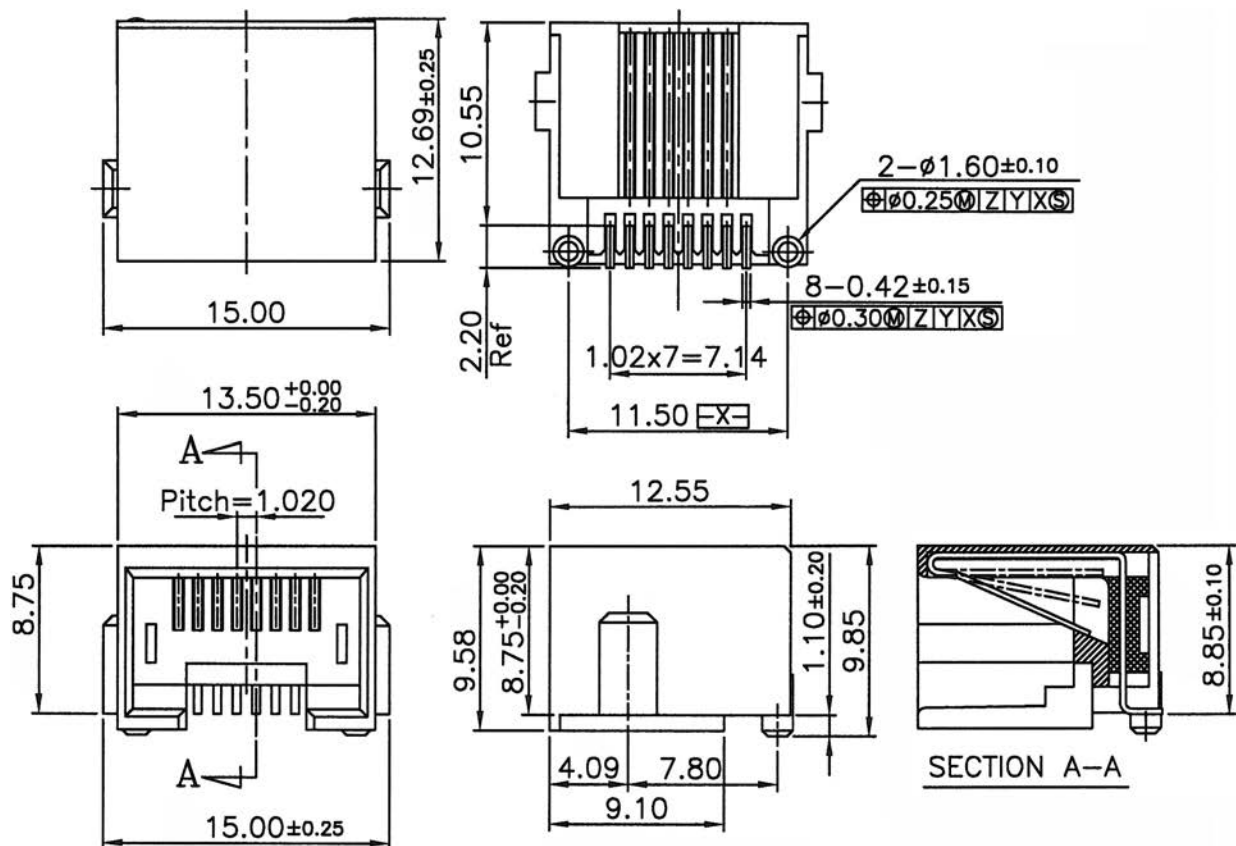
SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=9.58MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ2V - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

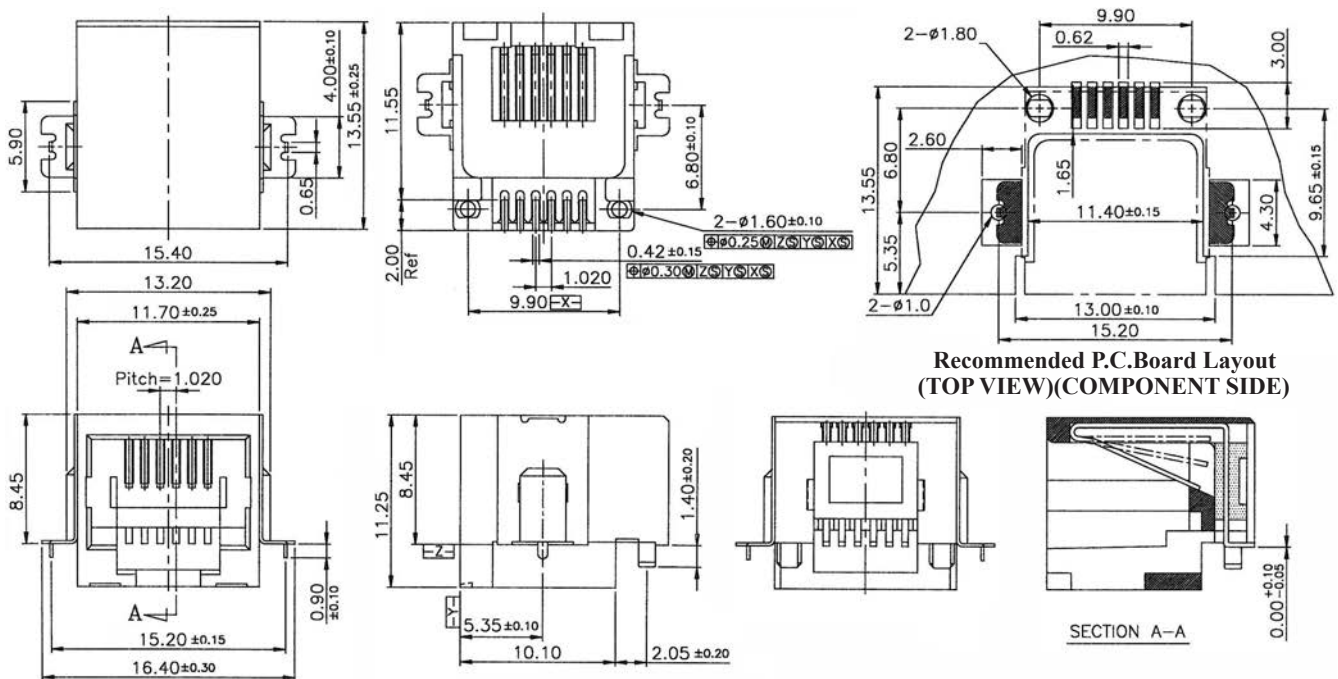
SIDE ENTRY EMBEDDED MODULAR SMT JACK 6P PROFILE=11.25MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ3Q - $\frac{x}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
 - "66" 6P6C
 - "64" 6P4C
2. CONTACT FINISH:
 - "A" 6 MICROINCH GOLD
 - "B" 15 MICROINCH GOLD
 - "C" 30 MICROINCH GOLD
 - "D" 50 MICROINCH GOLD
3. PACKAGE OPTION:
 - " " TRAY
 - "R" TAPE & REEL

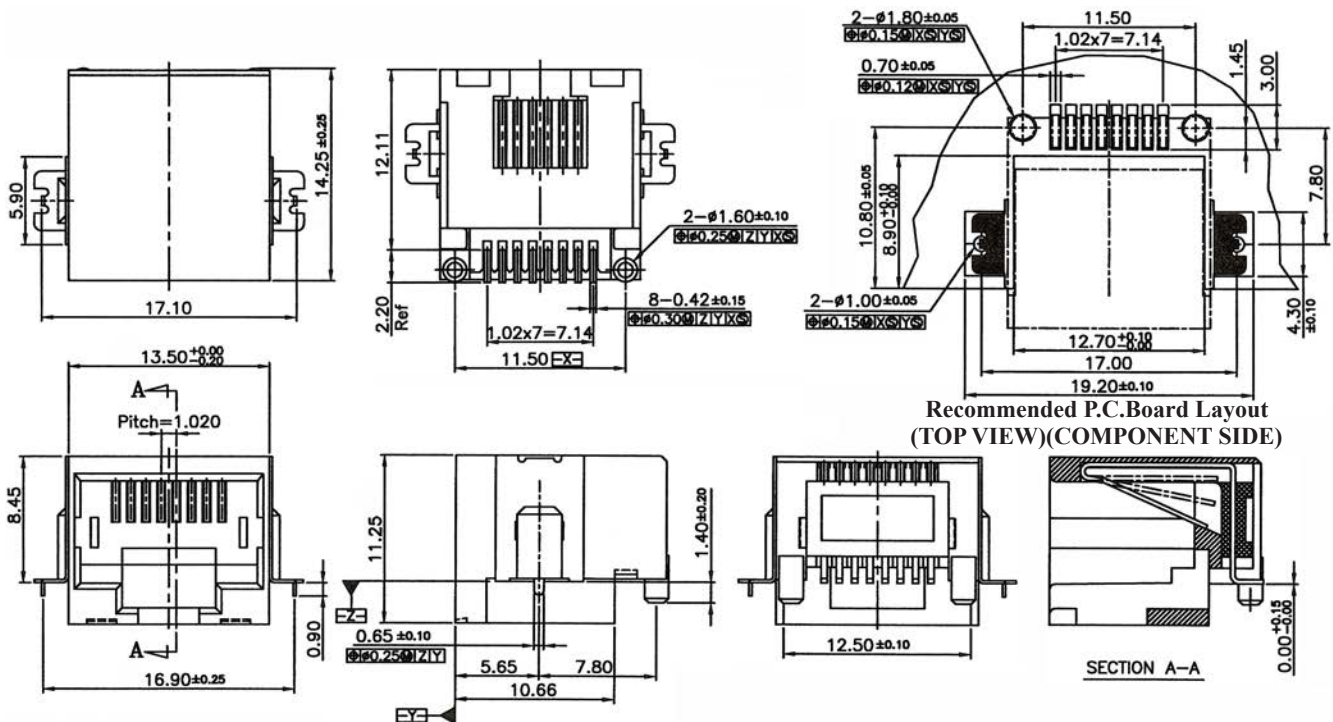
SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=11.25MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
 Contact Resistance: 20mΩ Max.
 Rating Current: 1.5A Max.
 Rating Voltage: 120V AC.
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.
 Temperature Range: -40°C / +85°C
 Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
 Soldering Temperature: 260°C
 Color: Black
 Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 *RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ3Q - $\frac{88}{T} \times \frac{B}{2} - \frac{X}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 4P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

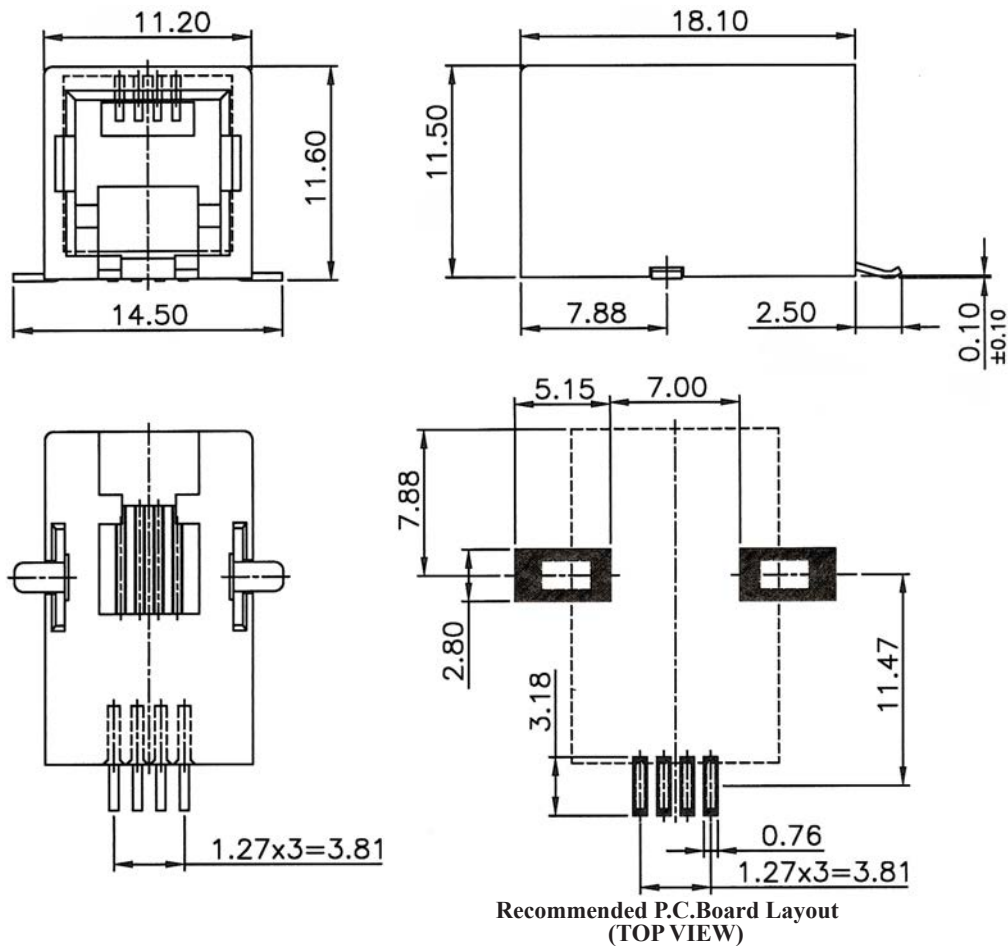
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 4 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"44" 4P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

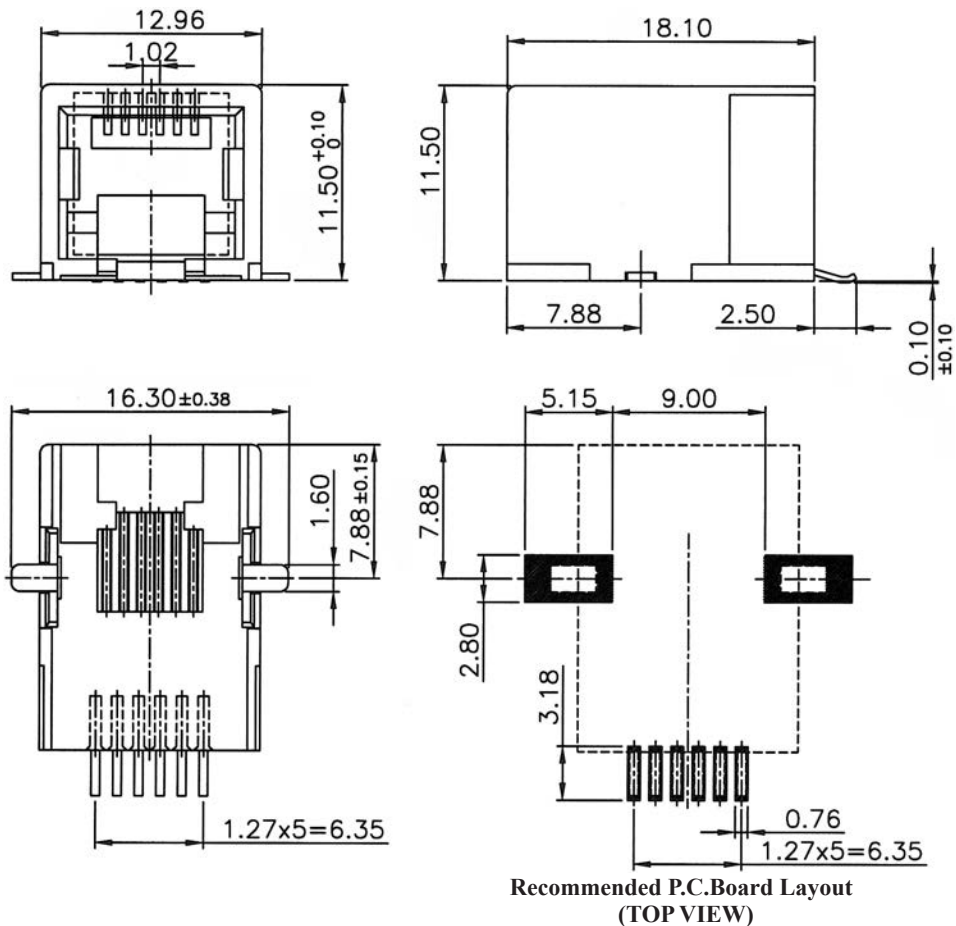
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 4 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

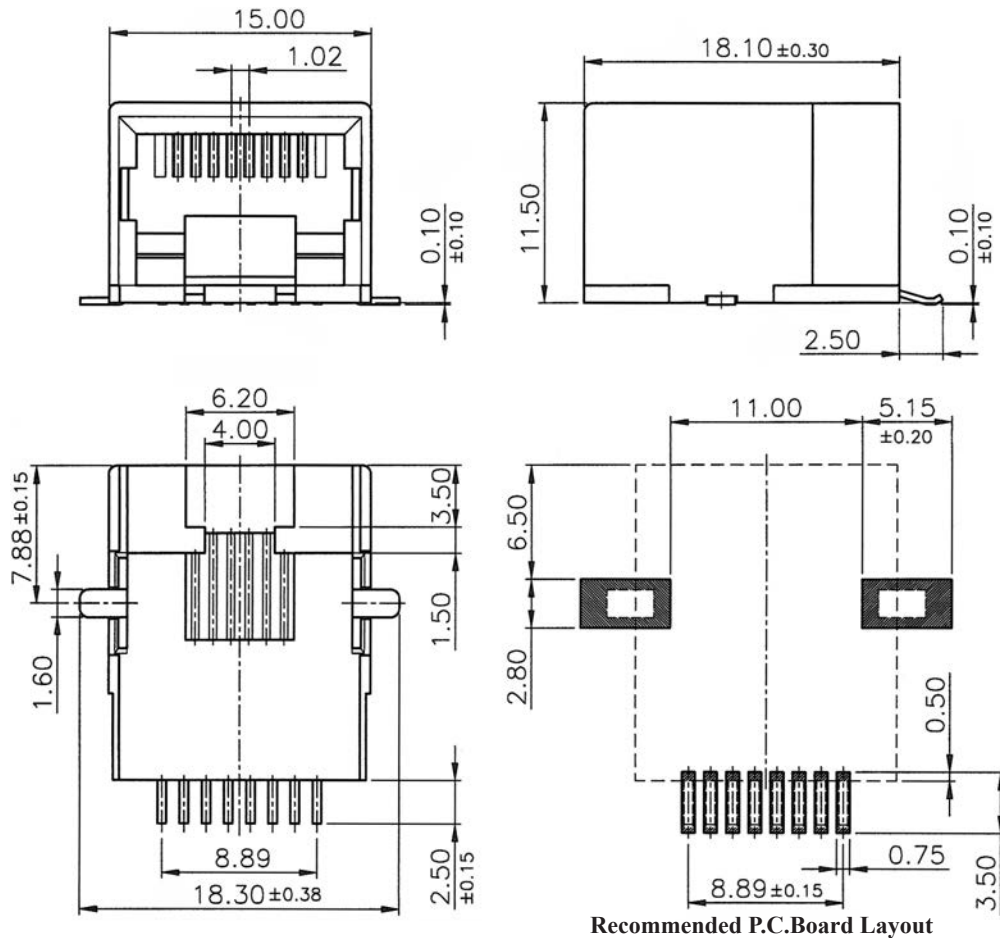
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 4 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

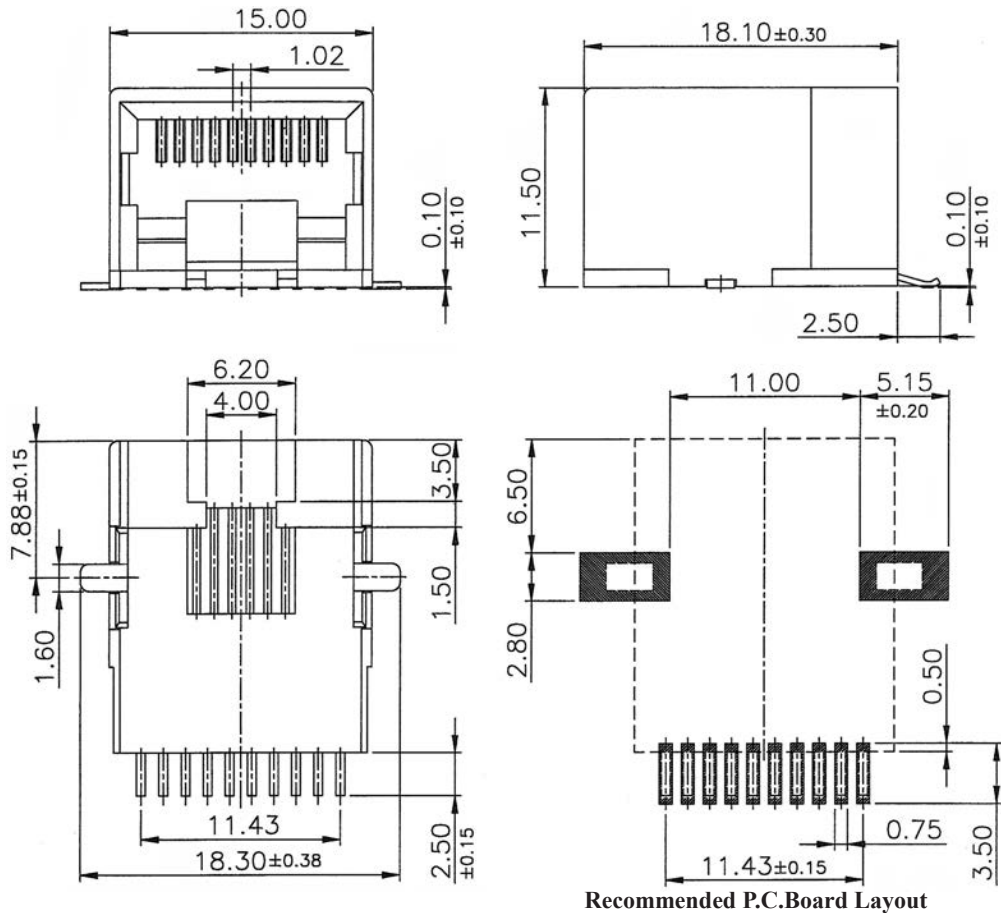
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 4 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

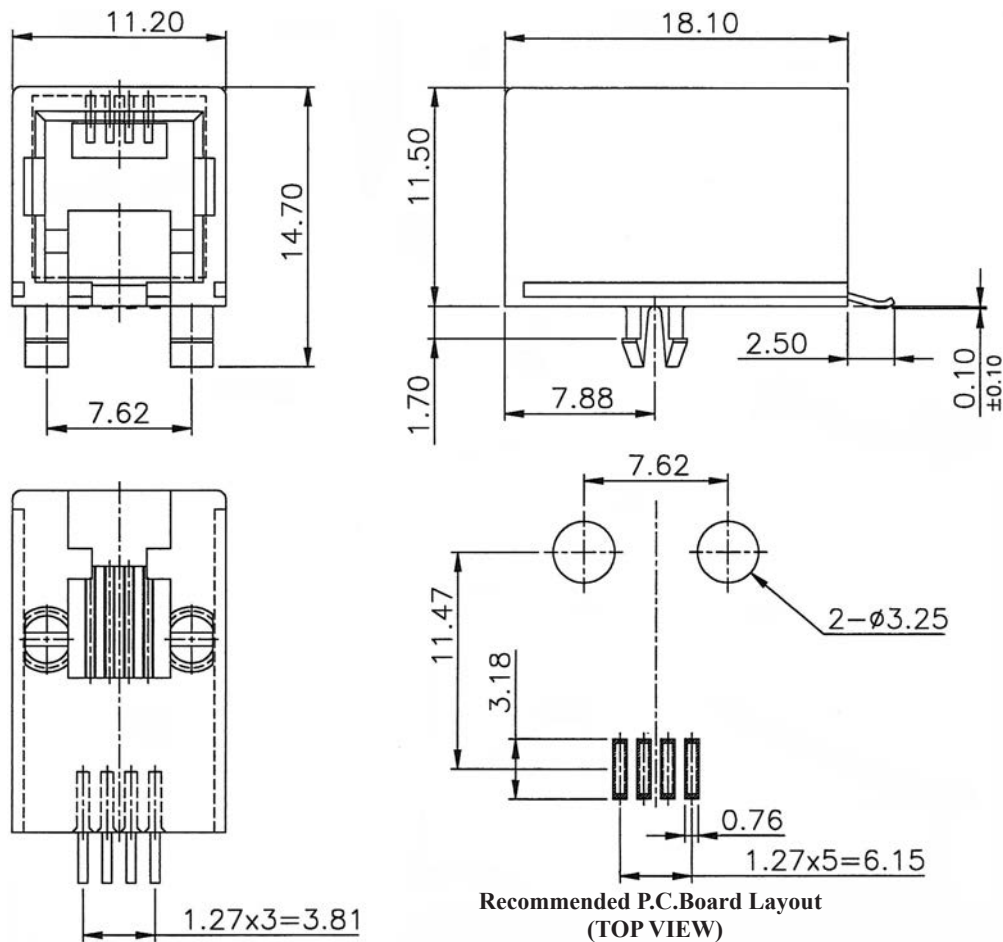
SIDE ENTRY MODULAR SMT JACK 4P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ17 - $\frac{x}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
 - "44" 4P4C
 - "42" 4P2C
- CONTACT FINISH:
 - "A" 6 MICROINCH GOLD
 - "B" 15 MICROINCH GOLD
 - "C" 30 MICROINCH GOLD
 - "D" 50 MICROINCH GOLD
- PACKAGE OPTION:
 - " " TRAY
 - "R" TAPE & REEL

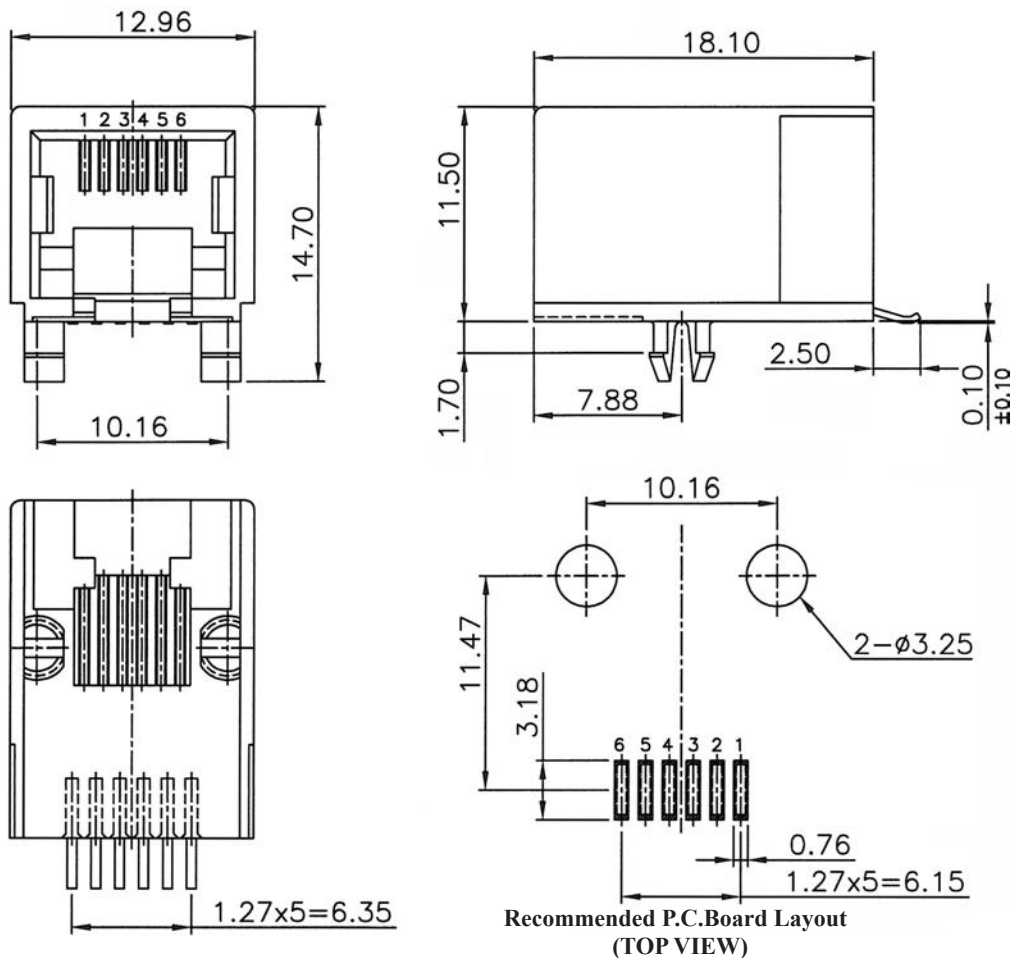
SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ17 - $\frac{x}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
 "64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY
 "R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

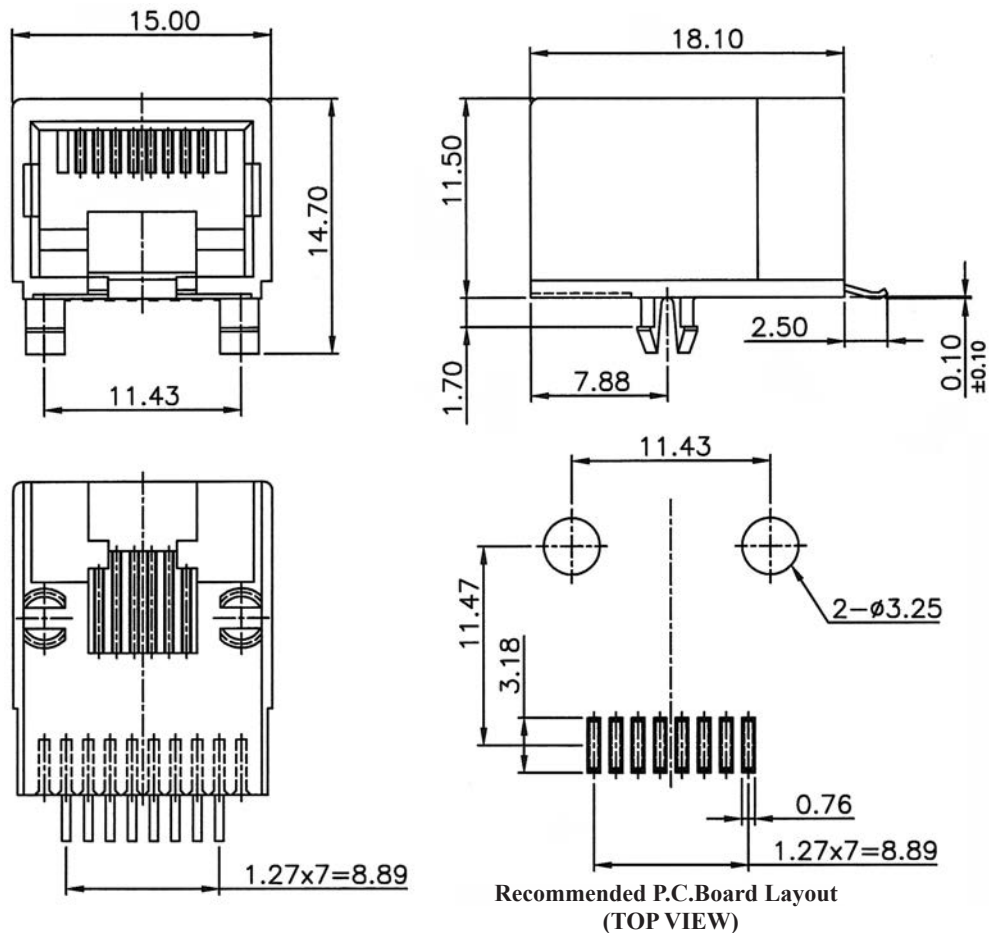
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J 1 7 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

IR Reflow Soldering Temperature: 255°C To 265°C(5~10 Seconds)

MATERIALS

Plastic Housing: High Temp. Thermoplastic

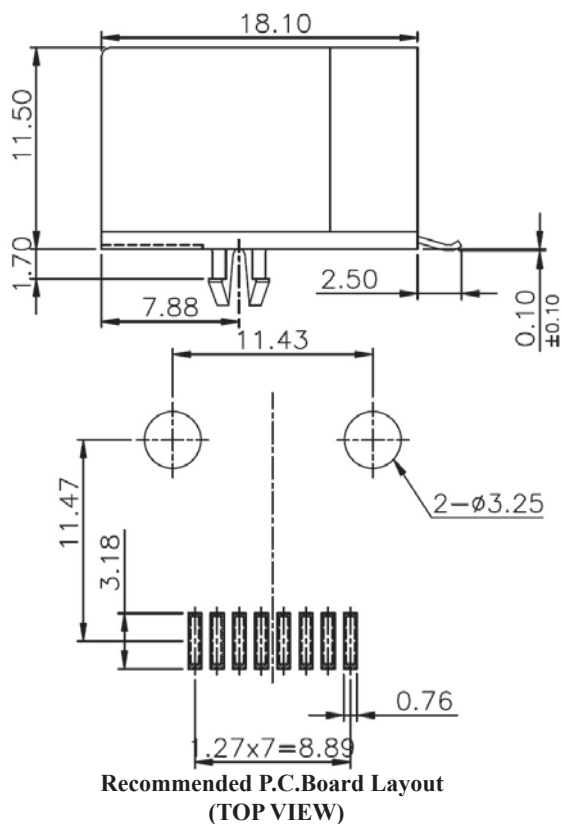
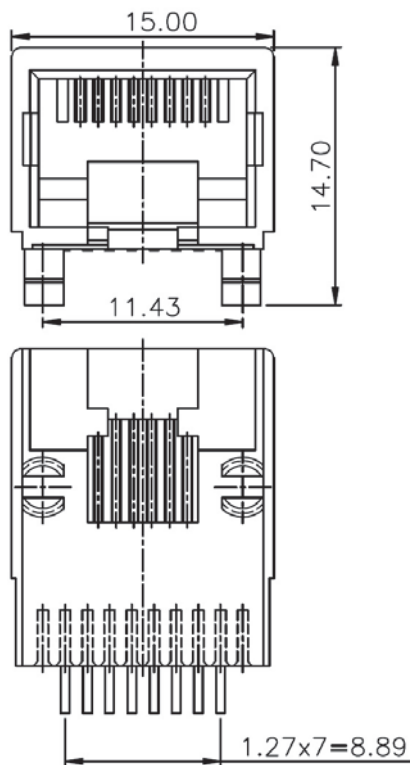
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,

Tin Plating Over Nickel In Solder Area.

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ $\frac{17J}{1} - \frac{88}{2} \frac{x}{3} B - \frac{x}{4}$

1. MODULAR JACK TYPE:
"17J" WITH LOACTING PEGS
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

NOTE: IT CAN BE USED FOR REPLACING P/N MJ17-88xB-x.

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Electrical:

Voltage Rating: 125 Vac Rms.

Current Rating: 1.5 Amp.

Contact Resistance: 40 Milliohms Max.

Insulation Resistance: 1000 Megohms Min @500 Vdc.

Dielectric Strength: 1000 Vac Rms 60Hz, 1Min.

Mechanical:

Operating: 750 Cycles Min.

Environmental:

Storage: -40°C To +85°C.

Operation: -40°C To +80°C.

IR Reflow Soldering Temperature: 255°C To 265°C(5~10 Seconds)

MATERIALS

Plastic Housing: High Temp. Thermoplastic

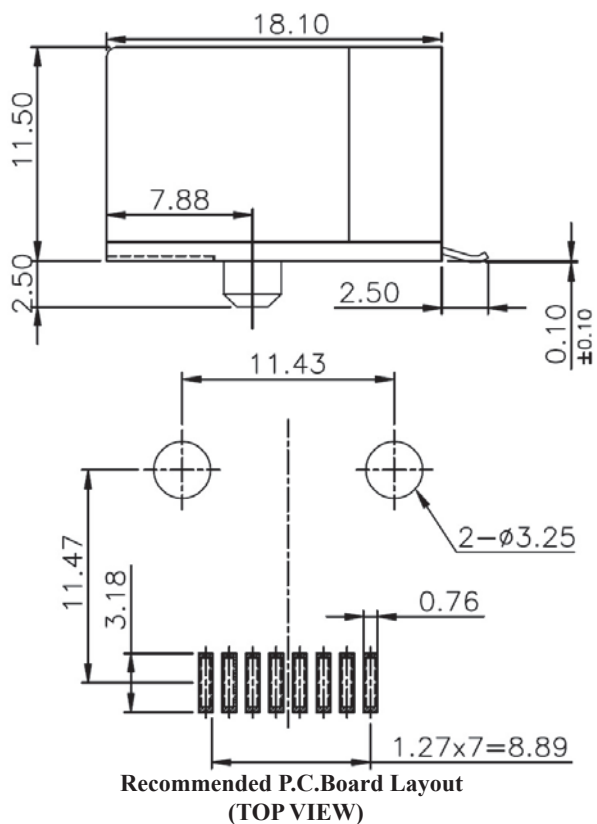
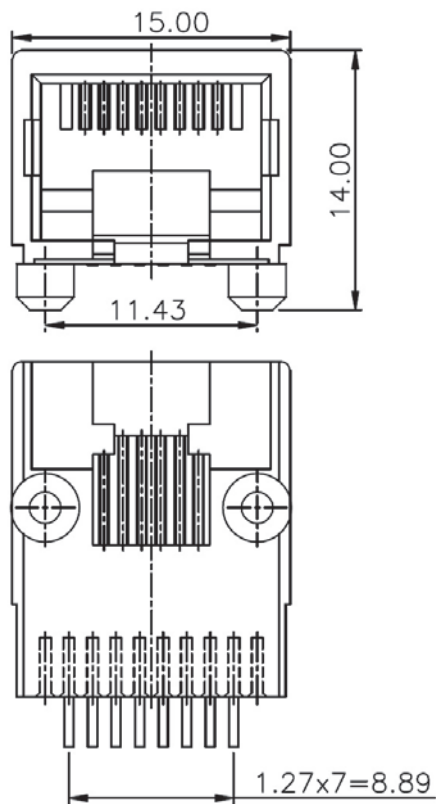
Flammability Rating UL 94V-0.

Contacts: Phosphor Bronze

Plating: Gold Plating Over Nickel In Contact,

Tin Plating Over Nickel In Solder Area.

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N MJ $\frac{1}{1}$ 7K - $\frac{88}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"17K" WITH LOACTING PEGS
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

NOTE: IT CAN BE USED FOR REPLACING P/N MJ17-88xB-x.

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

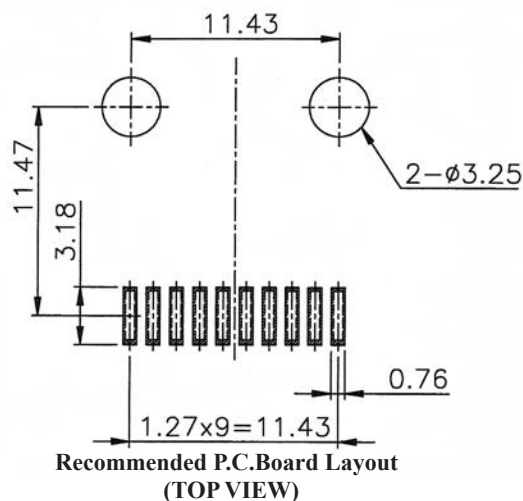
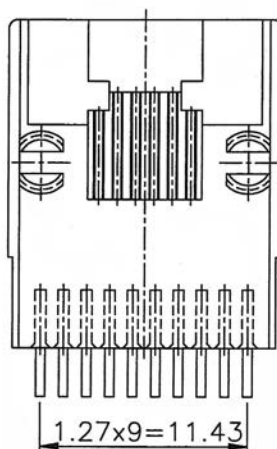
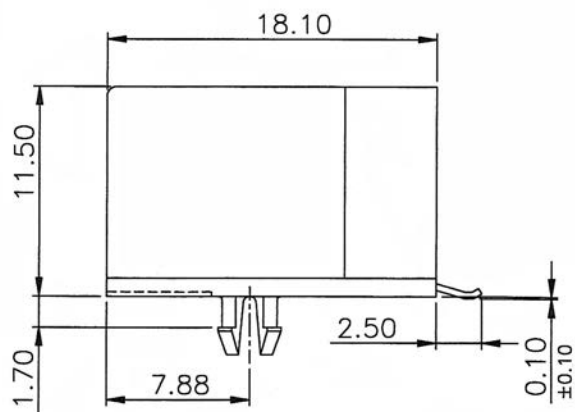
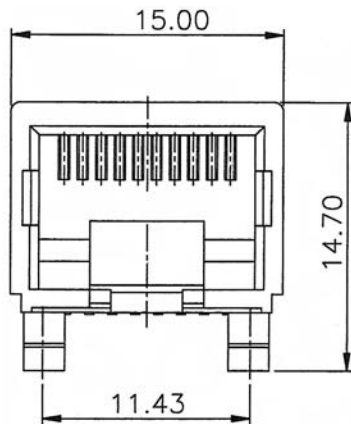
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 1 7 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"00" 10P10C

"08" 10P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

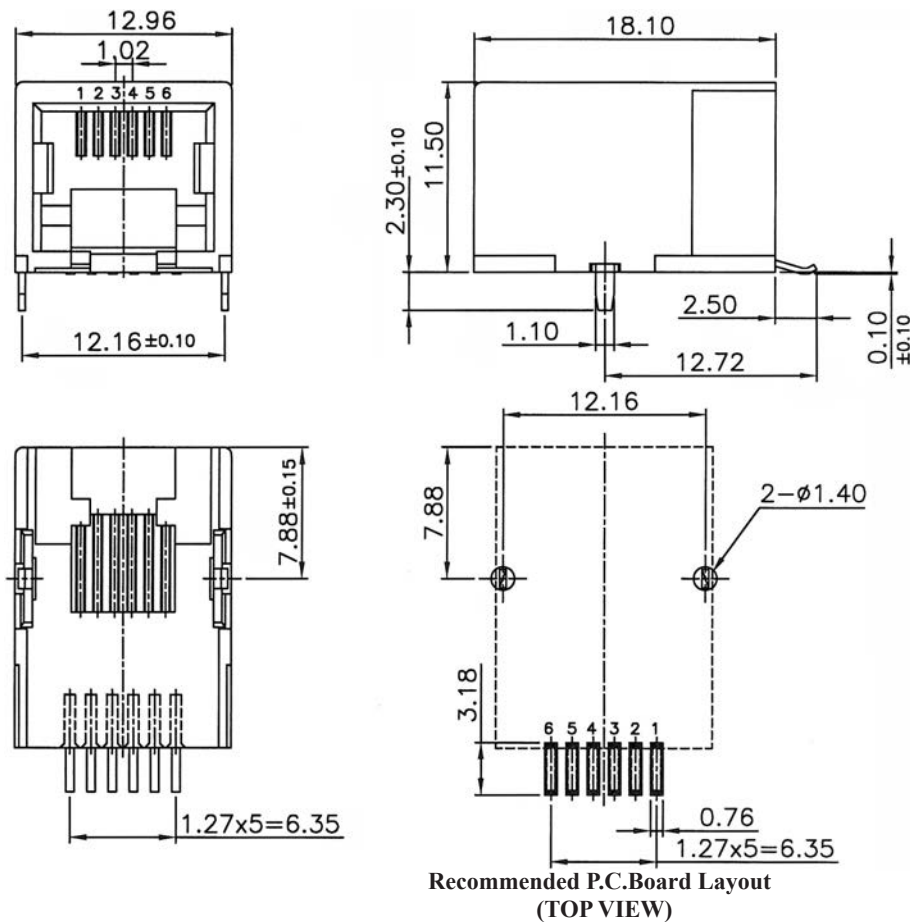
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 8 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

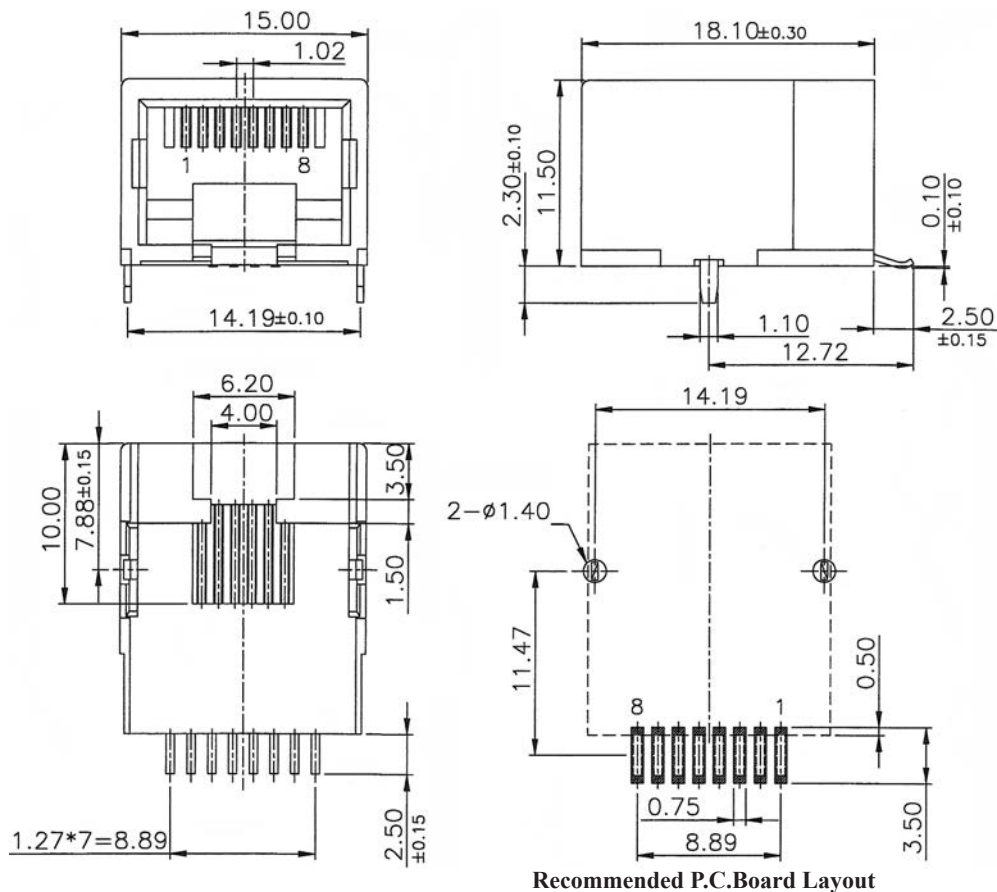
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J 4 8 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

"84" 8P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

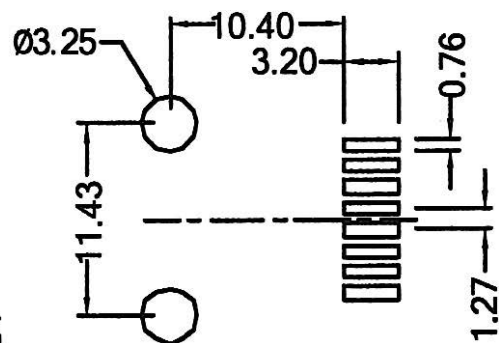
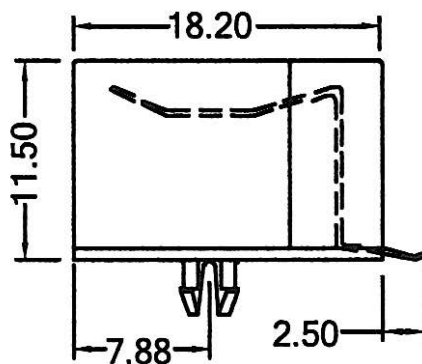
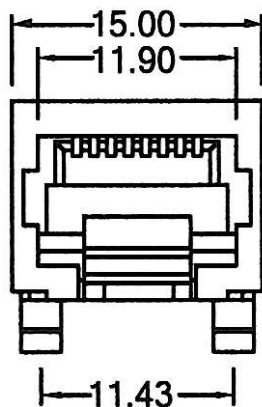
SIDE ENTRY MODULAR SMT JACK 8P+10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

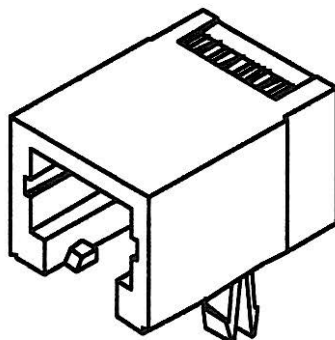
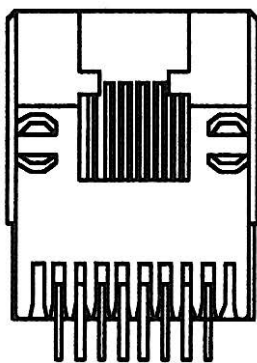
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJS3 - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C
 "00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY
 "R" TPAE & REEL

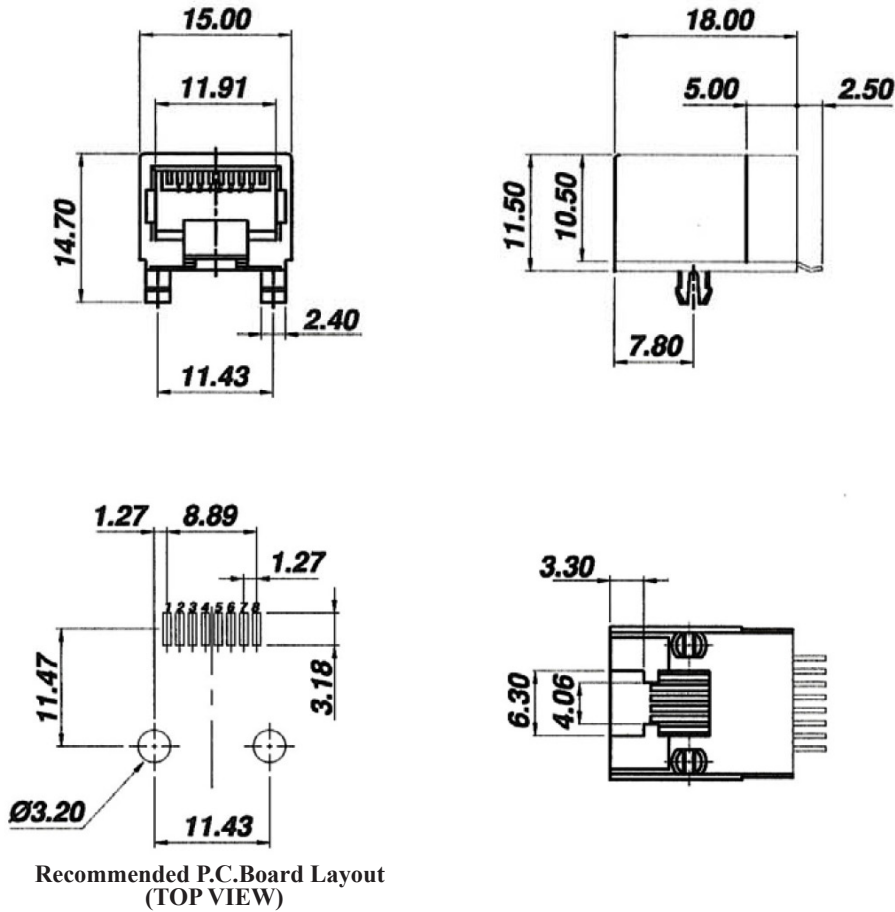
SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500 Megohms Min
Contact Resistance: 20 Milliohms Max.
Current Rating: 1.5 A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C To +85°C.
Operating: 500 Cycles Min.

MATERIALS

Housing: Nylon(UL 94V-0), Soldering Temperature:260°C
Color: Black
Spring Wire: 0.35mm Thickness Phosphor Bronze Over Nickel
Shield: Brass Plating Nickel
*** RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J L N - $\frac{x}{T} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

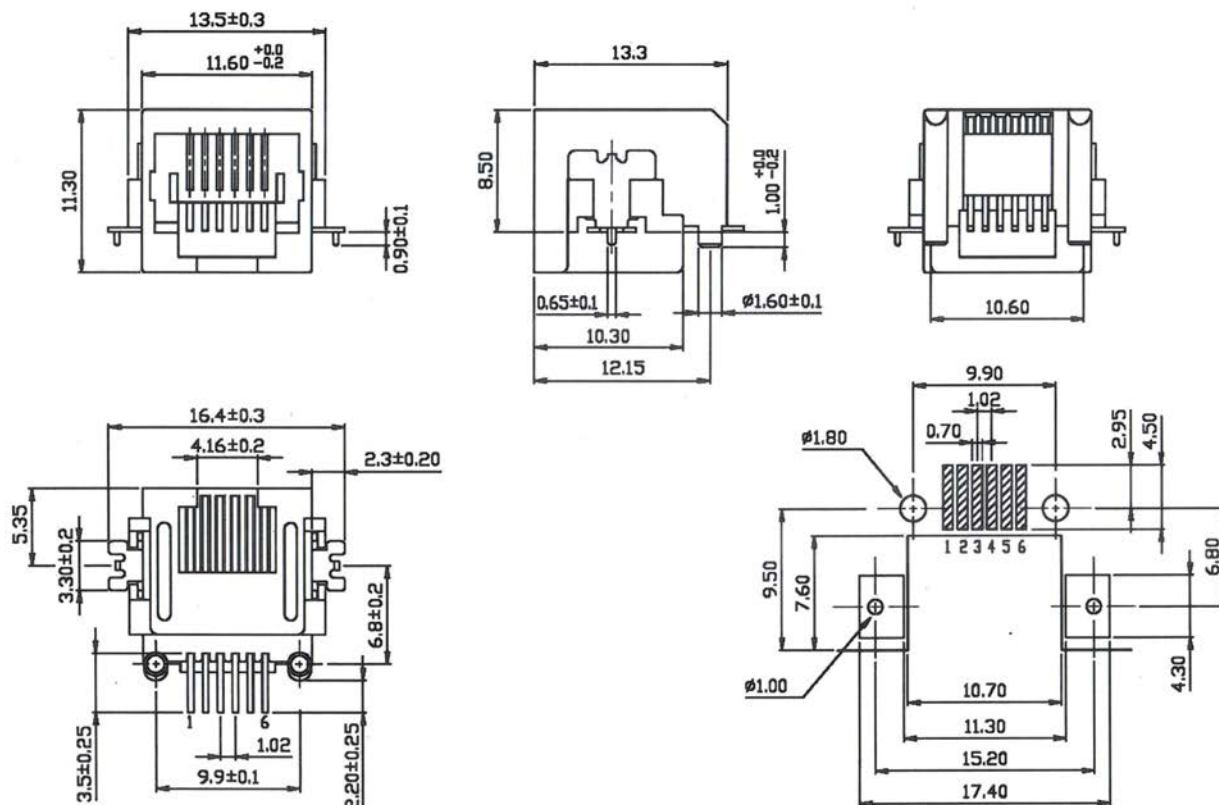
SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.30MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J F K - $\frac{x}{1}$ $\frac{x}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

- MODULAR JACK TYPE:
"FK" RJ12 SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"66" 6P6C
"64" 6P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

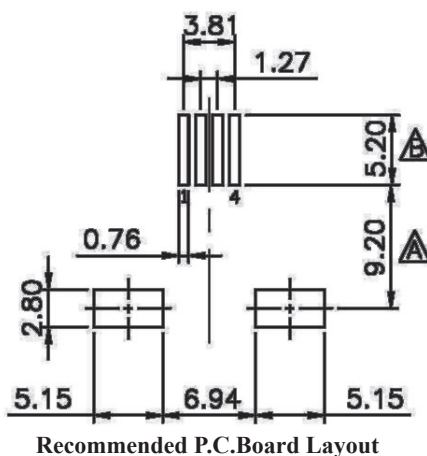
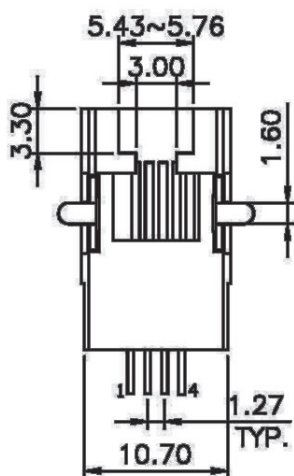
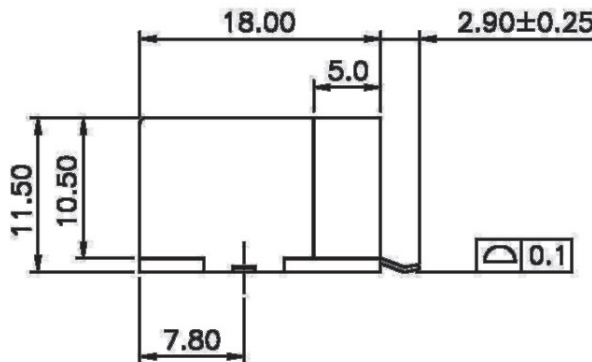
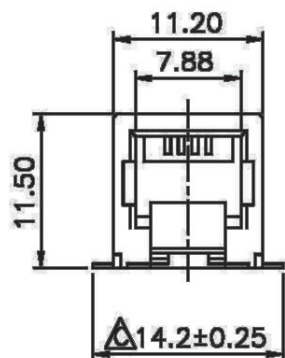
SIDE ENTRY MODULAR SMT JACK 4P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{FE}{1}$ - $\frac{44}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"FE" VERY LOW PROFILE SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

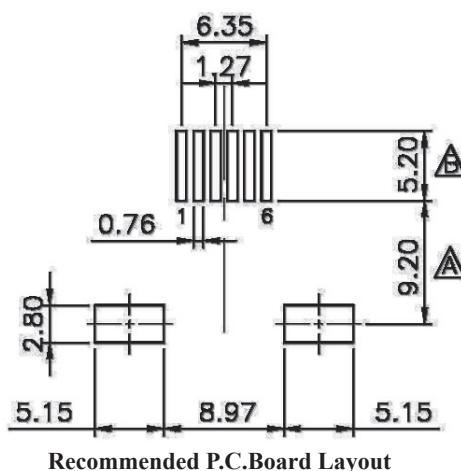
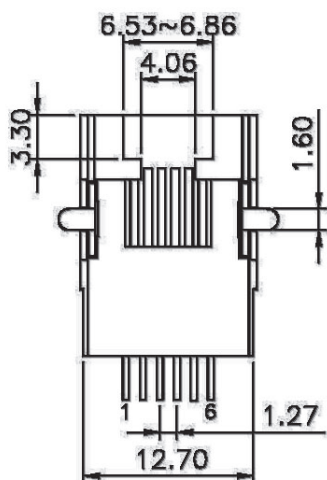
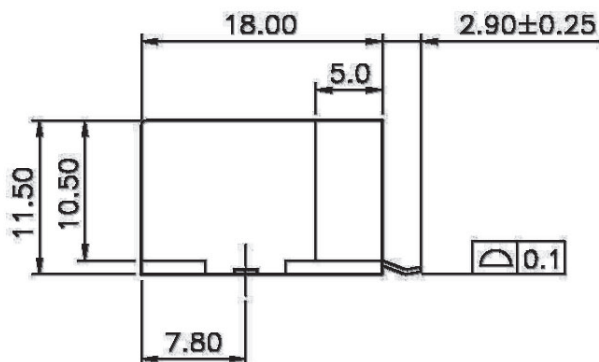
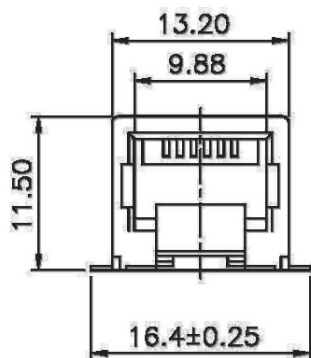
SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{FE}{1}$ - $\frac{xx}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

- MODULAR JACK TYPE:
"FE" VERY LOW PROFILE SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"66" 6P6C
"64" 6P4C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

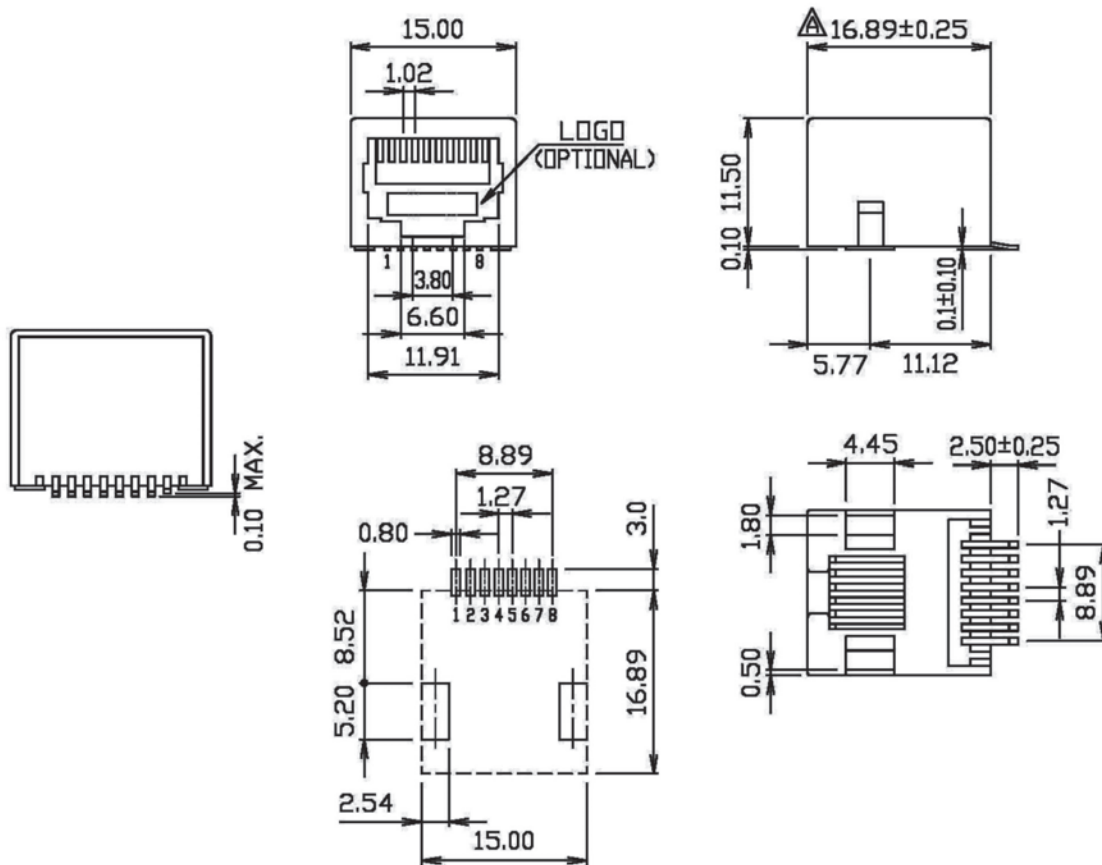
SIDE ENTRY MODULAR SMT JACK 10P8C PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{FF}{1}$ - $\frac{08}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"FF" VERY LOW PROFILE SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"08" 10P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

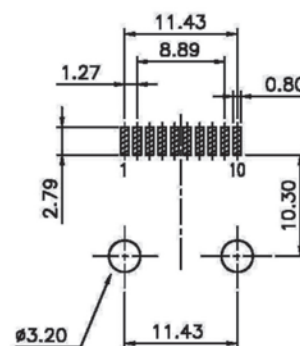
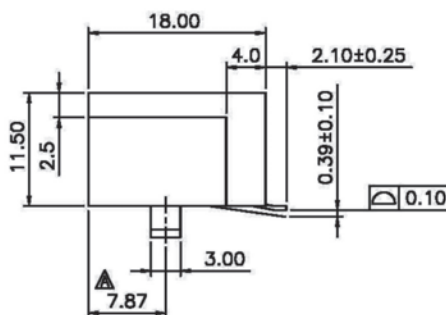
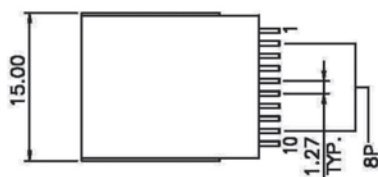
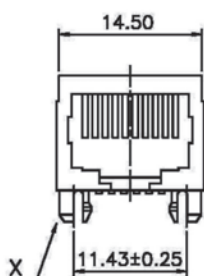
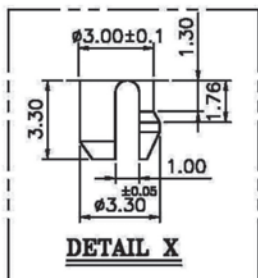
SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J $\frac{FC}{1}$ - $\frac{XX}{2}$ $\frac{X}{3}$ B - $\frac{X}{4}$

- MODULAR JACK TYPE:
"FC" VERY LOW PROFILE SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

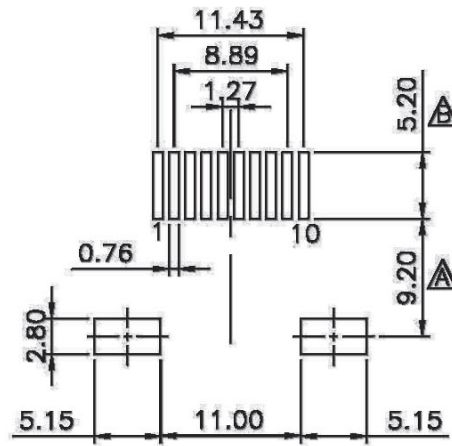
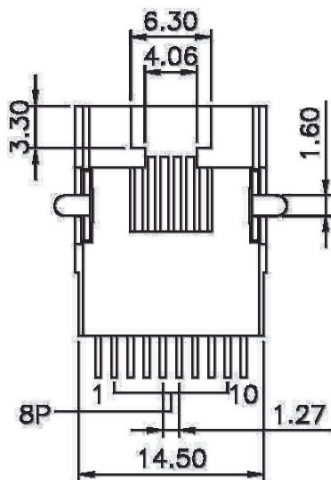
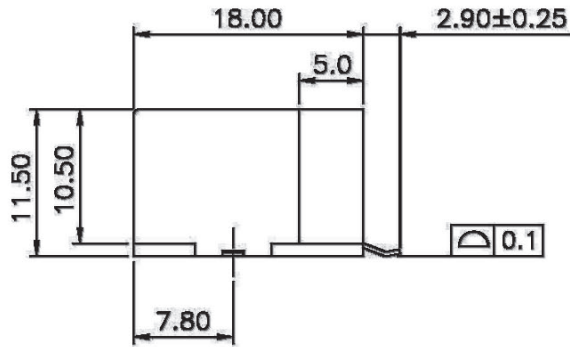
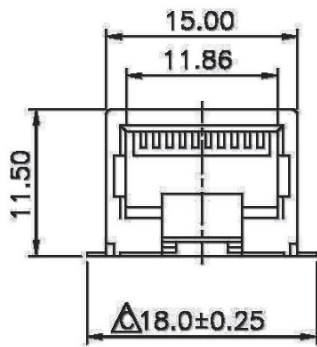
SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.50MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{FE}{1}$ - $\frac{x}{2}$ $\frac{x}{3}$ B - $\frac{x}{4}$

- MODULAR JACK TYPE:
"FE" VERY LOW PROFILE SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.60MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500 Megohms Min

Contact Resistance: 20 Milliohms Max.

Current Rating: 1.5 A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C To +85°C.

Operating: 500 Cycles Min.

MATERIALS

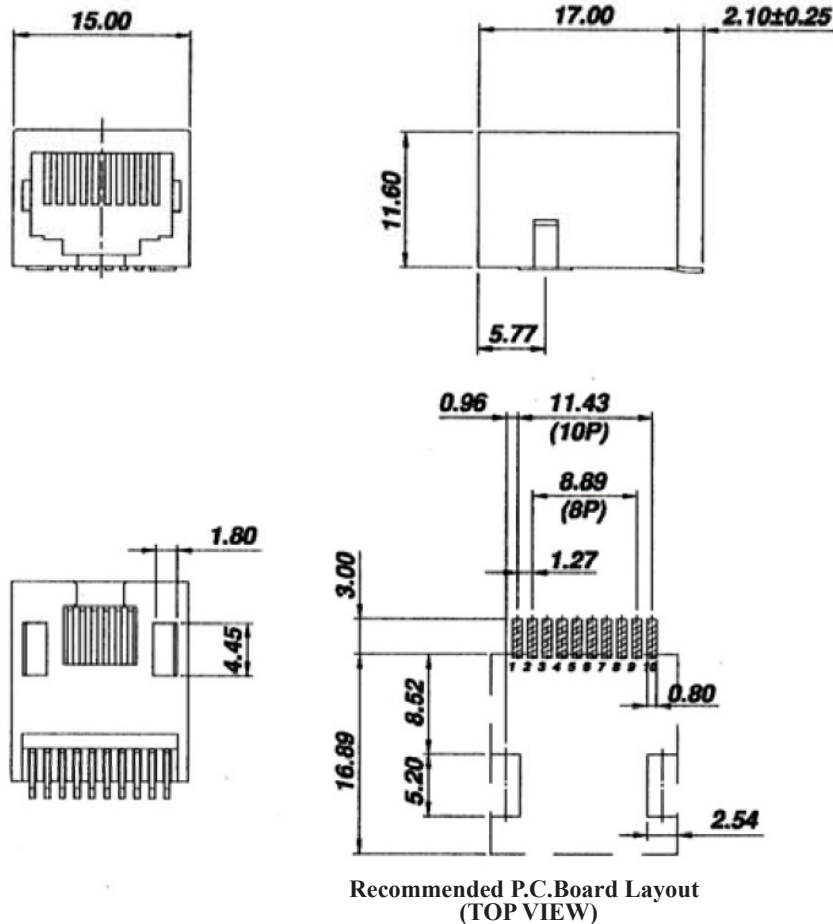
Housing: Nylon(UL 94V-0), Soldering Temperature:260°C

Color: Black

Spring Wire: 0.35mm Thickness Phosphor Bronze Over Nickel

Shield: Brass Plating Nickel

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J L P - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"08" 10P8C

"00" 10P10C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

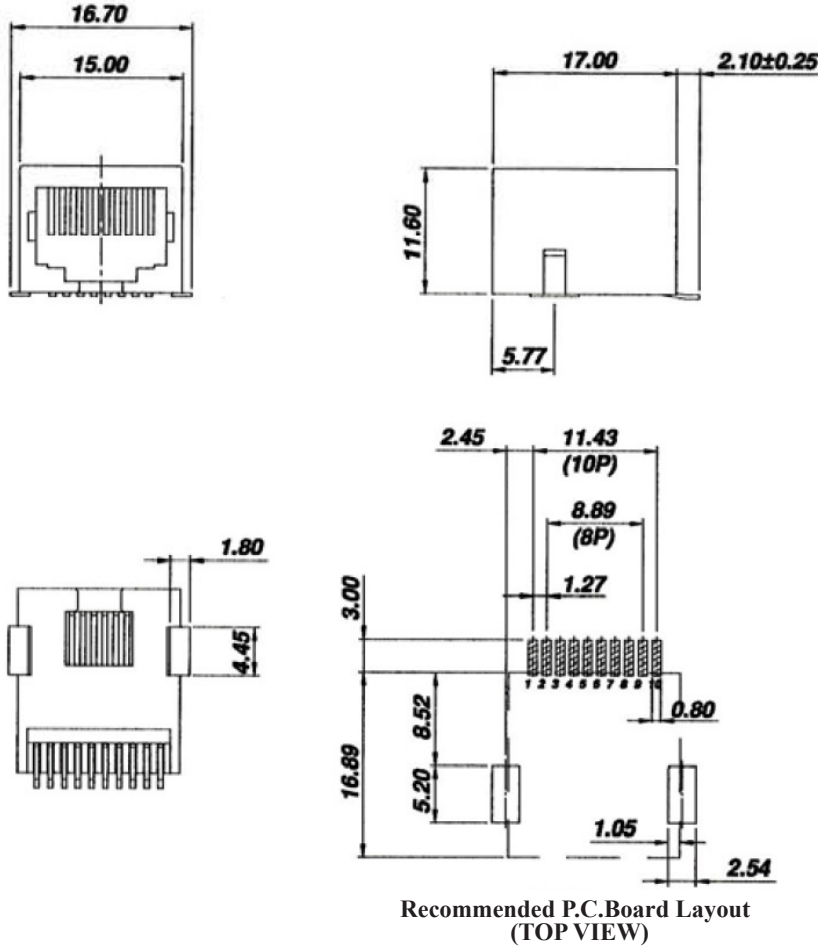
SIDE ENTRY MODULAR SMT JACK 10P PROFILE=11.60MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500 Megohms Min
Contact Resistance: 20 Milliohms Max.
Current Rating: 1.5 A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C To +85°C.
Operating: 500 Cycles Min.

MATERIALS

Housing: Nylon(UL 94V-0), Soldering Temperature:260°C
Color: Black
Spring Wire: 0.35mm Thickness Phosphor Bronze Over Nickel
Plating: Brass Plating Nickel
*** RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J L M - $\frac{x}{1}$ $\frac{x}{2}$ B - $\frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
"08" 10P8C
"00" 10P10C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
3. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

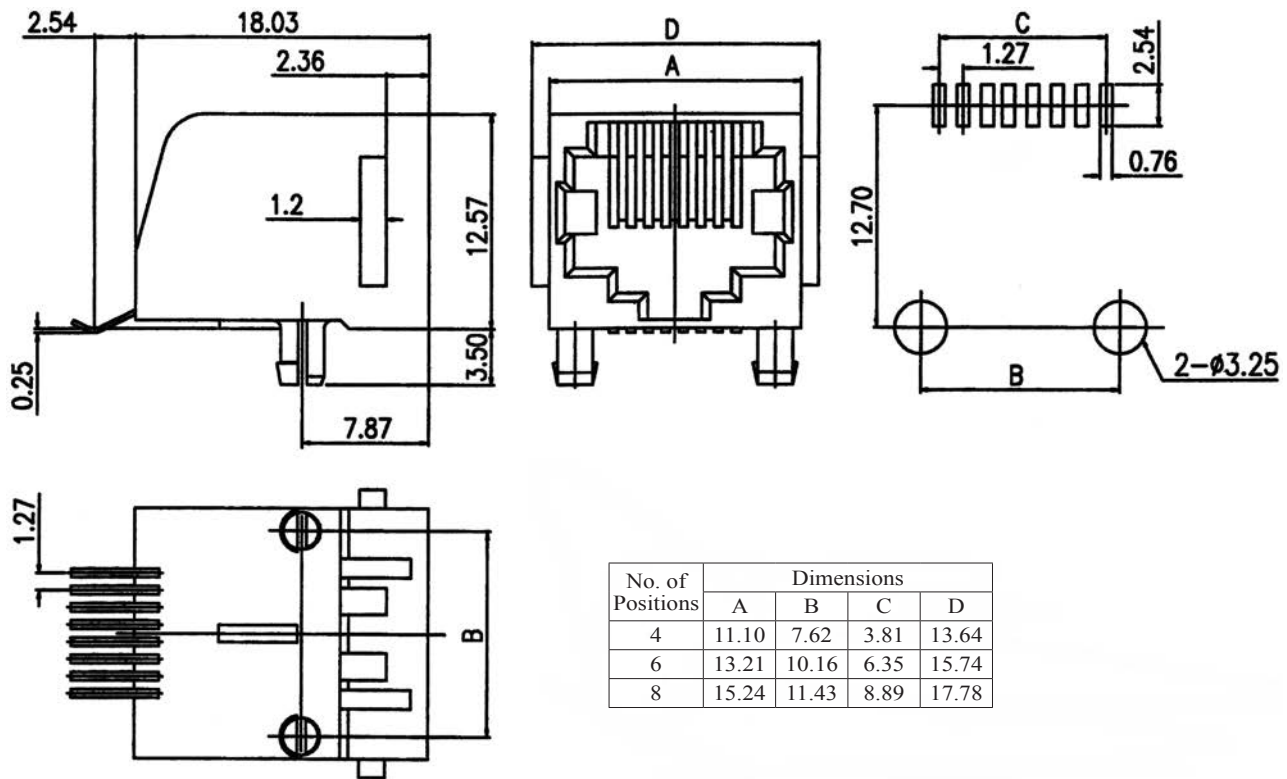
SIDE ENTRY MODULAR SMT JACK 4P+6P+8P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{XX}{1} - \frac{XXX}{2} \frac{B}{3} - \frac{X}{4}$

- PANEL STOP OPTION:
 "13" WITH PANEL STOP
 "14" W/O PANEL STOP
- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
 "88" 8P8C
 "44" 4P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

- PACKAGE OPTION:
 " " TRAY
 "R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 10P PROFILE=12.57MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

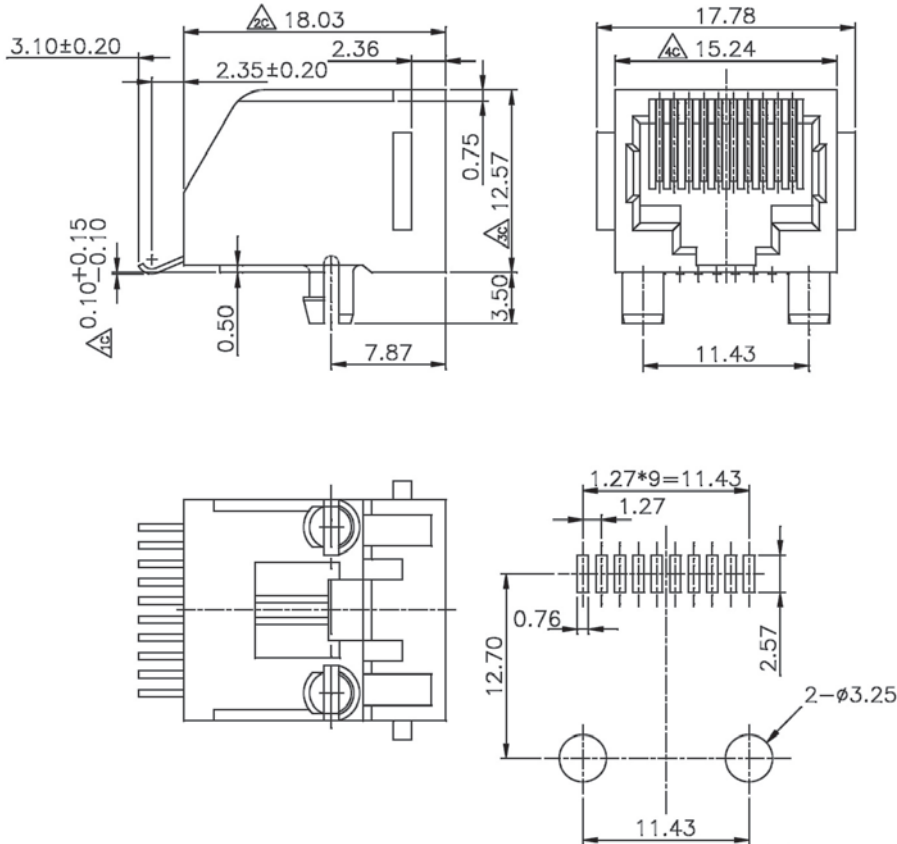
Soldering Temperature: 235°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

***RoHS & REACH compliant.**



Recommended P.C.Board Layout
(Top View)

ORDERING INFORMATION:

P/N M J $\frac{x}{1}x - \frac{x}{2}x \frac{x}{3}B - \frac{x}{4}$

1. PANEL STOP OPTION:
"13" WITH PANEL STOP
"14" WITHOUT PANEL STOP
2. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 4P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

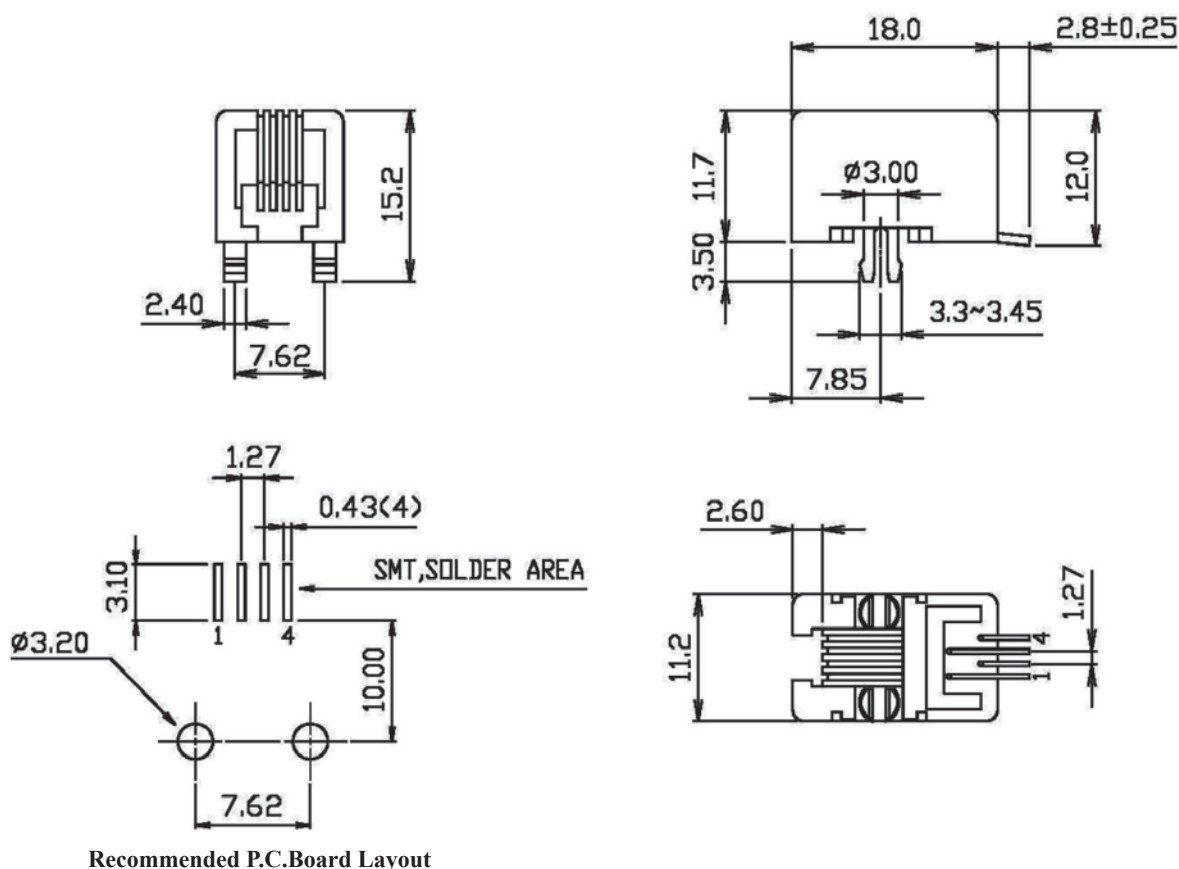
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{FA}{1} - \frac{44}{2} \frac{x}{3} B - \frac{x}{4}$

1. MODULAR JACK TYPE:
"FA" VERY LOW PROFILE SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

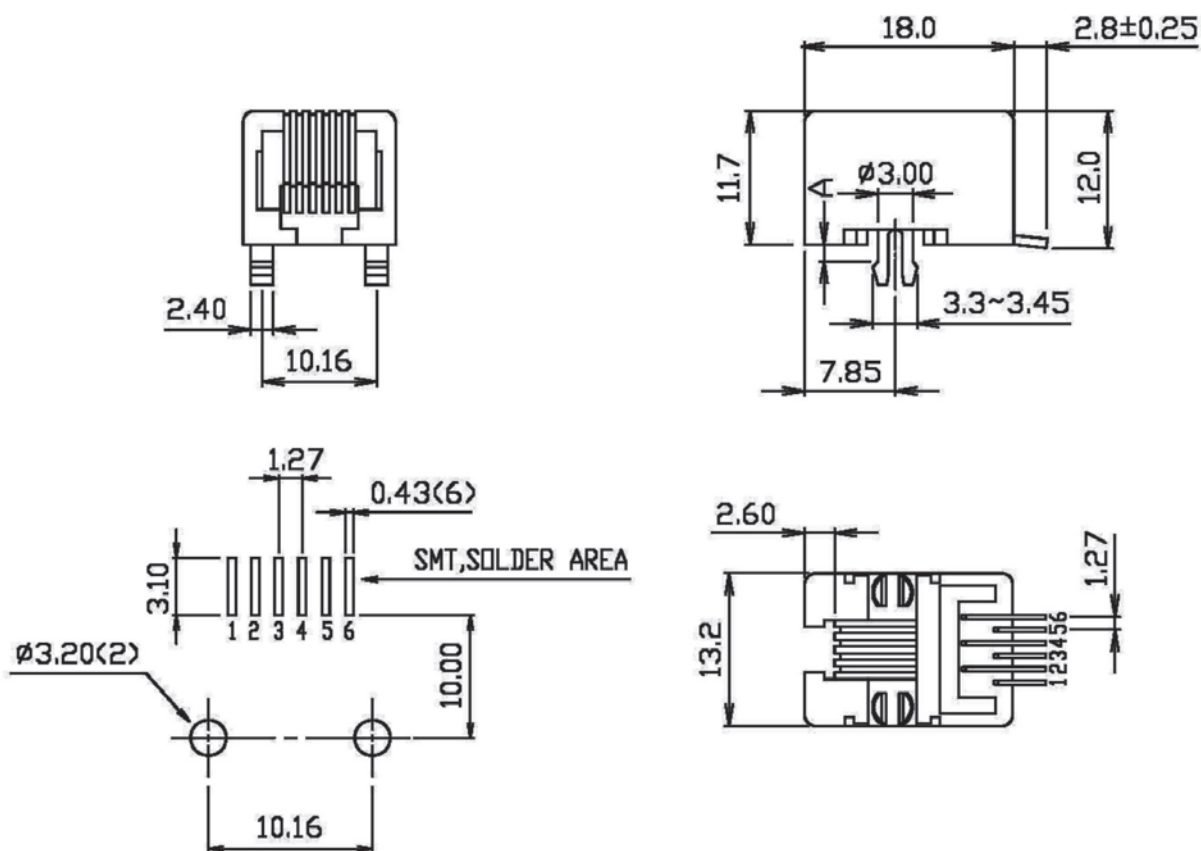
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

* RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{FA}{1}$ - $\frac{66}{2}$ x $\frac{B}{3}$ - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"FA" VERY LOW PROFILE SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"66" 6P6C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

SIDE ENTRY MULTI-PORT MODULAR SMT JACK 6P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

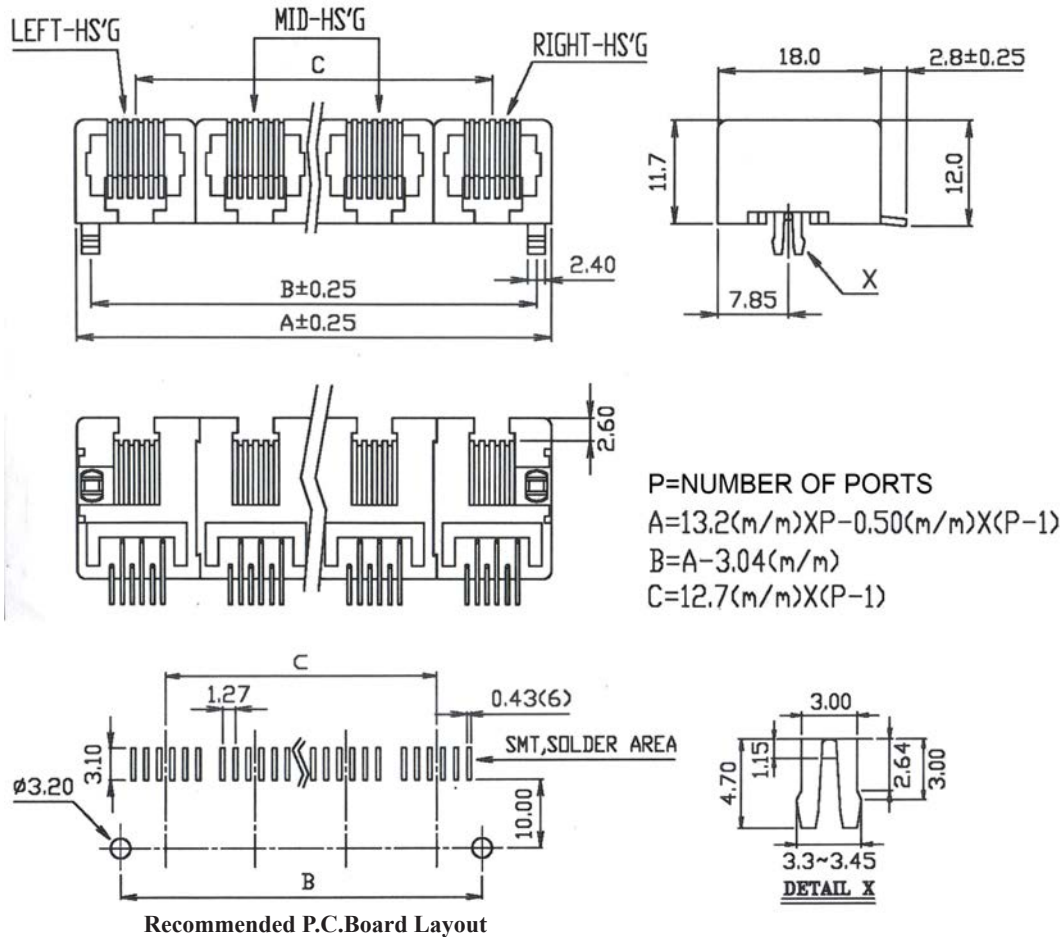
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

* RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{FB}{1}$ - $\frac{66}{2}$ $\frac{X}{3}$ B $\frac{X}{4}$

- MODULAR JACK TYPE:
"FB" VERY LOW PROFILE GANGED JACK
- NO. OF POSITIONS & CONTACTS:
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK
- NO. OF PORTS:
02, 03, 04

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=11.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

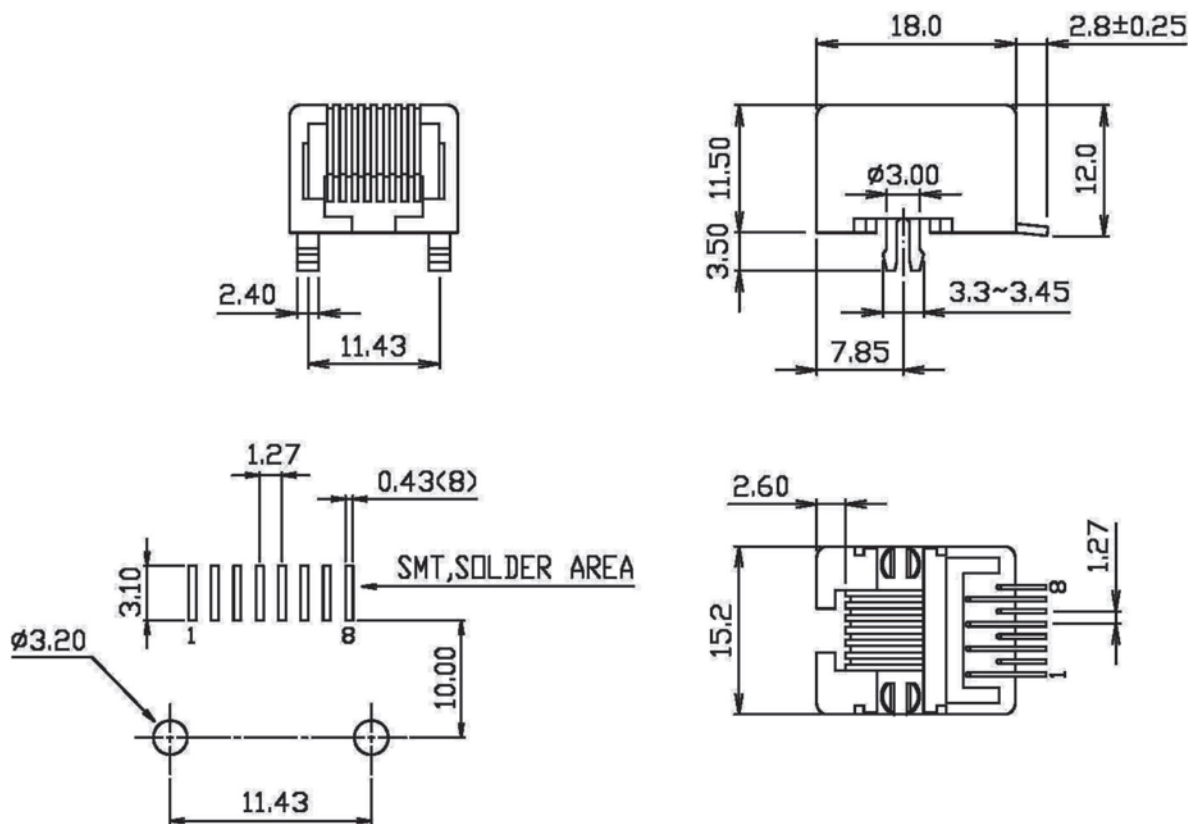
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

* RoHS & REACH compliant.



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{FA}{1} - \frac{88}{2} \frac{x}{3} B - \frac{x}{4}$

1. MODULAR JACK TYPE:
"FA" VERY LOW PROFILE SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK
5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

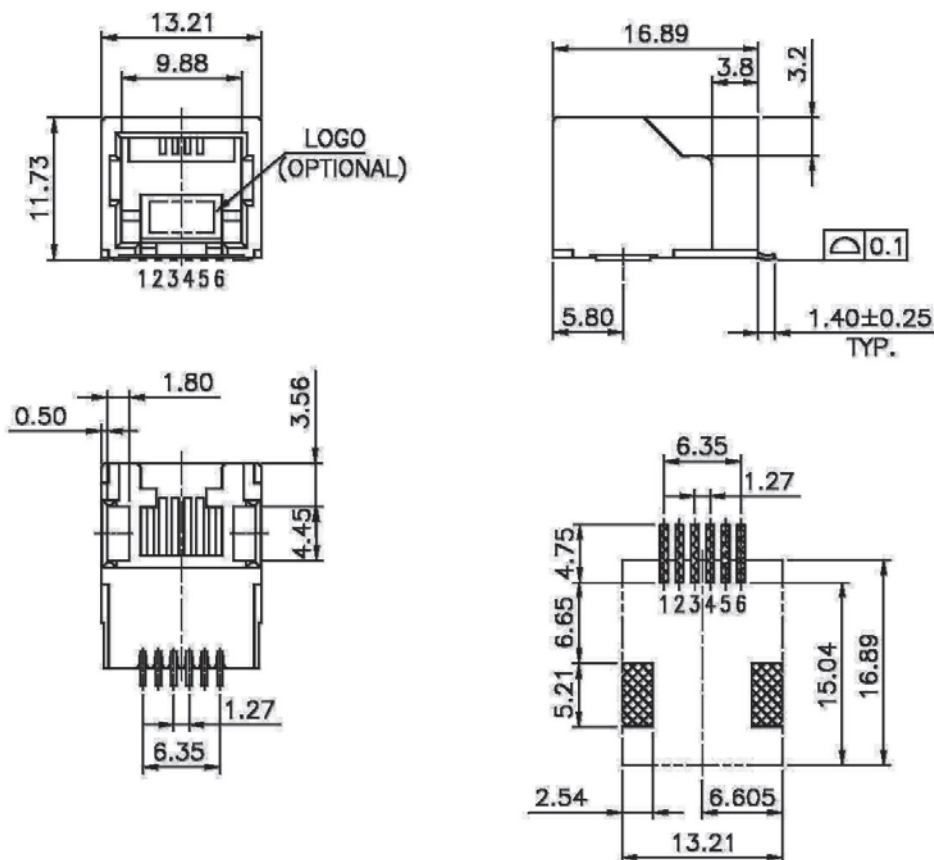
SIDE ENTRY MODULAR SMT JACK 6P PROFILE=11.73MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



Recommended P.C.Board Layout

ORDERING INFORMATION:

P/N M J $\frac{FD}{1}$ - $\frac{xx}{2}$ $\frac{xx}{3}$ B - $\frac{x}{4}$

1. MODULAR JACK TYPE:
"FD" VERY LOW PROFILE SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"66" 6P6C
"64" 6P4C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK

5. PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

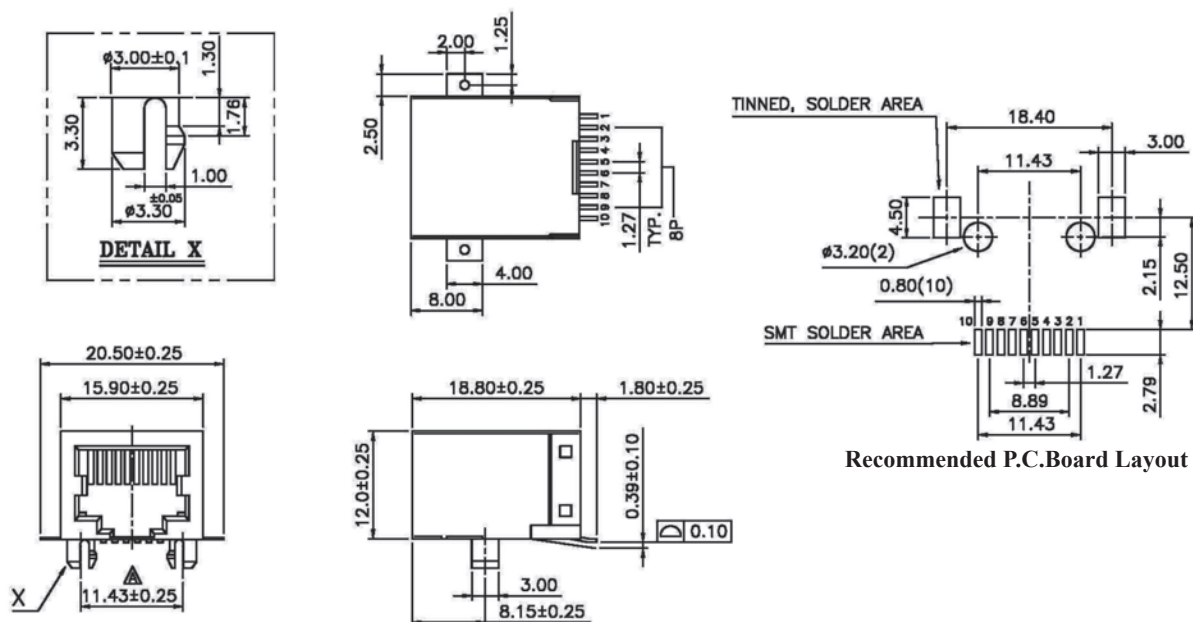
SIDE ENTRY MODULAR SMT JACK 10P PROFILE=12.00MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J F J - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{4}$

- MODULAR JACK TYPE:
"FJ" LOW PROFILE SMT TYPE
- NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- PACKAGE TYPE:
" " TRAY
"R" TAPE & REEL

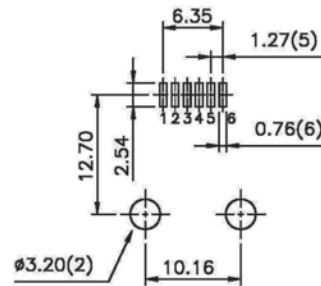
SIDE ENTRY MODULAR SMT JACK 6P OFF-SET TYPE PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

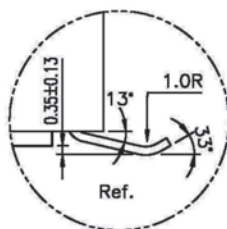
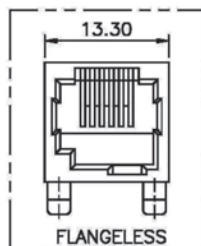
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

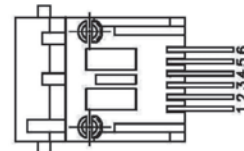
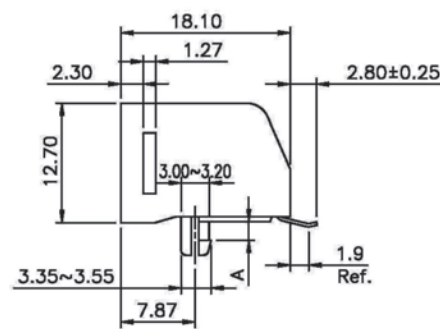
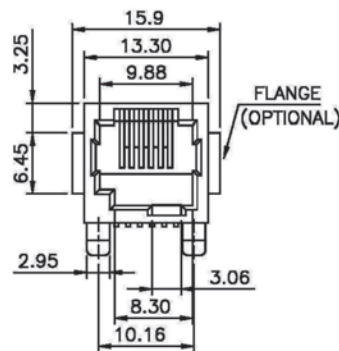
Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



Recommended P.C.Board Layout



DETAIL X



ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - 66 $\frac{x}{2}$ B $\frac{K}{345}$

- MODULAR JACK TYPE:
"FP" FLANGED OFF-SET TYPE
"FQ" FLANGELESS OFF-SET TYPE
- NO. OF POSITIONS & CONTACTS:
"66" 6P6C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK
- KEY OPTION:
"K" OFF-CENTER TYPE

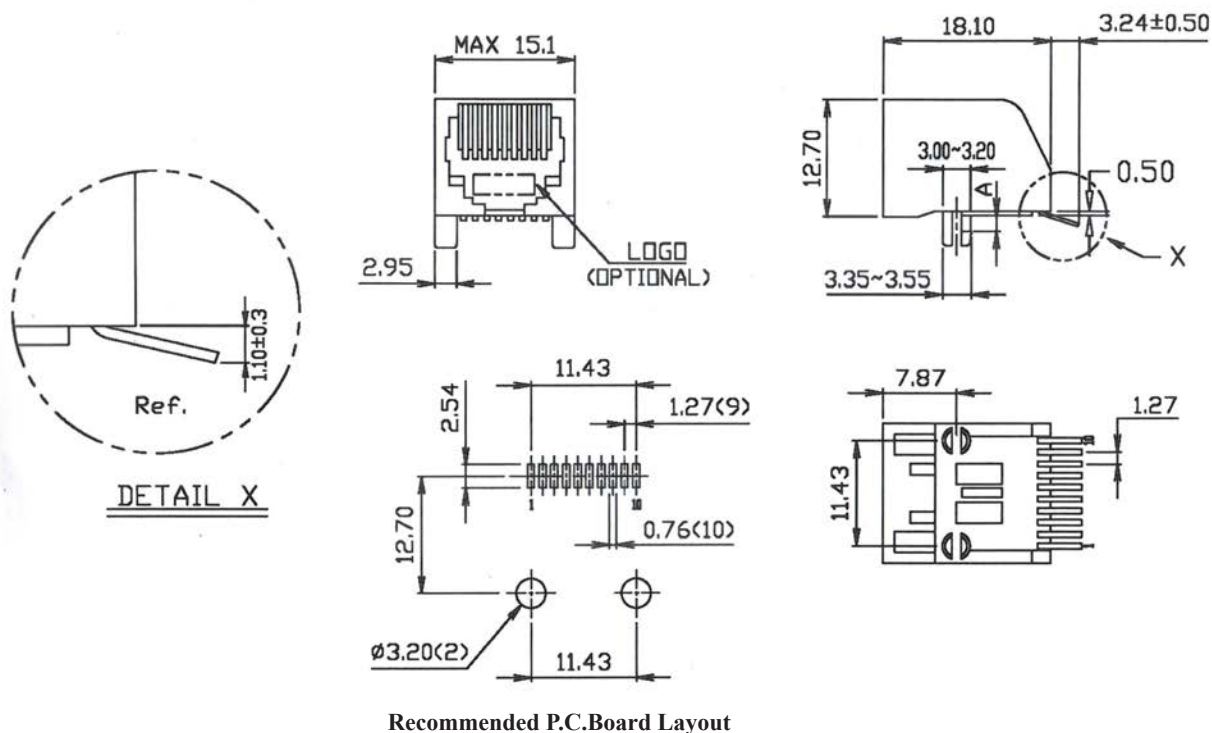
SIDE ENTRY MODULAR SMT JACK 10P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
*** RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J F N - x x x B

1. MODULAR JACK TYPE:
"FN" 10P SMT TYPE
2. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
"08" 10P8C
3. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
4. HOUSINH COLOR:
"B" BLACK

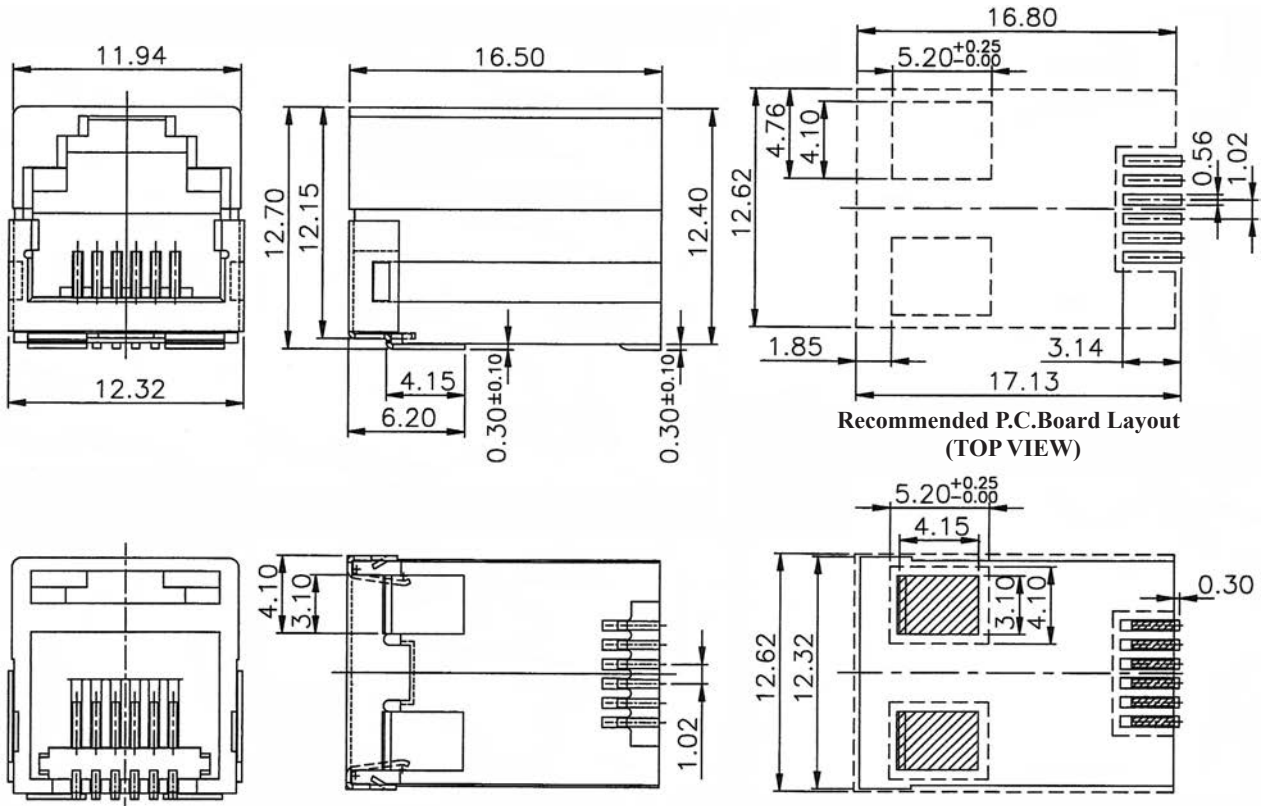
SIDE ENTRY UP LATCH SMT JACK 6P WITH SOLDER PAD PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N MJ4U - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
3. PACKAGE OPTION:
 " " TRAY
 "R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

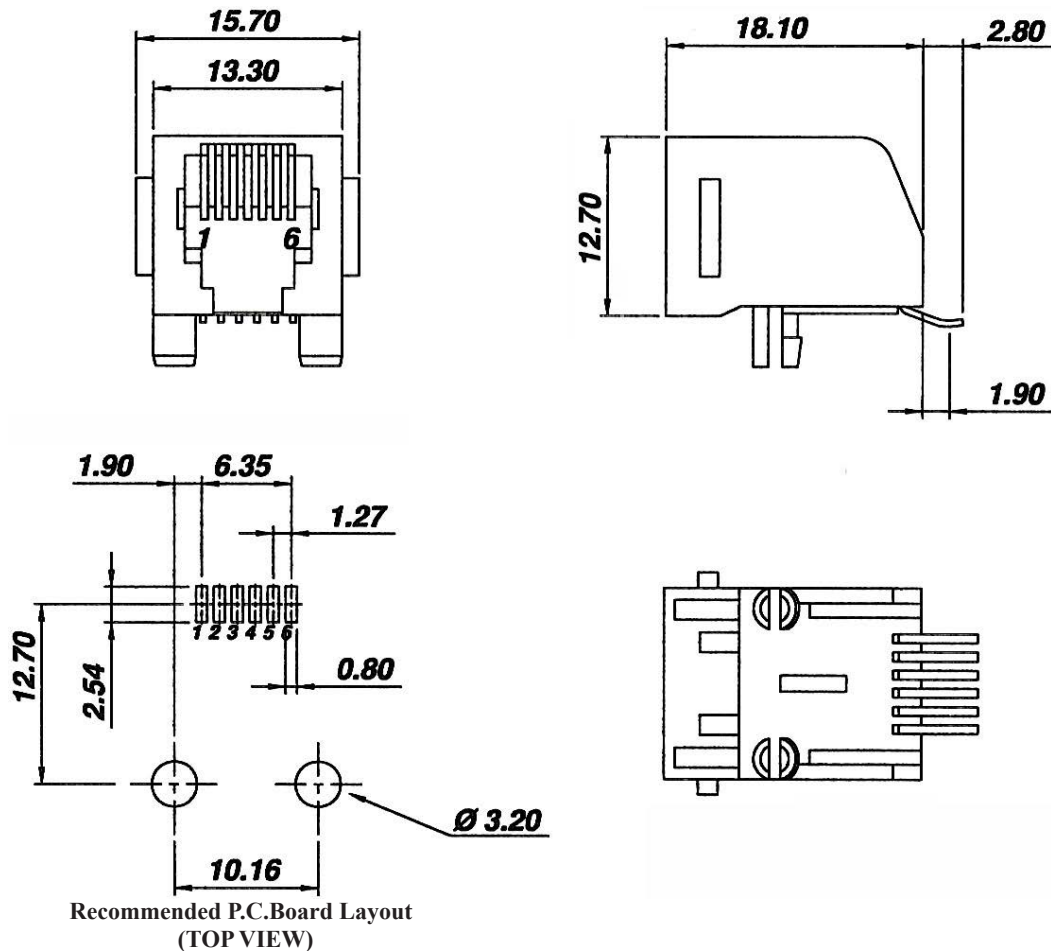
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R M - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

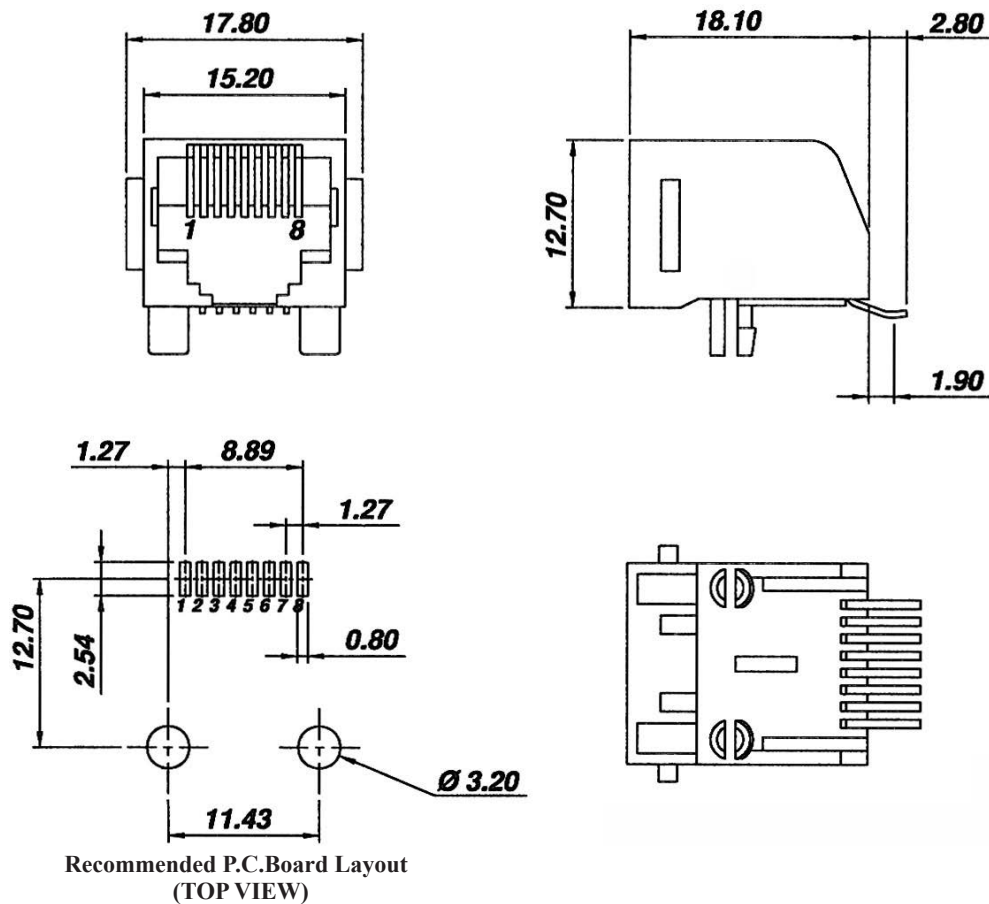
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R M - $\frac{88}{1} \frac{x}{2} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 6P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

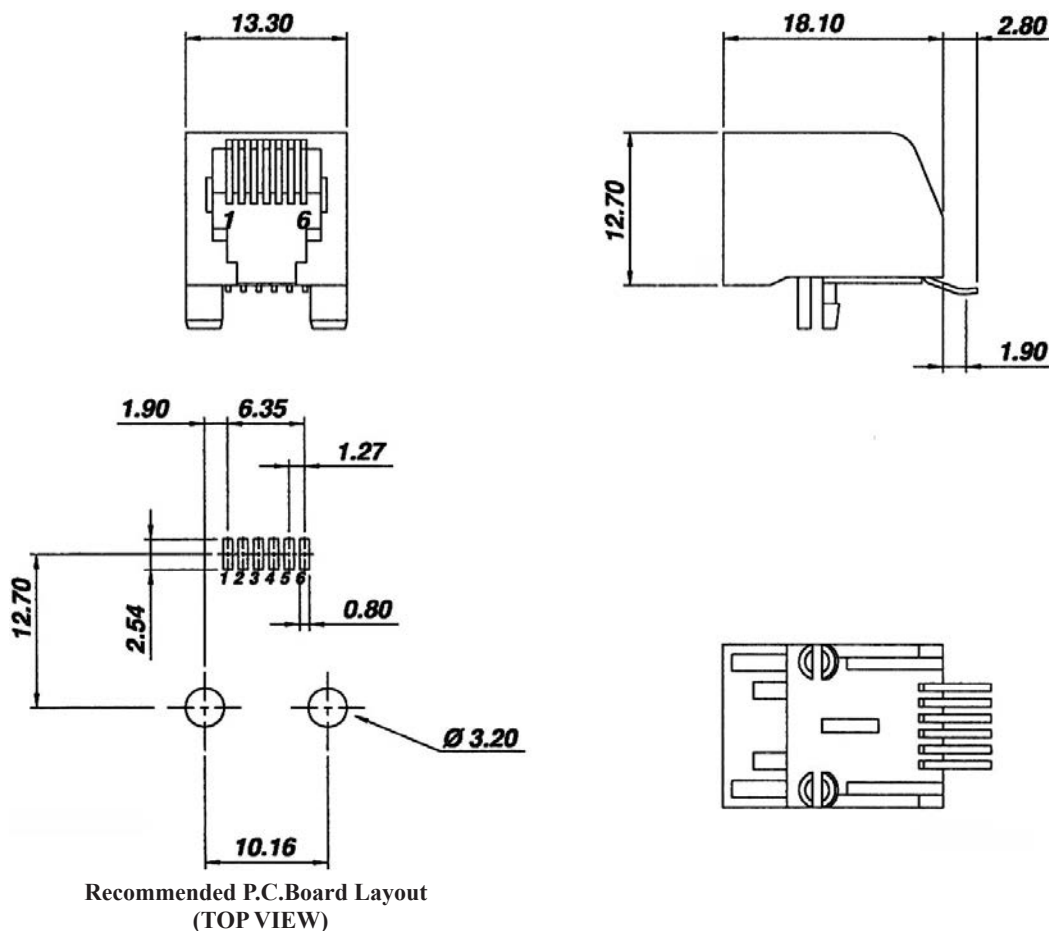
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R N - $\frac{x}{1} \frac{x}{2} \frac{x}{3} B - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C

"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

SIDE ENTRY MODULAR SMT JACK 8P PROFILE=12.70MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)

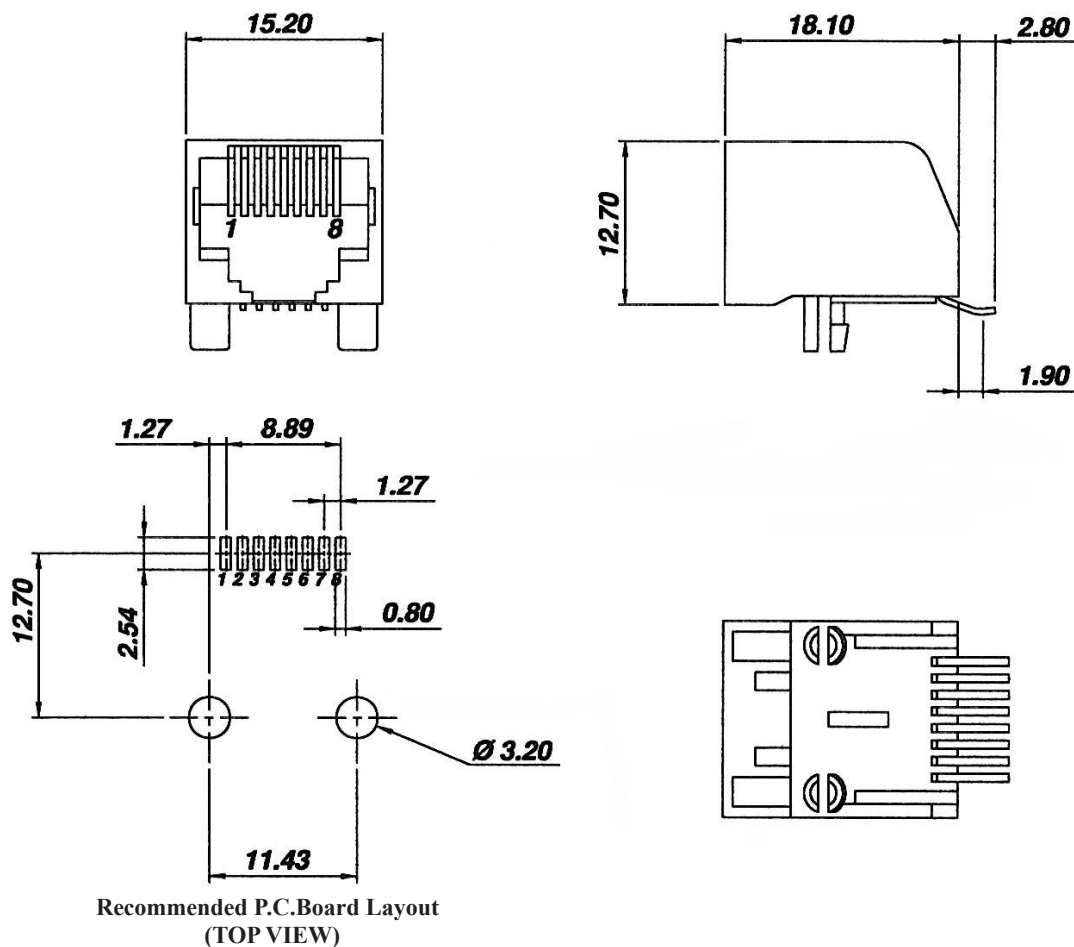
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J R N - $\frac{88}{1} \times \frac{B}{2} - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. PACKAGE OPTION:

" " TRAY

"R" TAPE & REEL

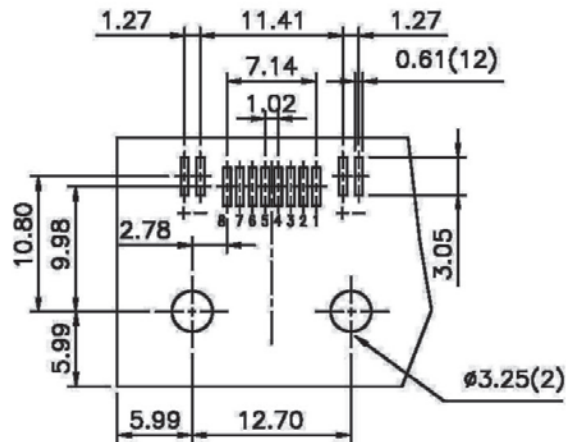
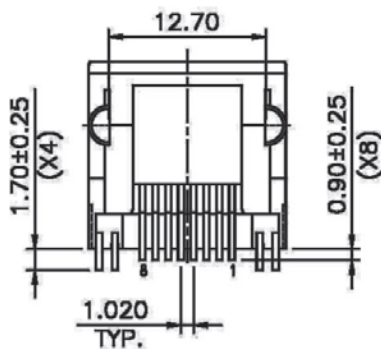
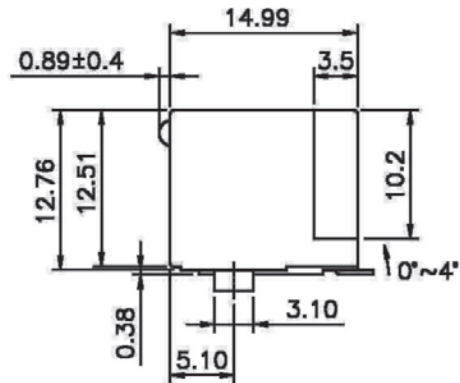
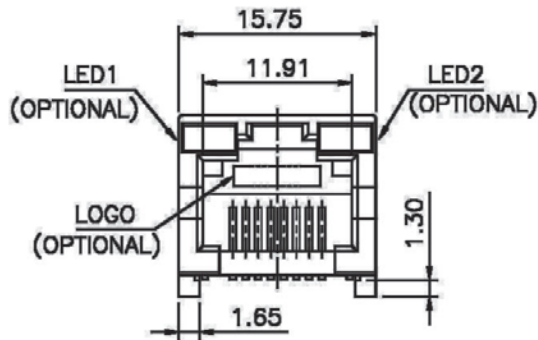
SIDE ENTRY MODULAR SMT JACK 8P WITH LED PROFILE=12.76MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
 * RoHS & REACH compliant.



Recommended P.C. Board Layout

ORDERING INFORMATION:

P/N M J FL - 8 8 X B X X
1 2 3 4

- MODULAR JACK TYPE:
"FL" RJ45 SMT TYPE WITH LED
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
- HOUSINH COLOR:
"B" BLACK

- LED COLORS:
"NN" LED 1/2 = GREEN/GREEN
"NY" LED 1/2 = GREEN/YELLOW
"YN" LED 1/2 = YELLOW/GREEN
"YY" LED 1/2 = YELLOW/YELLOW

NOTE: OTHER LED COLORS UPOM REQUEST!

SIDE ENTRY LOCK TYPE MODULAR PCB JACK 8P PROFILE=14.65MM (FULLY SHIELDED)

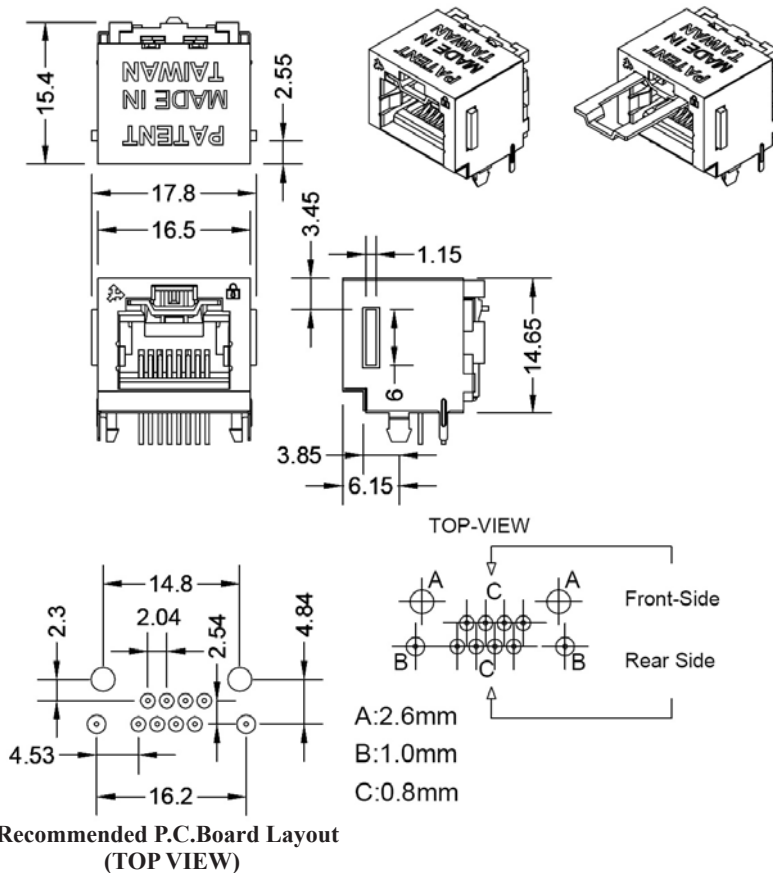
SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Lock Bar: Metal (SPCC)
Spring: SUS
Spring Base: Fireproof UL 94V-2-PC
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel

*RoHS & REACH compliant.



ORDERING INFORMATION:

P/N M J $\frac{x}{1}x$ - 88 $\frac{x}{2}x$ B

- PANEL STOP OPTION:
"K1" WITH PANEL STOP
"K2" WITHOUT PANEL STOP
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD (STANDARD)

NOTE: IF NECESSARY, USE LOCK KEY P/N LKEY-88MT (METAL)
 OR P/N LKEY-88Px (x=B=BLACK ; x=R=RED)!
 SEE PAGE N2291 & N2992!

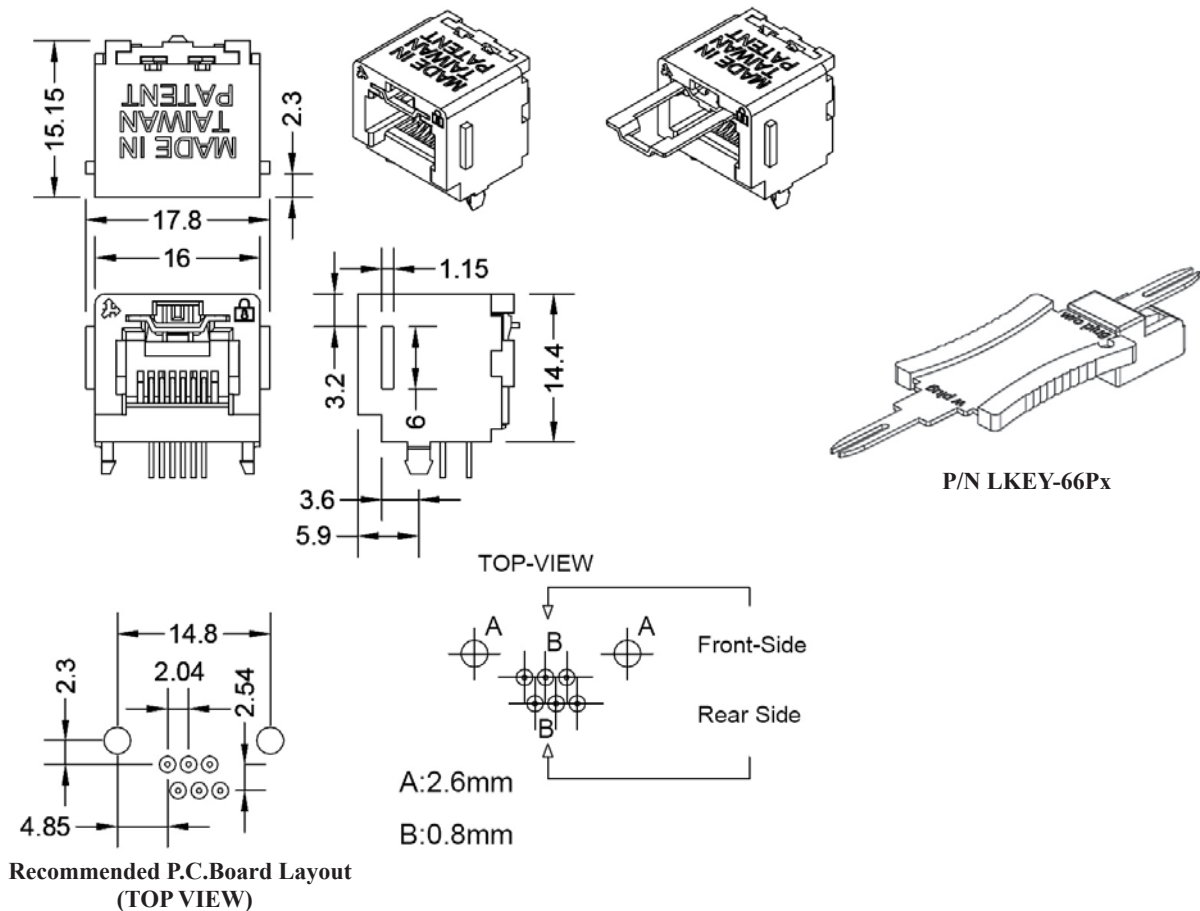
SIDE ENTRY LOCK TYPE MODULAR PCB JACK 6P PROFILE=14.40MM (UNSHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
***RoHS & REACH compliant.**



ORDERING INFORMATION:

P/N M J $\frac{x}{1} x - 66 \frac{x}{2} \frac{x}{3} B$

- PANEL STOP OPTION:**
 "K3" WITH PANEL STOP
 "K4" WITHOUT PANEL STOP
- NO. OF POSITIONS & CONTACTS:**
 "66" 6P6C
- CONTACT FINISH:**
 "A" 6 MICROINCH GOLD (STANDARD)
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

**NOTE: IF NECESSARY, USE LOCK KEY P/N LKEY-66MT (METAL)
 OR P/N LKEY-66Px (x=B=BLACK ; x=R=RED)!**
 SEE PAGE N2291 & N2992!

SIDE ENTRY LOCK TYPE MODULAR PCB JACK 8P PROFILE=14.40MM (UNSHIELDED)

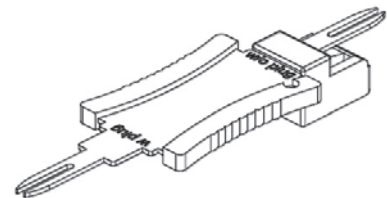
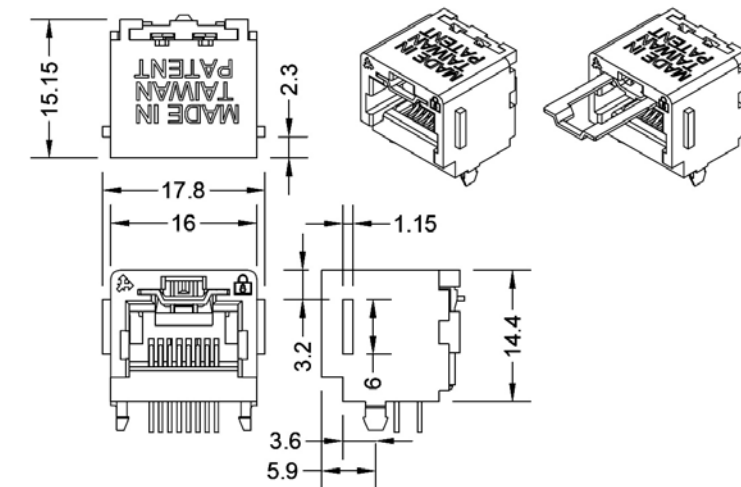
SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

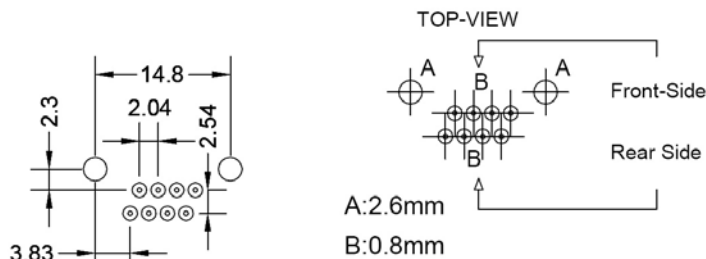
MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Lock Bar: Metal (SPCC)
Spring: SUS
Spring Base: Fireproof UL 94V-2-PC
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel

*RoHS & REACH compliant.



P/N LKEY-88Px



Recommended P.C.Board Layout
(TOP VIEW)

ORDERING INFORMATION:

P/N M J $\frac{x}{1}$ - 88 $\frac{x}{2}$ B $\frac{x}{3}$

- PANEL STOP OPTION:
"K3" WITH PANEL STOP
"K4" WITHOUT PANEL STOP
- NO. OF POSITIONS & CONTACTS:
"88" 8P8C
- CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD (STANDARD)

NOTE: IF NECESSARY, USE LOCK KEY P/N LKEY-88MT (METAL)
OR P/N LKEY-88Px (x=B=BLACK ; x=R=RED)!
SEE PAGE N2291 & N2992!

METALLIC LOCK KEY WITH PVC MOLDED FOR LOCKING & SECURITY RJ45/RJ12 JACK

MATERIALS

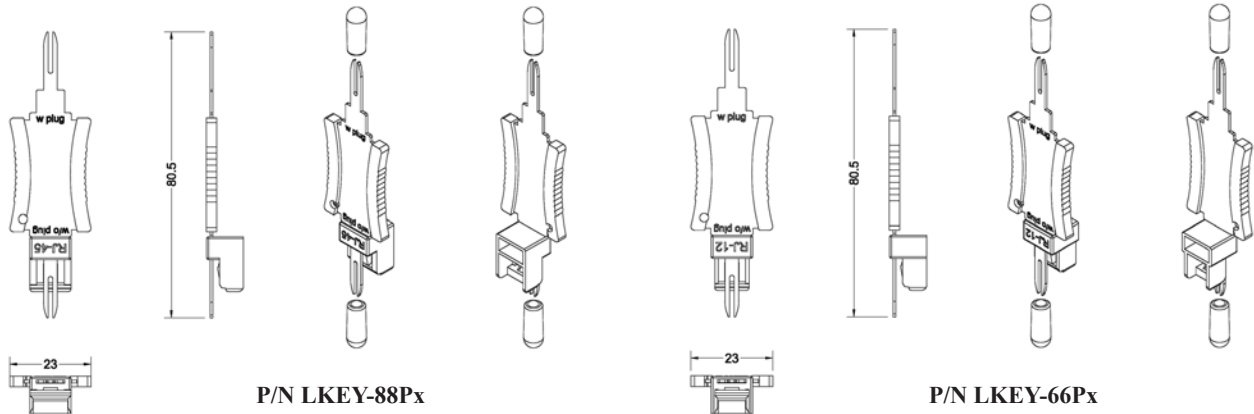
Metal: SPCC

Molding: PVC

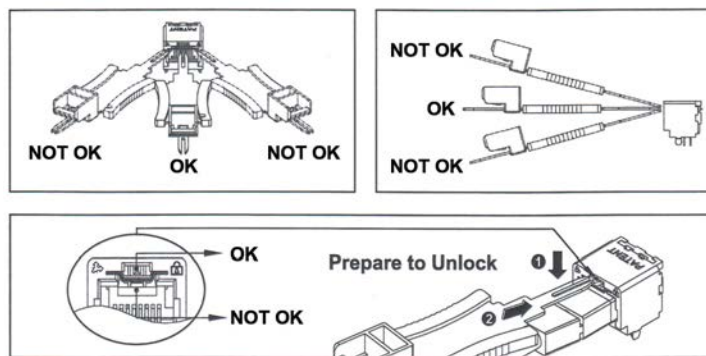
RJ45: PC

Protect Cover: PVC

*RoHS & REACH compliant.



Caution !



Security Applications

Banks, Hotels, Airports, Schools, Hospitals, Retail Stores,
IP Camera Surveillance, Military Equipment.

Vibration Applications

Trains, Aircraft, Vibrating Machinery, Transportation Equipment,
Other Moving Vehicles

ORDERING INFORMATION:

P/N LKEY - $\frac{xx}{1}$ P $\frac{x}{2}$

1. RJ TYPE:

"88" FOR 8P8C (RJ45)

"66" FOR 6P6C (RJ12)

2. PVC COLOR:

"B" BLACK

"R" RED

METALLIC LOCK KEY WITHOUT PVC MOLDED FOR LOCKING & SECURITY RJ45/RJ12 JACK

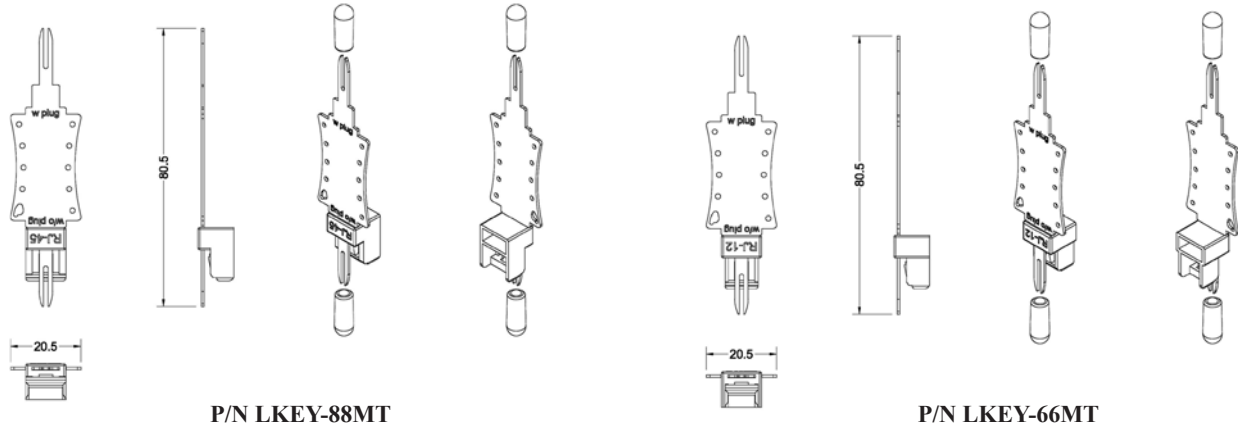
MATERIALS

Metal: SPCC

RJ45: PC

Protect Cover: PVC

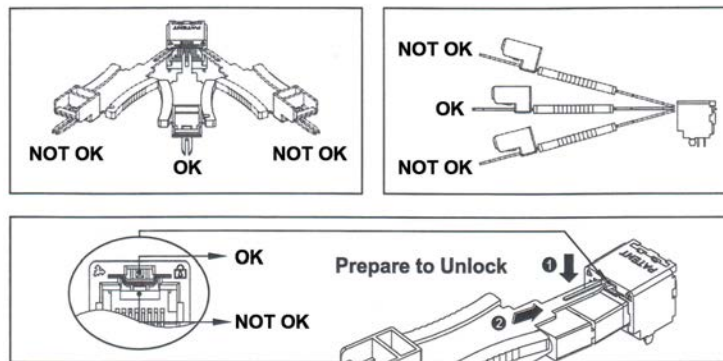
*RoHS & REACH compliant.



P/N LKEY-88MT

P/N LKEY-66MT

Caution !



Security Applications

Banks, Hotels, Airports, Schools, Hospitals, Retail Stores,
IP Camera Surveillance, Military Equipment.

Vibration Applications

Trains, Aircraft, Vibrating Machinery, Transportation Equipment,
Other Moving Vehicles

ORDERING INFORMATION:

P/N LKEY - $\frac{x}{T}$ MT

1. RJ TYPE:

"88" FOR 8P8C (RJ45)

"66" FOR 6P6C (RJ12)